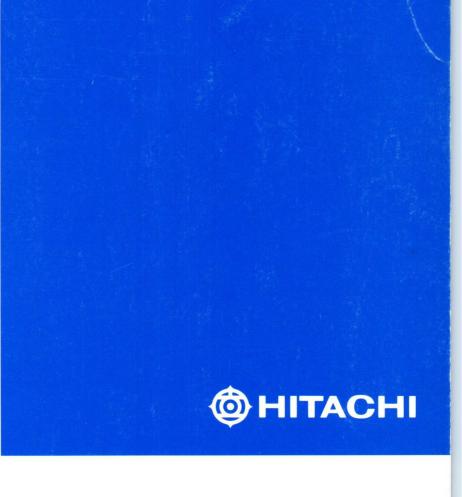
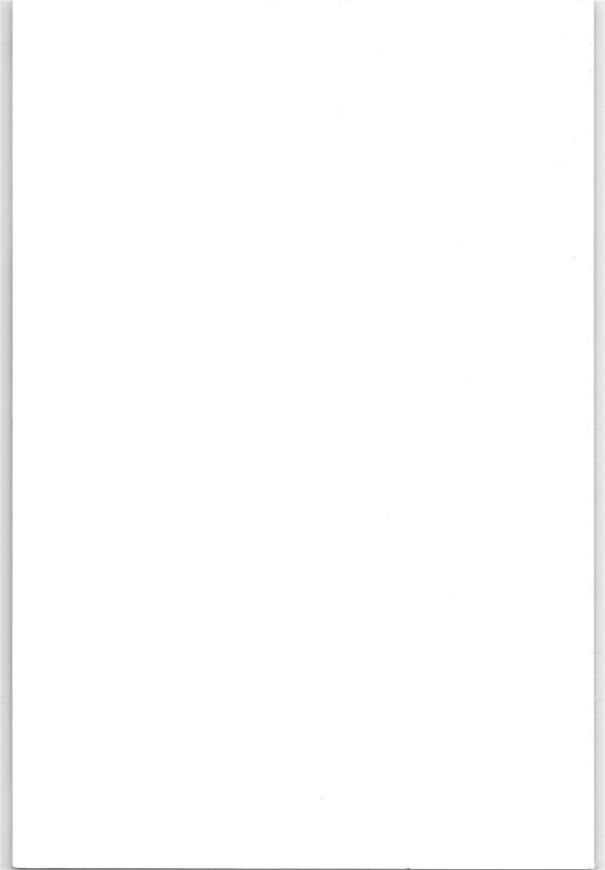
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8-/16-Bit Microprocessor

1986





HITACHI MICROCOMPUTER DATA BOOK 8-BIT-16-BIT MICROPROCESSOR

1986

MEDICAL APPLICATIONS

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NOTICE

The information in this document has been carefully checked. However, no responsibility is assumed for inaccuracies.

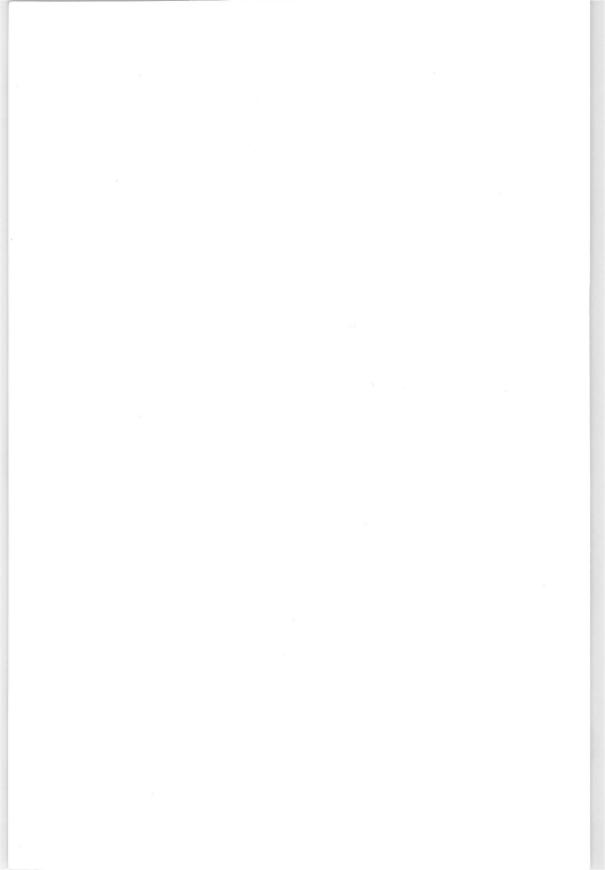
The example of an applied circuit or combination with other equipment shown herein indicates characteristics and performance of a semiconductor-applied products. The Company shall assume to responsibility for any problem involving a patent caused when applying the descriptions in the example.

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HD68000/HD68HC000	AD-E0084A



GENERAL INFORMATION

- Quick Reference Guide
- Introduction of Packages
- Reliability and Quality Assurance
- Reliability Test Data of Microcomputer
- Program Development and Support System



QUICK REFERENCE GUIDE

■ NMOS 8-BIT MICROPROCESSOR

Type No.	HD6800 HD68A00 HD68B00	HD6802	HD6802W	HD6803 HD6803-1	HD6809 HD68A09 HD68B09	HD6809E HD68A09E HD68B09E
Clock Frequency (MHz)	1.0 (HD6800) 1.5 (HD68A00) 2.0 (HD68B00)	1.0	1.0	1.0 (HD6803) 1.25 (HD6803-1)	1.0 (HD6809) 1.5 (HD68A09) 2.0 (HD68B09)	1.0 (HD6809E) 1.5 (HD68A09E 2.0 (HD68B09E
Supply Voltage (V)	5.0	5.0	5.0	5.0	5.0	5.0
Operating Temperature *	−20~+75	-20~+75	-20~+75	0~+70	−20~+75	-20~+75
RAM (byte)	-	128	256	128	-	-
Oscillator	-	Yes	Yes	Yes	Yes	-
Package	DP-40	DP-40	DP-40	DP-40	DP-40	DP-40
Features	•65k bytes address space	Internal oscillate added to the HE 32 byte RAM Baup possible	06800	Upward instruction compatibility with the HD6800 On-chip SCI and timer	• The highest version of the HMCS6800 family • Powerful ad- dressing modes • Easy relocat- able/reentrant programming	•Full software compatibility with the HD6809 •Bus employment on time sharing basis •External clock
Compatibility	MC6800 MC68A00 MC68B00	MC6802	_	MC6803 MC6803-1	MC6809 MC68A09 MC68B09	MC6809E MC68A09E MC68B09E
Reference Page	41	73	86	99	126	158

^{*} Wide Temperature Range ($-40^{\circ}+85^{\circ}$ C) version is available.

■ CMOS 8-BIT MICROPROCESSOR

Type No.	HD6303R HD63A03R HD63B03R	HD6303X HD63A03X HD63B03X	HD6303Y HD63A03Y HD63B03Y
Clock Frequency (MHz)	1.0 (HD6303R) 1.5 (HD63A03R) 2.0 (HD63B03R)	1.0 (HD6303X) 1.5 (HD63A03X) 2.0 (HD63B03X)	1.0 (HD6303Y) 1.5 (HD63A03Y) 2.0 (HD63B03Y)
Supply Voltage (V)	5.0	5.0	5.0
Operating Temperature* (°C)	0 ~ +70	0 ~ +70	0 ~ +70
RAM (byte)	128	192	256
External Memory Expansion (byte)	65k	65k	65k
Package	DP-40, FP-54, CG-40, CP-52	DP-64S, FP-80, CP-68	DP-64S, FP-64
Features	On-chip timer and synchronc Upward instruction compatil Low power consumption mo	pility with the HD6800	
Reference Page	194	227	266

^{*}Wide Temperature Range ($-40^{\circ}+85^{\circ}$ C) version is available. CP/M $^{\circledR}$ is the registered trade mark of Digital Research Inc.

HD6305X2	HD6305Y2	T	
HD6305X2 HD63A05X2 HD63B05X2	HD6305Y2 HD63B05Y2 HD63B05Y2	HD63B09E HD63C09E	HD64A180R0 HD64B180R0
1.0 (HD6305X2) 1.5 (HD63A05X2) 2.0 (HD63B05X2)	1.0 (HD6305Y2) 1.5 (HD63A05Y2) 2.0 (HD63B05Y2)	2.0 (HD63B09E) 3.0 (HD63C09E)	4.0 (HD64A180R0) 6.0 (HD64B180R0)
5.0	5.0	5.0	5.0
0 ~ +70	0 ~ +70	-20 ∼ +75	0~+70
128	256	_	_
16k	16k	65k	512k
DP-64S, FP-64	DP-64S, FP-64	DP-40	DP-64S, FP-80, CP-68
On-chip timer and synchronou Powerful bit manipulation inst Low power consumption mode	ruction	Software compatibility with the HD6809E Easy relocatable/ reentrant programming Flexible system expansion capabilities	On-chip MMU, DMAC, synchronous/asynchro- nous SCI and timer Software compatibility with CP/M-80®
310	310	344	381

QUICK REFERENCE GUIDE ----

■ NMOS 16-BIT MICROPROCESSOR

Type No.	HD68000-6 HD68000-8 HD68000-10 HD68000-12	HD68000Y6 HD68000Y8 HD68000Y10 HD68000Y12	HD68000P6 HD68000P8	HD68000PS6 HD68000PS8	HD68000CP6 HD68000CP8
Clock Frequency (MHz)	6.0(HD68000-6) 8.0(HD68000-8) 10.0(HD68000-10) 12.5(HD68000-12)	6.0(HD68000Y6) 8.0(HD68000Y8) 10.0(HD68000Y10) 12.5(HD68000Y12)	6.0(HD68000P6) 8.0(HD68000P8)	6.0(HD68000PS6) 8.0(HD68000PS8)	6.0(HD68000CP6) 8.0(HD68000CP8)
Supply Voltage (V)			5.0		
Operating Temperature (°C)			0~+70		
Power Dissipation (W)		8MHz, 10MHz), 12.5 MHz)		0.9 (f = 8MHz)	
Package	DC-64	PGA-68	DP-64	DP-64S	CP-68
Feature	Н	ligh performance MPI	J featuring 32-bit da	ta processing functio	n
Compatibility	MC68000L6 MC68000L8 MC68000L10 MC68000L12	MC68000R6 MC68000R8 MC68000R10 MC68000R12	MC68000P6 MC68000P8		MC68000FN6 MC68000FN8
Reference Page	523	523	523	523	

■ CMOS 16-BIT MICROPROCESSOR

Type No.	HD68HC000-8 HD68HC000-10 HD68HC000-12	HD68HC000Y8 HD68HC000Y10 HD68HC000Y12	HD68HC000P8 HD68HC000P10 HD68HC000P12	HD68HC000PS8 HD68HC000PS10 HD68HC000PS12	HD68HC000CP8 HD68HC000CP10 HD68HC000CP12
Clock Frequency (MHz)	8.0(HD68HC000-8) 10.0(HD68HC000-10) 12.5(HD68HC000-12)				8.0(HD68HC000CP8) 10.0(HD68HC000CP10) 12.5(HD68HC000CP12)
Supply Voltage (V)			5.0		
Operating Tempera- ture (°C)			0 ~ +70		
Current Dissipa- tion (mA)			25 (f = 8 MHz) 30 (f = 10 MHz) 35 (f = 12.5 MHz)		
Package	DC-64	PGA-68	DP-64	DP-64S	CP-68
Feature		High performan	ce MPU featuring 32-bit	data processing function	
Compati- bility	MC68HC000L8 MC68HC000L10 MC68HC000L12	MC68HC000R8 MC68HC000R10 MC68HC000R12	MC68HC000G8 MC68HC000G10 MC68HC000G12		MC68HC000FN8 MC68HC000FN10 MC68HC000FN12
Reference Page	523	523	523	523	523

INTRODUCTION OF PACKAGES

Hitachi microcomputer devices include various types of package which meet a lot of requirements such as ever smaller, thinner and more versatile electric appliances. When selecting a package suitable for the customers' use, please refer to the following for Hitachi microcomputer packages.

multi-function types, applicable to each kind of mounting method. Also, plastic and ceramic materials are offered according to use.

Fig. 1 shows the package classification according to the mounting types on the Printed Circuit Board (PCB) and the materials.

1. Package Classification

There are pin insertion types, surface mounting types and

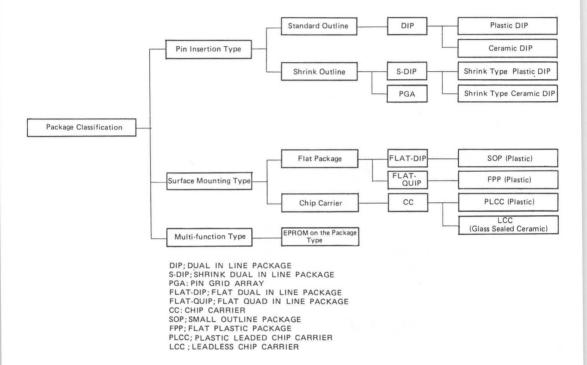


Fig. 1 Package Classification according to the Mounting Type on the Printed Circuit Board and the Materials.

2. Type No. and Package Code Indication

Type No. of Hitachi microprocessor is followed by package material and outline specifications, as shown below. The package type used for each device is identified by code as follows, illustrated in the data sheet of each device.

When ordering, please write the package code beside the type number.

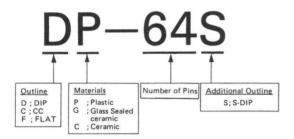
Type No. Indication



Package designation

CP ; PLCC
CG ; LCC
Y ; PGA (16-bit microcomputer device)

Package Code Indication



(Note) PGA packages of 16-bit microcomputer devices have a different indication.



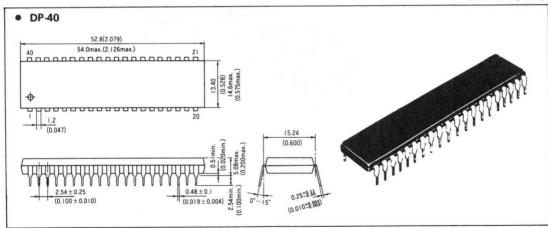
3. Package Dimensional Outline Hitachi microprocessor employs the packages shown in

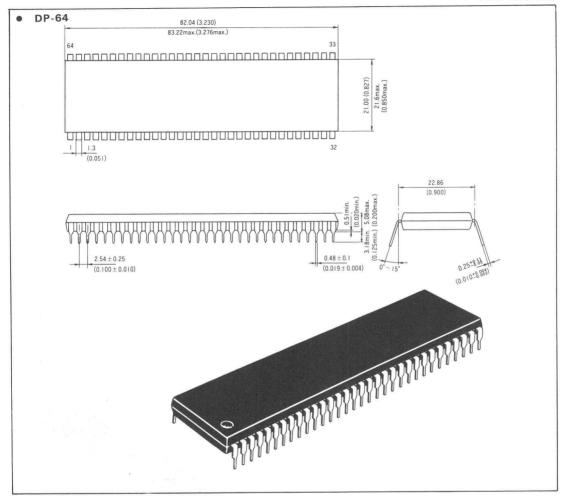
Table 1 according to the mounting method on the PCB.

Table 1 Package List

Method of Mounting Package Classification		Package Material	Package Code	
	Standard Outline (DIP)		Plastic	DP-40 DP-64
D	Standard Gatimo (,	Ceramic	DC-64
Pin Insertion Type	St. i. t. O. ali	S-DIP	Plastic	DP-64S
	Shrink Outline	PGA	Glass Sealed Ceramic	PGA-68
	Flat Package	FLAT-QUIP (FPP)	Plastic	FP-54 FP-64 FP-80
Surface Mounting Type		PLCC	Plastic	CP-52 CP-68
	Chip Carrier	LCC	Glass Sealed Ceramic	CG-40

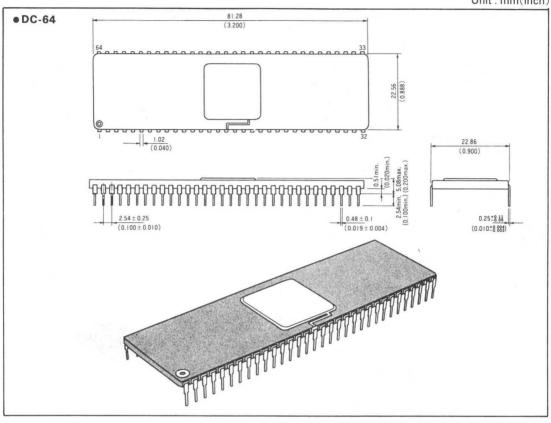




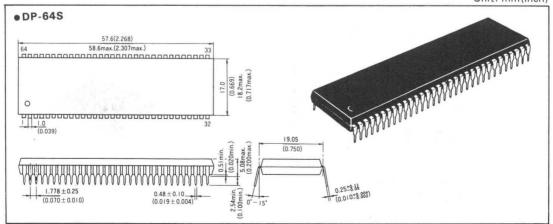


Ceramic DIP

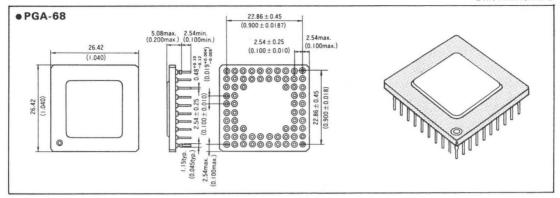
Unit: mm(inch)



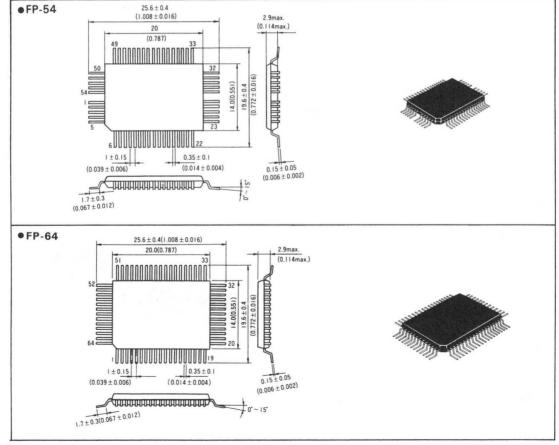
Shrink Type Plastic DIP

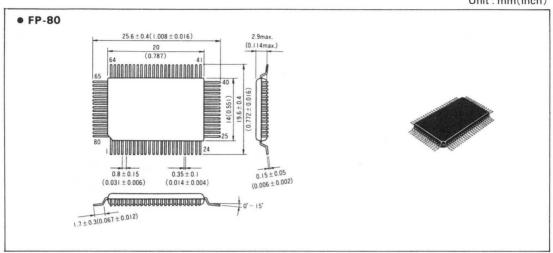




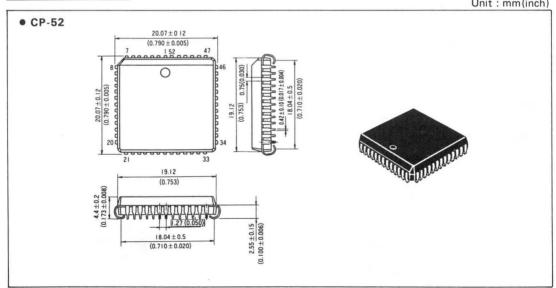


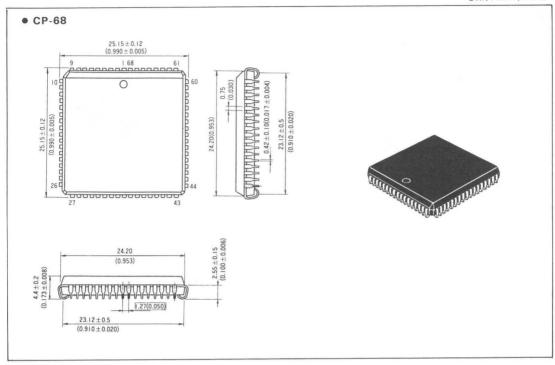
Flat Package

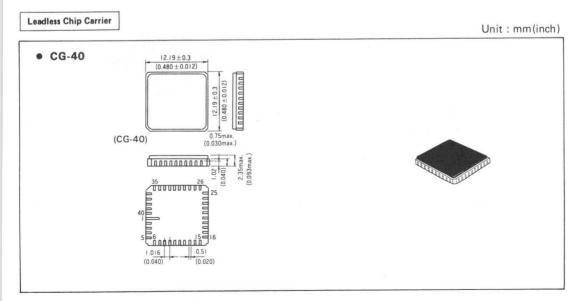




Plastic Leaded Chip Carrier







4. Mounting Method on Board

Lead pins of the package have surface treatment, such as solder coating or solder plating, to make them easy to mount on the PCB. The lead pins are connected to the package by eutectic solder. The following explains the common connecting method of leads and precautions.

4.1 Mounting Method of Pin Insertion Type Package

Insert lead pins of the package into through-holes (usually about ϕ 0.8mm) on the PCB. Soak the lead part of the package in a wave solder tub.

Lead pins of the package are held by the through-holes. Therefore, it is easy to handle the package through the process up to soldering, and easy to automate the soldering process. When soldering the lead part of the package in the wave solder tub, be careful not to get the solder on the package, because the wave solder will damage it.

4.2 Mounting Method of Surface Mounting Type Package

Apply the specified quantity of solder paste to the pattern on any printed board by the screen printing method, and put a package on it. The package is now temporarily fixed to the printed board by the surface tension of the paste. The solder paste melts when heated in a reflowing furnace, and the leads of the package and the pattern of the printed board are fixed together by the surface tension of the melted solder and the self alignment.

The size of the pattern where the leads are attached, partly depending on paste material or furnace adjustment, should be 1.1 to 1.3 times the leads' width.

The temperature of the reflowing furnace depends on package material and also package types. Fig. 2 lists the adjustment of the reflowing furnace for FPP. Pre-heat the furnace to 150°C. The surface temperature of the resin should be kept at 235°C max. for 10 minutes or less.

- The temperature of the leads should be kept at 260°C for 10 minutes or less.
- (2) The temperature of the resin should be kept at 235°C for 10 minutes or less.
- (3) Below is shown the temperature profile when soldering a package by the reflowing method.

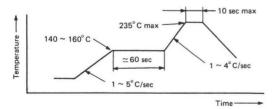


Figure 2 Reflowing Furnace Adjustment for FPP

Ensure good heater or temperature controls because the material of a plastic package is black epoxy-resin which damages easily. When an infrared heater is used, if the temperature is higher than the glass transition point of epoxy-resin (about 150°C), for a long time, the package may be damaged and the reliability lowered. Equalize the temperature inside and outside the packages by lessening the heat of the upper surface of the packages.

Leads of FPP may be easily bent under shipment or during handling and cannot be soldered onto the printed board. If they are, heat the bent leads again with a soldering iron to reshape them.

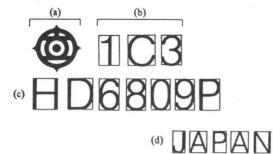
Use a rosin flux when soldering. Don't use a chloric flux because the chlorine in the flux tends to remain on the leads and lower the reliability of the product.

Even if you use a rosin flux, remaining flux can cause the leads to deteriorate. Wash away flux from packages with alcohol, chlorothene or freon. But don't leave these solvents on the packages for a long time because the marking may disappear.

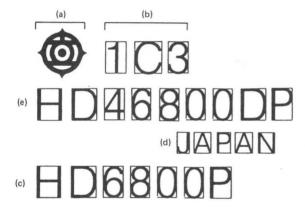
5. Marking

Hitachi trademark, product type No., etc. are printed on packages. Case I and Case II give examples of marks and Nos. Case I applies to products which have only a standard type No. Case II applies to products which have an old type No. and a standard type No.

Case I; Includes a standard type No.



Case II; Includes an old type No. and a standard type No.



Meaning of Each Mark

	arming or Edon marri
(a)	Hitachi Trademark
(b)	Lot Code
(c)	Standard Type No.
(d)	Japan Mark
(e)	Old Type No.
	(a) (b) (c) (d)

RELIABILITY AND QUALITY ASSURANCE

1. VIEWS ON QUALITY AND RELIABILITY

Basic views on quality in Hitachi are to meet individual user's purchase purpose and quality required, and to be at the satisfied quality level considering general marketability. Quality required by users is specifically clear if the contract specification is provided. If not, quality required is not always definite. In both cases, efforts are made to assure the reliability so that semiconductor devices delivered can perform their ability in actual operating circumstances. To realize such quality in manufacturing process, the key points should be to establish quality control system in the process and to enhance morale for quality.

In addition, quality required by users on semiconductor devices is going toward higher level as performance of electronic system in the market is going toward higher one and is expanding size and application fields. To cover the situation, actual bases Hitachi is performing is as follows:

 Build the reliability in design at the stage of new product development.

(2) Build the quality at the sources of manufacturing process.

(3) Execute the harder inspection and reliability confirmation of final products.

(4) Make quality level higher with field data feed back.

(5) Cooperate with research laboratories for higher quality and reliability.

With the views and methods mentioned above, utmost efforts are made for users' requirements.

2. RELIABILITY DESIGN OF SEMICONDUCTOR DEVICES

2.1 Reliability Targets

Reliability target is the important factor in manufacture and sales as well as performance and price. It is not practical to rate reliability target with failure rate at the certain common test condition. The reliability target is determined corresponding to character of equipments taking design, manufacture, inner process quality control, screening and test method, etc. into consideration, and considering operating circumstances of equipments the semiconductor device used in, reliability target of system, derating applied in design, operating condition, maintenance, etc.

2.2 Reliability Design

To achieve the reliability required based on reliability targets, timely sude and execution of design standardization, device design (including process design, structure design), design review, reliability test are essential.

(1) Design Standardization

Establishment of design rule, and standardization of parts, material and process are necessary. As for design rule, critical items on quality and reliability are always studied at circuit design, device design, layout design, etc. Therefore, as long as standardized process, material, etc. are used, reliability risk is extremely small even in new development devices, only except for in the case special requirements in function needed.

(2) Device Design

It is important for device design to consider total balance of process design, structure design, circuit and layout design. Especially in the case new process and new material are employed, technical study is deeply executed prior to device development.

(3) Reliability Evaluation by Test Site

Test site is sometimes called Test Pattern. It is useful method for design and process reliability evaluation of IC and LSI which have complicated functions.

1. Purposes of Test Site are as follows;

· Making clear about fundamental failure mode

Analysis of relation between failure mode and manufacturing process condition

Search for failure mechanism analysis

Establishment of QC point in manufacturing

2. Effectiveness of evaluation by Test Site are as follows;

- Common fundamental failure mode and failure mechanism in devices can be evaluated.
- Factors dominating failure mode can be picked up, and comparison can be made with process having been experienced in field.
- Able to analyze relation between failure causes and manufacturing factors.
- Easy to run tests.

etc

2.3 Design Review

Design review is organized method to confirm that design satisfies the performance required including users' and design work follows the specified ways, and whether or not technical improved items accumulated in test data of individual major fields and field data are effectively built in. In addition, from the standpoint of enhancement of competitive power of products, the major purpose of design review is to ensure quality and reliability of the products. In Hitachi, design review is performed from the planning stage for new products and even for design changed products. Items discussed and determined at design review are as follows;

(1) Description of the products based on specified design

(2) From the standpoint of specialty of individual participants, design documents are studied, and if unclear matter is found, sub-program of calculation, experiments, investigation, etc. will be carried out.

(3) Determine contents of reliability and methods, etc. based on design document and drawing.

(4) Check process ability of manufacturing line to achieve design goal.

(5) Discussion about preparation for production.

(6) Planning and execution of sub-programs for design change proposed by individual specialist, and for tests, experiments and calculation to confirm the design change.

(7) Reference of past failure experiences with similar devices, confirmation of method to prevent them, and planning and execution of test program for confirmation of them. These studies and decisions are made using check lists made individually depending on the objects.

3. QUALITY ASSURANCE SYSTEM OF SEMICONDUCTOR DEVICES

3.1 Activity of Quality Assurance

General views of overall quality assurance in Hitachi are as follows:

(1) Problems in individual process should be solved in the

process. Therefore, at final product stage, the potential failure factors have been already removed.

- (2) Feedback of information should be made to ensure satisfied level of process ability.
- (3) To assure reliability required as an result of the things mentioned above is the purpose of quality assurance.

The followings are regarding device design, quality approval at mass production, inner process quality control, product inspection and reliability tests.

3.2 Quality Approval

To ensure quality and reliability required, quality approval is carried out at trial production stage of device design and mass production stage based on reliability design described at section 2.

The views on quality approval are as follows;

- The third party performs approval objectively from the standpoint of customers.
- Fully consider past failure experiences and information from field.
- (3) Approval is needed for design change and work change.
- (4) Intensive approval is executed on parts material and process.
- (5) Study process ability and fluctuation factor, and set up control points at mass production stage.

Considering the views mentioned above, quality approval shown in Fig. 1 is performed.

3.3 Quality and Reliability Control at Mass Production

For quality assurance of products in mass production, quality control is executed with organic division of functions

in manufacturing department, quality assurance department, which are major, and other departments related. The total function flow is shown in Fig. 2. The main points are described below.

3.3.1 Quality Control of Parts and Material

As the performance and the reliability of semiconductor devices are getting higher, importance is increasing in quality control of material and parts, which are crystal, lead frame, fine wire for wire bonding, package, to build products, and materials needed in manufacturing process, which are mask pattern and chemicals. Besides quality approval on parts and materials stated in section 3.2, the incoming inspection is, also, key in quality control of parts and materials. The incoming inspection is performed based on incoming inspection specification following purchase specification and drawing, and sampling inspection is executed based on MIL-STD-105D mainly.

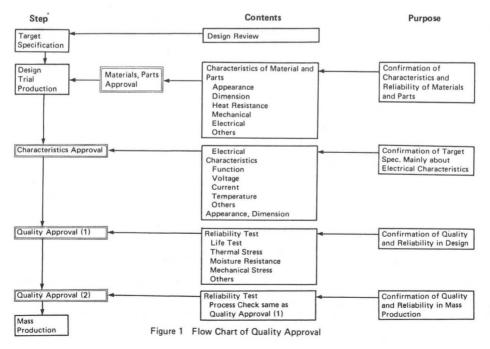
The other activities of quality assurance are as follows:

- (1) Outside Vendor Technical Information Meeting
- (2) Approval on outside vendors, and guidance of outside vendors
- (3) Physical chemical analysis and test

The typical check points of parts and materials are shown in Table 1.

3.3.2 Inner Process Quality Control

Inner process quality control is performing very important function in quality assurance of semiconductor devices. The following is description about control of semi-final products, final products, manufacturing facilities, measuring equipments,



circumstances and sub-materials. The quality control in the manufacturing process is shown in Fig. 3 corresponding to the manufacturing process.

(1) Quality Control of Semi-final Products and Final Products

Potential failure factors of semiconductor devices should be removed preventively in manufacturing process. To achieve it, check points are set-up in each process, and products which have potential failure factor are not transfer to the next process. Especially, for high reliability semiconductor devices, manufacturing line is rigidly selected, and the quality control in the manufacturing process is tightly executed — rigid check in each process and each lot, 100% inspection in appropriate ways to remove failure factor caused by manufacturing fluctuation, and execution of screening needed, such as high temperature aging and temperature cycling. Contents of inner process quality control are as follows;

- Condition control on individual equipments and workers, and sampling check of semifinal products.
- Proposal and carrying-out improvement of work
- · Education of workers
- Maintenance and improvement of yield
- Picking-up of quality problems, and execution of counter-

measures

Transmission of information about quality

 Quality Control of Manufacturing Facilities and Measuring Equipment

Equipments for manufacturing semiconductor devices have been developing extraordinarily with necessary high performance devices and improvement of production, and are important factors to determine quality and reliability. In Hitachi, automatization of manufacturing equipments are promoted to improve manufacturing fluctuation, and controls are made to maintain proper operation of high performance equipments and perform the proper function. As for maintenance inspection for quality control, there are daily inspection which is performed daily based on specification related, and periodical inspection which is performed periodically. At the inspection, inspection points listed in the specification are checked one by one not to make any omission. As for adjustment and maintenance of measuring equipments, maintenance number, specification are checked one by one to maintain and improve quality.

(3) Quality Control of Manufacturing Circumstances and Submaterials

Quality and reliability of semiconductor device is highly

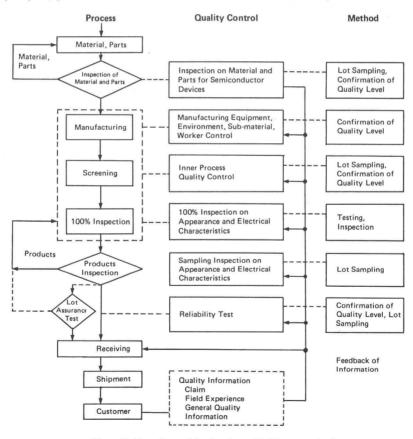


Figure 2 Flow Chart of Quality Control in Manufacturing Process

affected by manufacturing process. Therefore, the controls of manufacturing circumstances - temperature, humidity, dust and the control of submaterials - gas, pure water - used in manufacturing process are intensively executed. Dust control

is described in more detail below.

Dust control is essential to realize higher integration and higher reliability of devices. In Hitachi, maintenance and improvement of cleanness in manufacturing site are executed with paying intensive attention on buildings, facilities, airconditioning systems, materials delivered-in, clothes, work, etc., and periodical inspection on floating dust in room, falling dusts and dirtiness of floor.

3.3.3 Final Product Inspection and Reliability Assurance

(1) Final Product Inspection

Lot inspection is done by quality assurance department for products which were judged as good products in 100% test, which is final process in manufacturing department. Though 100% of good products is expected, sampling inspection is executed to prevent mixture of failed products by mistake of work, etc. The inspection is executed not only to confirm that the products meet users' requirement, but to consider potential factors. Lot inspection is executed based on MIL-STD-105D.

(2) Reliability Assurance Tests

To assure reliability of semiconductor devices, periodical reliability tests and reliability tests on individual manufacturing lot required by user are performed.

Table 1 Quality Control Check Points of Material and Parts (Example)

Material, Parts	Important Control Items	Point for Check
Wafer	Appearance Dimension Sheet Resistance Defect Density Crystal Axis	Damage and Contamina- tion on Surface Flatness Resistance Defect Numbers
Mask	Appearance Dimension Resistoration Gradation	Defect Numbers, Scratch Dimension Level Uniformity of Gradation
Fine Wire for Wire Bonding	Appearance Dimension Purity Elongation Ratio	Contamination, Scratch, Bend, Twist Purity Level Mechanical Strength
Frame	Appearance Dimension Processing Accuracy Plating Mounting Characteristics	Contamination, Scratch Dimension Level Bondability, Solderability Heat Resistance
Ceramic Package	Appearance Dimension Leak Resistance Plating Mounting Characteristics Electrical Characteristics Mechanical Strength	Contamination, Scratch Dimension Level Airtightness Bondability, Solderability Heat Resistance Mechanical Strength
Plastic	Composition Electrical Characteristics Thermal Characteristics Molding Performance Mounting Characteristics	Characteristics of Plastic Material Molding Performance Mounting Characteristics



Figure 3 Example of Inner Process Quality Control

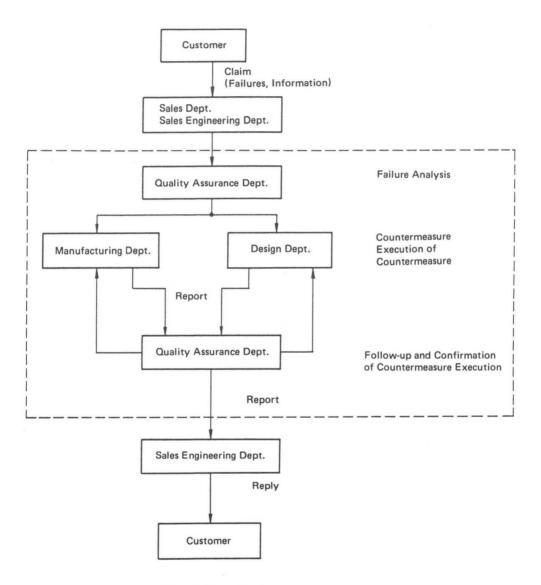


Figure 4 Process Flow Chart of Field Failure

RELIABILITY TEST DATA OF MICROCOMPUTER

1. INTRODUCTION

Microcomputer is required to provide higher reliability and quality with increasing function, enlarging scale and widening application. To meet this demand, Hitachi is improving the quality by evaluating reliability, building up quality in process, strengthening inspection and analyzing field data etc..

This chapter describes reliability and quality assurance data for Hitachi 8-bit and 16-bit multi-chip microcomputer based on test and failure analysis results. More detail data and new information will be reported in another reliability data sheet.

2. PACKAGE AND CHIP STRUCTURE

2.1 Package

The reliability of plastic molded type has been greatly improved, recently their applications have been expanded to automobiles measuring and control systems, and computer terminal equipment operated under relatively severe conditions and production output and application of plastic molded type will continue to increase.

To meet such requirements, Hitachi has considerably improved moisture resistance, operation stability, and chip and plastic manufacturing process.

Plastic and ceramic package type structure are shown in Figure 1 and Table 1.

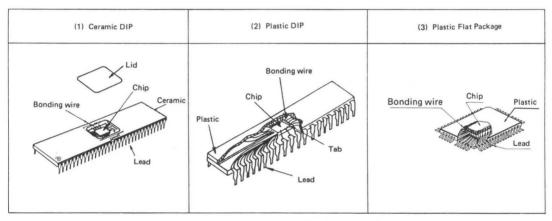


Figure 1 Package Structure

Table 1 Package Material and Properties

Item	Ceramic DIP	Plastic DIP	Plastic Flat Package
Package	Alumina	Ероху	Epoxy
Lead	Tin plating Brazed Alloy 42	Solder dipping Alloy 42 or Cu	Solder plating Alloy 42
Seal	Au-Sn Alloy	N.A	N.A
Die bond	Au-Si	Au-Si or Ag paste	Au-Si or Ag paste
Wire bond	Ultrasonic	Thermo compression	Thermo compression
Wire	Al	Au	Au

2.2 Chip Structure

Hitachi microcomputers are produced in NMOS E/D technology or low power CMOS technology. Si-gate process is used

in both types because of high reliability and high density. Chip structure and basic circuit are shown in Figure 2.

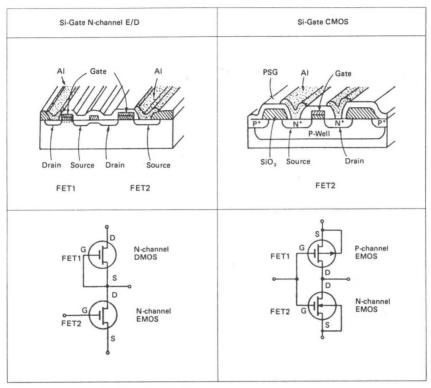


Figure 2 Chip Structure and Basic Circuit

3. QUALITY QUALIFICATION AND EVALUATION

3.1 Reliability Test Methods

Reliability test methods shown in Table 2 are used to qualify and evaluate the new products and new process.

Table 2 Reliability Test Methods

Test Items	Test Condition	MIL-STD-883B Method No.
Operating Life Test	125°C, 1000hr	1005,2
High Temp, Storage Low Temp, Storage Steady State Humidity Steady State Humidity Biased	Tstg max, 1000hr Tstg min, 1000hr 65°C 95%RH, 1000hr 85°C 85%RH, 1000hr	1008,1
Temperature Cycling Temperature Cycling	-55°C ∼ 150°C, 10 cycles -20°C ∼ 125°C, 200 cycles	1010,4
Thermal Shock Soldering Heat	0°C ~ 100°C, 100 cycles 260°C, 10 sec	1011,3
Mechanical Shock	1500G 0.5 msec, 3 times/X, Y, Z	2002,2
Vibration Fatigue	60Hz 20G, 32hrs/X, Y, Z	2005,1
Variable Frequency	20~2000Hz 20G, 4 min/X, Y, Z	2007,1
Constant Acceleration	20000G, 1 min/X, Y, Z	2001,2
Lead Integrity	225gr, 90° 3 times	2004,3

RELIABILITY TEST DATA OF MICROCOMPUTER

3.2 Reliability Test Result

Reliability test result of 8-bit microprocessors is shown in Table 3 to Table 7, that of 16-bit microprocessors in Table 8,

Table 9. There is little difference according to device series, as the design and production process, etc. are standardized.

Table 3 Dynamic Life Test (8-bit microprocessor)

Device Type	Sample Size	Component Hours	Failures
HD6800	248 pcs	248000	0
HD6802	452	153712	1*
HD6809	85	85000	0
Total	785	486712	1

*leakage current

Estimated Field Failure Rate = 0.01% / 1000 hrs at Ta = 75°C (Activation Energy = 0.7eV, Confidence Level 60%)

Table 4 High Temperature, High Humidity Test (8-bit microprocessor) (Moisture Resistance Test)

(1) 85°C 85%RH Bias Test

Device Type	Vcc Bias	168 hrs	500 hrs	1000 hrs
HD6800P	5.5V	0/45	0/45	0/45
HD6802P	5.5V	0/38	0/38	0/38
HD6809P	5.5V	0/22	0/22	0/22
Total		0/105	0/105	0/105

(2) High Temperature-High Humidity Storage Life Test

Device Type	Condition	168 hrs	500 hrs	1000 hrs
HD6800P	65°C 95%RH	0/22	0/22	0/22
HD6802P	80°C 90%RH	0/22	0/22	0/22
HD6802P	65°C 95%RH	0/38	0/38	0/38
HD6809P	65°C 95%RH	0/45	0/45	0/45

(3) Pressure Cooker Test

(Condition; 2atm 121°C)

Device Type	40 hrs	60 hrs	100 hrs
HD6800P	0/42	0/42	0/42
HD6802P	0/22	0/22	0/22

(4) MIL-STD-883B Moisture Resistance Test

(Condition; 65° C $\sim -10^{\circ}$ C, over 90%RH, Vcc = 5.5V)

10 cycles	20 cycles	40 cycles
0/25	0/25	0/25
0/25	0/25	0/25
	0/25	0/25 0/25

RELIABILITY TEST DATA OF MICROCOMPUTER-

Table 5 Temperature Cycling Test (8-bit microprocessor) (–55°C \sim 25°C \sim 150°C)

Device Type	10 cycles	100 cycles	200 cycles
HD6800P	0/453	0/44	0/44
HD6802P	0/502	0/77	0/77
HD6809P	0/202	0/45	0/45

Table 6 High Temperature, Low Temperature Storage Life Test (8-bit microprocessor)

Device	Temperature	168 hrs	500 hrs	1000 hrs
	150°C	0/88	0/88	0/88
MPU total	-55°C	0/76	0/76	0/76

Table 7 Mechanical and Environmental Test (8-bit microprocessor)

-	0 111	Plastic DIP		Flat Plastic Package	
Test Item	Condition	Sample Size	Failure	Sample Size	Failure
Thermal Shock	0°C ∼ 100°C 10 cycles	110	0	100	0
Soldering Heat	260°C, 10 sec.	180	0	20	0
Salt Water Spray	35°C, NaCl 5% 24 hrs	110	0	20	0
Solderability	230°C, 5 sec. Rosin flux	159	0	34	0
Drop Test	75cm, maple board 3 times	110	0	20	0
Mechanical Shock	1500G, 0.5 ms 3 times/X, Y, Z	110	0	20	0
Vibration Fatigue	60 Hz, 20G 32 hrs/X, Y, Z	110	0	20	0
Vibration Variable Freq.	100 ~ 2000 Hz 20G, 4 times/X, Y, Z	110	0	20	0
Lead Integrity	225 g, 90° Bonding 3 times	110	0	20	0

-RELIABILITY TEST DATA OF MICROCOMPUTER

Table 8 Dynamic Life Test (16-bit microprocessor)

D : T	Condition		1001	5001	10001
Device Type	Та	Vcc	168 hrs	500 hrs	1000 hrs
HD68000	125°C	5.5V	0/62	0/62	0/62
	150°C	5.5V	0/52	0/52	0/52

Estimated Field Failure Rate = 0.013%/1000 hrs at Ta = 75°C (Activation Energy 0.7eV, Confidence Level 60%)

Table 9 Mechanical and Environmental Test (16-bit microprocessor)

	0	Device '	Туре	
Test Item	Condition	Sample Size	Failure	
High Temperature Storage	Ta = 295°C, 1000 hrs	42	0	
Low Temperature Storage	$Ta = -55^{\circ}C$, 1000 hrs	42	0	
Temperature Cycling (1)	-55°C ∼ 25°C ∼ 150°C 10 cycles	189	0	
Temperature Cycling (2)	-20°C ∼ 25°C ∼ 125°C 500 cycles	44	0	
Thermal Shock	−55°C ~ 125°C 15 cycles	44	0	
Soldering heat	260°C, 10 sec	44	0	
Solderability	230°C, 5 sec	44	0	
Mechanical Shock	1500G, 0.5 msec 3 times/X, Y, Z	44	0	
Vibration Variable Freq.	20 ~ 2000 Hz, 20G 3 times/X, Y, Z	44	0	
Constant Acceleration	20000G 1 min/X, Y, Z	20000G 44		

4. PRECAUTION

4.1 Storage

It is preferable to store semiconductor devices in the following ways to prevent detrioration in their electrical characteristics, solderability, and appearance, or breakage.

- Store in an ambient temperature of 5 to 30°C, and in a relative humidity of 40 to 60%.
- (2) Store in a clean air environment, free from dust and active
- (3) Store in a container which does not induce static electricity.
- (4) Store without any physical load.
- (5) If semiconductor devices are stored for a long time, store them in the unfabricated form. If their lead wires are formed beforehand, bent parts may corrode during storage.
- (6) If the chips are unsealed, store them in a cool, dry, dark, and dustless place. Assemble them within 5 days after unpacking. Storage in nitrogen gas is desirable. They can be stored for 20 days or less in dry nitrogen gas with a dew point at -30°C or lower. Unpacked devices must not be stored for over 3 months.
- (7) Take care not to allow condensation during storage due to rapid temperature changes.

4.2 Transportation

As with storage methods, general precautions for other electronic component parts are applicable to the transportation of semiconductors, semiconductor-incorporating units and other similar systems. In addition, the following considerations must be given, too:

- Use containers or jigs which will not induce static electricity as the result of vibration during transportation. It is desirable to use an electrically conductive container or aluminium foil.
- (2) In order to prevent device breakage from clothes-induced static electricity, workers should be properly grounded with a resistor while handling devices. The resistor of about 1 M ohm must be provided near the worker to protect from electric shock.
- (3) When transporting the printed circuit boards on which semiconductor devices are mounted, suitable preventive measures against static electricity induction must be taken; for example, voltage built-up is prevented by shorting terminal circuit. When a belt conveyor is used, prevent the conveyor belt from being electrically charged by applying some surface treatment.
- (4) When transporting semiconductor devices or printed circuit boards, minimize mechanical vibration and shock.

4.3 Handling for Measurement

Avoid static electricity, noise and surge-voltage when semi-conductor devices are measured. It is possible to prevent breakage by shorting their terminal circuits to equalize electrical potential during transportation. However, when the devices are to be measured or mounted, their terminals are left open to provide the possibility that they may be accidentally touched by a worker, measuring instrument, work bench, soldering iron, belt conveyor, etc. The device will fail if it touches something which leaks current or has a static charge. Take care not to allow curve tracers, synchroscopes, pulse generators, D.C. stabilizing power supply units etc. to leak current through their terminals or housings.

Especially, while the devices are being tested, take care not

to apply surge voltage from the tester, to attach a clamping circuit to the tester, or not to apply any abnormal voltage through a bad contact from a current source.

During measurement, avoid miswiring and short-circuiting. When inspecting a printed circuit board, make sure that no soldering bridge or foreign matter exists before turning on the power switch.

Since these precautions depend upon the types of semiconductor devices, contact Hitachi for further details.

4.4 Soldering

Semiconductor devices should not be left at high temperatures for a long time. Regardless of the soldering method, soldering must be done in a short time and at the lowest possible temperature. Soldering work must meet soldering heat test conditions, namely, 260°C for 10 seconds and 350°C for 3 seconds at a point 1 to 1.5 mm away from the end of the device package.

Use of a strong alkali or acid flux may corrode the leads, deteriorating device characteristics. The recommended soldering iron is the type that is operated with a secondary voltage supplied by a transformer and grounded to protect from lead current. Solder the leads at the farthest point from the device package.

4.5 Removing Residual Flux

To ensure the reliability of electronic systems, residual flux must be removed from circuit boards. Detergent or ultrasonic cleaning is usually applied. If chloric detergent is used for the plastic molded devices, package corrosion may occur. Since cleaning over extended periods or at high temperatures will cause swollen chip coating due to solvent permeation, select the type of detergent and cleaning condition carefully. Lotus Solvent and Dyfron Solvent are recommended as a detergent. Do not use any trichloroethylene solvent. For ultrasonic cleaning, the following conditions are advisable:

- Frequency: 28 to 29 kHz (to avoid device resonation)
- Ultrasonic output: 15W/Q
- Keep the devices out of direct contact with the power generator.
- Cleaning time: Less than 30 seconds

PROGRAM DEVELOPMENT AND SUPPORT SYSTEM

PROGRAM DEVELOPMENT AND SUPPORT SYSTEM OF 8-BIT/16-BIT MICROPROCESSOR

H680SD200 is prepared as system development device to develop software and hardware of various types of microcomputer system.

Fig. 1 shows the program development procedure using this system development device.

H680SD200 loads a universal OS, CP/M-68K $^{\circledR}$ developed jointly with Digital Research Inc. and operates with the existing CP/M $^{\circledR}$.

*CP/ $M^{\mbox{\scriptsize B}}$ and CP/M-68K $^{\mbox{\scriptsize B}}$ are registered trademarks of Digital Research Inc.

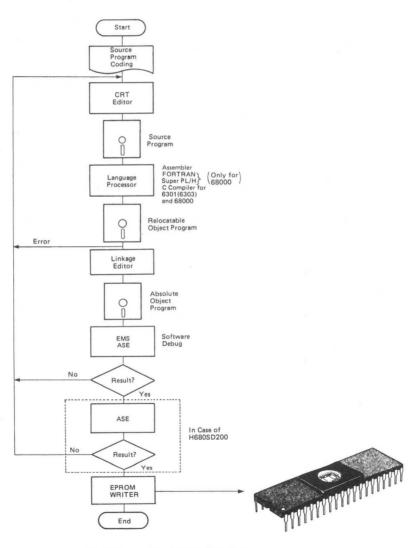


Fig. 1 Program Development Procedure



PROGRAM DEVELOPMENT AND SUPPORT SYSTEM-

Table 1 System Development Equipment SD200

MPU	Product Name	Product Code	Function	Note
-	CP/M-68K	S680CPM3F	 Single user Operating System. 68000 Assembler, C compiler, Screen editor and Linker are included. 	
	VAX-11 Interface Program	S680CLC3F	 Interface Program between the SD200 and theVAX-11. File transfer function. VT52 Terminal Emulation. 	Option
DATA I/O - EPROM Programmer Interface Program		S680CDI1F	• Interface Program between the SD200 and the DATA I/O EPROM Programmer model 22/29.	
	PKW-1000/7000 EPROM Programmer Interface Program	S680CPK2F	Interface Program between the SD200 and the PKW-1000/7000 EPROM Programmer (Aval Corp. Japan).	
	FORTRAN	S680CFR1F	• FORTRAN Compiler. (Subset of FORTRAN77)	Option
Super PL/H Super PL/H Symbolic Debugger 68000ASE02E	Super PL/H	S680CPL1F	• Super PL/H Compiler.	Option
	Symbolic Debugger	S680CSD2F	• Symbolic Debugger for programs written in 68000 Assembler or Super PL/H.	Option
	S680CAS2F	Realtime In-circuit Emulator for 68000 and 68HC000 MPU. (Up to 12MHz version)	Supplied with H680AS02E	
	64180 Macro Assembler	S180XAS6F	64180 Macro Assembler. Object code is absolute address format.	Option
	64180ASE	S180CAS1F	Realtime In-circuit Emulator for 64180.	Supplied with H180AS01E
	6305/63L05/6805 Macro Assembler	S35XAS6-F	• 6305Z/63L05/6805 Macro Assembler. • Linkage editor is included.	Option
	6301/6801/6800 Macro Assembler	S31XAS6-F	• 6301/6801/6800 Macro Assembler. • Linkage editor is included.	Option
	6301 C Compiler	S31CCLN-F	• C Compiler for 6301(6303).	Option

-PROGRAM DEVELOPMENT AND SUPPORT SYSTEM

Table 2 Cross System

MPU	Machine	os	Product Name	Product Code	Function
		ISIS-II	6305/63L05/6805 Assembler	S35MDS1-F	6305/63L05/6805 Assembler. Object code is absolute address format. Conditional assemble function.
		CP/M	6305/63L05/6805 Assembler	S35MDS2-F	6305/63L05/6805 Assembler. Object code is absolute address format. Conditional assemble function.
8-bit MCU	Intel MDS	ISIS-II	6301 Assembler	S31MDS1-F	6301/6801 Assembler. Object code is absolute address format. Conditional Assemble function.
		CP/M	6301 Assembler	S31MDS2-F	6301/6801 Assembler. Object code is absolute address format. Conditional Assemble function.
	IBM-PC	PC-DOS	6301 Macro Assembler	S31IAS1-F*	6301 Macro Assembler. Linkage Editor is included.
	1BIVI-FC	10-003	6305 Macro Assembler	S35IAS1-F*	6305 Macro Assembler.Linkage Editor is included.
8-bit MPU	VAX11	VMS	64180 Macro Assembler	S400VAS1F*	64180 Macro Assembler.Linkage Editor is included.

*Under development.

PROGRAM DEVELOPMENT AND SUPPORT SYSTEM-

Table 3 Third Parties' Products

Assemblers for HITACHI's microcomputers are provided by the other companies. Hitachi introduce some venders and their

products listed below. Please contact those venders directly if you have questions or requests to purchase these products.

Vender Name	Product Name	OS/System	Product Code
	6301 Assembler		ASM68
	6305 Assembler		ASM05
	6809 Assembler		ASM69
	68000 Assembler	- VAVII	ASM68K
	64180 Assembler	VAX11	ASM180
	64180 Simulator		INT180
MICROTEC 505W Olive, Suite 325	64180 C		MCC180
Sunnyvale, CA94086 (408)733-2919 U.S.A.	64180 Pascal		PAS180
	6301 Assembler		ASM68
	6305 Assembler	IBM-PC	ASM05
	64180 Assembler	TBW-FC	ASM180
S.	64180 C		MCC180
	64180 Pascal		PAS180
CAMELOT 79 London Road	6301 Assembler	101100	
Knebworth Herts, SG3 6HG, England Stevenage (0438) 812215	6305 Assembler	- IBM-PC -	*
AVOCET SYSTEMS, INC.	6800/6801/6301 Assembler	MS-DOS, CP/M CP/M-86	XASM-68
804 South State St. Dover, DE19901 (302) 734-0151	6805 Assembler	MS-DOS, CP/M CP/M-86	XASM-05
U.S.A.	6309/6809 Assembler	MS-DOS, CP/M CP/M-86	XASM-09
	64180 Assembler	MS-DOS, CP/M CP/M-86	XASM-180
MICROWARE SYSTEMS CORPORA- TION 5835 Grand Avenue	6309/6809 Assembler	OS-9	_
Dos Moines, IA50312 (512) 279-8844 U.S.A.	68000/68HC000 Assembler	OS-9	KCRS

^{*}Under development



PROGRAM DEVELOPMENT AND SUPPORT SYSTEM

Development System for 4-Bit, 8-Bit, and 16-Bit Microcomputers <H680SD200>

The H680SD200 is a development system for Hitachi 4-bit, 8-bit and 16-bit microcomputers. It is a desktop system in which a 16-bit microprocessor HD68000 is loaded as the CPU. Its standard system configuration includes a CRT, a keyboard, and two floppy disk drives. An assembler, compiler, and incircuit emulator (ASE) associated with the user's MCU are available as options.

APPLICABLE DEVICES

- HMCS400 series
- HD6305U, HD6305V
- HD6301V, HD6301X, HD6301Y
- HD64180
- HD68000, HD68HC000

(Other 4-bit and 8-bit microcomputers will be supported in the future.)

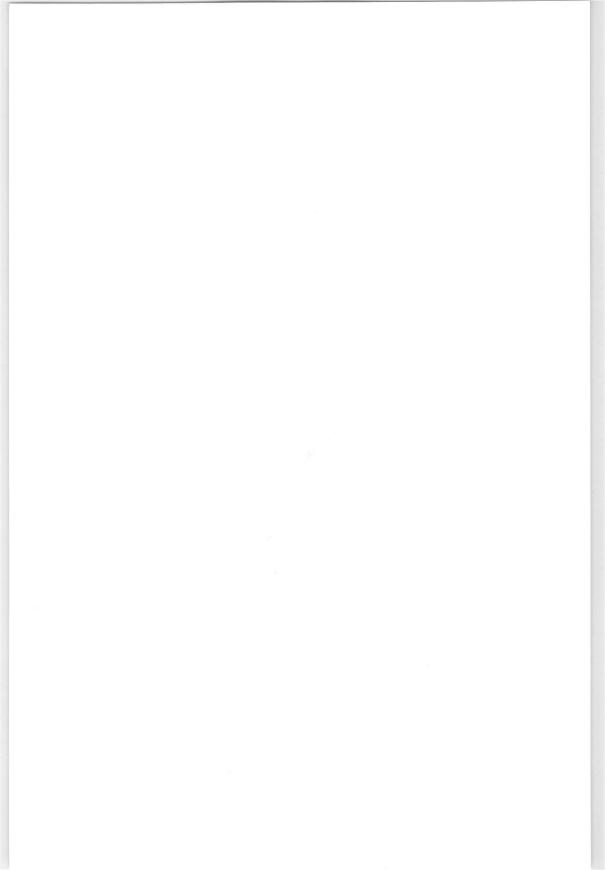
■ FEATURES

- Adopts general CP/M-68K[®] operating system
- Two internal 8 inch floppy disk drives (double-sided, doubledensity) and a 40M byte hard disk (available as an option)

make it possible to provide substantial external memory.

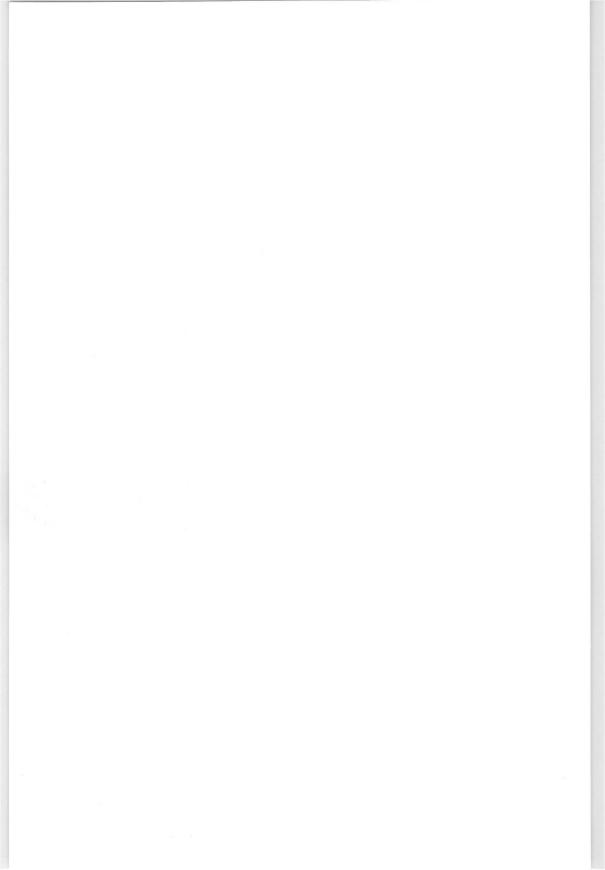
- Since CRT editor (screen editor) is included in the standard system, efficient programming, editing, and debugging of source programs are possible.
- C compiler for HD68000 is included. FORTRAN and Super PL/H for HD68000 and C Compiler for HD6301 (HD6303) are available as options.
- User prototype system can easily be debugged using incircuit emulator (ASE) associated with the user's MCU.
- With connection of VAX-11[®] to RS-232C interface, H680SD200 operates as VAX-11[®] (OS, VMS) work station.
- When 2M byte memory board is connected, high-speed operation can be realized.
- · Following interface are included
 - (1) EPROM programmer
 - (2) Printer (Centronics specification)
 - (3) Serial interface emulator for 4-bit and 8-bit single chip microcomputers
 - *CP/M[®] is a registered trade mark of Digital Research Inc.
 - **VAX-11® is a registered trade mark of Digital Equipment Corp.





DATA SHEETS

NMOS 8-BIT MICROPROCESSOR



HD6800, HD68A00, HD68B00

MPU (Micro Processing Unit)

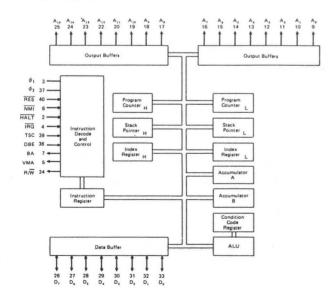
The HD6800 is a monolithic 8-bit microprocessor forming the central control function for Hitachi's HMCS6800 family. Compatible with TTL, the HD6800 as with all HMCS6800 system parts, requires only one 5V power supply, and no external TTL devices for bus interface. The HD68A00 and HD68B00 are high speed versions.

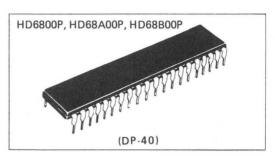
The HD6800 is capable of addressing 65k bytes of memory with its 16-bit address lines. The 8-bit data bus is bi-directional as well as 3-state, making direct memory addressing and multiprocessing applications realizable.

FEATURES

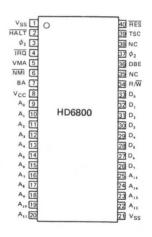
- Versatile 72 Instruction Variable Length (1~3 Byte)
- Seven Addressing Modes Direct, Relative, Immediate, Indexed, Extended, Implied and Accumulator
- Variable Length Stack
- Vectored Restart
- Maskable Interrupt
- Separate Non-Maskable Interrupt Internal Registers Saved in Stack
- Six Internal Registers Two Accumulators, Index Register, Program Counter, Stack Pointer and Condition Code Register
- Direct Memory Accessing (DMA) and Multiple Processor Capability
- Clock Rates as High as 2.0 MHz (HD6800 ··· 1 MHz, HD68A00 ··· 1.5 MHz, HD68B00 ··· 2.0 MHz)
- Halt and Single Instruction Execution Capability
- Compatible with MC6800, MC68A00 and MC68B00

BLOCK DIAGRAM





■ PIN ARRANGEMENT



(Top View)

HD6800, HD68A00, HD68B00-

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc} *	-0.3 ∼ +7.0	V
Input Voltage	V _{in} *	-0.3 ∼ +7.0	V
Operating Temperature	Topr	- 20 ∼ + 75	°C
Storage Temperature	T _{stg}	- 55 ∼ +150	°C

■ RECOMMENDED OPERATING CONDITION

Item	Symbol	min	typ	max	Unit
Supply Voltage	V _{cc} *	4.75	5.0	5.25	V
	V1L*	-0.3	-	0.8	V
Input Voltage	V _{IH} *	2.0	_	V _{cc}	V
Operating Temperature	Topr	-20	25	75	°C

^{*} With respect to V_{SS} (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (V_{CC} = 5V ± 5%, V_{SS} = 0V, Ta = -20~+75°C, unless otherwise noted.)

Item		Symbol	Test Condition	min	typ*	max	Unit
Input "High" Voltage	Logic**	V _{IH}		2.0	_	Vcc	V
Input "Low" Voltage	Logic**	VIL		- 0.3	_	0.8	V
Clock Input "High" Voltage	ϕ_1 , ϕ_2	V _{IHC}		V _{CC} - 0.6	-	V _{CC} + 0.3	V
Clock Input "Low" Voltage	ϕ_1 , ϕ_2	VILC		-0.3	-	0.4	V
	D ₀ ~D ₇		I _{OH} = -205μA	2.4	-	-	V
Output "High" Voltage	$A_0 \sim A_{15}$, R/\overline{W} VMA	V _{OH}	.l _{OH} = -145μA	2.4	_	_	V
	ВА		$I_{OH} = -100 \mu A$	2.4	-	-	V
Output"Low" Voltage	4	VoL	I _{OL} = 1.6mA	-	-	0.4	V
	Logic***		V _{in} = 0~5.25V,	-2.5	-	2.5	μΑ
Input Leakage Current	ϕ_1 , ϕ_2	- l _{in}	All other pins are connected to GND	-100	-	100	μΑ
Three-State (Off-state)	D ₀ ~D ₇	1	V - 0.4 a. 2.4V	-10	-	10	μΑ
Input Current	A ₀ ~A ₁₅ , R/W	ITSI	$V_{in} = 0.4 \sim 2.4 V$	-100	1-	100	μΑ
Power Dissipation		PD		-	0.5	1.0	W
6	Logic***			-	6.5	10	pF
Innut Considerate	D ₀ ~D ₇		$V_{in} = 0V$, $Ta = 25$ °C,	-	10	12.5	pF
Input Capacitance	ϕ_1	C _{in}	f = 1 MHz	-	25	35	pF
	ϕ_2			-	45	70	pF
Output Capacitance	A ₀ ~A ₁₅ , R/W VMA, BA	Cout	V _{in} = 0V, Ta = 25°C, f = 1 MHz	-	-	12	pF

^{*} With respect to V_{SS} (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum rating are exceeded. Normal operation should be under recommended operating conditions.

If these conditions are exceeded, it could affect reliability of LSI.

^{*} Ta = 25°C, V_{CC} = 5V ** All inputs except ϕ_1 and ϕ_2 *** All inputs except ϕ_1 , ϕ_2 and $D_0 \sim D_7$

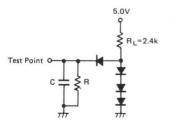
• AC CHARACTERISTICS (V_{CC} = 5V \pm 5%, V_{SS} = 0V, Ta = -20 \sim +75 $^{\circ}$ C, unless otherwise noted.)

1. TIMING CHARACTERISTICS OF CLOCK PULSE ϕ_1 and ϕ_2

la		Cumbal	Test	Н	D6800)	Н	D68A	00	Н	Unit		
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
requency of Operation		f		0.1	-	1.0	0.1	-	1.5	0.1		2.0	MHz
ycle Time		t _{cyc}	Fig. 10	1.000	_	10	0.666	_	10	0.500	-	10	μs
Clock Pulse Width	ϕ_1,ϕ_2	PW _{CH1} , PW _{CH2}	Fig. 10	400	-	4,500	230	-	4,500	180		4,500	ns
Rise and Fall Times	ϕ_1,ϕ_2	t _r , t _f	Fig. 10	-	-	100	-	-	100	-	-	100	ns
Delay Time (Clock In	nternal)	t _d	Fig. 10	0	-	4,500	0	-	4,500	0	-	4,500	ns
Clock "High" Level	Γime	t _{UT}	Fig. 10	900	-	_	600	_	-	440	_	-	ns

2. READ/WRITE CHARACTERISTICS

la		Cumbal	Test	Н	D6800		H	ID68A	00	H	ID68B	00	Unit
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Onit
Address Delay	C=90pF	t _{AD1}	Fig. 11, Fig. 12	-	-	270	-	_	180	_	-	150	ns
Time	C=30pF	t _{AD2}	Fig. 11, Fig. 12		-	250	-	-	165	-	-	135	ns
Data Setup Time (Rea	ad)	t _{DSR}	Fig. 11	100	-	-	60	-	-	40	_	_	ns
Peripheral Read Accest		t _{acc}	Fig. 11	530	-	-	360	-	-	250	-	-	ns
Input Data Hold Time	е	t _H	Fig. 11	10	-	-	10	-	-	10	-	_	ns
Output Data Hold Tir	ne	t _H	Fig. 12	20	-	_	20	-	-	20	7-7	-	ns
Address Hold Time (Address, R/W, VMA))	t _{AH}	Fig. 11, Fig. 12	10	_	-	10	-	-	10	-	-	ns
Enable "High" Time Input	for DBE	t _{EH}	Fig. 12	450	-	-	280	-	-	220	-	-	ns
Data Delay Time (Wr	ite)	t _{DDW}	Fig. 12	_	-	225	_	-	200	-	1-1	160	ns
Data Bus Enable Dow (During ϕ_1 Up Time)	n Time	tobe	Fig. 12	150	-	-	120	-	-	75	-	-	ns
Data Bus Enable Dela	y Time	t _{DBED}	Fig. 12	300	-	-	250	-	_	180	-	_	ns
Data Bus Enable Rise and Fall Times		t _{DBEr}	Fig. 12	_	_	25	-	-	25	-	-	25	ns
Processor Control Set	tup Time	t _{PCS}		200	-	-	140	-	-	110	_	-	ns
Processor Control Rise and Fall Times		t _{PCr} t _{PCf}		-	-	100	-	-	100	-	-	100	ns
Bus Available Delay 7	Γime (BA)	t _{BA}		-	-	250	-	-	165	-	_	135	ns
Three-State Delay Tir	me	t _{TSD}		-	-	270	-	-	270	-	-	220	ns



All diodes are 1S2074 (B) or equivalent.

Figure 1 Bus Timing Test Load

C = 130pF for $D_0 \sim D_{\gamma}$ = 90pF for $A_0 \sim A_{15}$, R/\overline{W} , and VMA

^{= 30}pF for BA

 $R = 11k\Omega$ for $D_0 \sim D_7$

⁼ $16k\Omega$ for $A_0 \sim A_{15}$, R/\overline{W} and VMA = $24k\Omega$ for BA

C includes Stray Capacitance.

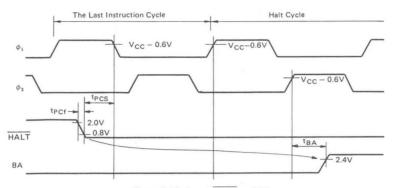


Figure 2 Timing of HALT and BA

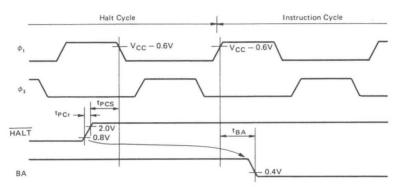


Figure 3 Timing of HALT and BA

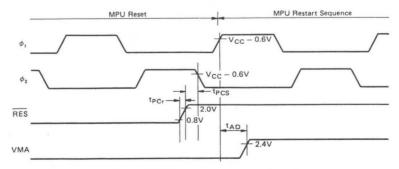


Figure 4 RES and MPU Restart Sequence



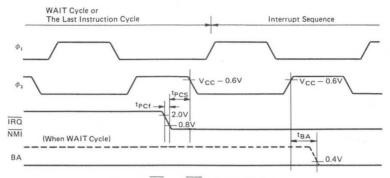


Figure 5 IRQ and NMI Interrupt Timing

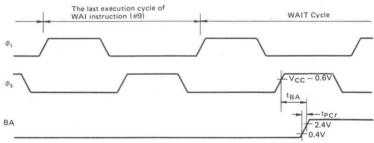
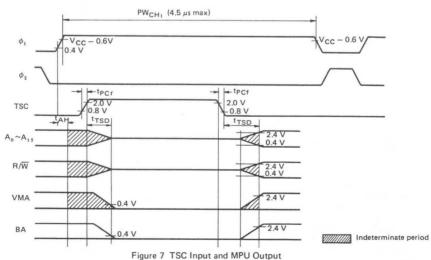


Figure 6 WAI Instruction and BA Timing



igure / 130 input and ini o Outpu

■ MPU REGISTERS

The MPU provides several registers in Fig. 8, which is available for use by the programmer.

Each register is described below.

Program Counter (PC)

The program counter is a two byte (16-bit) register that points to the current program address.

Stack Pointer (SP)

The stack pointer is a two byte register that contains the address of the next available location in an external push-down/pop-up stack. This stack is normally a random access Read/Write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be nonvolatile.

Index Register (IX)

The index register is a two byte register that is used to store data or a sixteen bit memory address for the Indexed mode of memory addressing.

Accumulators (ACCA, ACCB)

The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit (ALU).

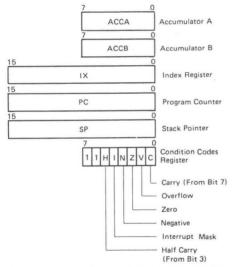


Figure 8 Programming Model of the Microprocessing Unit

Condition Code Register (CCR)

The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative (N), Zero (Z), Overflow (V), Carry from bit 7 (C), and half carry from bit 3(H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit (I). The unused bits of the Condition Code Register (b6 and b7) are "1". The detail block diagram of the microprossing unit is shown in Fig. 9.

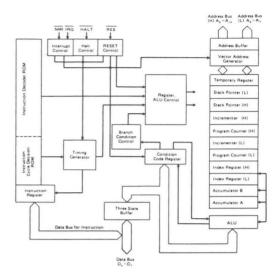


Figure 9 Internal Block Diagram of MPU

■ MPU SIGNAL DESCRIPTION

Proper operations of the MPU requires that certain control and timing signals (Fig. 9) be provided to accomplish specific functions. The functions of pins are explained in this section.

• Clock (ϕ_2, ϕ_2)

Two pins are used to provide the clock signals. A two-phase non-overlapping clock is provided as shown in Fig. 10.

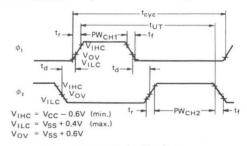


Figure 10 Clock Timing Waveform

Address Bus (A₀~A₁₅)

Sixteen pins are used for the address bus. The outputs are three-state bus drivers capable of driving one standard TTL load and 90pF. When the output is turned off, it is essentially an open circuit. This permits the MPU to be used in DMA applications. Putting TSC in its high state forces the Address bus to go into the three-state mode.

Data Bus (D₀∼D₇)

Eight pins are used for the data bus. It is bidirectional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130pF. Data Bus is placed in the three-state mode when DBE is "Low."

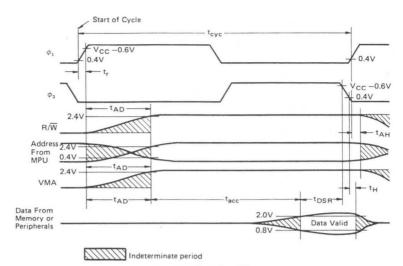


Figure 11 Read from Memory or Peripherals

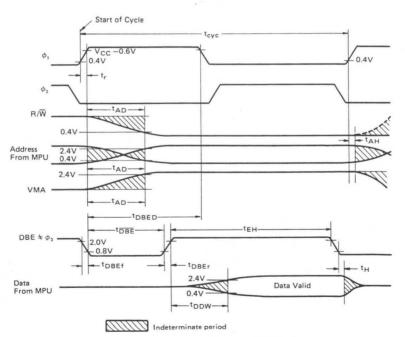


Figure 12 Write to Memory or Peripherals

Data Bus Enable (DBE)

This input is the three-state control signal for the MPU data bus and will enable the bus drivers when in the "High" state; will make the bus driver off when in the "Low" state. This input is TTL compatible; however in normal operation, it would be driven by ϕ_2 clock. During an MPU read cycle, the data bus drivers will be disabled internally. When it is desired that another device control the data bus such as in Direct Memory Access (DMA) applications, DBE should be held "Low."

If additional data setup or hold time is required on an MPU write, the DBE down time can be decreased as shown in Fig. 13 (DBE $\, \neq \, \phi_2$). The minimum down time for DBE is $t_{\overline{D}B\overline{E}}$ as shown and must occur within ϕ_1 up time. As for the characteristical values in Fig. 12, refer to the table of electrical characteristics.

Bus Available (BA)

The BA signal will normally be in the "Low" state. When activated, it will go to the "High" state indicating that the microprocessor has stopped and that the address bus is available. This will occur if the \overline{HALT} line is in the "Low" state or the processor is in the WAIT state as a result of the execution of a WAIT instruction. At such time, all three-state output drivers will go to their off state and other outputs to their normally inactive level. The processor is removed from the WAIT state by the occurrence of a maskable (mask bit I=0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30pF. If TSC is in the "High" state, Bus Available will be "Low".

Read/Write (R/W)

This TTL compatible output signals the peripherals and memory devices whether the MPU is in a Read ("High") or

Write ("Low") state. The normal standby state of this signal is Read ("High"). Three-State Control going "High" will turn R/\overline{W} to the off (high impedance) state. Also, when the processor is halted, it will be in the off state. This output is capable of driving one standard TTL load and 90pF.

Reset (RES)

The \overline{RES} input is used to reset and start the MPU from a power down condition resulting from a power failure or initial start-up of the processor. This input can also be used to reinitialize the machine at any time after start-up.

If a "High" level is detected in this input, this will signal the MPU to begin the reset sequence. During the reset sequence, the contents of the last two locations (FFFE, FFFF) in memory will be loaded into the Program Counter to point to the beginning of the reset routine. During the reset routine, the interrupt mask bit is set and must be cleared under program control before the MPU can be interrupted by IRQ. While RES is "Low" (assuming a minimum of 8 clock cycles have occured) the MPU output signals will be in the following states; VMA = "Low", BA = "Low", Data Bus = high impedance, R/W = "High" (read state), and the Address Bus will contain the reset address FFFE. Fig. 13 illustrates a power up sequence using the Reset control line. After the power supply reaches 4.75V, a minimum of eight clock cycles are required for the processor to stabilize in preparation for restarting. During these eight cycles, VMA will be in an indeterminate state so any devices that are enabled by VMA which could accept a false write during this time (such as a battery-backed RAM) must be disabled until VMA is forced "Low" after eight cycles. RES can go "High" asynchronously with the system clock any time after the eighth cycle.

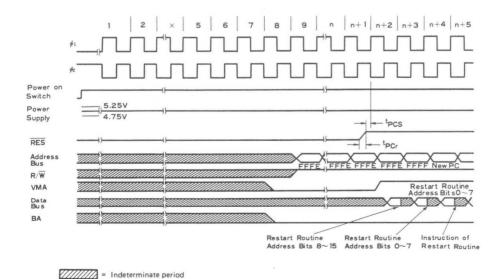


Figure 13 RES Timing

The Reset control line may also be used to reinitialize the MPU system at any time during its operation. This is accomplished by pulsing RES "Low" for the duration of a minimum of three complete ϕ_2 cycles. The RES pulse can be completely asynchronous with the MPU system clock and will be recognized during ϕ_2 if setup time tpcs is met.

Interrupt Request (IRQ)

This level sensitive input requests that an interrupt sequence be generated within the machine. The processor will wait until it completes the current instruction that is being executed before it recognizes the request. If the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The Program Counter, Index Register, Accumulators, and Condition Code Register are stored away on the stack.

Next the MPU will respond to the interrupt request by setting the interrupt mask bit "1" so that no further interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFF8 and FFF9. An address loaded at these locations causes the MPU to branch to an interrupt routine in memory. Interrupt timing is shown in Fig. 14.

The \overline{HALT} line must be in the "High" state for interrupts to be serviced. Interrupts will be latched internally while \overline{HALT} is "Low". The \overline{IRQ} has a high impedance pullup device internal to the chip; however a $3k\Omega$ external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Non-Maskable Interrupt (NMI) and Wait for Interrupt (WAI)

The MPU is capable of handling two types of interrupts: maskable (\overline{IRQ}) as described earlier, and non-maskable (\overline{NM}). IRQ is maskable by the interrupt mask in the Condition Code Register while \overline{NM} is not maskable. The handling of these interrupts by the MPU is the same except that each has its own vector address. The behavior of the MPU when interrupted is shown in Fig. 14 which details the MPU response to an interrupt while the MPU is executing the control program. The interrupt shown could be either \overline{IRQ} or \overline{NMI} and can be asynchronous with respect to ϕ_2 . The interrupt is shown going "Low" at time t_{PCS} in cycle #0 which precedes the first cycle of an instruction (OP code fetch). This instruction is not executed but instead the Program Counter (PC), Index Register (IX), Accumulators (ACCX), and the Condition Code Register (CCR) are pushed onto the stack.

The Interrupt Mask bit is set to prevent further interrupts. The address of the interrupt service routine is then fetched from FFFC, FFFD for an NMI interrupt and from FFF8, FFF9 for an IRQ interrupt. Upon completion of the interrupt service routine, the execution of RTI will pull the PC, IX, ACCX, and CCR off of the stack; the Interrupt Mask bit is restored to its condition prior to interrupts. Fig. 15 is a similar interrupt sequence, except in this case, a WAIT instruction has been executed in preparation for the interrupt. This technique speeds up the MPU's response to the interrupt because the stacking of

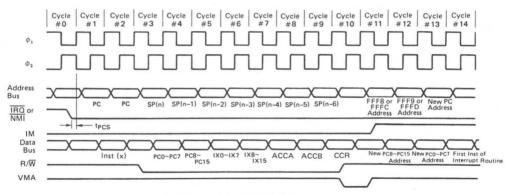
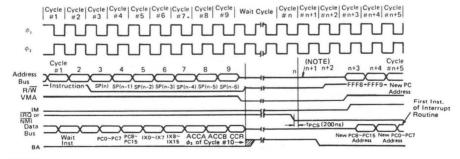


Figure 14 Interrupt Timing



(NOTE) Midrange waveform indicates high impedance state

Figure 15 WAI Instruction Timing



the PC, IX, ACCX, and the CCR is already done.

While the MPU is waiting for the interrupt, Bus Available will go "High" indicating the following states of the control lines: VMA is "Low", and the Address Bus, R/\overline{W} and Data Bus are all in the high impedance state. After the interrupt occurs, it is serviced as previously described.

Table 1 Memory Map for Interrupt Vectors

Ved	ctor	Description
MS	LS	Description
FFFE	FFFF	Restart
FFFC	FFFD	Non-maskable Interrupt
FFFA	FFFB	Software Interrupt
FFF8	FFF9	Interrupt Request

Refer to Figure 18 for program flow for Interrupts.

• Three State Control (TSC)

When the Three State Control (TSC) line is "High" level, the Address Bus and the R/\overline{W} line are placed in a high impedance State. VMA and BA are forced "Low" when TSC = "High" to prevent false reads or writes on any device enabled by VMA. It is necessary to delay program execution while TSC is held "High". This is done by insuring that no transitions of ϕ_1 (or ϕ_2) occur during this period. (Logic levels of the clocks are irrelevant so long as they do not change.)

Since the MPU is a dynamic device, the ϕ_1 clock can be stopped for a maximum time PW_{CH1} without destroying data within the MPU. TSC then can be used in a short Direct Me-

mory Access (DMA) application.

Fig. 16 shows the effect of TSC on the MPU. The Address Bus and R/\overline{W} line will reach the high impedance state at t_{TSD} (three-state delay), with VMA being forced "Low". In this example, the Data Bus is also in the high impedance state while ϕ_2 is being held "Low" since DBE= ϕ_2 . At this point in time, a DMA transfer could occur on cycles #3 and #4. When TSC is returned "Low," the MPU address and R/\overline{W} lines return to the bus. Because it is too late in cycle #5 to access memory, this cycle is dead and used for synchronization. Program execution resumes in cycle #6.

Valid Memory Address (VMA)

This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90pF may be directly driven by this active "High" signal.

• Halt (HALT)

When this input is in the "Low" state, all activity in the machine will be halted. This input is level sensitive.

The HALT line provides an input to the MPU to allow control or program execution by an outside source. If HALT is "High", the MPU will execute the instructions; if it is "Low", the MPU will go to a halted or idle mode. A response signal, Bus Available (BA) provides an indication of the current MPU status. When BA is "Low", the MPU is in the process of executing the control program; if BA is "High", the MPU has halted and all internal activity has stopped.

When BA is "High", the Address Bus, Data Bus, and R/\overline{W} line will be in a high impedance state, effectively removing the MPU from the system bus. VMA is forced "Low" so that the floating system bus will not activate any device on the bus that

is enabled by VMA.

While the MPU is halted, all program activity is stopped, and if either an \overline{NMI} or \overline{IRQ} interrupt occurs, it will be latched into the MPU and acted on as soon as the MPU is taken out of the halted mode. If a \overline{RES} command occurs while the MPU is halted, the following states occur: VMA = "Low", BA = "Low", Data Bus = high impedance, R/\overline{W} = "High" (read state), and the Address Bus will contain address FFFE as long as \overline{RES} is "Low". As soon as the \overline{RES} line goes "High", the MPU will go to locations FFFE and FFFF for the address of the reset routine.

Fig. 18 shows the timing relationships involved when halting the MPU. The instruction illustrated is a one byte, 2 cycle instruction such as CLRA. When \overline{HALT} goes "Low", the MPU will halt after completing execution of the current instruction. The transition of \overline{HALT} must occur tpcs before the trailing edge of ϕ_1 of the last cycle of an instruction (point A of Fig. 18). \overline{HALT} must not go "Low" any time later than the minimum tpcs specified.

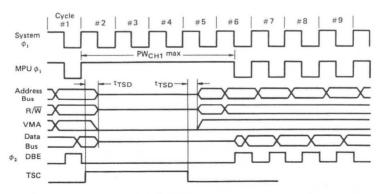


Figure 16 TSC Control Timing

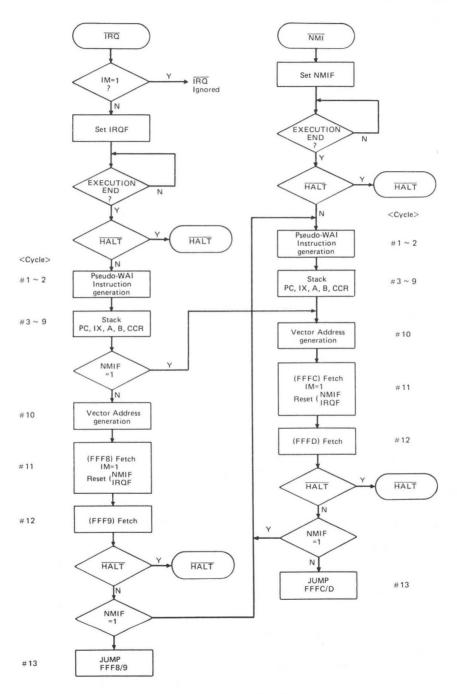
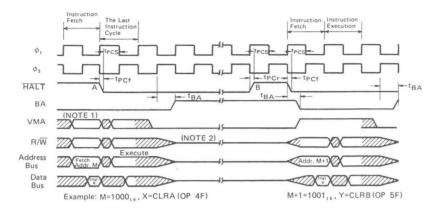


Figure 17 MPU Interrupt Flow Chart



(NOTE) 1. Oblique lines indicate indeterminate range of data.
2. Midrange waveform indicates high impedance, state.

Figure 18 HALT and Single Instruction Execution for System Dubug

Table 2 Operation States of MPU and Signal Outputs (Except the Execution of Instruction)

Signals	Halt state	Reset state	Halt and Reset state	WAI state	TSC state
ВА	"H"	"L"	"L"	"H"	"L"
VMA	"L"	"L"	"L"	"L"	"L"
R/W	"T"	"H"	"H"	"T"	"T"
$A_0 \sim A_{15}$	"T"	(FFFE) ₁₆	(FFFE) ₁₆	"T"	"T"
$D_0 \sim D_7$	"T"	"T"	"T"	"T"	_

[&]quot;T" indicates high impedance state.

The fetch of the OP code by the MPU is the first cycle of the instruction. If \overline{HALT} had not been "Low" at Point A but went "Low" during ϕ_2 of the cycle, the MPU would have halted after completion of the following instruction. BA will go "High" by time t_{BA} (bus available delay time) after the last instruction cycle. At this point in time, VMA is "Low" and R/\overline{W} , Address Bus, and the Data Bus are in the high impedance state.

To debug programs it is advantageous to step through programs instruction by instruction. To do this, \overline{HALT} must be brought "High" for one MPU cycle and then returned "Low" as shown at point B of Fig. 18. Again, the transitions of \overline{HALT} must occur t_{PCS} before the trailing edge of ϕ_1 . BA will go "Low" at t_{BA} after the leading edge of the next ϕ_1 , indicating that the Address Bus, Data Bus, VMA and R/\overline{W} lines are back on the bus. A single byte, 2 cycle instruction such as LSR is used for this example also. During the first cycle, the instruction Y is fetched from address M+1. BA returns "High" at t_{BA} on the last cycle of the instruction indicating the MPU is off the bus, if instruction Y had been three cycles, the width of the BA "Low" time would have been increased by one cycle.

Table 2 shows the relation between the state of MPU and signal outputs.

■ MPU INSTRUCTION SET

This Section will provide a brief introduction and discuss their use in developing HD6800 MPU control programs. The HD6800 MPU has a set of 72 different executable source instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions.

Each of the 72 executable instructions of the source language assembles into 1 to 3 bytes of machine code. The number of bytes depends on the particular instruction and on the addressing mode. (The addressing modes which are available for use with the various executive instructions are discussed later.)

The coding of the first (or only) byte corresponding to an executable instruction is sufficient to identify the instruction and the addressing mode. The hexadecimal equivalents of the binary codes, which result from the translation of the 72 instructions in all valid modes of addressing, are shown in Table 3. There are 197 valid machine codes, 59 of the 256 possible codes being unassigned.

When an instruction translates into two or three bytes of code, the second byte, or second and third bytes contain(s) an operand, an address, or information from which an address is obtained during execution.

Microprocessor instructions are often devided into three general classifications; (1) memory reference, so called because they operate on specific memory locations; (2) operating instructions that function without needing a memory reference; (3) I/O instructions for transferring data between the microprocessor and peripheral devices.

In many instances, the HD6800 MPU performs the same operation on both its internal accumulators and the external memory locations. In addition, the HD6800 MPU allow the MPU to treat peripheral devices exactly like other memory locations, hence, no I/O instructions as such are required. Because of these features, other classifications are more suitable for introducing the HD6800's instruction set: (1) Accumulator and memory operations; (2) Program control operations; (3) Condition Code Register operations.

For Accumulator and Memory Operations, refer to Table 4.

Table 3 Hexadecimal Values of Machine Codes

LSB	0	1	2	3	4	5	6	7	8	9	А	В	С	D	E	E
0		NOP (IMP)					TAP (IMP)	TPA (IMP)	INX (IMP)	DEX (IMP)	CLV (IMP)	SEV (IMP)	CLC (IMP)	SEC (IMP)	CLI (IMP)	SEI (IMP)
1	SBA (A, B)	CBA (A, B)					TAB (IMP)	TBA (IMP)		DAA (IMP)		ABA (IMP)		•		
2	BRA (REL)		BHI (REL)	BLS (REL)	BCC (REL)	BCS (REL)	BNE (REL)	BEO (REL)	BVC (REL)	BVS (REL)	BPL (REL)	BMI (REL)	BGE (REL)	BLT (REL)	BGT (REL)	BLE (REL)
3	TSX (IMP)	INS (IMP)	PUL (A)	PUL (B)	DES (IMP)	TXS (IMP)	PSH (A)	PSH (B)		RTS (IMP)	•	RTI (IMP)			WAI (IMP)	SWI (IMP)
4	NEG (A)			COM (A)	LSR (A)		ROR (A)	ASR (A)	ASL (A)	ROL (A)	DEC (A)	*	INC (A)	TST (A)	•	CLR (A)
5	NEG (B)			COM (B)	LSR (B)		ROR (B)	ASR (B)	ASL (B)	ROL (B)	DEC (B)		INC (B)	TST (B)		CLR (B)
6	NEG (IND)			COM (IND)	LSR (IND)		ROR (IND)	ASR (IND)	ASL (IND)	ROL (IND)	DEC (IND)		INC (IND)	TST (IND)	JMP (IND)	CLR (IND)
7	NEG (EXT)			COM (EXT)	LSR (EXT)		ROR (EXT)	ASR (EXT)	ASL (EXT)	ROL (EXT)	DEC (EXT)		INC (EXT)	TST (EXT)	JMP (EXT)	CLR (EXT)
8	SUB (IMM) ^(A)	CMP (IMM)(A)	SBC (IMM)(A)		AND (IMM)(A)	BIT (IMM)	LDA (IMM)	•	EOR (A)	ADC (A)	ORA (IMM)	ADD (A)	CPX (IMM)	BSR (REL)	LDS (IMM)	
9	SUB (A)	CMP (A)	SBC (A)		AND (A)	BIT (A)	LDA (DIR)	STA (DIR)	EOR (A)	ADC (A)	ORA (A)	ADD (A)	CPX (DIR)		LDS (DIR)	STS (DIR)
Α	SUB (A)	CMP (IND)	SBC (A)		AND (IND)	BIT (A)	LDA (IND)	STA (IND)	EOR (A)	ADC (A)	ORA (A)	ADD (A)	CPX (IND)	JSR (IND)	LDS (IND)	STS (IND)
В	SUB (A)	CMP (A)	SBC (EXT)(A)		AND (A)	BIT (EXT)	LDA (EXT)	STA (EXT)	EOR (A)	ADC (A)	ORA (A)	ADD (A)	CPX (EXT)(A)	JSR (EXT)	LDS (EXT)	STS (EXT)
С	SUB (B)	CMP (B)	SBC (B)		AND (B)	BIT (B)	LDA (IMM)(B)		EOR (B)	ADC (B)	ORA (B)	ADD (B)			LDX (IMM)	
D	SUB (B)	CMP (B)	SBC (B)		AND (B)	BIT (B)	LDA (B)	STA (B)	EOR (B)	ADC (B)	ORA (B)	ADD (B)			(DIR)	STX (DIR)
E	SUB (B)	CMP (B)	SBC (B)		AND (B)	BIT (IND) (B)	LDA (IND)	STA (B)	EOR (B)	ADC (B)	ORA (B)	ADD (B)	•		LDX (IND)	STX (IND)
F	SUB (B)	CMP (EXT)(B)	SBC (B)		AND (B)	BIT (EXT)(B)	LDA (EXT)	STA (EXT)(B)	EOR (B)	ADC (B)	ORA (B)	ADD (B)			LDX (EXT)	STX (EXT)

DIR = Direct Addressing Mode

EXT = Extended Addressing Mode IMM = Immediate Addressing Mode

IND = Index Addressing Mode

IMP = Implied Addressing Mode REL = Relative Addressing Mode

A = Accumulator A B = Accumulator B

Table 4 Accumulator and Memory Operations

Operation	Mnemonic	18.5	ME	-												Boolean/					
		1101	IIVIE	D	DII	REC	1	INL	DEX	1	EXI	ND		IMPL	-IE	Arithmetic Operation	5	4	3	2	-
		OF	~	#	OF	~	#	OP	~ #		OP	~ #		OP	~ #		Н	1	N	Z	٧
dd	ADDA	88	2	2	9B	3	2	AB	5	2 B	В	4	3			A + M → A	1		1	‡	1
	ADDB	СВ	2	2	DB	3		EB		2 F	В	4	3	- 1		$B + M \rightarrow B$	1		‡	‡	1
dd Acmitrs	ABA		-										1	B	2	1 A + B → A	1		‡	1	1
dd with Carry	ADCA	89	2	2	99	3	2	A9	5	2 B	19	4			-	$A + M + C \rightarrow A$	1		‡	1	1
dd with Carry	ADCB	C9	2	2	D9	3		E9		2 F			3			$B + M + C \rightarrow B$	1		1	1	t
- 4		84	2	2	94	3		A4	5	2 B			3			A · M → A			1	1	R
and	ANDA		2	2			2	E4		2 F			3			B · M → B			:	:	R
	ANDB	C4	2	2	D4	3												:		1	R
it Test	BITA	85	2	2	95	3		A5	5	2 B			3	-	- 1	A • M			‡		
	BITB	C5	2	2	D5	3		E5	5	2 F			3			B · M			‡	\$	R
lear	CLR							6F	7	2 7	F	6				00 → M			R	S	R
	CLRA															1 00 → A			R	S	R
	CLRB												1 5	5F	2	1 00 → B			R	S	R
ompare	CMPA	81	2	2	91	3	2	A1	5	2 B	1	4 :	3		- 1	A - M			1	‡	\$
	СМРВ	C1	2	2	D1	3		E1	5	2 F		4 :	3			B - M			1	1	1
ompare Acmitrs	CBA	٠.	-	_	-	-	- 1							11	2	1 A - B			1	1	1
	COM							63	7 :	2 7	2	6			-	$\overline{M} \rightarrow M$			1	1	R
omplement, 1's								03	,	2 /	3	0 ,									
	COMA															1 A → A			‡	‡	R
	COMB										l			53	2	1 B → B		•	‡	‡	
omplement, 2's	NEG							60	7	2 7	0	6				00 − M → M	•		\$	‡	1
Vegate)	NEGA												4	10	2	1 00 − A → A			1	‡	1
	NEGB										- 1			50	2	1 00 − B → B			1	1	1
onimal Adiust A	DAA															1 Converts Binary Add of BCD			1	1	1
ecimal Adjust, A	DAA												11.0	13	-	Characters into BCD Format		-	*		
	050								-											1	0
ecrement	DEC							6A	7	2 7	A	6			_	$M-1 \rightarrow M$	•		‡		4
	DECA															1 A − 1 → A	•		‡	\$	4
	DECB												1 5	5A	2	1 B − 1 → B			1	‡	4
xclusive OR	EORA	88	2	2	98	3	2	A8	5	2 B	8	4 :	3		- 1	$A \oplus M \rightarrow A$			1	\$	R
	EORB	C8	2	2	D8	3	2	E8		2 F	8	4 :	3			$B \oplus M \rightarrow B$			1	1	R
ncrement	INC		-	-		- 1		6C		2 7		6	3		- 1	M + 1 → M			1	1	(5)
Crement	INCA					. 1		00	'	-	٠,	0		1C	2	1 A + 1 → A			‡	‡	(5)
								- 1		1											
	INCB													5C	2	1 B + 1 → B			\$	‡	(5)
oad Acmitr	LDAA	86	2	2	96	3		A6		2 B		4 :				M → A	•		1	1	R
	LDAB	C6	2	2	D6	3	2	E6	5	2 F	6	4 :	3			M → B			1	‡	R
r, Inclusive	ORAA	8A	2	2	9A	3	2	AA	5	2 B	A	4 :	3			$A + M \rightarrow A$			1	‡	R
,	ORAB	CA	2	2	DA	3		EA		2 F		4 3				B + M → B			1	‡	R
		UA	-	-	DA	3	-			• '		7 1		00							
ush Data	PSHA							- 1													
	PSHB														7.1	1 B \rightarrow Msp, SP $-1 \rightarrow$ SP					
ull Data	PULA												13	32	4	1 SP + 1 → SP, Msp → A					
	PULB												13	33	4	1 SP + 1 → SP, Msp → B					
otate Left	ROL							69	7 3	2 7	9	6 :				M			1	1	(6)
Otate Lett	BOLA							00	1		-	× °		19	2	1 A			1	1	(6)
								- 1												:	6
	ROLB										- 1			59	2				\$		
otate Right	ROR							66	7 :	2 7	6	6				M)			‡	‡	(6)
	RORA							- 1					4			1 A +0 + 00000			1	‡	(6
	RORB												1 5	66	2	1 B C b7 → b0			1	1	(6
hift Left, Arithmetic	ASL							68	7 :	2 7	8	6	3			M)			1	‡	(6
int Lore, rentimetre	ASLA							00	1		٠	٠,		18	2	1 A D+ IIIIIII + 0			1	‡	(6)
	ASLB							- 1								1 B C b7 b0			1		6
											-			8	2					‡	
hift Right, Arithmetic	ASR							67	7 :	2 7	/	6			_	M)			\$	‡	(6
	ASRA												4			1 A			\$	‡	(6
	ASRB							- 1				- 1		57	2	1 B) b7 b0 C			1	\$	(6
hift Right, Logic	LSR							64	7 :	2 7	4	6 3	3			M)			R	1	(6)
	LSRA												4	14	2	1 A 0 + CONTIND + D			R	1	6
	LSRB															1 B b7 b0 C			R	1	(6
tore Acmitr	STAA				97	4	2	A7	6	2 B	7	5 3		1	-	A → M			1	1	R
ore Acmiti																					
	STAB		_	_	D7	4				2 F		5				B → M	•	•	1	‡	R
ubtract	SUBA	80	2	2	90	3				2 B		4 3			1	$A - M \rightarrow A$			\$	‡	1
	SUBB	CO	2	2	D0	3	2	E0	5	2 F	0	4 :	3			$B - M \rightarrow B$			\$	1	1
ubtract Acmitrs	SBA							1					1	10	2	1 A - B → A			1	‡	1
ubtr with Carry	SBCA	82	2	2	92	3	2	A2	5	2 B	2	4 3			-	$A - M - C \rightarrow A$			1	‡	1
abt. Hitti Carry		C2	2	2	D2	3				2 F		4			1						
	SBCB	02	1	2	UZ	3	4	-2	0		4	4 .			2	$B - M - C \rightarrow B$	1		1	‡	1
ransfer Acmitrs	TAB															1 A → B	•	•	\$	‡	R
	TBA													17	2	1 B → A			\$	‡	R
est Zero or Minus	TST							6D	7 :	2 7	D	6 3	3			M - 00			1	1	R
	TSTA						1						4	D	2	1 A - 00			1	1	R
	TSTB							- 1		1		- 1				1 B - 00			i	1	R
	.0.0	-				_	_		_	_	_	_	_	_	_			_	*	*	
EGEND:																SYMBOLS:					
P Operation Code (Hex	(adecimal)	+			lean					Н		alf-c	arry	y fro	m t	pit 3 R Reset Always					
Number of MPU Cyc	les	(+)			lean				3	1				mas		S Set Always					
Number of Program	Bytes	M			nplem			Λ		N	I N	egat	ive	(sign		t) ‡ Test and set if true, c	leared	d of	ther	wis	е
Arithmetic Plus		\rightarrow			nsfer					Z	Z	ero	(byt	te)		 Not Affected 					
Arithmetic Minus		0	- 1		= Zer e = Z					V	0	verf	fro	, 2's	COI	mplement					

- LEGEND:
 OP Operation Code (Hexadecimal)
 Number of MPU Cycles
 Number of Program Bytes
 Arithmetic Plus
 Arithmetic Rinus
 OBoolean AND
 OO

- Msp Contents of memory location pointed to be Stack Pointer
- Boolean Inclusive OR Boolean Exclusive OR Complement of M Transfer Into Bit = Zero Byte = Zero

(Note) Accumulator addressing mode instructions are included in the column for IMPLIED addressing.

CONDITION CODE REGISTER NOTES:

(Bit set if test is true and cleared otherwise)

- (Bit set if test is true and cleared otherwise)

 (Bit V) Test: Result = 10000000?

 (Bit C) Test: Result \$\phi\00000000?

 (Bit C) Test: Decimal value of most significant BCD Character greater than nine?
 - (Not cleared if previously set.)
- (Bit V) Test: Operand = 10000000 prior to execution? (Bit V) Test: Operand = 01111111 prior to execution?
- ⑥ (Bit V) Test: Set equal to result of N⊕C after shift has occurred.

■ PROGRAM CONTROL OPERATIONS

Program Control operation can be subdivided into two categories: (1) Index Register/Stack Pointer instructions: (2) Jump and Branch of operations.

Index Register/Stack Pointer Operations

The instructions for direct operation on the MPU's Index Register and Stack Pointer are summarized in Table 5. Decrement (DEX, DES), increment (INX, INS), load (LDX, LDS), and store (STX, STS) instructions are provided for both. The Compare instruction, CPX, can be used to compare the Index Register to a 16-bit value and update the Condition Code Register accordingly.

The TSX instruction causes the Index Register to be loaded with the address of the last data byte put onto the "stack". The TXS instruction loads the Stack Pointer with a value equal to one less than the current contents of the Index Register. This causes the next byte to be pulled from the "stack" to come from the location indicated by the Index Register. The utility of these two instructions can be clarified by describing the "stack" concept relative to the HMCS 6800 system.

The "stack" can be thought of as a sequential list of data stored in the MPU's read/write memory. The Stack Pointer contains a 16-bit memory address that is used to access the list from one end on a last-in-first-out (LIFO) basis in contrast to the random access mode used by the MPU's other addressing modes.

The HD6800 MPU instruction set and interrupt structure allow extensive use of the stack concept for efficient handling of data movement, subroutines and interrupts. The instructions can be used to establish one or more "stacks" anywhere in read/write memory. Stack length is limited only by the amount of memory that is made available.

Operation of the Stack Pointer with the Push and Pull instructions is illustrated in Figs. 19 and 20. The Push instruction (PSHA) causes the contents of the indicated accumulator (A in

this example) to be stored in memory at the location indicated by the Stack Pointer. The Stack Pointer is automatically decremented by one following the storage operation and is "pointing" to the next empty stack location.

The Pull instruction (PULA or PULB) causes the last byte stacked to be loaded into the appropriate accumulator. The Stack Pointer is automatically incremented by one just prior to the data transfer so that it will point to the last byte stacked rather than the next empty location. Note that the PULL instruction does not "remove" the data from memory; in the example, 1A is still in location (m+1) following execution of PULA. A subsequent PUSH instruction would overwrite than location with the new "pushed" data.

Execution of the Branch to Subroutine (BSR) and Jump to Subroutine (JSR) instructions cause a return address to be save on the stack as shown in Figs. 21 through 23. The stack is decremented after each byte of the return address is pushed onto the stack. For both of the these instructions, the return address is the memory location following the bytes of code that correspond to the BSR and JSR instruction. The code required for BSR or JSR may be either two or three bytes, depending on whether the JSR is in the indexed (two bytes) or the extended (three bytes) addressing mode. Before it is stacked, the Program Counter is automatically incremented the correct number of times to be pointing at the location of the next instruction. The Return from Subroutine instruction, RTS, causes the return address to be retrieved and loaded into the Program Counter as shown in Fig. 24.

There are several operations that cause the status of the MPU to be saved on the stack. The Software Interrupt (SWI) and Wait for Interrupt (WAI) instructions as well as the maskable (\overline{IRQ}) and non-maskable (\overline{NMI}) hardware interrupts all cause the MPU's internal registers (except for the Stack Pointer itself) to be stacked as shown in Fig. 25. MPU status is restored by the Return from interrupt, RTI, as shown in Fig. 26.

Table 5 Index Register and Stack Pointer Instructions

							Ad	dress	ing	Мо	des						2	C	onc	i. C	ode	Re	g.
Operation	Mnemonic	IM	ME	D	DIE	REC	т	IN	DE)	X	EX	TN	D	IME	PLII	ED	Boolean/ Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	, , , , , , , , , , , , , , , , , , ,	Н	1	N	Z	٧	С
Compare Index Reg	CPX	8C	3	3	9C	4	2	AC	6	2	вс	5	3				$(X_H) - (M), (X_L) - (M+1)$			1	‡	2	
Decrement Index Reg	DEX													09	4	1	$X - 1 \rightarrow X$				‡		
Decrement Stack Pntr	DES													34	4	1	$SP - 1 \rightarrow SP$			•			
Increment Index Reg	INX													08	4	1	$X + 1 \rightarrow X$				‡		
Increment Stack Pntr	INS								1					31	4	1	SP + 1 → SP			•			
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	6	2	FE	5	3				$M \rightarrow X_H, (M+1) \rightarrow X_I$			3	‡	R	
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	6	2	BE	5	3				$M \rightarrow SP_H, (M+1) \rightarrow SP_L$			3	‡	R	
Store Index Reg	STX				DF	5	2	EF	7	2	FF	6	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$			3	‡	R	
Store Stack Pntr	STS				9F	5	2	AF	7	2	BF	6	3				$SP_H \rightarrow M, SP_L \rightarrow (M+1)$			3	‡	R	
Index Reg → Stack Pntr	TXS													35	4	1	$X-1 \rightarrow SP$				•	•	
Stack Pntr → Index Reg	TSX													30	4	1	SP + 1 → X						

① (Bit N) Test: Sign bit of most significant (MS) byte of result = 1?

② (Bit V) Test: 2's complement overflow from subtraction of ms bytes?

(3) (Bit N) Test: Result less than zero? (Bit 15 = 1)

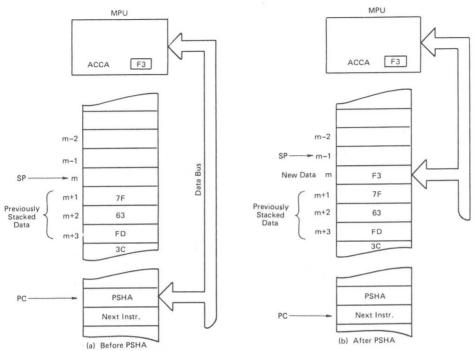
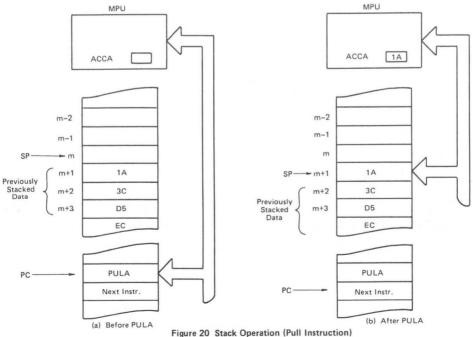


Figure 19 Stack Operation (Push Instruction)



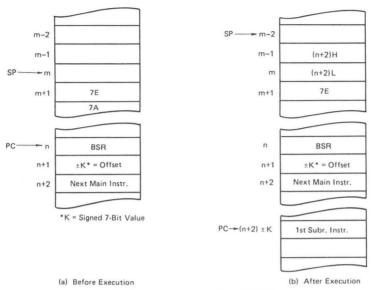


Figure 21 Program Flow for BSR

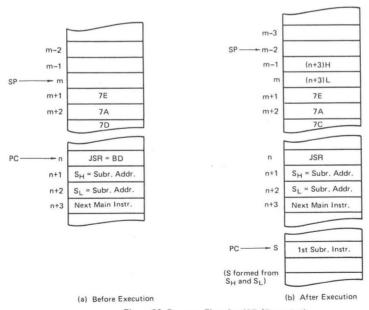


Figure 22 Program Flow for JSR (Extended)

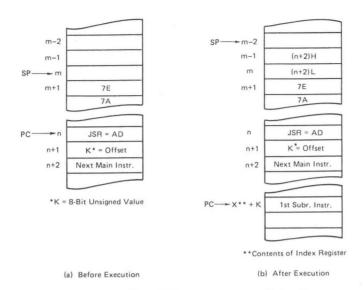


Figure 23 Program Flow for JSR (Indexed)

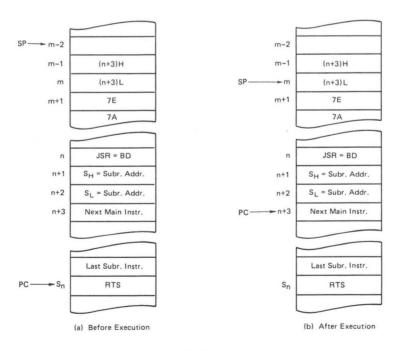


Figure 24 Program Flow for RTS



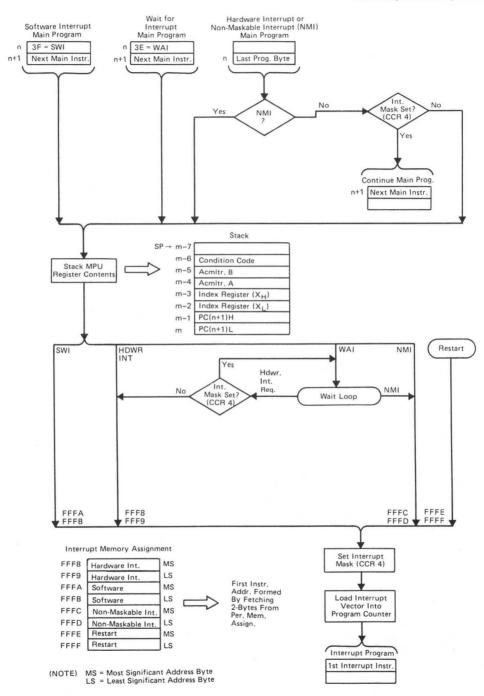


Figure 25 Program Flow for Interrupts

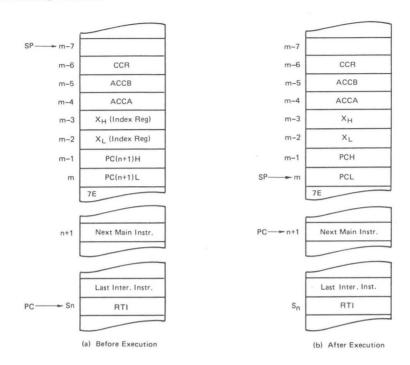


Figure 26 Program Flow for RTI

Jump and Branch Operation

The Jump and Branch instructions are summarized in Table 6. These instructions are used to control the transfer of operation from one point to another in the control program.

The No Operation instruction, NOP, while included here, is a jump operation in a very limited sense. Its only effect is to increment the Program Counter by one. It is useful during program development as a "stand-in" for some other instruction that is to be determined during debug. It is also used for equalizing the execution time through alternate paths in a control program.

Execution of the Jump Instruction, JMP, and Branch Always, BRA, affects program flow as shown in Fig. 27. When the MPU encounters the Jump (Index) instruction, it adds the offset to the value in the Index Register and uses the result as the address of the next instruction to be executed. In the extended addressing mode, the address of the next instruction to be executed is fetched from the two locations immediately following the JMP instruction. The Branch Always (BRA) instruction is similar to the JMP (extended) instruction except that the relative addressing mode applies and the branch is limited to the range within -125 or +127 bytes of the branch instruction itself. The opcode for the BRA instruction requires one less byte than JMP (extended) but takes one more cycle to execute.

The effect on program flow for the Jump to Subroutine (JSR) and Branch to Subroutine (BSR) is shown in Figs. 21 through 23. Note that the Program Counter is properly in-

cremented to be pointing at the correct return address before it is stacked. Operation of the Branch to Subroutine and Jump to Subroutine (extended) instruction is similar except for the range. The BSR instruction requires less opcode than JSR (2 bytes versus 3 bytes) and also executes one cycle faster than JSR. The Return from Subroutine, RTS, is used at the end of a subroutine to return to the main program as indicated in Fig. 24.

The effect of executing the Software Interrupt, SWI, and the Wait for Interrupt, WAI, and their relationship to the hardware interrupts is shown in Fig. 25. SWI causes the MPU contents to be stacked and then fetches the starting address of the interrupt routine from the memory locations that respond to the addresses FFFA and FFFB. Note that as in the case of the subroutine instructions, the Program Counter is incremented to point at the correct return address before being stacked. The Return from Interrupt instruction, RTI, (Fig. 26) is used at the end of an interrupt routine to restore control to the main program. The SWI instruction is useful for inserting break points in the control program, that is, it can be used to stop operation and put the MPU registers in memory where they can be examined. The WAI instruction is used to decrease the time required to service a hardware interrupt; it stacks the MPU contents and then waits for the interrupt to occur, effectively removing the stacking time from a hardware interrupt sequence.

Table 6	HIMP	PRANCH	Instruction
I anie n	JUNE	BRANGE	Instruction

					,	Add	ressi	ng Mo	des							Con	d. C	ode	Reg.	
Operation	Mnemonic	REL	ATI	VE	IN	DE	X	E	(TN	D	IM	PLIE	ED	Branch Test	5	4	3	2	1	0
100 pt (100 pt/2002) 4000 b		OP	~	#	OP	~	#	ОР	~	#	OP	~	#		Н	1	N	Z	V	С
Branch Always	BRA	20	4	2										None	•	•	•	•	•	•
Branch If Carry Clear	BCC	24	4	2										C = 0			•	•	•	•
Branch If Carry Set	BCS	25	4	2										C = 1	•		•	•	•	•
Branch If = Zero	BEQ	27	4	2										Z = 1			•			
Branch If ≧ Zero	BGE	2C	4	2										N + V = 0						
Branch If > Zero	BGT	2E	4	2										$Z + (N \oplus V) = 0$						
Branch If Higher	BHI	22	4	2										C + Z = 0		•	•	•		•
Branch If ≤ Zero	BLE	2F	4	2										$Z + (N \oplus V) = 1$			•	•		
Branch If Lower Or Same	BLS	23	4	2										C + Z = 1		•		•	•	
Branch If < Zero	BLT	2D	4	2										N + V = 1		•			•	
Branch If Minus	BMI	2B	4	2										N = 1		•		•		•
Branch If Not Equal Zero	BNE	26	4	2										Z = 0	•	•				
Branch If Overflow Clear	BVC	28	4	2										V = 0						
Branch If Overflow Set	BVS	29	4	2			1							V = 1						
Branch If Plus	BPL	2A	4	2										N = 0		•				
Branch To Subroutine	BSR	8D	8	2											•	•	•		•	
Jump	JMP				6E	4	2	7E	3	3					•		•			
Jump To Subroutine	JSR	1			AD	8	2	BD	9	3					•	•				
No Operation	NOP	1									01	2	1	Advances Prog Cntr Only	•					
Return From Interrupt	RTI										3B	10	1		-	-	- (<u> </u>	-	-
Return From Subroutine	RTS										39	5	1							
Software Interrupt	SWI										3F	12	1			S				
Wait for Interrupt	WAI										3E	9	1		•	2	•		•	

- ① (All) Load Condition Code Register from Stack. (See Special Operations)
- ② (Bit I) Set when interrupt occurs. If previously set, a Non-Maskable interrupt is required to exit the wait state.

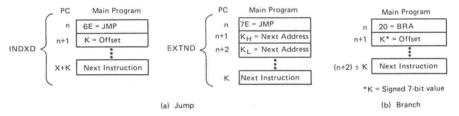


Figure 27 Program Flow for JUMP/BRANCH Instructions

BMI		N = 1;	BEQ	:	Z = 1;
			BNE	:	Z = 0;
BVC	:	V = 0;	BCC		C = 0;
BVS	:	V = 1;	BCS		C = 1;
вні	:	C + Z = 0;	BLT	:	$N \oplus V = 1$;
BLS	:	C + Z = 1;	BGE	:	$N \oplus V = 0$;
		BLE : Z+(1	V (V V)	= 1	:
		BGT : Z+()	(V (+) V)	= ();

Figure 28 Conditional Branch Instructions

The conditional branch instructions, Fig. 28, consists of seven pairs of complementary instructions. They are used to test the results of the preceding operation and either continue with the next instruction in sequence (test fails) or cause a branch to another point in the program (test succeeds).

Four of the pairs are used for simple tests of status bits N, Z, V, and C:

- Branch on Minus (BMI) and Branch On Plus (BPL) tests the sign bit, N, to determine if the previous result was negative or positive, respectively.
- 2. Branch On Equal (BEQ) and Branch On Not Equal (BNE) are used to test the zero status bit, Z, to determine whether or not the result of the previous operation was equal to "0". These two instructions are useful following a Compare (CMP) instruction to test for equality between an accumulator and the operand. They are also used following the Bit Test (BIT) to determine whether or not the same bit positions are set in an accumulator and the operand.

3. Branch On Overflow Clear (BVC) and Branch On Overflow Set (BVS) tests the state of the V bit to determine if the previous operation caused an arithmetic overflow.

4. Branch On Carry Clear (BCC) and Branch On Carry Set (BCS) tests the state of the C bit to determine if the previous operation caused a carry to occur. BCC and BCS are useful for testing relative magnitude when the values being tested are regarded as unsigned binary numbers, that is, the values are in the range "00" (lowest) of "FF" (highest). BCC following a comparison (CMP) will cause a branch if the (unsigned) value in the accumulator is higher than or the same as the value of the operand. Conversely, BCS will cause a branch if the accumulator value is lower than the operand.

The Fifth complementary pair, Branch On Higher (BHI) and Branch On Lower or Same (BLS) are in a sense complements to BCC and BCS. BHI tests for both C and Z = "0", if used following a CMP, it will cause a branch if the value in the accumulator is higher than the operand. Conversely, BLS will cause a branch if the unsigned binary value in the accumulator is lower than or the same as the operand.

The remaining two pairs are useful in testing results of operations in which the values are regarded as signed two's complement numbers. This differs from the unsigned binary case in the following sense: In unsigned, the orientation is higher or lower; in signed two's complement, the comparison is between larger or smaller where the range of values is between -128 and +127.

Branch On Less Than Zero (BLT) and Branch On Greater Than Or Equal Zero (BGE) test the status bits for N⊕V = "1" and N ⊕ V = "0", respectively. BLT will always cause a branch following an operation in which two negative numbers were added. In addition, it will cause a branch following a CMP in which the value in the accumulator was negative and the operand was positive. BLT will never cause a branch following a CMP in which the accumulator value was positive and the operand negative. BGE, the complement to BLT, will cause a branch following operations in which two positive values were added or in which the result was "0"

The last pair, Branch On Less Than Or Equal Zero (BLE) and Branch On Greater Than Zero (BGT) test the status bits for $Z \oplus (N + V) = "1"$ and $Z \oplus (N + V) = "0"$, respectively, The action of BLE is identical to that for BLT except that a branch will also occur if the result of the previous result was "O". Conversely, BGT is similar to BGE except that no branch will occur following a "0" result.

■ CONDITION CODE REGISTER OPERATIONS

The Condition Code Register (CCR) is a 6-bit register within the MPU that is useful in controlling program flow during system operation. The bits are defined in Fig. 29.

The instructions shown in Table 7 are available to the user for direct manipulation of the CCR. In addition, the MPU automatically sets or clears the appropriate status bits as many of the other instructions on the condition code register was indicated as they were introduced.

Systems which require an interrupt window to be opened under program control should use a CLI-NOP-SEI sequence rather than CLI-SEL.

b5	b4	b3	b2	b1	b0
Н	1	N	Z	V	С

- H = Half-carry; set whenever a carry from b3 to b4 of the result is generated by ADD, ABA, ADC; cleared if no b3 to b4 carry: not affected by other instructions.
- I = Interrupt Mask; set by hardware of software interrupt or SEI instruction; cleared by CLI instruction. (Normally not used in arithmetic operations.) Restored to a "O" as a result of an RTI instruction if IM stored on the stacked is "0"
- N = Negative; set if high order bit (b7) of result is set; cleared otherwise.
- Z = Zero; set if result = "0"; cleared otherwise.
- V = Overflow; set if there was arithmetic overflow as a result of the operation: cleared otherwise.
- C = Carry; set if there was a carry from the most significant bit (b7) of the result; cleared otherwise.

Figure 29 Condition Code Register Bit Definition

ADDRESSING MODES

The MPU operates on 8-bit binary numbers presented to it via the Data Bus. A given number (byte) may represent either data or an instruction to be executed, depending on where it is encountered in the control program. The HD6800 MPU has 72 unique instructions, however, it recognizes and takes action on 197 of the 256 possibilities that can occur using an 8-bit word length. This larger number of instructions results from the fact that many of the executive instructions have more than one addressing mode.

Table 7 Condition Code Register Instructions

		Add	dressi	ng			Co	nd. C	ode F	Reg.	
Operations	Mnemonic		LIEC)	Boolean Operation	5	4	3	2	1	0
		OP	~	#	3-00-04-04-04-04-04-04-04-04-04-04-04-04-	Н	-1	N	Z	٧	С
Clear Carry	CLC	ОС	2	1	0 → C	•	•	•		•	R
Clear Interrupt Mask	CLI	OE	2	1	0 -> 1	•	R			•	
Clear Overflow	CLV	0A	2	1	0 → V	•		•		R	
Set Carry	SEC	0D	2	1	1 → C	•	•	•	•	•	S
Set Interrupt Mask	SEI	OF	2	1	1 → 1	•	S	•	•	•	
Set Overflow	SEV	OB	2	1	1 → V	•	•		•	S	
AcmItr A → CCR	TAP	06	2	1	A → CCR	-		(1)	_	_
CCR → Acmltr A	TPA	07	2	1	CCR → A	•	•				

R = Reset

S = Set

 ⁼ Not affected

⁽ALL) Set according to the contents of Accumulator A.

These addressing modes refer to the manner in which the program causes the MPU to obtain its instructions and data. The programmer must have a method for addressing the MPU's internal registers and all of the external memory locations.

Selection of the desired addressing mode is made by the user as the source statements are written. Translation into appropriate opcode then depends on the method used. If manual translation is used, the addressing mode is implied in the opcode. For example, the Immediate, Direct, Indexed, and Extended modes may all be used with the ADD instruction. The proper mode is determined by selecting (hexidecimal notation) 8B, 9B, AB, or BB, respectively.

The source statement format includes adequate information for the selection if an assembler program is used to generate the opcode. For instance, the Immediate mode is selected by the

Assembler whenever it encounters the "#" symbol in the operand field. Similarly, an "X" in the operand field causes the Indexed mode to be selected. Only the Relative mode applies to the branch instructions, therefore, the mnemonic instruction itself is enough for the Assembler to determine addressing mode.

For the instructions that use both Direct and Extended modes, the Assembler selects the Direct mode if the operand value is in the range $0\sim255$ and Extended otherwise. There are a number of instructions for which the Extended mode is valid but the Direct is not. For these instructions, the Assembler automatically selects the Extended mode even if the operand is in the $0\sim255$ range. The addressing modes are summarized in Fig. 30.

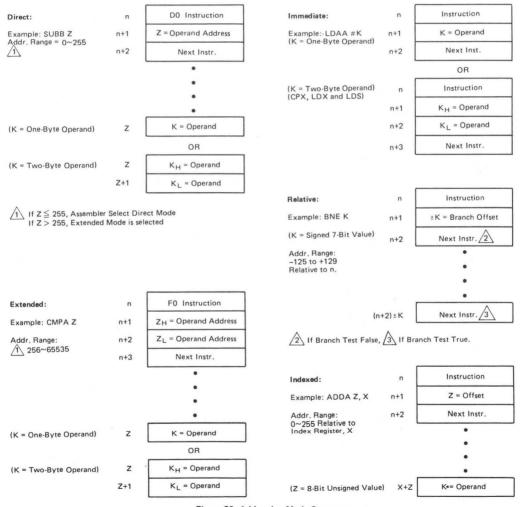


Figure 30 Addressing Mode Summary



Implied (Includes "Accumulator Addressing" Mode)

The successive fields in a statement are normally separated by one or more spaces. An exception to this rule occurs for instructions that use dual addressing in the operand field and for instructions that must distinguish between the two accumulators. In these cases, A and B are "operands" but the space between them and the operator may be omitted. This is commonly done, resulting in apparent four character mnemonics for those instructions.

The addition instruction, ADD, provides an example of dual addressing in the operand fields;

	Operator	Operand		Comm	nent			
	ADDA	MEM12	ADD	CONTENTS	OF	MEM12	TO	ACCA
or	ADDB	MEM12	ADD	CONTENTS	OF	MEM12	TO	ACCB

The example used earlier for the test instruction, TST, also applies to the accumulators and uses the "accumulator addressing mode" to designate which of the two accumulators is being tested:

O	perator	Comment
	TSTB	TEST CONTENTS OF ACCB
or	TSTA	TEST CONTENTS OF ACCA

A number of the instructions either alone or together with an accumulator operand contain all of the address information that is required, that is, "inherent" in the instruction, itself. For instance, the instruction ABA causes the MPU to add the contents of accumulators A and B together and place the result in accumulator A. The instruction INCB, another example of "accumulator addressing", causes the contents of accumulator B to be increased by one. Similarly, INX, increment the Index Register, causes the contents of the Index Register to be increased by one.

Program flow for instructions of this type is illustrated in Figures 31 and 32. In these figures, the general case is shown on the left and a specific example is shown on the right. Numerical examples are in decimal notation. Instructions of this type require only one byte of opcode. Cycle-by-cycle operation of the implied mode is shown in Table 8.

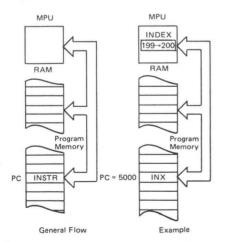


Figure 31 Implied Addressing

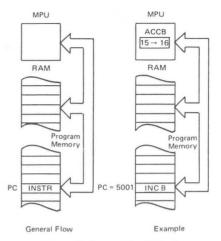


Figure 32 Accumulator Addressing

Immediate Addressing Mode

In the Immediate addressing mode, the operand is the value that is to be operated on. For instance, the instruction

Operator	Operand	Comment
LDAA	#25	LOAD 25 INTO ACCA

causes the MPU to "immediately load accumulator A with the value 25"; no further address reference is required. The Immediate mode is selected by preceding the operand value with the "#" symbol. Program flow for this addressing mode is illustrated in Fig. 33.

The operand format allows either properly defined symbols or numerical values. Except for the instructions CPX, LDX, and LDS, the operand may be any value in the range $0 \sim 255$. Since Compare Index Register (CPX), Load Index Register (LDX), Load Stack Pointer (LDS), require 16-bit values, the immediate mode for these three instructions requie two-byte operands.

Table 9 shows the cycle-by-cycle operation for the immediate addressing mode.

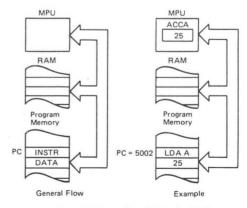


Figure 33 Immediate Addressing Mode



Table 8 Implied Mode Cycle by Cycle Operation

Addres and Inst		Cycle	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
ABA DA			1	1	Op Code Address	1	Op Code
ASL DE ASR INC CBA LS	C SEV	2	2	1	Op Code Address + 1	1	Op Code of Next Instruction
CLC NE							
CLI NO							
CLR RO							
CLV RO							
COM SB	Α						
DES			1	1	Op Code Address	1	Op Code
INS		4	2	1 0	Op Code Address + 1 Previous Register Contents	1 1	Op Code of Next Instruction Irrelevant Data (NOTE 1)
INX			4	0	New Register Contents	1 1	Irrelevant Data (NOTE 1)
PSH		+	1	1	Op Code Address	1	Op Code
			2	1	Op Code Address + 1	1 1	Op Code of Next Instruction
		4	3	1	Stack Pointer	0	Accumulator Data
			4	0	Stack Pointer - 1	1	Accumulator Data
PUL			1	1	Op Code Address	1	Op Code
		4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
			3	0	Stack Pointer Stack Pointer + 1	1 1	Irrelevant Data (NOTE 1) Operand Data from Stack
		-	-	-		-	
TSX			1 2	1	Op Code Address Op Code Address + 1	1	Op Code Op Code of Next Instruction
		4	3	0	Stack Pointer	1	Irrelevant Data (NOTE 1)
			4	0	New Index Register	1	Irrelevant Data (NOTE 1)
TXS			1	1	Op Code Address	1	Op Code
		4	2	1	Op Code Address + 1	1	Op Code of Next Instruction
		4	3	0	Index Register	1	Irrelevant Data
			4	0	New Stack Pointer	1	Irrelevant Data
RTS			1	1	Op Code Address	1	Op Code
		5	2	1	Op Code Address + 1	1	Irrelevant Data (NOTE 2)
		5	3	0	Stack Pointer Stack Pointer + 1	1 1	Irrelevant Data (NOTE 1) Address of Next Instruction (High Order By
		1	5	1	Stack Pointer + 2	i	Address of Next Instruction (Low Order By
WAI			1	1	Op Code Address	1	Op Code
			2	1	Op Code Address + 1	1	Op Code of Next Instruction
			3	1	Stack Pointer	0	Return Address (Low Order Byte)
		9	4 5	1	Stack Pointer - 1 Stack Pointer - 2	0	Return Address (High Order Byte) Index Register (Low Order Byte)
		9	6	1	Stack Pointer – 2	0	Index Register (High Order Byte)
			7	1	Stack Pointer – 4	0	Contents of Accumulator A
			8	1	Stack Pointer - 5	0	Contents of Accumulator B
			9	1	Stack Pointer - 6 (NOTE 3)	1	Contents of Cond. Code Register
RTI			1	1	Op Code Address	1	Op Code
			2	1	Op Code Address + 1	1	Irrelevant Data (NOTE 2)
			3	0	Stack Pointer Stack Pointer + 1	1 1	Irrelevant Data (NOTE 1) Contents of Cond, Code Register from Stac
			5	1	Stack Pointer + 1	1 1	Contents of Cond. Code Register from Stack
		10	6	1	Stack Pointer + 3	1	Contents of Accumulator A from Stack
			7	1	Stack Pointer + 4	1	Index Register from Stack (High Order Byt
			8	1	Stack Pointer + 5	1	Index Register from Stack (Low Order Byte
			9	1	Stack Pointer + 6	1	Next Instruction Address from Stack (High Order Byte)
			10	1	Stack Pointer + 7	1	Next Instruction Address from Stack (Low Order Byte)
SWI			1	1	Op Code Address	1	Op Code
			2	1	Op Code Address + 1	1	Irrelevant Data (NOTE 1)
			3	1	Stack Pointer	0	Return Address (Low Order Byte)
			4	1	Stack Pointer — 1	0	Return Address (High Order Byte)
			5	1	Stack Pointer - 2 Stack Pointer - 3	0	Index Register (Low Order Byte) Index Register (High Order Byte)
		12	7	1	Stack Pointer – 3	0	Contents of Accumulator A
			8	i	Stack Pointer – 5	0	Contents of Accumulator B
				100			
			9	1	Stack Pointer — 6	0	Contents of Cond. Code Register
			9 10 11	1 0 1	Stack Pointer — 6 Stack Pointer — 7 Vector Address FFFA (Hex)	1 1	Contents of Cond. Code Register Irrelevant Data (NOTE 1) Address of Subroutine (High Order Byte)

NOTE 1. If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition.

Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.

NOTE 2. Data is ignored by the MPU.

NOTE 3. While the MPU is waiting for the interrupt, Bus Available will go "High" indicating the following states of the control lines: VMA is "Low"; Address Bus,R/W, and Data Bus are all in the high impedance state.



Table 9 Immediate Mode Cycle by Cycle Operation

	ddress Mode Instructions	Cycle	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
ADC ADD AND BIT CMP	EOR LDA ORA SBC SUB	2	1 2	1	Op Code Address Op Code Address + 1	1 1	Op Code Operand Data
DS DX		3	1 2 3	1 1 1	Op Code Address Op Code Address + 1 Op Code Address + 2	1 1 1	Op Code Operand Data (High Order Byte) Operand Data (Low Order Byte)

Direct and Extended Addressing Modes

In the Direct and Extended modes of addressing, the operand field of the source statement is the address of the value that is to be operated on. The Direct and Extended modes differ only in the range of memory locations to which they can direct the MPU. Direct addressing generates a single 8-bit operand and, hence, can address only memory locations 0 \sim 255; a two byte operand is generated for Extended addressing, enabling the MPU to reach the remaining memory locations, 256 \sim 65535. An example of Direct addressing and its effect on program flow is illustrated in Fig. 34.

Table 10 shows the cycle-by-cycle operations of this mode.

The MPU, after encountering the opcode for the instrution LDAA (Direct) at memory location 5004 (Program Counter = 5004), looks in the next location, 5005, for the address of the operand. It then sets the program counter equal to the value found there (100 in the example) and fetches the operand, in

this case a value to be loaded into accumulator A, from that location. For instructions requiring a two-byte operand such as LDX (Load the Index Register), the operand bytes would be retrieved from locations 100 and 101.

Extended addressing, Fig. 35, is similar except that a two-byte address is obtained from locations 5007 and 5008 after the LDAB (Extended) opcode shows up in location 5006. Extended addressing can be thought of as the "standard" addressing mode, that is, it is a method of reaching anyplace in memory. Direct addressing, since only one address byte is required, provides a faster method of processing data and generates fewer bytes of control code. In most applications, the direct addressing range, memory locations 0 ~ 255, are reserved for RAM. They are used for data buffering and temporary storage of system variables, the area in which faster addressing is of most value, Cycle-by-cycle operation is shown in Table 11 for Extended Addressing.

Table 10 Direct Mode Cycle by Cycle Operation

Address Mode and Instructions	Cycle	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
ADC EOR		1	1	Op Code Address	1	Op Code
ADD LDA		2	1	Op Code Address + 1	1	Address of Operand
AND ORA	3	3	1	Address of Operand	1	Operand Data
BIT SBC						
CMP SUB						
CPX		1	1	Op Code Address	1	Op Code
LDS		2	1	Op Code Address + 1	1	Address of Operand
LDX	4	3	1	Address of Operand	1	Operand Data (High Order Byte)
		4	1	Operand Address + 1	1	Operand Data (Low Order Byte)
STA		1	1	Op Code Address	1	Op Code
		2	1	Op Code Address + 1	1	Destination Address
	4	3	0	Destination Address	1	Irrelevant Data (NOTE 1)
		4	1	Destination Address	0	Data from Accumulator
STS		1	1	Op Code Address	1	Op Code
STX		2	1	Op Code Address + 1	1	Address of Operand
	5	3	0	Address of Operand	1	Irrelevant Data (NOTE 1)
		4	1	Address of Operand	0	Register Data (High Order Byte)
		5	1	Address of Operand + 1	0	Register Data (Low Order Byte)

NOTE 1. If device which is address during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition.

Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.

Table 11 Extended Mode Cycle by Cycle

Address Mode and Instructions	Cycle	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
STS STX	6	1 2 3 4 5 6	1 1 1 0 1	Op Code Address Op Code Address + 1 Op Code Address + 2 Address of Operand Address of Operand Address of Operand	1 1 1 1 0 0	Op Code Address of Operand (High Order Byte) Address of Operand (Low Order Byte) Irrelevant Data (NOTE 1) Operand Data (High Order Byte) Operand Data (Low Order Byte)
JSR	9	1 2 3 4 5 6 7 8	1 1 1 1 1 1 0 0	Op Code Address Op Code Address + 1 Op Code Address + 2 Subroutine Starting Address Stack Pointer Stack Pointer - 1 Stack Pointer - 2 Op Code Address + 2 Op Code Address + 2	1 1 1 1 0 0 1 1	Op Code Address of Subroutine (High Order Byte) Address of Subroutine (Low Order Byte) Op Code of Next Instruction Return Address (Low Order Byte) Return Address (High Order Byte) Irrelevant Data (NOTE 1) Address of Subroutine (Low Order Byte)
JMP	3	1 2 3	1 1 1	Op Code Address Op Code Address + 1 Op Code Address + 2	1 1 1	Op Code Jump Address (High Order Byte) Jump Address (Low Order Byte)
ADC EOR ADD LDA AND ORA BIT SBC CMP SUB	4	1 2 3 4	1 1 1	Op Code Address Op Code Address + 1 Op Code Address + 2 Address of Operand	1 1 1 1	Op Code Address of Operand (High Order Byte) Address of Operand (Low Order Byte) Operand Data
CPX LDS LDX	5	1 2 3 4 5	1 1 1 1 1 1	Op Code Address Op Code Address + 1 Op Code Address + 2 Address of Operand Address of Operand + 1	1 1 1 1	Op Code Address of Operand (High Order Byte) Address of Operand (Low Order Byte) Operand Data (High Order Byte) Operand Data (Low Order Byte)
STA A STA B	5	1 2 3 4 5	1 1 1 0	Op Code Address Op Code Address + 1 Op Code Address + 2 Operand Destination Address Operand Destination Address	1 1 1 1 0	Op Code Destination Address (High Order Byte) Destination Address (Low Order Byte) Irrelevant Data (NOTE 1) Data from Accumulator
ASL LSR ASR NEG CLR ROL COM ROR DEC TST INC	6	1 2 3 4 5 6	1 1 1 1 0 1/0 (NOTE 2)	Op Code Address Op Code Address + 1 Op Code Address + 2 Address of Operand Address of Operand Address of Operand	1 1 1 1 1 0	Op Code Address of Operand (High Order Byte) Address of Operand (Low Order Byte) Current Operand Data Irrelevant Data (NOTE 1) New Operand Data (NOTE 2)

NOTE 1. If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition.

Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.

NOTE 2. For TST, VMA = 0 and Operand data does not change.

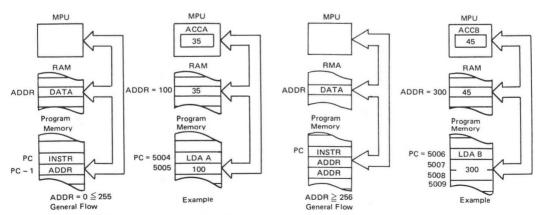


Figure 34 Direct Addressing Mode

Figure 35 Extended Addressing Mode

Relative Address Mode

In both the Direct and Extended modes, the address obtained by the MPU is an absolute numerical address. The Relative addressing mode, implemented for the MPU's branch instructions, specifies a memory location relative to the Program Counter's current location. Branch instructions generate two bytes of machine code, one for the instruction opcode and one for the "relative" address (see Fig. 36). Since it is desirable to be able to branch in either direction, the 8-bit address byte is interpreted as a signed 7-bit value; the 8th bit of the operand is treated as a sign bit, "0" = plus and "1" = minus. The remaining seven bits represent the numerical value. This result in a relative addressing range of ±127 with respect to the location of the branch instruction itself. However, the branch range is computed with respect to the next instruction that would be executed if the branch conditions are not satisfied. Since two byte are generated, the next instruction is located at PC+2. If, D is defined as the address of the branch destination, the range is then:

or $(PC+2) -128 \le D \le (PC+2) + 127$ $PC -126 \le D \le PC + 129$ that is, the destination of the branch instruction must be within -126 to +129 memory locations of the branch instruction itself. For transferring control beyond this range, the unconditional jump (JMP), jump to subroutine (JSR), and return from subroutine (RTS) are used.

In Fig. 36, when the MPU encounters the opcode for BEQ (Branch if result of last instruction was zero), it tests the Zero bit in the Condition Code Register. If that bit is "0", indicating a non-zero result, the MPU continues execution with the next instruction (in location 5010 in Fig. 36). If the previous result was zero, the branch condition is satisfied and the MPU adds the offset, 15 in this case, to PC+2 and branches to location 5025 for the next instruction.

The branch instructions allow the programmer to efficiently direct the MPU to one point or another in the control program depending on the outcome of test results. Since the control program is normally in read-only memory and cannot be changed, the relative address used in execution of branch instructions is a constant numerical value. Cycle-by-cycle operation is shown in Table 12 for relative addressing.

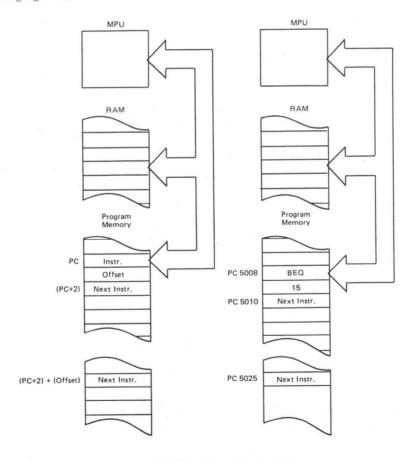


Figure 36 Relative Addressing Mode



Table 12	Relative	Mode	Cycle-by	v-C	vcle	Operation
----------	----------	------	----------	-----	------	-----------

	dress Me nstruct		Cycle	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
BCS BEQ BGE	BHI BLE BLS BLT BMI	BNE BPL BRA BVC BVS	4	1 2 3 4	1 1 0 0	Op Code Address Op Code Address + 1 Op Code Address + 2 Branch Address	1 1 1 1	Op Code Branch Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1)
BSR			8	1 2 3 4 5 6 7 8	1 1 0 . 1 1 0 0	Op Code Address Op Code Address + 1 Return Address of Main Program Stack Pointer Stack Pointer — 1 Stack Pointer — 2 Return Address of Main Program Subroutine Address	1 1 1 0 0 1 1	Op Code Branch Offset Irrelevant Data (NOTE 1) Return Address (Low Order Byte) Return Address (High Order Byte) Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1)

NOTE 1. If device which is addressed during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition.

Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.

Indexed Addressing Mode

With Indexed addressing the numerical address is variable and depend on the current contents of the Index Register. A source statement such as

Operator	Operand	Commer	nt
STAA	X	PUT A IN INDEXE	LOCATION
		and the same of th	

causes the MPU to store the contents of accumulator A in the memory location specified by the contents of the Index Register (recall that the label X is reserved to designate the Index Register). Since there are instructions for manipulating X during program execution (LDX, INX, DEX, etc.), the Indexed addressing mode provides a dynamic "on the fly" way to modify program activity.

The operand field can also contain a numerical value that will be automatically added to X during execution. This format is illustrated in Fig. 37.

When the MPU encounters the LDAB (Indexed) opcode in location 5006, it looks in the next memory location for the value to be added to X (5 in the example) and calculates the required address by adding 5 to the present Index Register value of 400. In the operand format, the offset may be represented by a label or a numerical value in the range 0 \sim 255 as in the example. In the earlier example, STAA X, the operand is equivalent to 0, X , that is, the "0" may be omitted when the desired address is equal to X. Table 13 shows the cycle-by-cycle operation for the Indexed Mode of Addressing.

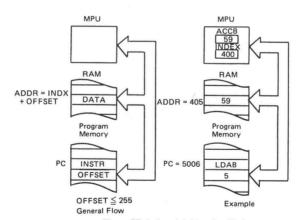


Figure 37 Indexed Addressing Mode

Table 13 Indexed Mode Cycle by Cycle

Address Mode and Instructions	Cycle	Cycle #	VMA Line	Address Bus	R/W Line	Data Bus
JMP	4	1 2 3 4	1 1 0 0	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry)	1 1 1 1	Op Code Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1)
ADC EOR ADD LDA AND QRA BIT SBC CMP SUB	5	1 2 3 4 5	1 1 0 0	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry-) Index Register Plus Offset	1 1 1 1	Op Code Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Operand Data
CPX LDS LDX	6	1 2 3 4 5 6	1 1 0 0 1 1	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry) Index Register Plus Offset Index Register Plus Offset + 1	1 1 1 1 1	Op Code Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Operand Data (High Order Byte) Operand Data (Low Order Byte)
STA	6	1 2 3 4 5 6	1 1 0 0 0	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry) Index Register Plus Offset Index Register Plus Offset	1 1 1 1 1 0	Op Code Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Operand Data
ASL LSR ASR NEG CLR ROL COM ROR DEC TST INC	7	1 2 3 4 5 6 7	1 1 0 0 1 0 1/0 (NOTE 2)	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry) Index Register Plus Offset Index Register Plus Offset Index Register Plus Offset Index Register Plus Offset	1 1 1 1 1 1 0	Op Code Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Current Operand Data Irrelevant Data (NOTE 1) New Operand Data (NOTE 2)
STS STX	7	1 2 3 4 5 6 7	1 1 0 0 0 1 1	Op Code Address Op Code Address + 1 Index Register Index Register Plus Offset (w/o Carry) Index Register Plus Offset Index Register Plus Offset Index Register Plus Offset	1 1 1 1 1 0 0	Op Code Offset Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1) Operand Data (High Order Byte) Operand Data (Low Oder Byte)
JSR 1 1 2 1 3 0 4 1 1 6 0 7 7 0 8 0		Op Code Address Op Code Address + 1 Index Register Stack Pointer Stack Pointer — 1 Stack Pointer — 2 Index Register Index Register Plus Offset (w/o Carry)	1 1 1 0 0 1 1	Op Code Offset Irrelevant Data (NOTE 1) Return Address (Low Order Byte) Return Address (High Order Byte) Irrelevant Data (NOTE 1) Irrelevant Data (NOTE 1)		

NOTE 1. If Device which is addressed during this cycle uses VMA, then the Data Bus will go to the high impedance three-state condition.

Depending on bus capacitance, data from the previous cycle may be retained on the Data Bus.

NOTE 2. For TST, VMA = 0 and Operand data does not change.

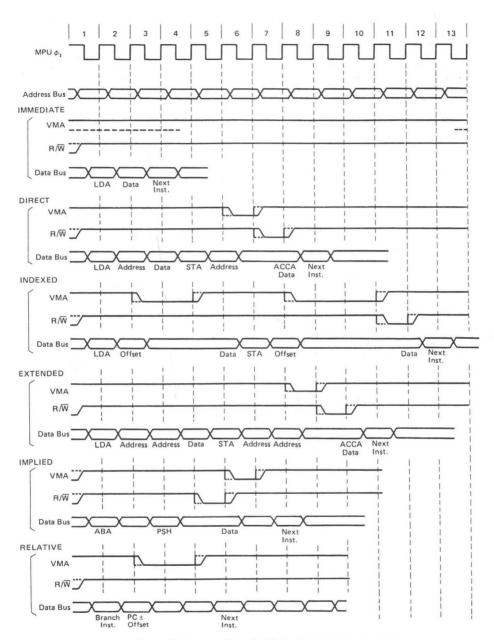


Figure 38 Example of Excution Timing in Each Addressing Mode

■ NOTE FOR THE RELATION BETWEEN WAI INSTRUCTION AND HALT OPERATION OF HD6800

When HALT input signal is asserted to "Low" level, the MPU will be halted after the execution of the current instruction except WAI instruction.

The "Halt" signal is not accepted after the fetch cycle of the WAI instruction (See ① in Fig. 39). In the case of the "WAI" instruction, the MPU enters the "WAIT" cycle after stacking the internal registers and

outputs the "High" level on the BA line.

When an interrupt request signal is input to the MPU, the MPU accepts the interrupt regardless the "Halt" signal and releases the "WAIT" state and outputs the interrupt's vector address. If the "Halt" signal is "Low" level, the MPU halts after the fetch of new PC contents. The sequense is shown below.

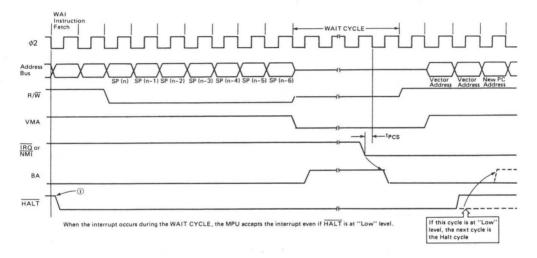


Figure 39 HD6800 WAIT CYCLE & HALT Request

HD6802

MPU (Microprocessor with Clock and RAM)

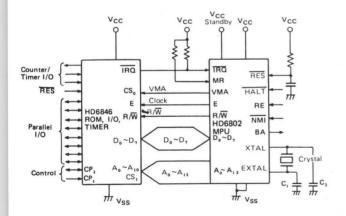
The HD6802 is a monolithic 8-bit microprocessor that contains all the registers and accumulators of the present HD6800 plus an internal clock oscillator and driver on the same chip. In addition, the HD6802 has 128 bytes of RAM on the chip located at hex addresses 0000 to 007F. The first 32 bytes of RAM, at hex addresses 0000 to 001F, may be retained in a low power mode by utilizing $V_{\rm CC}$ standby, thus facilitating memory retention during a power-down situation.

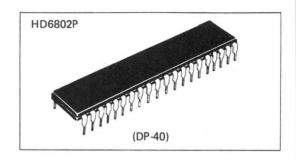
The HD6802 is completely software compatible with the HD6800 as well as the entire HMCS6800 family of parts. Hence, the HD6802 is expandable to 65k words.

FEATURES

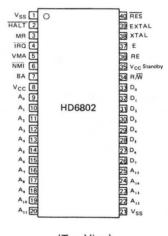
- · On-Chip Clock Circuit
- 128 × 8 Bit On-Chip RAM
- 32 Bytes of RAM are Retainable
- Software-Compatible with the HD6800
- Expandable to 65k words
- Standard TTL-Compatible Inputs and Outputs
- 8 Bit Word Size
- 16 Bit Memory Addressing
- Interrupt Capability
- Compatible with MC6802

BLOCK DIAGRAM





■ PIN ARRANGEMENT



(Top View)

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{CC} * V _{CC} Standby*	-0.3 ~ +7.0	V
Input Voltage	V _{in} *	-0.3 ~ +7.0	V
Operating Temperature	T _{opr}	-20 ~ ·+75	°C
Storage Temperature	T _{stg}	-55 ∼ +150	°C

^{*} With respect to VSS (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol		min	typ	max	Unit
Supply Voltage	V _{CC} * V _{CC} Standby*		4.75	5.0	5.25	V
		V _{IL} *	-0.3	-	0.8	V
Input Voltage	\/ *	Except RES	2.0	-	Vcc	V
	V _{IH} *	RES	4.25	-	Vcc	V
Operation Temperature	Topr		-20	25	75	°C

^{*} With respect to VSS (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (V_{CC}=5.0V±5%, V_{CC} Standby=5.0V±5%, V_{SS}=0V, Ta=-20∼+75°C, unless otherwise noted.)

Item		Symbol	Test Condition	min	typ**	max	Unit
	Except RES	.,		2.0	-	Vcc	V
Input "High" Voltage	RES	V _{IH}		4.25	_	V _{CC}	V
	Except RES ***			-0.3	_	0.8	V
Input "Low" Voltage	RES	VIL		-0.3	-	0.8	V
	D₀~D₁, E		I _{OH} = -205μA	2.4	-	-	V
Output "High" Voltage	$A_0 \sim A_{15}$, R/\overline{W} , VMA	VoH	$I_{OH} = -145 \mu A$	2.4	-	-	
	BA		I _{OH} = -100μA	2.4	_	-	
Output "Low" Voltage		VoL	I _{OL} = 1.6mA	_	-	0.4	V
Three State (Off State) Input Current	$D_0 \sim D_7$	I _{TSI}	V _{in} = 0.4~2.4 V	-10	-	10	μΑ
Input Leakage Current	Except D ₀ ~D ₇ ****	lin	V _{in} = 0∼5.25V	-2.5	_	2.5	μΑ
Power Dissipation		P _D *		_	0.6	1.2	W
	D ₀ ~D ₇	0	V _{in} =0V, T _a =25°C,	_	10	12.5	pF
Input Capacitance	Except D ₀ ~D ₇	Gin	f=1.0MHz	-	6.5	10	pi
Output Capacitance	A ₀ ~A ₁₅ , R/W, BA, VMA, E	Cout	V _{in} =0V, T _a =25°C, f=1.0MHz	-	-	12	pF

In power-down mode, maximum power dissipation is less than 42mW.
 T_a=25° C, V_C=5V
 As RES input has histeresis character, applied voltage up to 2.4V is regarded as "Low" level when it goes up from 0V.

^{****} Does not include EXTAL and XTAL, which are crystal inputs.

• AC CHARACTERISTICS (V_{CC}=5.0V±5%, V_{CC} Standby=5.0V±5%, V_{SS}=0V, Ta=-20~+75°C, unless otherwise noted.)

1. CLOCK TIMING CHARACTERISTICS

Item		Symbol	Test Condition	min	typ	max	Unit
F	Input Clock ÷ 4	f		0.1	-	1.0	MHz
Frequency of Operation	Crystal Frequency	f _{XTAL}		1.0	-	4.0	IVITIZ
Cycle Time		t _{cyc}	Fig. 2, Fig. 3	1.0	-	10	μs
	"High" Level	$PW_{\phi H}$	at 2.4V (Fig. 2, Fig. 3)	450 -			ns
Clock Pulse Width	"Low" Level	$PW_{\phi L}$	at 0.8V (Fig. 2, Fig. 3)		_	4500	
Clock Fall Time		tφ	0.8V ~ 2.4V(Fig.2,Fig.3)	_	_	25	ns

2. READ/WRITE TIMING

Item	Symbol	Test Condition	min	typ*	max	Unit
Address Delay	t _{AD}	Fig. 2, Fig. 3, Fig. 6	-	-	270	ns
Peripheral Read Access Time	t _{acc}	Fig. 2	530	-	-	ns
Data Setup Time (Read)	t _{DSR}	Fig. 2	100	-	-	ns
Input Data Hold Time	t _H	Fig. 2	10	-	-	ns
Output Data Hold Time	t _H	Fig. 3	20	-	-	ns
Address Hold Time (Address, R/W, VMA)	t _{AH}	Fig. 2, Fig. 3	10	-	-	ns
Data Delay Time (Write)	t _{DDW}	Fig. 3	-	-	225	ns
Bus Available Delay	t _{BA}	Fig. 4, Fig. 5, Fig. 7, Fig. 8	-	-	250	ns
Processor Controls Processor Control Setup Time	t _{PCS}	Fig. 4~Fig. 7, Fig. 12	200	_	_	ns
Processor Control Rise and Fall Time (Measured at 0.8V and 2.0V)	t _{PCr} t _{PCf}	Fig. 4~Fig. 7, Fig. 12, Fig. 13, Fig. 16	-	-	100	ns

^{*}Ta = 25°C, V_{CC} = 5V

3. POWER DOWN SEQUENCE TIMING, POWER UP RESET TIMING AND MEMORY READY TIMING

Item	Symbol	Test Condition	min	typ	max	Unit
RAM Enable Reset Time (1)	t _{RE1}	Fig. 13	150	-	_	ns
RAM Enable Reset Time (2)	t _{RE2}	Fig. 13	E-3 cycles	-	-	
Reset Release Time	t _{LRES}	Fig. 12	20*	-	-	ms
RAM Enable Reset Time (3)	t _{RE3}	Fig. 12	0	-	_	ns
Memory Ready Setup Time	t _{SMR}	Fig. 16	300	-	-	ns
Memory Ready Hold Time	t _{HMR}	Fig. 16	0	-	200	ns

^{*}tRES = 20 msec min. for S type, 50 msec min. for R type.

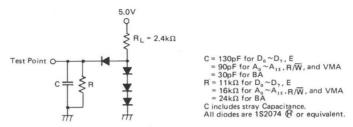


Figure 1 Bus Timing Test Load

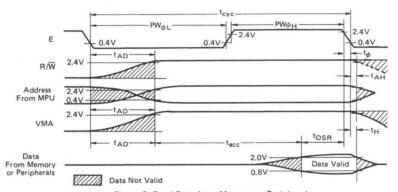


Figure 2 Read Data from Memory or Peripherals

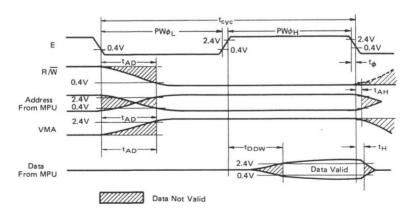


Figure 3 Write Data in Memory or Peripherals

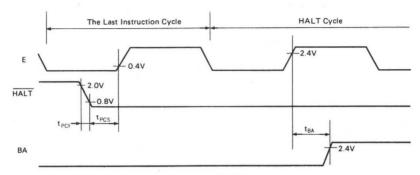


Figure 4 Timing of HALT and BA

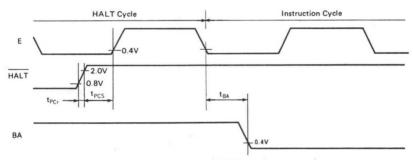


Figure 5 Timing of HALT and BA

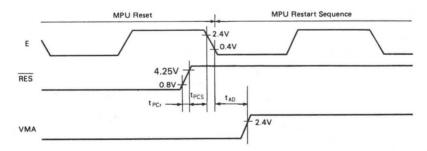


Figure 6 RES and MPU Restart Sequence

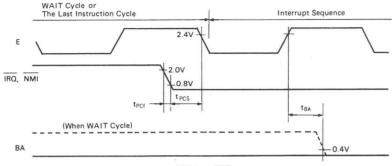


Figure 7 IRQ and NMI Interrupt Timing

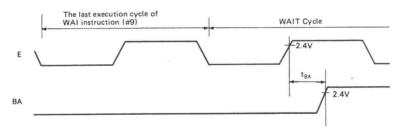


Figure 8 WAI Instruction and BA Timing

■ MPU REGISTERS

A general block diagram of the HD6802 is shown in Fig. 9. As shown, the number and configuration of the registers are the same as for the HD6800. The 128×8 bit RAM has been added to the basic MPU. The first 32 bytes may be operated in a low power mode via a V_{CC} standby. These 32 bytes can be retained during power-up and power-down conditions via the RE signal.

The MPU has three 16-bit registers and three 8-bit registers available for use by the programmer (Fig. 10).

Program Counter (PC)

The program counter is a two byte (16-bit) register that points to the current program address.

Stack Pointer (SP)

The stack pointer is a two byte (16-bit) register that contains the address of the next available location in an external push-down/pop-up stack. This stack is normally a random access Read/Write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be non-volatile.

Index Register (IX)

The index register is a two byte register that is used to store data or a sixteen bit memory address for the Indexed mode of memory addressing.

Accumulators (ACCA, ACCB)

The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit(ALU).

Condition Code Register (CCR)

The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative(N), Zero(Z), Overflow(V), Carry from bit7(C), and half carry from bit3(H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit(I). The used bits of the Condition Code Register (B6 and B7) are ones.

Fig. 11 shows the order of saying the microprocessor status within the stack.



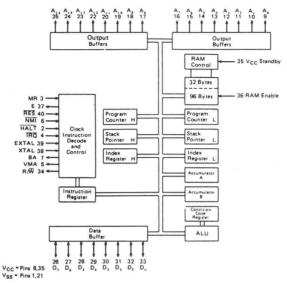


Figure 9 Expanded Block Diagram

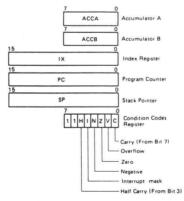


Figure 10 Programming Model of The Microprocessing Unit

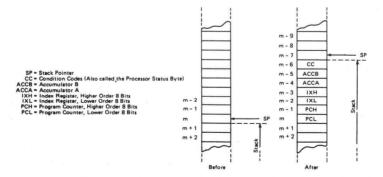


Figure 11 Saving The Status of The Microprocessor in The Stack



■ HD6802 MPU SIGNAL DESCRIPTION

Proper operation of the MPU requires that certain control and timing signals be provided to accomplish specific functions and that other signal lines be monitored to determine the state of the processor. These control and timing signals for the HD6802 are similar to those of the HD6800 except that TSC, DBE, ϕ_1 , ϕ_2 input, and two unused pins have been eliminated, and the following signal and timing lines have been added.

RAM Enable (RE)

Crystal Connections EXTAL and XTAL

Memory Ready(MR)

V_{CC} Standby

Enable ϕ_2 Output(E)

The following is a summary of the HD6802 MPU signals:

Address Bus (A₀ ~ A₁₅)

Sixteen pins are used for the address bus. The outputs are capable of driving one standard TTL load and 90pF.

● Data Bus (D₀ ~ D₇)

Eight pins are used for the data bus. It is bidirectional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130pF.

Data Bus will be in the output mode when the internal RAM is accessed. This prohibits external data entering the MPU. It should be noted that the internal RAM is fully decoded from \$0000 to \$007F. External RAM at \$0000 to \$007F must be disabled when internal RAM is accessed.

· HALT

When this input is in the "Low" state, all activity in the machine will be halted: This input is level sensitive.

In the halt mode, the machine will stop at the end of an instruction. Bus Available will be at a "High" state. Valid Memory Address will be at a "Low" state. The address bus will display the address of the next instruction.

To insure single instruction operation, transition of the HALT line must not occur during the last 250ns of E and the HALT line must go "High" for one Clock cycle.

HALT should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part.

• Read/Write (R/W)

This TTL compatible output signals the peripherals and memory devices whether the MPU is in a Read ("High") or Write ("Low") state. The normal standby state of this signal is Read ("High"). When the processor is halted, it will be in the logical one state ("High").

This output is capable of driving one standard TTL load and 90pF.

Valid Memory Address (VMA)

This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90pF may be directly driven by this active high signal.

Bus Available (BA)

The Bus Available signal will normally be in the "Low" state. When activated, it will go to the "High" state indicating that the microprocessor has stopped and that the address bus is available (but not in a three-state condition). This will occur if the HALT line is in the "Low" state or the processor is in the wait state as a result of the execution of a WAI instruction. At such time, all three-state output drivers will go to their off state and other

outputs to their normally inactive level.

The processor is removed from the wait state by the occurrence of a maskable (mask bit I=0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30pF.

• Interrupt Request (IRQ)

This level sensitive input requests that an interrupt sequence be generated within the machine. The processor will wait, until it completes the current instruction that is being executed before it recognizes the request. At that time, if the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFF8 and FFF9. An address loaded at these locations causes the MPU to branch to an interrupt routine in memory.

The \overline{HALT} line must be in the "High" state for interrupts to be serviced. Interrupts will be latched internally while \overline{HALT} is

"Low"

A $3k\Omega$ external register to V_{CC} should be used for wire-OR and optimum control of interrupts.

Reset (RES)

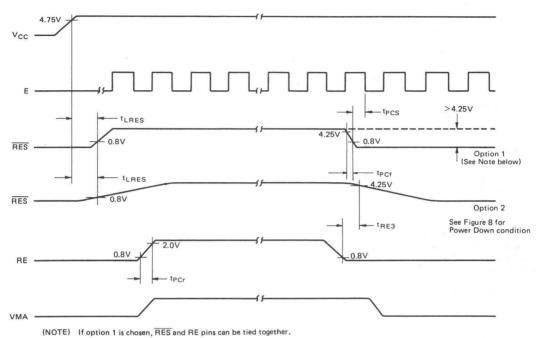
This input is used to reset and start the MPU from a power-down condition, resulting from a power failure or an initial start-up of the processor. When this line is "Low", the MPU is inactive and the information in the registers will be lost. If a "High" level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execution of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced "High". For the restart, the last two(FFFE, FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by \overline{IRQ} . Power-up and reset timing and power-down sequences are shown in Fig. 12 and Fig. 13 respectively.

Non-Maskable Interrupt (NMI)

A low-going edge on this input requests that a non-mask-interrupt sequence be generated within the processor. As with the \overline{IRQ} signal, the processor will complete the current instruction that is being executed before it recognizes the \overline{NMI} signal. The interrupt mask bit in the Condition Code Register has no effect on \overline{NMI} .

The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFFC and FFFD. An address loaded at these locations causes the MPU to branch to a non-maskable interrupt routine in memory. A $3k\Omega$ external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Inputs \overline{IRQ} and \overline{NMI} are hardware interrupt lines that are sampled when E is "High" and will start the interrupt routine on a "Low" E following the completion of an instruction. \overline{IRQ} and \overline{NMI} should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part. Fig. 14 is a flowchart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.



200

Figure 12 Power-up and Reset Timing

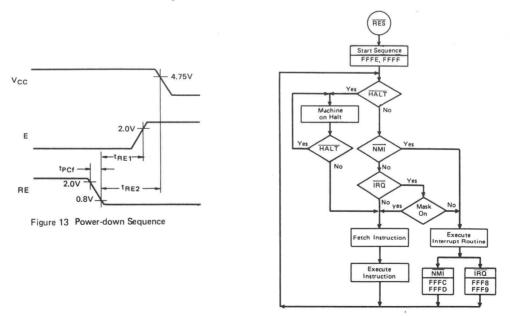


Figure 14 MPU Flow Chart

Table 1 Memory Map for Interrupt Vectors

	Description	tor	Vec
	Description	LS	MS
(RES)	Restart	FFFF	FFFE
(NMI	Non-Maskable Interrupt	FFFD	FFFC
(SWI)	Software Interrupt	FFFB	FFFA
(TRQ)	Interrupt Request	FFF9	FFF8

RAM Enable (RE)

A TTL-compatible RAM enable input controls the on-chip RAM of the HD6802. When placed in the "High" state, the on-chip memory is enabled to respond to the MPU controls. In the "Low" state, RAM is disabled. This pin may also be utilized to disable reading and writing the on-chip RAM during a power-down situation. RAM enable must be "Low" three cycles before V_{CC} goes below $4.75\,\mathrm{V}$ during power-down.

RE should be tied to the correct "High" or "Low" state if not used. This is good engineering design practice in general and necessary to insure proper operation of the part.

EXTAL and XTAL

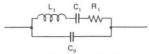
The HD6802 has an internal oscillator that may be crystal controlled. These connections are for a parallel resonant fundamental crystal (AT cut). A divide-by-four circuit has been added to the HD6802 so that a 4MHz crystal may be used in lieu of a 1MHz crystal for a more cost-effective system. Pin39 of the HD6802 may be driven externally by a TTL input signal if a separate clock is required. Pin38 is to be left open in this mode.

An RC network is not directly usable as a frequency source on pins 38 and 39. An RC network type TTL or CMOS oscillator will work well as long as the TTL or CMOS output drives the HD6802.

If an external clock is used, it may not be halted for more than $4.5\mu s$. The HD6802 is a dynamic part except for the internal RAM, and requires the external clock to retain information.

Conditions for Crystal (4 MHz)

- AT Cut Parallel resonant
- $C_0 = 7 \text{ pF max}$.
- $R_1 = 80 \Omega \text{ max}$.



Crystal Equivalent Circuit

Recommended Oscillator (4MHz)

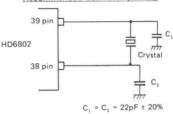


Figure 15 Crystal Oscillator

When using the crystal, see the note for Board Design of the Oscillation Circuit in HD6802.

Memory Ready (MR)

MR is a TTL compatible input control signal which allows stretching of E. When MR is "High", E will be in normal operation. When MR is "Low", E may be stretched integral multiples of half periods, thus allowing interface to slow memories. Memory Ready timing is shown in Fig. 16.

memories, Memory Ready timing is shown in Fig. 16.

MR should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part. A maximum stretch is 4.5 µs.

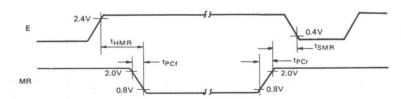


Figure 16 Memory Ready Control Function

• Enable (E)

This pin supplies the clock for the MPU and the rest of the system. This is a single phase, TTL compatible clock. This clock may be conditioned by a Memory Ready Signal. This is equivalent to ϕ_2 on the HD6800.

V_{CC} Standby

This pin supplies the dc voltage to the first 32 bytes of RAM as well as the RAM Enable (RE) control logic. Thus retention of data in this portion of the RAM on a power up, power-down, or standby condition is guaranteed at the range of 4.0 V to 5.25 V.

Maximum current drain at 5.25V is 8mA.

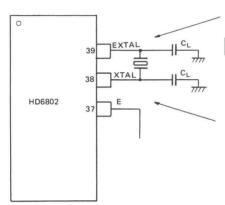
■ MPU INSTRUCTION SET

The HD6802 has a set of 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions.

This instruction set is the same as that for the 6800MPU(HD6800 etc.) and is not explained again in this data sheet.

NOTE FOR BOARD DESIGN OF THE OSCILLATION CIRCUIT IN HD6802

In designing the board, the following notes should be taken when the crystal oscillator is used.

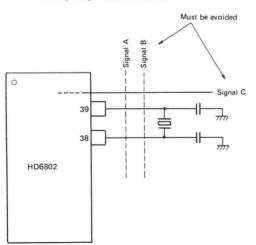


Crystal oscillator and load capacity C_L must be placed near the LSI as much as possible.

Normal oscillation may be disturbed when external noise is induced to pin 38 and 39.

Pin 38 signal line should be wired apart from pin 37 signal line as much as possible. Don't wire them in parallel, or normal oscillation may be disturbed when E signal is feedbacked to XTAL.

The following design must be avoided.



A signal line or a power source line must not cross or go near the oscillation circuit line as shown in the left figure to prevent the induction from these lines and perform the correct oscillation. The resistance among XTAL, EXTAL and other pins should be over $10M\Omega$.

Figure 17 Note for Board Design of the Oscillation Circuit



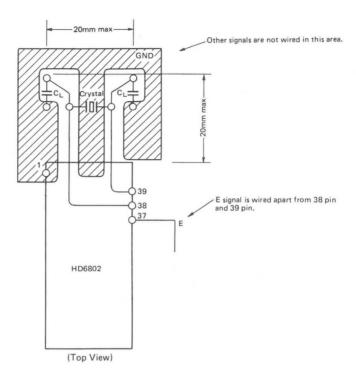


Figure 18 Example of Board Design Using the Crystal Oscillator

■ NOTE FOR THE RELATION BETWEEN WAI INSTRUCTION AND HALT OPERATION OF HD6802

When HALT input signal is asserted to "Low" level, the MPU will be halted after the execution of the current instruction except WAI instruction.

The "Halt" signal is not accepted after the fetch cycle of the WAI instruction (See ① in Fig. 19). In the case of the "WAI" instruction, the MPU enters the "WAIT" cycle after stacking the internal registers and

outputs the "High" level on the BA line.

When an interrupt request signal is input to the MPU, the MPU accepts the interrupt regardless the "Halt" signal and releases the "WAIT" state and outputs the interrupt's vector address. If the "Halt" signal is "Low" level, the MPU halts after the fetch of new PC contents. The sequense is shown below.

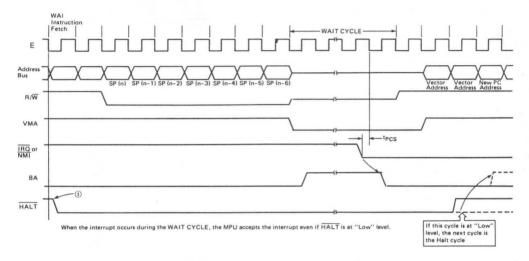


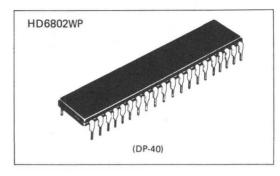
Figure 19 HD6802 WAIT CYCLE & HALT Request

HD6802W MPU (Microprocessor with Clock and RAM)

HD6802W is the enhanced version of HD6802 which contains MPU, clock and 256 bytes RAM. Internal RAM has been extended from 128 to 256 bytes to increase the capacity of system read/write memory for handling temporary data and manipulating the stack.

The internal RAM is located at hex addresses 0000 to 00FF. The first 32 bytes of RAM, at hex addresses 0000 to 001F, may be retained in a low power mode by utilizing $V_{\rm CC}$ standby, thus facilitating memory retention during a power-down situation.

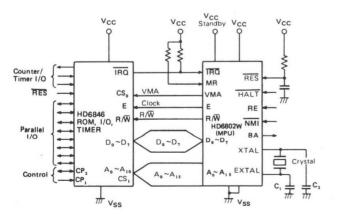
The HD6802W is completely software compatible with the HD6800 as well as the entire HMCS6800 family of parts. Hence, the HD6802W is expandable to 65k words.



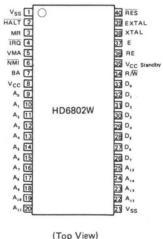
FEATURES

- On-Chip Clock Circuit
- 256 × 8 Bit On-Chip RAM
- 32 Bytes of RAM are Retainable
- Software-Compatible with the HD6800, HD6802
- Expandable to 65k words
- Standard TTL-Compatible Inputs and Outputs
- 8 Bit Word Size
- 16 Bit Memory Addressing
- Interrupt Capability

BLOCK DIAGRAM



PIN ARRANGEMENT



A expanded block diagram of the HD6802W is shown in Fig. 1. As shown, the number and configuration of the registers are

the same as the HD6802 except that the internal RAM has been extended to $256\ bytes$.

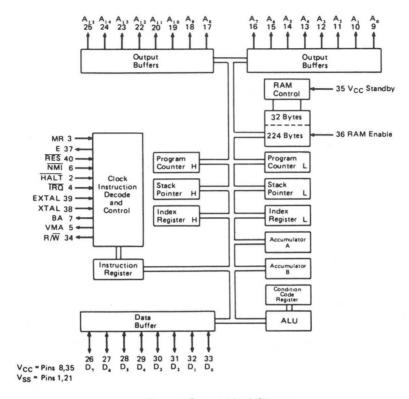


Figure 1 Expanded Block Diagram

Address Map of RAM is shown is Fig. 2.

The HD6802W has 256 bytes of RAM on the chip located at hex addresses 0000 to 00FF. The first 32 bytes of RAM, at hex addresses 0000 to 001F, may be retained in a low power

mode by utilizing V_{CC} standby and setting RAM Enable Signal "Low" level, thus facilitating memory retention during a power-down situation.

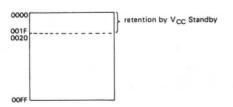


Figure 2 Address Map of HD6802W

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{CC} * V _{CC} Standby*	-0.3 ∼ +7.0	V
Input Voltage	V _{in} *	-0.3 ~ +7.0	V
Operating Temperature	T _{opr}	-20 ~ +75	°C
Storage Temperature	T _{stg}	-55 ∼ +150	°C

^{*} With respect to VSS (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ RECOMMENDED OPERATING CONDITIONS

Item		Symbol	min	typ	max	Unit
Supply Voltage	V _{CC} *		4.75	5.0	5,25	1/
	V _{CC} St	tandby*	4.0	5.0	5,25	v
	\	/ _{IL} *	-0.3	_	8.0	V
Input Voltage	*	Except RES	2.0	-	V _{cc}	
	V _{IH} *	RES	V _{CC} -0.75	-	V _{cc}	V
Operation Temperature	7	opr	-20	25	75	°C

^{*} With respect to VSS (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC}=5.0V±5%, V_{CC} Standby=5.0V±5%, V_{SS}=0V, Ta=-20~+75°C, unless otherwise noted.)

Item		Symbol	Test Condition	min	typ*	max	Unit
	Except RES	.,		2.0	_	V _{CC}	V
Input "High" Voltage	RES	V _{IH}		V _{CC} -0.75	_	V _{cc}	V
	Except RES	xcept RES **		-0.3	0.3 - 0.8		V
Input "Low" Voltage	RES	VIL		-0.3	_	0.8	V
	D₀~D₁, E		$I_{OH} = -205 \mu A$	2.4	-	-	v
Output "High" Voltage	$A_0 \sim A_{15}$, R/W, VMA	VoH	$I_{OH} = -145 \mu A$	2.4	-	_	
	BA		$I_{OH} = -100 \mu A$	2.4	_	-	
Output "Low" Voltage		VoL	I _{OL} = 1.6mA	_	-	0.4	V
Three State (Off State) Input Current	D ₀ ~D ₇	I _{TSI}	V _{in} = 0.4~2.4 V	-10	-	10	μΑ
Input Leakage Current	Except D ₀ ~D ₇	lin ***	V _{in} = 0~5.25V	-2.5	-	2.5	μΑ
Power Dissipation		P _D ****		_	0.7	1.2	W
	D ₀ ~D ₇	0	$V_{in} = 0V, T_a = 25^{\circ}C,$	_	10	12.5	pF
Input Capacitancé	Except D ₀ ~D ₇	- C _{in}	f=1.0MHz	_	6.5	10	þΓ
Output Capacitance	A ₀ ~A ₁₅ , R/₩, BA, VMA	Cout	V _{in} =0V, T _a =25°C, f=1.0MHz	-	-	12	pF

^{*} $T_a=25^{\circ}$ C, V_{CC} =5V
* As RES input has histeresis character, applied voltage up to 2.4V is regarded as "Low" level when it goes up from 0V.

^{***} Does not include EXTAL and XTAL, which are crystal inputs.

^{****} In power-down mode, maximum power dissipation is less than 42mW.

● AC CHARACTERISTICS (V_{CC}=5.0V±5%, V_{CC} Standby=5.0V±5%, V_{SS}=0V, Ta=-20~+75°C, unless otherwise noted.)

1. CLOCK TIMING CHARACTERISTICS

Item		Symbol	Test Condition	min	typ	max	Unit
	Input Clock ÷ 4	f		0.1	-	1.0	MHz
Frequency of Operation	Crystal Frequency	f _{XTAL}		1.0	-	4.0	IVITIZ
Cycle Time		t _{cyc}	Fig. 4, Fig. 5	1.0	_	10	μs
	"High" Level	$PW_{\phi H}$	at 2.4V (Fig. 4, Fig. 5)	450		4500	ns
Clock Pulse Width	"Low" Level	$PW_{\phi L}$	at 0.8V (Fig. 4, Fig. 5)	450 -	_	4500	
Clock Fall Time		tφ	0.8V ~ 2.4V (Fig.4,Fig.5)	-	-	25	ns

2. READ/WRITE TIMING

Item	Symbol	Test Condition	min	typ*	max	Unit
Address Delay	t _{AD}	Fig. 4, Fig. 5, Fig. 8	-	-	270	ns
Peripheral Read Access Time	t _{acc}	Fig. 4	530	_	-	ns
Data Setup Time (Read)	t _{DSR}	Fig. 4	100	-	-	ns
Input Data Hold Time	t _H	Fig. 4	10	_	-	ns
Output Data Hold Time	t _H	Fig. 5	20	-	_	ns
Address Hold Time (Address, R/W, VMA)	t _{AH}	Fig. 4, Fig. 5	10	-	-	ns
Data Delay Time (Write)	t _{DDW}	Fig. 5	-	_	225	ns
Bus Available Delay	t _{BA}	Fig. 6, Fig. 7, Fig. 9, Fig. 10	-	-	250	ns
Processor Controls Processor Control Setup Time	t _{PCS}	Fig. 6 ~ Fig. 9, Fig. 11	200	-	-	ns
Processor Control Rise and Fall Time (Measured at 0.8V and 2.0V)	t _{PCr} ,	Fig. 6 ~ Fig. 9, Fig. 11, Fig. 12, Fig. 14	-	-	100	ns

^{*} Ta = 25°C, V_{CC} = 5V

3. POWER DOWN SEQUENCE TIMING, POWER UP RESET TIMING AND MEMORY READY TIMING

Item	Symbol	Test Condition	min	typ	max	Unit
RAM Enable Reset Time (1)	t _{RE1}	Fig. 12	150	-	_	ns
RAM Enable Reset Time (2)	t _{RE2}	Fig. 12	E-3 cycles	-	-	
Reset Release Time	t _{LRES}	Fig. 11	20	-	_	ms
RAM Enable Reset Time (3)	t _{RE3}	Fig. 11	0	_	_	ns
Memory Ready Setup Time	t _{SMR}	Fig. 14	300	-	_	ns
Memory Ready Hold Time	t _{HMR}	Fig. 14	0	_	200	ns

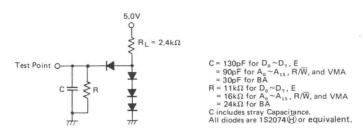


Figure 3 Bus Timing Test Load

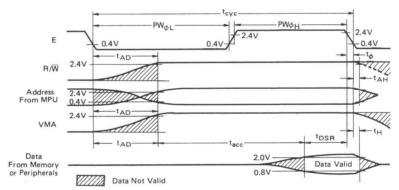


Figure 4 Read Data from Memory or Peripherals

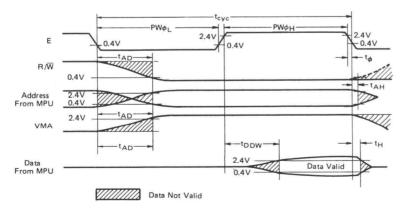


Figure 5 Write Data in Memory or Peripherals



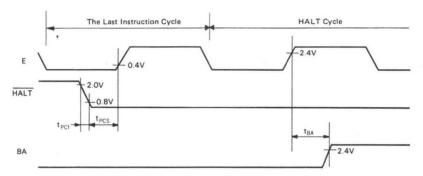


Figure 6 Timing of HALT and BA

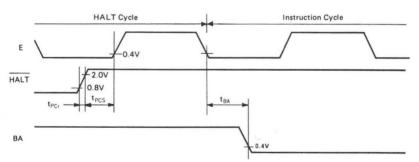


Figure 7 Timing of HALT and BA

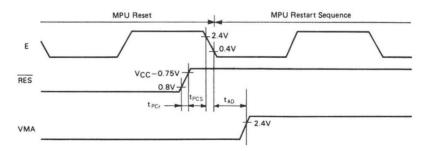


Figure 8 RES and MPU Restart Sequence

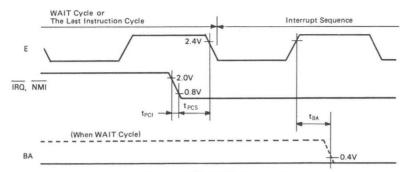


Figure 9 IRQ and NMI Interrupt Timing

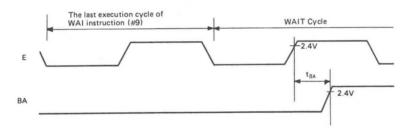


Figure 10 WAI Instruction and BA Timing

■ HD6802W MPU SIGNAL DESCRIPTION

Address Bus (A₀ ~ A₁₅)

Sixteen pins are used for the address bus. The outputs are capable of driving one standard TTL load and 90pF.

Data Bus (D₀ ~ D₇)

Eight pins are used for the data bus. It is bidirectional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130pF.

Data Bus will be in the output mode when the internal RAM is accessed. This prohibits external data entering the MPU. It should be noted that the internal RAM is fully decoded from \$0000 to \$00FF. External RAM at \$0000 to \$00FF must be disabled when internal RAM is accessed.

· HALT

When this input is in the "Low" state, all activity in the machine will be halted: This input is level sensitive.

In the halt mode, the machine will stop at the end of an instruction. Bus Available will be at a "High" state. Valid Memory Address will be at a "Low" state. The address bus will display the address of the next instruction.

 \overline{HALT} line must not occur during the last t_{PCS} of E and the \overline{HALT} line must go "High" for one Clock cycle.

HALT should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part.

Read/Write (R/W)

This TTL compatible output signals the peripherals and memory devices whether the MPU is in a Read ("High") or Write ("Low") state. The normal standby state of this signal is Read ("High"). When the processor is halted, it will be in the logical one state ("High").

This output is capable of driving one standard TTL load and 90pF.

Valid Memory Address (VMA)

This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90pF may be directly driven by this active high signal.

Bus Available (BA)

The Bus Available signal will normally be in the "Low" state. When activated, it will go to the "High" state indicating that the microprocessor has stopped and that the address bus is available (but not in a three-state condition). This will occur if the HALT line is in the "Low" state or the processor is in the wait state as a result of the execution of a WAI instruction. At such time, all three-state output drivers will go to their off state and other outputs to their normally inactive level.

The processor is removed from the wait state by the occurrence of a maskable (mask bit I=0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30pF.

• Interrupt Request (IRQ)

This level sensitive input requests that an interrupt sequence

be generated within the machine. The processor will wait, until it completes the current instruction that is being executed before it recognizes the request. At that time, if the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFF8 and FFF9. An address loaded at these locations causes the MPU to branch to an interrupt routine in memory.

The HALT line must be in the "High" state for interrupts to be serviced. Interrupts will be latched internally while HALT is "Low"

A $3k\Omega$ external register to V_{CC} should be used for wire-OR and optimum control of interrupts.

• Reset (RES)

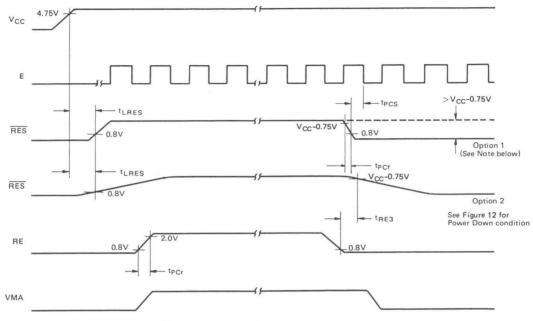
This input is used to reset and start the MPU from a power-down condition, resulting from a power failure or an initial start-up of the processor. When this line is "Low", the MPU is inactive and the information in the registers will be lost. If a "High" level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execution of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced "High". For the restart, the last two(FFFE, FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by \overline{IRQ} . Power-up and reset timing and power-down sequences are shown in Fig. 11 and Fig. 12 respectively.

Non-Maskable Interrupt (NMI)

A low-going edge on this input requests that a non-mask-interrupt sequence be generated within the processor. As with the \overline{IRQ} signal, the processor will complete the current instruction that is being executed before it recognizes the \overline{NMI} signal. The interrupt mask bit in the Condition Code Register has no effect on \overline{NMI} .

The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFFC and FFFD. An address loaded at these locations causes the MPU to branch to a non-maskable interrupt routine in memory. A $3k\Omega$ external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Inputs \overline{IRQ} and \overline{NMI} are hardware interrupt lines that are sampled when E is "High" and will start the interrupt routine on a "Low" E following the completion of an instruction. \overline{IRQ} and \overline{NMI} should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part. Fig. 13 is a flowchart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.



(NOTE) If option 1 is chosen, RES and RE pins can be tied together.

Figure 11 Power-up and Reset Timing

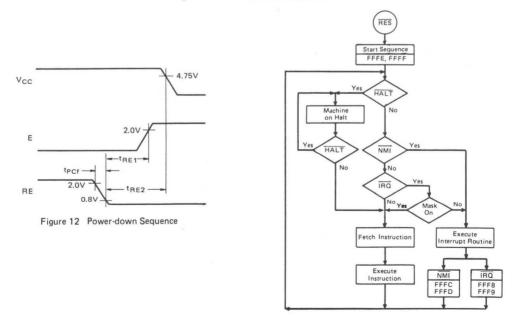


Figure 13 MPU Flow Chart

Table 1 Memory Map for Interrupt Vectors

Ved	ctor		
MS	LS	Description	
FFFE	FFFF	Restart	(RES)
FFFC	FFFD	Non-Maskable Interrupt	(NMI
FFFA	FFFB	Software Interrupt	(SWI)
FFF8	FFF9	Interrupt Request	(IRQ

RAM Enable (RE)

A TTL-compatible RAM enable input controls the on-chip RAM of the HD6802W. When placed in the "High" state, the on-chip memory is enabled to respond to the MPU controls. In the "Low" state, RAM is disabled. This pin may also be utilized to disable reading and writing the on-chip RAM during a power-down situation. RAM enable must be "Low" three cycles before V_{CC} goes below 4.75V during power-down.

RE should be tied to the correct "High" or "Low" state if not used. This is good engineering design practice in general and necessary to insure proper operation of the part.

EXTAL and XTAL

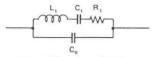
The HD6802W has an internal oscillator that may be crystal controlled. These connections are for a parallel resonant fundamental crystal (AT cut). A divide-by-four circuit has been added to the HD6802W so that a 4MHz crystal may be used in lieu of a 1MHz crystal for a more cost-effective system. Pin39 of the HD6802W may be driven externally by a TTL input signal if a separate clock is required. Pin38 is to be left open in this mode.

An RC network is not directly usable as a frequency source on pins 38 and 39. An RC network type TTL or CMOS oscillator will work well as long as the TTL or CMOS output drives the HD6802W.

If an external clock is used, it may not be halted for more than 4.5 μ s. The HD6802W is a dynamic part except for the internal RAM, and requires the external clock to retain information.

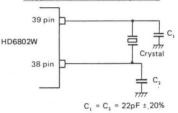
Conditions for Crystal (4 MHz)

- AT Cut Parallel resonant
- $C_0 = 7 pF max$.
- $R_1 = 80\Omega$ max.



Crystal Equivalent Circuit

Recommended Oscillator (4MHz)



When using the crystal, see the note for Board Design of the Oscillation Circuit in HD6802W.

Memory Ready (MR)

MR is a TTL compatible input control signal which allows stretching of E. When MR is "High", E will be in normal operation. When MR is "Low", E may be stretched integral multiples of half periods, thus allowing interface to slow memories. Memory Ready timing is shown in Fig. 14.

memories. Memory Ready timing is shown in Fig. 14.

MR should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part. A maximum stretch is 4.5 µs.

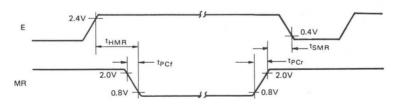


Figure 14 Memory Ready Control Function

Enable (E)

This pin supplies the clock for the MPU and the rest of the system. This is a single phase, TTL compatible clock. This clock may be conditioned by a Memory Ready Signal. This is equivalent to ϕ_2 on the HD6800.

V_{CC} Standby

This pin supplies the dc voltage to the first 32 bytes of RAM as well as the RAM Enable (RE) control logic. Thus retention of data in this portion of the RAM on a power-up, power-down, or standby condition is guaranteed at the range of 4.0 V to 5.25 V.

Maximum current drain at 5.25V is 8mA.

MPU INSTRUCTION SET

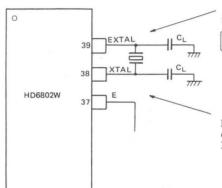
The HD6802W has a set of 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions.

This instruction set is the same as that for the 6800MPU (HD6800 etc.) and is not explained again in this data sheet.

uata silect.

NOTE FOR BOARD DESIGN OF THE OSCILLATION CIRCUIT IN HD6802W

In designing the board, the following notes should be taken when the crystal oscillator is used.

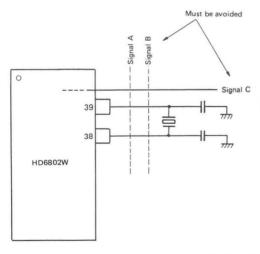


Crystal oscillator and load capacity C_L must be placed near the LSI as much as possible.

Normal oscillation may be disturbed when external noise is induced to pin 38 and 39.

Pin 38 signal line should be wired apart from pin 37 signal line as much as possible. Don't wire them in parallel, or normal oscillation may be disturbed when E signal is feedbacked to XTAL.

The following design must be avoided.



A signal line or a power source line must not cross or go near the oscillation circuit line as shown in the left figure to prevent the induction from these lines and perform the correct oscillation. The resistance among XTAL, EXTAL and other pins should be over $10M\Omega.$

Figure 15 Note for Board Design of the Oscillation Circuit



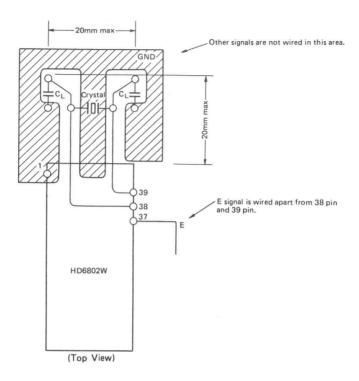


Figure 16 Example of Board Design Using the Crystal Oscillator

■ NOTE FOR THE RELATION BETWEEN WAI INSTRUCTION AND HALT OPERATION OF HD6802W

When HALT input signal is asserted to "Low" level, the MPU will be halted after the execution of the current instruction except WAI instruction.

The "Halt" signal is not accepted after the fetch cycle of the WAI instruction (See ① in Fig. 17). In the case of the "WAI" instruction, the MPU enters the "WAIT" cycle after stacking the internal registers and

outputs the "High" level on the BA line.

When an interrupt request signal is input to the MPU, the MPU accepts the interrupt regardless the "Halt" signal and releases the "WAIT" state and outputs the interrupt's vector address. If the "Halt" signal is "Low" level, the MPU halts after the fetch of new PC contents. The sequense is shown below.

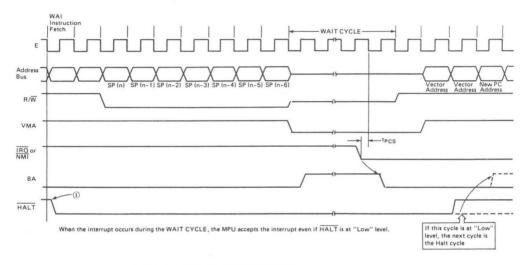


Figure 17 HD6802W WAIT CYCLE & HALT Request

HD6803, HD6803-1

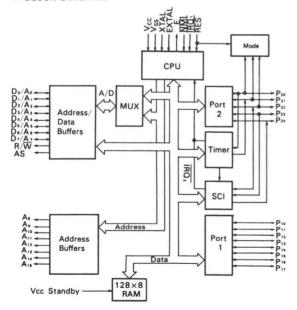
MPU (Micro Processing Unit)

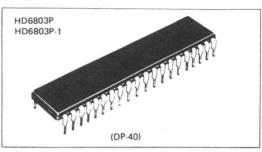
The HD6803 MPU is an 8-bit micro processing unit which is compatible with the HMCS6800 family of parts. The HD6803 MPU is object code compatible with the HD6800 with improved execution times of key instructions plus several new 16-bit and 8-bit instruction including an 8×8 unsigned multiply with 16-bit result. The HD6803 MPU can be expanded to 65k bytes. The HD6803 MPU is TTL compatible and requires one +0.5 volt power supply. The HD6803 MPU has 128 bytes of RAM, Serial Communications Interface (S.C.1.), and parallel I/O as well as a three function 16-bit timer. Features and Block Diagram of the HD6803 include the following:



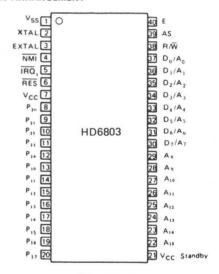
- Expanded HMCS6800 Instruction Set
- 8 x 8 Multiply
- On-Chip Serial Communications Interface (S.C.I.)
- Object Code Compatible with The HD6800 MPU
- 16-Bit Timer
- Expandable to 65k Bytes
- Multiplexed Address and Data
- 128 Bytes of RAM (64 Bytes Retainable On Power Down)
- 13 Parallel I/O Lines
- Internal Clock/Divided-By-Four
- TTL Compatible Inputs and Outputs
- Interrupt Capability
- Compatible with MC6803 and MC6803-1

BLOCK DIAGRAM





PIN ARRANGEMENT



(Top View)

■ TYPE OF PRODUCTS

Type No.	Bus Timing
HD6803	1.0MHz
HD6803-1	1.25MHz

ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc} *	-0.3 ~ +7.0	V
Input Voltage	V _{in} *	-0.3 ~ +7.0	V
Operating Temperature	Topr	0 ~+70	°C
Storage Temperature	T _{stp}	- 55 ∼ +150	°C

With respect to VSS (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC} =5.0V±5%, V_{SS} = 0V, Ta = 0 $^{\sim}$ +70 $^{\circ}$ C, unless otherwise noted.)

Ite	m	Symbol	Test Condition	min	typ	max	Unit
Innua //I link// Malana	RES			4.0	-	V _{cc}	V
Input "High" Voltage	Other Inputs*	VIH		2.0	-	V _{cc}	V
Input "Low" Voltage	All Inputs*	VIL		-0.3	-	8.0	V
Input Load Current	EXTAL	I _{in}	V _{in} = 0 ~ V _{CC}	-	-	0.8	mA
Input Leakage Current	NMI, IRQ ₁ , RES	I _{in}	$V_{in} = 0 \sim 5.25V$	-	-	2.5	μΑ
Three State (Offset)	$P_{10} \sim P_{17}, D_0/A_0 \sim D_7/A_7$	I _{TSI}	V -05 - 0 4V	-	-	10	μΑ
Leakage Current	$P_{20} \sim P_{24}$		$V_{in} = 0.5 \sim 2.4 V$	-	_	100	
	$D_0/A_0 \sim D_7/A_7$	V _{OH}	$I_{LOAD} = -205 \mu\text{A}$	2.4	-	-	v
Output "High" Voltage	A ₈ ~ A ₁₅ , E, R/W, AS		I _{LOAD} = -145 μA	2.4	-	-	
	Other Outputs		I _{LOAD} = -100 μA	2.4	-	-	
Output "Low" Voltage	All Outputs	VoL	I _{LOAD} = 1.6 mA	-	-	0.5	V
Darlington Drive Current	$P_{10} \sim P_{17}$	-l _{oh}	V _{out} = 1.5V	1.0	_	10.0	mA
Power Dissipation		P _D		-	-	1200	mW
Innut Considerate	$D_0/A_0 \sim D_7/A_7$	0	$V_{in} = 0V$, $Ta = 25$ °C,	-	-	12.5	n.E
Input Capacitance	Other Inputs	C _{in}	f = 1.0 MHz	-	-	10.0	pF
V _{CC} Standby	Powerdown	V _{SBB}		4.0	-	5.25	V
	Operating	V _{SB}		4.75	-	5.25	٧
Standby Current	Powerdown	I _{SBB}	V _{SBB} = 4.0V	-	-	8.0	mA

^{*}Except Mode Programming Levels.

[[]NOTE] Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

• AC CHARACTERISTICS BUS TIMING (V_{CC} = 5.0V ± 5%, V_{SS} = 0V, Ta = 0 \sim +70°C, unless otherwise noted.)

	Item	Cumbal	Test Condi-	HD6803			H	1D6803	3-1	Unit
rtem		Symbol	tion	min	typ	max	min	typ	max	Unit
Cycle Time		t _{cyc}		1	_	10	0.8	-	10	μs
Address Strobe Puls	e Width "High" *	PWASH		200	-	-	150	_	_	ns
Address Strobe Rise	Time	t _{ASr}	1 1	5	-	50	5	-	50	ns
Address Strobe Fall	Time	t _{ASf}	1 1	5	-	50	5	_	50	ns
Address Strobe Dela	ay Time *	t _{ASD}	1 1	60	-	-	30	-	-	ns
Enable Rise Time		t _{Er}		5	-	50	5	-	50	ns
Enable Fall Time		t _{Ef}		5	-	50	5	-	50	ns
Enable Pulse Width "High" Time *		PWEH	Fig. 1	450	-	-	340	-	-	ns
Enable Pulse Width "Low" Time *		PWEL		450	-	-	350	-	-	ns
Address Strobe to Enable Delay Time *		tASED		60	-	-	30	-	-	ns
Address Delay Time	1	t _{AD}		-	-	260	-	-	260	ns
Address Delay Time	for Latch *	tADL		-	-	270	-	-	260	ns
Data Set-up Write T	ime	t _{DSW}		225	-	-	115	-	-	ns
Data Set-up Read T	ime	t _{DSR}		80	_	-	70	-	-	ns
Data Hold Time	Read	t _{HR}		10	-	-	10	-	_	
Data Hold Time	Write	t _{HW}	1	20	-	-	20	_	-	ns
Address Set-up Time	e for Latch *	t _{ASL}	1	60	-	-	50	-	-	ns
Address Hold Time for Latch		tAHL	1	20	_	_	20	-	_	ns
Address Hold Time		t _{AH}		20	_	_	20	_	-	ns
Peripheral Read Access Time (Multiplexed Bus)*		(t _{ACCM})		-	-	(600)	-	_	(420)	ns
Oscillator stabilizati	on Time	t _{RC}	Fig. 8	100	_	-	100	_	-	ms
Processor Control S	et-up Time	t _{PCS}	Fig. 7,8	200	_	-	200	-	-	ns

^{*}These timings change in approximate proportion to t_{CYC} . The figures in this characteristics represent those when t_{CYC} is minimum (= in the highest speed operation).

PERIPHERAL PORT TIMING (V_{CC} = 5.0V \pm 5%, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

Item		Symbol	Test Condition	min	typ	max	Unit
Peripheral Data Setup Time	Port 1, 2	t _{PDSU}	Fig. 2	200	_	_	ns
Peripheral Data Hold Time	Port 1, 2	t _{PDH}	Fig. 2	200	-	-	ns
Delay Time, Enable Negative Transition to Peripheral Data Valid		t _{PWD}	Fig. 3	-	-	400	ns

^{*} Except P₂₁

TIMER, SCI TIMING (V_{CC} = 5.0V ±5%, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

Item	Symbol	Test Condition	min	typ	max	Unit
Timer Input Pulse Width	t _{PWT}		2t _{cyc} +200	_	_	ns
Delay Time, Enable Positive Transition to Timer Out	t _{TOD}	Fig. 4	-	-	600	ns
SCI Input Clock Cycle	t _{Scyc}		1	-	-	t _{cyc}
SCI Input Clock Pulse Width	tpwsck		0.4	-	0.6	t _{Scyc}

MODE PROGRAMMING (V_{CC} = 5.0V $\pm 5\%$, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

Item		Symbol	Test Condition	min	typ	max	Unit
Mode Programming Input "Low" Voltage		V _{MPL}		-	-	1.7	V
Mode Programming Input "High" Voltage		V _{MPH}	Fig. 5	4.0	-	-	V
RES "Low" Pulse Width		PWRSTL		3.0	-	-	t _{cyc}
Mode Programming Set-up Time		t _{MPS}		2.0	-	-	t _{cyc}
Mode Programming Hold Time	RES Rise Time ≥ 1μs	t _{MPH}		0	-	-	ns
	RES Rise Time < 1μs			100	-	_	113

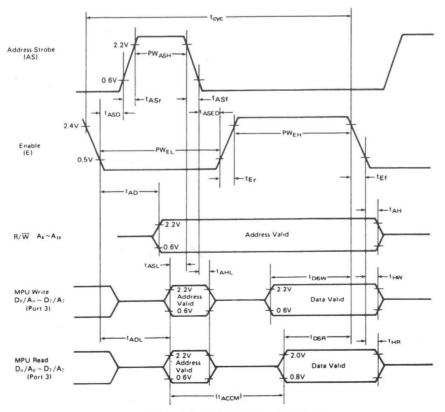


Figure 1 Expanded Multiplexed Bus Timing

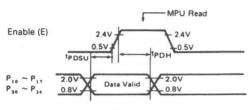


Figure 2 Data Set-up and Hold Times (MPU Read)

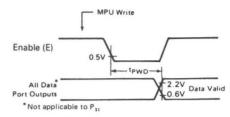


Figure 3 Port Data Delay Timing (MPU Write)

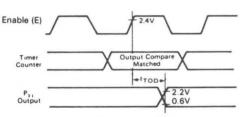


Figure 4 Timer Output Timing

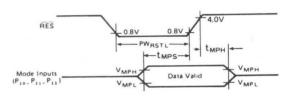
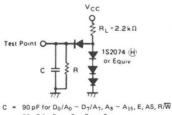


Figure 5 Mode Programming Timing



= 30 pF for $P_{10} \sim P_{17}$, $P_{20} \sim P_{24}$

= 12 k Ω for D $_0/A_0 \sim$ D $_7/A_7$, A $_8 \sim$ A $_{15}$, E, AS, R/W = 24 kΩ for P₁₀ ~ P₁₇, P₂₀ ~ P₂₄

TTL Load

Figure 6 Bus Timing Test Load

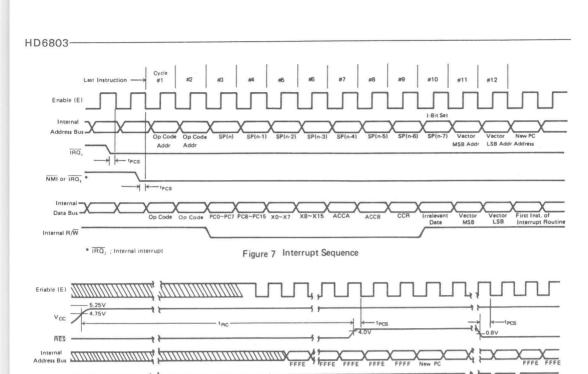


Figure 8 Reset Timing

SIGNAL DESCRIPTIONS

Not Valid

Vcc and Vss

These two pins are used to supply power and ground to the chip. The voltage supplied will be +5 volts ±5%.

XTAL and EXTAL

These connections are for a parallel resonant fundamental crystal, AT cut. Devide-by-4 circuitry is included with the internal clock, so a 4 MHz crystal may be used to run the system at 1 MHz. The devide-by-4 circuitry allows for use of the inexpensive 3.58 MHz Color TV crystal for non-time critical applications. Two 22pF capacitors are needed from the two crystal pins to ground to insure reliable operation. An example of the crystal interface is shown in Fig. 9. EXTAL may be driven by an external TTL compatible source with a 45% to 55% duty cycle. It will devided by 4 any frequency less than or equal to 5 MHz. XTAL must be grounded if an external clock is used.

Nominal Crystal Parameter

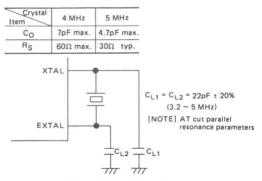


Figure 9 Crystal Interface

V_{CC} Standby

This pin will supply +5 volts $\pm 5\%$ to the standby RAM on the chip. The first 64 bytes of RAM will be maintained in the power down mode with 8 mA current max. The circuit of figure 13 can be utilized to assure that V_{CC} Standby does not go below V_{SBB} during power down.

To retain information in the RAM during power down the

following procedure is necessary:

- Write "0" into the RAM enable bit, RAME. RAME is bit 6 of the RAM Control Register at location \$0014. This disables the standby RAM, thereby protecting it at power down.
- 2) Keep VCC Standby greater than VSBB.

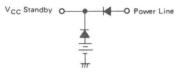


Figure 10 Battery Backup for V_{CC} Standby

Reset (RES)

This input is used to reset and start the MPU from a power down condition, resulting from a power failure or an initial startup of the processor. On power up, the reset must be held "Low" for at least 100 ms. When reset during operation, \overline{RES} must be held "Low" at least 3 clock cycles.

When a "High" level is detected, the CPU does the following;

- 1) All the higher order address lines will be forced "High".
- I/O Port 2 bits, 2, 1, and 0 are latched into programmed control bits PC2, PC1 and PC0.
- The last two (\$FFFE, \$FFFF) locations in memory will be used to load the program addressed by the program counter.
- The interrupt mask bit is set. Clear before the CPU can recognize maskable interrupts.

• Enable (E)

This supplies the external clock for the rest of the system when the internal oscillator is used. It is a single phase, TTL compatible clock, and will be the divide-by-4 result of the crystal oscillator frequency. It will drive one TTL load and 90 pF capacitance.

Non-Maskable Interrupt (NMI)

When the falling edge of the input signal is detected at this pin, the CPU begins non-maskable interrupt sequence internally. As with interrupt Request signal, the processor will complete the current instruction that is being executed before it recognizes the \overline{NMI} signal. The interrupt mask bit in the Condition Code Register has no effect on \overline{NMI} .

In response to an NMI interrupt, the Index Register, Program Counter, Accumulators, and Condition Code Register are stored on the stack. At the end of the sequence, a 16-bit address will be loaded that points to a vectoring address located in memory locations \$FFFC and \$FFFD. An address loaded at these locations causes the CPU to branch to a non-maskable interrupt service routine in memory.

A 3.3 $k\Omega$ external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Inputs \overline{IRQ}_1 and \overline{NMI} are hardware interrupt lines that are sampled during E and will start the interrupt routine on the

E following the completion of an instruction.

• Interrupt Request (IRQ₁)

This level sensitive input requests that an interrupt sequence be generated within the machine. The processor will complete the current instruction before it recognizes the request. At that time, if the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The Index Register, Program Counter, Accumulators, and Condition Code Register are stored on the stack. Next the CPU will respond to the interrupt request by setting the interrupt mask bit "High" so that no further maskable interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations \$FFF8 and \$FFF9. An address loaded at these locations causes the CPU to branch to an interrupt routine in memory.

The $\overline{IRQ_1}$ requires a 3.3 k Ω external resistor to V_{CC} which should be used for wire-OR and optimum control of interrupts. Internal Interrupts will use an internal interrupt line $(\overline{IRQ_2})$. This interrupt will operate the same as $\overline{IRQ_1}$ except that it will use the vector address of \$FFFO through \$FFF7. $\overline{IRQ_1}$ will have priority to $\overline{IRQ_2}$ if both occur at the same time. The Interrupt Mask Bit in the condition code register masks both interrupts (See Table 1).

Table 1 Interrupt Vector Location

Highest Priority

Vector		Interrupt
MSB	LSB	interrupt
FFFE	FFFF	RES
FFFC	FFFD	NMI
FFFA	FFFB	Software Interrupt (SWI)
FFF8	FFF9	ĪRQ ₁
FFF6	FFF7	ICF (Input Capture)
FFF4	FFF5	OCF (Output Compare)
FFF2	FFF3	TOF (Timer Overflow)
FFFO	FFF1	SCI (RDRF + ORFE + TDRE)

Lowest Priority

Read/Write (R/W)

This TTL compatible output signals the peripherals and memory devices whether the CPU is in a Read ("High") or a Write ("Low") state. The normal standby state of this signal is Read ("High"). This output can drive one TTL load and 90pF capacitance.

Address Strobe (AS)

In the expanded multiplexed mode of operation, address strobe is output on this pin. This signal is used to latch the 8 LSB's of address which are multiplexed with data on D_0/A_0 to D_7/A_7 . An 8-bit latch is utilized in conjunction with Address Strobe, as shown in figure 11. So D_0/A_0 to D_7/A_7 can become data bus during the E pulse. The timing for this signal is shown in Figure 1 of Bus Timing. This signal is also used to disable the address from the multiplexed bus allowing a deselect time, tasp before the data is enabled to the bus.

PORTS

There are two I/O ports on the HD6803 MPU; one 8-bit port and one 5-bit port. Each port has an associated write

only Data Direction Register which allows each I/O line to be programmed to act as an input or an output*. A "1" in the corresponding Data Direction Register bit will cause that I/O line to be an output. A "0" in the corresponding Data Direction Register bit will cause that I/O line to be an input. There are two ports: Port 1. Port 2. Their addresses and the addresses of their Data Direction registers are given in Table 2.

The only exception is bit 1 of Port 2, which can either be data input or Timer output.

Table 2 Port and Data Direction Register Addresses

Ports	Port Address	Data Direction Register Address
I/O Port 1	\$0002	\$0000
I/O Port 2	\$0003	\$0001

I/O Port 1

This is an 8-bit port whose individual bits may be defined as inputs or outputs by the corresponding bit in its data direction register. The 8 output buffers have three-state capability. allowing them to enter a high impedance state when the peripheral data lines are used as inputs. In order to be read properly, the voltage on the input lines must be greater than 2.0 V for a logic "1" and less than 0.8 V for a logic "0". As outputs, these lines are TTL compatible and may also be used as a source of up to 1 mA at 1.5 V to directly drive a Darlington base. After reset, the I/O lines are configured as inputs.

This port has five lines that may be defined as inputs or outputs by its data direction register. The 5 output buffers have three-state capability, allowing them to enter a high impedance

GND P OC 74LS373 Data/Address 0

state when used as an input. In order to be read properly, the voltage on the input lines must be greater than 2.0 V for a logic "1" and less than 0.8 V for a logic "0". As outputs, this port has no internal pullup resistors but will drive TTL inputs directly. For driving CMOS inputs, external pullup resistors are required. After reset, the I/O lines are configured as inputs. Three pins on Port 2 (pin 8, 9 and 10 of the chip) are requested to set following values (Table 3) during reset. The values of above three pins during reset are latched into the three MSBs (Bit 5, 6 and 7) of Port 2 which are read only.

Port 2 can be configured as I/O and provides access to the Serial Communications Interface and the Timer. Bit 1 is the only pin restricted to data input or Timer output.

Table 3 The Values of three pins

		-
Pin Number	Value	_
8	L	_
9	Н	_
10	L	

[NOTES] L; Logical "0" H; Logical "1"

B RUS

Data/Address Lines (Do/Ao ~ D7/A7)

Since the data bus is multiplexed with the lower order address bus in Data/Address, latches are required to latch those address bits. The 74LS373 Transparent Octal D-type latch can be used with the HD6803 to latch the least significant address byte. Figure 11 shows how to connect the latch to the HD6803. The output control to the 74LS373 may be connected to ground.

Address Lines (A₈ ~ A₁₅)

Each line is TTL compatible and can drive one TTL load and 90 pF. After reset, these pins become output for upper order address lines (As to A15).

■ INTERRUPT FLOWCHART

The Interrupt flowchart is depicted in Figure 16 and is common to every interrupt excluding reset.

Address: A, ~A,

Function Table

Output	Enable		Output
Control	G	D	Q
L	н	н	Н
L	н	L	L
L	L	×	Q,
н	×	×	Z

Data: Do~D,

Figure 11 Latch Connection

■ MEMORY MAP

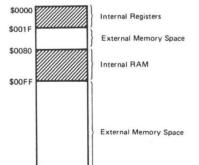
The MPU can provide up to 65k byte address space. A memory map is shown in Figure 12. The first 32 locations are reserved for the MPU's internal register area, as shown in Table 4 with exceptions as indicated.

Table 4 Internal Register Area

Register	Address
Port 1 Data Direction Register**	00
Port 2 Data Direction Register**	01
Port 1 Data Register	02
Port 2 Data Register	03
Not Used	04*
Not Used	05*
Not Used	06*
Not Used	07*
Timer Control and Status Register	08
Counter (High Byte)	09
Counter (Low Byte)	OA
Output Compare Register (High Byte)	ОВ
Output Compare Register (Low Byte)	ОС
Input Capture Register (High Byte)	0D
Input Capture Register (Low Byte)	OE
Not Used	OF*
Rate and Mode Control Register	10
Transmit/Receive Control and Status Register	11
Receive Data Register	12
Transmit Data Register	13
RAM Control Register	14
Reserved	15-1F

- External Address
- ** 1; Output, 0; Input

Multiplexed/RAM



[NOTE]

\$FFF0

\$FFFF

Excludes the following addresses which may be used externally: \$04, \$05, \$06, \$07, and \$0F.

External Interrupt Vectors

Figure 12 HD6803 Memory Map

■ PROGRAMMABLE TIMER

The HD6803 contains an on-chip 16-bit programmable timer which may be used to measure an input waveform while independently generating an output waveform. Pulse widths for both input and output signals may vary from a few microseconds to many seconds. The timer hardware consists of

- · an 8-bit control and status register,
- · a 16-bit free running counter,
- · a 16-bit output compare register,
- · a 16-bit input capture register

A block diagram of the timer registers is shown in Figure 13.

Free Running Counter (\$0009:\$000A)

The key element in the programmable timer is a 16-bit free running counter which is driven to increasing values by E (Enable). The counter value may be read by the CPU software at any time. The counter is cleared to zero by reset and may be considered a read-only register with one exception. Any CPU write to the counter's address (\$09) will always result in preset value of \$FFF8 being loaded into the counter regardless of the value involved in the write. This preset figure is intended for testing operation of the part, but may be of value in some applications.

Output Compare Register (\$000B:\$000C)

The Output Compare Register is a 16-bit read/write register which is used to control an output waveform. The contents of this register are constantly compared with the current value of the free running counter. When a match is found, a flag is set (OCF) in the Timer Control and Status Register (TCSR) and the current value of the Output Level bit (OLVL) in the TCSR is clocked to the Output Level Register. Providing the Data Direction Register for Port 2, Bit 1 contains a "1" (Output), the output level register value will appear on the pin for Port 2 Bit 1. The values in the Output Compare Register and Output Level bit may then be changed to control the output level on the next compare value. The Output Compare Register is set to \$FFFF during reset. The Compare function is inhibited for one cycle following a write to the high byte of the Output Compare Register to insure a valid 16-bit value is in the register before a compare is made.

• Input Capture Register (\$000D:\$000E)

The Input Capture Register is a 16-bit read-only register used to store the current value of the free running counter when the proper transition of an external input signal occurs. The input transition change required to trigger the counter transfer is controlled by the input Edge bit (IEDG) in the TCSR. The Data Direction Register bit for Port 2 Bit 0, should* be clear (zero) in order to gate in the external input signal to the edge detect unit in the timer.

The input pulse width must be at least two E-cycles to ensure an input capture under all conditions.

With Port 2 Bit 0 configured as an output and set to "1", the external input will still be seen by the edge detect unit.

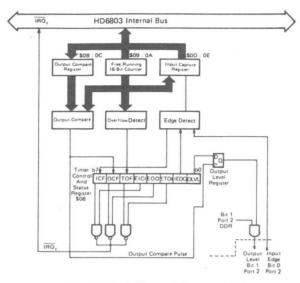


Figure 13 Block Diagram of Programmable Timer

Timer Control and Status Register

7	6	5	4	3	2	1	0	
ICF	OCF	TOF	EICI	EOCI	ETOI	IEDG	OLVL	\$0008

• Timer Control and Status Register (TCSR) (\$0008)

The Timer Control and Status Register consists of an 8-bit register of which all 8 bits are readable but only the low order 5 bits may be written. The upper three bits contain read-only timer status information and indicate the followings:

 a proper transition has taken place on the input pin with a subsequent transfer of the current counter value to the input capture register.

 a match has been found between the value in the free running counter and the output compare register, and when \$0000 is in the free running counter.

Each of the flags may be enabled onto the HD6803 internal bus $(\overline{IRQ_2})$ with an individual Enable bit in the TCSR. If the I-bit in the HD6803 Condition Code register has been cleared, a prior vectored interrupt will occur corresponding to the flag bit(s) set. A description for each bit follows:

Bit 0 OLVL Output Level - This value is clocked to the output level register on a successful output compare. If the DDR for Port 2 bit 1 is set, the value will appear on the output pin.

Bit 1 IEDG Input Edge — This bit controls which transition of an input will trigger a transfer of the counter to the input capture register. The DDR for Port 2 Bit 0 must be clear for this function to operate. IEDG = 0 Transfer takes place on a negative edge ("High"-to-"Low" transition).

IEDG = 1 Transfer takes place on a positive edge

("Low"-to-"High" transition).

Bit 2 ETOI Enable Timer Overflow Interrupt — When set, this bit enables $\overline{IRQ_2}$ to occur on the internal bus for a TOF interrupt; when clear the interrupt is inhibited.

Bit 3 EOCI Enable Output Compare Interrupt – When set, this bit enables $\overline{IRQ_2}$ to appear on the internal bus for an output compare interrupt; when clear the interrupt is inhibited.

Bit 4 EICI Enable input Capture Interrupt – When set, this bit enables $\overline{IRQ_2}$ to occur on the internal bus for an input capture interrupt; when clear the interrupt is inhibited.

Bit 5 TOF Timer Overflow Flag — This read-only bit is set when the counter contains \$FFFF.It is cleared by a read of the TCSR (with TOF set) followed by an CPU read of the Counter (\$09).

Bit 6 OCF Output Compare Flag — This read-only bit is set when a match is found between the output compare register and the free running counter. It is cleared by a read of the TCSR (with OCF set) followed by an CPU write to the output compare register (SOB or SOC).

Bit 7 ICF Input Capture Flag - This read-only status bit is set by a proper transition on the input; it is cleared by a read of the TCSR (with ICF set) followed by an CPU read of the Input Capture Register (\$0D).

SERIAL COMMUNICATIONS INTERFACE

The HD6803 contains a full-duplex asynchronous serial communications interface (SCI) on chip. The controller comprises a transmitter and a receiver which operate independently or each other but in the same data format and at the same data rate. Both transmitter and receiver communicate with the CPU via the data bus and with the outside world via pins 2, 3, and 4 of Port 2. The hardware, software, and registers are explained in the following paragraphs.

Wake-Up Feature

In a typical multi-processor application, the software protocol will usually contain a destination address in the initial byte(s) of the message. In order to permit non-selected MPU's to ignore the remainder of the message, a wake-up feature is included whereby all further interrupt processing may be optionally inhibited until the beginning of the next message. When the next message appears, the hardware re-enables (or "wakes-up") for the next message. The "wake-up" is automatically triggered by a string of ten consecutive 1's which indicates an idle transmit line. The software protocol must provide for the short idle period between any two consecutive messages.

Programmable Options

The following features of the HD6803 serial I/O section are programmable:

- · format standard mark/space (NRZ)
- · Clock external or internal
- baud rate one of 4 per given CPU φ₂ clock frequency or external clock ×8 input
- · wake-up feature enabled or disabled
- Interrupt requests enabled or masked individually for transmitter and receiver data registers
- clock output internal clock enabled or disabled to Port 2 (Bit 2)
- Port 2 (bits 3 and 4) dedicated or not dedicated to serial I/O individually for transmitter and receiver.

Serial Communications Hardware

The serial communications hardware is controlled by 4 registers as shown in Figure 14. The registers include:

- · an 8-bit control and status register
- · a 4-bit rate and mode control register (write only)
- · an 8-bit read only receive data register and
- · an 8-bit write only transmit data register.

In addition to the four registers, the serial I/O section utilizes bit 3 (serial input) and bit 4 (serial output) of Port 2. Bit 2 of Port 2 is utilized if the internal-clock-out or external-clock-in options are selected.

Transmit/Receive Control and Status (TRCS) Register

The TRCS register consists of an 8-bit register of which all 8 bits may be read while only bits 0~4 may be written. The register is initialized to \$20 by reset. The bits in the TRCS register are defined as follows:

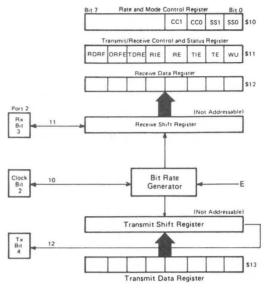


Figure 14 Serial I/O Registers

- Bit 0 WU "Wake-up" on Next Message set by HD6803 software and cleared by hardware on receipt of ten consecutive 1's or reset of RE flag. It should be noted that RE flag should be set in advance of CPU set of WU flag.
- Bit 1 TE

 Transmit Enable set by HD6803 to produce preamble of nine consecutive 1's and to enable gating of transmitter output to Port 2, bit 4 regardless of the DDR value corresponding to this bit; when clear, serial I/O has no effect on Port 2

TE set should be after at least one bit time of data transmit rate from the set-up of transmit data rate and mode.

- Bit 2 TIE $\frac{1}{RQ_2}$ Interrupt Enable when set, will permit an $\frac{1}{RQ_2}$ interrupt to occur when bit 5 (TDRE) is set; when clear, the TDRE value is masked from the bus.
- Bit 3 RE Receiver Enable when set, gates Port 2 bit 3 to input of receiver regardless of DDR value for this bit; when clear, serial I/O has no effect on Port 2 bit 3.
- Bit 4 RIE Receiver Interrupt Enable when set, will permit an IRQ2 interrupt to occur when bit 7 (RDRF) or bit 6 (ORFE) is set; when clear, the interrupt is masked.

Transmit/Receive Control and Status Register



Bit 5 TDRE Transmit Data Register Empty – set by hardware when a transfer is made from the transmit data register to the output shift register. The TDRE bit is cleared by reading the status register, then

writing a new byte into the transmit data register, TDRE is initialized to 1 by reset.

Bit 6 ORFE Over-Run-Framing Error – set by hardware when an overrun or framing error occurs (receive only).

Rate and Mode Control Register

7	6	5	4	3	2	1	0
х	×	X	Х	CC1	CCO	SS1	SSO

ADDR: \$0010

An overrun is defined as a new byte received with last byte still in Data Register/Buffer. A framing error has occured when the byte boundaries in bit stream are not synchronized to bit counter. If WU-flag is set, the ORFE bit will not be set. The ORFE bit is cleard by reading the status register, then reading the Receive Data Register, or by reset.

Bit 7 RDRF Receiver Data Register Full-set by hardware when a transfer from the input shift register to the receiver data register is made. If WU-flag is set, the RDRF bit will not be set. The RDRF bit is cleared by reading the status register, then reading the Receive Data Register, or by reset.

Rate and Mode Control Register (RMCR)

The Rate and Mode Control register controls the following serial I/O variables:

· Baud rate

- · format
- · clocking source,
- · Port 2 bit 2 configuration

The register consists of 4 bits all of which are write-only and cleared by reset. The 4 bits in the register may be considered as a pair of 2-bit fields. The two low order bits control the bit rate for internal clocking and the remaining two bits control the format and clock select logic. The register definition is as follows:

Bit 0 SS0 Speed Select — These bits select the Baud rate for Bit 1 SS1 the internal clock. The four rates which may be selected are a function of the CPU \$\phi_2\$ clock frequency. Table 5 lists the available Baud rates.

Bit 2 CC0 Clock Control and Format Select – this 2-bit field
Bit 3 CC1 controls the format and clock select logic. Table 6
defines the bit field.

Table 5 SCI Bit Times and Rates

	XTAL	2.4576 MHz	4.0 MHz	4.9152 MHz*
SS1: SS0	E	614.4 kHz	1.0 MHz	1.2288 MHz
0 0	E ÷ 16	26 μs/38,400 Baud	16 μs/62,500 Baud	13.0 μs/76,800 Baud
0 1	E ÷ 128	208 μs/4,800 Baud	128 μs/7812.5 Baud	104.2 μs/9,600 Baud
1 0	E ÷ 1024	1.67 ms/600 Baud	1.024 ms/976.6 Baud	833.3 μs/1,200 Baud
1 1	E ÷ 4096	6.67 ms/150 Baud	4.096 ms/244.1 Baud	3.33 ms/300 Baud

^{*} HD6803-1 Only

Table 6 SCI Format and Clock Source Control

CC1: CC0	Format	Clock Source	Port 2 Bit 2	Port 2 Bit 3	Port 2 Bit 4
0 0	_	_	-	_	-
0 1	NRZ	Internal	Not Used	**	**
1 0	NRZ	Internal	Output*	**	**
1 1	NRZ	External	Input	**	**

* Clock output is available regardless of values for bits RE and TE.

** Bit 3 is used for serial input if RE = "1" in TRCS; bit 4 is used for serial output if TE = "1" in TRCS.

Internally Generated Clock

If the user wishes for the serial I/O to furnish a clock, the following requirements are applicable:

- · the values of RE and TE are immaterial.
- CC1. CC0 must be set to 10
- the maximum clock rate will be E ÷ 16.
- the clock will be at 1x the bit rate and will have a rising edge at mid-bit.

Externally Generated Clock

If the user wishes to provide an external clock for the serial I/O, the following requirements are applicable:

- the CC1, CC0, field in the Rate and Mode Control Register must be set to 11,
- the external clock must be set to 8 times (×8) the desired baud rate and
- the maximum external clock frequency is 1.0 MHz.

Serial Operations

The serial I/O hardware should be initialized by the HD6803 software prior to operation. This sequence will normally consist of;

- writing the desired operation control bits to the Rate and Mode Control Register and
- writing the desired operational control bits in the Transmit/ Receive Control and Status Register.

The Transmitter Enable (TE) and Receiver Enable (RE) bits may be left set for dedicated operations.

Transmit Operations

The transmit operation is enabled by the TE bit in the Transmit/Receive Control and Status Register. This bit when set, gates the output of the serial transmit shift register to Port 2 Bit 4 and takes unconditional control over the Data Direction Register value for Port 2. Bit 4.

Following a RES the user should configure both the Rate and Mode Control Register and the Transmit/Receive Control and Status Register for desired operation. Setting the TE bit during this procedure initiates the serial output by first transmitting a nine-bit preamble of 1's. Following the preamble, internal synchronization is established and the transmitter section is ready for operation.

At this point one of two situation exist:

- if the Transmit Data Register is empty (TDRE = 1), a continuous string of ones will be sent indicating an idle line, or.
- if data has been loaded into the Transmit Data Register (TDRE = 0), the word is transferred to the output shift register and transmission of the data word will begin.

During the data transmit, the 0 start bit is first transmitted. Then the 8 data bits (beginning with bit 0) followed by the stop bit, are transmitted. When the Transmitter Data Register has been emptied, the hardware sets the TDRE flag bit.

If the HD6803 fails to respond to the flag within the proper time, (TDRE is still set when the next normal transfer from the parallel data register to the serial output register should occur) then a 1 will be sent (instead of a 0) at "Start" bit time, followed by more 1's until more data is supplied to the data register. No 0's will be sent while TDRE remains a 1.

Receive Operation

The receive operation is enabled by the RE bit which gates in the serial input through Port 2, Bit 3. The receiver section operation is conditioned by the contents of the Transmit/Receive Control and Status Register and the Rate and Mode Control Register.

The receiver bit interval is divided into 8 sub-intervals for internal synchronization. In the NRZ Mode, the received bit stream is synchronized by the first 0 (space) encountered.

The approximate center of each bit time is strobed during the next 10 bits. If the tenth bit is not a 1 (stop bit) a framing error is assumed, and bit ORFE is set. If the tenth bit as a 1, the data is transferred to the Receive Data Register, and interrupt flag RDRF is set. If RDRF is still set at the next tenth bit time. ORFE will be set, indicating an overrun has occurred. When the HD6803 responds to either flag (RDRF or ORFE) by reading the status register followed by reading the Data Register, RDRF (or ORFE) will be cleared.

RAM CONTROL REGISTER

This register, which is addressed at \$0014, gives status information about the standby RAM. A 0 in the RAM enable bit (RAME) will disable the standby RAM, thereby protecting

it at power down if V_{CC} Standby is held greater than V_{SBB} volts, as explained previously in the signal description for V_{CC} Standby.

	11	RA	M Co	ntrol Re	gister			
\$0014	STBY PWR	RAME	×	×	×	х	×	×

Bit 0 Not used.

Bit 1 Not used.

Bit 2 Not used.

Bit 3 Not used. Bit 4 Not used.

Bit 5 Not used.

Bit 6 RAME The RAM Enable control bit allows the user the ability to disable the standby RAM. This bit is set to a logic "1" by RES which enables the standby RAM and can be written to one or zero under program control. When the RAM is disabled, data is read from external memory.

Bit 7 STBY The S PWR by vol

The Standby Power bit is cleared when the standby voltage is removed. This bit is a read/write status flag that the user can read which indicates that the standby RAM voltage has been applied, and the data in the standby RAM is valid.

■ GENERAL DESCRIPTION OF INSTRUCTION SET

The HD6803 is upward object code compatible with the HD6800 as it implements the full HMCS6800 instruction set. The execution times of key instructions have been reduced to increase throughout. In addition, new instructions have been added; these include 16-bit operations and a hardware multiply.

Included in the instruction set section are the following:

- · CPU Programming Model-Figure 15.
- · Addressing modes
- · Accumulator and memory instructions Table 7
- · New instructions
- Index register and stack manipulations instructions Table
- · Jump and branch instructions Table 9
- Condition code register manipulation instructions Table 10
- Instructions Execution times in machine cycles Table
- · Summary of cycle by cycle operation Table 12
- · Summary of undefined instructions Table 13

CPU Programming Model

The programming model for the HD6803 is shown in Figure 15. The double (D) accumulator is physically the same as the Accumulator A concatenated with the Accumulator B so that any operation using accumulator D will destroy information in A and B.

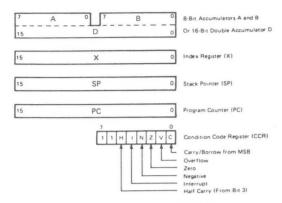


Figure 15 CPU Programming Model

CPU Addressing Modes

The HD6803 8-bit micro processing unit has seven address modes that can be used by a programmer, with the addressing mode a function of both the type of instruction and the coding within the instruction. A summary of the addressing modes for a particular instruction can be found in Table 11 along with the associated instruction execution time that is given in machine cycles. With a clock frequency of 4 MHz, these times would be microseconds.

Accumulator (ACCX) Addressing

In accumulator only addressing, either accumulator A or accumulator B is specified. These are one-byte instructions.

Immediate Addressing

In immediate addressing, the operand is contained in the second byte of the instruction except LDS and LDX which have the operand in the second and third bytes of the instruction. The CPU addresses this location when it fetches the immediate instruction for execution. These are two or three-byte instructions.

Table 7 Accumulator & Memory Instructions

							Add	dressi	ing l	Mod	les							0	Conc		on (le
Operations	Mnemonic	IMI	ME	D.	DIF	REC	T	IN	DE	×	EX	TEN	ID	IME	LIE	D	Boolean/ Arithmetic Operation	5	4		2	1	To
		ОР	~	#	ОР	~	#	ОР	~	#	ОР	~	#	ОР	~	#	Arithmetic Operation	н	1	N	z	v	0
Add	ADDA	8B	2	2	9В	3	2	AB	4	2	вв	4	3				$A + M \rightarrow A$	1		1	1	1	1
	ADDB	СВ	2	2	DB	3	2	EB	4	2	FB	4	3				B + M → B	1		1	1	1	1
Add Double	ADDD	C3	4	3	D3	5	2	E3	6	2	F3	6	3				A:B+M:M+1A:B			1	1	1	t
Add Accumulators	ABA													1B	2	1	A + B → A	1		1	1	1	t
Add With Carry	ADCA	89	2	2	99	3	2	A9	4	2	В9	4	3				A + M + C → A	1		1	1	1	t
	ADCB	C9	2	2	D9	3	2	E9	4	2	F9	4	3				B + M + C → B	1		1	1	1	t
AND	ANDA	84	2	2	94	3	2	A4	4	2	В4	4	3				A·M → A			1	1	R	t,
	ANDB	C4	2	2	D4	3	2	E4	4	2	F4	4	3				B·M → B			1	1	R	+
Bit Test	BITA	85	2	2	95	3	2	A5	4	2	B5	4	3				A·M			1	1	R	+
	BIT B	C5	2	2	D5	3	2	E5	4	2	F5	4	3				В∙М			1	1	R	+
Clear	CLR	1	-	-	-	-	-	6F	6	2	7F	6	3				00 → M			R	S	R	1
	CLRA	1				-								4F	2	1	00 → A			R	S	R	F
	CLRB	1												5F	2	1	00 → B			R	S	R	1
Compare	CMPA	81	2	2	91	3	2	A1	4	2	В1	4	3		-	2 1 00 → A				1	1	1	t
	СМРВ	C1	2	2	D1	3	2	E1	4	2	F1	4	3							1	1-	1	t
Compare Accumulators	CBA		Ī	-			-							11	2	1	A - B	•	•	1	1	1	t
Complement, 1's	COM							63	6	2	73	6	3				M → M			1	1	R	1
	COMA	\vdash	\vdash				+	-	-	-	-	-	-	43	2	1	$\overline{A} \to A$			1	1	R	+
	COMB				-		1							53	2	1	B → B			1	1	R	1
Complement, 2's	NEG	+-	-	-	-	-	+	60	6	2	70	6	3	-	-	i -	00 - M → M			1	-	1	1
(Negate)	NEGA		+	\vdash	-		+	-	-	-	-	1	-	40	2	1	00 - A → A			1	-	0	+
(ivegute)	NEGB		1				1					+		50	2	1	00 - B → B			1	1	0	-
Decimal Adjust, A	DAA													19	2	1	Converts binary add of BCD characters into BCD format			1	1	1	6
Decrement	DEC							6A	6	2	7A	6	3				M − 1 → M			1	1	4	t
	DECA													4A	2	1	A - 1 → A			1	1	4	1
	DECB													5A	2	1	B - 1 - B			1	1	4	+
Exclusive OR	EORA	88	2	2	98	3	2	A8	4	2	88	4	3				A ⊕ M → A		•	1	1	R	t
	EORB	C8	2	2	D8	3	2	E8	4	2	F8	4	3				B ⊕ M→ B			1	1	R	t
Increment	INC		1					6C	6	2	7C	6	3			\vdash	M + 1 → M			1	1	(3)	t
	INCA		+				+							4C	2	1	A + 1 - A			1	1	3	-
	INCB	1	+	-	-		+	-		-	-	-	-	5C	2	1	B + 1 · · B			1	1	(3)	_
Load	LDAA	86	2	2	96	3	2	A6	4	2	В6	4	3	50	-	+	M A			1	1	R	+
Accumulator	LDAB	C6	2	2	D6	3	2	E6	4	2	F6	4	3			\vdash	M → B			1	1	R	t
Load Double Accumulator	LDD	СС	3	3	DC	4	2	EC	5	2	FC	5	3				M + 1 → B, M → A			1	1	R	1
Multiply Unsigned	MUL													3D	10	1	A×B · A : B	•	•	•	•	•	1
OR, Inclusive	ORAA	8A	2	2	9A	3	2	AA	4	2	ВА	4	3				A + M → A		•	1	:	R	t
	ORAB	CA	2	2	DA	3	2	EA	4	2	FA	4	3			\vdash	B + M → B			:	1	R	t
Push Data	PSHA	1	1	-		-	+		-		-	-		36	3	1	A → Msp, SP – 1 · SP		•	•	•		t
	PSHB		1	1			1							37	3	1	B → Msp, SP – 1 · SP				•		t
Pull Data	PULA		+	1			1					-		32	4	1	SP + 1 → SP, Msp → A				•		t
	PULB	1	1	-	1		+					1		33	4	1	SP + 1 → SP, Msp → B						t
Rotate Left	ROL	1	+	-	_	-	+	69	6	2	79	6	3	-	-	Ė	5			1	1	6	4
notate Leit	ROLA	+-	-	-	+	-	-	03	-	2	13	-	3	49	2	1	M) [:	1	6	_
	ROLB	+	+	-	+	-	+	-	-	-	-	+	-	59	2	1	A C b7 b0	•		1	1	6	_
Rotate Right	ROR	+	+	-	+	-	+	66	6	2	76	6	3	33	-	+	M			1	1	6	4
motate might	RORA	1	+	+	+	-	+	100	-	-	1,0	1	-	46	2	1	A			1	1	6	
	1101111	1	1	1	1	1	1	1	1	1	1	1		1		1 '	B C b7 b0	1	1	1	1 '	10	1

The Condition Code Register notes are listed after Table 10.

Table 7 Accumulator & Memory Instructions (Continued)

							Add	dressi	ng l	Mod	es							C			on (Cod	е
Operations	Mnemonic	IMI	ME	D.	DIF	REC	Г	IN	DE:	X	EXT	TEN	ID	IMP	LIE	D	Boolean/ Arithmetic Operation	5	4	3	2	1	0
		ОР	~	#	ОР	~	#	ОР	~	#	OP	~	#	ОР	~	п	Authorite Speration	н	1	N	z	V	С
Shift Left	ASL							68	6	2	78	6	3				M) 4	•	•	1	‡	6	1
Arithmetic	ASLA													48	2	1	A	•	•	1	‡	6	1
	ASLB													58	2	1	B C 67 60			1	‡	6	\$
Double Shift Left, Arithmetic	ASLD													05	3	1	ACC A/ ACC B ← 0 C A7 A0 B7 B0	•	•	1	1	6	1
Shift Right	ASR							67	6	2	77	6	3				M)			‡	1	6	1
Arithmetic	ASRA													47	2	1	A		•	‡	1	6	‡
	ASRB													57	2	1	B) b/ b0 C			‡	1	6	‡
Shift Right	LSR							64	6	2	74	6	3				M)			R	1	6	‡
Logical	LSRA													44	2	1	A 0-	•		R	‡	6	‡
	LSRB													54	2	1	B) 67 60 C			R	1	6	\$
Double Shift Right Logical	LSRD													04	3	1	0→ ACC A/ ACC B → C A7 A0 B7 B0 C	•		R	‡	6	1
Store	STAA				97	3	2	A7	4	2	В7	4	3				A → M			1	‡	R	
Accumulator	STAB			Г	D7	3	2	E7	4	2	F7	4	3				B → M			‡	1	R	
Store Double Accumulator	STD				DD	4	2	ED	5	2	FD	5	3				A → M B → M + 1	•	•	1	‡	R	•
Subtract	SUBA	80	2	2	90	3	2	A0	4	2	во	4	3				$A - M \rightarrow A$	•	•	‡	‡	‡	1
	SUBB	CO	2	2	D0	3	2	EO	4	2	FO	4	3				B - M → B			1	1	1	1
Double Subtract	SUBD	83	4	3	93	5	2	A3	6	2	В3	6	3				A : B − M : M + 1 → A : B		•	1	1	1	1
Subtract Accumulators	SBA													10	2	1	A - B → A	•	•	‡	1	1	‡
Subtract	SBCA	82	2	2	92	3	2	A2	4	2	B2	4	3				$A - M - C \rightarrow A$		•	1	1	1	‡
With Carry	SBCB	C2	2	2	D2	3	2	E2	4	2	F2	4	3				B - M - C → B			1	1	1	1
Transfer	TAB													16	2	1	A → B			1	‡	R	•
Accumulators	TBA										-			17	2	1	B → A		•	1	1	R	
Test Zero or	TST							6D	6	2	7D	6	3				M - 00			1	1	R	R
Minus	TSTA													4D	2	1	A - 00			‡	1	R	R
	TSTB	T												5D	2	1	B - 00			1	1	R	R

The Condition Code Register notes are listed after Table 10.

Direct Addressing

In direct addressing, the address of the operand is contained in the second byte of the instruction. Direct addressing allows the user to directly address the lowest 256 bytes in the machine i.e., locations zero through 255. Enhanced execution times are achieved by storing data in these locations. In most configurations, it should be a random access memory. These are two-byte instructions.

Extended Addressing

In extended addressing, the address contained in the second byte of the instruction is used as the higher 8-bits of the address of the operand. The third byte of the instruction is used as the lower 8-bits of the address for the operand. This is an absolute address in memory. These are three-byte instructions.

Indexed Addressing

In indexed addressing, the address contained in the second byte of the instruction is added to the index register's lowest 8-bits in the CPU. The carry is then added to the higher order 8-bits of the index register. This result is then used to address memory. The modified address is held in a temporary address register so there is no change to the index register. These are two-byte instructions.

Implied Addressing

In the implied addressing mode the instruction gives the address (i.e., stack pointer, index register, etc.). These are one-byte instructions.

Relative Addressing

In relative addressing, the address contained in the second byte of the instruction is added to the program counter's lowest 8-bits plus two. The carry or borrow is then added to the high 8-bits. This allows the user to address data within a range of -126 to +129 bytes of the present instruction. These are two-byte instructions.



New Instructions

In addition to the existing 6800 Instruction Set, the following new instructions are incorporated in the HD6803 Microcomputer.

- ABX Adds the 8-bit unsigned accumulator B to the 16-bit X-Register taking into account the possible carry out of the low order byte of the X-Register.
- ADDD Adds the double precision ACCD* to the double precision value M:M+1 and places the results in ACCD.
- ASLD Shifts all bits of ACCD one place to the left. Bit 0 is loaded with zero, The C bit is loaded from the most significant bit of ACCD.
- LDD Loads the contents of double precision memory location into the double accumulator A:B. The condition codes are set according to the data.
- LSRD Shifts all bits of ACCD one place to the right. Bit 15 is loaded with zero. The C bit is loaded from the least significant bit to ACCD.
- MUL Multiplies the 8 bits in accumulator A with the 8 bits in accumulator B to obtain a 16-bit unsigned number in A:B, ACCA contains MSB of result.
- **PSHX** The contents of the index register is pushed onto the stack at the address contained in the stack pointer. The stack pointer is decremented by 2.
- PULX The index register is pulled from the stack beginning at the current address contained in the stack pointer +1. The stack pointer is incremented by 2 in total.
- STD Stores the contents of double accumulator A:B in memory. The contents of ACCD remain unchanged.
- SUBD Subtracts the contents of M:M + 1 from the contents of double accumulator AB and places the result in ACCD.
- BRN Never branches. If effect, this instruction can be considered a two byte NOP (No operation) requiring three cycles for execution.
- CPX Internal processing modified to permit its use with any conditional branch instruction.

Table 8 Index Register and Stack Manipulation Instructions

							Add	dress	ing	Мо	des						Boolean/	(ditio			e
Pointer Operations	Mnemonic	IM	ME	D.	DII	REC	ст	IN	DE:	X	EX	TNE)	IMP	LIE	D	Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		Н	1	N	Z	٧	С
Compare Index Reg	CPX	8C	4	3	9C	5	2	AC	6	2	ВС	6	3				X - M : M + 1	•		1	1	1	1
Decrement Index Reg	DEX													09	3	1	X − 1 → X			•	1		
Decrement Stack Pntr	DES													34	3	1	SP - 1 → SP	•	•	•			•
Increment Index Reg	INX													08	3	1	X + 1 → X	•	•	•	1	•	•
Increment Stack Pntr	INS													31	3	1	SP + 1 → SP						•
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	5	2	FE	5	3				$M \rightarrow X_H, (M+1) \rightarrow X_L$	•		7	1	R	
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	5	2	BE	5	3				$M \rightarrow SP_H, (M+1) \rightarrow SP_L$	•	•	(7)	1	R	
Store Index Reg	STX				DF	4	2	EF	5	2	FF	5	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$	•		1	1	R	
Store Stack Pntr	STS				9F	4	2	AF	5	2	BF	5	3				$SP_H \rightarrow M, SP_L \rightarrow (M+1)$		•	7	1	R	
Index Reg → Stack Pntr	TXS													35	3	1	X - 1 → SP	•		•	•		
Stack Pntr → Index Reg	TSX													30	3	1	SP + 1 → X	•	•	•	•		•
Add	ABX													3A	3	1	$B + X \rightarrow X$	•				•	
Push Data	PSHX													3C	4	1	$X_L \rightarrow M_{sp}$, $SP - 1 \rightarrow SP$	•		•	•		
																	$X_H \rightarrow M_{sp}$, SP - 1 \rightarrow SP						
Pull Data	PULX													38	5	1	SP + 1 → SP, M _{sp} → X _H	•		•	•		
																	SP + 1 - SP, M _{SD} - XL						

The Condition Code Register notes are listed after Table 10.

^{*}ACCD' is the 16 bit register (A:B) formed by concatenating the A and B accumulators. The A-accumulator is the most significant byte.

Table 9 Jump and Branch Instructions

							Ad	dres	sing	Мо	des							(diti Reg		Cod	е
Operations	Mnemonic	REL	ATI	VE	DII	REC	T	IN	DE	X	EX	TND)	IME	LIE	D	Branch Test	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		Н	1	N	Z	٧	С
Branch Always	BRA	20	3	2													None		0	0			
Branch Never	BRN	21	3	2													None		•			•	
Branch If Carry Clear	всс	24	3	2													C = 0						
Branch If Carry Set	BCS	25	3	2													C = 1			0		0	
Branch If = Zero	BEQ	27	3	2		*											Z = 1			•	•	•	
Branch If ≥ Zero	BGE	2C	3	2													N + V = 0						
Branch If > Zero	BGT	2E	3	2													Z + (N + V) = 0		•		•	•	
Branch If Higher	вні	22	3	2													C + Z = 0						
Branch If ≤ Zero	BLE	2F	3	2													Z + (N + V) = 1		•				
Branch If Lower Or Same	BLS	23	3	2													C + Z = 1	•	•	•	•	•	•
Branch If < Zero	BLT	2D	3	2													N + V = 1				•	•	•
Branch If Minus	BMI	2B	3	2													N = 1		•			•	
Branch If Not Equal Zero	BNE	26	3	2													Z = 0	•	•			•	•
Branch If Overflow Clear	BVC	28	3	2													V = 0			•	•	•	•
Branch If Overflow Set	BVS	29	3	2													V = 1						
Branch If Plus	BPL	2A	3	2													N = 0		•				•
Branch To Subroutine	BSR	8D	6	2																			
Jumpi	JMP							6E	3	2	7E	3	3								•		
Jump To Subroutine	JSR				9D	5	2	AD	6	2	BD	6	3							0	•	•	
No Operation	NOP													01	2	1	Advances Prog. Cntr. Only	•	•	•		•	•
Return From Interrupt	RTI													3B	10	1	V *	-		- (8	_	_
Return From Subroutine	RTS													39	5	1		•		•	•	•	•
Software Interrupt	SWI													3F	12	1			S		0		
Wait for Interrupt	WAI													3E	9	1			9		•		

Table 10 Condition Code Register Manipulation Instructions

		Addre	ssingf	Modes		C	ondit	ion C	ode l	Regis	ter
Operations	Mnemonic	IM	PLIE	D	Boolean Operation	5	4	3	2	1	0
		OP	~	#		Н	- 1	N	Z	V	С
Clear Carry	CLC	0C	2	1	0 → C	•	•	•	•		R
Clear Interrupt Mask	CLI	0E	2	1	0 → 1		R	•		•	•
Clear Overflow	CLV	0A	2	1	0 → V	•				R	
Set Carry	SEC	0D	2	1	1 → C	•	•	•	•		S
Set Interrupt Mask	SEI	OF	2	1	1 → 1	•	S			•	
Set Overflow	SEV	ОВ	2	1	1 → V	•				S	
Accumulator A → CCR	TAP	06	2	1	A→ CCR	_		_ (0 –	_	
CCR → Accumulator A	TPA	07	2	1	CCR → A	•					

Condition Code Register Notes: (Bit set it test is true and cleared otherwise)

Condition Code Register Notes: (Bit set it test is true and cleared otherwise)

(1) (Bit V) Test: Result = 10000000?

(2) (Bit C) Test: Result = 00000000?

(3) (Bit C) Test: Decimal value of most significant BCD Character greater than nine? (Not cleared if previously set)

(4) (Bit V) Test: Operand = 100000000 prior to execution?

(5) (Bit V) Test: Operand = 01111111 prior to execution?

(6) (Bit V) Test: Set equal to result of N (a) C after shift has occurred.

(7) (Bit N) Test: Result less than zero? (Bit 15 = 1)

(8) (All) Load Condition Code Register from Stack. (See Special Operations)

(9) (Bit 1) Set when interrupt occurs, if previously set, a Non-Maskable Interrupt is required to exit the wait state.

(10) (All) Set equal to result of Bit 7 (ACCB)



Table 11 Instruction Execution Times in Machine Cycle

	ACCX	Imme- diate	Direct	Ex- tended	In- dexed	Im- plied	Re- lative		ACCX	Imme- diate	Direct	Ex- tended	In- dexed	Im- plied	Re- lative	
ABA	•	•	•	•	•	2	•	INX	•	•	•	•	•	3	•	
ABX	•	•	•	•	•	3	•	JMP	•	•	•	3	3	•	•	
ADC	•	2	3	4	4		•	JSR		•	5	6	6	•	•	
ADD	•	2	3	4	4	•	•	LDA		2	3	4	4	•	•	
ADDD		4	5	6	6	•	•	LDD	•	3	4	5	5	•	•	
AND		2	3	4	4	•	•	LDS	•	3	4	5	5	•	•	
ASL	2	•	•	6	6	•	•	LDX		3	4	5	5	•	•	
ASLD		•		•	•	3	•	LSR	2	•	•	6	6	•	•	
ASR	2	•	•	6	6		•	LSRD	•	•		•	•	3	•	
BCC	•	•			•	•	3	MUL	•	•	•	•	•	10	•	
BCS	•	•	•	•	•		3	NEG	2	•		6	6	•	•	
BEQ		•	•	•	•	•	3	NOP	•	•	•	•	•	2		
BGE	•	•	•	•	•	•	3	ORA		2	3	4	4	•	•	
BGT		•	•		•		3	PSH	3	•	•	•	•	•	•	
вні	•	•	•	•	•		3	PSHX	•	•		•	•	4	•	
BIT		2	3	4	4		•	PUL	4	•	•	•	•	•	•	
BLE	•	•	•	•	•		3	PULX	•		•	•	•	5	•	
BLS		•			•	•	3	ROL	2	•	•	6	6	•		
BLT						•	3	ROR	2	•	•	6	6		•	
BMI					•	•	3	RTI		•		•	•	10	•	
BNE					•		3	RTS				•	•	5		
BPL							3	SBA			•		•	2		
BRA					•		3	SBC		2	3	4	4	•	•	
BRN							3	SEC		•	•		•	2	•	
BSR			•				6	SEI		•		•		2	•	
BVC					•	•	3	SEV	•	•		•	•	2	•	
BVS							3	STA	•		3	4	4	•		
CBA						2		STD		•	4	5	5	•	•	
CLC						2		STS			4	5	5		•	
CLI						2	•	STX	•		4	5	5	•	•	
				6	6			SUB		2	3	4	4	•		
CLR	2					2		SUBD		4	5	6	6			
CLV	•			4	4			SWI			•	•	•	12		
CMP	•	2	3	6	6			TAB						2		
СОМ	2	•	5	6	6			TAP						2		
CPX	•	4	9	•		2		TBA						2		
DAA	2			6	6			TPA			•			2		
	•					3		TST	2			6	6		•	
DES						3		TSX			•	•	•	3		
DEX	•							TXS						3		
EOR	•	2	3	4	4			WAI						9		
INC	2	•	•	6	6	•		WAI	•	•	-	-	-	3	•	
INS	•	•	•	•	•	3	•									

• Summary of Cycle by Cycle Operation

Table 12 provides a detailed description of the information present on the Address Bus, Data Bus, and the Read/Write line (R/\overline{W}) during each cycle for each instruction.

This information is useful in comparing actual with expected results during debug of both software and hardware as the

control program is executed. The information is categorized in groups according to addressing mode and number of cycles per instruction. (In general, instructions with the same addressing mode and number of cycles execute in the same manner; exceptions are indicated in the table).

Table 12 Cycle by Cycle Operation

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W Line	Data Bus
MMEDIATE					
ADC EOR	2	1	Op Code Address	1	Op Code
ADD LDA		2	Op Code Address + 1	1	Operand Data
AND ORA					
BIT SBC					
CMP SUB					
LDS	3	1	Op Code Address	1	Op Code
LDX		2	Op Code Address + 1	1	Operand Data (High Order Byte)
LDD		3	Op Code Address + 2	1	Operand Data (Low Order Byte)
CPX	4	1	Op Code Address	1	Op Code
SUBD		2	Op Code Address + 1	1	Operand Data (High Order Byte)
ADDD		3	Op Code Address + 2	1	Operand Data (Low Order Byte)
		4	Address Bus FFFF	1	Low Byte of Restart Vector
DIRECT					
ADC EOR	3	1	Op Code Address	1	Op Code
ADD LDA		2	Op Code Address + 1	1	Address of Operand
AND ORA		3	Address of Operand	1	Operand Data
BIT SBC			~		
CMP SUB					
STA	3	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Destination Address
\$16.2		3	Destination Address	0	Data from Accumulator
LDS	4	1	Op Code Address	1	Op Code
LDX		2	Op Code Address + 1	1	Address of Operand
LDD		3	Address of Operand	1	Operand Data (High Order Byte)
		4	Operand Address + 1	1	Operand Data (Low Order Byte)
STS	4	- 1	Op Code Address	1	Op Code
STX		2	Op Code Address + 1	1	Address of Operand
STD		3	Address of Operand	0	Register Data (High Order Byte)
		4	Address of Operand + 1	0	Register Data (Low Crder Byte)
CPX	5	1	Op Code Address	1	Op Code
SUBD		2	Op Code Address + 1	1	Address of Operand
ADDD		3	Operand Address Operand Address + 1	1	Operand Data (High Order Byte) Operand Data (Low Order Byte)
		5	Address Bus FFFF	1	Low Byte of Restart Vector
JSR	5	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Irrelevant Data
		3	Subroutine Address	1	First Subroutine Op Code
		4	Stack Pointer	0	Return Address (Low Order Byte)
	1	5	Stack Pointer + 1	0	Return Address (High Order Byte)



Table 12 Cycle by Cycle Operation (Continued)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W Line	Data Bus
NDEXED					
JMP	3	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Offset
		3	Address Bus FFFF	1	Low Byte of Restart Vector
ADC EOR	4	1	Op Code Address	1	Op Code
ADD LDA		2	Op Code Address + 1	1	Offset
AND ORA		3	Address Bus FFFF	1	Low Byte of Restart Vector
BIT SBC		4	Index Register Plus Offset	1	Operand Data
CMP SUB					
STA	4	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Offset
		3	Address Bus FFFF	1	Low Byte of Restart Vector
		4	Index Register Plus Offset	0	Operand Data
LDS	5	1	Op Code Address	1	Op Code
LDX		2	Op Code Address + 1	1	Offset
LDD		3	Address Bus FFFF	1	Low Byte of Restart Vector
LDD		4	Index Register Plus Offset	1	Operand Data (High Order Byte)
LDD		5	Index Register Plus Offset + 1	1	Operand Data (Low Order Byte)
STS	5	1	-		
STX	5	2	Op Code Address	1	Op Code Offset
STD		3	Op Code Address + 1 Address Bus FFFF	1	
310		4		0	Low Byte of Restart Vector
		5	Index Register Plus Offset Index Register Plus Offset + 1	0	Operand Data (High Order Byte) Operand Data (Low Order Byte)
	-				
ASL LSR	6	1	Op Code Address	1	Op Code
ASR NEG		2	Op Code Address + 1	1	Offset
CLR ROL		3	Address Bus FFFF	1	Low Byte of Restart Vector
COM ROR		4	Index Register Plus Offset	1	Current Operand Data
DEC TST*		5	Address Bus FFFF	1	Low Byte of Restart Vector
INC	-	6	Index Register Plus Offset	0	New Operand Data
CPX	6	1	Op Code Address	1	Op Code
SUBD		2	Op Code Address + 1	1	Offset
ADDD		3	Address Bus FFFF	1	Low Byte of Restart Vector
		4	Index Register + Offset	1	Operand Data (High Order Byte)
		5	Index Register + Offset + 1	1	Operand Data (Low Order Byte)
	-	6	Address Bus FFFF		Low Byte of Restart Vector
JSR	6	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Offset
		3	Address Bus FFFF	1	Low Byte of Restart Vector
		4	Index Register + Offset	1	First Subroutine Op Code
		5	Stack Pointer	0	Return Address (Low Order Byte)
		6	Stack Pointer - 1	0	Return Address (High Order Byte)

[•] In the TST instruction, R/W line of the sixth cycle is "1" level, and AB = FFFF, DB = Low Byte of Reset Vector.

Table 12 Cycle by Cycle Operation (Continued)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W Line	Data Bus
EXTENDED					×
JMP	3	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Jump Address (High Order Byte)
		3	Op Code Address + 2	1	Jump Address (Low Order Byte)
ADC EOR	4	1	Op Code Address	1	Op Code
ADD LDA		2	Op Code Address + 1	1	Address of Operand (High Order Byte)
AND ORA		3	Op Code Address + 2	1	Address of Operand (Low Order Byte)
BIT SBC		4	Address of Operand	1	Operand Data
CMP SUB					
STA	4	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Destination Address (High Order Byte)
		3	Op Code Address + 2	1	Destination Address (Low Order Byte)
		4	Operand Destination Address	0	Data from Accumulator
LDS	5	1	Op Code Address	1	Op Code
LDX		2	Op Code Address + 1	1	Address of Operand (High Order Byte)
LDD		3	Op Code Address + 2	1	Address of Operand (Low Order Byte)
		4	Address of Operand	1	Operand Data (High Order Byte)
		5	Address of Operand + 1	1	Operand Data (Low Order Byte)
STS	5	1	Op Code Address	1	Op Code
STX		2	Op Code Address + 1	1	Address of Operand (High Order Byte)
STD		3	Op Code Address + 2	1	Address of Operand (Low Order Byte)
0.0		4	Address of Operand	0	Operand Data (High Order Byte)
		5	Address of Operand + 1	0	Operand Data (Low Order Byte)
ASL LSR	6	1	Op Code Address	1	Op Code
ASR NEG		2	Op Code Address + 1	1	Address of Operand (High Order Byte)
CLR ROL		3	Op Code Address + 2	1	Address of Operand (Low Order Byte)
COM ROR		4	Address of Operand	1	Current Operand Data
DEC TST*		5	Address Bus FFFF	1	Low Byte of Restart Vector
INC		6	Address of Operand	0	New Operand Data
CPX	6	1	Op Code Address	1	Op Code
SUBD		2	Op Code Address + 1	1	Operand Address (High Order Byte)
ADDD		3	Op Code Address + 2	1	Operand Address (Low Order Byte)
		4	Operand Address	1	Operand Data (High Order Byte)
		5	Operand Address + 1	1	Operand Data (Low Order Byte)
		6	Address Bus FFFF	1	Low Byte of Restart Vector
JSR	6	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Address of Subroutine (High Order Byte
		3	Op Code Address + 2	1	Address of Subroutine (Low Order Byte
	1	4	Subroutine Starting Address	1	Op Code of Next Instruction
		5	Stack Pointer	0	Return Address (Low Order Byte)
		6	Stack Pointer - 1	0	Return Address (High Order Byte)

^{*} In the TST instruction, R/\overline{W} line of the sixth cycle is "1" level, and AB = FFFF, DB = Low Byte of Reset Vector.



Table 12 Cycle by Cycle Operation (Continued)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W Line	Data Bus
MPLIED	- 4				
ABA DAA SEC ASL DEC SEI ASR INC SEV CBA LSR TAB CLC NEG TAP	2	1 2	Op Code Address Op Code Address + 1	1 1	Op Code Op Code of Next Instruction
CLI NOP TBA CLR ROL TPA CLV ROR TST COM SBA					
ABX	3	1 2 3	Op Code Address Op Code Address + 1 Address Bus FFFF	1 1 1	Op Code Irrelevant Data Low Byte of Restart Vector
ASLD LSRD	3	1 2 3	Op Code Address Op Code Address + 1 Address Bus FFFF	1 1 1	Op Code Irrelevant Data Low Byte of Restart Vector
DES INS	3	1 2 3	Op Code Address Op Code Address + 1 Previous Register Contents	1 1 1	Op Code Op Code of Next Instruction Irrelevant Data
INX DEX	3	1 2 3	Op Code Address Op Code Address + 1 Address Bus FFFF	1 1 1	Op Code Op Code of Next Instruction Low Byte of Restart Vector
PSHA PSHB	3	1 2 3	Op Code Address Op Code Address + 1 Stack Pointer	1 1 0	Op Code Op Code of Next Instruction Accumulator Data
TSX	3	1 2 3	Op Code Address Op Code Address + 1 Stack Pointer	1 1 1	Op Code Op Code of Next Instruction Irrelevant Data
TXS	3	1 2 3	Op Code Address Op Code Address + 1 Address Bus FFFF	1 1 1	Op Code Op Code of Next Instruction Low Byte of Restart Vector
PULA PULB	4	1 2 3 4	Op Code Address Op Code Address + 1 Stack Pointer Stack Pointer + 1	1 1 1	Op Code Op Code of Next Instruction Irrelevant Data Operand Data from Stack
PSHX	4	1 2 3 4	Op Code Address Op Code Address + 1 Stack Pointer Stack Pointer - 1	1 1 0 0	Op Code Irrelevant Data Index Register (Low Order Byte) Index Register (High Order Byte)
PULX	5	1 2 3 4	Op Code Address Op Code Address + 1 Stack Pointer Stack Pointer + 1	1 1 1	Op Code Irrelevant Data Irrelevant Data Index Register (High Order Byte)
RTS	5	5 1 2 3 4	Stack Pointer +2 Op Code Address Op Code Address + 1 Stack Pointer Stack Pointer + 1	1 1 1 1 1 1	Index Register (Low Order Byte) Op Code Irrelevant Data Irrelevant Data Address of Next Instruction
		5	Stack Pointer + 2	1	(High Order Byte) Address of Next Instruction (Low Order Byte)
WAI**	9	1 2 3 4	Op Code Address Op Code Address + 1 Stack Pointer Stack Pointer - 1	1 1 0	Op Code Op Code of Next Instruction Return Address (Low Order Byte Return Address (High Order Byte



Table 12 Cycle by Cycle Operation (Continued)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W Line	Data Bus
WAI**	1	5	Stack Pointer – 2	0	Index Register (Low Order Byte)
		6	Stack Pointer – 3	0	Index Register (High Order Byte)
		7	Stack Pointer – 4	0	Contents of Accumulator A
		8	Stack Pointer - 5	0	Contents of Accumulator B
		9	Stack Pointer – 6	0	Contents of Cond. Code Register
MUL	10	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Irrelevant Data
		3	Address Bus FFFF	1	Low Byte of Restart Vector
		4	Address Bus FFFF	1	Low Byte of Restart Vector
		5	Address Bus FFFF	1	Low Byte of Restart Vector
		6	Address Bus FFFF	1	Low Byte of Restart Vector
		7	Address Bus FFFF	1	Low Byte of Restart Vector
		8	Address Bus FFFF	1	Low Byte of Restart Vector
		9	Address Bus FFFF	1	Low Byte of Restart Vector
		10	Address Bus FFFF	1	Low Byte of Restart Vector
RTI	10	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Irrelevant Data
		3	Stack Pointer	1	Irrelevant Data
		4	Stack Pointer + 1	1	Contents of Cond. Code Reg. from Stack
		5	Stack Pointer + 2	1	Contents of Accumulator B
		5	Stack Fornter 12		from Stack
		6	Stack Pointer + 3	1	Contents of Accumulator A
					from Stack
		7	Stack Pointer + 4	1	Index Register from Stack
					(High Order Byte)
		8	Stack Pointer + 5	1	Index Register from Stack
	1				(Low Order Byte)
		9	Stack Pointer + 6	1	Next Instruction Address from
					Stack (High Order Byte)
		10	Stack Pointer + 7	1	Next Instruction Address from
					Stack (Low Order Byte)
SWI	12	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Irrelevant Data
		3	Stack Pointer	0	Return Address (Low Order Byte
		4	Stack Pointer - 1	0	Return Address (High Order Byte
		5	Stack Pointer - 2	0	Index Register (Low Order Byte)
		6	Stack Pointer - 3	0	Index Register (High Order Byte)
		7	Stack Pointer - 4	0	Contents of Accumulator A
	1	8	Stack Pointer - 5	0	Contents of Accumulator B
	1	9	Stack Pointer - 6	0	Contents of Cond. Code Register
		10	Stack Pointer - 7	1	Irrelevant Data
		11	Vector Address FFFA (Hex)	1	Address of Subroutine
					(High Order Byte)
	1	12	Vector Address FFFB (Hex)	1	Address of Subroutine
	1				(Low Order Byte)



^{**} While the MPU is in the "Wait" state, its bus state will appear as a series of MPU reads of an address which is seven locations less than the original contents of the Stack Pointer. Contrary to the HD6800, none of the ports are driven to the high impedance state by a WAI instruction.

Table 12 Cycle by Cycle Operation (Continued)

RELATIVE

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W Line	Data Bus
BCC BHT BNE	3	1	Op Code Address	1	Op Code
BCS BLE BPL		2	Op Code Address + 1	1	Branch Offset
BEQ BLS BRA BGE BLT BVC BGT BMT BVS BRN		3	Address Bus FFFF	1	Low Byte of Restart Vector
BSR	6	1	Op Code Address	1	Op Code
		2	Op Code Address + 1	1	Branch Offset
		3	Address Bus FFFF	1	Low Byte of Restart Vector
		4	Subroutine Starting Address	1	Op Code of Next Instruction
		5	Stack Pointer	0	Return Address (Low Order Byte)
		6	Stack Pointer - 1	0	Return Address (High Order Byte)

Summary of Undefined Instruction Operations

The HD6803 has 36 underfined instructions. When these are carried out, the contents of Register and Memory in MPU change at random.

When the op codes (4E, 5E) are used to execute the MPU continues to increase the program counter and it will not stop until the Reset signal enters. These op codes are used to test the LSI.

Table 13 Op codes Map

(OP					ACC	ACC		CVT	AC	CA or	SP		A	CCB or	X	
	DE					Α	В	IND	EXT	IMM	DIR	IND	EXT	IMM	DIR	IND	EXT
	н	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
LO \		0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F
0000	0		SBA	BRA	TSX		NE	G					SI	JB			
0001	1	NOP	CBA	BRN	INS								CI	MP			
0010	2			вні	PULA (+1)								SI	ВС			
0011	3			BLS	PULB (+1)		CC	M		•	SUB	D (+2)		•	ADD	D (+2)	
0100	4	LSRD (+1)		BCC	DES	LSR				AND							
0101	5	ASLD (+1)		BCS	TXS				BIT								
0110	6	TAP	TAB	BNE	PSHA		RC	R		LDA							
0111	7	TPA	TBA	BEQ	PSHB		AS	R				STA				STA	
1000	8	INX (+1)		BVC	PULX (+2)		AS	SL					E	OR			
1001	9	DEX (+1)	DAA	BVS	RTS (+2)		R	DL					Α	DC			
1010	Α	CLV		BPL	ABX		DI	С					0	RA			
1011	В	SEV	ABA	ВМІ	RTI (+7)								A	DD			
1100	С	CLC		BGE	PSHX (+1)		11	IC			CP:	x (+2)			LDI	D (+1)	
1101	D	SEC		BLT	MUL (+7)		TS	т		BSR (+4)		SR (+2	2)	• (+1)	S	TD (+	1)
1110	E	CLI		BGT	WAI (+6)	_ •		JMP	(-3)	•	LD	S (+1)		•	LD	X (+1)	
1111	F	SEI		BLE	SWI (+9)		CI	R		• (+1)	5	TS (+1	1)	• (+1)	S	TX (+	1)
BYTE/C	YCLE	1/2	1/2	2/3	1/3	1/2	1/2	2/6	3/6	2/2	2/3	2/4	3/4	2/2	2/3	2/4	3/4

[NOTES]

- 1) Undefined Op codes are marked with ______.
- 2) () indicate that the number in parenthesis must be added to the cycle count for that instruction,
- The instructions shown below are all 3 bytes and are marked with "*".
 Immediate addressing mode of SUBD, CPX, LDS, ADDD, LDD and LDX instructions, and undefined op codes (8F, CD, CF).
- 4) The Op codes (4E, 5E) are 1 byte/∞ cycles instructions, and are marked with "**"

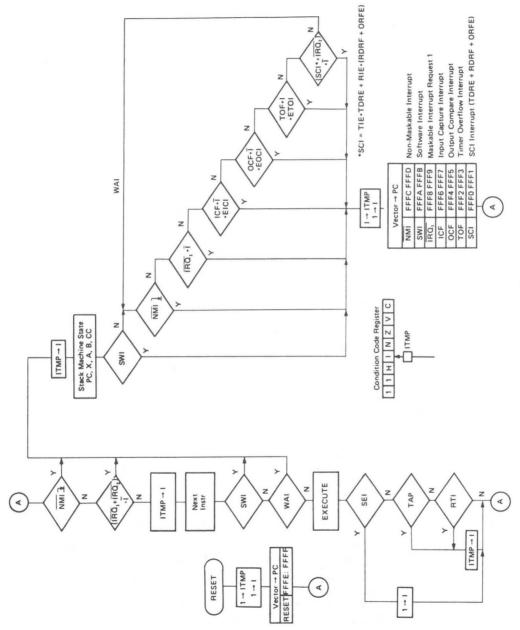


Figure 16 Interrupt Flowchart

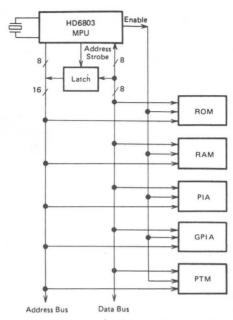


Figure 17 HD6803 MPU Expanded Multiplexed Bus

■ Caution for the HD6803 Family SCI, TIMER Status Flag
The flags shown in Table 14 are cleared by reading/writing
(flag reset condition 2) the data register corresponding to each
flag after reading the status register (flag reset condition 1).

To clear the flag correctly, take the following procedure:

- 1. Read the status register.
- 2. Test the flag.
- 3. Read the data register.

Table 14 Status Flag Reset Conditions

	Status Flag	Flag Reset Condition 1 (Status Register)	Flag Reset Condition 2 (Data Register)		
	ICF	Man	ICR/Read		
TIMER	OCF	When each flag is "1", TRCSR/Read	OCR/Write		
TOF	THOSA/ Nead	TC/Read			
	RDRF	140	RDR/Read		
SCI	ORFE	When each flag is "1", TRCSR/Read	ADR/ Read		
	TDRE	I NCSR/Read	TDR/Write		

HD6809,HD68A09,HD68B09

MPU (Micro Processing Unit)

The HD6809 is a revolutionary high performance 8-bit microprocessor which supports modern programming techniques such as position independence, reentrancy, and modular programming.

This third-generation addition to the HMCS6800 family has major architectural improvements which include additional registers, instructions and addressing modes.

The basic instructions of any computer are greatly enhanced by the presence of powerful addressing modes. The HD6809 has the most complete set of addressing modes available on any 8-bit microprocessor today.

The HD6809 has hardware and software features which make it an ideal processor for higher level language execution or standard controller applications.

HD6800 COMPATIBLE

- Hardware Interfaces with All HMCS6800 Peripherals
- Software Upward Source Code Compatible Instruction Set and Addressing Modes

■ ARCHITECTURAL FEATURES

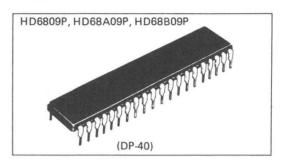
- Two 16-bit Index Registers
- Two 16-bit Indexable Stack Pointers
- Two 8-bit Accumulators can be Concatenated to Form One 16-Bit Accumulator
- Direct Page Register Allows Direct Addressing Throughout Memory

HARDWARE FEATURES

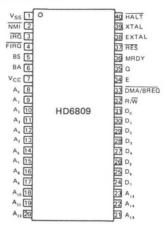
- On Chip Oscillator
- DMA/BREQ Allows DMA Operation or Memory Refresh
- Fast Interrupt Request Input Stacks Only Condition Code Register and Program Counter
- MRDY Input Extends Data Access Times for Use With Slow Memory
- Interrupt Acknowledge Output Allows Vectoring By Devices
- SYNC Acknowledge Output Allows for Synchronization to External Event
- Single Bus-Cycle RESET
- Single 5-Volt Supply Operation
- NMI Blocked After RESET Until After First Load of Stack Pointer
- Early Address Valid Allows Use With Slower Memories
- Early Write-Data for Dynamic Memories
- Compatible with MC6809, MC68A09 and MC68B09

SOFTWARE FEATURES

- 10 Addressing Modes
 - HMCS6800 Upward Compatible Addressing Modes
 - · Direct Addressing Anywhere in Memory Map
 - · Long Relative Branches
 - · Program Counter Relative
 - True Indirect Addressing
 - · Expanded Indexed Addressing:



■ PIN ARRANGEMENT



(Top View)

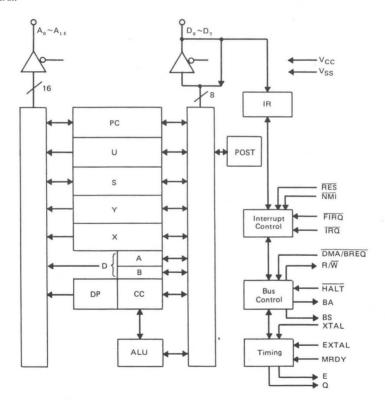
0, 5, 8, or 16-bit Constant Offsets

8, or 16-bit Accumulator Offsets

Auto-Increment/Decrement by 1 or 2

- Improved Stack Manipulation
- 1464 Instructions with Unique Addressing Modes
- 8 x 8 Unsigned Multiply
- 16-bit Arithmetic
- Transfer⁴Exchange All Registers
- Push/Pull Any Registers or Any Set of Registers
- Load Effective Address

■ BLOCK DIAGRAM



■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc} *	-0.3 ∼ +7.0	V
Input Voltage	V _{in} *	-0.3 ~ +7.0	V
Operating Temperature	Topr	-20 ∼ +75	°C
Storage Temperature	T _{stq}	-55 ∼ +150	°C

^{*} With respect to V_{SS} (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ RECOMMENDED OPERATING CONDITIONS

Item		Symbol	min	typ	max	Unit
Supply Voltage		V _{cc} *	4.75	5.0	5.25	V
		V _{IL} *	-0.3	-	0.8	V
		Logic $(Ta = 0 \sim +75^{\circ}C)$	2.0	-	V _{cc}	
Input Voltage	V _{IH} *	$(Ta = -20 \sim 0^{\circ}C)$	2.2	-	V _{cc}	V
		RES	4.0	-	V_{CC}	
Operating Temperature		T _{opr}	-20	25	75	°C

^{*} With respect to $V_{\mbox{SS}}$ (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS ($V_{CC} = 5V \pm 5\%$, $V_{SS} = 0V$, $T_a = -20 \sim +75 ^{\circ} C$, unless otherwise noted.)

Item		Symbol	Test Condition		HD680	9	Н	D68A	09	Н	D68B	09	Unit
Item		Symbol	rest condition	min	typ*	max	min	typ*	max	min	typ*	max	Unit
	5 . 550		$Ta = 0 \sim +75^{\circ}C$	2.0	-	Vcc	2.0	-	Vcc	2.0	-	Vcc	
Input "High" Voltage	Except RES	VIH	$Ta = -20 \sim 0^{\circ}C$	2.2	-	Vcc	2.2	-	Vcc	2.2	-	Vcc	V
	RES			4.0	-	Vcc	4.0	-	Vcc	4.0	-	Vcc	
Input "Low" Voltage		VIL		-0.3	-	0.8	-0.3	-	0.8	-0.3	-	0.8	V
Input Leakage Current	Except EXTAL, XTAL	lin	Vin=0~5.25V, V _{CC} =max	-2.5	-	2.5	-2.5	-	2.5	-2.5	-	2.5	μА
Three State (Off State)	D ₀ ~D ₇	l	Vin=0.4~2.4V,	-10	-	10	-10	-	10	-10	-	10	μА
Input Current	$A_0 \sim A_{15}$, R/ \overline{W}	TSI	V _{CC} =max	-100	-	100	-100	-	100	-100	-	100	μА
	D ₀ ~D ₇		I _{LOAD} =-205μA, V _{CC} =min	2.4	-	-	2.4	-	-	2.4	-	-	
Output "High" Voltage	A ₀ ~A ₁₅ , R/W, Q, E	V _{OH}	I _{LOAD} =-145μA, V _{CC} =min	2.4	-	-	2.4	-	-	2.4	-	-	v
	BA, BS		I _{LOAD} =-100μA, V _{CC} =min	2.4	-	-	2.4	-	-	2.4	-	-	
Output "Low" Voltage		VOL	I _{LOAD} =2mA	-	-	0.5	-	_	0.5	-	-	0.5	V
Power Dissipation		PD		-	-	1.0	-	-	1.0	-	-	1.0	W
Input Capacitance	D ₀ ~D ₇	Cin	Vin=0V,	-	10	15	-	10	15	-	10	15	pF
	Except D ₀ ~D ₇	CIN	Ta=25°C,	_	7	10		7	10	-	7	10	pr
Output Capacitance	A _o ~A ₁₅ , R/W, BA, BS	Cout	f=1MHz	-	-	12	-	-	12	-	-	12	pF

^{*}Ta=25°C, V_{CC}=5V



• AC CHARACTERISTICS (V_{CC} =5V \pm 5%, V_{SS} = 0V, Ta = -20 \sim +75 $^{\circ}$ C, unless otherwise noted.)

1. CLOCK TIMING

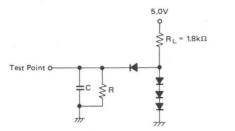
			н	1D680	9	Н	D68A	09	н	D68B0	09	
Item	Symbol	Test Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Frequency of Operation (Crystal or External Input)	fXTAL		0.4	-	4	0.4	-	6	0.4	-	8	MHz
Cycle Time	t _{cyc}		1000	-	10000	667	-	10000	500	-	10000	ns
Total Up Time	tur		975	-	-	640	-	-	480	-	-	ns
Processor Clock "High"	tpweh	1	450	-	15500	280	_	15700	220	-	15700	ns
Processor Clock "Low"	t _{PWEL}	1	430	-	5000	280	_	5000	210	-	5000	ns
E Rise and Fall Time	t _{Er} , t _{Ef}	Fig. 2, Fig. 3	-	-	25	-	-	25	-	-	20	ns
E _{Low} to Q _{High} Time	t _{AVS}		200	-	250	130	-	165	80	-	125	ns
Q Clock "High"	tpwQH		450	-	5000	280	-	5000	220	-	5000	ns
Q Clock "Low"	tpWQL	1	450	-	15500	280	-	15700	220	-	15700	ns
Q Rise and Fall Time	tar, taf		-	-	25	-	-	25	-	-	20	ns
Q _{Low} to E Falling	tae		200	-	-	133	-	_	100	-	-	ns

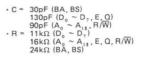
2. BUS TIMING

Item		Symbol	Symbol Test Condition	HD6809		HD68A09		HD68B09			Unit		
				min	typ	max	min	typ	max	min	typ	max	Oiii
Address Delay		t _{AD}		_	-	200	-	_	140	_	_	110	ns
Address Valid to Q _{High}		tAQ	Fig. 2, Fig. 3	50	-	-	25	-	_	15	-	-	ns
Peripheral Read Access Time (tut-tad-tdsR=tacc)		tACC		695	-	-	440	-	-	330	-	-	ns
Data Set Up Time (Read)		tDSR		80	-	_	60	-	-	40	-	_	ns
Input Data Hold Time		tDHR		10	-	-	10	-	-	10	-	-	ns
Address Hold Time	A - A - B/W		Fig. 2, Fig. 3 Ta=0~+75°C	20	-	-	20	-	-	20	-	-	ns
	A ₀ ~A ₁₅ , R/W	tAH	Fig. 2, Fig. 3 Ta=-20~0°C	10	-	-	10	-	-	10	-	-	ns
Data Delay Time (Write)		tDDW	Fig. 3	i —	-	200	-	-	140	-	-	110	ns
Output Hold Time		Hold Time t _{DHW}	Fig. 3 Ta=0~+75°C	30	-	-	30	-	-	30	-	-	ns
			Fig. 3 Ta=-20~0°C	20	-	-	20	-	-	20	-	-	ns

3. PROCESSOR CONTROL TIMING

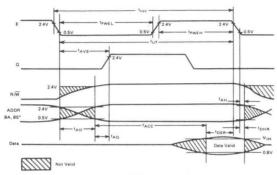
Item	Symbol	Test Condition	HD6809		HD68A09			HD68B09			Unit	
Item	Symbol	rest Condition	min	typ	max	min	typ	max	min	typ	max	Unit
MRDY Set Up Time	tPCSM		125	-	-	125	-	_	110	_	-	ns
Interrupts Set Up Time	tPCS		200	_	_	140	-	_	110	_	_	ns
HALT Set Up Time	tPCSH		200	-	_	140	_	_	110	_	_	ns
RES Set Up Time	tPCSR		200	_	-	140	_	-	110	_	_	ns
DMA/BREQ Set Up Time	tPCSD	Fig. 14, Fig. 15	125	-	-	125	-	-	110	-	-	ns
Processor Control Rise and Fall Time	tPCr, tPCf		-	-	100	-	-	100	-	-	100	ns
Crystal Oscillator Start Time	tRC		-	-	50	-	-	30	-	_	30	ms





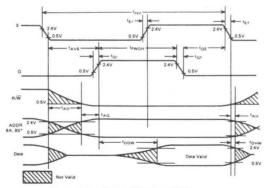
All diodes are 1S2074 or equivalent. C includes Stray Capacitance.

Figure 1 Bus Timing Test Load



*Hold time for BA, BS not specified.

Figure 2 Read Data from Memory or Peripherals



*Hold time for BA, BS not specified.

Figure 3 Write Data to Memory or Peripherals

■ PROGRAMMING MODEL

As shown in Figure 4, the HD6809 adds three registers to the set available in the HD6800. The added registers include a Direct Page Register, the User Stack pointer and a second Index Register.

Accumulators (A, B, D)

The A and B registers are general purpose accumulators which are used for arithmetic calculations and manipulation of data.

Certain instructions concatenate the A and B registers to form a single 16-bit accumulator. This is referred to as the $D\,$

register, and is formed with the A register as the most significant byte.

Direct Page Register (DP)

The Direct Page Register of the HD6809 serves to enhance the Direct Addressing Mode. The content of this register appears at the higher address outputs $(A_8 \sim A_{15})$ during Direct Addressing Instruction execution. This allows the direct mode to be used at any place in memory, under program control. To ensure HD6800 compatibility, all bits of this register are cleared during Processor Reset.

Index Registers (X, Y)

The Index Registers are used in indexed mode of addressing. The 16-bit address in this register takes part in the calculation of effective addresses. This address may be used to point to data directly or may be modified by an optional constant or register

offset. During some indexed modes, the contents of the index register are incremented or decremented to point to the next item of tabular type data. All four pointer registers (X, Y, U, S) may be used as index registers.

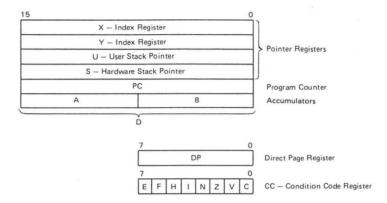


Figure 4 Programming Model of The Microprocessing Unit

Stack Pointer (U, S)

The Hardware Stack Pointer (S) is used automatically by the processor during subroutine calls and interrupts. The stack pointers of the HD6809 point to the top of the stack, in contrast to the HD6800 stack pointer, which pointed to the next free location on the stack. The User Stack Pointer (U) is controlled exclusively by the programmer thus allowing arguments to be passed to and from subroutines with ease. Both Stack Pointers have the same indexed mode addressing capabilities as the X and Y registers, but also support Push and Pull instructions. This allows the HD6809 to be used efficiently as a stack processor, greatly enhancing its ability to support higher level languages and modular programming.

Program Counter

The Program Counter is used by the processor to point to the address of the next instruction to be executed by the processor. Relative Addressing is provided allowing the Program Counter to be used like an index register in some situations.

Condition Code Register

The Condition Code Register defines the State of the Processor at any given time. See Fig. 5.

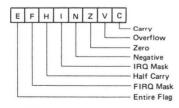


Figure 5 Condition Code Register Format

CONDITION CODE REGISTER DESCRIPTION

Bit 0 (C)

Bit 0 is the carry flag, and is usually the carry from the binary ALU. C is also used to represent a 'borrow' from subtract like instructions (CMP, NEG, SUB, SBC) and is the complement of the carry from the binary ALU.

Bit 1 (V)

Bit 1 is the overflow flag, and is set to a one by an operation which causes a signed two's complement arithmetic overflow. This overflow is detected in an operation in which the carry from the MSB in the ALU does not match the carry from the MSB-1.

Bit 2 (Z)

Bit 2 is the zero flag, and is set to a one if the result of the previous operation was identically zero.

Bit 3 (N)

Bit 3 is the negative flag, which contains exactly the value of the MSB of the result of the preceding operation. Thus, a negative two's-complement result will leave N set to a one.

Bit 4 (I)

Bit 4 is the IRQ mask bit. The processor will not recognize interrupts from the IRQ line if this bit is set to a one. NMI, FIRQ, IRQ, RES, and SWI all are set I to a one; SWI2 and SWI3 do not affect I.

Bit 5 (H)

Bit 5 is the half-carry bit, and is used to indicate a carry from bit 3 in the ALU as a result of an 8-bit addition only (ADC or ADD). This bit is used by the DAA instruction to perform a BCD decimal add adjust operation. The state of this flag is

undefined in all subtract-like instructions.

Bit 6 (F)

Bit 6 is the \overline{FIRQ} mask bit. The processor will not recognize interrupts from the \overline{FIRQ} line if this bit is a one. \overline{NMI} , \overline{FIRQ} , SWI, and \overline{RES} all set F to a one. \overline{IRQ} , SWI2 and SWI3 do not affect F.

Bit 7 (E)

Bit 7 is the entire flag, and when set to a one indicates that the complete machine state (all the registers) was stacked, as opposed to the subset state (PC and CC). The E bit of the stacked CC is used on a return from interrupt (RTI) to determine the extent of the unstacking. Therefore, the current E left in the Condition Code Register represents past action.

SIGNAL DESCRIPTION

Power (V_{SS}, V_{CC})

Two pins are used to supply power to the part: V_{SS} is ground or 0 volts, while V_{CC} is +5.0V ±5%.

Address Bus (A₀~A₁₅)

Sixteen pins are used to output address information from the MPU onto the Address Bus. When the processor does not require the bus for a data transfer, it will output address FFFF₁₆, R/\overline{W} = "High", and BS = "Low"; this is a "dummy access" or \overline{VMA} cycle. Addresses are valid on the rising edge of Q (see Figs. 2 and 3). All address bus drivers are made high impedance when output Bus Availalbe (BA) is "High". Each pin will drive one Schottky TTL load or four LS TTL loads, and typically 90 pF.

Data Bus (D₀∼D₇)

These eight pins provide communication with the system bi-directional data bus. Each pin will drive one Schottky TTL load or four LS TTL loads, and typically 130 pF.

■ Read/Write (R/W)

This signal indicates the direction of data transfer on the data bus. A "Low" indicates that the MPU is writing data onto the data bus. R/\overline{W} is made high impedance when BA is "High". R/\overline{W} is valid on the rising edge of Q. Refer to Figs. 2 and 3.

Reset (RES)

A "Low" level on this Schmitt-trigger input for greater than one bus cycle will reset the MPU, as shown in Fig. 6. The Reset vectors are fetched from locations FFFE₁₆ and FFFF₁₆ (Table 1) when Interrupt Acknowledge is true, (BA • BS=1). During initial power-on, the Reset line should be held "Low" until the clock oscillator is fully operational. See Fig. 7.

Because the HD6809 Reset pin has a Schmitt-trigger input with a threshold voltage higher than that of standard peripherals, a simple R/C network may be used to reset the entire system. This higher threshold voltage ensures that all peripherals are out

of the reset state before the Processor.

Table 1 Memory Map for Interrupt Vectors

	Map For ocations	Interrupt Vector			
MS	LS	Description			
FFFE	FFFF	RES			
FFFC	FFFD	NMI			
FFFA	FFFB	SWI			
FFF8	FFF9	IRQ			
FFF6	FFF7	FIRQ			
FFF4	FFF5	SW12			
FFF2	FFF3	SWI3			
FFF0	FFF1	Reserved			

• HALT

A "Low" level on this input pin will cause the MPU to stop running at the end of the present instruction and remain halted indefinitely without loss of data. When halted, the BA output is driven "High" indicating the buses are high impedance. BS is also "High" which indicates the processor is in the Halt or Bus Grant state. While halted, the MPU will not respond to external real-time requests (FIRQ, IRQ) although DMA/BREQ will always be accepted, and NMI or RES will be latched for later response. During the Halt state Q and E continue to run normally. If the MPU is not running (RES, DMA/BREQ), a halted state (BA·BS=1) can be achieved by pulling HALT "Low" while RES is still "Low". If DAM/BREQ and HALT are both pulled "Low", the processor will reach the last cycle of the instruction (by reverse cycle stealing) where the machine will then become halted. See Figs. 8 and 16.

Bus Available, Bus Status (BA, BS)

The BA output is an indication of an internal control signal which makes the MOS buses of the MPU high impedance. This signal does not imply that the bus will be available for more than one cycle. When BA goes "Low", an additional dead cycle will elapse before the MPU acquires the bus.

The BS output signal, when decoded with BA, represents the MPU state (valid with leading edge of Q).

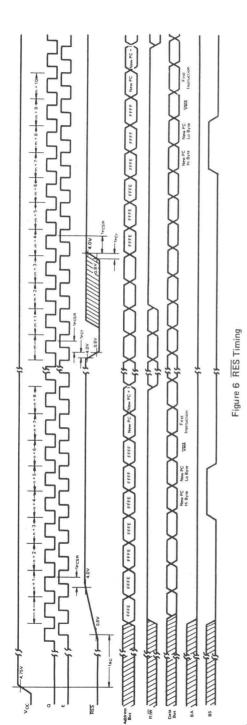
Table 2 MPU State Definition

ВА	BS	MPU State
0	0	Normal (Running)
0	1	Interrupt or RESET Acknowledge
1	0	SYNC Acknowledge
1	1	HALT or Bus Grant

Interrupt Acknowledge is indicated during both cycles of a hardware-vector-fetch (RES, NMI, FIRQ, IRQ, SWI, SWI2, SWI3). This signal, plus decoding of the lower four address lines, can provide the user with an indication of which interrupt level is being serviced and allow vectoring by device. See Table 1.

Sync Acknowledge is indicated while the MPU is waiting for external synchronization on an interrupt line.

Halt/Bus Grant is true when the HD6809 is in a Halt or Bus Grant condition.



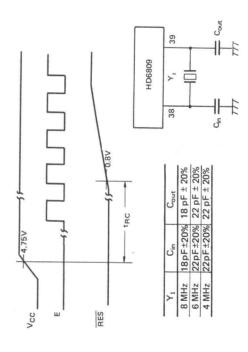


Figure 7 Crystal Connections and Oscillator Start Up

Non Maskable Interrupt (NMI)*

A negative edge on this input requests that a non-maskable interrupt sequence be generated. A non-maskable interrupt cannot be inhibited by the program, and also has a higher priority than $\overline{FIRQ}, \overline{IRQ}$ or software interrupts. During recognition of an $\overline{NMl},$ the entire machine state is saved on the

hardware stack. After reset, an \overline{NMI} will not be recognized until the first program load of the Hardware Stack Pointer (S). The pulse width of \overline{NMI} "Low" must be at least one E cycle. If the \overline{NMI} input does not meet the minimum set up with respect to Q, the interrupt will not be recognized until the next cycle. See Fig. 9.

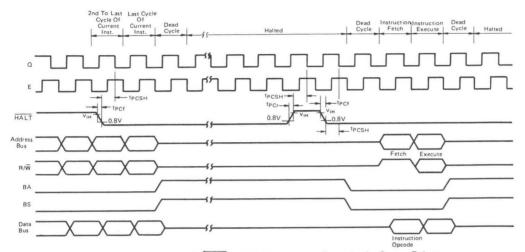


Figure 8 HALT and Single Instruction Execution for System Debug

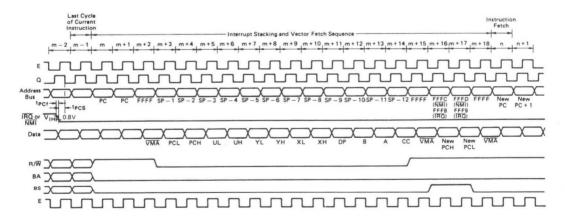


Figure 9 IRQ and NMI Interrupt Timing

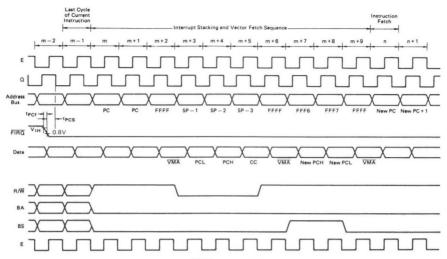


Figure 10 FIRQ Interrupt Timing

• Fast-Interrupt Request (FIRQ)*

A "Low" level on this input pin will initiate a fast interrupt sequence provided its mask bit (F) in the CC is clear. This sequence has priority over the standard Interrupt Request (IRQ), and is fast in the sense that it stacks only the contents of the condition code register and the program counter. The interrupt service routine should clear the source of the interrupt before doing an RTI. See Fig. 10.

Interrupt Request (IRQ)*

A "Low" level input on this pin will initiate an interrupt Request sequence provided the mask bit (I) in the CC is clear. Since \overline{IRQ} stacks the entire <u>machine</u> state it provides a slower response to interrupts than \overline{FIRQ} . \overline{IRQ} also has a lower priority than \overline{FIRQ} . Again, the interrupt service routine should clear the source of the interrupt before doing an RTI. See Fig. 9.

* NMI, FIRQ, and IRQ requests are sampled on the falling edge of Q. One cycle is required for synchronization before these interrupts are recognized. The pending interrupt(s) will not be serviced until completion of the current instruction unless a SYNC or CWAI condition is present. If IRQ and FIRQ do not remain "Low" until completion of the current instruction they may not be recognized. However, NMI is latched and need only remain "Low" for one cycle.

XTAL, EXTAL

These inputs are used to connect the on-chip oscillator to an external parallel-resonant crystal. Alternately, the pin EXTAL may be used as a TTL level input for external timing by grounding XTAL. The crystal or external frequency is four times the bus frequency. See Fig. 7. Proper RF layout techniques should be observed in the layout of printed circuit boards.

<NOTE FOR BOARD DESIGN OF THE OSCILLATION CIRCUIT>

In designing the board, the following notes should be taken when the crystal oscillator is used.

1) Crystal oscillator and load capacity Cin, Cout must be placed

near the LSI as much as possible.

Normal oscillation may be disturbed when external noise is induced to pin 38 and 39.

2) Pin 38 and 39 signal line should be wired apart from other signal line as much as possible. Don't wire them in parallel.

Normal oscillation may be disturbed when E or Q signal is feedbacked to pin 38 and 39.

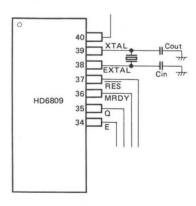


Figure 11 Board Design of the Oscillation Circuit.

<THE FOLLOWING DESIGN MUST BE AVOIDED>

A signal line or a power source line must not cross or go near the oscillation circuit line as shown in Fig. 12 to prevent the induction from these lines and perform the correct oscillation. The resistance among XTAL, EXTAL and other pins should be over $10M\Omega$.

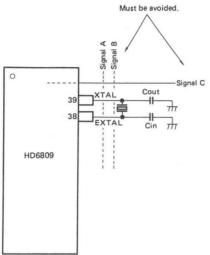


Figure 12 Example of Normal Oscillation may be Disturbed,

. E. Q

E is similar to the HD6800 bus timing signal ϕ_2 ; Q is a quadrature clock signal which leads E. Q has no parallel on the HD6800. Addresses from the MPU will be valid with the leading edge of Q. Data is latched on the falling edge of E. Timing for E and Q is shown in Fig. 13.

MRDY

This input control signal allows stretching of E and Q to extend data-access time. E and Q operate normally while MRDY is "High". When MRDY is "Low", E and Q may be stretched in integral multiples of quarter (1/4) bus cycles, thus allowing interface to slow memories, as shown in Fig. 14. A maximum

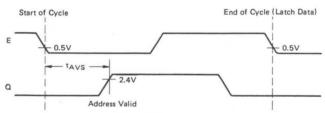


Figure 13 E/Q Relationship

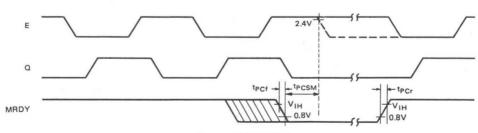


Figure 14 MRDY Timing



stretch is 10 microseconds. During nonvalid memory access (VMA cycles) MRDY has no effect on stretching E and Q; this inhibits slowing the processor during "don't care" bus accesses. MRDY may also be used to stretch clocks (for slow memory) when bus control has been transferred to an external device (through the use of HALT and DMA/BREQ).

Also MRDY has effect on stretching E and Q during Dead Cycle.

DMA/BREQ

The DMA/BREQ input provides a method of suspending execution and acquiring the MPU bus for another use, as shown in Fig. 15. Typical uses include DMA and dynamic memory refresh.

Transition of DMA/BREQ should occur during Q. A "Low" level on this pin will stop instruction execution at the end of the current cycle. The MPU will acknowledge DMA/BREQ by setting BA and BS to "High" level. The requesting device will now have up to 15 bus cycles before the MPU retrieves the bus for self-refresh. Self-refresh requires one bus cycle with a lead-

ing and trailing dead cycle, See Fig. 16.

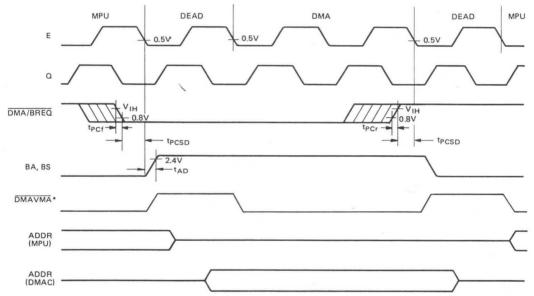
Typically, the DMA controller will request to use the bus by asserting DMA/BREQ pin "Low" on the leading edge of E. When the MPU replies by setting BA and BS to a one, that cycle will be a dead cycle used to transfer bus mastership to the DMA controller.

False memory accesses may be prevented during and dead cycles by developing a system DMAVMA signal which is "Low" in any cycle when BA has changed.

When BA goes "Low" (either as a result of DMA/BREQ = "High" or MPU self-refresh), the DMA device should be taken off the bus. Another dead cycle will elapse before the MPU accesses memory, to allow transfer of bus mastership without contention.

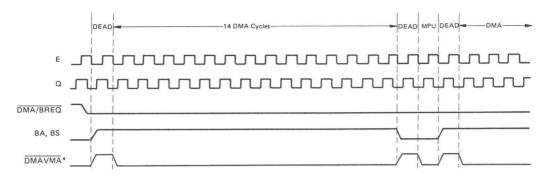
■ MPU OPERATION

During normal operation, the MPU fetches an instruction from memory and then executes the requested function. This



*DMAVMA is a signal which is developed externally, but is a system requirement for DMA.

Figure 15 Typical DMA Timing (<14 Cycles)



*DMAVMA is a signal which is developed externally, but is a system requirement for DMA.

Figure 16 Auto - Refresh DMA Timing (Reverse Cycle Stealing)

sequence begins at RES and is repeated indefinitely unless altered by a special instruction or hardware occurrence. Software instructions that alter normal MPU operation are: SWI, SWI2, SWI3, CWAI, RTI and SYNC. An interrupt, HALT or DMA/BREQ can also alter the normal execution of instructions. Fig. 17 illustrates the flow chart for the HD6809.

ADDRESSING MODES

The basic instructions of any computer are greatly enhanced by the presence of powerful addressing modes. The HD6809 has the most complete set of addressing modes available on any microcomputer today. For example, the HD6809 has 59 basic instructions; however, it recognizes 1464 different variations of instructions and addressing modes. The addressing modes support modern programming techniques. The following addressing modes are available on the HD6809:

- (1) Implied (Includes Accumulator)
- (2) Immediate
- (3) Extended
- (4) Extended Indirect
- (5) Direct
- (6) Register
- (7) Indexed

Zero-Offset

Constant Offset

Accumulator Offset

Auto Increment/Decrement

- (8) Indexed Indirect
- (9) Relative
- (10) Program Counter Relative

Implied (Includes Accumulator)

In this addressing mode, the opcode of the instruction contains all the address information necessary. Examples of Implied Addressing are: ABX, DAA, SWI, ASRA, and CLRB.

Immediate Addressing

In Immediate Addressing, the effective address of the data is the location immediately following the opcode (i.e., the data to be used in the instruction immediately follows the opcode of the instruction). The HD6809 uses both 8 and 16-bit immediate values depending on the size of argument specified by the opcode. Examples of instructions with Immediate Addressing are:

LDA #\$20

LDX #\$F000

LDY #CAT

(NOTE) # signifies Immediate addressing, \$ signifies hexadecimal value.

Extended Addressing

In Extended Addressing, the contents of the two bytes immediately following the opcode fully specify the 16-bit effective address used by the instruction. Note that the address generated by an extended instruction defines an absolute address and is not position independent. Examples of Extended Addressing include:

LDA CAT

STX MOUSE

LDD \$2000

Extended Indirect

As a special case of indexed addressing (discussed below), "1" level of indirection may be added to Extended Addressing. In Extended Indirect, the two bytes following the postbyte of an Indexed instruction contain the address of the data.

LDA [CAT]

LDX [SFFFE]

[DOG] STU

Direct Addressing

Direct addressing is similar to extended addressing except that only one byte of address follows the opcode. This byte specifies the lower 8-bit of the address to be used. The upper 8-bit of the address are supplied by the direct page register. Since only one byte of address is required in direct addressing, this mode requires less memory and executes faster than extended addressing. Of course, only 256 locations (one page) can be

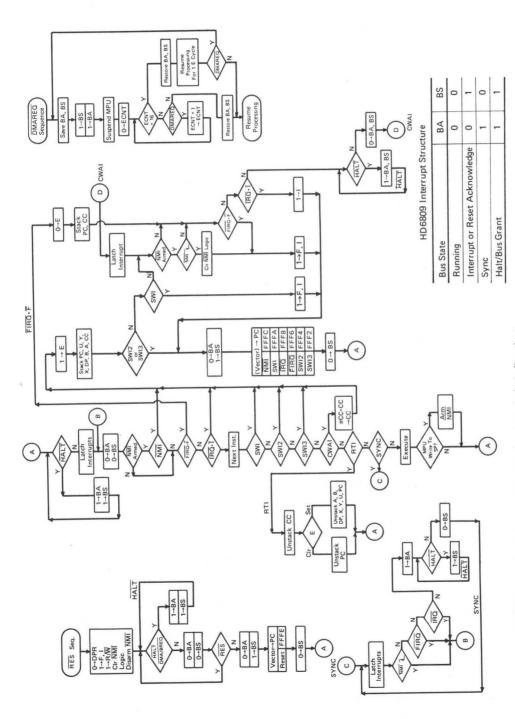


Figure 17 Flowchart for HD6809 Instruction (NOTE) Asserting RES will result in entering the reset sequence from any point in the flow chart.

accessed without redefining the contents of the DP register. Since the DP register is set to \$00 on Reset, direct addressing on the HD6809 is compatible with direct addressing on the HD6800. Indirection is not allowed in direct addressing. Some examples of direct addressing are:

LDA \$30

SETDP \$10 (Assembler directive)

LDB \$1030 LDD <CAT

(NOTE) < is an assembler directive which forces direct addressing.

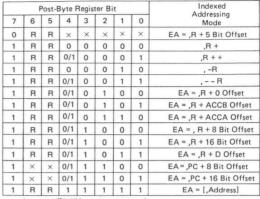
Register Addressing

Some opcodes are followed by a byte that defines a register or set of registers to be used by the instruction. This is called a postbyte. Some examples of register addressing are:

TFR X, Y Transfers X into Y
EXG A, B Exchanges A with B
PSHS A, B, X, Y Push Y, X, B and A onto S
PULU X, Y, D Pull D, X, and Y from U

Indexed Addressing

In all indexed addressing, one of the pointer registers (X, Y, U, S, and sometimes PC) is used in a calculation of the effective address of the operand to be used by the instruction. Five basic types of indexing are available and are discussed below. The postbyte of an indexed instruction specifies the basic type and variation of the addressing mode as well as the pointer register to be used. Fig. 18 lists the legal formats for the postbyte. Table 3 gives the assembler form and the number of cycles and bytes



Addressing Mode Field

Indirect Field
(Sigh bit when b7 = 0)
0 Non Indirect
1 Indirect
1 Indirect
Register Field : RR
00 = X
01 = Y
10 = U
11 = S

× = Don't Care

Figure 18 Index Addressing Postbyte Register Bit Assignments

Table 3 Indexed Addressing Mode

		N	on Indirect	Indirect					
Туре	Forms	Assembler Form	Postbyte OP Code	+ ~	+ #	Assembler Form	Postbyte OP Code	+ ~	+ #
Constant Offset From R	No Offset	,R	1RR00100	0	0	[,R]	1RR10100	3	0
(2's Complement Offsets)	5 Bit Offset	n, R ORRnnnn		1	0	defaults to 8-bit			
	8 Bit Offset	n, R	1RR01000	1	1	[n, R]	1RR11000	4	1
	16 Bit Offset	n, R	1RR01001	4	2	[n, R]	1RR11001	7	2
Accumulator Offset From R	A Register Offset	A, R	1RR00110	1	0	[A, R]	1RR10110	4	0
(2's Complement Offsets)	B Register Offset	B, R	1RR00101	1	0	[B, R]	1RR10101	4	0
	D Register Offset	D, R	1RR01011	4	0	[D, R]	1RR11011	7	0
Auto Increment/Decrement R	Increment By 1	,R +	1RR00000	2	0	not	allowed		
	Increment By 2	,R ++	1RR00001	3	0	[,R++]	1RR10001	6	0
	Decrement By 1	, - R	1RR00010	2	0	not allowed			
	Decrement By 2	, R	1RR00011	3	0	[,R]	1RR10011	6	0
Constant Offset From PC	8 Bit Offset	n, PCR	1××01100	1	1	[n, PCR]	1xx11100	4	1
(2's Complement Offsets)	16 Bit Offset	n, PCR	1××01101	5	2	[n, PCR]	1××11101	8	2
Extended Indirect	16 Bit Address	-	_	-	-	[n]	10011111	5	2

R = X, Y, U or S

RR:

× = Don't Care

00 = X 01 = Y

01 = Y 10 = U

11 = S

 $[\]stackrel{+}{\sim}$ and $\stackrel{+}{\#}$ indicate the number of additional cycles and bytes for the particular variation.

added to the basic values for indexed addressing for each variation.

Zero-Offset Indexed

In this mode, the selected pointer register contains the effective address of the data to be used by the instruction. This is the fastest indexing mode.

Examples are: LDD 0,X LDA S

Constant Offset Indexed

In this mode, a two's-complement offset and the contents of one of the pointer registers are added to form the effective address of the operand. The pointer register's initial content is unchanged by the addition.

Three sizes of offsets are available:

5-bit (-16 to +15) 8-bit (-128 to +127) 16-bit (-32768 to +32767)

The two's complement 5-bit offset is included in the postbyte and, therefore, is most efficient in use of bytes and cycles. The two's complement 8-bit offset is contained in a single byte following the postbyte. The two's complement 16-bit offset is in the two bytes following the postbyte. In most cases the programmer need not be concerned with the size of this offset since the assembler will select the optimal size automatically.

Examples of constant-offset indexing are:

LDA 23,X LDX -2,S LDY 300,X LDU CAT,Y

Accumulator-Offset Indexed

This mode is similar to constant offset indexed except that the two's-complement value in one of the accumulators (A, B or D) and the contents of one of the pointer registers are added to form the effective address of the operand. The contents of both the accumulator and the pointer register are unchanged by the addition. The postbyte specifies which accumulator to use as an offset and no additional bytes are required. The advantage of an accumulator offset is that the value of the offset can be calculated by a program at run-time.

Some examples are:

LDA B,Y LDX D,Y LEAX B,X

Auto Increment/Decrement Indexed

In the auto increment addressing mode, the pointer register contains the address of the operand. Then, after the pointer register is used it is incremented by one or two. This addressing mode is useful in stepping through tables, moving data, or for the creation of software stacks. In auto decrement, the pointer register is decremented prior to use as the address of the data. The use of auto decrement is similar to that of auto increment; but the tables, etc., are scanned from the "High" to "Low" addresses. The size of the increment/decrement can be either one or two to allow for tables of either 8 or 16-bit data to be accessed and is selectable by the programmer. The predecrement, post-increment nature of these modes allow them to be used to create additional software stacks that behave identically to the U and S stacks.

Some examples of the auto increment/decrement addressing modes are:

S are: LDA ,X+ STD ,Y++ LDB ,-Y LDX ,--S

Care should be taken in performing operations on 16-bit pointer registers (X, Y, U, S) where the same register is used to calculate the effective address.

Consider the following instruction:

STX 0, X + + (X initialized to 0)

The desired result is to store a 0 in locations \$0000 and \$0001 then increment X to point to \$0002. In reality, the following occurs:

0 → temp calculate the EA; temp is a holding register X + 2 → X perform autoincrement X → (temp) do store operation

Indexed Indirect

All of the indexing modes with the exception of auto increment/decrement by one, or a ±4-bit offset may have an additional level of indirection specified. In indirect addressing, the effective address is contained at the location specified by the contents of the Index register plus any offset. In the example below, the A accumulator is loaded indirectly using an effective address calculated from the Index register and an offset.

Before Execution
A = ×× (don't care)
X = \$F000
\$0100 LDA [\$10,X] EA is now \$F010
\$F010 \$F1 \$F150 is now the new EA

\$F150 \$AA

After Execution

A = \$AA Actual Data Loaded

X = F000

All modes of indexed indirect are included except those which are meaningless (e.g., auto increment/decrement by 1 indirect). Some examples of indexed indirect are:

LDA [,X] LDD [10,S] LDA [B,Y] LDD [,X++]

Relative Addressing

The byte(s) following the branch opcode is (are) treated as a signed offset which may be added to the program counter. If the branch condition is true then the calculated address (PC + signed offset) is loaded into the program counter. Program execution continues at the new location as indicated by the PC; short (1 byte offset) and long (2 bytes offset) relative addressing modes are available. All of memory can be reached in long relative addressing as an effective address is interpreted modulo 2^{16} . Some examples of relative addressing are:

	BEQ	CAT	(short)
	BGT	DOG	(short)
CAT	LBEQ	RAT	(long)
DOG	LBGT	RABBIT	(long)

RAT NOP RABBIT NOP

• Program Counter Relative

The PC can be used as the pointer register with 8 or 16-bit signed offsets. As in relative addressing, the offset is added to the current PC to create the effective address. The effective address is then used as the address of the operand or data. Program Counter Relative Addressing is used for writing position independent programs. Tables related to a particular routine will maintain the same relationship after the routine is moved, if referenced relative to the Program Counter. Examples are:

LDA CAT, PCR LEAX TABLE, PCR

Since program counter relative is a type of indexing, an additional level of indirection is available.

LDA [CAT, PCR] LDU [DOG, PCR]

■ HD6809 INSTRUCTION SET

The instruction set of the HD6809 is similar to that of the HD6800 and is upward compatible at the source code level. The number of opcodes has been reduced from 72 to 59, but because of the expanded architecture and additional addressing modes, the number of available opcodes (with different addressing modes) has risen from 197 to 1464.

Some of the new instructions and addressing modes are described in detail below:

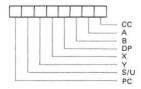
PSHU/PSHS

The push instructions have the capability of pushing onto either the hardware stack (S) or user stack (U) any single register, or set of registers with a single instruction.

PULU/PULS

The pull instructions have the same capability of the push instruction, in reverse order. The byte immediately following the push or pull opcode determines which register or registers are to be pushed or pulled. The actual PUSH/PULL sequence is fixed; each bit defines a unique register to push or pull, as shown in below.





●TFR/EXG

Within the HD6809, any register may be transferred to or exchanged with another of like-size; i.e., 8-bit to 8-bit or 16-bit to 16-bit. Bits 4-7 of postbyte define the source register, while bits 0-3 represent the destination register. Three are denoted as follows:

0000 - D	0101 - PC
0001 - X	1000 - A
0010 - Y	1001 - B
0011 - U	1010 - CC
0100 - S	1011 - DP

(NOTE) All other combinations are undefined and INVALID.

TRANSFER/EXCHANGE POST BYTE

DESTINATION

LEAX/LEAY/LEAU/LEAS

The LEA (Load Effective Address) works by calculating the effective address used in an indexed instruction and stores that address value, rather than the data at that address, in a pointer register. This makes all the features of the internal addressing hardware available to the programmer. Some of the implications of this instruction are illustrated in Table 4.

The LEA instruction also allows the user to access data in a position independent manner, For example:

LEAX MSG1, PCR
LBSR PDATA (Print message routine)

MSG1 FCC 'MESSAGE'

This sample program prints: 'MESSAGE'. By writing MSG1, PCR, the assembler computes the distance between the present address and MSG1. This result is placed as a constant into the LEAX instruction which will be indexed from the PC value at the time of execution. No matter where the code is located, when it is executed, the computed offset from the PC will put the absolute address of MSG1 into the X pointer register. This code is totally position independent.

The LEA instructions are very powerful and use an internal holding register (temp). Care must be exercised when using the LEA instructions with the autoincrement and autodecrement addressing modes due to the sequence of internal operations. The LEA internal sequence is outlined as follows:

LEAa, b+ (any of the 16-bit pointer registers X, Y, U or S may be substituted for a and b.)

1. b → temp (calculate the EA)

2. $b + 1 \rightarrow b$ (modify b, postincrement)

3. temp \rightarrow a (load a)

LEAa, -b

1. $b-1 \rightarrow temp$ (calculate EA with predecrement)

2. $b-1 \rightarrow b$ (modify b, predecrement)

3. $temp \rightarrow a$ (load a)

Autoincrement-by-two and autodecrement-by-two instructions work similarly. Note that LEAX, X+ does not change X, however LEAX, -X does decrement X. LEAX 1, X should be used to increment X by one.

Table 4 LEA Examples

Instruction	Operation	Comment
LEAX 10, X LEAX 500, X LEAY A, Y LEAY D, Y LEAU -10, U LEAS -10, S LEAS 10, S	$\begin{array}{c} X+10 \rightarrow X \\ X+500 \rightarrow X \\ Y+A \rightarrow Y \\ Y+D \rightarrow Y \\ U-10 \rightarrow U \\ S-10 \rightarrow S \\ S+10 \rightarrow S \end{array}$	Adds 5-bit constant 10 to X Adds 16-bit constant 500 to X Adds 8-bit accumulator to Y Adds 16-bit D accumulator to Y Subtracts 10 from U Used to reserve area on stack Used to 'clean up' stack
LEAX 5, S.	$S+5 \rightarrow X$	Transfers as well as adds

• MUL

Multiplies the unsigned binary numbers in the A and B accumulator and places the unsigned result into the 16-bit D accumulator. This unsigned multiply also allows multiple-precision multiplications.

Long And Short Relative Branches

The HD6809 has the capability of program counter relative branching throughout the entire memory map. In this mode, if the branch is to be taken, the 8 or 16-bit signed offset is added to the value of the program counter to be used as the effective address. This allows the program to branch anywhere in the 64k memory map. Position independent code can be easily generated through the use of relative branching. Both short (8-bit) and long (16-bit) branches are available.

SYNC

After encountering a Sync instruction, the MPU enters a Sync state, stops processing instructions and waits for an interrupt. If the pending interrupt is non-maskable (NMI) or maskable (FIRQ, IRQ) with its mask bit (F or I) clear, the processor will clear the Syne state and perform the normal interrupt stacking and service routine. Since FIRQ and IRQ are not edge-triggered, a "Low" level with a minimum duration of three bus cycles is required to assure that the interrupt will be taken. If the pending interrupt is maskable (FIRQ, IRQ) with its mask bit (F or I) set, the processor will clear the Sync state and continue processing by executing the next inline instruction. Fig. 19 depicts Sync timing.

Software Interrupts

A Software Interrupt is an instruction which will cause an interrupt, and its associated vector fetch. These Software Interrupts are useful in operating system calls, software debugging, trace operations, memory mapping, and software development systems. Three levels of SWI are available on this HD6809, and are prioritized in the following order: SWI, SWI2, SWI3.

16-Bit Operation

The HD6809 has the capability of processing 16-bit data. These instructions include loads, stores, compares, adds, subtracts, transfers, exchanges, pushes and pulls.

■ CYCLE-BY-CYCLE OPERATION

The address bus cycle-by-cycle performance chart illustrates the memory-access sequence corresponding to each possible instruction and addressing mode in the HD6809. Each instruction begins with an opcode fetch. While that opcode is being internally decoded, the next program byte is always fetched. (Most instructions will use the next byte, so this technique considerably speeds throughput.) Next, the operation of each opcode will follow the flow chart. VMA is an indication of

 $FFFF_{16}$ on the address bus, R/\overline{W} ="High" and BS="Low". The following examples illustrate the use of the chart; see Fig. 20.

Example 1: LBSR (Branch Taken)
Before Execution SP = F000

\$8000

\$A000	CAT			
		CYCLE	E-BY-CY	CLE FLOW
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	17	1	Opcode Fetch
2	8001	1F	1	Offset High Byte
3	8002	FD	1	Offset Low Byte
4	FFFF	*	1	VMA Cycle
5	FFFF	*	1	VMA Cycle
6	A000	*	1	Computed Branch
				Address
7	FFFF	*	1	VMA Cycle
8	EFFF	03	0	Stack Low Order

LBSR

CAT

Byte of Return Address

Stack High Order

Byte of Return

Address

Example 2: DEC (Extended)

EFFE

\$8000	DEC	\$A000
\$A000	FCB	\$80
	0110	

CYCLE-BY-CYCLE FLOW

0

Cycle #	Address	Data	R/\overline{W}	Description
1	8000	7A	1	Opcode Fetch
2	8001	A0	1	Operand Address, High Byte
3	8002	00	1	Operand Address, Low Byte
4	FFFF	*	1	VMA Cycle
5	A000	80	1	Read the Data
6	FFFF	*	1	VMA Cycle
7	A000	7F	0	Store the Decre- mented Data

^{*} The data bus has the data at that particular address.

■ HD6809 INSTRUCTION SET TABLES

The instructions of the HD6809 have been broken down into five different categories. They are as follows:

8-Bit operation (Table 5)

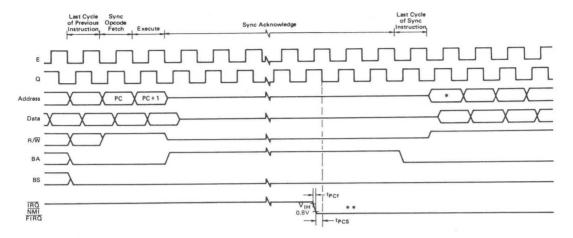
16-Bit operation (Table 6)

Index register/stack pointer instructions (Table 7)

Relative branches (long or short) (Table 8)

Miscellaneous instructions (Table 9)

HD6809 instruction set tables and Hexadecimal Values of instructions are shown in Table 10 and Table 11.

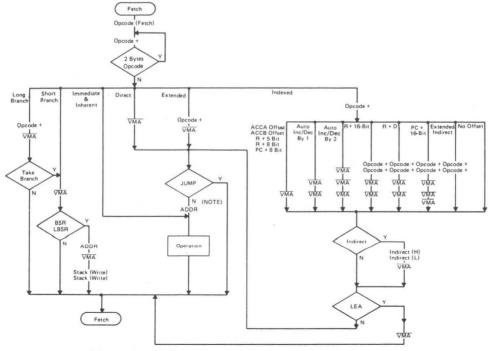


- (NOTES) ★ If the associated mask bit is set when the interrupt is requested, this cycle will be an instruction fetch from address location PC + 1.

 However, if the interrupt is accepted (NMI) or an unmasked FIRQ or IRQ) interrupt processing continues with this cycle as (m) on Figure 9 and 10 (Interrupt Timing).

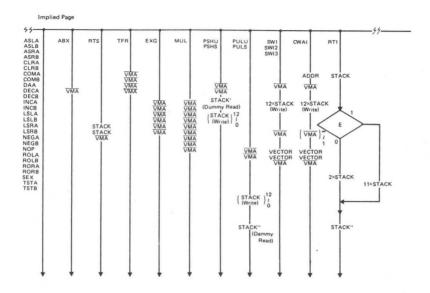
 ★ If mask bits are clear, IRQ and FIRQ must be held "Low" for three cycles to guarantee that interrupt will be taken, although only one cycle is necessary to bring the processor out of SYNC.

Figure 19 Sync Timing



(NOTE) Write operation during store instruction.

Figure 20 Address Bus Cycle-by-Cycle Performance



(NOTE) STACK': Address stored in stack pointer before execution.
STACK'': Address set to stack pointer as the result of the execution.

Figure 20 Address Bus Cycle-by-Cycle Performance (Continued)

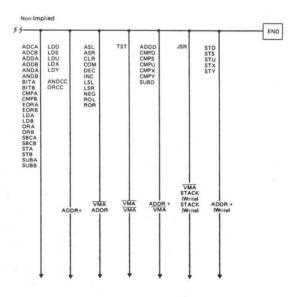


Figure 20 Address Bus Cycle-by-Cycle Performance (Continued)

Table 5 8-Bit Accumulator and Memory Instructions

Mnemonic(s)	Operation
ADCA, ADCB	Add memory to accumulator with carry
ADDA, ADDB	Add memory to accumulator
ANDA, ANDB	And memory with accumulator
ASL, ASLA, ASLB	Arithmetic shift of accumulator or memory left
ASR, ASRA, ASRB	Arithmetic shift of accumulator or memory right
BITA, BITB	Bit test memory with accumulator
CLR, CLRA, CLRB	Clear accumulator or memory location
CMPA, CMPB	Compare memory from accumulator
COM, COMA, COMB	Complement accumultor or memory location
DAA	Decimal adjust A accumulator
DEC, DECA, DECB	Decrement accumulator or memory location
EORA, EORB	Exclusive or memory with accumulator
EXG R1, R2	Exchange R1 with R2 (R1, R2 = A, B, CC, DP)
INC, INCA, INCB	Increment accumulator or memory location
LDA, LDB	Load accumulator from memory
LSL, LSLA, LSLB	Logical shift left accumulator or memory location
LSR, LSRA, LSRB	Logical shift right accumulator or memory location
MUL	Unsigned multiply $(A \times B \rightarrow D)$
NEG, NEGA, NEGB	Negate accumulator or memory
ORA, ORB	Or memory with accumulator
ROL, ROLA, ROLB	Rotate accumulator or memory left
ROR, RORA, RORB	Rotate accumulator or memory right
SBCA, SBCB	Subtract memory from accumulator with borrow
STA, STB	Store accumulator to memory
SUBA, SUBB	Subtract memory from accumulator
TST, TSTA, TSTB	Test accumulator or memory location
TFR R1, R2	Transfer R1 to R2 (R1, R2 = A, B, CC, DP)

(NOTE) A, B, CC or DP may be pushed to (pulled from) either stack with PSHS, PSHU (PULS, PULU) instructions.

Table 6 16-Bit Accumulator and Memory Instructions

Mnemonic(s)	Operation	
ADDD	Add memory to D accumulator	
CMPD	Compare memory from D accumulator	
EXG D, R	Exchange D with X, Y, S, U or PC	
LDD	Load D accumulator from memory	
SEX	Sign Extend B accumulator into A accumulator	
STD	Store D accumulator to memory	
SUBD	Subtract memory from D accumulator	
TFR D, R	Transfer D to X, Y, S, U or PC	
TFR R, D	Transfer X, Y, S, U or PC to D	

(NOTE) D may be pushed (pulled) to either stack with PSHS, PSHU (PULS, PULU) instructions.



Table 7 Index Register/Stack Pointer Instructions

Mnemonic(s)	Operation	
CMPS, CMPU	Compare memory from stack pointer	
CMPX, CMPY	Compare memory from index register	
EXG R1, R2	Exchange D, X, Y, S, U or PC with D, X, Y, S, U or PC	
LEAS, LEAU	Load effective address into stack pointer	
LEAX, LEAY	Load effective address into index register	
LDS, LDU	Load stack pointer from memory	
LDX, LDY	Load index register from memory	
PSHS	Push A, B, CC, DP, D, X, Y, U, or PC onto hardware stack	
PSHU	Push A, B, CC, DP, D, X, Y, S, or PC onto user stack	
PULS	Pull A, B, CC, DP, D, X, Y, U or PC from hardware stack	
PULU	Pull A, B, CC, DP, D, X, Y, S or PC from user stack	
STS, STU	Store stack pointer to memory	
STX, STY	Store index register to memory	
TFR R1, R2	Transfer D, X, Y, S, U or PC to D, X, Y, S, U or PC	-
ABX	Add B accumulator to X (unsigned)	

Table 8 Branch Instructions

Mnemonic(s)	Operation
	SIMPLE BRANCHES
BEQ, LBEQ	Branch if equal
BNE, LBNE	Branch if not equal
BMI, LBMI	Branch if minus
BPL, LBPL	Branch if plus
BCS, LBCS	Branch if carry set
BCC, LBCC	Branch if carry clear
BVS, LBVS	Branch if overflow set
BVC, LBVC	Branch if overflow clear
	SIGNED BRANCHES
BGT, LBGT	Branch if greater (signed)
BGE, LBGE	Branch if greater than or equal (signed)
BEQ, LBEQ	Branch if equal
BLE, LBLE	Branch if less than or equal (signed)
BLT, LBLT	Branch if less than (signed)
	UNSIGNED BRANCHES
BHI, LBHI	Branch if higher (unsigned)
BHS, LBHS	Branch if higher or same (unsigned)
BEQ, LBEQ	Branch if equal
BLS, LBLS	Branch if lower or same (unsigned)
BLO, LBLO	Branch if lower (unsigned)
	OTHER BRANCHES
BSR, LBSR	Branch to subroutine
BRA, LBRA	Branch always
BRN, LBRN	Branch never

Table 9 Miscellaneous Instructions

Mnemonic(s)	Operation	
ANDCC	AND condition code register	
CWAI	AND condition code register, then wait for interrupt	
NOP	No operation	
ORCC	OR condition code register	
JMP	Jump	1110000
JSR	Jump to subroutine	
RTI	Return from interrupt	
RTS	Return from subroutine	
SWI, SWI2, SWI3	Software interrupt (absolute indirect)	
SYNC	Synchronize with interrupt line	

Table 10 HD6809 Instruction Set Table

INSTE	UCTION/							D680	9 AE	DR	ESSIN	IG M	ODE	-											_
	DRMS	-	MPL	1	-	IREC		-	TEN	T	-	EDI	_	+	DEX	1	-	LATI	_	DESCRIPTION	5	3	2	1	I
4 D.:		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~3	#		Н	N	Z	٧	+
ABX	ADCA	3A	3	1	99	4	2	B9	5	3	89	2	2	A9	4+	2+				B + X → X (UNSIGNED) A + M + C → A	•	•	•	•	
ADD	ADCB ADDA				D9 9B	4	2	F9 BB	5	3	C9 8B	2	2	E9 AB	4+	2+				$B + M + C \rightarrow B$ $A + M \rightarrow A$	1	‡ ±	‡	1	
	ADDB ADDD				DB D3	6	2 2	FB F3	5	3	CB C3	2	2	EB E3	4+ 6+	2+ 2+				$B + M \rightarrow B$ D + M:M + 1 \rightarrow D	:	‡	‡	‡	
AND	ANDA ANDB ANDCC				94 D4	4 4	2 2	B4 F4	5	3	84 C4 1C	2 2 3	2 2 2	A4 E4	4+ 4+	2+ 2+				$A \wedge M \rightarrow A$ $B \wedge M \rightarrow B$ $CC \wedge IMM \rightarrow CC$	• (-	‡	‡ ‡	0	-
ASL	ASLA ASLB ASL	48 58	2 2	1	08	6	2	78	7	3				68	6+	2+				A B M	888	‡ ‡	‡ ‡	‡ ‡	
ASR	ASRA ASRB ASR	47 57	2 2	1	07	6	2	77	7	3				67	6+	2+				A B M	8 8 8	‡	‡		
всс	BCC LBCC				0,		_	''	ĺ	3				07	01	21	24	3 5(6)	2 4	Branch C = 0 Long Branch	•	•			
BCS	BCS LBCS																24 25 10	3 5(6)	2 4	C = 0 Branch C = 1 Long Branch			•		
BEQ	BEQ LBEQ																25 27 10 27	3 5(6)	2 4	C = 1 Branch Z = 1 Long Branch					
BGE	BGE LBGE																2C 10 2C	3 5(6)	2 4	Z = 1 Branch N⊕V=0 Long Branch N⊕V=0		•			
BGT	BGT LBGT																2E 10	3 5(6)	2 4	Branch Z√(N⊕V)=0 Long Branch		•	•		
вні	BHI LBHI																2E 22 10	3 5(6)	2 4	Z∨(N⊕V)=0 Branch C∨Z=0 Long Branch	:	•	•		
BHS	BHS																22	3	2	C∨Z=0 Branch					
	LBHS																10 24	5(6)	4	C=0 Long Branch C=0	•	•	•	•	
BIT	BITA BITB				95 D5	4	2 2	B5 F5	5 5	3	85 C5	2 2	2 2	A5 E5	4+ 4+	2+ 2+				Bit Test A (M ∧ A) Bit Test B (M ∧ B)	•	‡	‡	0	
BLE	BLE LBLE																2F 10 2F	3 5(6)	2 4	Branch $Z \lor (N \oplus V)=1$ Long Branch $Z \lor (N \oplus V)=1$:	•	•	•	
BLO	BLO LBLO																25 10 25	3 5(6)	2 4	Branch C=1 Long Branch C=1	•	•	•	•	
BLS	BLS																23	3	2	Branch C∨Z=1	•	•	•	•	
	LBLS																10 23	5(6)	4	Long Branch	•	•	•	•	
BLT	BLT LBLT																2D 10 2D	3 5(6)	2 4	Branch N ⊕ V=1 Long Branch N ⊕ V=1	•	•	•	•	
вмі	BMI LBMI																2B 10 2B	3 5(6)	2 4	Branch N=1 Long Branch N=1	:	•	•		-
BNE	BNE LBNE																26 10 26	3 5(6)	2 4	Branch Z = 0 Long Branch Z = 0	:	•	•		-
BPL	BPL LBPL																2A 10 2A	3 5(6)	2 4	Branch N = 0 Long Branch N = 0	•	•	•	•	_
BRA	BRA LBRA																20 16	3 5	2 3	Branch Always Long Branch/ Always	•	•	•	•	-
BRN	BRN LBRN																21 10 21	3 5	2 4	Branch Never Long Branch Never	•	•	•	•	

(to be continued)

INSTE	RUCTION/	-			_			09 A			T	-					_								Т
	ORMS	-	1PLII	1		IREC	1	-	TEN	_	-	/EDI	-	-	DEXI	-	-	LATI	-	DESCRIPTION	5	3	2	1	(
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~3	#		Н	N	Z	٧	+
BSR	BSR LBSR																8D	7 9	3	Branch to Subroutine Long Branch to	•	•		•	
BVC	BVC LBVC																28 10	3 5(6)	2 4	Subroutine Branch V = 0 Long Branch	:	•	•	•	
BVS	BVS LBVS																28 29 10	3 5(6)	2 4	V = 0 Branch V = 1 Long Branch V = 1	•	•	•		
CLR	CLRA CLRB CLR	4F 5F	2 2	1	0F	6	2	7F	7	3				6F	6+	2+	29			0 → A 0 → B 0 → M		0 0 0	1 1 1	0 0 0	
CMP	CMPA CMPB CMPD				91 D1 10	4 4 7	2 2 3	B1 F1 10	5 5 8	3 3 4	81 C1 10	2 2 5	2 2 4	A1 E1 10	4+ 4+ 7+	2+ 2+ 3+				Compare M from A Compare M from B Compare M: M + 1	(8)	‡ ‡	‡ ‡	‡ ‡ ‡	
	CMPS				93	7	3	B3	8	4	83 11	5	4	A3 11	7+	3+				from D Compare M: M + 1		1	‡	‡	
	CMPU				9C 11 93	7	3	BC 11 B3	8	4	8C 11 83	5	4	11 A3	7+	3+				from S Compare M: M + 1 from U		‡	ţ	‡	
	CMPX				9C	6	2	ВС	7	3	8C	4	3	AC	6+	2+				Compare M: M + 1 from X	•	‡	‡	1	
	CMPY				10 9C	7	3	10 BC	8	4	10 8C	5	4	10 AC	7+	3+				Compare M: M + 1 from Y	•	1	‡	\$	
СОМ	COMA COMB COM	43 53	2	1	03	6	2	73	7	3				63	6+	2+				$\overline{A} \rightarrow A$ $\overline{B} \rightarrow B$ $\overline{M} \rightarrow M$	•	‡	‡	0 0	
WAI											3C	≧20	2							CC ∧ IMM → CC (except 1→E) Wait for Interrupt	(-		1		1
DAA	DECA	19 4A	2	1																Decimal Adjust A A − 1 → A	•	‡ ‡	‡	(8)	
,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DECB	5A	2	i	0A	6	2	7A	7	3				6A	6+	2+				$\begin{array}{c} B-1 \rightarrow B \\ M-1 \rightarrow M \end{array}$	•	‡	‡	1	
EOR	EORA EORB				98 D8	4	2 2	B8 F8	5 5	3	88 C8	2 2	2 2	A8 E8	4+ 4+	2+ 2+				$\begin{array}{c} A \oplus M \rightarrow A \\ B \oplus M \rightarrow B \end{array}$	•	‡	‡	0	
XG	R1, R2	1E	7	2																R1 ↔ R2 ^②	(-	_	10	-	ł
NC	INCA INCB INC	4C 5C	2	1	0C	6	2	7C	7	3				6C	6+	2+				$A + 1 \rightarrow A$ $B + 1 \rightarrow B$ $M + 1 \rightarrow M$	•	‡ ‡	‡ ‡	‡ ‡	
IMP					0E	3	2	7E	4	3				6E	3+	2+				EA ³ → PC					
ISR					9D	7	2	BD	8	3				AD	7+	2+				Jump to Subroutine	•	•	•	•	
LD	LDA LDB LDD LDS				96 D6 DC 10	4 4 5 6	2 2 2 3	B6 F6 FC 10	5 5 6 7	3 3 4	86 C6 CC 10	2 2 3 4	2 2 3 4	A6 E6 EC 10	4+ 4+ 5+ 6+	2+ 2+ 2+ 3+				$M \rightarrow A$ $M \rightarrow B$ $M: M + 1 \rightarrow D$ $M: M + 1 \rightarrow S$	•	‡ ‡ ‡	‡ ‡ ‡	0 0 0	
	LDU LDX LDY				DE DE 9E 10 9E	5 5 6	2 2 3	FE FE BE 10 BE	6 6 7	3 3 4	CE CE 8E 10 8E	3 3 4	3 3 4	EE AE 10 AE	5+ 5+ 6+	2+ 2+ 3+				$\begin{array}{l} M\colon M+1\to U\\ M\colon M+1\to X\\ M\colon M+1\to Y \end{array}$	•	‡ ‡	‡ ‡	0 0 0	
_EA	LEAS LEAU LEAX LEAY													32 33 30 31	4+ 4+ 4+ 4+	2+ 2+ 2+ 2+				EA ^③ → S EA ^③ → U EA ^③ → X EA ^③ → Y			•		
SL	LSLA LSLB LSL	48 58	2 2	1	08	6	2	78	7	3				68	6+	2+				Å		‡ ‡	‡ ‡	‡	
.SR	LSRA LSRB LSR	44 54	2 2	1	04	6	2	74	7	3				64	6+	2+				A B M		0 0 0	‡ ‡		
MUL	2011	3D	11	1	04		-	, ,	,					04	0.	2.				A × B → D (Unsigned)	•	•	1	•	
NEG	NEGA NEGB NEG	40 50	2 2	1	00	6	2	70	7	3				60	6+	2+				A + 1 → A B + 1 → B M + 1 → M	8 8	‡ ‡	‡ ‡	‡	
NOP	1120	12	2	1	00	3	-	70	'	3				00	0+	2.7		1		No Operation	•	•	•	•	

(to be continued)



INSTR	RUCTION/						-	D6809			1	_		-							_	_			_
PSH PSHS PSHU PULS PULU ROL ROLA ROLA ROLA ROLA ROLA ROLA ROLA ROLA	ORMS	OP	MPLIE		OP	IREC	T	EXTE	NDE		OP	MEDI ~		_	DEX		-	LAT	1	DESCRIPTION	5	3	2	1	0
OR		UP	~	#	9A DA	4 4	2 2	BA FA	-	3 3	8A CA 1A	2 2 3	# 2 2 2	OP AA EA	4+	# 2+ 2+	OP	~~	#	$A \lor M \rightarrow A$ $B \lor M \rightarrow B$ $CC \lor IMM \rightarrow CC$	H • (-	† ‡	Z	V 0 0	0
PSH		34	5+④																	Push Registers on S Stack	•	•	•	•	
	PSHU	36	5+4	2																Push Registers on U Stack	•	•	•	•	•
PUL		35 37	5+ ⁴	-																Pull Registers from S Stack Pull Registers from U Stack			10		.)
ROL	ROLB	49 59	2 2	1	09	6	2	79	7	3				69	6+	2+				A B C Stack		‡ ‡ ‡	‡ ‡	‡ ‡	1 1 1
ROR		46 56	2 2	1	06	6	2	76	7	3				66	6+	2+				A B P		‡	‡ ‡		1 1 1
RTI		3B	6/15	1																Return From Interrupt	(-		(7)		.)
RTS		39	5	1																Return From Subroutine	•	•	•	•	•
SBC					92 D2	4	2 2	B2 F2	5 5	3	82 C2	2	2 2	A2 E2	4+ 4+	2+ 2+				$\begin{array}{l} A-M-C \rightarrow A \\ B-M-C \rightarrow B \end{array}$	8	‡ ‡	‡ ‡	‡	‡ ‡
SEX		1D	2	1																Sign Extend B into A	•	ţ	‡	•	•
ST	STB STD				97 D7 DD 10 DF	4 4 5 6	2 2 2 3	B7 F7 FD 10 FF	5 5 6 7	3 3 4				A7 E7 ED 10 EF	4+ 4+ 5+ 6+	2+ 2+ 2+ 3+				$A \rightarrow M$ $B \rightarrow M$ $D \rightarrow M$: $M+1$ $S \rightarrow M$: $M+1$	•	‡ ‡ ‡	‡ ‡ ‡	0 0 0	
	STX				DF 9F 10 9F	5 5 6	2 2 3	FF BF 10 BF	6 6 7	3 3 4				EF AF 10 AF	5+ 5+ 6+	2+ 2+ 3+				$\begin{array}{c} U \rightarrow M \colon M+1 \\ X \rightarrow M \colon M+1 \\ Y \rightarrow M \colon M+1 \end{array}$	•	‡ ‡	‡ ‡	0 0 0	•
SUB	SUBB				90 D0 93	4 4 6	2 2 2	B0 F0 B3	5 5 7	3 3 3	80 C0 83	2 2 4	2 2 3	A0 E0 A3	4+ 4+ 6+	2+ 2+ 2+				$A - M \rightarrow A$ $B - M \rightarrow B$ $D - M: M + 1 \rightarrow D$	(8) (8)	‡ ‡ ‡	‡ ‡ ‡	‡	‡ ‡
SWI	SWI® SWI2®	3F 10 3F	19 20	1 2																Software Interrupt1 Software Interrupt2	:	:	:	:	•
	SWI3®	11 3F	20	2																Software Interrupt3	•	•	•	•	•
SYNC		13	≧4	1																Synchronize to Interrupt	•	•	•	•	•
TFR	R1, R2	1F	6	2																R1 → R2 ^②	(-	-	10	-	•)
TST		4D 5D	2 2	1	0D	6	2	7D	7	3				6D	6+	2+				Test A Test B Test M	•	‡ ‡	‡ ‡ ‡	0 0 0	

(NOTES)

- This column gives a base cycle and byte count. To obtain total count, and the values obtained from the INDEXED ADDRESSING MODES table.
- This column gives a base cycle and byte count. To obtain total count, and the values obtain R1 and R2 may be any pair of 8 bit or any pair of 16 bit registers. The 8 bit registers are: A, B, CC, DP The 16 bit registers are: X, Y, U, S, D, PC EA is the effective address.

 The PSH and PUL instructions require 5 cycle plus 1 cycle for each byte pushed or pulled.
- 5(6) means: 5 cycles if branch not taken, 6 cycles if taken. SWI sets 1 and F bits. SWI2 and SWI3 do not affect I and F.
- Conditions Codes set as a direct result of the instruction.
- 8 Value of half-carry flag is undefined.
 9 Special Case Carry set if b7 is SET.
- no Condition Codes set as a direct result of the instruction if CC is specified, and not affected otherwise.

LEGEND:

- Operation Code (Hexadecimal)
- Number of MPU Cycles Number of Program Bytes Arithmetic Plus

- Arithmetic Minus Multiply ×M
- Complement of M
- Transfer Into Half-carry (from bit 3) Negative (sign bit)

- Zero (byte)
- Overflow, 2's complement C
 - Carry from bit 7
 Test and set if true, cleared otherwise
- 1 Not Affected
- CC Condition Code Register
- Concatenation
- Logical or
- Logical and
- **(** Logical Exclusive or



Table 11 Hexadecimal Values of Machine Codes

OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#
00	NEG	Direct	6	2	30	LEAX	Indexed	4+	2+	60	NEG	Indexed	6+	2+
01		A			31	LEAY	A	4+	2+	61		*		
02	*				32	LEAS	+	4+	2+	62				
03	COM		6	2	33	LEAU	Indexed	4+	2+	63	COM		6+	2+
04	LSR		6	2	34	PSHS	Implied	5+	2	64	LSR		6+	2+
05	*				35	PULS	A	5+	2	65	*			
06	ROR		6	2	36	PSHU		5+	2	66	ROR		6+	2+
07	ASR	1	6	2	37	PULU		5+	2	67	ASR		6+	2+
08	ASL, LSL		6	2	38		1			68	ASL, LS	L	6+	2+
09	ROL	1	6	2	39	RTS	1	5	1	69	ROL		6+	2+
0A	DEC	-	6	2	3A	ABX	1	3	1	6A	DEC		6+	2+
0B	*		0	2	3B	RTI	Implied	6,15	1	6B	*			
			6	2	3C	CWAI	Implied	≥20	2	6C	INC		6+	2+
OC	INC		6	2	3D	MUL	Implied	≥20	1	6D	TST		6+	2+
OD	TST	1	3	2	3E	*	mpnea	11	1	6E	JMP	1	3+	2+
0E	JMP	V	6	2	3F	SWI		19	1	6F	CLR	Indexed	6+	2+
OF	CLR	Direct	0	2	31	3441	Implied	15	1	Oi	CLIT	macxea	0.	-
10) See	_	_	-	40	NEGA	Implied	2	1	70	NEG	Extended	7	3
11	Next Page	-	-	-	41		A			71		A		
12	NOP	Implied	2	1	42					72				
13	SYNC	Implied	≥4	1	43	COMA	1	2	1	73	COM		7	3
14			= '		44	LSRA		2	1	74	LSR		7	3
15					45	*				75		1		
16	LBRA	Relative	5	3	46	RORA	1	2	1	76	ROR		7	3
17	LBSR	Relative	9	3	47	ASRA	1	2	1	77	ASR		7	3
18	*	110/01/10			48	ASLA, LSLA		2	1	78	ASL, LS	L	7	3
19	DAA	Implied	2	1	49	ROLA		2	1	79	ROL		7	3
1A	ORCC	Immed	3	2	4A	DECA		2	1	7A	DEC		7	3
1B	*	mmea		-	4B			_		7B				
1C	ANDCC	Immed	3	2	4C	INCA		2	1	7C	INC		7	3
1D	SEX	Implied	2	1	4D	TSTA		2	1	7D	TST		7	3
1E	EXG	1	8	2	4E	*	+	_		7E	JMP	1	4	3
1F	TFR	▼ Implied	6	2	4F	CLRA	Implied	2	1	7F	CLR	Extended	7	3
		Implied		-			mphod							
20	BRA	Relative	3	2	50	NEGB	Implied	2	1	80	SUBA	Immed	2	2
21	BRN	A	3	2	51		*			81	CMPA	*	2	2
22	вні		3	2	52					82	SBCA		2	2
23	BLS		3	2	53	COMB		2	1	83	SUBD		4	3
24	BHS, BCC	1	3	2	54	LSRB	1	2	1	84	ANDA		2	2
25	BLO, BCS		3	2	55		1			85	BITA		2	2
26	BNE		3	2	56	RORB	- 1	2	1	86	LDA		2	2
27	BEQ		3	2	57	ASRB		2	1	87	*	1		
28	BVC		3	2	58	ASLB, LSLB	1	2	1	88	EORA		2	2
29	BVS	1	3	2	59	ROLB		2	1	89	ADCA		2	2
29 2A	BPL	1	3	2	5A	DECB		2	1	8A	ORA		2	2
2B	BMI		3	2	5B	*		2	•	8B	ADDA	1	2	2
2C	BGE		3	2	5C	INCB		2	1	8C	CMPX	Immed	4	3
2D	BLT		3	2	5D	TSTB		2	1	8D	BSR	Relative	7	2
2E	BGT	Ţ	3	2	5E	*	1	~		8E	LDX	Immed	3	3
2F	BLE	Relative	3	2	5F	CLRB	Implied	2	1	8F	*		-	-
			-	-	-									

LEGEND:

Number of MPU cycles (less possible push pull or indexed-mode cycles)

Number of program bytes

Denotes unused opcode

(to be continued)



OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	ОР	Mnem	Mode	~	#
90	SUBA	Direct	4	2	C6	LDB	Immed	2	2	FC	LDD	Extended	6	3
91	CMPA	A	4	2	C7	*	A	_	-	FD	STD	A	6	3
92	SBCA	T	4	2	C8	EORB	Ť	2	2	FE	LDU	T	6	3
93	SUBD		6	2	C9	ADCB		2	2	FF		_ *	1.00	
94	ANDA		4	2	CA	ORB		2	2	FF	STU	Extended	6	3
95	BITA		4	2	CB									
96	LDA		4	2		ADDB		2	2			0		
97	STA		4	2	CC	LDD *		3	3		2 Byte	es Opcode		
98	EORA				CD			2.	2					
99	ADCA		4	2	CE	LDU	Immed	3	3		LBRN	Relative	5	4
99 9A	ORA		-	2	CF	*					LBHI	•	5(6)	4
9B	ADDA		4	2							LBLS		5(6)	4
			4	2	D0	SUBB	Direct	4	2		LBHS,		5(6)	4
9C	CMPX		6	2	D1	CMPB	•	4	2		LBCS,	LBLO	5(6)	4
9D	JSR		7	2	D2	SBCB		4	2		LBNE		5(6)	4
9E	LDX	₹	5	2	D3	ADDD		6	2	1027	LBEQ	1	5(6)	4
9F	STX	Direct	. 2	2	D4	ANDB		4	2	1028	LBVC		5(6)	4
					D5	BITB		4	2	1029	LBVS	1	5(6)	4
A0	SUBA	Indexed	4+	2+	D6	LDB		4	2	102A	LBPL		5(6)	4
A1	CMPA	A	4+	2+	D7	STB		4	2	102B	LBMI		5(6)	4
A2	SBCA	T	4+	2+	D8	EORB		4	2		LBGE		5(6)	4
A3	SUBD		6+	2+	D9	ADCB		4	2		LBLT		5(6)	4
A4	ANDA		4+	2+	DA	ORB		4	2		LBGT	<u> </u>	5(6)	4
A5	BITA		4+	2+	DB	ADDB		4	2		LBLE	Relative	5(6)	4
A6	LDA		4+	2+	DC	LDD		5	2	103F	SWI2	Implied	20	2
A7	STA	1	4+	2+	DD	STD		5	2	1083		Immed	5	4
A8	EORA		4+	2+	DE	LDU	<u> </u>	5	2		CMPY	A	5	4
A9	ADCA		4+	2+	DF	STU	Direct	5	2		LDY	Immed	4	4
AA	ORA		4+	2+		0.0	Direct	5	-		CMPD	Direct	7	3
AB	ADDA		4+	2+	EO	SUBB	Indexed	4+	2+		CMPY	Direct	7	
AC	CMPX		6+	2+	E1	CMPB	Muexed	4+	2+			Ť		3
AD	JSR		7+		E2		↑			109E			6	3
		1		2+		SBCB		4+	2+	109F		Direct	6	3
AE	LDX	V	5+	2+	E3	ADDD		6+	2+		CMPD	Indexed	7+	3+
AF	STX	Indexed	5+	2+	E4	ANDB	1	4+	2+		CMPY	*	7+	3+
					E5	BITB	1	4+	2+	10AE	LDY		6+	3+
BO	SUBA	Extended	5	3	E6	LDB		4+	2+	10AF	STY	Indexed	6+	3+
B1	CMPA	†	5	3	E7	STB		4+	2+	10B3	CMPD	Extended	8	4
B2	SBCA		5	3	E8	EORB		4+	2+	10BC	CMPY	•	8	4
B3	SUBD		7	3	E9	ADCB		4+	2+	10BE	LDY	<u> </u>	7	4
B4	ANDA		5	3	EA	ORB		4+	2+	10BF	STY	Extended	7	4
B5	BITA		5	3	EB	ADDB		4+	2+	10CE	LDS	Immed	4	4
B6	LDA		5	3	EC	LDD		5+	2+	10DE	LDS	Direct	6	3
B7	STA		5	3	ED	STD		5+	2+	10DF	STS	Direct	6	3
B8	EORA		5	3	EE	LDU	₩.	5+	2+	10EE	LDS	Indexed	6+	3+
B9	ADCA		5	3	EF	STU	Indexed	5+	2+	10EF	STS	Indexed	6+	3+
BA	ORA		5	3						10FE	LDS	Extended	7	4
BB	ADDA	1	5	3	FO	SUBB	Extended	5	3	10FF		Extended	7	4
BC	CMPX	1	7	3	F1	CMPB	A	5	3		SWI3	Implied	20	2
BD	JSR		8	3	F2	SBCB	T	5	3		CMPU	Immed	5	4
BE	LDX	1	6	3	F3	ADDD		7	3					
BF	STX	Extended	6	3	F4	ANDB		5	3		CMPS	Immed	5 7	4
Di		Extended	U	3	F5	BITB	1	5	3			Direct	7	3
CO	SUBB	Immed	2	2	F6	LDB		5	3		CMPS	Direct		3
C1	CMPB	A	2	2	F7	STB		5	3		CMPU	Indexed	7+	3+
C2	SBCB	T	2	2	F8			5			CMPS	Indexed	7+	3+
C3	ADDD		4	3	F8	EORB	1		3		CMPU	Extended	8	4
C4		1	2			ADCB		5	3	TIBC	CMPS	Extended	8	4
	ANDB	Imms-d		2	FA	ORB	*	5	3					
C5	BITB	Immed	2	2	FB	ADDB	Extended	5	3					

(NOTE): All unused opcodes are both undefined and illegal

NOTE FOR USE

[1] Exceptional Operation of HD6809

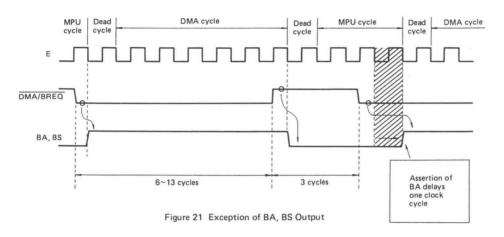
(a) Exceptional Operations of DMA/BREQ, BA signals

HD6809 acknowledges the input signal level of DMA/BREQ at the end of each cycle, then determines whether the next sequence is MPU or DMA. When "Low" level is detected, HD6809 executes DMA

sequence by setting BA, BS to "High" level. However, in the conditions shown below the assertion of BA, BS delays one clock cycle.

< Conditions for the exception >

(1) DMA/BREQ: "Low" for 6~13 cycles (2) DMA/BREQ: "High" for 3 cycles



(b) Exceptional Operations of DMA/BREQ, BA signals (#2)

HD6809 includes a self refresh counter for the re-

verce cycle steal. And it is only cleared if DMA/BREQ is inactive ("High") for 3 or more MPU cycles. So 1 or 2 inactive cycle(s) doesn't affect the self refresh counter.

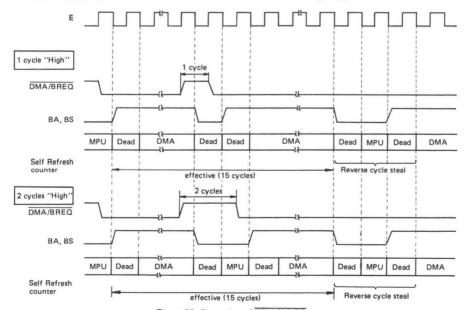


Figure 22 Exception of DMA/BREQ



How to avoid these exceptional operations

It is necessary to provide 4 or more cycles for in-

active DMA/BREQ level as shown in Fig. 23.

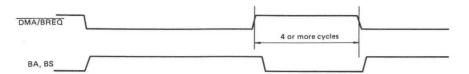


Figure 23 How to Avoid Exceptional Operations

[2] Restriction for DMA Transfer

There is a restriction for the DMA transfer in the HD6809 (MPU), HD6844 (DMAC) system. Please take care of following.

(a) An Example of the System Configuration

This restriction is applied to the following system.

- (1) DMA/BREO is used for DMA request.
- (2) "Halt Burst Mode" is used for DMA transfer

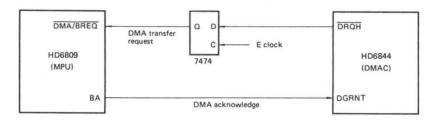


Figure 24 An Example of HD6809, HD6844 System

The restriction is also applied to the system which doesn't use 7474 Flip-Flop, Fig. 24, Fig. 25 shows an example which uses 7474 for synchronizing DMA request with E.

(b) Restriction

"The number of transfer Byte per one DMA Burst transfer must be less than or equal to 14."

Halt burst DMA transfer should be less than or equal to 14 cycles. In another word, the number stored into DMA Byte count register should be 0~14.

★ Please than care of the section [1](b) if 2 or more DMA channels are used for the DMA transfer.

(c) Incorrect operation of HD6809, HD6844 system

"Incorrect Operation" will occur if the number of DMA transfer Byte is more than 14 bytes. If DMA/ BREQ is kept in "Low" level HD6809 performs reverse cycle steals once in 14 DMA cycles by taking back the bus control. In this case, however, the action taken by MPU is a little bit different from the DMAC.

As shown in Fig. 25, DMA controller can't stop DMA transfer (A) by BA falling edge and excutes an extra DMA cycle during HD6809 dead cycle. So MPU cycle is excuted right after DMA cycle, the Bus confliction occurs at the beginning of MPU cycle.

How to impliment Halt Bust DMA transfer

(>14 cycles)

Please use HALT input of HD6809 for the DMA request instead of DMA/BREQ.

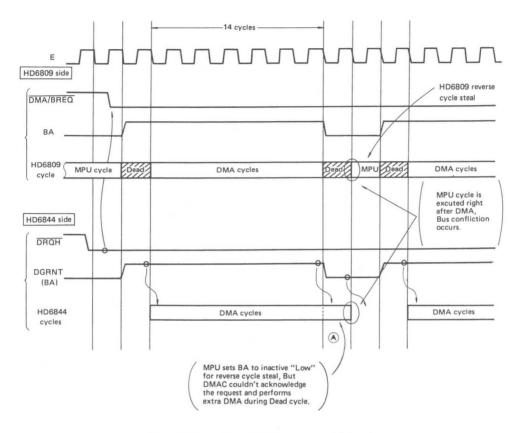


Figure 25 Comparison of HD6809, HD6844 DMA cycles

[3] Note for CLR Instruction

Cycle-by-cycle flow of CLR instruction (Direct, Extended, Indexed Addressing Mode) is shown below. In this sequence the content of the memory location specified by the operand is read before writing "00" into it. Note that status Flags, such as IRQ Flag, will be cleared by this extra data read operation when accessing the control/status register (sharing the same address between read and write) of peripheral devices.

Evamn	0.	CIR	(Extended)	

\$8000 \$A000	CLR FCB	\$A000 \$80		
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	7F	1	Opcode Fetch
2	8001	A0	1	Operand Address,
				High Byte
3	8002	00	1	Operand Address,
				Low Byte
4 5	FFFF	*	1	VMA Cycle
	A000	80	1	Read the Data
6	FFFF	*	1	VMA Cycle
7	A000	00	0	Store Fixed "00"
				into Specified
				Location
The date	hua baa sha a	1-44 41	4	.1 11

^{*} The data bus has the data at that particular address.

[4] Note for MRDY

HD6809 require synchronization of the MRDY input with the 4f clock. The synchronization necessitates an external oscillator as shown in Figure 26. The negative transition of the MRDY signal, normally derived from the chip select decoding, must meet the t_{PCS} timing. MRDY's positive transition must occur with the rising edge of 4f.

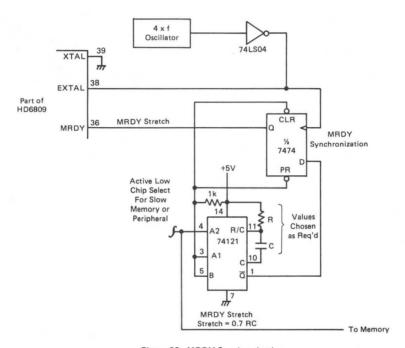


Figure 26 MRDY Synchronization

HD6809E, HD68A09E, HD68B09E MPU(Micro Processing Unit)

The HD6809E is a revolutionary high performance 8-bit microprocessor which supports modern programming techniques such as position independence, reentrancy, and modular programming.

This third-generation addition to the HMCS6800 family has major architectural improvements which include additional

registers, instructions and addressing modes.

The basic instructions of any computer are greatly enhanced by the presence of powerful addressing modes. The HD6809E has the most complete set of addressing modes available on any 8-bit microprocessor today.

The HD6809E has hardware and software features which make it an ideal processor for higher level language execution or standard controller applications. External clock inputs are provided to allow synchronization with peripherals, systems or other MPUs.

HD6800 COMPATIBLE

- Hardware Interfaces with All HMC\$6800 Peripherals
- Software Upward Source Code Compatible Instruction Set and Addressing Modes

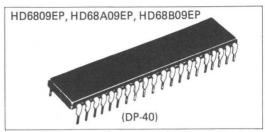
ARCHITECTURAL FEATURES

- Two 16-bit Index Registers
- Two 16-bit Indexable Stack Pointers
- Two 8-bit Accumulators can be Concatenated to Form One 16-Bit Accumulator
- Direct Page Register Allows Direct Addressing Throughout Memory

HARDWARE FEATURES

- External Clock Inputs, E and Q, Allow Synchronization
- TSC Input Controls Internal Bus Buffers
- LIC Indicates Opcode Fetch
- AVMA Allows Efficient Use of Common Resources in A Multiprocessor System
- BUSY is a Status Line for Multiprocessing
- Fast Interrupt Request Input Stacks Only Condition Code Register and Program Counter
- Interrupt Acknowledge Output Allows Vectoring By Devices
- SYNC Acknowledge Output Allows for Synchronization to External Event
- Single Bus-Cycle RESET
- Single 5-Volt Supply Operation
- NMI Blocked After RESET Until After First Load of Stack Pointer
- Early Address Valid Allows Use With Slower Memories
- Early Write-Data for Dynamic Memories
- **SOFTWARE FEATURES**
- 10 Addressing Modes
 - HMCS6800 Upward Compatible Addressing Modes
 - · Direct Addressing Anywhere in Memory Map
 - Long Relative Branches
 - · Program Counter Relative
 - · True Indirect Addressing
 - · Expanded Indexed Addressing:

0, 5, 8, or 16-bit Constant Offsets 8, or 16-bit Accumulator Offsets



Auto-Increment/Decrement by 1 or 2

- Improved Stack Manipulation
- 1464 Instruction with Unique Addressing Modes
- 8 x 8 Unsigned Multiply
- 16-bit Arithmetic
- Transfer/Exchange All Registers
- Push/Pull Any Registers or Any Set of Registers
- Load Effective Address

■ PIN ARRANGEMENT



■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	Vcc*	−0.3 ~ +7.0	V
Input Voltage	Vin*	-0.3 ~ +7.0	V
Operating Temperature Range	Topr	−20 ~+75	°C
Storage Temperature Range	Tstg	−55 ~ +150	°C

^{*} With respect to Vss (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ RECOMMENDED OPERATING CONDITIONS

	Item	Symbol	min	typ	max	unit	
Supply Voltage		Vcc*	4.75	5.0	5.25	V	
	Logic, Q, RES	VIL*	-0.2	_	0.8	V	
nput Voltage	E	VILC*	-0.3	_	0.4	V	
	Logic	*	2.2	_	Vcc*	V	
	RES	VIH*	4.0	_	Vcc*	V	
	E	VIHC*	Vcc* -0.75	_	Vcc* +0.3	V	
Operating Tempera	ature	Topr	-20	25	75	°C	

^{*} With respect to Vss (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC} = 5.0V ±5%, V_{SS} = 0V, T_a = -20 \sim +75 $^{\circ}$ C, unless otherwise noted.)

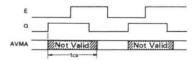
¥		0 1 1	Test Condition	HD	HD6809E			HD68A09E			HD68B09E		
Item		Symbol	lest Condition	min	typ*	max	min	typ*	max	min	typ*	max	Unit
	Logic, Q	VIH		2.2	-	Vcc	2.2	-	Vcc	2.2	-	Vcc	V
Input "High" Voltage	RES	VIHR		4.0	_	Vcc	4.0	-	Vcc	4.0	-	Vcc	V
	E	Viнc		Vcc -0.75	-	Vcc +0.3	Vcc -0.75	-	Vcc +0.3	Vcc -0.75	-	Vcc +0.3	v
	Logic, Q, RES	VIL		-0.2	-	0.8	-0.2	-	0.8	-0.2	-	0.8	V
Input "Low" Voltage	E	VILC		-0.3	_	0.4	-0.3	-	0.4	-0.3	-	0.4	V
1 7 1 8	Logic, Q, RES		Vin = 0 ~ 5,25V,	-2.5	-	2.5	-2.5	-	2.5	-2.5	-	2.5	μА
Input Leakage Current	E	lin	Vcc = max	-100	-	100	-100	-	100	-100	-	100	μА
50 [1]	D ₀ ~ D ₇		I _{Load} = -205μA, Vcc = min	2.4	-	-	2.4	-	-	2.4	-	-	V
Output "High" Voltage	$A_0 \sim A_{15}$, R/W	Vон	ILoad = -145μA, Vcc = min	2.4	_	-	2.4	-	-	2.4	-	-	V
	BA, BS, LIC, AVMA, BUSY		ILoad = -100μA, Vcc = min	2.4	-	1-	2.4	-	-	2.4	-		V
Output "Low" Voltage	•	Vol	ILoad = 2mA, Vcc = min	-	-	0,5	-	i —	0.5	-	-	0.5	V
Power Dissipation		PD		-	-	1.0	-	-	1.0	-	-	1.0	W
Input Capacitance	D ₀ ~ D ₇ , Logic Input, Q, RES	Cin	Vin = 0V, Ta = 25°C,	-	10	15	-	10	15	-	10	15	pF
100 - 100 C	E		f = 1MHz	-	30	50	-	30	50	_	30	50	pF
Output Capacitance $A_0 \sim A_{15}$, R/W , $B_0 \approx A_{15}$, R/W , $A_0 \approx A_{15}$, R/W , $A_0 \approx A_{15}$, $A_0 $		Ta = 25°C,	-	10	15	-	10	15	-	10	15	pF	
Frequency of Operation E, Q f		0.1	-	1,0	0.1	=	1,5	0.1	-	2.0	MHz		
Three-State (Off State)	D ₀ ~ D ₇	1	Vin = 0.4 ~ 2.4V.	-10	-	10	-10	-	10	-10	-	10	μА
Input Current	A ₀ ~ A ₁₅ , R/W	ITSI	Vcc = max	-100	_	100	-100	-	100	-100	-	100	μА

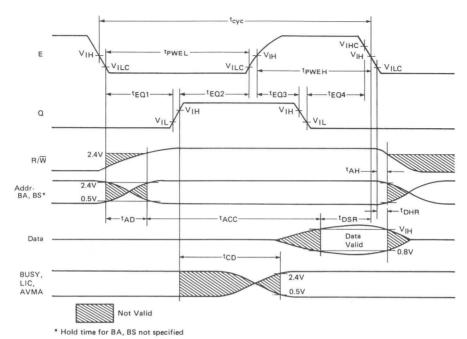
^{*} Ta = 25°C, V_{CC} = 5V

• AC CHARACTERISTICS (V_{CC} = 5.0V $\pm 5\%$, V_{SS} = 0V, Ta = -20 \sim +75 $^{\circ}$ C, unless otherwise noted.) READ/WRITE TIMING

Ite		Symbol	Test	Н	D6809	E	Н	D68A	09E	Н	D68B0	9E	Uni					
		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	-					
Cycle Time		tcyc		1000	-	10000	667	-	10000	500	-	10000	n					
Peripheral Read Access Tir $^{\rm t}$ cyc $ ^{\rm t}$ Ef $ ^{\rm t}$ AD $ ^{\rm t}$ DSR		tACC		695	-	-	440	-		330	-	-	n					
Data Setua Time (Read)		^t DSR		80	-	-	60	-	-	40	-	-	r					
Input Data Hold Time		tDHR		10	-	-	10	-	-	10	-	-	r					
	Ta = 0 ~ +75° C			30	-	-	30	_	_	30	-	-	1					
Output Data Hold Time	Ta = -20 ~ 0°C	tDHW		20	-	-	20	-	-	20	-	-	r					
Address Hold Time	Ta = 0 ~ +75°C			20	-	-	20	-	-	20	-	_						
(Address, R/ \overline{W}) Ta = -20 \sim 0°		t _{AH}		10	-	-	10	-	-	10	-	-						
Address Delay		tAD		_	-	200	-	-	140	-	-	120	ı					
Data Delay Time (Write)		tDDW	Fig. 1, 2, 7 ~ 10, 14 and 17	-	-	200	-	-	140	-	-	110	1					
E Clock "Low"		tPWEL							450	-	9500	295	-	9500	210	-	9500	
E Clock "High" (Measured at VIH)		tPWEH						450	-	9500	280	-	9500	220	-	9500	1	
E Rise and Fall Time		tEr, tEf		-	-	25	-	-	25	-	-	20						
Q Clock "High"		tpwQH		450	-	9500	280	-	9500	220	-	9500	1					
Q Rise and Fall Time		tQr, tQf		1-1	-	25	-	-	25	-	-	20						
E "Low" to Q Rising		tEQ1		200	-	-	130	-	-	100	-	-						
Q "High" to E Rising		tEQ2		200	-	-	130	-	-	100	-	-						
E "High" to Q Falling		tEQ3		200	-	-	130	-	-	100	-	-						
E "High" to Q Falling Q "Low" to E Falling		tEQ4		200	-	-	130	-	-	100	-	-						
Interrupts HALT, RES and TSC Setup Time		tPCS		200	-	-	140	-	-	110	-	-						
TSC Drive to Valid Logic Levels		tTSA		-	-	210	-	-	150	-	-	120						
TSC Release MOS Buffers to High Impedance		tTSR		-	-	200	-	-	140	-	-	110						
TSC Three-State Delay		tTSD		-	-	120	-	-	85	-	-	80						
Control Delay (BUSY, LIC)		tCD		-	-	300	-	-	250	-	-	200						
Control Delay (AVMA*)		tCD		-	-	300	-	-	270	-	-	240						
Processor Control Rise/Fa	II	tPCr, tPCf		-	-	100	-	-	100	-	-	100						
TSC Input Delay		tPCT		10	-	-	10	-	-	10	-	-	T					

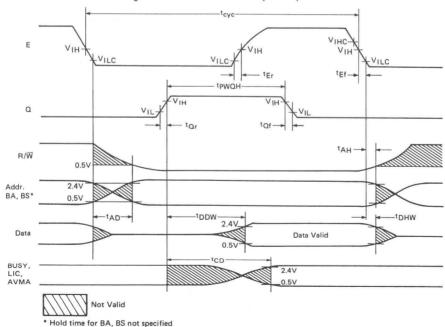
^{*} AVMA drives a not-valid data before providing correct output, so spec t_{CD max} = 270 nsec (HD68A09E) and 240 nsec (HD68B09E) are applied to this signal. When this delay time causes a problem in user's application, please use D-type latch to get stable output.





(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V_{IHmin} and logic "Low" = V_{ILmax} unless otherwise specified.

Figure 1 Read Data from Memory or Peripherals



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V_{1Hmin} and logic "Low" = V_{1Lmax} unless otherwise specified.

Figure 2 Write Data to Memory or Peripherals

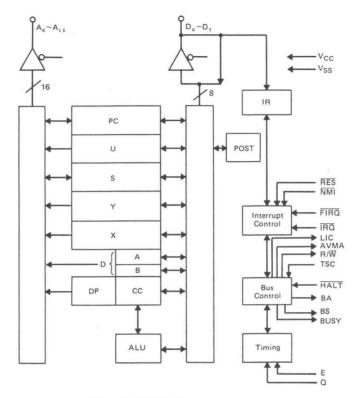
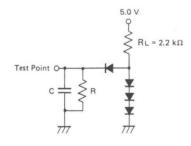


Figure 3 HD6809E Expanded Block Diagram



C = 30 pF for BA, BS, LIC, AVMA, BUSY 130 pF for $D_0 \sim D_7$ 90 pF for $A_0 \sim A_{15}$, R/W

R = 11.7 $\rm k\Omega$ for D₀ \sim D₇ 16.5 $\rm k\Omega$ for A₀ \sim A₁₅, R/ $\rm \overline{W}$ 24 $\rm k\Omega$ for BA, BS , LIC, AVMA, BUSY

All diodes are 1S2074 (H) or equivalent. C includes stray capacitance.

Figure 4 Bus Timing Test Load

■ PROGRAMMING MODEL

As shown in Figure 5, the HD6809E adds three registers to the set available in the HD6800. The added registers include a Direct Page Register, the User Stack pointer and a second Index Register.

Accumulators (A, B, D)

The A and B registers are general purpose accumulators which are used for arithmetic calculations and manipulation of data.

Certain instructions concatenate the A and B registers to form a single 16-bit accumulator. This is referred to as the D Register, and is formed with the A Register as the most significant byte.

• Direct Page Register (DP)

The Direct Page Register of the HD6809E serves to enhance the Direct Addressing Mode. The content of this register appears at the higher address outputs ($A_8 \sim A_{15}$) during direct addressing instruction execution. This allows the direct mode to be used at any place in memory, under program control. To ensure HD6800 compatibility, all bits of this register are cleared during Processor Reset.

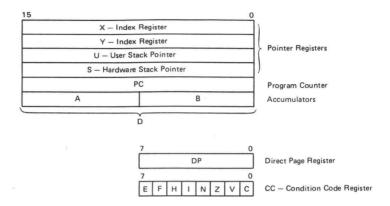


Figure 5 Programming Model of The Microprocessing Unit

Index Registers (X, Y)

The Index Registers are used in indexed mode of addressing. The 16-bit address in this register takes part in the calculation of effective addresses. This address may be used to point to data directly or may be modified by an optional constant or register offset. During some indexed modes, the contents of the index register are incremented or decremented to point to the next item of tabular type data. All four pointer registers (X, Y, U, S) may be used as index registers.

Stack Pointer (U, S)

The Hardware Stack Pointer (S) is used automatically by the processor during subroutine calls and interrupts. The User Stack Pointer (U) is controlled exclusively by the programmer thus allowing arguments to be passed to and from subroutines with ease. The U-register is frequently used as a stack marker. Both Stack Pointers have the same indexed mode addressing capabilities as the X and Y registers, but also support Push and Pull instructions. This allows the HD6809E to be used efficiently as a stack processor, greatly enhancing its ability to support higher level languages and modular programming.

(NOTE) The stack pointers of the HD6809E point to the top of the stack, in contrast to the HD6800 stack pointer, which pointed to the next free location on stack.

Program Counter (PC)

The Program Counter is used by the processor to point to the address of the next instruction to be executed by the processor. Relative Addressing is provided allowing the Program Counter to be used like an index register in some situations.

• Condition Code Register (CC)

The Condition Code Register defines the state of the processor at any given time. See Figure 6.

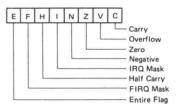


Figure 6 Condition Code Register Format

■ CONDITION CODE REGISTER DESCRIPTION

Bit 0 (C)

Bit 0 is the carry flag, and is usually the carry from the binary ALU. C is also used to represent a 'borrow' from subtract like instructions (CMP, NEG, SUB, SBC) and is the complement of the carry from the binary ALU.

Bit 1 (V)

Bit 1 is the overflow flag, and is set to a one by an operation which causes a signed two's complement arithmetic overflow. This overflow is detected in an operation in which the carry from the MSB in the ALU does not match the carry from the MSB-1.

Bit 2 (Z)

Bit 2 is the zero flag, and is set to a one if the result of the previous operation was identically zero.

Bit 3 (N)

Bit 3 is the negative flag, which contains exactly the value of the MSB of the result of the preceding operation. Thus, a negative two's-complement result will leave N set to a one.

Bit 4 (1)

Bit 4 is the \overline{IRQ} mask bit. The processor will not recognize interrupts from the \overline{IRQ} line if this bit is set to a one. \overline{NMI} , \overline{FIRQ} , \overline{IRQ} , \overline{RES} and SWI all set I to a one; SWI2 and SWI3 do not affect I.

• Bit 5 (H)

Bit 5 is the half-carry bit, and is used to indicate a carry from bit 3 in the ALU as a result of an 8-bit addition only (ADC or ADD). This bit is used by the DAA instruction to perform a BCD decimal add adjust operation. The state of this flag is undefined in all subtract-like instructions.

• Bit 6 (F)

Bit 6 is the \overline{FIRQ} mask bit. The processor will not recognize interrupts from the \overline{FIRQ} line if this bit is a one. \overline{NMI} , \overline{FIRQ} , SWI, and \overline{RES} all set F to a one. \overline{IRQ} , SWI2 and SWI3 do not affect F.

• Bit 7 (E)

Bit 7 is the entire flag, and when set to a one indicates that the complete machine state (all the registers) was stacked, as opposed to the subset state (PC and CC). The E bit of the stacked CC is used on a return from interrupt (RTI) to determine the extent of the unstacking. Therefore, the current E left in the Condition Code Register represents past action.

■ HD6809E MPU SIGNAL DESCRIPTION

Power (Vss, Vcc)

Two pins are used to supply power to the part: Vss is ground or 0 volts, while Vcc is +5.0 V ±5%.

Address Bus (A₀ ~ A₁₅)

Sixteen pins are used to output address information from the MPU onto the Address Bus. When the processor does not require the bus for a data transfer, it will output address FFFF₁₆, R/\overline{W} = "High", and BS = "Low"; this is a "dummy access" or \overline{VMA} cycle. All address bus drivers are made highimpedance when output Bus Available (BA) is "High" or when TSC is asserted. Each pin will drive one Schottky TTL load or four LS TTL loads, and 90 pF. Refer to Figures 1 and 2.

Data Bus (D₀ ~ D₂)

These eight pins provide communication with the system bi-directional data bus. Each pin will drive one Schottky TTL load or four LS TTL loads, and 130 pF.

Read/Write (R/W)

This signal indicates the direction of data transfer on the data bus. A "Low" indicates that the MPU is writing data onto the data bus. R/\overline{W} is made high impedance when BA is "High" or when TSC is asserted. Refer to Figures 1 and 2.

• RES

A "Low" level on this Schmitt-trigger input for greater than one bus cycle will reset the MPU, as shown in Figure 7. The Reset vectors are fetched from locations FFFE $_{16}$ and FFFF $_{16}$ (Table 1) when Interrupt Acknowledge is true, ($\overline{BA} \cdot BS = 1$). During initial power-on, the Reset line should be held "Low" until the clock input signals are fully operational.

Because the HD6809E Reset pin has a Schmitt-trigger input with a threshold voltage higher than that of standard peripherals, a simple R/C network may be used to reset the entire system.

This higher threshold voltage ensures that all peripherals are out of the reset state before the Processor.

Table 1 Memory Map for Interrupt Vectors

Memory Ma Locat	p for Vector	Interrupt Vector Description					
MS	LS	Description					
FFFE	FFFF	RES					
FFFC	FFFD	NMI					
FFFA	FFFB	SWI					
FFF8	FFF9	ĪRQ					
FFF6	FFF7	FIRQ					
FFF4	FFF5	SW12					
FFF2	FFF3	SWI3					
FFF0	FFF1	Reserved					

· HALT

A "Low" level on this input pin will cause the MPU to stop running at the end of the present instruction and remain halted indefinitely without loss of data. When halted, the BA output is driven "High" indicating the buses are high impedance. BS is also "High" which indicates the processor is in the Halt state. While halted, the MPU will not respond to external real-time requests (FIRQ, IRQ) although $\overline{\text{NMI}}$ or $\overline{\text{RES}}$ will be latched for later response. During the Halt state Q and E should continue to run normally. A halted state (BA \cdot BS = 1) can be achieved by pulling $\overline{\text{HALT}}$ "Low" while $\overline{\text{RES}}$ is still "Low". See Figure 8.

Bus Available, Bus Status (BA, BS)

The Bus Available output is an indication of an internal control signal which makes the MOS buses of the MPU high impedance. When BA goes "Low", a dead cycle will elapse before the MPU acquires the bus. BA will not be asserted when TSC is active, thus allowing dead cycle consistency.

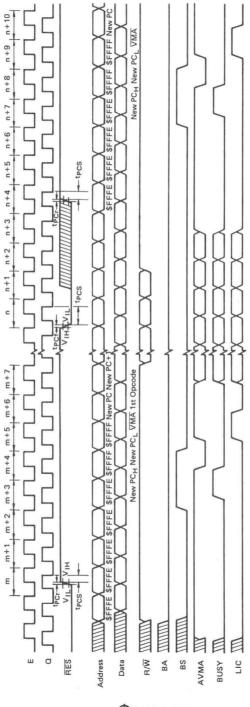
The Bus Status output signal, when decoded with BA, represents the MPU state (valid with leading edge of Q).

MPU	J State	MRII Com D. Code
ВА	BS	MPU State Definition
0	0	Normal (Running)
0	1	Interrupt or RESET Acknowledge
1	0	SYNC Acknowledge
1	1	HALT Acknowledge

Interrupt Acknowledge is indicated during both cycles of a hardware-vector-fetch (\overline{RES} , \overline{NMI} , \overline{FIRQ} , \overline{IRQ} , SWI, SWI2, SWI3). This signal, plus decoding of the lower four address lines, can provide the user with an indication of which interrupt level is being serviced and allow vectoring by device. See Table 1.

Sync Acknowledge is indicated while the MPU is waiting for external synchronization on an interrupt line.

Halt Acknowledge is indicated when the HD6809E is in a Halt condition.



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V IHmin and logic "Low" = V ILmax unless otherwise specified.

Figure 7 RES Timing

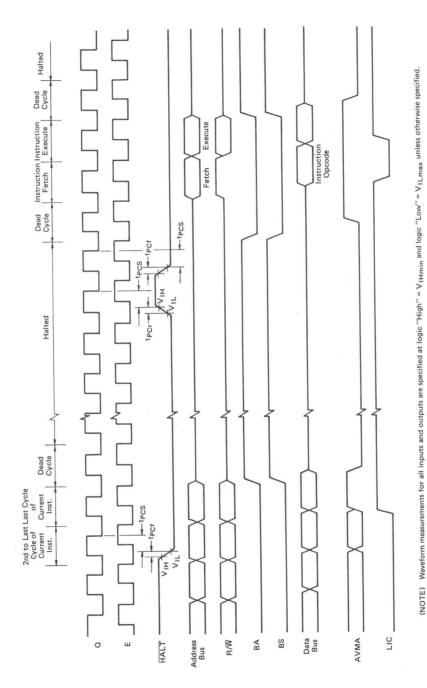


Figure 8 HALT and Single Instruction Execution for System Debug

Non Maskable Interrupt (NMI)*

A negative transition on this input requests that a non-maskable interrupt sequence be generated. A non-maskable interrupt cannot be inhibited by the program, and also has a higher priority than \overline{FIRQ} , \overline{IRQ} or software interrupts. During recognition of an \overline{NMI} , the entire machine state is saved on the hardware stack. After reset, an \overline{NMI} will not be recognized until the first program load of the Hardware Stack Pointer (S). The pulse width of \overline{NMI} low must be at least one E cycle. If the \overline{NMI} input does not meet the minimum set up with respect to Q, the interrupt will not be recognized until the next cycle. See Figure 9.

• Fast-Interrupt Request (FIRQ)*

A "Low" level on this input pin will initiate a fast interrupt sequence, provided its mask bit (F) in the CC is clear. This sequence has priority over the standard Interrupt Request (IRQ), and is fast in the sense that it stacks only the contents of the condition code register and the program counter. The interrupt service routine should clear the source of the interrupt before doing an RTI. See Figure 10.

• Interrupt Request (IRQ)*

A "Low" level input on this pin will initiate an Interrupt Request sequence provided the mask bit (I) in the CC is clear. Since IRQ stacks the entire machine state it provides a slower response to interrupts than FIRQ. IRQ also has a lower priority than FIRQ. Again, the interrupt service routine should clear the source of the interrupt before doing an RTI. See Figure 9.

* NMI, FIRQ, and IRQ requests are sampled on the falling edge of Q. One cycle is required for synchronization before these interrupts are recognized. The pending interrupt(s) will not be serviced until completion of the current instruction unless a SYNC or CWAI condition is present. If IRQ and FIRQ do not remain "Low" until completion of the current instruction they may not be recognized. However, NMI is latched and need only remain "Low" for one cycle.

Clock Inputs E, Q

E and Q are the clock signals required by the HD6809E. Q must lead E; that is, a transition on Q must be followed by a similar transition on E after a minimum delay. Addresses will be valid from the MPU, t_{AD} after the falling edge of E, and data will be latched from the bus by the falling edge of E. While the Q input is fully TTL compatible, the E input directly drives internal MOS circuitry and, thus, requires levels above normal TTL levels. This approach minimizes clock skew inherent with an internal buffer. Timing and waveforms for E and Q are shown in Figures 1 and 2 while Figure 11 shows a simple clock generator for the HD6809E.

BUSY

Busy will be "High" for the read and modify cycles of a readmodify-write instruction and during the access of the first byte of a double-byte operation (e.g., LDX, STD, ADDD). Busy is also "High" during the first byte of any indirect or other vector fetch (e.g., jump extended, SWI indirect etc.).

In a multi-processor system, busy indicates the need to defer the rearbitration of the next bus cycle to insure the integrity of the above operations. This difference provides the indivisible memory access required for a "test-and-set" primitive, using any one of several read-modify-write instructions.

Busy does not become active during PSH or PUL operations. A typical read-modify-write instruction (ASL) is shown in Figure 12. Timing information is given in Figure 13. Busy is valid t_{CD} after the rising edge of Q.

AVMA

AVMA is the Advanced VMA signal and indicates that the MPU will use the bus in the following bus cycle. The predictive nature of the AVMA signal allows efficient shared-bus multiprocessor systems. AVMA is "Low" when the MPU is in either a HALT or SYNC state. AVMA is valid t_{CD} after the rising edge of Q.

· IIC

LIC (Last Instruction Cycle) is "High" during the last cycle of every instruction, and its transition from "High" to "Low" will indicate that the first byte of an opcode will be latched at the end of the present bus cycle. LIC will be "High" when the MPU is Halted at the end of an instruction, (i.e., not in CWAI or RESET) in SYNC state or while stacking during interrupts. LIC is valid top after the rising edge of O.

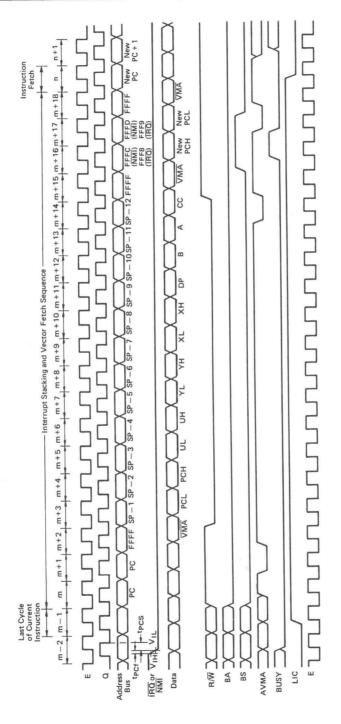
• TSO

TSC (Three-State Control) will cause MOS address, data, and R/\overline{W} buffers to assume a high-impedance state. The control signals (BA, BS, BUSY, AVMA and LIC) will not go to the high-impedance state. TSC is intended to allow a single bus to be shared with other bus masters (processors or DMA controllers)

While E is "Low", TSC controls the address buffers and R/\overline{W} directly. The data bus buffers during a write operation are in a high-impedance state until Q rises at which time, if TSC is true, they will remain in a high-impedance state. If TSC is held beyond the rising edge of E, then it will be internally latched, keeping the bus drivers in a high-impedance state for the remainder of the bus cycle. See Figure 14.

MPU Operation

During normal operation, the MPU fetches an instruction from memory and then executes the requested function. This sequence begins after RES and is repeated indefinitely unless altered by a special instruction or hardware occurrence. Software instructions that alter normal MPU operation are: SWI, SWI2, SWI3, CWAI, RTI and SYNC. An interrupt or HALT input can also alter the normal execution of instructions. Figure 15 illustrates the flow chart for the HD6809E.



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V IHmin and logic "Low" = V ILmax unless otherwise specified. E clock shown for reference only.

Figure 9 IRO and NMI Interrupt Timing

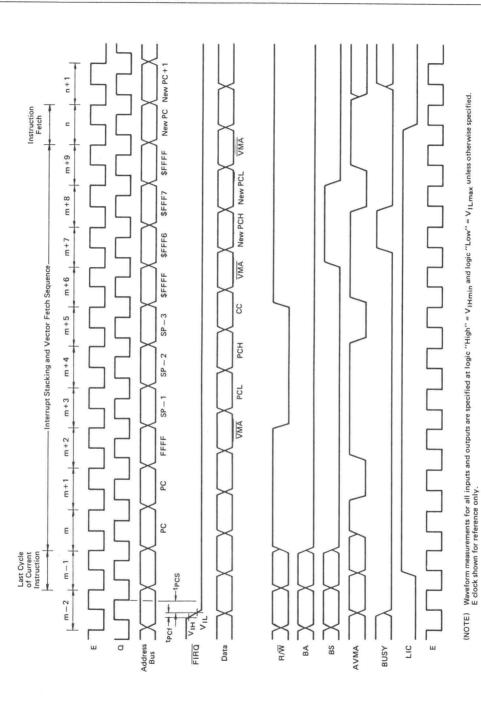


Figure 10 FIRO Interrupt Timing

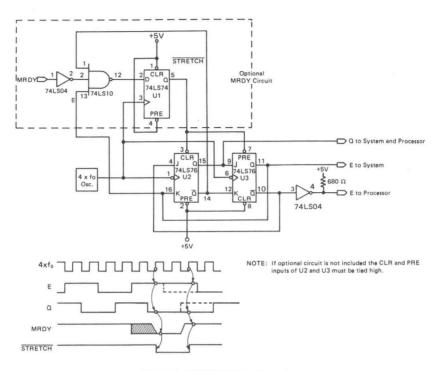


Figure 11 HD6809E Clock Generator

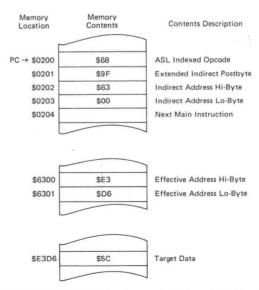
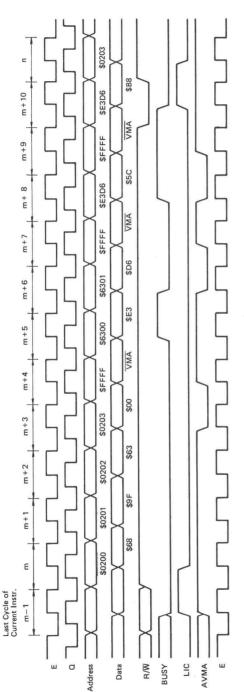
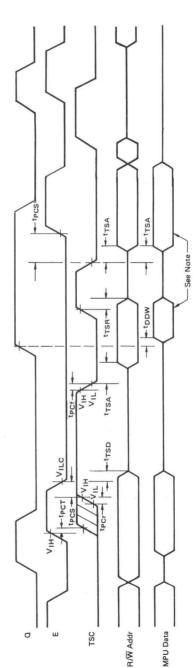


Figure 12 Read Modify Write Instruction Example (ASL Extended Indirect)



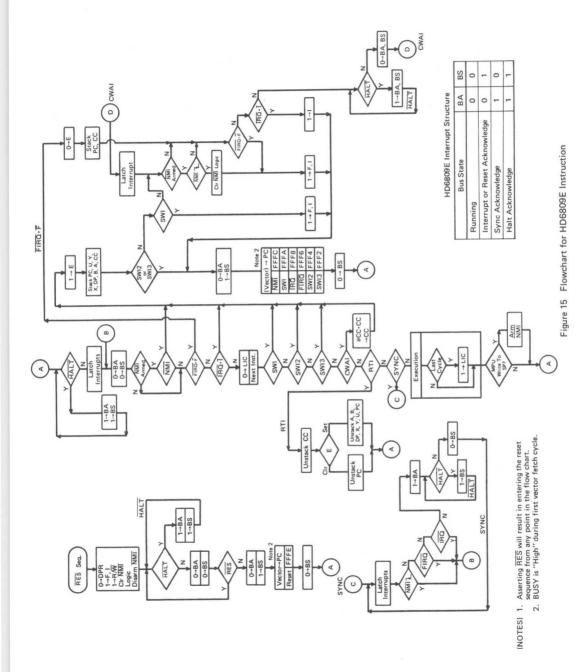
(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = VIHmin and logic "Low" = VILmax unless otherwise specified.

Figure 13 BUSY Timing (ASL Extended Indirect Instruction)



(NOTES) Data will be asserted by the MPU only during the interval while R/\overline{W} is "Low" and E or Q is "High". Waveform measurements for all inputs and outputs are specified at logic "High" = V_{ILmin} and logic "Low" = V_{ILmax} unless otherwise specified.

Figure 14 TSC Timing



(1) HITACHI

ADDRESSING MODES

The basic instructions of any computer are greatly enhanced by the presence of powerful addressing modes. The HD6809E has the most complete set of addressing modes available on any microcomputer today. For example, the HD6809E has 59 basic instructions; however, it recognizes 1464 different variations of instructions and addressing modes. The addressing modes support modern programming techniques. The following addressing modes are available on the HD6809E:

- (1) Implied (Includes Accumulator)
- (2) Immediate
- (3) Extended
- (4) Extended Indirect
- (5) Direct
- (6) Register
- (7) Indexed

Zero-Offset

Constant Offset

Accumulator Offset

Auto Increment/Decrement

- (8) Indexed Indirect
- (9) Relative
- (10) Program Counter Relative

Implied (Includes Accumulator)

In this addressing mode, the opcode of the instruction contains all the address information necessary. Examples of Implied Addressing are: ABX, DAA, SWI, ASRA, and CLRB.

Immediate Addressing

In Immediate Addressing, the effective address of the data is the location immediately following the opcode (i.e., the data to be used in the instruction immediately follows the opcode of the instruction). The HD6809E uses both 8 and 16-bit immediate values depending on the size of argument specified by the opcode. Examples of instructions with immediate Addressing are:

LDA #\$20 LDX #\$F000

LDY #CAT

(NOTE) # signifies immediate addressing, \$ signifies hexadecimal value.

Extended Addressing

In Extended Addressing, the contents of the two bytes immediately following the opcode fully specify the 16-bit effective address used by the instruction. Note that the address generated by an extended instruction defines an absolute address and is not position independent. Examples of Extended Addressing include:

LDA CAT STX MOUSE LDD \$2000

Extended Indirect

As a special case of indexed addressing (discussed below), one level of indirection may be added to Extended Addressing. In Extended Indirect, the two bytes following the postbyte of an Indexed instruction contain the address of the data.

LDA [CAT] LDX [\$FFFE] STU [DOG]

Direct Addressing

Direct addressing is similar to extended addressing except that only one byte of address follows the opcode. This byte specifies the lower 8 bits of the address to be used. The upper 8 bits of the address are supplied by the direct page register. Since only one byte of address is required in direct addressing, this mode requires less memory and executes faster than extended addressing. Of course, only 256 locations (one page) can be accessed without redefining the contents of the DP register. Since the DP register is set to \$00 on Reset, direct addressing on the HD6809E is compatible with direct addressing on the HD6800. Indirection is not allowed in direct addressing. Some examples of direct addressing are:

LDA \$30 SETDP \$10 (Assembler directive) LDB \$1030 LDD < CAT

(NOTE) < is an assembler directive which forces direct addressing.

Register Addressing

Some opcodes are followed by a byte that defines a register or set of registers to be used by the instruction. This is called a postbyte. Some examples of register addressing are:

TFR X, Y Transfer X into Y
EXG A, B Exchanges A with B
PSHS A, B, X, Y Push Y, X, B and A onto S
PULU X, Y, D Pull D, X, and Y from U

Indexed Addressing

In all indexed addressing, one of the pointer registers (X, Y, U, S, and sometimes PC) is used in a calculation of the effective address of the operand to be used by the instruction. Five basic types of indexing are available and are discussed below. The postbyte of an indexed instruction specifies the basic type and variation of the addressing mode as well as the pointer register to be used. Figure 16 lists the legal formats for the postbyte. Table 2 gives the assembler form and the number of cycles and bytes added to the basic values for indexed addressing for each variation.

Indexed		t	er Bi	Regist	yte F	ost-B				
Addressing Mode	0	1	2	3	4	5	6	7		
EA = ,R + 5 Bit Offset	d	d	d	d	d	R	R	0		
,R +	0	0	0	0	0	R	R	1		
,R ++	1	0	0	0	i	R	R	1		
, -R	0	1	0	0	0	R	R	1		
, R	1	1	0	0	i	R	R	1		
EA = ,R + 0 Offset	0	0	1	0	i	R	R	1		
EA = ,R + ACCB Offset	1	0	1	0	1	R	R	1		
EA = ,R + ACCA Offset	0	1	1	0	i	R	R	1		
EA = , R + 8 Bit Offset	0	0	0	1	i	R	R	1		
EA = ,R + 16 Bit Offset	1	0	0	1	i	R	R	1		
EA = ,R + D Offset	1	1	0	1	i	R	R	1		
EA = ,PC + 8 Bit Offset	0	0	1	1	i	×	×	1		
EA = ,PC + 16 Bit Offse	1	0	1	1	i	×	×	1		
EA = [.Address]	1	1	1	1	i	R	R	1		

Figure 16 Index Addressing Postbyte Register Bit Assignments

Table 2 Indexed Addressing Mode

		N	on Indirect				Indirect		_
Туре	Forms	Assembler Form	Postbyte OP Code	+ ~	+ #	Assembler Form	Postbyte OP Code	+ ~	1.
Constant Offset From R	No Offset	,R	1RR00100	0	0	[,R]	1RR10100	3	C
(2's Complement Offsets)	5 Bit Offset	n, R	0RRnnnnn	1	0	default	ts to 8-bit		Γ
	8 Bit Offset	n, R	1RR01000	1	1	[n, R]	1RR11000	4	1
	16 Bit Offset	n, R	1RR01001	4	2	[n, R]	1RR11001	7	2
Accumulator Offset From R	A Register Offset	A, R	1RR00110	1	0	[A, R]	1RR10110	4	C
(2's Complement Offsets)	B Register Offset	B, R	1RR00101	1	0	[B, R]	1RR10101	4	C
	D Register Offset	D, R	1RR01011	4	0	[D, R]	1RR11011	7	0
Auto Increment/Decrement R	Increment By 1	,R +	1RR00000	2	0	not	allowed		
	Increment By 2	,R + +	1RR00001	3	0	[,R++]	1RR10001	6	C
	Decrement By 1	, - R	1RR00010	2	0	not	allowed		
	Decrement By 2	, R	1RR00011	3	0	[, R]	1RR10011	6	C
Constant Offset From PC	8 Bit Offset	n, PCR	1xx01100	1	1	[n, PCR]	1xx11100	4	1
(2's Complement Offsets)	16 Bit Offset	n, PCR	1xx01101	5	2	[n, PCR]	1xx11101	8	2
Extended Indirect	16 Bit Address	_	_	-	-	[n]	10011111	5	2

R = X, Y, U or S

RR:

x = Don't Care

00 = X01 = Y

10 = U

11 = S

 $_{\sim}^{+}$ and $_{\#}^{+}$ indicate the number of additional cycles and bytes for the particular variation.

Zero-Offset Indexed

In this mode, the selected pointer register contains the effective address of the data to be used by the instruction. This is the fastest indexing mode.

Examples are:

LDD 0, X

LDA S

Constant Offset Indexed

In this mode, a two's-complement offset and the contents of one of the pointer registers are added to form the effective address of the operand. The pointer register's initial content is unchanged by the addition.

Three sizes of offsets are available:

5-bit (-16 to +15)

8-bit (-128 to +127)

16-bit (-32768 to +32767)

The two's complement 5-bit offset is included in the postbyte and, therefore, is most efficient in use of bytes and cycles. The two's complement 8-bit offset is contained in a single byte following the postbyte. The two's complement 16-bit offset is in the two bytes following the postbyte. In most cases the programmer need not be concerned with the size of this offset since the assembler will select the optimal size automatically.

Examples of constant-offset indexing are:

LDA 23. X

LDX -2, S

LDY 300, X LDU CAT, Y

Accumulator-Offset Indexed

This mode is similar to constant offset indexed except that the two's-complement value in one of the accumulators (A, B or D) and the contents of one of the pointer registers are added to form the effective address of the operand. The contents of both the accumulator and the pointer register are unchanged by the addition. The postbyte specifies which accumulator to use as an offset and no additional bytes are required. The advantage of an accumulator offset is that the value of the offset can be calculated by a program at run-time.

Some examples are:

LDA B, Y

LDX D, Y

LEAX B, X

Auto Increment/Decrement Indexed

In the auto increment addressing mode, the pointer register contains the address of the operand. Then, after the pointer register is used it is incremented by one or two. This addressing mode is useful in stepping through tables, moving data, or for the creation of software stacks. In auto decrement, the pointer register is decremented prior to use as the address of the data. The use of auto decrement is similar to that of auto increment; but the tables, etc., are scanned from the high to low addresses. The size of the increment/decrement can be either one or two to allow for tables of either 8- or 16-bit data to be accessed and is selectable by the programmer. The pre-

decrement, post-increment nature of these modes allow them to be used to create additional software stacks that behave identically to the U and S stacks.

Some examples of the auto increment/decrement addressing modes are:

LDA ,X+ STD ,Y++ LDB ,-Y LDX ,--S

Care should be taken in performing operations on 16-bit pointer registers (X, Y, U, S) where the same register is used to calculate the effective address.

Consider the following instruction:

STX 0, X + + (X initialized to 0)

The desired result is to store a 0 in locations \$0000 and \$0001 then increment X to point to \$0002. In reality, the following occurs:

 $0 \rightarrow \text{temp}$ calculate the EA; temp is a holding register $X + 2 \rightarrow X$ perform autoincrement $X \rightarrow (\text{temp})$ do store operation

Indexed Indirect

All of the indexing modes with the exception of auto increment/decrement by one, or a ±4-bit offset may have an additional level of indirection specified. In indirect addressing, the effective address is contained at the location specified by the contents of the Index Register plus any offset. In the example below, the A accumulator is loaded indirectly using an effective address calculated from the Index Register and an offset.

Before Execution
A = XX (don't care)
X = \$F000

\$0100 LDA [\$10, X] EA is now \$F010

\$F010 \$F1 \$F150 is now the new EA

\$F150 \$AA
After Execution
A = \$AA (Actual Data Loaded)

All modes of indexed indirect are included except those which are meaningless (e.g., auto increment/decrement by 1 indirect). Some examples of indexed indirect are:

LDA [, X] LDD [10, S] LDA [B, Y] LDD [, X++]

X = F000

Relative Addressing

The byte(s) following the branch opcode is (are) treated as a signed offset which may be added to the program counter. If the branch condition is true then the calculated address (PC + signed offset) is loaded into the program counter. Program execution continues at the new location as indicated by the PC; short (1 byte offset) and long (2 bytes offset) relative addressing modes are available. All of memory can be reached in long relative addressing as an effective address is interpreted modulo 2¹⁶. Some examples of relative addressing are:

BEQ CAT (short) BGT DOG (short)

CAT DOG	LBEQ LBGT	RAT RABBIT	(long) (long)
RAT	NOP		
RABBIT	NOP		

Program Counter Relative

The PC can be used as the pointer register with 8 or 16-bit signed offsets. As in relative addressing, the offset is added to the current PC to create the effective address. The effective address is then used as the address of the operand or data. Program Counter Relative Addressing is used for writing position independent programs. Tables related to a particular routine will maintain the same relationship after the routine is moved, if referenced relative to the Program Counter. Examples are:

LDA CAT, PCR LEAX TABLE, PCR

Since program counter relative is a type of indexing, an additional level of indirection is available.

LDA [CAT, PCR] LDU [DOG, PCR]

■ HD6809E INSTRUCTION SET

The instruction set of the HD6809E is similar to that of the HD6800 and is upward compatible at the source code level. The number of opcodes has been reduced from 72 to 59, but because of the expanded architecture and additional addressing modes, the number of available opcodes (with different addressing modes) has risen from 197 to 1464.

Some of the new instructions are described in detail below:

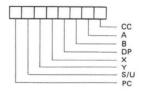
PSHU/PSHS

The push instructions have the capability of pushing onto either the hardware stack (S) or user stack (U) any single register, or set of registers with a single instruction.

PULU/PULS

The pull instructions have the same capability of the push instruction, in reverse order. The byte immediately following the push or pull opcode determines which register or registers are to be pushed or pulled. The actual PUSH/PULL sequence is fixed; each bit defines a unique register to push or pull, as shown in below.

PUSH/PULL POST BYTE



	← P	ull Or	der	I	Push O	rder →	
PC	U	Y	X	DP	В	A	CC
FFFF	. ← i	ncreasi	ng me	mory	addres	SS	0000
PC	S	V	X	DP	R	Δ	CC

TFR/EXG

Within the HD6809E, any register may be transferred to or exchanged with another of like-size; i.e., 8-bit to 8-bit or 16-bit to 16-bit. Bits $4\sim7$ of postbyte define the source register, while bits $0\sim3$ represent the destination register. These are denoted as follows:

0000 - D	0101 - PC
0001 - X	1000 - A
0010 - Y	1001 - B
0011 - U	1010 - CC
0100 - S	1011 - DP

(NOTE) All other combinations are undefined and INVALID.

TRANSFER/EXCHANGE POST BYTE

SOURCE	DESTINATION
--------	-------------

LEAX/LEAY/LEAU/LEAS

MSG1 FCC

The LEA (Load Effective Address) works by calculating the effective address used in an indexed instruction and stores that address value, rather than the data at that address, in a pointer register. This makes all the features of the internal addressing hardware available to the programmer. Some of the implications of this instruction are illustrated in Table 3.

The LEA instruction also allows the user to access data in a position independent manner. For example:

LEAX	MSG1, PCR
LBSR	PDATA (Print message routine)

This sample program prints: 'MESSAGE'. By writing MSG1, PCR, the assembler computes the distance between the present address and MSG1. This result is placed as a constant into the LEAX instruction which will be indexed from the PC value at the time of execution. No matter where the code is located, when it is executed, the computed offset from the PC will put the absolute address of MSG1 into the X pointer register. This code is totally position independent.

'MESSAGE'

The LEA instructions are very powerful and use an internal holding register (temp). Care must be exercised when using the LEA instructions with the autoincrement and autodecrement addressing modes due to the sequence of internal operations. The LEA internal sequence is outlined as follows:

LEAa, b+	(any of the 16-bit pointer registers X, Y, U
	or S may be substituted for a and b.)

1.	b → temp	(calculate the EA)
2.	$b + 1 \rightarrow b$	(modify b, postincrement)

3. temp
$$\rightarrow$$
 a (load a)

LEAa, -b1. $b-1 \rightarrow temp$ (calculate EA with predecrement) 2. $b-1 \rightarrow b$ (modify b, predecrement)

3. temp \rightarrow a (load a)

Autoincrement-by-two and autodecrement-by-two instructions work similarly. Note that LEAX, X+ does not change X, however LEAX, -X does decrement X. LEAX 1, X should be used to increment X by one.

Table 3 LEA Examples

Instruction	Operation	Comment		
LEAX 10, X	X + 10 → X	Adds 5-bit constant 10 to X		
LEAX 500, X	X + 500 → X	Adds 16-bit constant 500 to X		
LEAY A, Y	$Y + A \rightarrow Y$	Adds 8-bit A accumulator to Y		
LEAY D, Y	$Y + D \rightarrow Y$	Adds 16-bit D accumulator to Y		
LEAU -10, U	U - 10 → U	Subtracts 10 from U		
LEAS -10, S	S - 10 → S	Used to reserve area on stack		
LEAS 10. S	S + 10 → S	Used to 'clean up' stack		
LEAX 5, S	$S+5 \rightarrow X$	Transfers as well as adds		

MUL

Multiplies the unsigned binary numbers in the A and B accumulator and places the unsigned result into the 16-bit D accumulator. This unsigned multiply also allows multiple-precision multiplications,

Long and Short Relative Branches

The HD6809E has the capability of program counter relative branching throughout the entire memory map. In this mode, if the branch is to be taken, the 8 or 16-bit signed offset is added to the value of the program counter to be used as the effective address. This allows the program to branch anywhere in the 64k memory map. Position independent code can be easily generated through the use of relative branching. Both short (8-bit) and long (16-bit) branches are available.

SYNC

After encountering a Sync instruction, the MPU enters a Sync state, stops processing instructions and waits for an interrupt. If the pending interrupt is non-maskable (NMI) or maskable (FIRQ, IRQ) with its mask bit (F or I) clear, the processor will clear the Sync state and perform the normal interrupt stacking and service routine. Since FIRQ and IRQ are not edge-triggered, a low level with a minimum duration of three bus cycles is required to assure that the interrupt will be taken. If the pending interrupt is maskable (FIRQ, IRQ) with its mask bit (F or I) set, the processor will clear the Sync state and continue processing by executing the next inline instruction. Figure 17 depicts Sync timing.

Software Interrupts

A Software Interrupt is an instruction which will cause an interrupt, and its associated vector fetch. These Software Interrupts are useful in operating system calls, software debugging, trace operations, memory mapping, and software development systems. Three levels of SWI are available on this HD6809E, and are prioritized in the following order: SWI, SWI2, SWI3.

16-Bit Operation

The HD6809E has the capability of processing 16-bit data. These instructions include loads, stores, compares, adds, subtracts, transfers, exchanges, pushes and pulls.

■ CYCLE-BY-CYCLE OPERATION

The address bus cycle-by-cycle performance chart illustrates the memory-access sequence corresponding to each possible instruction and addressing mode in the HD6809E. Each instruction begins with an opcode fetch. While that opcode is being internally decoded, the next program byte is always fetched. (Most instructions will use the next byte, so this

technique considerably speeds throughput.) Next, the operation of each opcode will follow the flow chart. \overline{VMA} is an indication of FFFF $_{16}$ on the address bus, $R/\overline{W}=$ "High" and BS = "Low". The following examples illustrate the use of the chart; see Figure 18.

Example 1: LBSR (Branch Taken)
Before Execution SP = F000

		•		
\$8000		LBSR		CAT
		•		
\$A000	CAT			
		CVCLI	F-RV-CV	CLE FLOW
		CICLI		
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	17	1	Opcode Fetch
2	8001	1F	1	Offset High Byte
3	8002	FD	1	Offset Low Byte
4	FFFF	*	1	VMA Cycle
5	FFFF	*	1	VMA Cycle
6	FFFF	*	1	VMA Cycle
7	FFFF	*	1	VMA Cycle
8	EFFF	03	0	Stack Low Order
				Byte of Return
				Address
9	EFFE	80	0	Stack High Order

Byte of Return Address

Examp	le 2:	DEC	(Extended)	
-------	-------	-----	------------	--

DEC

22000

	40000	DEC		PAL	000	
	\$A000	FCB		\$80		
		CYCLE-BY-CYCLE FLOW				
	Cycle #	Address	Data	R/\overline{W}	Description	
	1	8000	7A	1	Opcode Fetch	
	2	8001	A0	1	Operand Address,	
					High Byte	
	3	8002	00	1	Operand Address,	
					Low Byte	
	4	FFFF	*	1	VMA Cycle	
	5	A000	80	1	Read the Data	
	6	FFFF	*	1	VMA Cycle	
	7	A000	7F	0	Store the Decre-	
					mented Data	

\$4000

■ HD6809E INSTRUCTION SET TABLES

Miscellaneous instructions (Table 8)

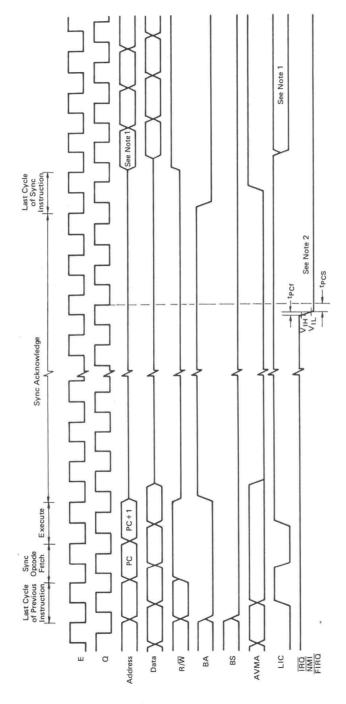
The instructions of the HD6809E have been broken down into five different categories. They are as follows:

8-Bit operation (Table 4) 16-Bit operation (Table 5)

Index register/stack pointer instructions (Table 6) Relative branches (long or short) (Table 7)

HD6809E instruction set tables and Hexadecimal Values of instructions are shown in Table 9 and Table 10.

^{*} The data bus has the data at that particular address.



(NOTES) 1. If the associated mask bit is set when the interrupt is requested, LIC will go "Low" and this cycle will be an instruction fetch from address location PC + 1. However, it the interrupt is accepted (NMI) or an unmasked FIRO or IRO) LIC will remain "High" and interrupt processing will start with this cycle as (m) on Figure 9 and 10 (Interrupt Timing).

2. If mask bits are clear, IRO and FIRO must be held "Low" for three cycles to guarantee that interrupt will be taken, although only one cycle

is necessary to bring the processor out of SYNC. Waveform measurements for all inputs and outputs are specified at logic "High" = V_{IHmin} and logic "Low" = V_{ILmax} unless otherwise e.

Figure 17 SYNC Timing

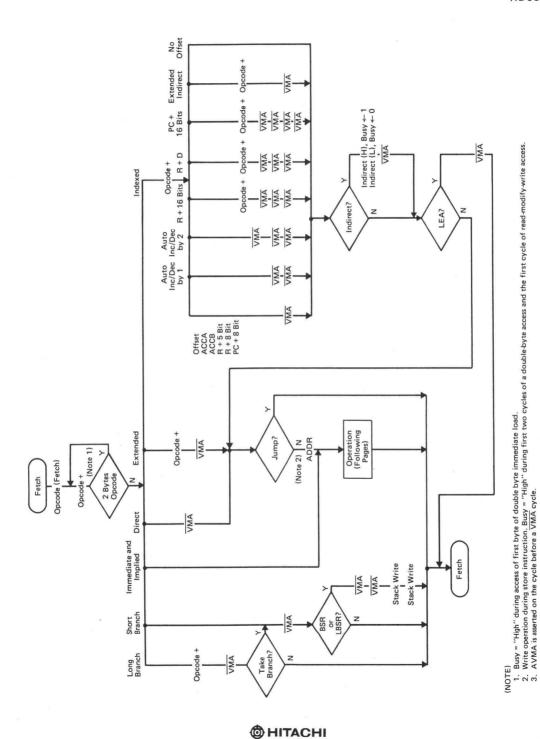
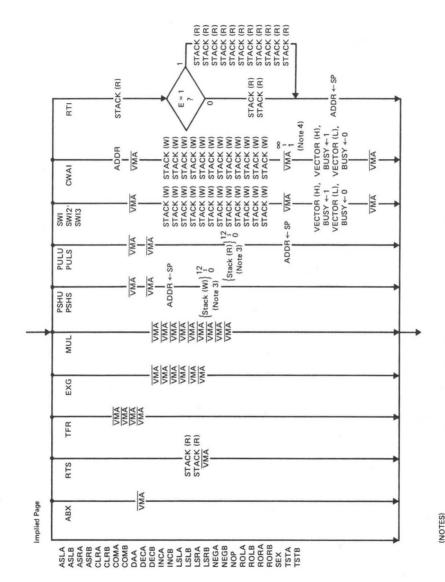


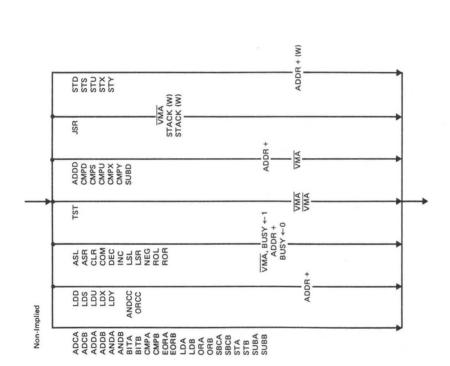
Figure 18 Address Bus Cycle-by-Cycle Performance



Stack (R) refers to the following sequence: ADDR ← SP with R/W = "High", then SP ← SP + 1. 1. Stack (W) refers to the following sequence: SP \leftarrow SP - 1, then ADDR \leftarrow SP with R/W = "Low"

PSHU, PULU instructions use the user stack pointer (i.e., SP = U) and PSHS, PULS use the hardware stack pointer (i.e., SP = S). Vector refers to the address of an interrupt or reset vector (see Table 1).
 The number of stack accesses will vary according to the number of bytes saved, 4 VMA eycles will occur until an interrupt occurs.

Figure 18 Address Bus Cycle-by-Cycle Performance (Continued)



(NOTES)

 Stack (W) refers to the following sequence: SP ← SP − 1, then ADDR ← SP with R/W = "Low".
 Stack (R) refers to the following sequence: ADDR ← SP with R/W = "High", then SP ← SP + 1.
 PSHU, PULU instructions use the user stack pointer (i.e., SP = U) and PSHS, PULS use the hardware stack pointer (i.e., SP = S). Vector refers to the address of an interrupt or reset vector (see Table 1).

The number of stack accesses will vary according to the number of bytes saved, $\overline{\sf VMA}$ cycles will occur until an interrupt occurs. 9 W 4

Figure 18 Address Bus Cycle-by-Cycle Performance (Continued)

Table 4 8-Bit Accumulator and Memory Instructions

Operation
Add memory to accumulator with carry
Add memory to accumulator
And memory with accumulator
Arithmetic shift of accumulator or memory left
Arithmetic shift of accumulator or memory right
Bit test memory with accumulator
Clear accumulator or memory location
Compare memory from accumulator
Complement accumultor or memory location
Decimal adjust A accumulator
Decrement accumulator or memory location
Exclusive or memory with accumulator
Exchange R1 with R2 (R1, R2 = A, B, CC, DP)
Increment accumulator or memory location
Load accumulator from memory
Logical shift left accumulator or memory location
Logical shift right accumulator or memory location
Unsigned multiply $(A \times B \rightarrow D)$
Negate accumulator or memory
Or memory with accumulator
Rotate accumulator or memory left
Rotate accumulator or memory right
Subtract memory from accumulator with borrow
Store accumulator to memory
Subtract memory from accumulator
Test accumulator or memory location
Transfer R1 to R2 (R1, R2 = A, B, CC, DP)

(NOTE) A, B, CC or DP may be pushed to (pulled from) either stack with PSHS, PSHU (PULS, PULU) instructions.

Table 5 16-Bit Accumulator and Memory Instructions

Mnemonic(s)	Operation					
ADDD	Add memory to D accumulator					
CMPD	Compare memory from D accumulator					
EXG D, R	Exchange D with X, Y, S, U or PC					
LDD	Load D accumulator from memory					
SEX	Sign Extend B accumulator into A accumulator					
STD	Store D accumulator to memory					
SUBD	Subtract memory from D accumulator					
TFR D, R	Transfer D to X, Y, S, U or PC					
TFR R, D Transfer X, Y, S, U or PC to D						

(NOTE) D may be pushed (pulled) to either stack with PSHS, PSHU (PULS, PULU) instructions.



Table 6 Index Register Stack Pointer Instructions

Mnemonic(s)	Operation
CMPS, CMPU	Compare memory from stack pointer
CMPX, CMPY	Compare memory from index register
EXG R1, R2	Exchange D, X, Y, S, U or PC with D, X, Y, S, U or PC
LEAS, LEAU	Load effective address into stack pointer
LEAX, LEAY	Load effective address into index register
LDS, LDU	Load stack pointer from memory
LDX, LDY	Load index register from memory
PSHS	Push A, B, CC, DP, D, X, Y, U, or PC onto hardware stack
PSHU	Push A, B, CC, DP, D, X, Y, S, or PC onto user stack
PULS	Pull A, B, CC, DP, D, X, Y, U or PC from hardware stack
PULU	Pull A, B, CC, DP, D, X, Y, S or PC from user stack
STS, STU	Store stack pointer to memory
ŞTX, STY	Store index register to memory
TFR R1, R2	Transfer D, X, Y, S, U or PC to D, X, Y, S, U or PC
ABX	Add B accumulator to X (unsigned)

Table 7 Branch Instructions

Mnemonic(s)	Operation					
	SIMPLE BRANCHES					
BEQ, LBEQ	Branch if equal					
BNE, LBNE	Branch if not equal					
BMI, LBMI	Branch if minus					
BPL, LBPL	Branch if plus					
BCS, LBCS	Branch if carry set					
BCC, LBCC	Branch if carry clear					
BVS, LBVS	Branch if overflow set					
BVC, LBVC	Branch if overflow clear					
	SIGNED BRANCHES					
BGT, LBGT	Branch if greater (signed)					
BGE, LBGE	Branch if greater than or equal (signed)					
BEQ, LBEQ	Branch if equal					
BLE, LBLE	Branch if less than or equal (signed)					
BLT, LBLT	Branch if less than (signed)					
	UNSIGNED BRANCHES					
BHI, LBHI	Branch if higher (unsigned)					
BHS, LBHS	Branch if higher or same (unsigned)					
BEQ, LBEQ	Branch if equal					
BLS, LBLS	Branch if lower or same (unsigned)					
BLO, LBLO	Branch if lower (unsigned)					
OTHER BRANCHES						
BSR, LBSR	Branch to subroutine					
BRA, LBRA	Branch always					
BRN, LBRN	Branch never					

Table 8 Miscellaneous Instructions

Mnemonic(s)	Operation				
ANDCC	AND condition code register				
CWAI	AND condition code register, then wait for interrupt				
NOP	No operation				
ORCC	OR condition code register				
JMP	Jump				
JSR	Jump to subroutine				
RTI	Return from interrupt				
RTS	Return from subroutine				
SWI, SWI2, SWI3	Software interrupt (absolute indirect)				
SYNC Synchronize with interrupt line					

Table 9 HD6809E Instruction Set Table

				-					ble 9		D680)II 26	ı ı a	nie								_
	UCTION/		4D1.1		T 50	050		_	_		RESSI			-	DEXI	-D(I)	DE	A T1			-				_
FC	ORMS	OP	/PLI	#	OP	REC	#	OP	TENI	#	OP	EDI/	#	OP	~	#	OP	LATI'	#	DESCRIPTION	5 H	3 N	2 Z	1 V	0
ABX		3A	3	1	0.		π	-	-	"	0.		"	01		π	01		π	$R + X \rightarrow X$	•				
ADC	ADCA ADCB				99 D9	4 4	2 2	B9 F9	5	3	89 C9	2 2	2 2	A9 E9	4+ 4+	2+ 2+				B + X → X (UNSIGNED) A + M + C → A B + M + C → B	‡	‡	‡	‡	‡
ADD	ADDA ADDB ADDD				9B DB D3	4 4 6	2 2 2	BB FB F3	5 5 7	3 3 3	SB CB C3	2 2 4	2 2 3	AB EB E3	4+ 4+ 6+	2+ 2+ 2+				$A + M \rightarrow A$ $B + M \rightarrow B$ $D + M:M + 1 \rightarrow D$:	‡ ‡ ‡	‡ ‡	‡	‡
AND	ANDA ANDB ANDCC				94 D4	4 4	2 2	B4 F4	5	3	84 C4 1C	2 2 3	2 2 2	A4 E4	4+	2+ 2+				$A \wedge M \rightarrow A$ $B \wedge M \rightarrow B$	•	‡	‡ ‡	0	
ASL	ASLA ASLB	48 58	2 2	1							10	3	2							CC∧ IMM → CC AB	(-88	‡	(7) ‡	‡	+
ASR	ASL ASRA ASRB	47 57	2 2	1	08	6	2	78	7	3				68	6+	2+				M) 6 67 3 8	(8)	‡ ‡	1 1	•	‡ ‡
всс	ASR BCC LBCC				07	6	2	77	7	3				67	6+	2+	24	3	2	M) 57 6 C		:		•	
BCS	BCS																10 24 25	5(6)	2	Long Branch C = 0 Branch C = 1					
	LBCS																10 25	5(6)	4	Long Branch C = 1	•	•	•	•	•
BEQ	BEQ LBEQ																27 10 27	3 5(6)	2	Branch Z = 1 Long Branch Z = 1	:	•	•	•	•
BGE	BGE LBGE																2C 10 2C	3 5(6)	2 4	Branch N⊕V=0 Long Branch N⊕V=0	•	•	•	:	•
BGT	BGT LBGT																2E 10 2E	3 5(6)	2 4	Branch Z√(N⊕V)=0 Long Branch Z√(N⊕V)=0	•	•	•	:	•
вні	BHI LBHI																22 10 22	3 5(6)	2 4	Branch C∨Z=0 Long Branch C∨Z=0	•	•	:	:	•
BHS	BHS																24	3	2	Branch C=0	•	•	•	•	•
	LBHS																10 24	5(6)	4	Long Branch C=0	•	•	•	•	•
BIT	BITA BITB				95 D5	4	2 2	B5 F5	5	3	85 C5	2	2 2	A5 E5	4+ 4+	2+ 2+				Bit Test A (M ∧ A) Bit Test B (M ∧ B)	•	1	‡	0	•
BLE	BLE LBLE																2F 10 2F	3 5(6)	4	Branch Z√(N⊕V)=1 Long Branch Z√(N⊕V)=1	•	:	•	•	•
BLO	BLO LBLO																25 10 25	3 5(6)	2	Branch C=1 Long Branch C=1	•	•	•	•	
BLS	BLS																23	3	2	Branch CV Z=1	•		•	•	•
	LBLS																10 23	5(6)	4	Long Branch C∨Z=1	•	•	•	•	•
BLT	BLT LBLT																2D 10 2D	3 5(6)	2	Branch N⊕V=1 Long Branch N⊕V=1		•	•		•
ВМІ	BMI LBMI																2B 10 2B	3 5(6)	2	Branch N=1 Long Branch N=1	•	:	•	•	•
BNE	BNE LBNE																26 10 26	3 5(6)	2	Branch Z = 0 Long Branch Z = 0	•	•	:		•
BPL	BPL LBPL																2A 10 2A	3 5(6)	2	Branch N = 0 Long Branch N = 0		•			
BRA	BRA LBRA																20 16	3 5	2	Branch Always Long Branch/	•	•	•	•	•
BRN	BRN LBRN																21 10 21	3 5	2 4	Always Branch Never Long Branch Never	:	•	:	•	•

(to be continued)



INSTR	/NO1TOU		101 :		T =		D680	_			1			104	DEV	ED(I)	DE	A T.			-		0		
FO	RMS		IPLI	_	-	IREC	_	-	TENE	_		MEDIA	_	-	DEX		-	LATI	_	DESCRIPTION	5	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP		#		Н	N	Z	٧	1
BSR	BSR LBSR																8D	7	3	Branch to Subroutine Long Branch to	•	•	•	•	
BVC	BVC																28	3	2	Subroutine Branch V = 0					
21.10	LBVC																10 28	5(6)	4	Long Branch V = 0	•	•	•	•	
BVS	BVS LBVS																29 10 29	3 5(6)	2 4	Branch V = 1 Long Branch V = 1	•	•	•	•	
CLR	CLRA CLRB CLR	4F 5F	2	1	0F	6	2	7F	7	3				6F	6+	2+				$\begin{array}{c} 0 \rightarrow A \\ 0 \rightarrow B \\ 0 \rightarrow M \end{array}$	•	0 0	1 1 1	0 0 0	
CMP	CMPA CMPB CMPD				91 D1 10	4 4 7	2 2 3	B1 F1 10	5 5 8	3 3 4	81 C1 10	2 2 5	2 2 4	A1 E1 10	4+ 4+ 7+	2+ 2+ 3+				Compare M from A Compare M from B Compare M: M + 1	(8)	‡ ‡	‡ ‡	‡ ‡	
	CMPS				93	7	3	B3	8	4	83	5	4	A3	7+	3+				from D Compare M: M + 1		ţ	‡	ţ	
	CMPU				9C 11 93	7	3	BC 11 B3	8	4	8C 11 83	5	4	11 A3	7+	3+				from S Compare M: M + 1 from U	•	1	‡	‡	
	CMPX				9C	6	2	ВС	7	3	8C	4	3	AC	6+	2+				Compare M: M + 1 from X	•	1	‡	‡	
	CMPY				10 9C	7	3	10 BC	8	4	10 8C	5	4	10 AC	7+	3+				Compare M: M + 1 from Y	•	1	‡	‡	
COM	COMA COMB COM	43 53	2	1	03	6	2	73	7	3				63	6+	2+				$\overline{A} \rightarrow A$ $\overline{B} \rightarrow B$ $\overline{M} \rightarrow M$	•	1	‡ ‡	0 0 0	
CWAI											3C	≧20	2							CC ∧ IMM → CC (except 1→E) Wait for Interrupt	(-	*	(7)		
DAA	DECA	19 4A	2	1																Decimal Adjust A A – 1 → A	•	‡ ±	‡ ±	(8)	
DEC	DECB	5A	2	i	0A	6	2	7A	7	3				6A	6+	2+				$B - 1 \rightarrow B$ $M - 1 \rightarrow M$	•	‡ ‡	‡	1	
EOR	EORA EORB				98 D8	4	2 2	B8 F8	5	3	88 C8	2 2	2 2	A8 E8	4+ 4+	2+ 2+				$A \oplus M \rightarrow A$ $B \oplus M \rightarrow B$		1	‡	0	
EXG	R1, R2	1E	7	2																R1 ↔ R2 ^②	(-	-	10	_	ł
NC	INCA INCB INC	4C 5C	2	1	0C	6	2	7C	7	3				6C	6+	2+				$A + 1 \rightarrow A$ $B + 1 \rightarrow B$ $M + 1 \rightarrow M$		‡ ‡	1 1 1	‡ ‡	
JMP					0E	3	2	7E	4	3				6E	3+	2+				EA ³ → PC				•	ı
JSR					9D.	7	2	BD	8	3				AD	7+	2+				Jump to Subroutine		•	•		
LD	LDA LDB LDD LDS				96 D6 DC 10	4 4 5 6	2 2 2 3	B6 F6 FC 10	5 5 6 7	3 3 4	86 C6 CC 10	2 2 3 4	2 2 3 4	A6 E6 EC 10	4+ 4+ 5+ 6+	2+ 2+ 2+ 3+				$M \rightarrow A$ $M \rightarrow B$ $M: M + 1 \rightarrow D$ $M: M + 1 \rightarrow S$		‡ ‡ ‡	‡ ‡ ‡	0 0 0	
	LDU LDX LDY				DE DE 9E 10 9E	5 5 6	2 2 3	FE FE BE 10 BE	6 6 7	3 4	CE CE 8E 10 8E	3 3 4	3 3 4	EE AE 10 AE	5+ 5+ 6+	2+ 2+ 3+				$\begin{array}{l} M\colon M+1\to U\\ M\colon M+1\to X\\ M\colon M+1\to Y \end{array}$		‡ ‡	‡ ‡	0 0 0	
LEA	LEAS LEAU LEAX LEAY				3C			DE			3E			32 33 30 31	4+ 4+ 4+ 4+	2+ 2+ 2+ 2+				$EA^{\textcircled{3}} \rightarrow S$ $EA^{\textcircled{3}} \rightarrow U$ $EA^{\textcircled{3}} \rightarrow X$ $EA^{\textcircled{3}} \rightarrow Y$			• : :		
SL	LSLA LSLB LSL	48 58	2 2	1	08	6	2	78	7	3				68	6+	2+				Å} [‡ ‡	‡	‡	
SR	LSRA LSRB	44 54	2 2	1																A)	•	0	‡		
MUL	LSR	3D	11	1	04	6	2	74	7	3				64	6+	2+				M) UTTTT U	•	0	‡	•	
NEG	NEGA NEGB	40 50	2 2	1 1																(Unsigned) Ā + 1 → A B + 1 → B	8	‡	‡	‡	
NOP	NEG	12	2	1	00	6	2	70	7	3				60	6+	2+				M + 1 → M No Operation	8	1	‡ •		

(to be continued)



INSTR	UCTION/	_			_			D6809							_						_	_	_	_	_
	RMS	-	MPLIE		-	IREC		EXTE				1EDI		+	_	ED ^①	-	LAT	_	DESCRIPTION	5	3	2	1	0
OR	ORA ORB	OP	~	#	OP 9A DA	4 4	2 2	OP BA FA	~ 5 5	3 3	OP 8A CA	2 2	2 2	OP AA EA		# 2+ 2+	OP	~®	#	$A \lor M \rightarrow A$ $B \lor M \rightarrow B$	н •	N	z	0 0	
	ORCC					1	-				1A	3	2							CC ∨ IMM → CC	(-	-	(7)	-	+3
PSH	PSHS	34	5+®	2																Push Registers on S Stack	•	•	•	•	1
	PSHU	36	5+®	2																Push Registers on U Stack	•	•	•	•	1
PUL	PULS	35	5+④	2																Pull Registers from S Stack	(-	\vdash	10	-	+
	PULU	37	5+④	2																Pull Registers from U Stack	(-		10	-	+
ROL	ROLA ROLB ROL	49 59	2	1	09	6	2	79	7	3				69	6+	2+				Å} (-,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	•	1 1	‡	‡ ‡	1
ROR	RORA RORB ROR	46 56	2 2	1	06	6	2	76	7	3				66	6+	2+				A B M	•	‡ ‡	‡ ‡		1
RTI		3B	6/15	1																Return From Interrupt	(-		(7)		+ 3
RTS		39	5	1																Return From Subroutine	•	•	•	•	
SBC	SBCA SBCB				92 D2	4	2 2	B2 F2	5	3	82 C2	2 2	2 2	A2 E2	4+	2+ 2+				$A - M - C \rightarrow A$ $B - M - C \rightarrow B$	8	‡	‡	‡	1
SEX		1D	2	1																Sign Extend B into A	•	1	‡	•	
ST	STA STB				97 D7	4	2 2	B7 F7	5	3				A7 E7	4+	2+ 2+				$A \rightarrow M$ $B \rightarrow M$		‡	‡	0	
	STD				DD 10	5 6	2	FD 10	6	3				10	5+ 6+	2+ 3+				D → M: M+ 1 S → M: M + 1		1	‡	0	
	STU				DF	5	2	FF	6	3				EF EF	5+	2+				U → M: M + 1	•	1	ţ	0	
	STX				9F 10 9F	5 6	3	BF 10 BF	6 7	3			a	10 AF	5+ 6+	2+ 3+				X → M: M + 1 Y → M: M + 1	•	1	‡	0	
SUB	SUBA SUBB				90 D0	4	2 2	B0 F0	5	3	80 C0	2 2	2	A0 E0	4+ 4+	2+ 2+				$A - M \rightarrow A$ $B - M \rightarrow B$	(8)	1	‡	1	1
	SUBD				93	6	2	В3	7	3	83	4	3	A3	6+	2+				D − M: M + 1 → D	•	1	1	‡	1
SWI	SWI® SWI2®	3F 10 3F	19 20	2																Software Interrupt1 Software Interrupt2	•	•	•	•	
	SWI3®	11 3F	20	2																Software Interrupt3	•	•	•	•	•
SYNC		13	≧4	1																Synchronize to Interrupt	•	•	•	•	•
TFR	R1, R2	1F	6	2																R1 → R2 ^②	(-	-	10	_	+
TST	TSTA TSTB TST	4D 5D	2 2	1	0D	6	2	7D	7	3				6D	6+	2+				Test A Test B Test M	•	‡ ‡	‡ ‡	0 0 0	

(NOTES)

- This column gives a base cycle and byte count. To obtain total count, and the values obtained from the INDEXED ADDRESSING MODES table. R1 and R2 may be any pair of 8 bit or any pair of 16 bit registers.
 The 8 bit registers are: A, B, CC, DP
 The 16 bit registers are: X, Y, U, S, D, PC

- EA is the effective address.

 The PSH and PUL instructions require 5 cycle plus 1 cycle for each byte pushed or pulled.
- The FSA and PCL instructions require a cycle pion is cycle in (6) means: 5 cycles if branch not taken, 6 cycles if taken. SWI sets 1 and F bits, SWI2 and SWI3 do not affect I and F. Conditions Codes set as a direct result of the instruction. Value of half-carry flag is undefined.
- 7
- (8)
- Special Case Carry set if b7 is SET. 9
- Condition Codes set as a direct result of the instruction if CC is specified, and not affected otherwise.
 - LEGEND: OP One
 - Operation Code (Hexadecimal) Number of MPU Cycles
 - Number of Program Bytes
 - Arithmetic Plus

 - Arithmetic Minus Multiply Complement of M ×
 - Transfer Into
 - Half-carry (from bit 3) Negative (sign bit)

- Zero (byte)
- Overflow, 2's complement C
- Carry from bit 7
 Test and set if true, cleared otherwise \$
- Not Affected
- CC Condition Code Register
- Concatenation
- Logical or Logical and
- Logical Exclusive or



Table 10 Hexadecimal Values of Machine Codes

OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#
00	NEG	Direct	6	2	30	LEAX	Indexed	4+	2+	60	NEG	Indexed	6+	2+
01	•	A			31	LEAY	A	4+	2+	61	*			
02					32	LEAS	1	4+	2+	62				
03	COM		6	2	33	LEAU	Indexed	4+	2+	63	COM		6+	2+
04	LSR		6	2	34	PSHS	Implied	5+	2	64	LSR		6+	2+
05	•				35	PULS	A	5+	2	65				
06	ROR	- 1	6	2	36	PSHU		5+	2	66	ROR		6+	2+
07	ASR		6	2	37	PULU		5+	2	67	ASR		6+	2+
08	ASL, LSL		6	2	38	•				68	ASL, LS	L	6+	2+
09	ROL		6	2	39	RTS		5	1	69	ROL		6+	2+
OA	DEC		6	2	3A	ABX	+	3	1	6A	DEC		6+	2+
ОВ					3B	RTI	Implied	6,15	1	6B	*			
OC	INC		6	2	3C	CWAI	Immed	≥20	2	6C	INC	-	6+	2+
0D	TST		6	2	3D	MUL	Implied	11	1	6D	TST	1	6+	2+
0E	JMP	. ↓	3	2	3E					6E	JMP	1	3+	2+
OF	CLR	Direct	6	2	3F	SWI	Implied	19	1	6F	CLR	Indexed	6+	2+
01	0211	5		-										
10) See	-	_	_	40	NEGA	Implied	2	1	70	NEG	Extended	7	3
11	Next Page	_	_	-	41		A			71		A		
12	NOP	Implied	2	1	42					72				
13	SYNC	Implied	≥4	1	43	COMA		2	1	73	COM		7	3
14			= -		44	LSRA		2	1	74	LSR	1	7	3
15					45					75				
16	LBRA	Relative	5	3	46	RORA		2	1	76	ROR		7	3
17	LBSR	Relative	9	3	47	ASRA	1	2	1	77	ASR		7	3
18					48	ASLA, LSLA	1	2	1	78	ASL, LS	L	7	3
19	DAA	Implied	2	1	49	ROLA		2	1	79	ROL		7	3
1A	ORCC	Immed	3	2	4A	DECA		2	1	7A	DEC	İ	7	3
1B	*	_	0	-	4B	*		_		7B		-		
1C	ANDCC	Immed	3	2	4C	INCA		2	1	7C	INC		7	3
1D	SEX	Implied	2	1	4D	TSTA		2	1	7D	TST		7	3
1E	EXG	‡	8	2	4E	*	1	-		7E	JMP	1	4	3
1F	TFR	Implied	6	2	4F	CLRA	Implied	2	1	7F	CLR	Extended	7	3
1.1	IFR	Implied	U	2	41	CLITA	Implied	-						-
20	BRA	Relative	3	2	50	NEGB	Implied	2	1	80	SUBA	Immed	2	2
21	BRN	A	3	.2	51	•	A	_		81	CMPA	A	2	2
22	BHI	Ţ	3	2	52		T			82	SBCA		2	2
23	BLS		3	2	53	COMB		2	1	83	SUBD		4	3
24	BHS, BCC		3	2	54	LSRB		2	1	84	ANDA		2	2
25	BLO, BCS		3	2	55	*		-		85	BITA		2	2
	BNE		3	2	56	RORB		2	1	86	LDA		2	2
26			3	2	57	ASRB		2	1	87	*		-	-
27	BEQ		3	2				2	1	88	EORA		2	2
28	BVC				58	ASLB, LSLB		2	1	89	ADCA		2	2
29	BVS		3	2	59	ROLB				8A	ORA		2	2
2A	BPL		3	2	5A	DECB		2	1	8A 8B	ADDA	1	2	2
2B	BMI		3	2	5B			2	1	8C	CMPX	♥ Immed	4	3
2C	BGE		3	2	5C	INCB		2	1	8D	BSR	Relative	7	2
2D	BLT	1	3	2	5D	TSTB	1	2	1	8E	LDX	Immed	3	3
2E	BGT	Deletine	3	2	5E 5F		▼ Implied	2	1	8F	*	minied	3	3
2F	BLE	Relative	3	2	51	CLRB	implied	2	1	or				

LEGEND:

Number of MPU cycles (less possible push pull or indexed-mode cycles)

Number of program bytes

Denotes unused opcode

(to be continued)



OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#
90	SUBA	Direct	4	2	C6	LDB	Immed	2	2	FC	LDD	Extended	6	3
91	CMPA	A	4	2	C7		A			FD	STD	•	6	3
92	SBCA		4	2	C8	EORB		2	2	FE	LDU	↓	6	3
93	SUBD		6	2	C9	ADCB		2	2	FF	STU	Extended	6	3
94	ANDA		4	2	CA	ORB		2	2					
95	BITA		4	2	CB	ADDB		2	2					
96	LDA		4	2	CC	LDD		3	3		2 Byte	s Opcode		
97	STA		4	2	CD		*							
98	EORA		4	2	CE	LDU	Immed	3	3	1021	LBRN	Relative	5	4
99	ADCA		4	2	CF	•				1022	LBHI	A	5(6)	4
9A	ORA		4	2						1023	LBLS		5(6)	4
9B	ADDA	1	4	2	D0	SUBB	Direct	4	2	1024	LBHS, I		5(6)	4
9C	CMPX		6	2	D1	CMPB	A	4	2	1025	LBCS, I	BLO	5(6)	4
9D	JSR	1	7	2	D2	SBCB		4	2		LBNE		5(6)	4
9E	LDX	*	5	2	D3	ADDD		6	2		LBEQ		5(6)	4
9F	STX	Direct	5	2	D4	ANDB		4	2	1028	LBVC		5(6)	4
					D5	BITB		4	2	1029	LBVS		5(6)	4
A0	SUBA	Indexed	4+	2+	D6	LDB		4	2	102A	LBPL		5(6)	4
A1	CMPA	A	4+	2+	D7	STB		4	2	102B	LBMI		5(6)	4
A2	SBCA	1	4+	2+	D8	EORB		4	2	102C	LBGE	1	5(6)	4
A3	SUBD		6+	2+	D9	ADCB		4	2	102D	LBLT	- 1	5(6)	4
A4	ANDA	1	4+	2+	DA	ORB		4	2	102E	LBGT	*	5(6)	4
A5	BITA	1	4+	2+	DB	ADDB		4	2	102F	LBLE	Relative	5(6)	4
A6	LDA		4+	2+	DC	LDD		5	2	103F	SWI2	Implied	20	2
A7	STA		4+	2+	DD	STD		5	2		CMPD	Immed	5	4
A8	EORA	1	4+	2+	DE	LDU	*	5	2		CMPY	‡	5	4
A9	ADCA		4+	2+	DF	STU	Direct	5	2		LDY	Immed	4	4
AA	ORA		4+	2+	120	100.00					CMPD	Direct	7	3
AB	ADDA		4+	2+	EO	SUBB	Indexed	4+	2+		CMPY	•	7	3
AC	CMPX		6+	2+	E1	CMPB	•	4+	2+	109E		*	6	3
AD	JSR	1	7+	2+	E2	SBCB		4+	2+	109F		Direct	6	3
AE	LDX		5+	2+	E3	ADDD	1	6+	2+	10.75	CMPD	Indexed	7+	3+
AF	STX	Indexed	5+	2+	E4	ANDB		4+	2+	10AC	CMPY	↑	7+	3+
Section 1					E5	BITB		4+	2+	10AE	LDY	*	6+	3+
во	SUBA	Extended	5	3	E6	LDB		4+	2+	10AF	STY	Indexed	6+	3+
B1	CMPA	•	5	3	E7	STB	-	4+	2+	10B3	CMPD	Extended	8	4
B2	SBCA		5	3	E8	EORB		4+	2+		CMPY	A	8	4
В3	SUBD		7	3	E9	ADCB		4+	2+	10BE	LDY	+	7	4
B4	ANDA		5	3	EA	ORB		4+	2+	10BF		Extended .	7	4
B5	BITA		5	3	EB	ADDB	1	4+	2+	10CE		Immed	4	4
В6	LDA		5	3	EC	LDD	1	5+	2+	10DE		Direct	6	3
B7	STA		5	3	ED	STD		5+	2+	10DF		Direct	6	3
B8	EORA		5	3	EE	LDU	*	5+	2+	10EE		Indexed	6+	3+
В9	ADCA		5	3	EF	STU	Indexed	5+	2+	10EF		Indexed	6+	3+
BA	ORA	l l	5	3	1000					10FE		Extended	7	4
BB	ADDA		5	3	FO	SUBB	Extended	5	3	10FF		Extended	7	4
BC	CMPX	1	7	3	F1	CMPB	A	5	3		SW13	Implied	20	2
BD	JSR		8	3	F2	SBCB		5	3		CMPU	Immed	5	4
BE	LDX	*	6	3	F3	ADDD		7	3		CMPS	Immed	5	4
BF	STX	Extended	6	3	F4	ANDB		5	3	1193	CMPU	Direct	7	3
					F5	BITB	1	5	3	119C	CMPS	Direct	7	3
CO	SUBB	Immed	2	2	F6	LDB	1	5	3	11A3	CMPU	Indexed	7+	3+
C1	CMPB	•	2	2	F7	STB		5	3	11AC	CMPS	Indexed	7+	3+
C2	SBCB		2	2	F8	EORB		5	3		CMPU	Extended	8	4
C3	ADDD		4	3	F9	ADCB		5	3	11BC	CMPS	Extended	8	4
C4	ANDB		2	2	FA	ORB	+	5	3					
C5	BITB	Immed	2	2	FB	ADDB	Extended	5	3					

(NOTE): All unused opcodes are both undefined and illegal

■ NOTE FOR USE

Execution Sequence of CLR Instruction

Cycle-by-cycle flow of CLR instruction (Direct, Extended, Indexed Addressing Mode) is shown below. In this sequence the content of the memory location specified by the operand is read before writing "00" into it. Note that status Flags, such as IRQ Flag, will be cleared by this extra data read operation when accessing the control/status register (sharing the same address between read and write) of peripheral devices.

Example: CLR (Extended)

\$8000 \$A000	CLR FCB	\$A000 \$80		
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	7F	1	Opcode Fetch
2	8001	A0	1	Operand Address,
				High Byte
3	8002	00	1	Operand Address,
				Low Byte
4	FFFF	*	1	VMA Cycle
5	A000	80	1	Read the Data
6	FFFF	*	1	VMA Cycle
7	A000	00	0	Store Fixed "00"
				into Specified
				Location

^{*} The data bus has the data at that particular address.

CMOS 8-BIT MICROPROCESSOR



HD6303R, HD63A03R, HD63B03R CMOS MPU (Micro Processing Unit)

The HD6303R is an 8-bit CMOS micro processing unit which has the completely compatible instruction set with the HD6301V1. 128 bytes RAM, Serial Communication Interface (SCI), parallel I/O ports and multi function timer are incorporated in the HD6303R. It is bus compatible with HMCS6800 and can be expanded up to 65k bytes. Like the HMCS6800 family, I/O level is TTL compatible with +5.0V single power supply. As the HD6303R is CMOS MPU, power dissipation is extremely low. And also HD6303R has Sleep Mode and Stand-by Mode as lower power dissipation mode. Therefore, flexible low power consumption application is possible.

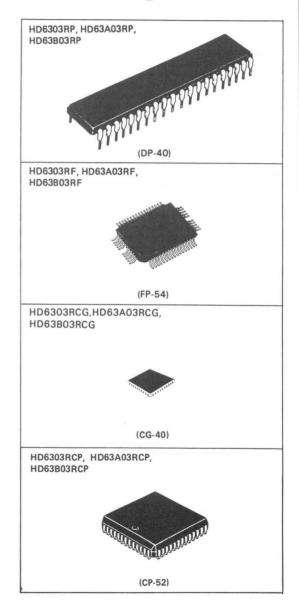
FEATURES

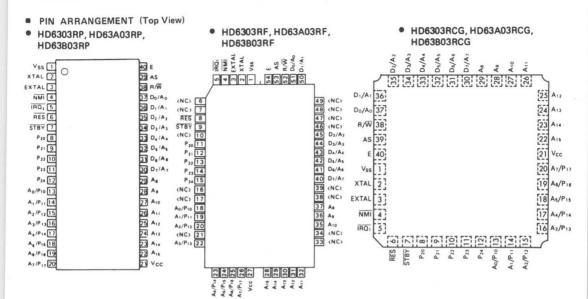
- Object Code Upward Compatible with the HD6800, HD6801, HD6802
- Multiplexed Bus (D₀/A₀~D₇/A₇A₈~A₁₅), Non Multiplexed Bus (D₀~D₇, A₀~A₁₅)
- Abundant On-Chip Functions Compatible with the HD6301V1; 128 Bytes RAM, 13 Parallel I/O Lines, 16-bit Timer, Serial Communication Interface (SCI)
- Low Power Consumption Mode; Sleep Mode, Stand-By Mode
- Minimum Instruction Execution Time
 1μs (f=1MHz), 0.67μs (f=1.5MHz), 0.5μs (f=2.0MHz)
- Bit Manipulation, Bit Test Instruction
- Error Detecting Function; Address Trap, Op Code Trap
- Up to 65k Bytes Address Space
- Wide Operation Range

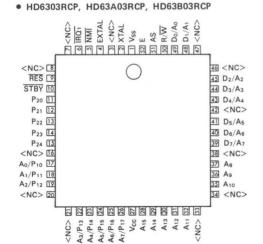
 V_{CC} = 3 to 6V (f = 0.1 \sim 0.5 MHz) f = 0.1 to 2.0 MHz (V_{CC} = 5V \pm 10%)

TYPE OF PRODUCTS

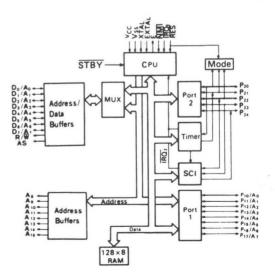
Type No.	Bus Timing
HD6303R	1.0 MHz
HD63A03R	1.5 MHz
HD63B03R	2.0 MHz







BLOCK DIAGRAM



■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc}	-0.3 ~ +7.0	V
Input Voltage	V _{in}	-0.3 ~ V _{cc} +0.3	V
Operating Temperature	Topr	0~+70	°C
Storage Temperature	T _{stg}	-55 ~ +150	°C

(NOTE) This product has protection circuits in input terminal from high static electricity voltage and high electric field. But be careful not to apply overvoltage more than maximum ratings to these high input impedance protection circuits. To assure the normal operation, we recommend V_{in} , V_{out} : $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$.

■ ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (V_{CC} = 5.0V±10%, V_{SS} = 0V, Ta = 0~+70°C, unless otherwise noted.)

It	em	Symbol	Test Condition	min	typ	max	Unit
	RES, STBY			V _{CC} -0.5	-	V _{CC}	
Input "High" Voltage	EXTAL	V _{IH}		V _{CC} x0.7	-	+0.3	V
	Other Inputs			2.0	-	10.0	
Input "Low" Voltage	All Inputs	VIL		-0.3	-	0.8	V
Input Leakage Current	NMI, IRQ1, RES, STBY	li _{in} l	$V_{in} = 0.5 \sim V_{CC} - 0.5 V$	-	_	1.0	μΑ
Three State (off-state) Leakage Current	$P_{10} \sim P_{17}, P_{20} \sim P_{24},$ $D_0 \sim D_7, A_8 \sim A_{15}$	I _{TSI}	V _{in} = 0.5~V _{CC} -0.5V	-	-	1.0	μΑ
Output "High" Voltage	All Outputs	V	I _{OH} = -200μA	2.4	-	-	V
Output High Voltage	All Outputs	V _{OH}	I _{OH} = -10μA	V _{CC} -0.7	_	-	٧
Output "Low" Voltage	All Outputs	VoL	I _{OL} = 1.6mA	-	-	0.55	V
Input Capacitance	All Inputs	C _{in}	V _{in} =0V, f=1.0MHz, Ta = 25°C	-	_	12.5	pF
Standby Current	Non Operation	Icc		-	2.0	15.0	μΑ
			Operating (f=1MHz**)	-	6.0	10.0	
Current Dissipation*		Icc	Sleeping (f=1MHz**)	-	1.0	2.0	mA
RAM Stand-By Voltage		VRAM		2.0	-	-	V

^{*} V_{IH} min = V_{CC}-1.0V, V_{IL} max = 0.8V

typ. value (f = xMHz) = typ. value $(f = 1MHz) \times x$ max. value (f = xMHz) = max. value $(f = 1MHz) \times x$

(both the sleeping and operating)

^{**} Current Dissipation of the operating or sleeping condition is proportional to the operating frequency. So the typ. or max, values about Current Dissipations at f = x MHz operation are decided according to the following formula;

• AC CHARACTERISTICS ($V_{CC} = 5.0V \pm 10\%$, $V_{SS} = 0V$, $T_a = 0 \sim +70^{\circ}C$, unless otherwise noted.)

BUS TIMING

Item			Symbol	Test Con-	Н	D630	3R	HD	63A)3R	H	063B	03R	Unit
Item			Symbol	dition	min	typ	max	min	typ	max	min	typ	max	Unit
Cycle Time			t _{cyc}		1	-	10	0.666		10	0.5	_	10	μs
Address Strobe F "High"	Pulse Wi	dth *	PW _{ASH}		220	_	-	150	-	-	110	-	-	ns
Address Strobe F	Rise Tin	ne	t _{ASr}		_	_	20	-	_	20	-	_	20	ns
Address Strobe F	all Tim	ie	t _{ASf}		-	_	20	-	_	20	-	-	20	ns
Address Strobe Delay Time *		ime *	t _{ASD}		60	_	_	40	_	_	20	_	_	ns
Enable Rise Time		t _{Er}		-	1-1	20	-	_	20	-	_	20	ns	
Enable Fall Time		t _{Ef}		_	_	20	_	-	20	-	_	20	ns	
Enable Pulse Width "High" Level*		PW_{EH}		450	_	-	300	-	_	220	-	_	ns	
Enable Pulse Width "Low" Level*		PW _{EL}		450	_	_	300	-	-	220	_	_	ns	
Address Strobe to Enable Delay* Time		t _{ASED}		60	-	-	40	-	-	20	-	-	ns	
Address Delay Time		t _{AD1}		-	-	250	-	-	190	-	-	160	ns	
Address Delay Tille		t _{AD2}	Fig. 1	-	-	250	-	-	190	-	-	160	ns	
Address Delay Ti	me for	Latch*	t _{ADL}	Fig. 2	-	-	250	-	-	190	-	-	160	ns
Data Cat up Time		Write	t _{DSW}		230	-	-	150	-	-	100	-	-	ns
Data Set-up Time	е	Read	t _{DSR}		80	-	-	60	-	-	50	-	-	ns
D. U.U.T		Read	t _{HR}		0	-	-	0	-	-	0	-	-	ns
Data Hold Time		Write	t _{HW}		20	-	-	20	-	-	20	_	-	ns
Address Set-up T	ime for	Latch*	t _{ASL}		60	-	-	40	_	-	20	-	-	ns
Address Hold Tir	ne for l	_atch	t _{AHL}		30	-	-	20	-	-	20	-	-	ns
Address Hold Tir	ne		t _{AH}		20	-	-	20	-	-	20	-	-	ns
A ₀ ~ A ₇ Set-up Time Before E*		efore E*	t _{ASM}		200	-	-	110	-	-	60	_	-	ns
Peripheral Read	Non-N Bus	fultiplexed	(t _{ACCN})		-	-	650	-	-	395	_	-	270	ns
Access Time Multiplexed Bus*		lexed Bus*	(t _{ACCM})		-	-	650	-	-	395	-	-	270	ns
Oscillator stabiliz	zation T	ime	t _{RC}	Fig. 8	20	-	-	20	-	-	20	-	-	ms
Processor Contro	Set-ur	Time	t _{PCS}	Fig. 9	200	_	_	200	-	-	200	-	-	ns

^{*}These timings change in approximate proportion to t_{CYC} . The figures in this characteristics represent those when t_{CYC} is minimum (= in the highest speed operation).

PERIPHERAL PORT TIMING

Item				Test Con-				HD63A03R			HD63B03R			Unit
rtem			Symbol	dition	min	typ	max	min	typ	max	min	typ	max	Unit
Peripheral Data Set-up Time	Port 1	, 2	t _{PDSU}	Fig. 3	200	-	-	200	-	-	200	_	-	ns
Peripheral Data Hold Time	Port 1,	, 2	t _{PDH}	Fig. 3	200	-	-	200	-	-	200	-	-	ns
Delay Time, Enablive Transition to pheral Data Valid	Peri-	Port 1, 2*	t _{PWD}	Fig. 4	-	-	300	-	-	300	-	-	300	ns

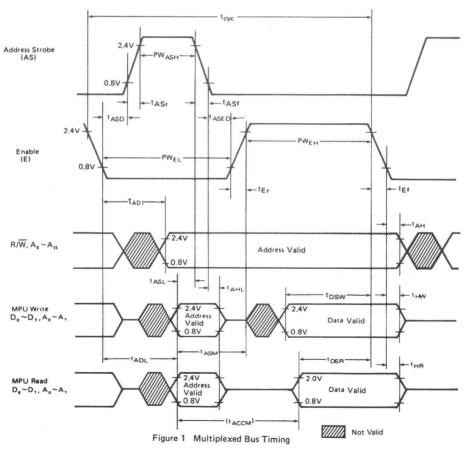
^{*} Except P₂₁

TIMER, SCI TIMING

la	Cumhal	Test Con-	Н	D630	3R	HD63A03R			Н	D63B	03R	Unit
Item	Symbol	dition	min	typ	max	min	typ	max	min	typ	max	Oiiit
Timer Input Pulse Width	t _{PWT}		2.0	-	-	2.0	_	-	2.0	_	-	t _{cyc}
Delay Time, Enable Positive Transition to Timer Out	t _{TOD}	Fig. 5	-	-	400	-	-	400	-	-	400	ns
SCI Input Clock Cycle	t _{Scyc}		2.0	-	_	2.0	-	_	2.0	_	_	t _{cyc}
SCI Input Clock Pulse Width	t _{PWSCK}		0.4	-	0.6	0.4	-	0.6	0.4	-	0.6	t _{Scyc}

MODE PROGRAMMING

la	0	Test	HD6303R		HD63A03R			HD63B03R			Unit	
Item	Symbol	Con- dition	min	typ	max	min	typ	max	min	typ	max	Onit
RES "Low" Pulse Width	PWRSTL		3	_	-	3	_	_	3	-	_	t _{cyc}
Mode Programming Set-up Time	t _{MPS}	Fig. 6	2	-	_	2	-	-	2	-	-	t _{cyc}
Mode Programming Hold Time	t _{MPH}		150	_	_	150	-	-	150	-	-	ns



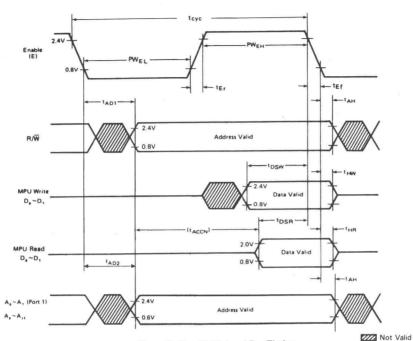


Figure 2 Non-Multiplexed Bus Timing

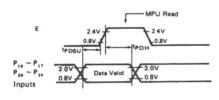


Figure 3 Port Data Set-up and Hold Times (MPU Read)

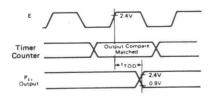
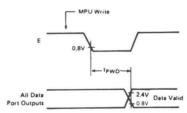


Figure 5 Timer Output Timing



Note) Port 2: Except P₂₁
Figure 4 Port Data Delay Times (MPU Write)

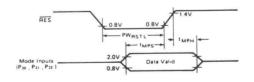
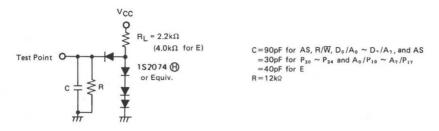


Figure 6 Mode Programming Timing



Interrupt

Figure 7 Bus Timing Test Loads (TTL Load)

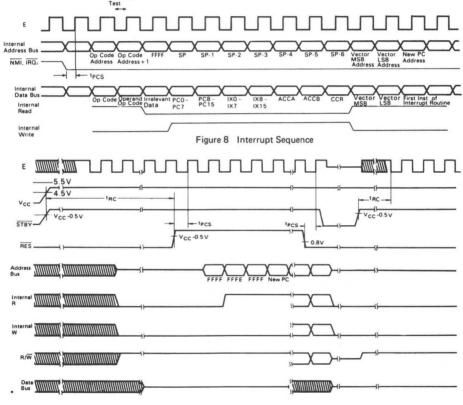


Figure 9 Reset Timing

FUNCTIONAL PIN DESCRIPTION

V_{CC}, V_{SS}

These two pins are used for power supply and GND. Recommended power supply voltage is $5V \pm 10\%$. 3 to 6V can be used for low speed operation ($100 \sim 500 \text{ kHz}$).

XTAL, EXTAL

These two pins are connected with parallel resonant funda-

mental crystal, AT cut. For instance, in order to obtain the system clock 1MHz, a 4MHz resonant fundamental crystal is used because the devide-by-4 circuitry is included. An example of the crystal interface is shown in Fig. 10. EXTAL accepts an external clock input of duty 45% to 55% to drive. For external clock, XTAL pin should be open. The crystal and capacitors should be mounted as close as possible to the pins.

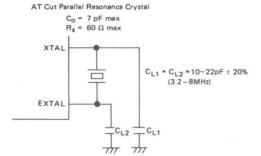


Figure 10 Crystal Interface

Standby (STBY)

This pin is used to place the MPU in the standby mode. If this goes to "Low" level, the oscillation stops, the internal clock is tied to V_{SS} or V_{CC} and the MPU is reset. In order to retain information in RAM during standby, write "0" into RAM enable bit (RAME). RAME is bit 6 of the RAM Control Register at address \$0014. This disables the RAM, so the contents of RAM is guaranteed. For details of the standby mode, see the Standby section.

• Reset (RES)

This input is used to reset the MPU. RES must be held "Low" for at least 20ms when the power starts up. It should be noted that, before clock generator stabilize, the internal state and I/O ports are uncertain, because MPU can not be reset without clock. To reset the MPU during system operation, it must be held "Low" for at least 3 system clock cycles. From the third cycle, all address buses become "high-impedance" and it continues while RES is "Low". If RES goes to "High", CPU does the following.

- (1) I/O Port 2 bits 2,1,0 are latched into bits PC2, PC1, PC0 of program control register.
- (2) The contents of the two Start Addresses, \$FFFE, \$FFFF are brought to the program counter, from which program starts (see Table 1).
- (3) The interrupt mask bit is set. In order to have the CPU recognize the maskable interrupts IRQ1 and IRQ2, clear it before those are used.

• Enable (E)

This output pin supplies system clock. Output is a singlephase, TTL compatible and 1/4 the crystal oscillation frequency. It will drive two LS TTL load and 40pF capacitance.

Non Maskable Interrupt (NMI)

When the falling edge of the input signal of this pin is recognized, NMI sequence starts. The current instruction is continued to complete, even if NMI signal is detected. Interrupt mask bit in Condition Code Register has no effect on NMI detection. In response to NMI interrupt, the information of Program Counter, Index Register, Accumulators, and Condition Code Register are stored on the stack. On completion of this sequence, vectoring address \$FFFC and \$FFFD are generated to load the contents to the program counter. Then the CPU branch to a non maskable interrupt service routine.

Interrupt Request (IRQ1)

This level sensitive input requests a maskable interrupt sequence. When IRQ1 goes to "Low", the CPU waits until it completes the current instruction that is being executed. Then, if the interrupt mask bit in Condition Code Register is not set, CPU begins interrupt sequence; otherwise, interrupt request is neglected.

Once the sequence has started, the information of Program Counter, Index Register, Accumulator, Condition Code Register are stored on the stack. Then the CPU sets the interrupt mask bit so that no further maskable interrupts may be responded.

Table 1 Interrupt Vectoring memory map

	Vec	tor	Interrupt
Highest	MSB	LSB	Interropt
Priority	FFFE	FFFF	RES
	FFEE	FFEF	TRAP
	FFFC	FFFD	NMI
	FFFA	FFFB	Software Interrupt (SWI)
	FFF8	FFF9	IRQ, (or IS3)
	FFF6	FFF7	ICF (Timer Input Cepture)
	FFF4	FFF5	OCF (Timer Output Compere
	FFF2	FFF3	TOF (Timer Overflow)
Lowest Priority	FFFO	FFF1	SCI (RDRF + ORFE + TDRE)
FIIOTILY			

At the end of the cycle, the CPU generates 16 bit vectoring addresses indicating memory addresses \$FFF8 and \$FFF9, and loads the contents to the Program Counter, then branch to an interrupt service routine.

The Internal Interrupt will generate signal (IRO₂) which is quite the same as IRQ1 except that it will use the vector address \$FFF0 to \$FFF7.

When IRQ1 and IRQ2 are generated at the same time, the former precedes the latter. Interrupt Mask Bit in the condition code register, if being set, will keep the both interrupts off.

On occurrence of Address error or Op-code error, TRAP interrupt is invoked. This interrupt has priority next to RES. Regardless of the interrupt Mask Bit condition, the CPU will start an interrupt sequence. The vector for this interrupt will be SFFEE, SFFEF.

Read/Write (R/W)

This TTL compatible output signals peripheral and memory devices whether CPU is in Read ("High"), or in Write ("Low"). The normal stand-by state is Read ("High"). Its output will drive one TTL load and 90pF capacitance.

Address Strobe (AS)

In the multiplexed mode, address strobe signal appears at this pin. It is used to latch the lower 8 bits addresses multiplexed with data at Do/Ao ~ D7/A7. The 8-bit latch is controlled by address strobe as shown in Figure 15. Thereby, Do/Ao ~ D7/A7 can become data bus during E pulse. The timing chart of this signal is shown in Figure 1.

Address Strobe (AS) is sent out even if the internal address is accessed.

■ PORTS

There are two I/O ports on HD6303R MPU (one 8-bit ports and one 5-bit port). Each port has an independent write-only data direction register to program individual I/O pins for input or output.*

When the bit of associated Data Direction Register is "1", I/O pin is programmed for output, if "0", then programmed for

an input.

There are two ports: Port 1, Port 2. Addresses of each port and associated Data Direction Register are shown in Table 2.

 Only one exception is bit 1 of Port 2 which becomes either a data input or a timer output. It cannot be used as an output port.

Table 2 Port and Data Direction Register Addresses

Ports	Port Address	Data Direction Register Address
I/O Port 1	\$0002	\$0000
I/O Port 2	\$0003	\$0001

I/O Port 1

This is an 8-bit port, each bit being defined individually as input or outputs by associated Data Direction Register. The 8-bit output buffers have three-state capability, maintaining in high impedance state when they are used for input. In order to be read accurately, the voltage on the input lines must be more than 2.0V for logic "1" and less than 0.8V for logic "0".

These are TTL compatible. After the MPU has been reset, all I/O lines are configured as inputs in Multiplexed mode. In Non Multiplexed mode, Port 1 will be output line for lower order address lines (Ao \sim A7), which can drive one TTL load and 30 pF capacitance.

I/O Port 2

This port has five lines, whose I/O direction depends on its data direction register. The 5-bit output buffers have three-state capability, going high impedance state when used as inputs. In order to be read accurately, the voltage on the input lines must be more than 2.0V for logic "1" and less than 0.8V for logic "0". After the MPU has been reset, I/O lines are configured as inputs. These pins on Port 2 (P20 \sim P22 of the chip) are used to program the mode of operation during reset. The values of these three pins during reset are latched into the upper 3 bits (bit 7, 6 and 5) of Port 2 Data Register which is explained in the MODE SELECTION section.

In all modes, Port 2 can be configured as I/O lines. This port also provides access to the Serial I/O and the Timer. However, note that bit 1 (P_{21}) is the only pin restricted to data input or Timer output.

BUS

D₀/A₀ ~ D₇/A₇

This TTL compatible three-state buffer can drive one TTL load and 90 pF capacitance.

Non Multiplexed Mode

In this mode, these pins become only data bus ($D_0 \sim D_7$). Multiplexed Mode

These pins becomes both the data bus $(D_0 \sim D_7)$ and lower bits of the address bus $(A_0 \sim A_7)$. An address strobe output is "High" when the address is on the pins.

A₈ ~ A₁₅

Each line is TTL compatible and can drive one TTL load and 90 pF capacitance. After reset, these pins become output for upper order address lines ($A_8 \sim A_{15}$).

MODE SELECTION

The operation mode after the reset must be determined by the user wiring the P₂₀, P₂₁, and P₂₂ externally. These three pins are lower order bits; I/O 0, I/O 1, I/O 2 of Port 2. They are latched into the control bits PCO, PC1, PC2 of I/O Port 2 register when RES goes "High". I/O Port 2 Register is shown below.

Port 2 DATA REGISTER



An example of external hardware used for Mode Selection is shown in Figure 11. The HD14053B is used to separate the peripheral device from the MPU during reset. It is necessary if the data may conflict between peripheral device and Mode generation circuit.

No mode can be changed through software because the bits 5, 6, and 7 of Port 2 Data Register are read-only. The mode selection of the HD6303R is shown in Table 3.

The HD6303R operates in two basic modes: (1) Multiplexed Mode, (2) Non Multiplexed Mode.

Multiplexed Mode

The data bus and the lower order address bus are multiplexed in the $D_0/A_0 \sim D_7/A_7$ and can be separated by the Address Strobe.

Port 2 is configured for 5 parallel I/O or Serial I/O, or Timer, or any combination thereof. Port 1 is configured for 8 parallel I/O.

Non Multiplexed Mode

In this mode, the HD6303R can directly address HMCS6800 peripherals with no address latch. $D_0/A_0 \sim D_7/A_7$ become a data bus and Port 1 becomes $A_0 \sim A_7$ address bus.

In this mode, the HD6303R is expandable up to 65k bytes with no address latch.

Lower Order Address Bus Latch

Because the data bus is multiplexed with the lower order address bus in $D_0/A_0 \sim D_7/A_7$ in the multiplexed mode, address bits must be latched. It requires the 74LS373 Transparent octal D-type to latch the LSB. Latch connection of the HD6303R is shown in Figure 15.

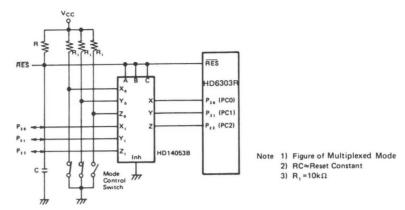


Figure 11 Recommended Circuit for Mode Selection

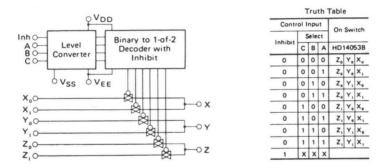


Figure 12 HD14053B Multiplexers/De-Multiplexers

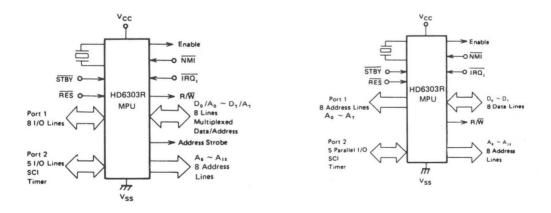
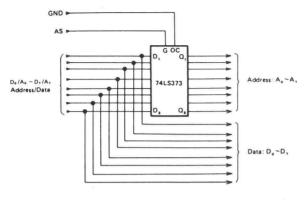


Figure 13 HD6303R MPU Multiplexed Mode

Figure 14 HD6303R MPU Non Multiplexed Mode



Function Table

Output	Ena	Output	
Control (OC)	G	D	Q
L	н	н	н
L	н	L	L
L	L	×	a.
н	×	×	Z

Figure 15 Latch Connection

Table 3 Mode Selection

Operating Mode	P ₂₀	P ₂₁	P22
Multiplexed Mode	L	Н	L
wurupiexea woae	L H	L	Н
Non Multiplexed Mode	Н	L	L

L: logic "0" H: logic "1"

■ MEMORY MAP

The MPU can provide up to 65k byte address space. Figure 16 shows a memory map for each operating mode. The first 32 locations of each map are for the CPU's internal register only, as shown in Table 4.

Table 4 Internal Register Area

Register	Addres
Port 1 Data Direction Register**	00*
Port 2 Data Direction Register**	01
Port 1 Data Register	02*
Port 2 Data Register	03
Timer Control and Status Register	08
Counter (High Byte)	09
Counter (Low Byte)	0A
Output Compare Register (High Byte)	ОВ
Output Compare Register (Low Byte)	OC
Input Capture Register (High Byte)	0D
Input Capture Register (Low Byte)	0E
Rate and Mode Control Register	10
Transmit/Receive Control and Status Register	11
Receive Data Register	12
Transmit Data Register	13
RAM Control Register	14
Reserved	15-1F

^{*} External address in Non Multiplexed Mode

^{** 1 =} Output, 0 = Input

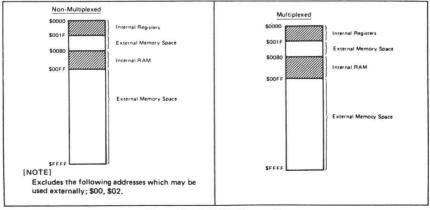


Figure 16 HD6303R Memory Maps



■ PROGRAMMABLE TIMER

The HD6303R contains 16-bit programmable timer which may measure input waveform. In addition to that it can generate an output waveform by itself. For both input and output waveform, the pulse width may vary from a few microseconds to several seconds.

The timer hardware consists of

- · an 8-bit control and status register
- · a 16-bit free running counter
- · a 16-bit output compare register
- · a 16-bit input capture register

A block diagram of the timer is shown in Figure 17.

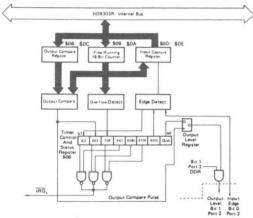


Figure 17 Programmable Timer Block Diagram

Free Running Counter (\$0009: \$000A)

The key element in the programmable timer is a 16-bit free running counter, that is driven by an E (Enable) clock to increment its values. The counter value will be read out by the CPU software at any time with no effects on the counter. Reset will clear the counter.

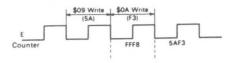
When the MSB of this counter is read, the LSB is stored in temporary latch. The data is fetched from this latch by the subsequent read of LSB. Thus consistent double byte data can be read from the counter.

When the CPU writes arbitrary data to the MSB (\$09), the value of \$FFF8 is being pre-set to the counter (\$09, \$0A) regardless of the write data value. Then the CPU writes arbitrary data to the LSB (\$0A), the data is set to the "Low" byte of the counter, at the same time, the data preceedingly written in the MSB (\$09) is set to "High" byte of the counter.

When the data is written to this counter, a double byte store instruction (ex. STD) must be used. If only the MSB of counter is written, the counter is set to \$FFF8.

The counter value written to the counter using the double byte store instruction is shown in Figure 18.

To write to the counter can disturb serial operations, so it should be inhibited during using the SCI. If external clock mode is used for SCI, this will not disturb serial operations.



(5AF3 written to the counter)

Figure 18 Counter Write Timing

Output Compare Register (\$000B:\$000C)

This is a 16-bit read/write register which is used to control an output waveform. The contents of this register are constantly being compared with current value of the free running counter.

When the contents match with the value of the free running counter, a flag (OCF) in the timer control/status register (TCSR) is set and the current value of an output level Bit (OLVL) in the TCSR is transferred to Port 2 bit 1. When bit 1 of the Port 2 data direction register is "1" (output), the OLVL value will appear on the bit 1 of Port 2. Then, the value of Output Compare Register and Output level bit may be changed for the next compare.

The output compare register is set to \$FFFF during reset.

The compare function is inhibited at the cycle of writing to the high byte of the output compare register and at the cycle just after that to ensure valid compare. It is also inhibited in same manner at writing to the free running counter.

In order to write a data to Output Compare Register, a double byte store instruction (ex.STD) must be used.

• Input Capture Register (\$000D: \$000E)

The input capture register is a 16-bit read-only register used to hold the current value of free running counter captured when the proper transition of an external input signal occurs.

The input transition change required to trigger the counter transfer is controlled by the input edge bit (IEDG).

To allow the external input signal to go in the edge detect unit, the bit of the Data Direction Register corresponding to bit 0 of Port 2 must have been cleared (to zero).

To insure input capture in all cases, the width of an input pulse requires at least 2 Enable cycles.

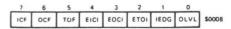
• Timer Control/Status Register (TCSR) (\$0008)

This is an 8-bit register. All 8-bits are readable and the lower 5 bits may be written. The upper 3 bits are read-only, indicating the timer status information as is shown below.

- A proper transition has been detected on the input pin (ICF).
- (2) A match has been found between the value in the free running counter and the output compare register (OCF).
- (3) When counting up to \$0000 (TOF).

Each flag has an individual enable bit in TCSR which determines whether or not an interrupt request may occur $(\overline{IRQ_2})$. If the I-bit in Condition Code Register has been cleared, a prior vectored address occurs corresponding to each flag. A description of each bit is as follows.

Timer Control / Status Register



Bit 0 OLVL (Output Level); When a match is found in the value between the counter and the output com-



pare register, this bit is transferred to the Port 2 bit 1. If the DDR corresponding to Port 2 bit 1 is set "1", the value will appear on the output pin of Port 2 bit 1.

Bit 1 IEDG (Input Edge): This bit control which transition of an input of Port 2 bit 0 will trigger the data transfer from the counter to the input capture register. The DDR corresponding to Port 2 bit 0 must be clear in advance of using this function.

When IEDG = 0, trigger takes place on a negative edge ("High"-to-"Low" transition). When IEDG = 1, trigger takes place on a positive edge ("Low"-to-"Low").

"High" transition).

Bit 2 ETOI (Enable Timer Overflow Interrupt); When set, this bit enables TOF interrupt to generate the interrupt request (IRQ2). When cleared, the interrupt is inhibited.

Bit 3 EOCI (Enable Output Compare Interrupt); When set, this bit enables OCF interrupt to generate the interrupt request (IRQ2). When cleared, the interrupt is inhibited.

Bit 4 EICI (Enable Input Capture Interrupt); When set, this bit enables ICF interrupt to generate the interrupt request (IRQ2). When cleared, the interrupt is inhibited.

Bit 5 TOF (Timer Over Flow Flag); This read-only bit is set at the transition of \$FFFF to \$0000 of the counter. It is cleared by CPU read of TCSR (with TOF set) followed by a CPU read of the counter (\$0009).

Bit 6 OCF (Output Compare Flag); This read-only bit is set when a match is found in the value between the output compare register and the counter. It is cleared by a read of TCSR (with OCF set) followed by a CPU write to the output compare register (\$000B or \$000C).

Bit 7 ICF (Input Capture Flag); The read-only bit is set by a proper transition on the input, and is cleared by a read of TCSR (with ICF set) followed by a CPU read of Input Capture Register (\$000D).

Reset will clear each bit of Timer Control and Status Register.

■ SERIAL COMMUNICATION INTERFACE

The **HD6303R** contains a full-duplex asynchronous Serial Communication Interface (SCI). SCI may select the several kinds of the data rate. It consists of a transmitter and a receiver which operate independently but with the same data format and the same data rate. Both of transmitter and receiver communicate with the CPU via the data bus and with the outside world through Port 2 bit 2, 3 and 4. Description of hardware, software and register is as follows.

Wake-Up Feature

In typical multiprocessor applications the software protocol will usually have the designated address at the initial byte of the message. The purpose of Wake-Up feature is to have the non-selected MPU neglect the remainder of the message. Thus the non-selected MPU can inhibit the all further interrupt process until the next message begins.

Wake-Up feature is re-enabled by a ten consecutive "1"s which indicates an idle transmit line. Therefore software protocol must put an idle period between the messages and must

prevent it within the message.

With this hardware feature, the non-selected MPU is reenabled (or "waked-up") by the next message.

Programmable Options

The HD6303R has the following programmable features.

- data format; standard mark/space (NRZ)
- · clock source; external or internal
- baud rate; one of 4 rates per given E clock frequency or 1/8 of external clock
- · wake-up feature; enabled or disabled
- interrupt requests; enabled or masked individually for transmitter and receiver
- clock output; internal clock enabled or disabled to Port
 2 bit 2
- Port 2 (bits 3, 4); dedicated or not dedicated to serial I/O individually

Serial Communication Hardware

The serial communications hardware is controlled by 4 registers as shown in Figure 19. The registers include:

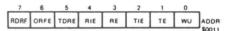
- · an 8-bit control/status register
- · a 4-bit rate/mode control register (write-only)
- · an 8-bit read-only receive data register
- · an 8-bit write-only transmit data register

Besides these 4 registers, Serial I/O utilizes Port 2 bit 3 (input) and bit 4 (output). Port 2 bit 2 can be used when an option is selected for the internal-clock-out or the external-clock-in.

• Transmit/Heceive Control Status Register (TRCSR)

TRCS Register consists of 8 bits which all may be read while only bits 0 to 4 may be written. The register is initialized to \$20 on RES. The bits of the TRCS Register are explained below.

Transmit / Receive Control Status Register

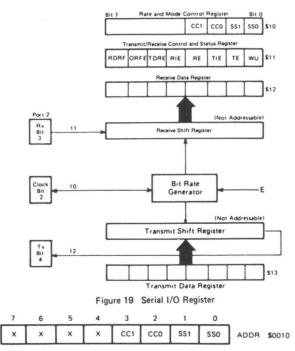


- Bit 0 WU (Wake Up); Set by software and cleared by hardware on receipt of ten consecutive "1"s. While this bit is "1", RDRF and ORFE flags are not set even if data are received or errors are detected. Therefore received data are ignored. It should be noted that RE flag must have already been set in advance of WU flag's set.
- Bit 1 TE (Transmit Enable); This bit enables transmitter. When this bit is set, bit 4 of Port 2 DDR is also forced to be set. It remains set even if TE is cleared. Preamble of ten consecutive "1"s is transmitted just after this bit is set, and then transmitter becomes ready to send data. If this bit is cleared, the transmitter is disabled and serial I/O affects nothing on Port 2 bit 4.
- Bit 2 TIE (Transmit Interrupt Enable); When this bit is set, TDRE (bit 5) causes an IRQ2 interrupt. When cleared, TDRE interrupt is masked.
- Bit 3 RE (Receive Enable); When set, Port 2 bit 3 can be used as an input of receive regardless of DDR value for this bit. When cleared, the receiver is disabled.
- Bit 4 RIE (Receive Interrupt Enable); When this bit is set, RDRF (bit 7) or ORFE (bit 6) cause an IRQ2 interrupt, When cleared, this interrupt is masked.

- Bit 5 TDRE (Transmit Data Register Empty); When the data is transferred from the Transmit Data Register to Output Shift Register, this bit is set by hardware. The bit is cleared by reading the status register followed by writing the next new data into the Transmit Data Register. TDRE is initialized to 1 by RES.
- Bit 6 ORFE (Over Run Framing Error); When overrun or framing error occurs (receive only), this bit is set by hardware. Over Run Error occurs if the attempt is made to transfer the new byte to the receive data register while the RDRF is "1". Framing Error occurs when the bit counter is not synchronized with the boundary of the byte in the re-

ceiving bit stream. When Framing Error is detected, RDRF is not set. Therefore Framing Error can be distinguished from Overrun Error. That is, if ORFE is "1" and RDRF is "1", Overrun Error is detected. Otherwise Framing Error occurs. The bit is cleared by reading the status register followed by reading the receive data register, or by RES.

Bit 7 RDRF (Receive Data Register Full); This bit is set by hardware when the data is transferred from the receive shift register to the receive data register. It is cleared by reading the status register followed by reading the receive data register, or by RES.



Transfer Rate / Mode Control Register

Table 5 SCI Bit Times and Transfer Rates

		XTAL	2.4576 MHz	4.0 MHz	4.9152MHz
SS1	SS0	E	614.4 kHz	1.0 MHz	1 2288MHz
0	0	E ÷ 16	26 μs/38,400 Baud	16 μs/62,500 Baud	13 μs/76,800Bau
0	1	E ÷ 128	208µs/4,800 Baud	128 μs/7812.5 Baud	104.2 _µ s/ 9,600Bau
1	0	E ÷ 1024	1.67ms/600 Baud	1.024ms/976.6 Baud	833.3 _µ s/ 1,200Bau
1	1	E ÷ 4096	6.67ms/150 Baud	4.096ms/244.1 Baud	3.333ms/ 300Bau

Table 6 SCI Format and Clock Source Control

CC1:	CCO	Format	Clock Source	Port 2 Bit 2	Port 2 Bit 3	Port 2 Bit 4
0	0	_	_	-	_	-
0	1	NRZ	Internal	Not Used ***	• •	••
1	0	NRZ	Internal	Output*	••	••
1	1	NRZ	External	Input	••	••

- * Clock output is available regardless of values for bits RE and TE.
- ** Bit 3 is used for serial input if RE = "1" in TRCS. Bit 4 is used for serial output if TE = "1" in TRCS.
- *** This pin can be used as I/O port.

Transfer Rate/Mode Control Register (RMCR)

The register controls the following serial I/O functions:

- Bauds rate data format clock source
- · Port 2 bit 2 feature

It is 4-bit write-only register, cleared by RES. The 4 bits are considered as a pair of 2-bit fields. The lower 2 bits control the bit rate of internal clock while the upper 2 bits control the format and the clock select logic.

These bits select the Baud rate for the internal clock. The rates selectable are function of E clock frequency of the CPU. Table 5 lists the available Baud Rates.

They control the data format and the clock select logic. Table 6 defines the bit field.

• Internally Generated Clock

If the user wish to use externally an internal clock of the serial I/O, the following requirements should be noted.

- ·CC1, CC0 must be set to "10".
- The maximum clock rate must be E/16.
- · The clock rate is equal to the bit rate.
- . The values of RE and TE have no effect.

Externally Generated Clock

If the user wish to supply an external clock to the Serial I/O, the following requirements should be noted.

- · The CC1, CC0 must be set to "11" (See Table 6).
- The external clock must be set to 8 times of the desired band rate.
- The maximum external clock frequency is E/2 clock.

Serial Operations

The serial I/O hardware must be initialized by the software before operation. The sequence will be normally as follows.

- •Writing the desired operation control bits of the Rate and Mode Control Register.
- *Writing the desired operation control bits of the TRCS

If Port 2 bit 3, 4 are used for serial I/O, TE, RE bits may be kept set. When TE, RE bit are cleared during SCI operation, and subsequently set again, it should be noted that TE, RE must be kept "0" for at least one bit time of the current baud rate. If TE, RE are set again within one bit time, there may be the case where the initializing of internal function for transmitter and receiver does not take place correctly.

Transmit Operation

Data transmission is enabled by the TE bit in the TRCS

register. When set, the output of the transmit shift register is connected with Port 2 bit 4 which is unconditionally configured as an output.

After RES, the user should initialize both the RMC register and the TRCS register for desired operation. Setting the TE bit causes a transmission of ten-bit preamble of "1"s. Following the preamble, internal synchronization is established and the transmitter is ready to operate. Then either of the following states exists.

- If the transmit data register is empty (TDRE = 1), the consecutive "1"s are transmitted indicating an idle states.
- (2) If the data has been loaded into the Transmit Data Register (TDRE = 0), it is transferred to the output shift register and data transmission begins.

During the data transfer, the start bit ("0") is first transferred. Next the 8-bit data (beginning at bit 0) and finally the stop bit ("1"). When the contents of the Transmit Data Register is transferred to the output shift register, the hardware sets the TDRE flag bit: If the CPU fails to respond to the flag within the proper time, TDRE is kept set and then a continuous string of 1's is sent until the data is supplied to the data register.

Receive Operation

The receive operation is enabled by the RE bit. The serial input is connected with Port 2 bit 3. The receiver operation is determined by the contents of the TRCS and RMC register. The received bit stream is synchronized by the first "0" (start bit). During 10-bit time, the data is strobed approximately at the center of each bit. If the tenth bit is not "1" (stop bit), the system assumes a framing error and the ORFE is set.

If the tenth bit is "1", the data is transferred to the receive data register, and the RDRF flag is set. If the tenth bit of the next data is received and still RDRF is preserved set, then ORFE is set indicating that an overrun error has occurred.

After the CPU read of the status register as a response to RDRF flag or ORFE flag, followed by the CPU read of the receive data register, RDRF or ORFE will be cleared.

RAM CONTROL REGISTER

The register assigned to the address \$0014 gives a status information about standby RAM.



Bit 0 Not used. Bit 1 Not used. Bit 2 Not used. Bit 3 Not used.

Bit 4 Not used.

Bit 5 Not used.

Bit 6 RAM Enable (RAME).

Using this control bit, the user can disable the RAM. RAM Enable bit is set on the positive edge of \overline{RES} and RAM is enabled. The program can write "1" or "0". If RAME is cleared, the RAM address becomes external address and the CPU may read the data from the outside memory.

Bit 7 Standby Power Bit (STBY PWR)

This bit can be read or written by the user program. It is cleared when the V_{CC} voltage is removed. Normally this bit is set by the program before going into stand-by mode. When the CPU recovers from stand-by mode, this bit should be checked. If it is "1", the data of the RAM is retained during stand-by and it is valid.

■ GENERAL DESCRIPTION OF INSTRUCTION SET

The HD6303R has an upward object code compatible with the HD6801 to utilize all instruction sets of the HMCS6800. The execution time of the key instruction is reduced to increase the system through-put. In addition, the bit operation instruction, the exchange instruction between the index and the accumulator, the sleep instruction are added. This section describes:

· CPU programming model (See Fig. 20)

· Addressing modes

 Accumulator and memory manipulation instructions (See Table 7)

· New instructions

*Index register and stack manipulation instructions (See Table 8)

· Jump and branch instructions (See Table 9)

*Condition code register manipulation instructions (See Table 10)

· Op-code map (See Table 11)

· Cycle-by-cycle operation (See Table 12)

CPU Programming Model

The programming model for the HD6303R is shown in Figure 20. The double accumulator is physically the same as the accumulator A concatenated with the accumulator B, so that the contents of A and B is changed with executing operation of an accumulator D.

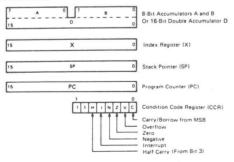


Figure 20 CPU Programming Model

CPU Addressing Modes

The HD6303R has seven address modes which depend on both of the instruction type and the code. The address mode for

every instruction is shown along with execution time given in terms of machine cycles (Table 7 to 11). When the clock frequency is 4 MHz, the machine cycle will be microseconds. Accumulator (ACCX) Addressing

Only the accumulator (A or B) is addressed. Either accumulator A or B is specified by one-byte instructions.

Immediate Addressing

In this mode, the operand is stored in the second byte of the instruction except that the operand in LDS and LDX, etc are stored in the second and the third byte. These are two or three-byte instructions.

Direct Addressing

In this mode, the second byte of instruction indicates the address where the operand is stored. Direct addressing allows the user to directly address the lowest 256 bytes in the machine; locations zero through 255. Improved execution times are achieved by storing data in these locations. For system configuration, it is recommended that these locations should be RAM and be utilized preferably for user's data realm. These are two-byte instructions except the AIM, OIM, EIM and TIM which have three-byte.

Extended Addressing

In this mode, the second byte indicates the upper 8 bit addresses where the operand is stored, while the third byte indicates the lower 8 bits. This is an absolute address in memory. These are three-byte instructions.

Indexed Addressing

In this mode, the contents of the second byte is added to the lower 8 bits in the Index Register. For each of AIM, OIM, EIM and TIM instructions, the contents of the third byte are added to the lower 8 bits in the Index Register. In addition, the resulting "carry" is added to the upper 8 bits in the Index Register. The result is used for addressing memory. Because the modified address is held in the Temporary Address Register, there is no change to the Index Register. These are two-byte instructions but AIM, OIM, EIM, TIM have three-byte.

Implied Addressing

In this mode, the instruction itself gives the address; stack pointer, index register, etc. These are 1-byte instructions.

Relative Addressing

In this mode, the contents of the second byte is added to the lower 8 bits in the program counter. The resulting carry or borrow is added to the upper 8 bits. This helps the user to address the data within a range of -126 to +129 bytes of the current execution instruction. These are two-byte instructions.

Table 7 Accumulator, Memory Manipulation Instructions

1000	1					Ade	dressi	ng	Mod	les								1		on (_
Mnemonic	IMI	ME	D	DIF	REC	т	IN	DE	x	EX	TEN	4D	IMI	PLIE	D	Boolean/	5	4	3	_	1	To
	OP	~	#	ОР	~	#	OP	~	#	OP	~	#	ОР	~	#	Arithmetic Operation	н	ı	N	z	v	0
ADDA	88	2	2	9B	3	2	AB	4	2	вв	4	3				A + M→ A	1	•	:	:	:	1
ADDB	СВ	2	2	DB	3	2	EB	4	2	FB	4	3				B + M → B	:		1	1	1	1
ADDD	СЗ	3	3	D3	4	2	E3	5	2	F3	5	3				A:B+M:M+1 - A:B			1	1	1	1
ABA													18	1	1	A + B → A	1	•	:	1	:	+
ADCA	89	2	2	99	3	2	A9	4	2	В9	4	3				A + M + C → A	1		:	1	1	Ť
ADCB	C9	2	2	D9	3	2	E9	4	2	F9	4	3				B + M + C → B	1		1	1	1	t
ANDA	84	2	2	94	3	2	A4	4	2	84	4	3				A·M → A			1	1	R	t
ANDB	C4	2	2	D4	3	2	E4	4	2	F4	4	3				B·M → B			1	1	R	t
BITA	85	2	2	95	3	2	A5	4	2	B5	4	3				A·M			1	1	R	t
BIT B	C5	2	2	D5	3	2	E5	4	2	F5	4	3				в·м			1	1	R	t
CLR						\vdash	6F	5	2	7F	5	3				00 → M			R	s	R	t
CLRA		\vdash				\vdash					Ė	1	4F	1	1	00 → A			R	s	R	t
CLRB													5F	1	1	00 → B			R	s	R	t
CMPA	81	2	2	91	3	2	A1	4	2	B1	4	3				A - M			1	1	1	t
СМРВ	C1	2	2	D1	3	2	E1	4	2	F1	4	3				B - M			-	-	+	t
CEA													11	1	1	A - B	•	•	1	1	1	t
СОМ				-			63	6	2	73	6	3			\vdash	M → M			1	1	R	t
		\vdash	\vdash		-	-	-	F	-	-	-	-	43	1	1			+-		-		+
					\vdash							H	-	-	-				-	-	-	t
	1	+		_	\vdash	-	60	6	2	70	6	3	-	+	Ė				-	-		1
					\vdash		-	Ť	-	-	-	-	40	1	1				÷	+ -	-	+
NEGB		\vdash	\vdash			\vdash						\vdash	-	-	-		+	+	-	-		
DAA											T	T	19	2	1	Converts binary add of BCD			:	:	1	0
DEC					\vdash	1	6A	6	2	7A	6	3			\vdash				1	1	(4)	t
		+	\vdash	_	\vdash	\vdash	-	-	-	-	-	۲	4A	1	1						-	1
_						\vdash		\vdash		-		+	-	<u> </u>	-				-	+		
	88	2	2	98	3	2	AR	4	2	RR	4	3	-	<u> </u>	Ė				-	+	1.	t
	-	-	-	-	-	-		-	-		-	-	\vdash	\vdash	\vdash		-	-	-	-	-	+
	100	-	-	-	-	-	_	-	-	_	-	-	-	-	-		+	+-	_	_	-	+
	+-	-	-	-	\vdash	-	00	0	-	10	0	13	40				-	-	-	-	-	1
	-	\vdash	-	-	-	-	-	-		-	\vdash	⊢	-	-	-		+	-	1		-	_
	-	-	-	-	-	-		-	-	_	-	ŀ	5C	יו	1		+	-	-	+	-	+
	1	+	+-	-	-	-	-	-	-	-	-	-	-	-	-		-	+	-	+	+	+
												1	-				•		+	1	+	+
	+	-	+	-	-	-	-	-	-	-	-	1	20	-	-	10 10 00000 100	+	-	-	-	-	+
	0.	12	12	0.4	2	2	4.6		2	0.4	-	12	30	/	1		-	-	-		-	1
				_	-			-					_		_							1
	CA	2	12	DA	3	2	EA	4	2	FA	4	3	-				-	-	1	-	-	1
	+-	⊢	\vdash	-	-	-	-	-	-	_	-	1	-	-	-		-	-		-	-	1
	-	+	-	-	-	-	-	-	-	-	-	-	-	-	-		-	-	+-	-	+	1
	+-	+	-	-	-	-	-	-	-	-	-	-	-	-	-		-	-	1	-	-	1
	+	-	-	-	-	-	-	-	-	-	-	-	33	3	1	SP + 1 → SP, Msp → B	+	-	-	+-	+	1
	-	-	-	-	_	-	69	6	2	79	6	3	-			M) [=	\vdash	-	_	-	-	+
	-	-	-	_	_	-		_				1		-	_		•		_	_	(6)	_
	-	L	L			1		L				L	59	1	1	8. 5 5.	•	•	:	:	_	1
ROR		_			_	-	66	6	2	76	6	3				M) [•	1	1	(6)	4
RORA													46	1	1				1	1	1	I
	ADDA ADDB ADDB ABA ADCB ABA ADCB ANDA BIT A BIT B CLR CLRA CMPB CCPA COMPB COMA COMB NEG NEGA NEGB	IM	IMME OP ~ ADDA	IMMED OP No	IMMED DIF	IMMED DIRECT Company Company	IMMED DIRECT OP	IMMED DIRECT IN	New New	New Part	IMMED DIRECT INDEX EXTENDED	IMMED DIRECT INDEX EXTENDED OP W OP W OP OR W OP OR	IMMED DIRECT INDEX EXTENDED COMA COMA	IMMED	Note	Name	IMMELED DIRECT INDEX EXTEND IMPLED Arithmetic Operation	IMMED DIRECT INDEX SETEND IMPLED SARITHMENTE OPERATION SETEND MANUAL SETEND MANUAL	Memorian	Memorian	Membran Memb	Memoria Memo

Note) Condition Code Register will be explained in Note of Table 10.

(to be continued)

Table 7 Accumulator, Memory Manipulation Instructions

							Add	dressi	ng l	Mod	les							C	ono		on (•
Operations	Mnemonic	IM	ME	D	DIF	REC	T	IN	DE	K	EX	TEN	ID	IM	PLI	ED	Boolean/ Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		н	1	N	z	v	С
Shift Left	ASL			T				68	6	2	78	6	3		\vdash	T	м	•		:	:	6	:
Arithmetic	ASLA													48	1	1	A D-111111-0		•	\$:	6	\$
	ASLB													58	1	1	B C 67 60		•	\$	\$	6	\$
Double Shift Left, Arithmetic	ASLD													05	1	1	ACC A/ ACC B -0	•	•	:	:	6	:
Shift Right	ASR		T					67	6	2	77	6	3				M) C	•	•	‡	:	6	:
Arithmetic	ASRA													47	1	1	^ \-(\)			:	:	6	:
	ASRB													57	1	1	B) 67 60 C	•	•	\$:	6	:
Shift Right	LSR							64	6	2	74	6	3				M)	•		R	:	6	:
Logical	LSRA													44	1	1	A 0→	•	•	R	:	6	:
	LSRB													54	1	1	8) 67 60 0		•	R	:	6	:
Double Shift Right Logical	LSRD													04	1	1	0→ ACC A/ ACC B → C A7 A0 B7 B0 C	•	•	R	:	6	:
Store	STAA				97	3	2	A7	4	2	B7	4	3				A → M		•	\$:	R	
Accumulator	STAB	1			D7	3	2	E7	4	2	F7	4	3				B → M		•	\$	\$	R	
Store Double Accumulator	STD				DD	4	2	ED	5	2	FD	5	3				A → M B → M + 1	•	•	:	:	R	•
Subtract	SUBA	80	2	2	90	3	2	A0	4	2	В0	4	3				$A - M \rightarrow A$:	:	:	1
	SUBB	co	2	2	DO	3	2	EO	4	2	FO	4	3				B - M → B	•	•	\$:	\$	‡
Double Subtract	SUBD	83	3	3	93	4	2	A3	5	2	В3	5	3				A:B-M:M+1→A:B	•	•	\$:	:	1
Subtract Accumulators	SBA													10	1	1	A - B → A	•	•	:	:	:	:
Subtract	SBCA	82	2	2	92	3	2	A2	4	2	B2	4	3				A - M - C → A		•	\$	\$	\$	1
With Carry	SBCB	C2	2	2	D2	3	2	E2	4	2	F2	4	3				B - M - C → B			\$:	‡	‡
Transfer	TAB													16	1	1	A → B		•	:	:	R	
Accumulators	TBA													17	1	1	B → A	•	•	:	1	R	
Test Zero or	TST							6D	4	2	7D	4	3				M - 00	•		:	:	R	R
Minus	TSTA													4D	1	1	A - 00			:	:	R	R
	TSTB													5D	1	1	B - 00	•	•	:	:	R	R
And Immediate	AIM				71	6	3	61	7	3					\vdash		M-IMM→M			1	1	R	
OR Immediate	OIM				72	6	3	62	7	3							M+IMM→M		•	1	1	R	
EOR Immediate	EIM				75	6	3	65	7	3							M⊕IMM→M			:	1	R	
Test Immediate	TIM				7B	4	3	6B	5	3			1		\vdash		M-IMM			:	1	R	

Note) Condition Code Register will be explained in Note of Table 10.

New Instructions

In addition to the HD6801 Instruction Set, the HD6303R has the following new instructions:

 $AIM - \cdots (M) \cdot (IMM) \rightarrow (M)$

Evaluates the AND of the immediate data and the memory, places the result in the memory.

 $OIM - \cdots (M) + (IMM) \rightarrow (M)$

Evaluates the OR of the immediate data and the memory, places the result in the memory.

 $EIM - - - (M) \oplus (IMM) \rightarrow (M)$

Evaluates the EOR of the immediate data and the memory, places the result in the memory.

 $TIM----(M) \cdot (IMM)$

Evaluates the AND of the immediate data and the memory, changes the flag of associated condition code register

Each instruction has three bytes; the first is op-code, the second is immediate data, the third is address modifier.

XGDX--(ACCD) ↔ (IX)

Exchanges the contents of accumulator and the index register.

SLP----The MPU is brought to the sleep mode. For sleep mode, see the "sleep mode" section.

Table 8 Index Register, Stack Manipulation Instructions

							Ade	dress	ing	Mod	des						Boolean/	(on (0
Pointer Operations	Mnemonic	IM	ME	D	DII	REC	CT	IN	DE	X	EX.	TEN	ID	IMP	LIE	D	Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		н	1	N	Z	٧	c
Compare Index Reg	CPX	8C	3	3	9C	4	2	AC	5	2	BC	5	3				X-M:M+1			:	\$	1	\$
Decrement Index Reg	DEX													09	1	1	X – 1 → X	•	•		1		
Decrement Stack Pntr	DES													34	1	1	SP - 1 → SP		•		•	•	
Increment Index Reg	INX													08	1	1	X + 1 → X		•		1	•	
Increment Stack Pntr	INS													31	1	1	SP + 1 → SP	•			•	•	
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	5	2	FE	5	3				$M \rightarrow X_H$, $(M+1) \rightarrow X_L$	•	•	(1)	\$	R	
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	5	2	BE	5	3				M → SPH, (M+1) → SPL	•	•	1	:	R	
Store Index Reg	STX				DF	4	2	EF	5	2	FF	5	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$		•	1	:	R	
Store Stack Pntr	STS				9F	4	2	AF	5	2	BF	5	3				SPH - M, SPL - (M+1)		•	1	:	R	
Index Reg → Stack Pntr	TXS													35	1	1	X - 1 → SP	•	•	•	•	•	
Stack Pntr → Index Reg	TSX													30	1	1	SP + 1 → X	•	•	•	•	•	•
Add	ABX													3A	1	1	B + X → X				•	•	
Push Data	PSHX													3C	5	1	$X_L \rightarrow M_{ap}$, $SP - 1 \rightarrow SP$ $X_H \rightarrow M_{ap}$, $SP - 1 \rightarrow SP$	•	•	•	•	•	•
Pull Data	PULX													38	4	1	SP + 1 → SP, M _{SP} → X _H SP + 1 → SP, M _{SP} → X _L	•	•	•	•	٠	•
Exchange	XGDX													18	2	1	ACCD↔IX		•				

Note) Condition Code Register will be explained in Note of Table 10.

Table 9 Jump, Branch Instruction

							Ad	dres	sing	Мо	des							(on (e
Operations	Mnemonic	REL	AT	VE	DI	REC	ст	IN	DE	x	EX	TEN	ID	IME	LIE	D	Branch Test	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		Н	1	N	Z	٧	С
Branch Always	BRA	20	3	2													None					•	•
Branch Never	BRN	21	3	2													None	•				•	•
Branch If Carry Clear	BCC	24	3	2									Π				C = 0					•	
Branch If Carry Set	BCS	25	3	2													C = 1	•	•				
Branch If = Zero	BEQ	27	3	2									Ι				Z = 1					•	
Branch If > Zero	BGE	2C	3	2													N ⊕ V = 0						
Branch If > Zero	BGT	2E	3	2													Z + (N + V) = 0						•
Branch If Higher	ВНІ	22	3	2													C + Z = 0				•		
Branch If ≤ Zero	BLE	2F	3	2													Z + (N + V) = 1		•				
Branch If Lower Or Same	BLS	23	3	2													C + Z = 1	•	•	•			•
Branch If < Zero	BLT	2D	3	2													N ⊕ V = 1						•
Branch If Minus	BMI	2B	3	2													N = 1						
Branch If Not Equal Zero	BNE	26	3	2													Z = 0	•			•		•
Branch If Overflow Clear	BVC	28	3	2													V = 0	•	•	•	•		•
Branch If Overflow Set	BVS	29	3	2									L				V = 1						
Branch If Plus	BPL	2A	3	2													N = 0				•	•	
Branch To Subroutine	BSR	8D	5	2									T										
Jump	JMP							6E	3	2	7E	3	3				1					•	•
Jump To Subroutine	JSR				9D	5	2	AD	5	2	BD	6	3					•				•	
No Operation	NOP													01	1	1	Advances Prog. Cntr. Only	•	•	•	•	•	
Return From Interrupt	RTI													38	10	1		-		- (1	_	_
Return From Subroutine	RTS													39	5	1		•	•		•	•	•
Software Interrupt	SWI													3F	12	1]		S		•		•
Wait for Interrupt®	WAI													3E	9	1			1		•		
Sleep	SLP													1A	4	1							

Note) *WAI puts R/W high; Address Bus goes to FFFF; Data Bus goes to the three state. Condition Code Register will be explained in Note of Table 10.

Table 10 Condition Code Register Manipulation Instructions

		Addre	ssingA	Modes		C	ondit	ion C	ode l	Regis	ter
Operations	Mnemonic	IM	PLIE	D	Boolean Operation	5	4	3	2	1	0
		OP	~	#		н	1	N	Z	٧	C
Clear Carry	CLC	ОС	1	1	0 → C		•	•	•	•	R
Clear Interrupt Mask	CLI	OE	1	1	0 → 1	•	R	•	•		
Clear Overflow	CLV	0A	1	1	0 → V					R	
Set Carry	SEC	OD	1	1	1 → C	•	•				S
Set Interrupt Mask	SEI	OF	1	1	1 → 1		S				
Set Overflow	SEV	08	1	1	1 → V		•			S	
Accumulator A → CCR	TAP	06	1	1	A→ CCR	_		- (0 -		_
CCR → Accumulator A	TPA	07	1	1	CCR → A						

[NOTE 1] Condition Code Register Notes: (Bit set if test is true and cleared otherwise)

- (Bit V) Test: Result = 10000000?
- (2) (Bit C) Test: Result + 00000000?
- Test: BCD Character of high-order byte greater than 9? (Not cleared if previously set) (Bit C)
- 3 Test: Operand = 10000000 prior to execution? (Bit V)
- Test: Operand = 01111111 prior to execution? (5) (Rit V)
- Test: Set equal to N⊕C=1 after the execution of instructions 6 (Bit V)
- Test: Result less than zero? (Bit 15=1) 7 (Bit N)
- (All Rit) Load Condition Code Register from Stack.
- Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exit the wait (Bit 1) state.
- (All Bit) Set according to the contents of Accumulator A.
- 11 (Bit C) Result of Multiplication Bit 7=1 of ACCB?

[NOTE 2] CLI instruction and interrupt.

If interrupt mask-bit is set (1="1") and interrupt is requested (IRQ₁ = "0" or IRQ₂ = "0"). and then CLI instruction is executed, the CPU responds as follows.

The next instruction of CLI is one-machine evals instruction.

- Subsequent two instructions are executed before the interrupt is responded.
 - That is, the next and the next of the next instruction are executed.
- The next instruction of CLI is two-machine cycle (or more) instruction.

Only the next instruction is executed and then the CPU jump to the interrupt routine. Even if TAP instruction is used, instead of CLI, the same thing occurs.

Table 11 OP-Code Map

OF	•					ACC	ACC	IND	EXT		ACCA	or SP			ACCE	or X		7
COL	DE					Α	В	IND	DIR	IMM	DIR	IND	EXT	IMM	DIR	IND	EXT	1
1	11	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111	1
LO	/	0	1	2	3	4	5	6	7	8	9	A	В	С	D	Ε	F	1
0000	0		SBA	BRA	TSX		N	EG					SI	JB				0
0001	1	NOP	CBA	BRN	INS			A	IM				CI	MP				1
0010	2			ВНІ	PULA			0	IM				SI	ВС				2
0011	3			BLS	PULB		CC	M			SU	BD			AD	DD		3
0100	4	LSRD		BCC	DES		LS	SR					Al	ND				4
0101	5	ASLD		BCS	TXS			E	IM				В	IT				5
0110	6	TAP	TAB	BNE	PSHA		R	OR					L	DA				6
0111	7	TPA	TBA	BEQ	PSHB		A:	SR				STA				STA		7
1000	8	INX	XGDX	BVC	PULX		A	SL					E	OR	-			8
1001	9	DEX	DAA	BVS	RTS		R	OL					Al	DC				9
1010	A	CLV	SLP	BPL	ABX		DI	EC					01	RA				A
1011	В	SEV	ABA	BMI	RTI		_	Т	IM				Al	OD				В
1100	С	CLC		BGE	PSHX		IN	iC			CI	PX			L	DD		C
1101	D	SEC		BLT	MUL		T	ST		BSR		JSR				STD		0
1110	Ε	CLI		BGT	WAI			JI	MP		L	os			L	X		E
1111	F	SEI		BLE	SWI		C	LR				STS				STX		F
		0	1	2	3	4	5	6	7	8	9	A	В	С	D	E	F	

UNDEFINED OF CODE

* Only for instructions of AIM, OIM, EIM, TIM

Instruction Execution Cycles

In the HMCS6800 series, the execution cycle of each instruction is the number of cycles between the start of the current instruction fetch and just before the start of the subsequent instruction fetch.

The HD6303R uses a mechanism of the pipeline control for the instruction fetch and the subsequent instruction fetch is performed during the current instruction being executed.

Therefore, the method to count instruction cycles used in the HMCS6800 series cannot be applied to the instruction cycles such as MILLT PILL DAA and YCDY in the HD6303R

cycles such as MULT, PULL, DAA and XGDX in the HD6303R.

Table 12 provides the information about the relationship among each data on the Address Bus, Data Bus, and R/W status in cycle-by-cycle basis during the execution of each instruction.

Table 12 Cycle-by-Cycle Operation

	s Mode &	Cycles	Cycle	Address Bus	R/W	Data Bus
Instr	uctions		#			
MMEDIA	TE					
ADC	ADD		1	Op Code Address+1	1	Operand Data
AND	BIT		2	Op Code Address+2	1	Next Op Code
CMP	EOR	2				
LDA	ORA					
SBC	SUB					
ADDD	CPX		1	Op Code Address+1	1	Operand Data (MSB)
LDD	LDS	3	2	Op Code Address+2	1	Operand Data (LSB)
LDX	SUBD	1	3	Op Code Address+3	1	Next Op Code
DIRECT						
ADC	ADD	T	1	Op Code Address+1	1	Address of Operand (LSB
AND	BIT		2	Address of Operand	1	Operand Data
CMP	EOR	3	3	Op Code Address+2	1	Next Op Code
LDA	ORA					
SBC	SUB					
STA		+	1	Op Code Address+1	1	Destination Address
		3	2	Destination Address	0	Accumulator Data
			3	Op Code Address+2	1	Next Op Code
ADDD	CPX		1	Op Code Address+1	1	Address of Operand (LSB
LDD	LDS		2	Address of Operand	1	Operand Data (MSB)
LDX	SUBD	4	3	Address of Operand+1	1	Operand Data (LSB)
			4	Op Code Address+2	1	Next Op Code
STD	STS		1	Op Code Address+1	1	Destination Address (LSB
STX			2	Destination Address	0	Register Data (MSB)
		4	3	Destination Address+1	0	Register Data (LSB)
			4	Op Code Address+2	1	Next Op Code
JSR			1	Op Code Address+1	1	Jump Address (LSB)
			2	FFFF	1	Restart Address (LSB)
		5	3	Stack Pointer	0	Return Address (LSB)
			4	Stack Pointer - 1	0	Return Address (MSB)
			5	Jump Address	1	First Subroutine Op Code
TIM			1	Op Code Address+1	1	Immediate Data
		4	2	Op Code Address+2	1	Address of Operand (LSB
		4	3	Address of Operand	1	Operand Data
			4	Op Code Address+3	1	Next Op Code
AIM	EIM	1	1	Op Code Address+1	1	Immediate Data
OIM			2	Op Code Address+2	1	Address of Operand (LSB
		6	3	Address of Operand	1	Operand Data
		0	4	FFFF	1	Restart Address (LSB)
			5	Address of Operand	0	New Operand Data
			6	Op Code Address+3	1	Next Op Code

- Continued -



Table 12 Cycle-by-Cycle Operation (Continued)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
NDEXED				16	
JMP		1	Op Code Address+1	1	Offset
	3	2	FFFF	1	Restart Address (LSB)
		3	Jump Address	1	First Op Code of Jump Routin
ADC ADD		1	Op Code Address+1	1	Offset
AND BIT		2	FFFF	1	Restart Address (LSB)
CMP EOR	4	3	IX+Offset	1	Operand Data
LDA ORA		4	Op Code Address+2	1	Next Op Corde
SBC SUB					
TST				1	
STA	5	1	Op Code Address+1	1	Offset
	4	2	FFFF	1	Restart Address (LSB)
		3	IX+Offset	0	Accumulator Data
ADDD		4	Op Code Address+2	1	Next Op Code
ADDD		1	Op Code Address+1	1	Offset
CPX LDD LDS LDX	5	2	FFFF IX+Offset	1	Restart Address (LSB)
SUBD	5	4	and the second s	1	Operand Data (MSB)
3000		5	IX+Offset+1 Op Code Address+2	1	Operand Data (LSB) Next Op Code
STD STS	+	1	Op Code Address+1	1	Offset
STX		2	FFFF	1	Restart Address (LSB)
OTA	5	3	IX+Offset	o	Register Data (MSB)
		4	IX+Offset+1	0	Register Data (LSB)
		5	Op Code Address+2	1	Next Op Code
JSR		1	Op Code Address+1	1	Offset
		2	FFFF	1	Restart Address (LSB)
	5	3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer – 1	0	Return Address (MSB)
		5	IX+Offset	1	First Subroutine Op Code
ASL ASR		1	Op Code Address+1	1	Offset
COM DEC		2	FFFF	1	Restart Address (LSB)
INC LSR	6	3	IX+Offset	1	Operand Data
NEG ROL	0	4	FFFF	1	Restart Address (LSB)
ROR		5	IX+Offset	0	New Operand Data
		6	Op Code Address+2	1	Next Op Code
TIM		1	Op Code Address+1	1	Immediate Data
		2	Op Code Address+2	1	Offset
	5	3	FFFF	1	Restart Address (LSB)
		4	IX+Offset	1	Operand Data
		5	Op Code Address+3	1	Next Op Code
CLR		1	Op Code Address+1	1	Offset
		2	FFFF	1	Restart Address (LSB)
	5	3	IX+Offset	1	Operand Data
		4	IX+Offset	0	00
AIRA FIRA	-	5	Op Code Address+2	1	Next Op Code
AIM EIM		1	Op Code Address+1	1	Immediate Data
OIM		2	Op Code Address+2	1	Offset
	7	3	FFFF	1	Restart Address (LSB)
	7	5	IX + Offset FFFF	1	Operand Data
		6			Restart Address (LSB)
		7	IX+Offset Op Code Address+3	0	New Operand Data
		-	Op Code Address + 3		Next Op Code



Table 12 Cycle-by-Cycle Operation (Continued)

	ss Mode &	Cycles	Cycle #	Address Bus	R/W	Data Bus
XTEND						
JMP			1	Op Code Address+1	1	Jump Address (MSB)
		3	2	Op Code Address+2	1	Jump Address (LSB)
			3	Jump Address	1	Next Op Code
ADC	ADD TST		1	Op Code Address+1	1	Address of Operand (MSE
AND	BIT		2	Op Code Address+2	1	Address of Operand (LSB)
CMP	EOR	4	3	Address of Operand	1	Operand Data
LDA	ORA		4	Op Code Address+3	1	Next Op Code
SBC	SUB			op odder tudi oso i o	'	None op oode
STA			1	Op Code Address+1	1	Destination Address (MSB
			2	Op Code Address+2	1	Destination Address (LSB)
		4	3	Destination Address	0	Accumulator Data
			4	Op Code Address+3	1	Next Op Code
ADDD			1	Op Code Address+1	1	Address of Operand (MSE
CPX	LDD		2	Op Code Address+2	1	Address of Operand (LSB)
LDS	LDX	5	3	Address of Operand	1	Operand Data (MSB)
SUBD			4	Address of Operand+1	1	Operand Data (LSB)
			5	Op Code Address+3	1	Next Op Code
STD	STS		1	Op Code Address+1	1	Destination Address (MSB
STX			2	Op Code Address+2	1	Destination Address (LSB)
		5	3	Destination Address	0	Register Data (MSB)
			4	Destination Address+1	0	Register Data (LSB)
			5	Op Code Address+3	1	Next Op Code
JSR			1	Op Code Address+1	1	Jump Address (MSB)
			2	Op Code Address + 2	1	Jump Address (LSB)
		6	3	FFFF	1	Restart Address (LSB)
		0	4	Stack Pointer	0	Return Address (LSB)
			5	Stack Pointer - 1	0	Return Address (MSB)
			6	Jump Address	1	First Subroutine Op Code
ASL	ASR		1	Op Code Address+1	1	Address of Operand (MSB
COM	DEC		2	Op Code Address + 2	1	Address of Operand (LSB)
INC	LSR	6	3	Address of Operand	1	Operand Data
NEG	ROL	0	4	FFFF	1	Restart Address (LSB)
ROR			5	Address of Operand	0	New Operand Data
			6	Op Code Address+3	1	Next Op Code
CLR			1	Op Code Address+1	1	Address of Operand (MSB
			2	Op Code Address + 2	1	Address of Operand (LSB)
		5	3	Address of Operand	1	Operand Data
			4	Address of Operand	0	00
			5	Op Code Address+3	1	Next Op Code



Table 12 Cycle-by-Cycle Operation (Continued)

	s Mode & uctions	Cycles	Cycle #	Address Bus	R/W	Data Bus
MPLIED						
ABA	ABX	1	1	Op Code Address+1	1	Next Op Code
ASL	ASLD					Tront op dodd
ASR	CBA					
CLC	CLI					
CLR	CLV					
COM	DEC					
DES	DEX					
INC	INS					
INX	LSR	1				
LSRD	ROL	'				
ROR	NOP					
SBA	SEC				1	
SEI	SEV					
TAB	TAP	1				
TBA	TPA					
TST	TSX					
TXS						
DAA	XGDX	2	1	Op Code Address + 1	1	Next Op Code
		_	2	FFFF	1	Restart Address (LSB)
PULA	PULB		1	Op Code Address+1	1	Next Op Code
		3	2	FFFF	1	Restart Address (LSB)
			3	Stack Pointer + 1	1	Data from Stack
PSHA	PSHB		1	Op Code Address+1	1	Next Op Code
			2	FFFF	1	Restart Address (LSB)
		4	3	Stack Pointer	0	Accumulator Data
			4	Op Code Address+1	1	Next Op Code
PULX			1	Op Code Address+1	1	Next Op Code
			2	FFFF	1	Restart Address (LSB)
		4	3	Stack Pointer + 1	1	Data from Stack (MSB)
			4	Stack Pointer+2	1	Data from Stack (LSB)
PSHX			1	Op Code Address+1	1	Next Op Code
			2	FFFF	1	Restart Address (LSB)
		5	3	Stack Pointer	0	Index Register (LSB)
			4	Stack Pointer – 1	0	Index Register (MSB)
			5	Op Code Address + 1	1	Next Op Code
RTS		+	1	Op Code Address + 1	1	Next Op Code
1110			2	FFFF	1	Restart Address (LSB)
		5	3	Stack Pointer + 1	1	Control of the contro
		5	4	Stack Pointer + 2	1	Return Address (MSB)
			5			Return Address (LSB)
MUL		-	1	Return Address	1 1	First Op Code of Return Routin
WICL			2	Op Code Address + 1 FFFF	1 1	Next Op Code
			_		1	Restart Address (LSB)
		-	3	FFFF	1 1	Restart Address (LSB)
		7	4	FFFF	1	Restart Address (LSB)
			5	FFFF	1	Restart Address (LSB)
			6	FFFF	1	Restart Address (LSB)
			7	FFFF	1	Restart Address (LSB)

Table 12 Cycle-by-Cycle Operation (Continued)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
mstructions		++			
IMPLIED					
WAI		1	Op Code Address+1	1	Next Op Code
		2	FFFF	1	Restart Address (LSB)
		3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer – 1	0	Return Address (MSB)
	9	5	Stack Pointer – 2	0	Index Register (LSB)
		6	Stack Pointer – 3	0	Index Register (MSB)
		7	Stack Pointer – 4	0	Accumulator, A
		8	Stack Pointer - 5	0	Accumulator B
		9	Stack Pointer – 6	0	Conditional Code Register
RTI		1	Op Code Address+1	1	Next Op Code
		2	FFFF	1	Restart Address (LSB)
		3	Stack Pointer +1	1	Conditional Code Register
		4	Stack Pointer + 2	1	Accumulator B
	10	5	Stack Pointer+3	1	Accumulator A
	10	6	Stack Pointer +4	1	Index Register (MSB)
		7	Stack Pointer +5	1	Index Register (LSB)
		8	Stack Pointer+6	1	Return Address (MSB)
		9	Stack Pointer + 7	1	Return Address (LSB)
		10	Return Address	1	First Op Code of Return Routine
SWI		1	Op Code Address+1	1	Next Op Code
		2	FFFF	1	Restart Address (LSB)
		3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer - 1	0	Return Address (MSB)
		5	Stack Pointer – 2	0	Index Register (LSB)
	12	6	Stack Pointer – 3	0	Index Register (MSB)
	12	7	Stack Pointer – 4	0	Accumulator A
		8	Stack Pointer - 5	0	Accumulator B
		9	Stack Pointer – 6	0	Conditional Code Register
		10	Vector Address FFFA	1	Address of SWI Routine (MSB)
		11	Vector Address FFFB	1	Address of SWI Routine (LSB)
		12	Address of SWI Routine	1	First Op Code of SWI Routine
SLP		1	Op Code Address+1	1	Next Op Code
		2	FFFF	1	Restart Address (LSB)
		1 1	FFFF		High Impedance-Non MPX Mod
	. 4	Sleep			Address Bus -MPX Mode
		Sicop			
		3	FFFF		Restart Address (LSB)
		4	Op Code Address+1		Next Op Code



Table 12	Cycle-by-Cycle	Operation	(Continued)
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	ess Mode & tructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
RELATI	VE.					
BCC	BCS		1	Op Code Address+1	1	Branch Offset
BEQ	BGE	3	2	FFFF	1	Restart Address (LSB)
BGT	BHI		3	Branch Address·····Test="1"	1	First Op Code of Branch Routing
BLE	BLS		3	Op Code Address+1···Test="0"	'	Next Op Code
BLT	BMT					
BNE	BPL					
BRA	BRN					
BVC	BVS					
BSR			1	Op Code Address+1	1	Offset
			2	FFFF	1	Restart Address (LSB)
		5	3	Stack Pointer	0	Return Address (LSB)
			4	Stack Pointer - 1	0	Return Address (MSB)
			5	Branch Address	1	First Op Code of Subroutine

LOW POWER CONSUMPTION MODE

The HD6303R has two low power consumption modes; sleep and standby mode.

Sleep Mode

On execution of SLP instruction, the MPU is brought to the sleep mode. In the sleep mode, the CPU stops its operation, but the contents of the registers in the CPU are retained. In this mode, the peripherals of CPU will remain active. So the operations such as transmit and receive of the SCI data and counter may keep in operation. In this mode, the power consumption is reduced to about 1/6 the value of a normal operation.

The escape from this mode can be done by interrupt, RES, STBY. The RES resets the MPU and the STBY brings it into the standby mode (This will be mentioned later). When interrupt is requested to the CPU and accepted, the sleep mode is released, then the CPU is brought in the operation mode and jumps to the interrupt routine. When the CPU has masked the interrupt, after recovering from the sleep mode, the next instruction of SLP starts to execute. However, in such a case that the timer interrupt is inhibited on the timer side, the sleep mode cannot be released due to the absence of the interrupt request to the CPU.

This sleep mode is available to reduce an average power consumption in the applications of the HD6303R which may not be always running.

Standby Mode

Bringing STBY "Low", the CPU becomes reset and all clocks of the HD6303R become inactive. It goes into the standby mode. This mode remarkably reduces the power consumptions of the HD6303R.

In the standby mode, if the HD6303R is continuously supplied with power, the contents of RAM is retained. The standby mode should escape by the reset start. The following is the typical application of this mode.

First, NMI routine stacks the CPU's internal information and the contents of SP in RAM, disables RAME bit of RAM control register, sets the standby bit, and then goes into the standby mode. If the standby bit keeps set on reset start, it means that the power has been kept during stand-by mode and the contents of RAM is normally guaranteed. The system recovery may be possible by returning SP and bringing into the condition before the standby mode has started. The timing relation for each line in this application is shown in Figure 21.

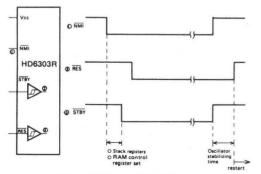


Figure 21 Standby Mode Timing

■ ERROR PROCESSING

When the HD6303R fetches an undefined instruction or fetches an instruction from unusable memory area, it generates the highest priority internal interrupt, that may protect from system upset due to noise or a program error,

Op-Code Error

Fetching an undefined op-code, the HD6303R will stack the CPU register as in the case of a normal interrupt and vector to the TRAP (\$FFEE, \$FFEF), that has a second highest priority (RES is the highest).

Address Error

When an instruction is fetched from other than a resident RAM, or an external memory area, the CPU starts the same interrupt as op-code error. In the case which the instruction is fetched from external memory area and that area is not usable, the address error can not be detected.

The address which cause address error are shown in Table 13.

This feature is applicable only to the instruction fetch, not to normal read/write of data accessing.

Transitions among the active mode, sleep mode, standby mode and reset are shown in Figure 22.

Figures 23, 24 show a system configuration.

The system flow chart of HD6303R is shown in Figure 25.

Table 13 Address Error

Address Error	
\$0000 ~ \$001F	

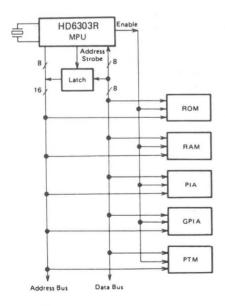


Figure 23 HD6303R MPU Multiplexed Mode

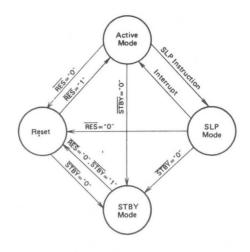


Figure 22 Transitions among Active Mode, Standby Mode, Sleep Mode, and Reset

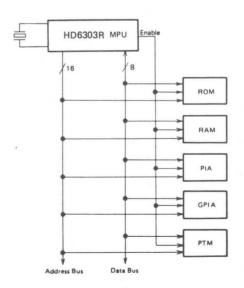


Figure 24 HD6303R MPU Non-Multiplexed Mode



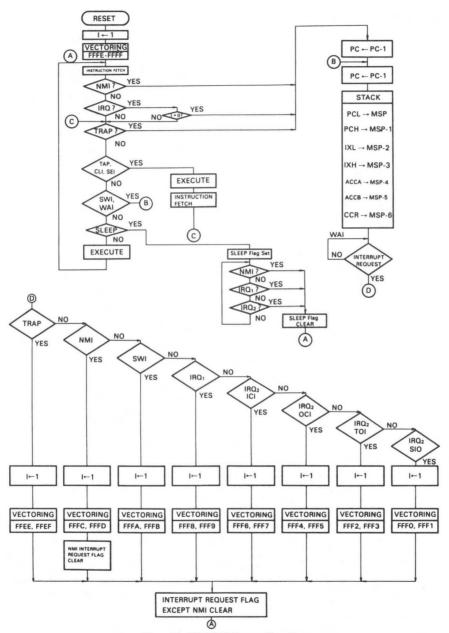
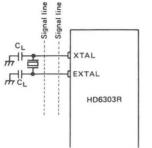


Figure 25 HD6303R System Flow Chart

PRECAUTION TO THE BOARD DESIGN OF OSCILLA-TION CIRCUIT

As shown in Fig. 26, there is a case that the cross talk disturbs the normal oscillation if signal lines are put near the oscillation circuit. When designing a board, pay attention to this. Crystal and C_L must be put as near the HD6303R as possible.



Do not use this kind of print board design.

Figure 26 Precaution to the boad design of oscillation circuit

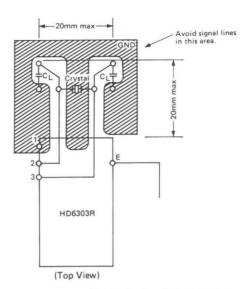


Fig. 27 Example of Oscillation Circuits in Board Design

■ PIN CONDITIONS AT SLEEP AND STANDBY STATE

Sleep State

The conditions of power supply pins, clock pins, input pins and E clock pin are the same as those of operation. Refer to Table 14 for the other pin conditions.

Standby State

Only power supply pins and STBY are active. As for the clock pin EXTAL, its input is fixed internally so the MPU is not influenced by the pin conditions. XTAL is in "1" output. All the other pins are in high impedance.

Table 14 Pin Condition in Sleep State

Pin	Mode	Non Multiplexed Mode	Multiplexed Mode
	Function	I/O Port	I/O Port
P ₂₀ ~ P ₂₄	Condition	Keep the condition just before sleep	-
Ao /P10 ~	Function	Address Bus (A ₀ ~A ₇)	I/O Port
A7/P17	Condition	Output "1"	Keep the condition just before sleep
A8 ~ A15	Function	Address Bus (A ₈ ~A ₁₅)	Address Bus (A ₈ ~A ₁₅)
A8 ~ A15	Condition	Output "1"	-
Do/Ao ~	Function	Data Bus $(D_0 \sim D_7)$	Ē: Address Bus (A ₀ ∼A ₇), E: Data Bus
D7/A7	Condition	High Impedance	Ē: Output "1", E: High Impedance
D. ATT	Function	R/W Signal	R/W Signal
R/W	Condition	Output "1"	-
AS		_	Output AS

Table 15 Pin Condition during RESET

Mode	Non-Multiplexed Mode	Multiplexed Mode
P ₂₀ ~ P ₂₄	High Impedance	4
A ₀ /P ₁₀ ~ A ₇ /P ₁₇	High Impedance	4
A8 ~ A15	High Impedance	-
Do/Ao ~ D7/A7	High Impedance	E:"1" Output E:"1" Output (Note) (High Impedance)
R/W	"1" Output	•
AS	E: "1" Output E: High Impedance	4

(Note) In the multiplexed mode, the data bus is set to "1" output state during E = "1" and it causes the conflict with the output of external memory. Following 1 and 2 should be done to avoid the conflict;

(1) Construct the system that disables the external memory during reset.

(2) Add 4.7 kΩ pull-down resistance to the AS pin to make AS pin "0" level during E = "1". This operation makes the data bus high impedance state.

■ DIFFERENCE BETWEEN HD6303 AND HD6303R

The HD6303R is an upgraded version of the HD6303. The difference between HD6303 and HD6303R is shown in Table 16

Table 16 Difference between HD6303 and HD6303R

Item	HD6303	HD6303R
Operating Mode	Mode 2: Not defined	Mode 2: Multiplexed Mode (Equivalent to Mode 4)
Electrical Character- istics	The electrical characteristics of 2MHz version (B version) are not specified.	Some characteristics are improved. The 2MHz version is guaranteed.
Timer	Has problem in output compare function. (Can be avoided by software.)	The problem is solved.

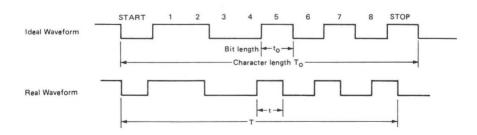
■ RECEIVE MARGIN OF THE SCI

Receive margin of the SCI contained in the HD6303R is shown in Table 17.

Note: SCI = Serial Communication Interface

Table 17

	Bit distortion tolerance (t-to) /to	Character distortion tolerance (T-To) /To
HD6303R	±37.5%	+3.75% -2.5%



APPLICATION NOTE FOR HIGH SPEED SYSTEM DESIGN USING THE HD6303R

This note describes the solutions of the potential problem caused by noise generation in the system using the HD6303R.

The CMOS ICs and LSIs featured by low power consumption

and high noise immunity are generally considered to be enough with simply designed power source and the GND line.

But this does not apply to the applications configured of high speed system or of high speed parts. Such high speed system may have a chance to work incorrectly because of the noise by the transient current generated during switching. One of example is a system in which the HD6303R directly accesses high speed memory such as the HM6264. The noise generation owing to the over current (Sometimes it may be several hundreds mA for peak level.) during switching may cause data write error.

This noise problem may be observed only at the Expanded Mode (Mode 1, 2, 4, 5 and 6) of the HD6303R.

Assuming the HD6303R is used as CPU in a system.

I. Noise Occurrence

If the HD6303R is connected to high speed RAM, a write error may occur. As shown in Fig. 28, the noise is generated in address bus during write cycle and data is written into an unexpected address from the HD6303R. This phenomenon causes random failures in systems whose data bus load capacitance exceeds the specification value (90 pF max.) and/or the impedance of the GND line is high.

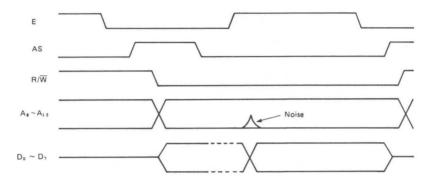
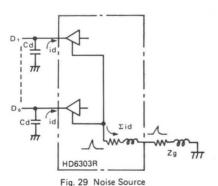


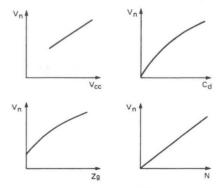
Fig. 28 Noise Occurrence in address bus during write cycle

If the data bus $D_0 \sim D_7$ changes from "FF" to "00", extremely large transient current flows through the GND line. Then the noise is generated on the LSI's V_{SS} pins proportioning to the transient current and to the impedance [Zg] of the GND line.



This noise level, V_{I} , appears on all output pins on the LSI including the address bus.

Fig. 30 shows the dependency of the noise voltage on the each parameter.



Vn: Noise Voltage Zg: GND Impedance

Cd: Data bus load capacitance

N: Number of data bus lines switching from H to L

Fig. 30 Dependency of the noise voltage on each parameter

II. Noise Protection

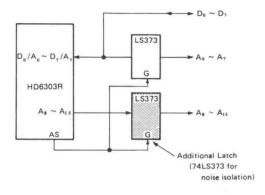
To avoid the noise on the address bus during the system operation mentioned before, there are two solutions as follows:

The one method is to isolate the HD6303R from peripheral devices so that peripherals are not affected by the noise. The other is to reduce noise level to the extent of not affecting peripherals using analog method.



1. Noise Isolation

Addresses should be latched at the negative edge of the AS signal or at the positive edge of the E signal. The 74LS373 is often used in this case.



2. Noise Reduction

As the noise level depends on each parameter such Cd, V_{CC}, Zg, the noise level can be reduced to the allowable level by controlling those analog parameters.

(a) Transient Current Reduction

- Reduce the data bus load capacitance. If large load capacitance is expected, a bus buffer should be inserted.
- Lower the power supply voltage V_{CC} within specification.
- (3) Increase a time constant at transient state by inserting a resistor ($100 \sim 200\Omega$) to Data Buses in series to keep noise level down.

Table 18 shows the relationship between a series resistor and noise level or a resistor and DC/AC characteristics.

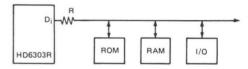


Table 18.

Item		Resistor	No	100Ω	200Ω		
	Noise Voltage Leve	ı		See Fig. 31			
DC Characteri	istics	OL	1.6 mA	1.6 mA	1.0 mA		
	f = 1 MHz	No change					
AC		t _{ADL}	190 ns	190 ns	210 ns		
Charac- teristics	f = 1.5 MHz	^t ACCM	395 ns	395 ns	375 ns		
teristics		^t ADL	160 ns	180 ns	200 ns		
	f = 2 MHz	^t ASL	20 ns	20 ns	0 ns		
		^t ACCM	270 ns	250 ns	230 ns		

Fig. 31 shows an example of the dependency of the noise voltage on the load capacitance of the data bus.*

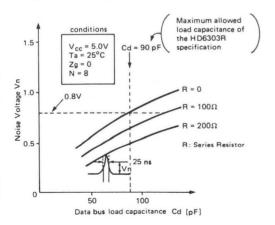


Fig. 31

*Note: The value of series resistor should be carefully selected because it heavily depends on each parameter of actual application system.

Fig. 32 shows the typical wave form of the noise.

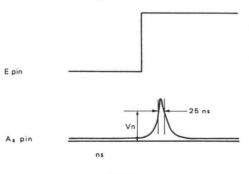


Fig. 32

- (b) Reduction of GND line impedance
 - (1) Widen the GND line width on the PC board.
 - (2) Place the HD6303R close by power source.

(3) Insert a bypass capacitor between the V_{CC} line and the GND of the HD6303R. A tantalum capacitor (about 0.1μF) is effective on the reduction.

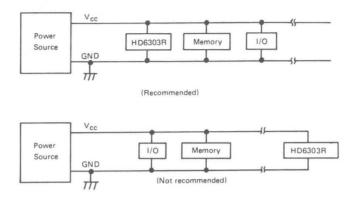


Fig. 33 Layout of the HD6303R on the PC board

■ POWER-ON RESET

At power-on it is necessary to hold RES "low" to reset the internal state of the device and to provide sufficient time for the oscillator to stabilize. Pay attention to the following.

*Just after power-on, the MPU doesn't enter reset state until the oscillation starts. This is because the reset signal is input internally, with the clocked synchronization as shown below.

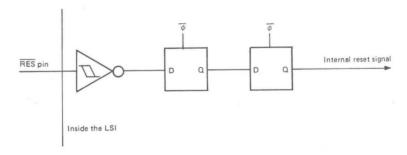


Fig. 34 Reset Circuit

Thus, just after power-on the LSI state (I/O port, mode condition etc.) is unstable until the oscillation starts. If it is

necessary to inform the LSI state to the external devices during this period, it needs to be done by the external circuits.

HD6303X,HD63A03X, HD63B03X CMOS MPU (Micro Processing Unit)

The HD6303X is a CMOS 8-bit micro processing unit (MPU) which includes a CPU compatible with the HD6301VI, 192 bytes of RAM, 24 parallel I/O pins, a Serial Communication Interface (SCI) and two timers on chip.

FEATURES

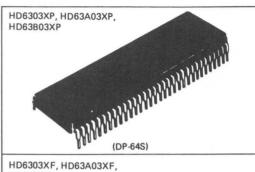
- Instruction Set Compatible with the HD6301V1
- 192 Bytes of RAM
- 24 Parallel I/O Pins 16 I/O Pins-Port 2, 6 8 Input Pins-Port 5
- Darlington Transistor Drive (Port 2, 6)
- 16-Bit Programmable Timer Input Capture Register x 1 Free Running Counter x 1

Output Compare Register x 2

- 8-Bit Reloadable Timer External Event Counter Square Wave Generation
- Serial Communication Interface
- Memory Ready
- Error-Detection (Address Trap, Op-Code Trap)
- Interrupts . . . 3 External, 7 Internal
- Up to 65k Bytes Address Space
- Low Power Dissipation Mode Sleep Mode Standby Mode
- Minimum Instruction Execution Time -0.5μs (f = 2.0 MHz)
- Wide Range of Operation $V_{CC} = 3 \sim 6V \text{ (f = 0.1 ~ 0.5 MHz)}.$

$$V_{CC} = 5V\pm10\%$$

$$\begin{cases} f = 0.1 \sim 1.0 \text{ MHz; } HD6303X \\ f = 0.1 \sim 1.5 \text{ MHz; } HD63A03X \\ f = 0.1 \sim 2.0 \text{ MHz; } HD63B03X \end{cases}$$



HD63B03XF



(FP-80)

HD6303XCP, HD63A03XCP, HD63B03XCP

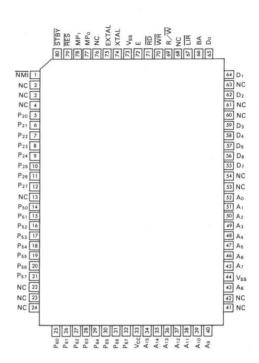


(CP-68)

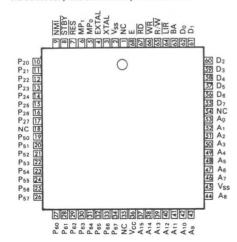
- PIN ARRANGEMENT (Top View)
- HD6303XP, HD63A03XP, HD63B03XP

Vss 1 0 XTAL 2 EXTAL 3 MP₀ 4 MP₁ 5 STBY 7 NMI 8 P₂₀ 9 P₂₁ 10 P₂₂ 11 P₂₃ 12 P₂₄ [3] P₂₅ [4] P₂₆ [5] P₂₇ [6] P₅₀ [7] P₆₁ 18 P₅₂ 19 P₅₃ 20 P₅₄ 21 P₅₅ 22 P₅₆ 23 P₅₇ 24 P₆₀ 25 P₆₁ 26 P₆₂ 27 P₆₃ 28 39 A₁₀ 38 A11 37 A12 36 A13 35 A14 34 A15 P₆₄ 29 P₆₅ 30 P₆₇ 32 33 V_{cc}

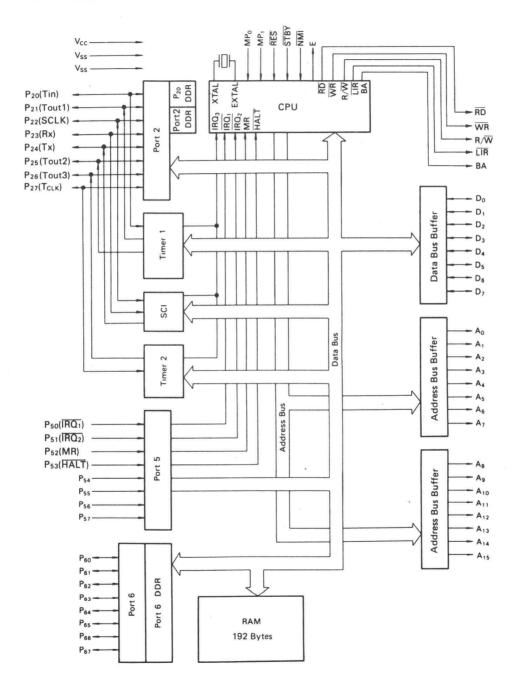
HD6303XF, HD63A03XF, HD63B03XF



HD6303XCP, HD63A03XCP, HD63B03XCP



■ BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc}	-0.3 ~ +7.0	V
Input Voltage	V _{in}	-0.3 ~ V _{CC} +0.3	V
Operating Temperature	Topr	0~+70	°C
Storage Temperature	T _{stg}	-55 ∼ +150	°C

(NOTE) This product has protection circuits in input terminal from high static electricity voltage and high electric field. But be careful not to apply overvoltage more than maximum ratings to these high input impedance protection circuits. To assure the normal operation, we recommend V_{in} , V_{out} : $V_{SS} \le (V_{in} \text{ or } V_{out}) \le V_{CC}$.

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC} = $5.0V\pm10\%$, V_{SS} = 0V, Ta = $0\sim+70^{\circ}$ C, unless otherwise noted.)

Iten	n	Symbol	Test Condition	min	typ	max	Unit
	RES, STBY			V _{CC} -0.5	_		
Input "High" Voltage	EXTAL	VIH		V _{CC} x0.7	_	V _{CC} +0.3	V
	Other Inputs			2.0	_	1 .0.5	
Input "Low" Voltage	All Inputs	VIL		-0.3	_	0.8	٧
Input Leakage Current	NMI, RES, STBY, MP ₀ , MP ₁ , Port 5	I _{in}	$V_{in} = 0.5 \sim V_{CC} - 0.5 V$	-	-	1.0	μА
Three State (off-state) Leakage Current	$A_0 \sim A_{1.5}$, $D_0 \sim D_7$, \overline{RD} , \overline{WR} , R/\overline{W} , Port 2, Port 6	I _{TSI}	$V_{in} = 0.5 \sim V_{CC} - 0.5V$	-	-	1.0	μА
O	All Outroots	1/	I _{OH} = -200μA	2.4	-	-	V
Output "High" Voltage	All Outputs	V _{OH}	I _{OH} = -10μA	V _{CC} -0.7	_	-	V
Output "Low" Voltage	All Outputs	VoL	I _{OL} = 1.6mA	-	_	0.4	V
Darlington Drive Current	Ports 2, 6	-I _{OH}	Vout = 1.5V	1.0	_	10.0	mA
Input Capacitance	All Inputs	Cin	$V_{in} = 0V$, $f = 1MHz$, Ta = 25°C	-	-	12.5	pF
Standby Current	Non Operation	I _{STB}		-	3.0	15.0	μΑ
9			Sleeping (f = 1MHz**)	-	1.5	3.0	mA
		ISLP	Sleeping (f = 1.5MHz**)	-	2.3	4.5	mA
			Sleeping (f = 2MHz**)	-	3.0	6.0	mA
Current Dissipation*			Operating (f = 1MHz**)	-	7.0	10.0	mA
		Icc	Operating (f = 1.5MHz**)	-	10.5	15.0	mA
			Operating (f = 2MHz**)	-	14.0	20.0	mA
RAM Standby Voltage		VRAM		2.0	-	-	V

 $^{^{\}circ}$ V $_{IH}$ min = V $_{CC}$ -1.0V, V $_{IL}$ max = 0.8V , All output terminals are at no load.

typ. value (f = x MHz) = typ. value (f = 1 MHz) x x max. value (f = x MHz) = max. value (f = 1 MHz) x

(both the sleeping and operating)

^{**} Current Dissipation of the operating or sleeping condition is proportional to the operating frequency. So the typ. or max. values about Current Dissipations at x MHz operation are decided according to the following formula;

• AC CHARACTERISTICS (V_{CC} = 5.0V±10%, V_{SS} = 0V, T_a = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

BUS TIMING

la		Comphal	Test	Н	D6303	K	н	063A03	3X	Н	D63B0	3X	Unit
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Uni
Cycle Time		t _{cyc}		1	_	10	0.666	-	10	0.5	-	10	μs
Enable Rise Time		t _{Er}		-	-	25	-	-	25	-	-	25	ns
Enable Fall Time		t _{Ef}		_	_	25	-	-	25	_	_	25	ns
Enable Pulse Width "	High" Level*	PWEH		450	_	-	300	-	-	220	-	-	ns
Enable Pulse Width "	Low" Level*	PWEL		450	-	_	300	_	-	220	-	-	ns
Address, R/W Delay	Γime*	t _{AD}		_	-	250	-	-	190	-	-	160	ns
Data Delay Time	Write	t _{DDW}		_	-	200	-	-	160	-	-	120	ns
Data Set-up Time	Read	t _{DSR}	Fig. 1	80	-	-	70	-	-	70	-	-	ns
Address, R/W Hold T	ime*	t _{AH}	Fig. I	80	_	_	50	-	-	35	- '	-	ns
Data Hold Time	Write*	t _{HW}		80	-	-	50	_	-	40	-	_	ns
Data Hold Time	Read	t _{HR}		0	_	_	0		_	0		_	ns
RD, WR Pulse Width*		PWRW		450	-	_	300	-	-	220	-		ns
RD, WR Delay Time		t _{RWD}		-	-	40	-	_	40	-	-	40	ns
RD, WR Hold Time		t _{HRW}		-	-	30	-	-	30	-	-	25	ns
LIR Delay Time		tola	1	-	_	200	_	-	160	_	-	120	ns
LIR Hold Time		tHLR		10	-	, '-	10		-	10	-		ns
MR Set-up Time*		t _{SMR}		400	-	_	280	_	-	230	_	-	ns
MR Hold Time*		t _{HMR}	Fig. 2	_	-	90	_	-	40	-	_	0	ns
E Clock Pulse Width	at MR	PWEMR		_	_	9	-	-	9	-	-	9	μs
Processor Control Set	t-up Time	t _{PCS}	Fig. 3, 10, 11	200	-	-	200	-	-	200	-	_	ns
Processor Control Ris	se Time	t _{PCr}	F:- 0 0	-	-	100	-	-	100	_	_	100	ns
Processor Control Fa	Processor Control Fall Time		Fig. 2, 3	-	_	100	-	-	100	-	-	100	ns
BA Delay Time		t _{BA}	Fig. 3	-	-	250	-	-	190	-	-	160	ns
Oscillator Stabilization	n Time	t _{RC}	Fig. 11	20	-	-	20	-	-	20	-	_	m
Reset Pulse Width		PWRST		3	_	_	3	_	-	3	-	-	t _{cy}

^{*} These timings change in approximate proportion to t_{CYC} . The figures in this characteristics represent those when t_{CYC} is minimum (= in the highest speed operation).

PERIPHERAL PORT TIMING

la.			Symbol	Test	Н	D6303	X	н	D63A03	3X	Н	D63B0	3X	Unit
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit	
Peripheral Data Set-up Time	Port	s 2, 5, 6	t _{PDSU}	Fig. 5	200	-	-	200	-	-	200	-	-	ns
Peripheral Data Hold Time Ports 2, 5, 6		t _{PDH}	Fig. 5	200	-	-	200	-	-	200	-	-	ns	
Delay Time (Enable Negative Transition to Peripheral Data Valid)		t _{PWD}	Fig. 6	-	· _	300	-	-	300	-	-	300	ns	

TIMER, SCI TIMING

Item			Test	Н	D6303	×	Н	D63A03	3X	н	D63B03	3X	Unit
. 11	tem	Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Onit
Timer 1 Input	Pulse Width	tpwT	Fig. 8	2.0	-	-	2.0	-	-	2.0	-	-	t _{cyc}
Pelay Time (Enable Positive ransition to Timer Output)		t _{TOD}	Fig. 7	-	-	400	-	-	400	-	-	400	ns
SCI Input	Async. Mode		Fig. 8	1.0	-	-	1.0	-	-	1.0	-	-	t _{cyc}
Clock Cycle	Clock Sync.	t _{Scyc}	Fig. 4, 8	2.0	-	-	2.0	-	-	2.0	-	-	t _{cyc}
SCI Transmit Data Delay Time (Clock Sync. Mode)		t _{TXD}		-	-	200	-	-	200	-	-	200	ns
SCI Receive Data Set-up Time (Clock Sync. Mode)		t _{SRX}	Fig. 4	290	-	-	290	-	-	290	-	-	ns
SCI Receive D (Clock Sync.)	oata Hold Time Mode)	t _{HRX}		100	-	-	100	-	-	100	-	-	ns
SCI Input Clo	ock Pulse Width	t _{PWSCK}		0.4	_	0.6	0.4	-	0.6	0.4	-	0.6	t _{Scyc}
Timer 2 Input	t Clock Cycle	t _{tcyc}	i	2.0	-	-	2.0	-	-	2.0	-	-	t _{cyc}
Timer 2 Input Clock Pulse Width		t _{PWTCK}	Fig. 8	200	-	-	200	-	-	200	-	-	ns
Timer 1·2, SCI Input Clock Rise Time		t _{CKr}		-	-	100	-	-	100	-	-	100	ns
Timer 1.2, SC Fall Time	CI Input Clock	t _{CKf}		_	-	100	-	-	100	-	-	100	ns

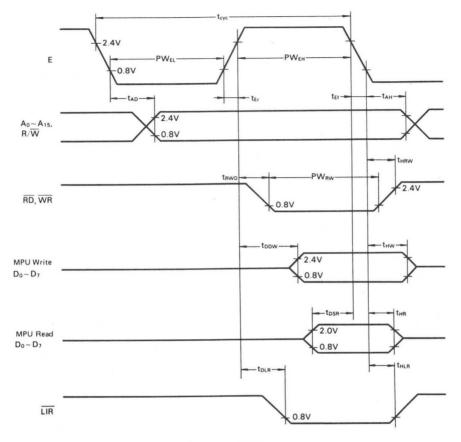


Figure 1 Bus Timing

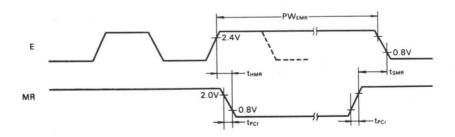


Figure 2 Memory Ready and E Clock Timing

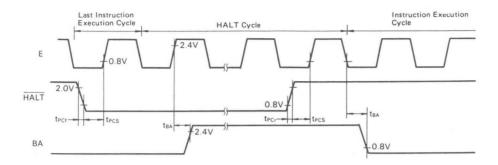
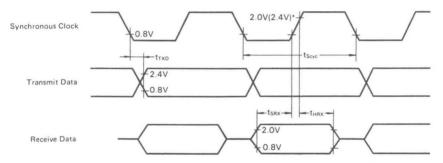
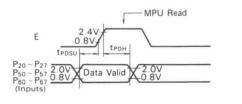


Figure 3 HALT and BA Timing



* 2.0V is high level when clock input. 2.4V is high level when clock output.

Figure 4 SCI Clocked Synchronous Timing



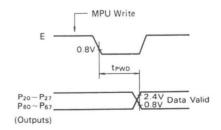
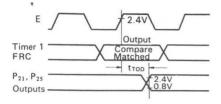
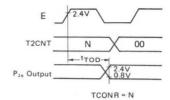


Figure 5 Port Data Set-up and Hold Times (MPU Read)

Figure 6 Port Data Delay Times (MPU Write)

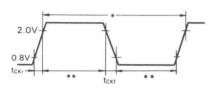




(a) Timer 1 Output Timing

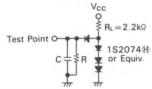
(b) Timer 2 Output Timing

Figure 7 Timer Output Timing



*Timer 2; ttcyc SCI ; tScyc SCI ; tPWT Timer 2; tPWTCK SCI ; tPWSCK

Figure 8 Timer 1.2, SCI Input Clock Timing



C =90pF for $D_0 \sim D_7$, $A_0 \sim A_{1.5}$, E=30pF for Port 2, Port 6, \overline{RD} , \overline{WR} , R/\overline{W} , BA, \overline{LIR} R=12k Ω

Figure 9 Bus Timing Test Loads (TTL Load)

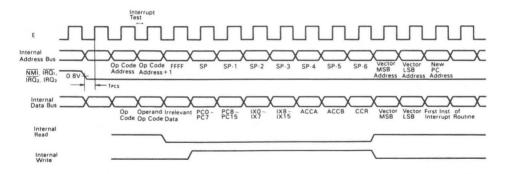


Figure 10 Interrupt Sequence

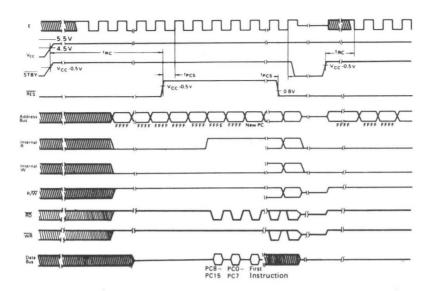


Figure 11 Reset Timing

■ FUNCTIONAL PIN DESCRIPTION

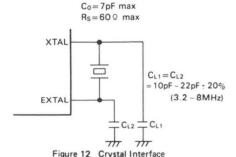
· Vcc, Vss

 V_{CC} and V_{SS} provide power to the MPU with 5V±10% supply. In the case of low speed operation (fmax = 500kHz), the MPU can operate with three through six volts. Two V_{SS} pins should be tied to ground.

XTAL, EXTAL

These two pins interface with an AT-cut parallel resonant crystal. Divide-by-four circuit is on chip, so if 4MHz crystal oscillator is used, the system clock is 1MHz for example.

AT Cut Parallel Resonant Crystal Oscillator



EXTAL pin can be drived by the external clock of 45 to 55% duty, and one fourth frequency of the external clock is produced in the LSI. The external clock frequency should be less than four times of the maximum operable frequency. When using the external clock, XTAL pin should be open. Fig. 12 shows an example of the crystal interface. The crystal and C_{L1}, C_{L2} should be mounted as close as possible to XTAL

and EXTAL pins. Any line must not cross the line between the crystal oscillator and XTAL, EXTAL.

• STBY

This pin makes the MPU standby mode. In "Low" level, the oscillation stops and the internal clock is stabilized to make reset condition. To retain the contents of RAM at standby mode, "0" should be written into RAM enable bit (RAME). RAME is the bit 6 of the RAM/port 5 control register at \$0014. RAM is disabled by this operation and its contents is sustained.

Refer to "LOW POWER DISSIPATION MODE" for the standby mode.

Reset (RES)

This pin resets the MPU from power OFF state and provides a startup procedure. During power-on, RES pin must be held "Low" level for at least 20ms.

The CPU registers (accumulator, index register, stack pointer, condition code register except for interrupt mask bit), RAM and the data register of a port are not initialized during reset, so their contents are unknown in this procedure.

To reset the MPU during operation, RES should be held "Low" for at least 3 system-clock cycles. At the 3rd cycle during "Low" level, all the address buses become "High". When RES remains "Low", the address buses keep "High". If RES becomes "High", the MPU starts the next operation.

- (1) Latch the value of the mode program pins; MP₀ and MP₁.
- (2) Initialize each internal register (Refer to Table 3).
- (3) Set the interrupt mask bit. For the CPU to recognize the maskable interrupts IRQ₁, IRQ₂ and IRQ₃, this bit should be cleared in advance.
- (4) Put the contents (= start address) of the last two addresses (\$FFFE, \$FFFF) into the program counter and start the program from this address. (Refer to Table 1).
 - *The MPU is usable to accept a reset input until the clock

becomes normal oscillation after power on (max. 20ms). During this transient time, the MPU and I/O pins are undefined. Please be aware of this for system designing.

Enable (E)

This pin provides a TTL-compatible system clock to external circuits. Its frequency is one fourth that of the crystal oscillator or external clock. This pin can drive one TTL load and 90pF capacitance.

Non-Maskable Interrupt (NMI)

When the falling edge of the input signal is detected at this pin, the CPU begins non-maskable interrupt sequence internally. As well as the IRQ mentioned below, the instruction being executed at $\overline{\text{NMI}}$ signal detection will proceed to its completion. The interrupt mask bit of the condition code register doesn't affect non-maskable interrupt at all.

When starting the acknowledge to the NMI, the contents of the program counter, index register, accumulators and condition code register will be saved onto the stack. Upon completion of this sequence, a vector is fetched from SFFFC and SFFFD to transfer their contents into the program counter and branch to the non-maskable interrupt service routine.

(Note) After reset start, the stack pointer should be initialized on an appropriate memory area and then the falling edge should be input to NMI pin.

Interrupt Request (IRQ₁, IRQ₂)

These are level-sensitive pins which request an internal interrupt sequence to the CPU. At interrupt request, the CPU will complete the current instruction before its request acknowledgement. Unless the interrupt mask in the condition code register is set, the CPU starts an interrupt sequence; if set, the interrupt request will be ignored. When the sequence starts, the contents of the program counter, index register, accumulators and condition code register will be saved onto the stack, then the CPU sets the interrupt mask bit and will not acknowledge the maskable request. During the last cycle, the CPU fetches vectors depicted in Table 1 and transfers their contents to the program counter and branches to the service routine.

The CPU uses the external interrupt pins, $\overline{IRQ_1}$ and $\overline{IRQ_2}$, also as port pins P_{50} and P_{51} , so it provides an enable bit to Bit 0 and 1 of the RAM port 5 control register at \$0014. Refer to "RAM/PORT 5 CONTROL REGISTER" for the details.

When one of the internal interrupts, ICI, OCI, TOI, CMI or SIO is generated, the CPU produces internal interrupt signal (IRQ₃). IRQ₃ functions just the same as $\overline{\text{IRQ}_1}$ or $\overline{\text{IRQ}_2}$ except for its vector address. Fig. 13 shows the block diagram of the interrupt circuit.

Table 1 Interrupt Vector Memory Map

Deionitu	Ve	ctor	l-t
Priority	MSB	LSB	Interrupt
Highest	FFFE	FFFF	RES
†	FFEE	FFEF	TRAP
	FFFC	FFFD	NMI
	FFFA	FFFB	SWI (Software Interrupt)
	FFF8	FFF9	ĪRQ ₁
	FFF6	FFF7	ICI (Timer 1 Input Capture)
	FFF4	FFF5	OCI (Timer 1 Output Compare 1, 2)
	FFF2	FFF3	TOI (Timer 1 Overflow)
	FFEC	FFED	CMI (Timer 2 Counter Match)
1	FFEA	FFEB	ĪRQ ₂
Lowest	FFF0	FFF1	SIO (RDRF+ORFE+TDRE)

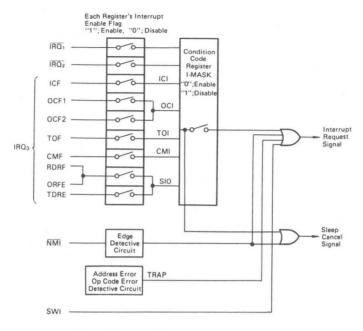


Figure 13 Interrupt Circuit Block Diagram

Mode Program (MP₀, MP₁)

To operate MPU, MP_0 pin should be connected to "High" level and MP_1 should be connected to "Low" level (refer to Fig. 15).

Read/Write (R/W)

This signal, usually be in read state ("High"), shows whether the CPU is in read ("High") or write ("Low") state to the peripheral or memory devices. This can drive one TTL load and 30pF capacitance.

· RD, WR

These signals show active low outputs when the CPU is reading/writing to the peripherals or memories. This enables the CPU easy to access the peripheral LSI with $\overline{\text{RD}}$ and $\overline{\text{WR}}$ input pins. These pins can drive one TTL load and 30pF capacitance.

Load Instruction Register (LIR)

This signal shows the instruction opecode being on data bus (active low). This pin can drive one TTL load and 30pF capacitance.

Memory Ready (MR; P₅₂)

This is the input control signal which stretches the system clock's "High" period to access low-speed memories. During this signal is in "High", the system clock operates in normal sequence. But this signal in "Low", the "High" period of the system clock will be stretched depending on its "Low" level duration in integral multiples of the cycle time. This allows the CPU to interface with low-speed memories (see Fig. 2). Up to 9 µs can be stretched.

During internal address space access or nonvalid memory

access, MR is prohibited internally to prevent decrease of operation speed. Even in the halt state, MR can also stretch "High" period of system clock to allow peripheral devices to access low-speed memories. As this signal is used also as P₅₂, an enable bit is provided at bit 2 of the RAM/port 5 control register at \$0014. Refer to "RAM/PORT 5 CONTROL REGISTER" for more details.

• Halt (HALT; Ps3)

This is an input control signal to stop instruction execution and to release buses. When this signal switches to "Low", the CPU stops to enter into the halt state after having executed the present instruction. When entering into the halt state, it makes BA (P_{74}) "High" and also an address bus, data bus, \overline{RD} , \overline{WR} , R/\overline{W} high impedance. When an interrupt is generated in the halt state, the CPU uses the interrupt handler after the halt is cancelled.

(Note) Please don't switch the HALT signal to "Low" when the CPU executes the WAI instruction and is in the interrupt wait state to avoid the trouble of the CPU's operation after the halt is cancelled.

Bus Available (BA)

This is an output control signal which is normally "Low" but "High" when the CPU accepts \overline{HALT} and releases the buses. The HD6800 and HD6802 make BA "High" and release the buses at WAI execution, while the HD6303X doesn't make BA "High" under the same condition. But if the \overline{HALT} becomes "Low" when the CPU is in the interrupt wait state after having executed the WAI, the CPU makes BA "High" and releases the buses. And when the \overline{HALT} becomes "High", the CPU returns to the interrupt wait state.



■ PORT

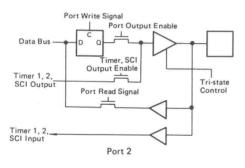
The HD6303X provides three I/O ports. Table 2 gives the address of ports and the data direction register and Fig. 14 the block diagrams of each port.

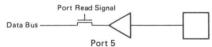
Table 2 Port and Data Direction Register Address

Port	Port Address	Data Direction Register
Port 2	\$0003	\$0001
Port 5	\$0015	_
Port 6	\$0017	\$0016

Port 2

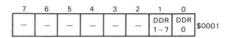
An 8-bit input/output port. The data direction register (DDR) of port 2 controls the I/O state. It provides two bits; bit 0 decides the I/O direction of P_{20} and bit 1 the I/O direction of P_{21} to P_{27} ("0" for input, "1" for output).





Port 2 is also used as an I/O pin for the timers and the SCI. When used as an I/O pin for the timers and the SCI, port 2 except P_{20} automatically becomes an input or an output depending on their functions regardless of the data direction register's value.

Port 2 Data Direction Register



A reset clears the DDR of port 2 and configures port 2 as an input port. This port can drive one TTL and 30pF capacitance. In addition, it can produce 1mA current when $V_{out} = 1.5V$ to drive directly the base of Darlington transistors.

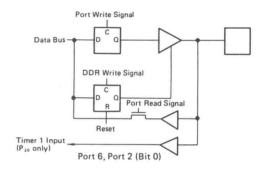


Figure 14 Port Block Diagram

Port 5

An 8-bit port for input only. The lower four bits are also usable as input pins for interrupt, MR and HALT.

Port 6

An 8-bit I/O port. This port provides an 8-bit DDR corresponding to each bit and can specify input or output by the bit ("0" for input, "1" for output). This port can drive one TTL load and 30pF capacitance. A reset clears the DDR of port 6. In addition, it can produce ImA current when Voot = 1.5V to drive directly the base of Darlington transistors.

BUS

D₀~D₂

These pins are data bus and can drive one TTL load and 90pF capacitance respectively.

A₀~A₁₅

These pins are address bus and can drive one TTL load and 90pF capacitance respectively.

■ RAM/PORT 5 CONTROL REGISTER

The control register located at \$0014 controls on-chip

RAM and port 5.

RAM/Port 5 Control Register

7	6	5	4	3	2	1	0	
STBY PWR	RAME	-	_	HLTE	MRE	IRQ ₂ E	IRQ1	\$0014

Bit 0, Bit 1 IRQ1, IRQ2 Enable Bit (IRQ1E, IRQ2E)

When using P_{50} and P_{51} as interrupt pins, write "1" in these bits. When "0", the CPU doesn't accept an external interrupt or a sleep cancellation by the external interrupt. These bits become "0" during reset.

Bit 2 Memory Ready Enable Bit (MRE)

When using P_{52} as an input for Memory Ready signal, write "1" in this bit. When "0", the memory ready function is prohibited and P_{52} can be used as I/O port. This bit becomes "1" during reset.

Bit 3 Halt Enable bit (HLTE)

When using P53 as an input for Halt signal, write "1" in this

bit. When "0", the halt function is prohibited and P_{53} can be used as I/O port. This bit becomes "1" during reset.

(Note) When using P₅₂ and P₅₃ as the input ports in mode 1 and 2, MRE and HLTE bit should be cleared just after the reset.

Notice that memory ready and halt function is enable till MRE and HLTE bit is cleared.

Bit 4, Bit 5 Not Used.

Bit 6 RAM Enable (RAME)

On-chip RAM can be disabled by this control bit. By resetting the MPU, "1" is set to this bit, and on-chip RAM is enabled. This bit can be written "1" or "0" by software. When RAM is in disable condition (= logic "0"), on-chip RAM is invalid and the CPU can read data from external memory. This bit should be "0" before getting into the standby mode to protect on-chip RAM data.

Bit 7 Standby Power Bit (STBY PWR)

When V_{CC} is not provided in standby mode, this bit is cleared. This is a flag for both read/write by software. If this bit is set before standby mode, and remains set even after returning from standby mode, V_{CC} voltage is provided during standby mode and the on-chip RAM data is valid.

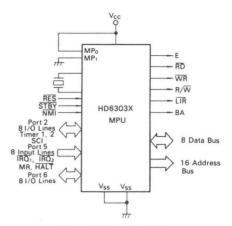


Figure 15 Operation Mode

MEMORY MAP

The MPU can address up to 65k bytes. Fig. 16 gives memory map of HD6303X. 32 internal registers use addresses from "00" as shown in Table 3.

Table 3 Internal Register

Address	Registers	R/W***	Initialize at RESET
00	-	_	_
01	Port 2 Data Direction Register	W	\$FC
02*	-	_	-
03	Port 2	R/W	Undefined
04*	-	-	-
05	_	_	_
06*	-	-	_
07*	-	_	_
08	Timer Control/Status Register 1	R/W	\$00
09	Free Running Counter ("High")	R/W	\$00
0A	Free Running Counter ("Low")	R/W	\$00
OB	Output Compare Register 1 ("High")	R/W	\$FF
0C	Output Compare Register 1 ("Low")	R/W	\$FF
0D	Input Capture Register ("High")	R	\$00
0E	Input Capture Register ("Low")	R	\$00
0F	Timer Control/Status Register 2	R/W	\$10
10	Rate, Mode Control Register	R/W	\$00
11	Tx/Rx Control Status Register	R/W	\$20
12	Receive Data Register	R	\$00
13	Transmit Data Register	W	\$00
14	RAM/Port 5 Control Register	R/W	\$7C or \$FC
15	Port 5	R	_
٦6	Port 6 Data Direction Register	W	\$00

(continued)



Table 3 Internal Register

Address	Registers	R/W***	Initialize at RESET
17	Port 6	R/W	Undefined
18*	-	-	_
19	Output Compare Register 2 ("High")	R/W	\$FF
1A	Output Compare Register 2 ("Low")	R/W	\$FF
1B	Timer Control/Status Register 3	R/W	\$20
1C	Time Constant Register	W	\$FF
1D	Timer 2 Up Counter	R/W	\$00
1E	-	_	_
1F**	Test Register	_	_

External Address.

** Test Register. Do not access to this register.

*** R : Read Only Register
W : Write Only Register
R/W: Read/Write Register

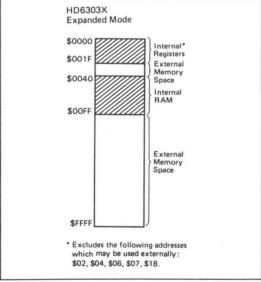


Figure 16 HD6303X Memory Map

TIMED 1

The HD6303X provides a 16-bit programmable timer which can simultaneously measure an input waveform and generate two independent output waveforms. The pulse widths of both input/output waveforms vary from microseconds to seconds.

Timer 1 is configurated as follows (refer to Fig. 18).

- · Control/Status Register 1 (8 bit)
- · Control/Status Register 2 (7 bit)
- · Free Running Counter (16 bit)
- Output Compare Register 1 (16 bit)
- · Output Compare Register 2 (16 bit)
- · Input Capture Register (16 bit)

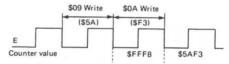
• Free-Running Counter (FRC) (\$0009 : 000A)

The key timer element is a 16-bit free-running counter driven

and incremented by system clock. The counter value is readable by software without affecting the counter. The counter is cleared by reset.

When writing to the upper byte (\$09), the CPU writes the preset value (\$FFF8) into the counter (address \$09, \$0A) regardless of the write data value. But when writing to the lower byte (\$0A) after the upper byte writing, the CPU writes not only the lower byte data into lower 8 bit, but also the upper byte data into higher 8 bit of the FRC.

The counter will be as follows when the CPU writes to it by double store instructions (STD, STX etc.).



In the case of the CPU write (\$5AF3) to the FRC

Figure 17 Counter Write Timing

Output Compare Register (OCR) (\$000B, \$000C; OCR1) (\$0019, \$001A; OCR2)

The output compare register is a 16-bit read/write register which can control an output waveform. The data of OCR is always compared with the FRC.

When the data matches, output compare flag (OCF) in the timer control/status register (TCSR) is set. If an output enable bit (OE) in the TCSR2 is "1", an output level bit (OLVL) in the TCSR will be output to bit 1 (Tout 1) and bit 5 (Tout 2) of port 2. To control the output level again by the next compare, the value of OCR and OLVL should be changed. The OCR is set to \$FFFF at reset. The compare function is inhibited for a cycle just after a write to the OCR or to the upper byte of the FRC. This is to begin the comparison after setting the 16-bit value valid in the register and to inhibit the compare function at this cycle, because the CPU writes the upper byte to the FRC, and at the next cycle the counter is set to \$FFF8.

* For data write to the FRC or the OCR, 2-byte transfer instruction (such as STX etc.) should be used.

Input Capture Register (ICR) (\$000D : 000E)

The input capture register is a 16-bit read only register which stores the FRC's value when external input signal transition generates an input capture pulse. Such transition is controlled by input edge bit (IEDG) in the TCSR1.

In order to input the external input signal to the edge detecter, a bit of the DDR corresponding to bit 0 of port 2 should be cleared ("0"). When an input capture pulse occurs by the external input signal transition at the next cycle of CPU's high-byte read of the ICR, the input capture pulse will be delayed by one cycle. In order to ensure the input capture operation, a CPU read of the ICR needs 2-byte transfer instruction. The input pulse width should be at least 2 system cycles. This register is cleared (\$0000) during reset.

• Timer Control/Status Register 1 (TCSR1) (\$0008)

The timer control/status register 1 is an 8-bit register. All bits are readable and the lower 5 bits are also writable. The upper 3 bits are read only which indicate the following timer status.

Bit 5 The counter value reached to \$0000 as a result of counting-up (TOF).

Bit 6 A match has occured between the FRC and the OCR 1 (OCF1).

Bit 7 Defined transition of the timer input signal causes the counter to transfer its data to the ICR (ICF).

The followings are each bit descriptions.

Timer Control/Status Register 1

7	6	5	4	3	2	1	0	
ICF	OCF1	TOF	EICI	EOCI1	ETOI	IEDG	OLVL1	\$0008

Bit 0 OLVL1 Output Level 1

OLVL1 is transferred to port 2, bit 1 when a match occurs between the counter and the OCR1. If bit 0 of the TCSR2 (OE1) is set to "1", OLVL1 will appear at bit 1 of port 2.

Bit 1 IEDG Input Edge

This bit determines which edge, rising or falling, of input signal of port 2, bit 0 will trigger data transfer from the counter to the ICR. For this function, the DDR corresponding to port 2, bit 0 should be cleared beforehand.

IEDG=0, triggered on a falling edge ("High" to "Low")

IEDG=1, triggered on a rising edge ("Low" to "High")

Bit 2 ETOI Enable Timer Overflow Interrupt

When this bit is set, an internal interrupt (IRQ3) by TOI interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 3 EOCI1 Enable Output Compare Interrupt 1

When this bit is set, an internal interrupt (IRQ3) by OCII interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 4 EICI Enable Input Capture Interrupt

When this bit is set, an internal interrupt (IRQ3) by ICI interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 5 TOF Timer Overflow Flag

This read-only bit is set when the counter increments from \$FFFF by 1. Cleared when the counter's upper byte (\$0009) is ready by the CPU after the TCSR1 read.

Bit 6 OCF1 Output Compare Flag 1

This read-only bit is set when a match occurs between the OCR1 and the FRC. Cleared when writing

to the OCR1 (\$000B or \$000C) after the TCSR1 or TCSR2 read.

Bit 7 ICF Input Capture Flag

This read-only bit is set when an input signal of port 2, bit 0 makes a transition as defined by IEDG and the FRC is transferred to the ICR. Cleared when reading the upper byte (\$000D) of the ICR following the TCSR1 or TCSR2 read.

• Timer Control/Status Register 2 (TCSR2) (\$000F)

The timer control/status register 2 is a 7-bit register. All bits are readable and the lower 4 bits are also writable. But the upper 3 bits are read-only which indicate the following timer status.

Bit 5 A match has occured between the FRC and the OCR2 (OCF2).

Bit 6 The same status flag as the OCF1 flag of the TCSR1, bit 6.

Bit 7 The same status flag as the ICF flag of the TCSR1, bit 7. The followings are the each bit descriptions.

Timer Control/Status Register 2

7	6	5	4	3	2	1	0	
ICF	OCF1	OCF2	-	EOC12	OLVL 2	OE2	OE1	\$000F

Bit 0 OE1 Output Enable 1

This bit enables the OLVL1 to appear at port 2, bit 1 when a match has occurred between the counter and the output compare register 1. When this bit is cleared, bit 1 of port 2 will be an I/O port. When set, it will be an output of OLVL1 automatically.

Bit 1 OE2 Output Enable 2

This bit enables the OLVL2 to appear at port 2, bit 5 when a match has occurred between the counter and the output compare register 2. When this bit is cleared, port 2, bit 5 will be an I/O port. When set, it will be an output of OLVL2 automatically.

Bit 2 OLVL2 Output Level 2

OLVL2 is transferred to port 2, bit 5 when a match has occurred between the counter and the OCR2. If bit 5 of the TCSR2 (OE2) is set to "1", OLVL2 will appear at port 2, bit 5.

Bit 3 EOCI2 Enable Output Compare Interrupt 2

When this bit is set, an internal interrupt (IRQ3) by OCI2 interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 4 Not Used

Bit 5 OCF2 Output Compare Flag 2

This read-only bit is set when a match has occurred between the counter and the OCR2. Cleared when writing to the OCR2 (\$0019 or \$001A) after the TCSR2 read.

Bit 6 OCF1 Output Compare Flag 1

Bit 7 ICF Input Capture Flag

OCF1 and ICF addresses are partially decoded. The CPU read of the TCSR1/TCSR2 makes it possible to read OCF1 and ICF into bit 6 and bit 7.

Both the TCSR1 and TCSR2 will be cleared during reset.

(Note) If OE1 or OE2 is set to "1" before the first output compare match occurs after reset restart, bit 1 or bit 5 of port 2 will produce "0" respectively.

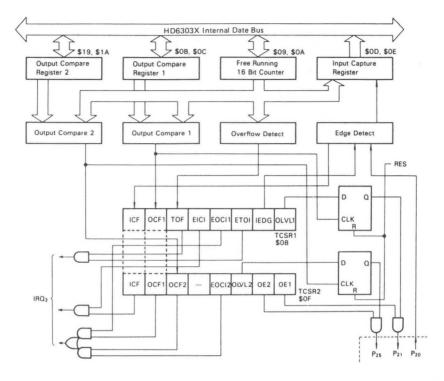


Figure 18 Timer 1 Block Diagram

■ TIMER 2

In addition to the timer 1, the HD6303X provides an 8-bit reloadable timer, which is capable of counting the external event. This timer 2 contains a timer output, so the MPU can generate three independent waveforms (refer to Fig. 19).

The timer 2 is configured as follows:

Control/Status Register 3 (7 bit)

8-bit Up Counter

Time Constant Register (8 bit)

Timer 2 Up Counter (T2CNT) (\$001D)

This is an 8-bit up counter which operates with the clock decided by CKS0 and CKS1 of the TCSR3. The CPU can read the value of the counter without affecting the counter. In addition, any value can be written to the counter by software even during counting.

The counter is cleared when a match occurs between the counter and the TCONR or during reset.

If a write operation is made by software to the counter at the cycle of counter clear, it does not reset the counter but put the write data to the counter.

• Time Constant Register (TCONR) (\$001C)

The time constant register is an 8-bit write only register. It is always compared with the counter.

When a match has occurred, counter match flag (CMF) of the timer control status register 3 (TCSR3) is set and the value selected by TOSO and TOSI of the TCSR3 will appear at port 2, bit 6. When CMF is set, the counter will be cleared simultaneously and then start counting from \$00. This enables regular interrupts and waveform outputs without any software support. The TCONR is set to "\$FF" during reset.

• Timer Control/Status Register 3 (TCSR3) (\$001B)

The timer control/status register 3 is a 7-bit register. All bits are readable and 6 bits except for CMF can be written.

The followings are each pin descriptions.



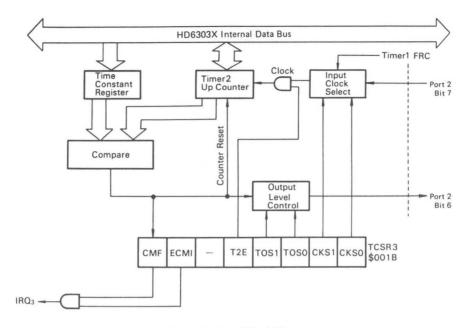


Figure 19 Timer 2 Block Diagram

Bit 0 CKS0 Input Clock Select 0 Bit 1 CKS1 Input Clock Select 1

Input clock to the counter is selected as shown in Table 4 depending on these two bits. When an external clock is selected, bit 7 of port 2 will be a clock input automatically. Timer 2 detects the rising edge of the external clock and increments the counter. The external clock is countable up to half the frequency of the system clock.

Table 4 Input Clock Select

CKS1	CKS0	Input Clock to the Counter
0	0	E clock
0	1	E clock/8*
1	0	E clock/128*
1	1	External clock

^{*} These clocks come from the FRC of the timer 1. If one of these clocks is selected as an input clock to the up counter, the CPU should not write to the FRC of the timer 1.

Bit 2 TOS0 Timer Output Select 0

Bit 3 TOS1 Timer Output Select 1

When a match occurs between the counter and the TCONR timer 2 outputs shown in Table 5 will appear at port 2, bit 6 depending on these two bits. When both TOSO and TOS1 are "0", bit 6 of port 2 will be an I/O port.

Table 5 Timer 2 Output Select

TOS1	TOS0	Timer Output
0	0	Timer Output Inhibited
0	1	Toggle Output*
1	0	Output "0"
1	1	Output "1"

^{*} When a match occurs between the counter and the TCONR, timer 2 output level is reversed. This leads to production of a square wave with 50% duty to the external without any software support.

Bit 4 T2E Timer 2 Enable Bit

When this bit is cleared, a clock input to the up counter is prohibited and the up counter stops. When set to "1", a clock selected by CKS1 and CKS0 (Table 4) is input to the up counter.

(Note) P₂₆ outputs "0" when T2E bit cleared and timer 2 set in output enable condition by TOS1 or TOS0. It also outputs "0" when T2E bit set "1" and timer 2 set in output enable condition before the first counter match occurs.

Bit 5 Not Used

Bit 6 ECMI Enable Counter Match Interrupt

When this bit is set, an internal interrupt (IRQ3) by CMI is enabled. When cleared, the interrupt is inhibited.

Bit 7 CMF Counter Match Flag

This read-only bit is set when a match occurs between the up counter and the TCONR. Cleared by writing "0" by software write (unable to write "1" by software).

Each bit of the TCSR3 is cleared during reset.

■ SERIAL COMMUNICATION INTERFACE (SCI)

The HD6303X SCI contains two operation modes; one is an asynchronous mode by the NRZ format and the other is a clocked synchronous mode which transfers data synchronizing with the serial clock.

The SCI consists of the following registers as shown in Fig. 20 Block Diagram:

- · Control/Status Register (TRCSR)
- · Rate/Mode Control Register (RMCR)
- · Receive Data Register (RDR)
- · Receive Data Shift Register (RDSR)
- · Transmit Data Register (TDR)
- · Transmit Data Shift Register (TDSR)

The serial I/O hardware requires an initialization by software for operation. The procedure is usually as follows:

- Write a desirable operation mode into each corresponding control bit of the RMCR.
- Write a desirable operation mode into each corresponding control bit of the TRCSR.

When using bit 3 and 4 of port 2 for serial I/O only, there is no problem even if TE and RE bit are set. But when setting the baud rate and operation mode, TE and RE should be "0". When clearing TE and RE bit and setting them again, more than 1 bit cycle of the current baud rate is necessary. If set in less than 1 bit cycle, there may be a case that the internal transmit/receive initialization fails.

Asynchronous Mode

An asynchronous mode contains the following two data formats:

- 1 Start Bit + 8 Bit Data + 1 Stop Bit
- 1 Start Bit + 9 Bit Data + 1 Stop Bit

In addition, if the 9th bit is set to "1" when making 9 bit data format, the format of

1 Start bit + 8 Bit Data + 2 Stop Bit

is also transferred.

Data transmission is enabled by setting TE bit of the TRCSR, then port 2, bit 4 will become a serial output independently of

the corresponding DDR.

For data transmit, both the RMCR and TRCSR should be set under the desirable operating conditions. When TE bit is set during this process, 10 bit preamble will be sent in 8-bit data format and 11 bit in 9-bit data format. When the preamble is produced, the internal synchronization will become stable and the transmitter is ready to act.

The conditions at this stage are as follows.

 If the TDR is empty (TDRE=1), consecutive 1's are produced to indicate the idle state. 2) If the TDR contains data (TDRE=0), data is sent to the transmit data shift register and data transmit starts.

During data transmit, a start bit of "0" is transmitted first. Then 8-bit or 9-bit data (starts from bit 0) and a stop bit "1" are transmitted.

When the TDR is "empty", hardware sets TDRE flag bit. If the CPU doesn't respond to the flag in proper timing (the TDRE is in set condition till the next normal data transfer starts from the transmit data register to the transmit sift register), "1" is transferred instead of the start bit "0" and continues to be transferred till data is provided to the data register. While the TDRE is "1", "0" is not transferred.

Data receive is possible by setting RE bit. This makes port 2, bit 3 be a serial input. The operation mode of data receive is decided by the contents of the TRCSR and RMCR. The first "0" (space) synchronizes the receive bit flow. Each bit of the following data will be strobed in the middle. If a stop bit is not "1", a framing error assumed and ORFE is set.

When a framing error occurs, receive data is transferred to the receive data register and the CPU can read error-generating data. This makes it possible to detect a line break.

If the stop bit is "1", data is transferred to the receive data register and an interrupt flag RDRF is set. If RDRF is still set when receiving the stop bit of the next data, ORFE is set to indicate overrun generation.

When the $CP\bar{U}$ read the receive data register as a response to RDRF flag or ORFE flag after having read TRCS, RDRF or

ORFE is cleared.

(Note) Clock Source in Asynchronous Mode

If CC1: CC0 = 10, the internal bit rate clock is provided at P_{22} regardless of the values for TE or RE. Maximum clock rate is $E\div 16$.

If both CC1 and CC0 are set, an external TTL compatible clock must be connected to P_{22} at sixteen times $(16\times)$ the desired bit rate, but not greater than E.

Clocked Synchronous Mode

In the clocked synchronous mode, data transmit is synchronized with the clock pulse. The HD6303X SC1 provides functionally independent transmitter and receiver which makes full duplex operation possible in the asynchronous mode. But in the clocked synchronous mode an SCI clock I/O pin is only P_{22} , so the simultaneous receive and transmit operation is not available. In this mode, TE and RE should not be in set condition ("1") simultaneously. Fig. 21 gives a synchronous clock and a data format in the clocked synchronous mode.

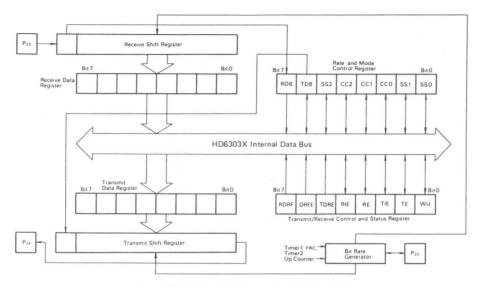


Figure 20 Serial Communication Interface Block Diagram

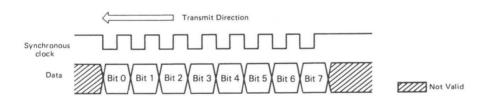
Data transmit is realized by setting TE bit in the TRCSR. Port 2, bit 4 becomes an output unconditionally independent of the value of the corresponding DDR.

Both the RMCR and TRCSR should be set in the desirable operating condition for data transmit.

When an external clock input is selected, data transmit is

performed under the TDRE flag "0" from port 2, bit 4, synchronizing with 8 clock pulses input from external to port 2, bit 2.

Data is transmitted from bit 0 and the TDRE is set when the transmit data shift register is "empty". More than 9th clock pulse of external are ignored.



- · Transmit data is output from a falling edge of a synchronous clock to the next falling edge.
- · Receive data is latched at the rising edge.

Figure 21 Clocked Synchronous Mode Format

When data transmit is selected to the clock output, the MPU produces transmit data and synchronous clock at TDRE flag clear.

Data receive is enabled by setting RE bit. Port 2, bit 3 will be a serial input. The operating mode of data receive is decided by the TRCSR and the RMCR.

If the external clock input is selected, RE bit should be set when P22 is "High". Then 8 external clock pulses and the synchronized receive data are input to port 2, bit 2 and bit 3 respectively. The MPU put receive data into the receive data shift register by this clock and set the RDRF flag at the termination of 8 bit data receive. More than 9th clock pulse of external input are ignored. When RDRF is cleared by reading the receive data register, the MPU starts

receiving the next data. So RDRF should be cleared with P_{22} "High"

When data receive is selected to the clock output, 8 synchronous clocks are output to the external by setting RE bit. So receive data should be input from external, synchronously with this clock. When the first byte data is received, the RDRF flag is set. After the second byte, receive operation is performed and output the synchronous clock to the external by clearing the RDRF bit.

Transmit/Receive Control Status Register (TRCSR) (\$0011)
 The TRCSR is composed of 8 bits which are all readable. Bits 0 to 4 are also writable. This register is initialized to \$20 during reset. Each bit functions as follows.

Transmit/Receive Control Status Register

7	6	5	4	3	2	1	0	
RDRF	ORFE	TDRE	RIE	RE	TIE	TE	wu	\$0011

Bit 0 WU Wake-up

In a typical multi-processor configuration, the software protocol provides the destination address at the first byte of the message. In order to make uninterested MPU ignore the remaining message, a wake-up function is available. By this, uninterested MPU can inhibit all further receive processing till the next message starts.

Then wake-up function is triggered by consecutive 1's with 1 frame length (10 bits for 8-bit data, 11 for 9-bit). The software protocol should provide the idle time between messages.

By setting this bit, the MPU stops data receive till the next message. The receive of consecutive "1" with one frame length wakes up and clears this bit and then the MPU restarts receive operation. However, the RE flag should be already set before setting this bit. In the clocked synchronous mode WU is not available, so this bit should not be set.

Bit 1 TE Transmit Enable

When this bit is set, transmit data will appear at port 2, bit 4 after one frame preamble in asynchronous mode, while in clocked synchronous mode it appears immediately. This is executed regardless of the value of the corresponding DDR. When TE is cleared, the serial I/O doesn't affect port 2, bit 4.

Bit 2 TIE Transmit Interrupt Enable

When this bit is set, an internal interrupt (IRQ3) is enabled when TDRE (bit 5) is set. When cleared, the interrupt is inhibited.

Bit 3 RE Receive Enable

When set, a signal is input to the receiver from port 2, bit 3 regardless of the value of the DDR. When RE is cleared, the serial I/O doesn't affect port 2, bit 3.

Bit 4 RIE Receive Interrupt Enable

When this bit is set, an internal interrupt, IRQ3 is enabled when RDRF (bit 7) or ORFE (bit 6) is set. When cleared, the interrupt is inhibited.

Bit 5 TDRE Transmit Data Register Empty

TDRE is set when the TDR is transferred to the transmit data shift register in the asynchronous mode, while in clocked synchronous mode when the TDSR is "empty". This bit is reset by reading the TRCSR and writing new transmit data to the transmit data register. TDRE is set to "1" during reset.

(Note) TDRE should be cleared in the transmittable state after the TE set.

Bit 6 ORFE Overrun Framing Error

ORFE is set by hardware when an overrun or a framing error is generated (during data receive only). An overrun error occurs when new receive data is ready to be transferred to the RDR during RDRF still being set. A framing error occurs when a stop bit is "0". But in clocked synchronous mode, this bit is not affected. This bit is cleared when reading the TRCSR, then the RDR, or during reset.

Bit 7 RDRF Receive Data Register Full

RDRF is set by hardware when the RDSR is transferred to the RDR. Cleared when reading the TRCSR, then the RDR, or during reset.

(Note) When a few bits are set between bit 5 to bit 7 in the TRCSR, a read of the TRCSR is sufficient for clearing those bits. It is not necessary to read the TRCSR everytime to clear each bit.

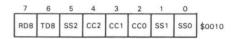
• Transmit Rate/Mode Control Register (RMCR)

The RMCR controls the following serial I/O:

- · Baud Rate · Data Format
- · Clock Source · Port 2, Bit 2 Function

In addition, if 9-bit data format is set in the asynchronous mode, the 9th bit is put in this register. All bits are readable and writable except bit 7 (read only). This register is set to \$00 during reset.

Transfer Rate/Mode Control Register



Bit 0 SS0 Bit 1 SS1 Speed Select Bit 5 SS2

These bits control the baud rate used for the SCI. Table 6 lists the available baud rates. The timer 1 FRC (SS2=0) and the timer 2 up counter (SS2=1) provide the internal clock to the SCI. When selecting the timer 2 as a baud rate source, it functions as a baud rate generator. The timer 2 generates the baud rate listed in Table 7 depending on the value of the TCONR.

(Note) When operating the SCI with internal clock, do not perform write operation to the timer/counter which is the clock source of the SCI.

These bits control the data format and the clock source (refer to Table 8).

* CCO, CC1 and CC2 are cleared during reset and the MPU goes to the clocked synchronous mode of the external clock operation. Then the MPU sets port 2, bit 2 into the clock input state. When using port 2, bit 2 as an output port, the DDR of port 2 should be set to "1" and CC1 and CC0 to "0" and "1" respectively.

Table 6 SCI Bit Times and Transfer Rates

(1) Asynchronous Mode

			XTAL	2.4576MHz	4.0MHz	4.9152MHz
SS2	SS1	SS0	E	614.4kHz	1.0MHz	1.2288MHz
0	0	0	E÷16	26 µs/38400Baud	16µs/62500Baud	13 μs/76800Baud
0	0	1	E÷128	208 µs/4800Baud	128µs/7812.5Baud	104.2 μs/9600Baud
0	1	0	E÷1024	1.67ms/600Baud	1.024ms/976.6Baud	833.3 µs/1200 Baud
0	1	1	E÷4096	6.67ms/150Baud	4.096ms/244.1Baud	3.333ms/300Baud
1	_	-	_	*	*	*

^{*} When SS2 is "1", Timer 2 provides SCI clocks. The baud rate is shown as follows with the TCONR as N.

Baud Rate =
$$\frac{f}{32 \text{ (N+1)}}$$
 $\left(\begin{array}{c} f: \text{ input clock frequency to the} \\ \text{timer 2 counter} \\ \text{N} = 0 \sim 255 \end{array}\right)$

(2) Clocked Synchronous Mode *

			XTAL	4.0MHz	6.0MHz	8.0MHz
SS2	SS1	SS0	E	1.0MHz	1.5MHz	2.0MHz
0	0	0	E÷2	2µs/bit	1.33µs/bit	1μs/bit
0	0	1	E÷16	16µs/bit	10.7µs/bit	8µs/bit
0	1	0	E÷128	128µs/bit	85.3µs/bit	64µs/bit
0	1	1	E÷512	512µs/bit	341 µs/bit	$256\mu s/bit$
1	_	-	-	* *	**	* *

^{*} Bit rates in the case of internal clock operation. In the case of external clock operation, the external clock is operatable up to DC $\sim 1/2$ system clock.

Bit Rate (
$$\mu$$
s/bit) = $\frac{4 (N+1)}{f}$ $\begin{pmatrix} f: \text{ input clock frequency to the } \\ \text{timer 2 counter} \\ N = 0 \sim 255 \end{pmatrix}$

Table 7 Baud Rate and Time Constant Register Example

Baud Rate (Baud)	2.4576MHz	3.6864MHz	4.0MHz	4.9152MHz	8.0MHz
110	21°	32*	35*	43*	70°
150	127	191	207	255	51°
300	63	95	103	127	207
600	31	47	51	63	103
1200	15	23	25	31	51
2400	7	11	12	15	25
4800	3	5	_	7	12
9600	1	2	-	3	
19200	0	-	-	1	_
38400	_		_	0	_

^{*} E/8 clock is input to the timer 2 up counter and E clock otherwise.

^{**} The bit rate is shown as follows with the TCONR as N.

Table 8 SCI Format and Clock Source Control

CC2	CC1	CCO	Format	Mode	Clock Source	Port 2, Bit 2	Port 2, Bit 3	Port 2, Bit 4
0	0	0	8-bit data	Clocked Synchronous	External	Input	h	
0	0	1	8-bit data	Asynchronous	Internal	Not Used**		DE 1 :: : !/4//
0	1	0	8-bit data	Asynchronous	Internal	Output*	When the TRCSR, RE bit is "1", bit 3 is used as a serial input.	
0	1	1	8-bit data	Asynchronous	External	Input		
1	0	0	8-bit data	Clocked Synchronous	Internal	Output		
1	0	1	9-bit data	Asynchronous	Internal	Not Used**		TE
1	1	0	9-bit data	Asynchronous	Internal	Output*	When the TRCSR, TE bit is "1", bit 4 is used as a serial output.	
1	1	1	9-bit data	Asynchronous	External	Input	Dit 4 is used as a s	eriai output.

^{*} Clock output regardless of the TRCSR, bit RE and TE.

Bit 6 TD8 Transmit Data Bit 8

When selecting 9-bit data format in the asynchronous mode, this bit is transmitted as the 9th data. In transmitting 9-bit data, write the 9th data into this bit then write data to the receive data register.

Bit 7 RD8 Receive Data Bit 8

When selecting 9-bit data format in the asynchronous mode, this bit stores the 9th bit data. In receiving 9-bit data, read this bit then the receive data register.

■ TIMER, SCI STATUS FLAG

Table 9 shows the set and reset conditions of each status

flag in the timer 1, timer 2 and SCI.

As for Timer 1 and Timer 2 status flag, if the set and reset condition occur simultaneously, the set condition is prior to the reset condition. But in case of SCI control status flag, the reset condition has priority. Especially as for OCF1 and OCF2 of Timer 1, the set signal is generated periodically whenever FRC matches OCR after the set, and which can cause the unclear of the flag. To clear surely, the method is necessary to avoid the occurence of the set signal between TCSR Read and OCR write. For example, match the OCR value to FRC first, and next read TCSR, and then write OCR at once.

Table 9 Timer 1, Timer 2 and SCI Status Flag

		Set Condition	Reset Condition		
	ICF	FRC \rightarrow ICR by edge input to P ₂₀ .	Read the TCSR1 or TCSR2 then ICRH, when ICF=1		
			2. RES=0		
	OCF1	OCR1=FRC	Read the TCSR1 or TCSR2 then write to the OCR1H or OCR1L, when OCF1=1 RES=0		
Timer 1	OCF2	OCR2=FRC	1. Read the TCSR2 then write to the OCR2H or OCR2L, when OCF2=1 2. RES=0		
	TOF	FRC=\$FFFF+1 cycle	Read the TCSR1 then FRCH, when TOF=1 RES=0		
Timer 2	CMF	T2CNT=TCONR	1. Write "0" to CMF, when CMF=1 2. RES=0		
	RDRF	Receive Shift Register → RDR	 Read the TRCSR then RDR, when RDRF=1 RES=0 		
SCI	ORFE	 Framing Error (Asynchronous Mode) Stop Bit = 0 Overrun Error (Asynchronous Mode) Receive Shift Register → RDR when RDRF=1 	1. Read the TRCSR then RDR, when ORFE=1 2. RES=0		
	TDRE	 Asynchronous Mode TDR → Transmit Shift Register Clocked Synchronous Mode Transmit Shift Register is "empty" RES=0 	Read the TRCSR then write to the TDR, when TDRE=1 (Note) TDRE should be reset after the TE set.		

(Note) 1. →: transfer

^{2.} For example; "ICRH" means High byte of ICR.



^{**} Not used for the SCI.

LOW POWER DISSIPATION MODE

The HD6303X provides two low power dissipation modes; sleep and standby.

Sleep Mode

The MPU goes to the sleep mode by SLP instruction execution. In the sleep mode, the CPU stops its operation, while the registers' contents are retained. In this mode, the peripherals except the CPU such as timers, SCI etc. continue their functions. The power dissipation of sleep-condition is one fifth that of operating condition.

The MPU returns from this mode by an interrupt, RES or STBY; it goes to the reset state by RES and the standby mode by STBY. When the CPU acknowledges an interrupt request, it cancels the sleep mode, returns to the operation mode and branches to the interrupt routine. When the CPU masks this interrupt, it cancels the sleep mode and executes the next instruction. However, for example if the timer 1 or 2 prohibits a timer interrupt, the CPU doesn't cancel the sleep mode because of no interrupt request.

This sleep mode is effective to reduce the power dissipation

for a system with no need of the HD6303X's consecutive operation.

Standby Mode

The HD6303X stops all the clocks and goes to the reset state with \overline{STBY} "Low". In this mode, the power dissipation is reduced conspicuously. All pins except for the power supply, the \overline{STBY} and XTAL are detached from the MPU internally and go to the high impedance state.

In this mode the power is supplied to the HD6303X, so the contents of RAM is retained. The MPU returns from this mode during reset. The followings are typical usage of this mode.

Save the CPU information and SP contents on RAM by \overline{NMI}. Then disable the RAME bit of the RAM control register and set the STBY PWR bit to go to the standby mode. If the STBY PWR bit is still set at reset start, that indicates the power is supplied to the MPU and RAM contents are retained properly. So system can restore itself by returning their pre-standby informations to the SP and the CPU. Fig. 22 depicts the timing at each pin with this example.

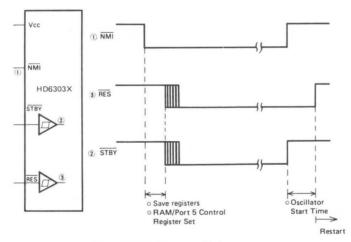


Figure 22 Standby Mode Timing

■ TRAP FUNCTION

The CPU generates an interrupt with the highest priority (TRAP) when fetching an undefined instruction or an instruction from non-memory space. The TRAP prevents the systemburst caused by noise or a program error.

Op Code Error

When fetching an undefined op code, the CPU saves CPU registers as well as a normal interrupt and branches to the TRAP (SFFEE, SFFEF). This has the priority next to reset.

Address Error

When an instruction fetch is made from internal register (\$0000~\$001F), the MPU generates an interrupt as well as an op code error. But on the system with no memory in its external memory area, this function is not applicable if an instruction fetch is made from the external non-memory area.

This function is available only for an instruction fetch and is not applicable to the access of normal data read/write.

(Note) The TRAP interrupt provides a retry function differently from other interrupts. This is a program flow return to the address where the TRAP occurs when a sequence returns to a main routine from the TRAP interrupt routine by RTI. The retry can prevent the system burst caused by noise etc.

However, if another TRAP occurs, the program repeats the TRAP interrupt forever, so the consideration is necessary in programming.

INSTRUCTION SET

The HD6303X provides object code upward compatible with the HD6801 to utilize all instruction set of the HMCS6800. It also reduces the execution times of key instruc-

tions for throughput improvement.

Bit manipulation instruction, change instruction of the index register and accumulator and sleep instruction are also added.

The followings are explained here.

- · CPU Programming Model (refer to Fig. 23)
- · Addressing Mode
- Accumulator and Memory Manipulation Instruction (refer to Table 10)
- New Instruction
- Index Register and Stack Manipulation Instruction (refer to Table 11)
- · Jump and Branch Instruction (refer to Table 12)
- Condition Code Register Manipulation (refer to Table 13)
- · Op Code Map (refer to Table 14)

Programming Model

Fig. 23 depicts the HD6303X programming model. The double accumulator D consists of accumulator A and B, so when using the accumulator D, the contents of A and B are destroyed.

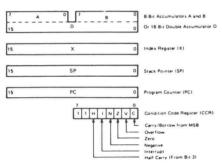


Figure 23 CPU Programming Model

CPU Addressing Mode

The HD6303X provides 7 addressing modes. The addressing mode is decided by an instruction type and code. Table 10 through 14 show addressing modes of each instruction with the execution times counted by the machine cycle.

When the clock frequency is 4 MHz, the machine cycle time becomes microseconds directly.

Accumulator (ACCX) Addressing

Only an accumulator is addressed and the accumulator A or B is selected. This is a one-byte instruction.

Immediate Addressing

This addressing locates a data in the second byte of an instruction. However, LDS and LDX locate a data in the second and third byte exceptionally. This addressing is a 2 or 3-byte instruction.

Direct Addressing

In this addressing mode, the second byte of an instruction shows the address where a data is stored. 256 bytes (\$0 through \$255) can be addressed directly. Execution times can be reduced by storing data in this area so it is recommended to make it RAM for users' data area in configurating a system. This is a 2-byte instruction, while 3-byte with regard to AIM, OIM, EIM and TIM.

Extended Addressing

In this mode, the second byte shows the upper 8 bit of the data stored address and the third byte the lower 8 bit. This indicates the absolute address of 3-byte instruction in the memory.

Indexed Addressing

The second byte of an instruction and the lower 8 bit of the index register are added in this mode. As for AIM, OIM, EIM and TIM, the third byte of an instruction and the lower 8 bits of the index register are added.

This carry is added to the upper 8 bit of the index register and the result is used for addressing the memory. The modified address is retained in the temporary address register, so the contents of the index register doesn't change. This is a 2-byte instruction except AIM, OIM, EIM and TIM (3-byte instruction).

Implied Addressing

An instruction itself specifies the address. That is, the instruction addresses a stack pointer, index register etc. This is a one-byte instruction.

Relative Addressing

The second byte of an instruction and the lower 8 bits of the program counter are added. The carry or borrow is added to the upper 8 bit. So addressing from -126 to +129 byte of the current instruction is enabled. This is a 2-byte instruction. (Note) CLI, SEI Instructions and Interrupt Operation

When accepting the IRQ at a preset timing with CLI and SEI instructions, more than 2 cycles are necessary between the CLI and SEI instructions. For example, the following program (a) (b) don't accept the IRQ but (c) accepts it.

	CLI
CLI	NOP
NOP	NOP
SEI	SEI
19	
(1.0)	
(b)	(c)
	CLI NOP SEI

The same thing can be said to the TAP instruction instead of the CLI and SEI instructions.

Table 10 Accumulator, Memory Manipulation Instructions

							Add	dress	ing	Mod	des							0			on i		le
Operations	Mnemonic	IMI	ME	D	DIF	REC	T	IN	DE	X	EX	TEN	ND	IME	PLIE	D	Boolean/ Arithmetic Operation	5	4	3	2	1	To
		ОР	~	#	ОР	~	#	ОР	~	#	ОР	~	#	ОР	~	#	Antimetic Operation	н	1	N	z	v	0
Add	ADDA	88	2	2	9B	3	2	AB	4	2	ВВ	4	3				A + M→ A	1		1	‡	‡	1
	ADDB	СВ	2	2	DB	3	2	EB	4	2	FB	4	3				B + M → B	1		\$	1	\$	1
Add Double	ADDD	СЗ	3	3	D3	4	2	E3	5	2	F3	5	3				A:B+M:M+1→A:B			\$	1	1	1
Add Accumulators	ABA	-	-				+						-	1B	1	1	A + B → A	1		1	1	1	1
Add With Carry	ADCA	89	2	2	99	3	2	A9	4	2	В9	4	3				A + M + C → A	1		:	1	1	1
	ADCB	C9	2	2	D9	3	2	E9	4	2	F9	4	3				B + M + C → B	1		‡	1	:	1
AND	ANDA	84	2	2	94	3	2	A4	4	2	В4	4	3				A·M → A			1	1	R	
	ANDB	C4	2	2	D4	3	2	E4	4	2	F4	4	3				B·M → B			1	1	R	
Bit Test	BITA	85	2	2	95	3	2	A5	4	2	85	4	3				A·M			1	1	R	
	BIT B	C5	2	2	D5	3	2	E5	4	2	F5	4	3				B·M			1	1	R	
Clear	CLR							6F	5	2	7F	5	3				00 → M			R	S	R	F
	CLRA						1							4F	1	1	00 → A			R	S	R	F
	CLRB													5F	1	1	00 → B			R	S	R	F
Compare	CMPA	81	2	2	91	3	2	A1	4	2	В1	4	3				A - M			1	1	:	1
	СМРВ	C1	2	2	D1	3	2	E1	4	2	F1	4	3				B - M			1	1	1	1
Compare Accumulators	СВА													11	1	1	A - B	•		1	;	1	1
Complement, 1's	сом							63	6	2	73	6	3				M → M			‡	1	R	5
	COMA	_			1								-	43	1	1	$\overline{A} \rightarrow A$			1	1	R	5
	СОМВ													53	1	1	$\overline{B} \to B$			1	1	R	S
Complement, 2's	NEG	1	+				+	60	6	2	70	6	3				00 - M → M			1	1	0	0
(Negate)	NEGA													40	1	1	00 - A → A			1	:	0	C
	NEGB									\vdash				50	1	1	00 - B → B			1	:	0	C
Decimal Adjust, A	DAA													19	2	1	Converts binary add of BCD characters into BCD format	•		:	:	1	a
Decrement	DEC							6A	6	2	7A	6	3				M - 1 → M			1	1	0	
	DECA													4A	1	1	A - 1 → A			1	:	0	•
	DECB													5A	1	1	B - 1 → B			1	1	0	
Exclusive OR	EORA	88	2	2	98	3	2	A8	4	2	В8	4	3				$A \oplus M \rightarrow A$			1	1	R	0
	EORB	C8	2	2	D8	3	2	E8	4	2	F8	4	3				B ⊕ M→ B		•	1	1	R	
Increment	INC							6C	6	2	7C	6	3				M + 1 → M			:	1	3	•
	INCA													4C	1	1	A + 1 → A			1	1	3	
	INCB													5C	1	1	B + 1 → B			1	:	5	
Load	LDAA	86	2	2	96	3	2	A6	4	2	В6	4	3				M → A			1	1	R	
Accumulator	LDAB	C6	2	2	D6	3	2	E6	4	2	F6	4	3				M → B			1	:	R	
Load Double Accumulator	LDD	СС	3	3	DC	4	2	EC	5	2	FC	5	3				M + 1 → B, M → A	•		:	:	R	
Multiply Unsigned	MUL													3D	7	1	A x B → A : B				•	•	0
OR, Inclusive	ORAA	8A	2	2	9A	3	2	AA	4	2	ВА	4	3				A + M → A			1	1	R	
	ORAB	CA	2	2	DA	3	2	EA	4	2	FA	4	3				B + M → B			1	1	R	
Push Data	PSHA													36	4	1	A → Msp, SP - 1 → SP		•		•	•	1
	PSHB													37	4	1	B → Msp, SP - 1 → SP		•			•	1
Pull Data	PULA													32	3	1	SP + 1 → SP, Msp → A						1
	PULB													33	3	1	SP + 1 → SP, Msp → B						
Rotate Left	ROL							69	6	2	79	6	3				м			1	1	0	1
	ROLA													49	1	1	M) 4041111114			1	1	6	t
	ROLB			1			1					-		59	1	1	B C b7 b0			1	1	0	_
Rotate Right	ROR		1					66	6	2	76	6	3		-		м,			1	1	0	1
	RORA						T							46	1	1	A C b7 b0		•	1	1	6	1
	RORB	1	1	1	1	-	1	1	1	1	1	1	-	56	1	1	B C b7 b0			:	1	(6)	_

(Note) Condition Code Register will be explained in Note of Table 13.



Table 10 Accumulator, Memory Manipulation Instructions

							Add	Iressi	ng A	Mod	es							С			on (Code	è
Operations	Mnemonic	IMI	ME	٥.	DIF	REC	Т	IN	DE)	K	EXT	TEN	D	IMI	PLIE	D	Boolean/ Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		н	1	N	z	v	С
Shift Left	ASL						Г	68	6	2	78	6	3				M)	•	•	:	\$	6	:
Arithmetic	ASLA													48	1	1	A 0+11111+0	•	•	\$	\$.	6	\$
	ASLB													58	1	1	B C b7 b0	•		\$	\$	6	\$
Double Shift Left, Arithmetic	ASLD													05	1	1	ACC A/ ACC B -0 C A7 A0 B7 B0	•	•	1	1	6	‡
Shift Right	ASR							67	6	2	77	6	3				M)	•		\$	\$	6	:
Arithmetic	ASRA													47	1	1	v			:	:	6	:
	ASRB											9		57	1	1	B) 67 60 C			1	1	6	:
Shift Right	LSR							64	6	2	74	6	3			Г	M)			R	1	6	:
Logical	LSRA												Г	44	1	1	A 0+		•	R	:	6	:
	LSRB													54	1	1	B 67 60 C			R	1	6	:
Double Shift Right Logical	LSRD													04	1	1	0-ACC A/ ACC B - A7 A0 B7 B0 C	•		R	:	6	:
Store	STAA				97	3	2	A7	4	2	B7	4	3				A → M			1	1	R	•
Accumulator	STAB				D7	3	2	E7	4	2	F7	4	3				B → M		•	1	:	R	•
Store Double Accumulator	STD				DD	4	2	ED	5	2	FD	5	3				A → M B → M + 1	•	•	1	1	R	
Subtract	SUBA	80	2	2	90	3	2	A0	4	2	ВО	4	3				A - M → A	•	•	‡	1	1	1
	SUBB	CO	2	2	D0	3	2	EO	4	2	FO	4	3				B - M → B		•	\$	1	:	1
Double Subtract	SUBD	83	3	3	93	4	2	A3	5	2	В3	5	3				A : B - M : M + 1 → A : B	•	•	1	1	1	1
Subtract Accumulators	SBA													10	1	1	A - B → A	•	•	1	:	:	\$
Subtract	SBCA	82	2	2	92	3	2	A2	4	2	B2	4	3				A - M - C → A	•		\$	\$:	:
With Carry	SBCB	C2	2	2	D2	3	2	E2	4	2	F2	4	3				B - M - C → B	•	•	:	\$	1	‡
Transfer	TAB			L								L		16	1	1	A → B	•	•	1	‡	R	
Accumulators	TBA	1	1	_	_	_			_	_		_	L	17	1	1	B → A		•	\$	1	R	
Test Zero or	TST	_	1	_	_	_		6D	4	2	7D	4	3	_	1	1	M - 00		•	1	1	R	R
Minus	TSTA		1	_	_					_		┖	L	4D	1	1	A - 00		•	1	1	R	R
	TSTB	1	_		_								L	5D	1	1	B - 00	•		:	1	R	R
And Immediate	AIM	_	1	L	71	6	3	61	7	3							M·IMM→M			1	1	R	
OR Immediate	OIM				72	6	3	62	7	3							M+IMM→M	•	•	1	1	R	
EOR Immediate	EIM				75	6	3	65	7	3							M⊕IMM→M			1	1	R	
Test Immediate	TIM				7B	4	3	6B	5	3		Г	Г			Г	M-IMM			1	1	R	

(Note) Condition Code Register will be explained in Note of Table 13.

Additional Instruction

In addition to the HD6801 instruction set, the HD6303X prepares the following new instructions.

$$AIM \dots (M) \cdot (IMM) \rightarrow (M)$$

Executes "AND" operation to immediate data and the memory contents and stores its result in the memory.

$$OIM \dots (M) + (IMM) \rightarrow (M)$$

Executes "OR" operation to immediate data and the memory contents and stores its result in the memory.

$$EIM \dots (M) \oplus (IMM) \rightarrow (M)$$

Executes "EOR" operation to immediate data and the memory contents and stores its result in the memory.

$$TIM \dots (M) \cdot (IMM)$$

Executes "AND" operation to immediate data and changes the relative flag of the condition code register.

These area 3-byte instructions; the first byte is op code, the second immediate data and the third address modifier.

$$XGDX \dots (ACCD) \leftrightarrow (IX)$$

Exchanges the contents of accumulator and the index register.

SLP

Goes to the sleep mode. Refer to "LOW POWER DIS-SIPATION MODE" for more details of the sleep mode.

Table 11 Index Register, Stack Manipulation Instructions

							Ad	dress	ing	Mo	des						Boolean/	C		dition Reg			0
Pointer Operations	Mnemonic	IM	MEI	D.	DII	REC	T	IN	DE	X	EX.	TEN	ID	IMP	LIE	D	Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		Н	1	N	Z	٧	С
Compare Index Reg	CPX	8C	3	3	9C	4	2	AC	5	2	ВС	5	3				X - M:M + 1			:	:	:	:
Decrement Index Reg	DEX													09	1	1	X – 1 → X				1	0	
Decrement Stack Pntr	DES													34	1	1	SP - 1 → SP		0				
Increment Index Reg	INX													08	1	1	X + 1 → X	•			1		
Increment Stack Pntr	INS													31	1	1	SP + 1 → SP		•			•	•
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	5	2	FE	5	3				M → XH, (M+1) → XL.			0	1	R	•
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	5	2	BE	5	3				M → SPH, (M+1) → SPL	•	•	0	‡	R	•
Store Index Reg	STX				DF	4	2	EF	5	2	FF	5	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$	•	•	0	‡	R	
Store Stack Pntr	STS				9F	4	2	AF	5	2	BF	5	3				SPH - M, SPL - (M+1)	•	•	0	‡	R	
Index Reg → Stack Pntr	TXS													35	1	1	X - 1 → SP		•				
Stack Pntr → Index Reg	TSX													30	1	1	SP + 1 → X	•					
Add	ABX													3A	1	1	B + X → X		•	•			
Push Data	PSHX													3C	5	1	$X_L \rightarrow M_{sp}$, $SP - 1 \rightarrow SP$ $X_H \rightarrow M_{sp}$, $SP - 1 \rightarrow SP$	•	•	•	•	•	•
Pull Data	PULX													38	4	1	$SP + 1 \rightarrow SP, M_{SP} \rightarrow X_{H}$ $SP + 1 \rightarrow SP, M_{SP} \rightarrow X_{L}$	•	•	•	•	•	•
Exchange	XGDX													18	2	1	ACCDIX						

(Note) Condition Code Register will be explained in Note of Table 13.

Table 12 Jump, Branch Instructions

							Ad	dress	ing	Мо	des							(Con	diti			e
Operations	Mnemonic	REL	ATI	VE	DIE	REC	т	IN	DE	×	EXT	EN	D	IMP	LIE	D	Branch Test	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		н	1	N	z	٧	С
Branch Always	BRA	20	3	2													None	•	•	•	•	•	•
Branch Never	BRN	21	3	2													None				•	•	•
Branch If Carry Clear	BCC	24	3	2													C = 0			•		•	
Branch If Carry Set	BCS	25	3	2													C = 1	•	•	•	•	•	•
Branch If = Zero	BEQ	27	3	2													Z = 1			•	•		•
Branch If > Zero	BGE	2C	3	2													N + V = 0					•	•
Branch If > Zero	BGT	2E	3	2													Z + (N + V) = 0						•
Branch If Higher	ВНІ	22	3	2													C + Z = 0						•
Branch If ≤ Zero	BLE	2F	3	2													Z + (N + V) = 1						
Branch If Lower Or Same	BLS	23	3	2													C + Z = 1	•	•	•	•	•	•
Branch If < Zero	BLT	2D	3	2													N + V = 1						
Branch If Minus	BMI	28	3	2													N = 1		•	•	•	•	•
Branch If Not Equal Zero	BNE	26	3	2		1											Z = 0	•		•	•	•	•
Branch If Overflow Clear	BVC	28	3	2													V = 0	•	•	•	•	•	•
Branch If Overflow Set	BVS	29	3	2													V = 1						
Branch If Plus	BPL	2A	3	2													N = 0						•
Branch To Subroutine	BSR	8D	5	2									Г										
Jump	JMP							6E	3	2	7E	3	3								•		
Jump To Subroutine	JSR				9D	5	2	AD	5	2	BD	6	3										
No Operation	NOP													01	1	1	Advances Prog. Cntr. Only	•	•	•		•	•
Return From Interrupt	RTI									П				3B	10	1		-		- (3	_	_
Return From Subroutine	RTS													39	5	1		•	•	•	•	•	•
Software Interrupt	SWI													3F	12	1]	•	S	•	•	•	
Wait for Interrupt*	WAI													3E	9	1		•	9	•	•	•	•
Sleep	SLP													1A	4	1							

(Note) *WAI puts R/ \overline{W} high; Address Bus goes to FFFF; Data Bus goes to the three state. Condition Code Register will be explained in Note of Table 13.

Table 13 Condition Code Register Manipulation Instructions

		Addre	ssing	Modes		C	ondit	ion C	ode F	Regist	ter
Operations	Mnemonic	IM	PLIE	D	Boolean Operation	5	4	3	2	1	0
		OP	~	#		н	1	N	Z	V	С
Clear Carry	CLC	oc	1	1	0 → C	•	•	•	•	•	R
Clear Interrupt Mask	CLI	0E	1	1	0 → 1	•	R	•	•		
Clear Overflow	CLV	OA	1	1	0 → V	•	•	•	•	R	
Set Carry	SEC	0D	1	1	1 → C	•		•	•	•	S
Set Interrupt Mask	SEI	OF	1	1	1 → 1	•	S				
Set Overflow	SEV	ОВ	1	1	1 → V	•	•	•	•	S	
Accumulator A → CCR	TAP	06	1	1	A→ CCR	_		- 0	0 -		_
CCR → Accumulator A	TPA	07	1	1	CCR → A						

LEGEND

- OP Operation Code (Hexadecimal)
- Number of MCU Cycles

MSP Contents of memory location pointed to by Stack Pointer

- Number of Program Bytes
- Arithmetic Plus
- Arithmetic Minus
- Boolean AND
- Boolean Inclusive OR
- Boolean Exclusive OR
- Complement of M
- Transfer into Bit = Zero
- 00 Byte = Zero

CONDITION CODE SYMBOLS

- H Half-carry from bit 3 to bit 4
- Interrupt mask
- Negative (sign bit) N
- Zero (byte) 7
- Overflow, 2's complement C
- Carry/Borrow from/to bit 7
- R Reset Always
- Set Always
- Set if true after test or clear
 - Not Affected

(Note) Condition Code Register Notes: (Bit set if test is true and cleared otherwise)

- ① (Bit V) Test: Result = 10000000?
- (2) (Bit C) Test: Result \ 00000000?
- (3) (Bit C) Test: BCD Character of high-order byte greater than 10? (Not cleared if previously set)
- (Bit V) Test: Operand = 10000000 prior to execution?
- 5 (Bit V) Test: Operand = 01111111 prior to execution?
- 6 (Bit V) Test: Set equal to N⊕ C = 1 after the execution of instructions
- 7 (Bit N) Test: Result less than zero? (Bit 15=1)
- (8) (All Bit) Load Condition Code Register from Stack.
- (9) (Bit 1) Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exit the wait state.
- (All Bit) Set according to the contents of Accumulator A.
- (II) (Bit C) Result of Multiplication Bit 7=1? (ACCB)

Table 14 OP-Code Map

OP						ACC	ACC	IND	EXT		ACCA	or SP			ACCE	3 or X		
COD	E					Α	В	IND	DIR	IMM	DIR	IND	EXT	IMM	DIR	IND	EXT	
H	H	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111	
LO	\	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F	
0000	0		SBA	BRA	TSX		N	EG					S	UB				0
0001	1	NOP	CBA	BRN	INS			A	IM				CI	МР				1
0010	2	/	/	ВНІ	PULA			0	IM				S	BC				2
0011	3			BLS	PULB		C	MC			SU	IBD			AD	DD		3
0100	4	LSRD	/	BCC	DES		L	SR					A	ND				4
0101	5	ASLD		BCS	TXS			E	IM				В	IT				5
0110	6	TAP	TAB	BNE	PSHA		R	OR					LI	DA				6
0111	7	TPA	TBA	BEQ	PSHB		Α	SR				STA				STA		7
1000	8	INX	XGDX	BVC	PULX		Α	SL					E	OR				8
1001	9	DEX	DAA	BVS	RTS		R	OL					Α	DC.				9
1010	A	CLV	SLP	BPL	ABX		D	EC					0	RA				A
1011	В	SEV	ABA	BMI	RTI			Т	IM				А	DD				В
1100	С	CLC		BGE	PSHX		11	VC.			С	PX			L	DD		C
1101	D	SEC	/	BLT	MUL		Т	ST		BSR		JSR				STD		D
1110	E	CLI		BGT	WAI			J	MP		L	DS			LI	DX		E
1111	F	SEI		BLE	SWI		С	LR				STS				STX		F
		0	1	2	3	4	5	6	7	8	9	A	В	С	D	E	F	T

^{&#}x27;UNDEFINED OP CODE

^{*} Only each instructions of AIM, OIM, EIM, TIM

■ CPU OPERATION

CPU Instruction Flow

When operating, the CPU fetches an instruction from a memory and executes the required function. This sequence starts with RES cancel and repeats itself limitlessly if not affected by a special instruction or a control signal. SWI, RTI, WAI and SLP instructions change this operation, while \overline{NMI} , $\overline{IRQ_1}$, $\overline{IRQ_2}$, $\overline{IRQ_3}$, \overline{HALT} and \overline{STBY} control it. Fig. 24 gives the CPU mode transition and Fig. 25 the CPU system flow chart. Table 15 shows CPU operating states and port states.

Operation at Each Instruction Cycle

Table 16 shows the operation at each instruction cycle. By the pipeline control of the HD6303X, MULT, PUL, DAA and XGDX instructions etc. prefetch the next instruction. So attention is necessary to the counting of the instruction cycles because it is different from the usual one ----- op code fetch to the next instruction op code.

Table 15 CPU Operation State and Port State

Port	Reset	STBY***	HALT	Sleep
$A_0 \sim A_7$	Н	T	Т	Н
Port 2	Т	Т	Keep	Keep
$D_0 \sim D_7$	Т	Т	Т	Т
A ₈ ~ A ₁₅	Н	Т	Т	Н
Port 5	Т	Т	Т	Т
Port 6	Т	Т	Keep	Keep
Control Signal	*	Т	**	

H; High, L; Low, T; High Impedance
* RD, WR, R/W, LIR = H, BA = L

- ** RD, WR, R/W = T, LIR, BA = H
- *** E pin goes to high impedance state.

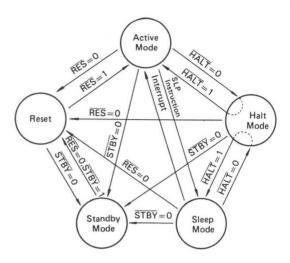


Figure 24 CPU Operation Mode Transition

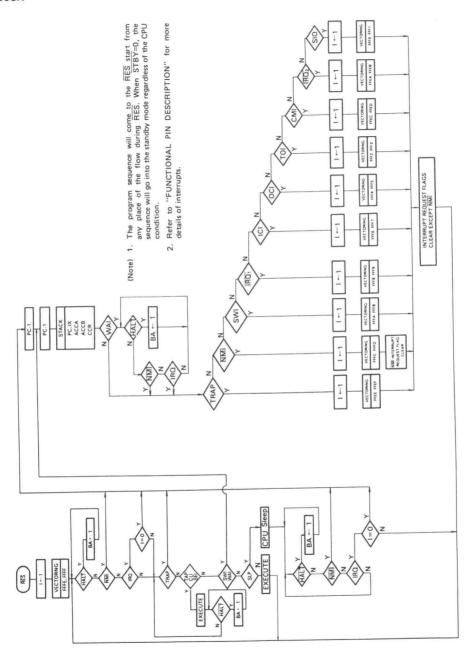


Figure 25 HD6303X System Flow Chart

Table 16 Cycle-by-Cycle Operation

	s Mode &	Cycles	Cycle	Address Bus	R/W	RD	WR	LIR	Data Bus
			*						L
MMEDIA									
ADC	ADD	T	1	Op Code Address+1	1	0	1	1	Operand Data
AND	BIT		2	Op Code Address + 2	1	0	1	0	Next Op Code
CMP	EOR	2		1000					0.50
LDA	ORA								
SBC	SUB								
ADDD	CPX		1	Op Code Address + 1	1	0	-1	1	Operand Data (MSB)
LDD	LDS	3	2	Op Code Address + 2	1	0	1	1	Operand Data (LSB)
LDX	SUBD		3	Op Code Address+3	1	0	1	0	Next Op Code
DIRECT									•
ADC	ADD		1	Op Code Address + 1	1 1	0	1	1	Address of Operand (LSE
AND	BIT		2	Address of Operand	1	0	1	1	Operand Data
CMP	EOR	3	3	Op Code Address + 2	1	0	1	0	Next Op Code
LDA	ORA			ACTOR CONTRACTOR ACTOR ACCORDED ACCORDED				-	
SBC	SUB								
STA			1	Op Code Address + 1	1 1	0	1	1	Destination Address
		3	2	Destination Address	0	1	0	1	Accumulator Data
			3	Op Code Address + 2	1	o	1	0	Next Op Code
ADDD	CPX		1	Op Code Address + 1	1	0	1	1	Address of Operand (LSE
LDD	LDS		2	Address of Operand	1	0	1	i	Operand Data (MSB)
LDX	SUBD	4	3	Address of Operand + 1	1 1	0	1	1	Operand Data (LSB)
			4	Op Code Address + 2	1	0	1	0	Next Op Code
STD	STS		1	Op Code Address + 1	1 1	0	1	1	Destination Address (LSE
STX		1 . 1	2	Destination Address	0	1	0	1	Register Data (MSB)
		4	3	Destination Address + 1	0	1	0	1	Register Data (LSB)
			4	Op Code Address + 2	1 1	0	1	0	Next Op Code
JSR			1	Op Code Address + 1	1 1	0	10	1	Jump Address (LSB)
		1 1	2	FFFF	1 1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer	0	1	0	1	Return Address (LSB)
			4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
			5	Jump Address	1	0	1	0	First Subroutine Op Code
TIM			1	Op Code Address + 1	1	0	1	1	Immediate Data
		4	2	Op Code Address + 2	1	0	1	1	Address of Operand (LSE
		4	3	Address of Operand	1	0	1	1	Operand Data
			4	Op Code Address + 3	1	0	1	0	Next Op Code
AIM	EIM		1	Op Code Address + 1	1	0	1	1	Immediate Data
OIM			2	Op Code Address + 2	1	0	1	1	Address of Operand (LSE
			3	Address of Operand	1 1	0	1	1	Operand Data
		6	4	FFFF	1	1	1	1	Restart Address (LSB)
			5	Address of Operand	0	1	o	1	New Operand Data
		1	6	Op Code Address + 3	1	0	1	ò	Next Op Code



Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
NDEXED								
JMP		1	Op Code Address + 1	1	0	1	1	Offset
	3	2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Jump Address	1	0	1	0	First Op Code of Jump Routin
ADC ADD	1	1	Op Code Address+1	1	0	1	1	Offset
AND BIT		2	FFFF	1	1	1	1	Restart Address (LSB)
CMP EOR	4	3	IX+Offset	1	0	1	1	Operand Data
LDA ORA	4	4	Op Code Address + 2	1	0	1	0	Next Op Code
SBC SUB								
TST								
STA		1	Op Code Address + 1	1	0	1	1	Offset
	4	2	FFFF	1	1	1	1	Restart Address (LSB)
	"	3	IX + Offset	0	1	0	1	Accumulator Data
		4	Op Code Address + 2	1	0	1	0	Next Op Code
ADDD		1	Op Code Address + 1	1	0	1	1	Offset
CPX LDD		2	FFFF	1	1	1	1	Restart Address (LSB)
LDS LDX	5	3	IX + Offset	1	0	1	1	Operand Data (MSB)
SUBD		4	IX + Offset + 1	1	0	1	1	Operand Data (LSB)
		5	Op Code Address+2	1	0	1	0	Next Op Code
STD STS		1	Op Code Address + 1	1	0	1	1	Offset
STX		2	FFFF	1	1	1	1	Restart Address (LSB)
	5	3	IX + Offset	0	1	0	1	Register Data (MSB)
		4	IX+Offset+1	0	1	0	1	Register Data (LSB)
JSR	-	5	Op Code Address + 2 Op Code Address + 1	1	0	1		Next Op Code Offset
JSR		2	FFFF	1 1	1	1	1	
	5	3	Stack Pointer	0	1	0	1	Restart Address (LSB) Return Address (LSB)
	"	4	Stack Pointer – 1	0	1	0	1	Return Address (MSB)
		5	IX+Offset	1	0	1	0	First Subroutine Op Code
ASL ASR	+	1	Op Code Address + 1	1	0	1	1	Offset
COM DEC		2	FFFF	1 1	1	1	1	Restart Address (LSB)
INC LSR		3	IX + Offset	1	0	1	1	Operand Data
NEG ROL	6	4	FFFF	1	1	1	1	Restart Address (LSB)
ROR		5	IX + Offset	0	1	0	1	New Operand Data
		6	Op Code Address + 2	1	0	1	0	Next Op Code
TIM		1	Op Code Address + 1	1	0	1	1	Immediate Data
		2	Op Code Address + 2	1	0	1	1	Offset
	5	3	FFFF	1	1	1	1	Restart Address (LSB)
		4	IX + Offset	1	0	1	1	Operand Data
		5	Op Code Address + 3	1	0	1	0	Next Op Code
CLR		1	Op Code Address+1	1	0	1	1	Offset
		2	FFFF	1	1	1	1	Restart Address (LSB)
	5	3	IX + Offset	1	0	1	1	Operand Data
		4	IX+Offset	0	1	0	1	00
		5	Op Code Address + 2	1	0	1	0	Next Op Code
AIM EIM		1	Op Code Address + 1	1	0	1	1	Immediate Data
OIM		2	Op Code Address + 2	1	0	1	1	Offset
		3	FFFF	1	1	1	1	Restart Address (LSB)
	7	4	IX + Offset	1	0	1	1	Operand Data
		5	FFFF	1	1	1	1	Restart Address (LSB)
		6	IX + Offset	0	1	0	1	New Operand Data
		7	Op Code Address + 3	1	0	1	0	Next Op Code



	ess Mode & tructions	Cycles	Cycle	Address Bus	R/W	RD	WR	LIR	Data Bus
XTEND)		,		-				-
JMP			1	Op Code Address + 1	1	0	1	1	Jump Address (MSB)
		3	2	Op Code Address + 2	1	0	1	1	Jump Address (LSB)
			3	Jump Address	1	0	1	0	Next Op Code
ADC	ADD TST		1	Op Code Address + 1	1	0	1	1	Address of Operand (MSI
AND	BIT	4	2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB
CMP	EOR	1	3	Address of Operand	1	0	1	1	Operand Data
LDA	ORA		4	Op Code Address + 3	1	0	1	0	Next Op Code
SBC	SUB								
STA			1	Op Code Address + 1	1	0	1	1	Destination Address (MSI
		4	2	Op Code Address + 2	1	0	1	- 1	Destination Address (LSB
		4	3	Destination Address	0	1	0	1	Accumulator Data
			4	Op Code Address + 3	1	0	1	0	Next Op Code
ADDD	1		1	Op Code Address + 1	1	0	1	1	Address of Operand (MS
CPX	LDD		2	Op Code Address + 2	1	0	1	1	Address of Operand (LSE
LDS	LDX	5	3	Address of Operand	1	0	1	1	Operand Data (MSB)
SUBD			4	Address of Operand + 1	1	0	1	1	Operand Data (LSB)
			5	Op Code Address + 3	1	0	1	0	Next Op Code
STD	STS		1	Op Code Address + 1	1	0	1	1	Destination Address (MS)
STX			2	Op Code Address + 2	1	0	1	1	Destination Address (LSB
		5	3	Destination Address	0	1	0	1	Register Data (MSB)
			4	Destination Address + 1	0	1	0	1	Register Data (LSB)
			5	Op Code Address + 3	1	0	1	0	Next Op Code
JSR			1	Op Code Address + 1	1	0	1	1	Jump Address (MSB)
.=.=			2	Op Code Address + 2	1	0	1	1	Jump Address (LSB)
			3	FFFF	1	1	1	1	Restart Address (LSB)
		6	4	Stack Pointer	0	1	o	1	Return Address (LSB)
			5	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
			6	Jump Address	1	o	1	0	First Subroutine Op Code
ASL	ASR	+	1	Op Code Address + 1	1	0	1	1	Address of Operand (MS
COM	DEC		2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB
INC	LSR		3	Address of Operand	1	0	1	1	Operand Data
NEG	ROL	6	4	FFFF	i	1	1	1	Restart Address (LSB)
ROR			5	Address of Operand	o	1	o	1	New Operand Data
HOH			6	Op Code Address + 3	1	ò	1	0	Next Op Code
CLR		+	1	Op Code Address + 1	1	0	1	1	Address of Operand (MS)
CLN			2	Op Code Address + 2	1	0	1	1	Address of Operand (MS)
		5	3			0	1	1	
		5		Address of Operand		//			Operand Data
			4	Address of Operand	0	1	0	1	00
			5	Op Code Address + 3	1	0	1	0	Next Op Code

	s Mode & uctions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
MPLIED									
ABA	ABX	T	1	Op Code Address + 1	1	0	1	0	Next Op Code
ASL	ASLD								
ASR	CBA								
CLC	CLI								
CLR	CLV								
COM	DEC	1 1							
DES	DEX								
INC	INS								
INX	LSR	1							
LSRD	ROL								
ROR	NOP								
SBA	SEC								
SEI	SEV								
TAB	TAP								
TBA	TPA								
TST	TSX								
TXS									,
DAA	XGDX	-	1	Op Code Address + 1	1	0	1	0	Next Op Code
מאמ	AGDA	2	2	FFFF	1	1	1	1	Restart Address (LSB)
PULA	PULB		1	Op Code Address+1	1	0	1	0	Next Op Code
FULA	FOLD	3	2	FFFF	1	1	1	1	Restart Address (LSB)
			3	Stack Pointer + 1	1	0	1	1	Data from Stack
PSHA	PSHB	-	1	Op Code Address + 1	1	0	1	1	Next Op Code
1 3116	1 3110		2	FFFF	1	1	1	1	Restart Address (LSB)
		4	3	Stack Pointer	0	1	0	1	Accumulator Data
		1 1	4	Op Code Address + 1	1	0	1	0	Next Op Code
PULX		-	1	Op Code Address + 1	1	0	1	0	Next Op Code
FULX			2	FFFF	1	1	1	1	Restart Address (LSB)
		4	3	Stack Pointer + 1	1	0	1	1	Data from Stack (MSB)
			4	Stack Pointer + 2	1	0	1	1	Data from Stack (LSB)
PSHX		-	1	Op Code Address + 1	1	0	1	1	Next Op Code
FSHX			2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer	o	1	0	1	Index Register (LSB)
		5	4	Stack Pointer – 1	0	1	0	1	Index Register (MSB)
		1 1	5		1	o	1	o	Next Op Code
DTO		-	1	Op Code Address + 1 Op Code Address + 1	1	0	1	1	Next Op Code
RTS			2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer + 1	1	0	1	1	Return Address (MSB)
		5	4	Stack Pointer + 2	1	0	1	1	Return Address (MSB)
			5	Return Address	1	0	1	o	First Op Code of Return Rout
MUL		-	1	Op Code Address + 1	1	0	1	0	Next Op Code of Neturn Hout
MUL			2	FFFF	1	1	1	1	Restart Address (LSB)
				FFFF	1	1	1	1	
		,	3	7.7 4.7	1	1	1	1	Restart Address (LSB)
		7	4	FFFF		1		1	Restart Address (LSB)
			5	FFFF	1	2.	1	100	Restart Address (LSB)
		1	6	FFFF	1	1	1	1	Restart Address (LSB)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
MPLIED								
WAI	T	1	Op Code Address + 1	1	0	1	1	Next Op Code
		2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Stack Pointer	0	1	0	1	Return Address (LSB)
		4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
	9	5	Stack Pointer - 2	0	1	0	1	Index Register (LSB)
	3	6	Stack Pointer = 3	0	1	0	1	Index Register (MSB)
		7	Stack Pointer - 4	0	1	0	1	Accumulator A
		8	Stack Pointer - 5	0	1	0	1	Accumulator B
		9	Stack Pointer - 5	0	1	0	1	Conditional Code Register
RTI	-	1	Op Code Address + 1	1	0	1	1	Next Op Code
HII		2	FFFF	1	1	1	1	
				1	0	1	1	Restart Address (LSB)
		3	Stack Pointer + 1		0	1	1	Conditional Code Register
		4	Stack Pointer + 2	1	0			Accumulator B
	10	5	Stack Pointer + 3	1	-	1	1	Accumulator A
		6	Stack Pointer +4	1	0	1	1	Index Register (MSB)
		7	Stack Pointer + 5	1	0	1	1	Index Register (LSB)
		8	Stack Pointer+6	1	0	1	1	Return Address (MSB)
		9	Stack Pointer + 7	1	0	1	1	Return Address (LSB)
		10	Return Address	1	0	1	0	First Op Code of Return Routin
SWI		1	Op Code Address + 1	1	0	1	1	Next Op Code
		2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Stack Pointer	0	1	0	1	Return Address (LSB)
		4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
		5	Stack Pointer - 2	0	1	0	1	Index Register (LSB)
		6	Stack Pointer - 3	0	1	0	1	Index Register (MSB)
	12	7	Stack Pointer -4	0	1	0	1	Accumulator A
		8	Stack Pointer - 5	0	1	0	1	Accumulator B
		9	Stack Pointer - 6	0	i	0	1	Conditional Code Register
		10	Vector Address FFFA	1	Ö	1	i	Address of SWI Routine (MSB)
		11	Vector Address FFFB	1	0	i	1	Address of SWI Routine (LSB)
		12	Address of SWI Routine	1	0	1	o	First Op Code of SWI Routine
01.0	-	1		1	0	1	1	Next Op Code
SLP			Op Code Address + 1					Account to the second s
		2	FFFF	1	1	1	1	Restart Address (LSB)
	4	Sleep						
		J						
						1	1	
		3	FFFF	1	1	1	1	Restart Address (LSB)
		4	Op Code Address + 1	1	0	1	0	Next Op Code
RELATIVE			On Code Address t		1 0			T D 0#
BCC BCS		1	Op Code Address + 1	1	0	1	1	Branch Offset
BEQ BGE	3	2	1111	1	1	1	1	Restart Address (LSB)
BGT BHI		3	Branch Address ····· Test = "1"	1	0	1	0	First Op Code of Branch Routi
BLE BLS			Op Code Address + 1 ··· Test = "0"					Next Op Code
BLT BMT		1						
BNE BPL								1 1 1 1
BRA BRN								
BVC BVS								
BSR		1	Op Code Address+1	1	0	1	1	Offset
	1	2	FFFF	1	1	1	1	Restart Address (LSB)
	5	3	Stack Pointer	0	1	0	1	Return Address (LSB)
	3	4	Stack Pointer - 1	0	li	0	1	Return Address (MSB)
		5		1	0	1	0	
	1	1 5	Branch Address	1 1	LU	1	1 0	First Op Code of Subroutine

PRECAUTION TO THE BOARD DESIGN OF OSCILLA-TION CIRCUIT

As shown in Fig. 26, there is a case that the cross talk disturbs the normal oscillation if signal lines are put near the oscillation circuit. When designing a board, pay attention to this. Crystal and C_L must be put as near the HD6303X as possible.

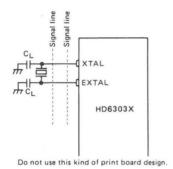


Figure 26 Precaution to the boad design of oscillation circuit

■ RECEIVE MARGIN OF THE SCI

Receive margin of the SCI contained in the HD6303X is shown in Table 17.

Note: SCI = Serial Communication Interface

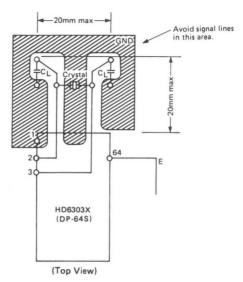
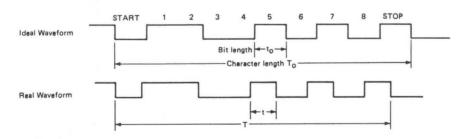


Figure 27 Example of Oscillation Circuits in Board Design

Table 17

	Bit distortion tolerance (t-to) /to	Character distortion tolerance (T-To) /To		
HD6303X	±43.7%	±4.37%		



■ POWER-ON RESET

At power-on it is necessary to hold RES "low" to reset the internal state of the device and to provide sufficient time for the oscillator to stabilize. Pay attention to the following.

*Just after power-on, the MPU doesn't enter reset state until the oscillation starts. This is because the reset signal is input internally, with the clocked synchronization as shown below.

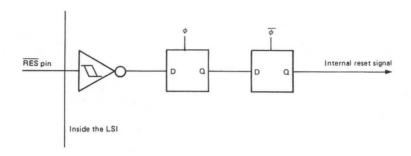


Fig. 28 Reset Circuit

Thus, just after power on the LSI state (I/O port, mode condition etc.) is unstable until the oscillation starts. If it is necessary to inform the LSI state to the external devices during this period, it needs to be done by the external circuits.

■ RESET SIGNAL AND MEMORY READY FUNCTION

The reset signal is strobed to CPU synchronized with internal clock. Since internal clock is held to "High" level during memory-ready-state (\overline{MR} = "Low"), reset sygnal is not strobed to CPU.

Please \overline{MR} input (P_{s2}) should be "High" level during resetstate.

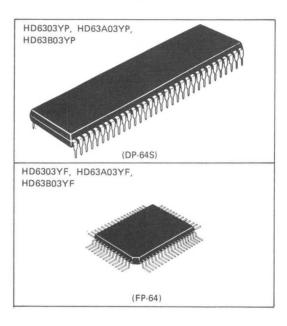
HD6303Y, HD63A03Y, HD63B03Y CMOS MPU (Micro Processing Unit)

The HD6303Y is a CMOS 8-bit single-chip microprocessing unit which contains a CPU compatible with the CMOS 8-bit microcomputer HD6301V, 256 bytes of RAM, 24 parallel I/O pins, Serial Communication Interface (SCI) and two timers.

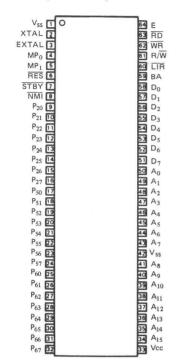
FEATURES

- Instruction Set Compatible with the HD6301V1
- 256 Bytes of RAM
- 24 Parallel I/O Pins
- Parallel Handshake Interface (Port 6)
- Darlington Transistor Drive (Port 2, 6)
- 16-Bit Programmable Timer Input Capture Register × 1 Free Running Counter × 1 Output Compare Register × 2
- 8-Bit Reloadable Timer External Event Counter
- Square Wave Generation
 Serial Communication Interface (SCI)
 - Asynchronous Mode (8 Transmit Formats, Hardware Parity) Clocked Synchronous Mode
- Memory Ready
 - 3 Kinds of Memory Ready
- Halt
- Error Detection (Address Error, Op-code Error)
- Interrupt External 3, Internal 7
- Maximum 65k Bytes Address Space
- Low Power Dissipation Mode Sleep Mode
 - Standby Mode (Hardware Standby, Software Standby)
- Minimum Instruction Execution Time $-0.5\mu s$ (f = 2MHz)
- Wide Range of Operation

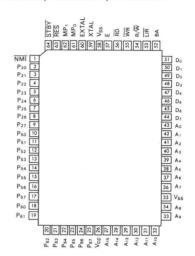
$$V_{CC} = \bar{3} \text{ to 5.5V}$$
 (f=0.1 to 0.5MHz)
 $V_{CC} = 5V \pm 10\%$ (f=0.1 to 1.0MHz : HD6303Y)
f=0.1 to 1.5MHz : HD63A03Y
f=0.1 to 2.0MHz : HD63B03Y



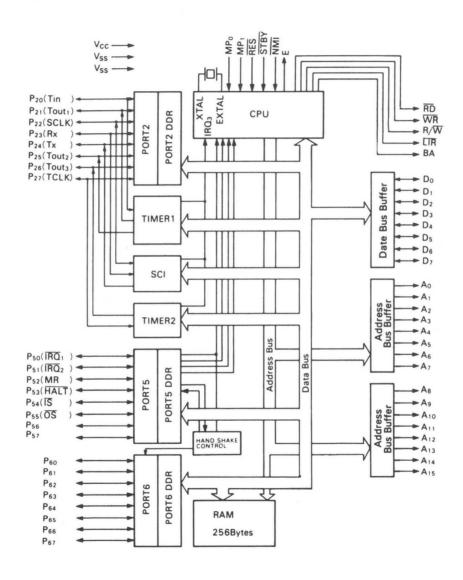
- PIN ARRANGEMENT (Top View)
- HD6303YP, HD63A03YP, HD63B03YP



HD6303YF, HD63A03YF, HD63B03YF



BLOCK DIAGRAM



M ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc}	-0.3~+7.0	٧
Input Voltage	V _{in}	-0.3~V _{CC} +0.3	٧
Operating Temperature	T _{opr}	0~+70	°C
Storage Temperature	T _{stg}	-55~+150	°C

(NOTE) This product has protection circuits in input terminal from high static electricity voltage and high electric field. But be careful not to apply overvoltage more than maximum ratings to these high input impedance protection circuits. To assure the normal operation, we recommend V_{in} , V_{out} : $V_{SS} \le (V_{in} \text{ or } V_{out}) \le V_{CC}$.

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS ($V_{CC} = 5.0V \pm 10\%$, $V_{SS} = 0V$, Ta = $0 \sim +70^{\circ}$ C, unless otherwise noted.)

Ite	m	Symbol	Test Condition	min	typ	max	Unit
	RES, STBY			V _{CC} -0.5	_		
Input "High" Voltage	EXTAL	VIH		V _{cc} ×0.7	-	V _{CC} + 0.3	V
	Other Inputs			2.0	_	1 0.5	
Input "Low" Voltage	All Inputs	V _{IL}		-0.3	-	0.8	V
Input Leakage Current	NMI, RES, STBY, MP ₀ , MP ₁	I _{in}	$V_{in} = 0.5 \sim V_{CC} - 0.5V$		_	1.0	μΑ
Three State Leakage Current	A ₀ ~A ₁₅ , D ₀ ~D ₇ , RD, WR, R/W, Ports 2, 5, 6	I _{TSI}	$V_{in} = 0.5 \sim V_{CC} - 0.5V$	-	_	1.0	μΑ
Output "High" Voltage	All Outputs	V	$I_{OH} = -200\mu A$	2.4	-	-	V
Output High Voltage	All Outputs	V _{OH}	$I_{OH} = -10\mu A$	V _{CC} -0.7	_	_	٧
Output "Low" Voltage	All Outputs	V _{OL}	I _{OL} = 1.6mA	_	_	0.4	٧
Darlington Drive Current	Ports 2, 6	— I _{ОН}	V _{out} = 1.5V	1.0	-	10.0	mA
Input Capacitance	All Inputs	C _{in}	$V_{in} = 0V$, $f = 1MHz$, Ta = 25°C	_	-	12.5	pF
Standby Current	Non Operation	I _{STB}		_	3.0	15.0	μΑ
			Sleeping (f=1MHz**)	-	1.5	3.0	mA
		I _{SLP}	Sleeping (f=1.5MHz**)	-	2.3	4.5	mA
Current Dissipation*			Sleeping (f=2MHz**)		3.0	6.0	mA
Current Dissipation		е	Operating (f=1MHz**)	_	7.0	10.0	mA
		Icc	Operating (f=1.5MHz**)	-	10.5	15.0	mA
			Operating (f=2MHz**)	_	14.0	20.0	mA
RAM Standby Voltage		V _{RAM}		2.0	-	_	V
				1			

Dissipations at X MHz operating or seeping condition is proportional to the of Dissipations at X MHz operation are decided according to the following formula: typ. value (f = X MHz) = typ. value (f = 1 MHz) × X max. value (f = X MHz) = max. value (f = 1 MHz) × X (both the sleeping and operating)

 $V_{\rm HH}$ min = $V_{\rm CC} - 1.0$ V, $V_{\rm IL}$ max = 0.8V (All output terminals are at no load.) Current Dissipation of the operating or sleeping condition is proportional to the operating frequency. So the typ. or max. values about Current

• AC CHARACTERISTICS (V $_{CC}=5.0V\pm10\%$, V $_{SS}=0V$, T $_{a}=0$ $\sim+70$ $^{\circ}$ C, unless otherwise noted.) BUS TIMING

		Cumbal	Test	Н	D6303	Υ	HD	63A03	3Y	н	63B0	3Y	Unit
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Cycle Time		t _{cyc}		1	_	10	0.666	-	10	0.5	-	10	μs
Enable Rise Time		t _{Er}	1	-	-	25	-	_	25	-	-	25	ns
Enable Fall Time		t _{Ef}	1	-	-	25	-	-	25	-	-	25	ns
Enable Pulse Width	"High" Level*	PW _{EH}	1	450	-	-	300	-	-	220	-	-	ns
Enable Pulse Width	"Low" Level*	PW _{EL}	1	450	-	_	300	_	-	220	-	-	ns
Address, R/W Delay	y Time*	t _{AD}	1	-	-	250	-	-	190	-	-	160	ns
Data Delay Time	Write	t _{DDW}	1	-	-	200	-	-	160	-	-	120	ns
Data Set-up Time	Read	t _{DSR}	1	80	-	-	70	-	-	60	-	-	ns
Address, R/W Hold	Time*	t _{AH}	Fig. 1	80	-	-	50	-	_	40	-	-	ns
D	Write*	t _{HW}	1	70	-	-	50	-	-	40	-	-	ns
Data Hold Time	Read	t _{HR}	1	0	-	-	0	-	-	0	-	-	ns
RD, WR Pulse Widt	h*	PW _{RW}	1	450	-	-	300	-	-	220	-	-	ns
RD, WR Delay Time		t _{RWD}	1	-	-	40		-	40	-	-	40	ns
RD, WR Hold Time		t _{HRW}	1	-	-	20	-	-	20	_	-	20	ns
LIR Delay Time		t _{DLR}	1	-	-	200	-	-	160	-	-	120	ns
LIR Hold Time		t _{HLR}	1	10	-	-	10	-	-	10	-	-	ns
MR Set-up Time*		t _{SMR}		400	-	-	280	-	-	230	-	-	ns
MR Hold Time*		t _{HMR}	Fig. 2	-	-	100	-	-	70	-	-	50	ns
E Clock Pulse Width	n at MR	PW _{EMR}	1	-	-	9	_	-	9	-	_	9	μs
Processor Control S	Set-up Time	t _{PCS}	Fig. 3, 13, 14	200	-	-	200	-	-	200	-	-	ns
Processor Control F	Rise Time	t _{PCr}	F:- 2 2	-	-	100	-	-	100	-	-	100	ns
Processor Control F	all Time	t _{PCf}	Fig. 2, 3	-	-	100	-	-	100	-	-	100	ns
BA Delay Time		t _{BA}	Fig. 3	-	-	250	-	-	190	_	-	160	ns
Oscillator Stabilizat	ion Time	t _{RC}	Fig. 14	20	-	-	20	-	-	20	-	-	ms
Reset Pulse Width		PW _{RST}		3	-	_	3	-	-	3	-	-	t _{cyc}

These timings change in approximate proportion to t_{cyc}. The figures in this characteristics represent those when t_{cyc} is minimum (= in the highest speed operation).

PERIPHERAL PORT TIMING

			Test	н	06303	3Y	HD	63A0	3Y	HD	63B0	3Y	11-14
Item		Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Peripheral Data Set Up Time	Port 2, 5, 6	t _{PDSU}	- Fig. 5	200	-	-	200	-	-	200	-	-	ns
Peripheral Data Hold Time	Port 2, 5, 6	t _{PDH}	Fig. 5	200	-	-	200	-	-	200	-	-	ns
Delay Time (From Enable Fall Edge to Peripheral Output)	Port 2, 5, 6	t _{PWD}	Fig. 6	-	-	300	-	-	300	-	-	300	ns
Input Strobe Pulse Width		t _{PWIS}		200	-	-	200	-	-	200	-	-	ns
Input Data Hold Time	Port 6	t _{IH}	Fig. 10	150	-	-	150	-	-	150	-	-	ns
Input Data Set-Up Time	Port 6	t _{iS}		100	-	-	100	-	-	100	-	-	ns
Output Strobe Delay Time		t _{OSD1}	Fig. 11	_	_	200	_	_	200	_	_	200	ns
Carpar C. CCC Dolay Tillio		t _{OSD2}				-20							

TIMER, SCI TIMING

		Combal	Test	Н	D6303	Υ	HE	63A0	3Y	HE	063B0	3Y	Unit
It	tem	Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Timer 1 Input Pu	ulse Width	t _{PWT}	Fig. 9	2.0	-	-	2.0	-	-	2.0	-	-	t _{cyc}
Delay Time (Ena Transition to Tir		t _{TOD}	Fig. 7, 8	-	-	400	-	-	400	-	-	400	ns
SCI Input	Async. Mode	1.	Fig. 9	1.0	_	-	1.0	_	-	1.0	-	-	t _{cyc}
Clock Cycle	Clock Sync.	t _{Scyc}	Fig. 4	2.0	-	-	2.0	_	-	2.0	-	-	t _{cyc}
SCI Transmit Da Time (Clock Syr		t _{TXD}		-	-	220	-	-	220	-	-	220	ns
SCI Receive Dat Time (Clock Syr		t _{SRX}	Fig. 4	260	-	-	260	-	-	260	-	-	ns
SCI Receive Dat (Clock Sync. Mc		t _{HRX}		100	-	-	100	-	-	100	-	-	ns
SCI Input Clock	Pulse Width	t _{PWSCK}		0.4	-	0.6	0.4	-	0.6	0.4	-	0.6	t _{Scyc}
Timer 2 Input C	lock Cycle	t _{tcyc}	7	2.0	-	-	2.0	-	-	2.0	-	-	t _{cyc}
Timer 2 Input C Width	lock Pulse	t _{PWTCK}	Fig. 9	200	-	-	200	-	-	200	-	-	ns
Timer 1·2, SCII Rise Time	nput Clock	t _{CKr}		-	-	100	-	-	100	-	_	100	ns
Timer 1·2, SCII Fall Time	nput Clock	t _{CKf}		-	-	100	-	-	100	-	-	100	ns

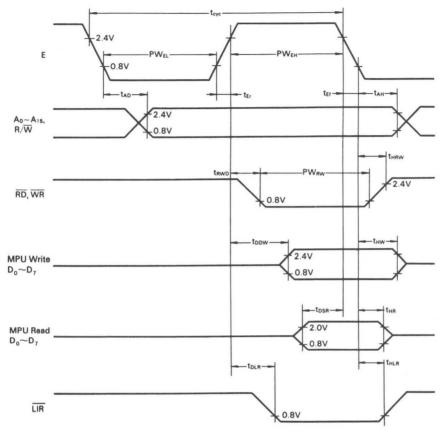


Figure 1 Bus Timing

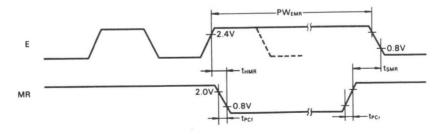


Figure 2 Memory Ready and E Clock Timing

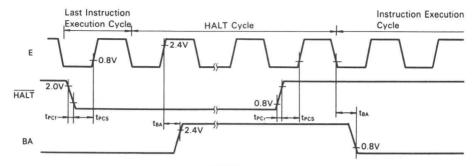
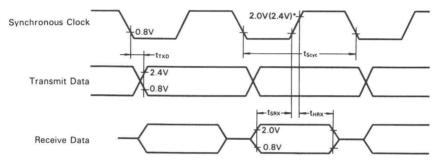


Figure 3 HALT and BA Timing



*2.0V is high level when clock input. 2.4V is high level when clock output.

Figure 4 SCI Clocked Synchronous Timing

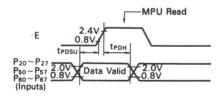


Figure 5 Port Data Set-up and Hold Times (MPU Read)

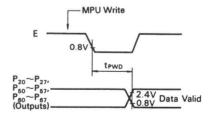


Figure 6 Port Data Delay Times (MPU Write)

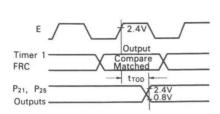


Figure 7 Timer 1 Output Timing

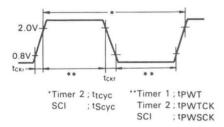


Figure 9 Timer 1.2, SCI Input Clock Timing

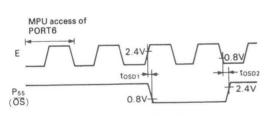


Figure 11 Output Strobe Timing

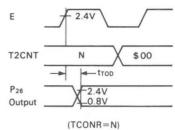


Figure 8 Timer 2 Output Timing

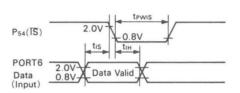


Figure 10 Port 6 Input Latch Timing

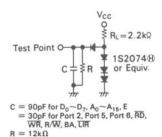


Figure 12 Bus Timing Test Loads (TTL Load)

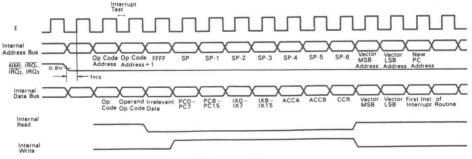


Figure 13 Interrupt Sequence

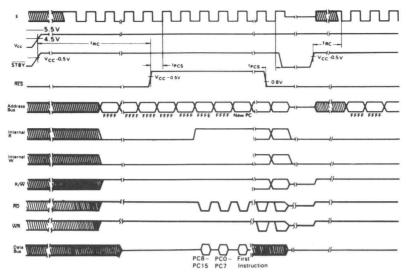


Figure 14 Reset Timing

FUNCTIONAL PIN DESCRIPTION

Vcc, Vss

 V_{CC} and V_{SS} provide power to the MPU with $5V\pm10\%$ supply. In the case of low speed operation (fmax=500kHz), the MPU can operate with 3 to 5.5 volts. Two V_{SS} pins should be tied to ground.

XTAL, EXTAL

These two pins interface with an AT-cut parallel resonant crystal. Divide-by-four circuit is on chip, so if 4MHz crystal oscillator is used, the system clock is 1MHz for example.

EXTAL pin can be drived by the external clock with 45% to 55% duty. The system clock which is one fourth frequency of the external clock is generated in the LSI. The external clock frequency should be less than four times of the maximum operating frequency. When using the external clock, XTAL pin should be open. Fig. 15 shows examples of connection circuit. The crystal and C_{L1} , C_{L2} should be mounted as close as possible to XTAL and EXTAL pins. Any line must not cross the line between the crystal oscillator and XTAL, EXTAL.

AT Cut Parallel Resonant Crystal Oscillator

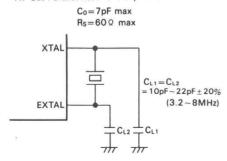


Figure 15 Connection Circuit

• STBY

This pin makes the MPU standby mode. In "Low" level, the oscillation stops and the internal clock is stabilized to make reset condition. To retain the contents of RAM at standby mode, "0" should be written into RAM enable bit (RAME). RAME is the bit 6 of the RAM/port 5 control register at \$0014. RAM is disabled by this operation and its contents is sustained.

Refer to "LOW POWER DISSIPATION MODE" for the standby mode.

• Reset (RES)

This pin resets the MPU from power OFF state and provides a startup procedure. During power-on, \overline{RES} pin must be held "Low" level for at least 20ms.

The CPU registers (accumulator, index register, stack pointer, condition code register except for interrupt mask bit), RAM and the data register of ports are not initialized during reset, so their contents are undefined in this procedure.

To reset the MPU during operation, RES should be held "Low" for at least 3 system-clock cycles. At the 3rd cycle during "Low" level, all the address buses become "High". When RES remains "Low", the address buses keep "High". If RES becomes "High", the MPU starts the next operation.

- (1) Latch the value of the mode program pins; MP₀ and MP₁.
- (2) Initialize each internal register (Refer to Table 4).
- (3) Set the interrupt mask bit. For the CPU to recognize the maskable interrupts IRQ₁, IRQ₂ and IRQ₃, this bit should be cleared in advance.
- (4) Put the contents (=start address) of the last two addresses (\$FFFE, \$FFFF) into the program counter and start the program from this address. (Refer to Table 1).

e Enable (E)

This pin provides a TTL-compatible system clock to external circuits. Its frequency is one fourth that of the crystal oscillator or external clock. This pin can drive one TTL load and 90pF capacitance.

Non-Maskable Interrupt (NMI)

When the falling edge of the input signal is detected at this pin, the CPU begins non-maskable interrupt sequence internally. As well as the IRQ mentioned below, the instruction being executed at NMI signal detection will proceed to its compeletion. The interrupt mask bit of the condition code register doesn't affect non-maskable interrupt at all.

In response to an NMI interrupt, the contents of the program counter, index register, accumulators and condition code register will be saved onto the stack. Upon completion of this sequence, a vector is fetched from \$FFFC and \$FFFD to transfer their contents into the program counter and branch to the non-maskable interrupt service routine.

(Note) At reset start, the stack pointer should be initialized on an appropriate memory area and then the falling edge be input to NMI pin.

Interrupt Request (IRQ1, IRQ2)

These are level-sensitive pins which request an internal interrupt sequence to the CPU. At interrupt request, the CPU will complete

the current instruction before the acceptance of the request. Unless the interrupt mask in the condition code register is set, the CPU starts an interrupt sequence; if set, the interrupt request will be ignored. When the sequence starts, the contents of the program counter, index register, accumulators and condition code register will be saved onto the stack, then the CPU sets the interrupt mask bit and will not acknowledge the maskable request. During the last cycle, the CPU fetches vectors depicted in Table 1 and transfers their contents to the program counter and branches to the service routine.

The CPU uses the external interrupt pins $(\overline{IRQ}_1 \text{ and } \overline{IRQ}_2)$ also as port pins P_{50} and P_{51} , so it provides an enable bit to Bit 0 and 1 of the RAM port 5 control register at \$0014. Refer to "RAM/PORT 5 CONTROL REGISTER" for the details.

When one of the internal interrupts, ICI, OCI, TOI, CMI or SIO is generated, the CPU produces internal interrupt signal (IRQ₃). IRQ₃ functions just the same as $\overline{IRQ_1}$ or $\overline{IRQ_2}$ except for its vector address. Fig. 16 shows the block diagram of the interrupt circuit.

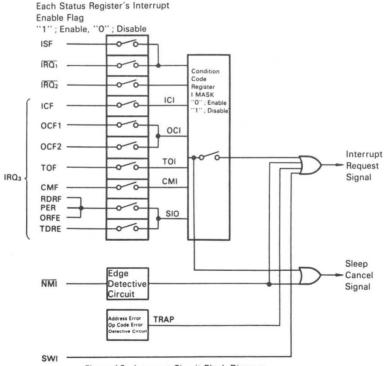


Figure 16 Interrupt Circuit Block Diagram

Table 1 Interrupt Vector Memory Map

Dula via	Ve	ctor	1
Priority	MSB	LSB	Interrupt
Highest	FFFE	FFFF	RES
1	FFEE	FFEF	TRAP
	FFFC	FFFD	NMI
	FFFA	FFFB	SWI (Software Interrupt)
	FFF8	FFF9	TRQ ₁ , ISF (port 6 Input Strobe)
	FFF6	FFF7	ICI (Timer 1 Input Capture)
	FFF4	FFF5	OCI (Timer 1 Output Compare 1, 2)
	FFF2	FFF3	TOI (Timer 1 Overflow)
	FFEC	FFED	CMI (Timer 2 Counter Match)
	FFEA	FFEB	ĪRQ ₂
Lowest	FFFO	FFF1	SIO (RDRF+ORFE+TDRE+PER)

Mode Program (MP₀, MP₁)
 Set MP₀ "High" and MP₁ "Low".

Read/Write (R/W)

This signal, usually be in read state ("High"), shows whether the CPU is in read ("High") or write ("Low") state to the peripheral or memory devices. This can drive one TTL load and 30pF capacitance.

• RD, WR

These signals show active low outputs when the CPU is reading/writing to the peripherals or memories. This enables the CPU easy to access the peripheral LSI with \overline{RD} and \overline{WR} input pins. These pins can drive one TTL load and 30pF capacitance.

Load Instruction Register (LIR)

This signal shows the instruction opecode being on data bus (active low). This pin can drive one TTL load and 30pF capacitance.

Memory Ready (MR; P₅₂)

This is the input control signal which stretches the system clock's "High" period to access low-speed memories. HD6303Y can select three kinds of low-speed memory access method by RAM/Port 5 Control Register's MRE bit and AMRE bit. In the case that CPU accesses low-speed memories by the external MR signal (MRE="1", AMRE="0"), the system clock operates in normal sequence when this signal is in "High".

But this signal in "Low", the "High" period of the system clock will be stretched depending on its "Low" level duration in integral multiples of the cycle time. This allows the CPU to interface with low-speed memories (See Fig. 2). Up to 9µs can be stretched.

During internal address space access or nonvalid memory access, MR is prohibited internally to prevent decrease of operation speed. Even in the halt state, MR can also stretch "High" period of system clock to allow peripheral devices to access low-speed memo-

ries. Refer to "RAM/PORT 5 CONTROL REGISTER" for more details.

Halt (HALT; P₅₃)

This is an input control signal to stop instruction execution and to release buses. When this signal switches to "Low", the CPU stops to enter into the halt state after having executed the present instruction. When entering into the halt state, it makes BA "High" and also an address bus, data bus, \overline{RD} , \overline{WR} , R/\overline{W} high impedance. When an interrupt is generated in the halt state, the CPU uses the interrupt handler after the halt is cancelled. When halted during the sleep state, the CPU keeps the sleep state, while BA is "High" and releases the buses. Then the CPU returns to the previous sleep state when the \overline{HALT} signal becomes "High".

(Note) Please don't switch the HALT signal to "Low" when the CPU executes the WAI instruction and is in the interrupt wait state to avoid the trouble of the CPU's operation after the halt is cancelled.

Bus Available (BA)

This is an output control signal which is normally "Low" but "High" when the CPU accepts HALT and releases the buses. The HD6800 and HD6802 make BA "High" and release the buses at WAI execution, while the HD6303Y doesn't make BA "High" under the same condition.

PORT

The HD6303Y provides three 8-bit I/O ports. Each port provides Data Direction Register (DDR) which controls the I/O state by the bit.

Table 2 Port and Data Direction Register Address

Port	Port Address	Data Direction Register
Port 2	\$0003	\$0001
Port 5	\$0015	\$0020
Port 6	\$0017	\$0016

Port 2

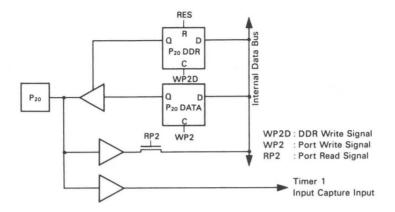
An 8-bit I/O port. Port 2 DDR (P2DDR) controls the I/O state. This port provides DDR corresponding to each bit and can define input or output by the bit ("0" for input, "1" for output).

As Port 2 DDR is cleared during reset, it will be an input port. Port 2 is also used as an I/O pin for timer 1, Timer 2 and the SCI. Pins for Timers and the SCI set or reset each DDR depending on their functions and become I/O pins. When port 2 functions as an I/O port after used as I/O pins of the timers or the SCI, the I/O direction of the pins remain as it is used as the I/O pin of timer and SCI.

Port 2 can drive one TTL load and 30pF capacitance. This port can produce 1mA when $V_{\text{out}}\!=\!1.5V$ to drive directly the base of Darlington transistor.

Pag (Tin)

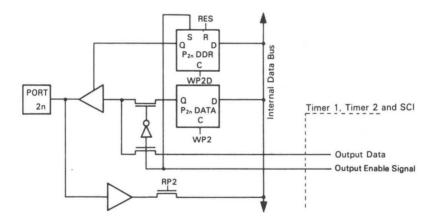
 P_{20} is also used as an external input pin for the input-capture. This pin is an I/O port which is an input or output as defined by the Data Direction Register (P_{20} DDR) ("0" for an input and "1" for an output). Then either a signal to or from P_{20} ("to" for an output port, "from" for an input port) is always input to the Timer 1 input capture.



P₂₁ (Tout 1), P₂₄ (Tx), P₂₅ (Tout 2), P₂₆ (Tout 3)

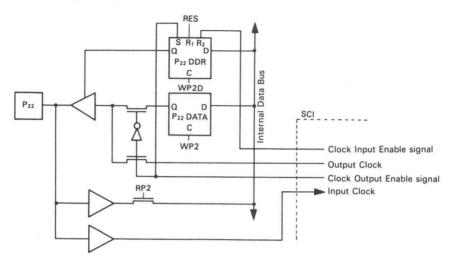
These four pins can be also used as output pins for Timer 1,
Timer 2 and a transmit output of the SCI. Timer 1, and the SCI

have a register which enables output. By setting these registers, they automatically will be output pins of timer or the SCI.



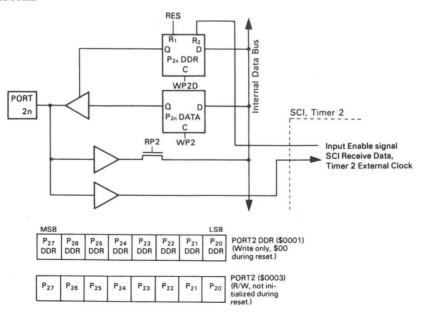
 $\textbf{P}_{\textbf{22}}$ (SCLK) $\textbf{P}_{\textbf{22}}$ is also used as a clock I/O pin for the SCI. It is selected as a clock input or output pin by the operating mode of the SCI. It is usa-

ble as an I/O port when the SCI has no clock input or output (as an output port if P₂₂ DDR=1, as an input port if P₂₂ DDR=0).



 $\begin{array}{l} \textbf{P}_{23} \left(\textbf{Rx} \right), \textbf{P}_{27} \left(\textbf{TCLK} \right) \\ \textbf{P}_{23} \text{ and } \textbf{P}_{27} \text{ are also used as received data input pins for the SCI} \\ \textbf{and external clock input pins for Timer 2}. \text{ The SCI and Timer 2} \end{array}$ have registers which enable input. If the registers are set, the DDR (P₂₃ DDR, P₂₇ DDR) are cleared and P₂₃ and P₂₇ will be input pins for Rx and TCLK.

Since the SCI will be a clocked synchronous mode by an external clock-input during reset, the DDR of P22 is cleared automatically and P_{22} is an input port. Set the SCI to a mode where P_{22} is not used (CC0 or CC1 of the RMC Register is "0" or "1" respectively) and write "1" to the P22 DDR to make P22 an output port.



Port 5

An 8-bit I/O port. The DDR of port 5 controls I/O state. Each bit of port 5 has a DDR which defines I/O state ("0" for input and "1" for output).

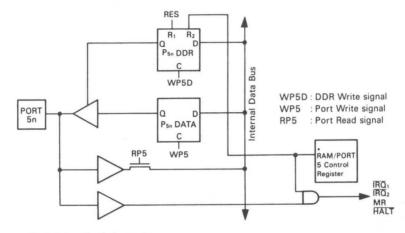
During reset, the DDR of port 5 is cleared and port 5 becomes

an input port.

Port 5 is also usable as $\overline{IRQ_1}$, $\overline{IRQ_2}$, \overline{HALT} , MR and the strobed signal of port 6 for handshake $(\overline{IS}, \overline{OS})$. It is set to input or output automatically if it is used as these control signal pins (except P54, IS). Since the DDR of port 5, as is port 2, is set or reset by the control signal, I/O directions of the I/O ports are retained after the control signal is disabled. Port 5 can drive one TTL load and 90pF capacitance.

 P_{50} (IRQ₁), P_{51} (IRQ₂) P_{50} and P_{51} are also usable as interrupt pins. The RAM/port 5 control registers of $\overline{IRQ_1}$ and $\overline{IRQ_2}$ have enable bits (IQ1E, IQ2E). When these bits are set to "1", P_{50} and P_{51} will automatically be interrupt input pins.

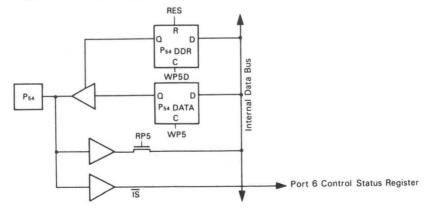
 $\begin{array}{c} \textbf{P_{52}~(MR), P_{53}~(HALT)} \\ \textbf{P_{52}~and P_{53}~are~also~usable~as~MR~and~\overline{HALT}~inputs.~MR~and} \\ \textbf{HALT~have~enable~bits~(MRE, HLTE)~in~the~RAM/Port~5~Control} \end{array}$ Register as \overline{IRQ}_1 and \overline{IRQ}_2 . Since MRE is cleared during reset, P_{52} is usable as an I/O port, and HLTE is set during reset, the DDR of P_{53} will be automatically reset to be a HALT input pin. HLTE of the RAM/Port 5 Control Register has to be cleared to use P53 as an I/O



Initializing value during reset;
 IRQ1E = "0", IRQ2E = "0", MRE = "0", HLTE = "1"

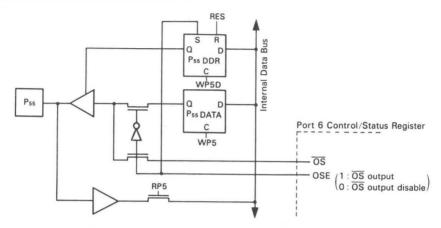
 $\mathbf{P_{54}}$ ($\overline{\mathbf{IS}}$) $\mathbf{P_{54}}$ is also usable as the input strobe ($\overline{\mathbf{IS}}$) for port 6 handshake interface. This pin, as is P20, is always an I/O port. If P54 is used as an

output port (set the DDR of P54 to "1"), an output signal from P54 will be the input to IS.

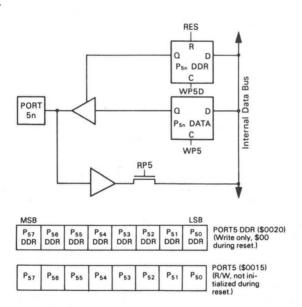


 $\begin{array}{c} \mathbf{P_{55}} \ (\overline{OS}) \\ \mathbf{P_{55}} \ \text{is also usable as the output strobe } (\overline{OS}) \ \text{for port 6 handshake} \\ \text{interface. It will be an I/O port during reset, and an } \overline{OS} \ \text{output pin} \end{array}$

by setting the \overline{OS} enable register (OSE) of the port 6 Control Status Register (P6CSR).



 $P_{\mathbf{56}}$, $P_{\mathbf{57}}$ $P_{\mathbf{56}}$ and $P_{\mathbf{57}}$ are I/O ports.

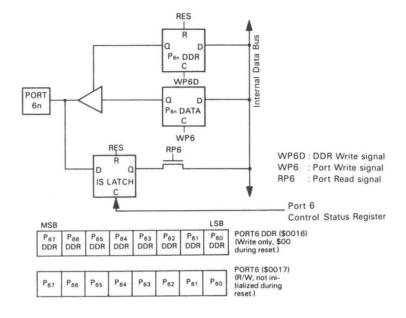


Port 6

8-bit I/O port. Port 6 DDR controls I/O state. Each bit of port 6 has a DDR and designates input or output ("0" for input, "1" for output). During reset, Port 6 DDR is cleared and port 6 becomes an input port.

Port 6 controls parallel handshake interface besides functions as an I/O port. Therefore, it provides DDRs to control and IS LATCH to latch the input data.

Port 6 can drive one TTL load and 30pF capacitance. It can drive directly the base of Darlington transistor as port 2.



- BUS

Address Bus ($A_0 \sim A_{15}$) Address Bus ($A_0 \sim A_{15}$) is used for addressing the memory and peripheral LSI.

This bus can interface with the bus of HMCS 6800 and drive one TTL load and 90pF capacitance.

Data Bus (Do ~ D7)

8-bit parallel data bus for data transmit between the memory or peripheral LSI. This bus can drive one TTL load and 90pF capaci-

RAM/PORT 5 CONTROL REGISTER

The control register located at \$0014 controls on-chip RAM and port 5.

RAM/Port 5 Control Register (RP5CR)

7	6	5	4	3	2	1	0	
STBY PWR	RAME	STBY FLAG	AMR E	HLTE	MRE	IRQ ₂	IRQ ₁	\$0014

Bit 0, Bit 1 IRQ1, IRQ2 Enable Bit (IRQ1E, IRQ2E)

When using P_{50} and P_{51} as interrupt pins, write "1" in these bits. When the bit is set to "1", the DDRs corresponding to P_{50} and

 P_{51} are cleared and become $\overline{IRQ_1}$ input pin and $\overline{IRQ_2}$ input pin. When IRQ_1E and IRQ_2E are set, P_{50} and P_{51} cannot be used as an output ports. When "0", the CPU doesn't accept an external interrupt or a sleep cancellation by the external interrupt. These bits are cleared during reset.

Bit 2 Memory Ready Enable Bit (MRE)

When using P52 as an input pin of the "memory ready" signal, write "1" in this bit. When set, P₅₂ DDR is automatically cleared and becomes the MR input pin. The bit is cleared during reset.

Bit 3 Halt Enable Bit (HLTE)

When using P53 as an input pin of the HALT signal, write "1" in this bit. When this bit is set, P₅₃ DDR is automatically cleared and becomes the Halt input pin. If the bit is "0", the Halt function is inhibited and P53 is used as an I/O port. The bit is set to "1" during reset.

Bit 4 Auto Memory Ready Enable Bit (AMRE)

When the bit is set and the CPU accesses the external address. "memory ready" operates automatically and stretches the E clock's "High" duration for one system clock. When MRE bit of bit 2 is cleared and when the CPU accesses the external address space, the function operates. When MRE bit is set and then the CPU accesses the external address space with P₅₂(MR) pin in "low", "memory ready" operates automatically. This bit is set to "1" during reset.

Table 3 "Memory Ready" Function

MRE	AMRE	Function
0	0	"Memory ready" inhibited.
0	1	When the CPU accesses the external address, "High" duration of E clock automatically becomes one-cycle longer. This state is retained during reset.
1	0	"Memory ready" operates by P ₅₂ (MR) pin. The function is the same as that of the HD6301XO.
1	1	When the CPU accesses the external address space with the P ₅₂ (MR) pin in "low", the "auto memory ready" operates. This function is effective if it has both "high-speed memory" and "slow memory" outside. Input CS signal of "slow memory" to MR pin.

Bit 5 Standby Flag (STBY FLAG)

By clearing this flag, HD6303Y gets into the standby mode by software. This flag is set to "1" during reset, so the standby mode is canceled with RES pin in "low". The RES pin should be in "low" until oscillon becomes stable (min. 20ms.). If the $\overline{\text{STBY}}$ pin in is in "low", the standby mode can not be canceled with the $\overline{\text{RES}}$ pin in "low".

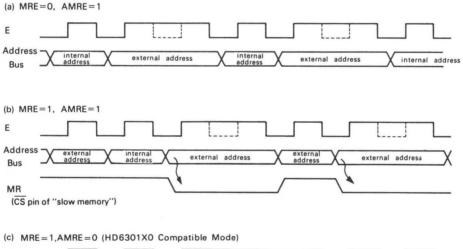
Bit 6 RAM Enable (RAME)

On-chip RAM can be disabled by this control bit. By resetting the MPU, "1" is set to this bit, and on-chip RAM is enabled. When

this bit is cleared (=logic "0") on-chip RAM is invalid and the CPU can read data from external memory. This bit should be "0" before getting into the standby mode to protect on-chip RAM data.

Bit 7 Standby Power Bit (STBY PWR)

When V_{CC} is not provided in standby mode, this bit is cleared. This is a flag for read/write and can be read by software. If this bit is set before standby mode, and remains set even after returning from standby mode, V_{CC} voltage is provided during standby mode and the on-chip RAM data is valid.



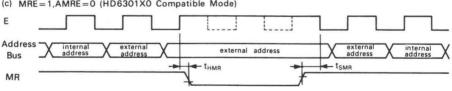


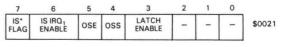
Figure 17 Memory Ready Timing

■ Port 6 Control/Status Register

This is the Control/Status Register for parallel handshake interface using Port 6. The functions are as follows;

- 1) Latches input data to Port 6 at the IS (P₅₄) falling edge.
- Outputs a strobe signal OS (P₅₅) outward by reading or writing to port 6.
- When IS FLAG is set at the IS falling edge, an interrupt occurs.

The following shows Port 6 Control/Status Register (P6CSR).



*Bit 7 is Read-Only bit

Bit 0

Bit 1 Not used.

Bit 2

Bit 3: Latch Enable

This register controls the input latch for Port 6 (ISLATCH). When this bit is set to "1", the input data to port 6 will be latched inward at the $\overline{15}$ (P_{64}) falling edge. An input latch will be canceled by reading Port 6, which enables to latch the next data. If cleared, the input latch remains canceled and this bit functions as a usual input port. This bit is cleared during reset.

Bit 4: OSS Output Strobe Select

This register initiates an output strobe (\overline{OS}) from P_{55} by reading or writing to port 6. When cleared, \overline{OS} occurs by reading Port 6. When set, \overline{OS} occurs by writing to Port 6. This bit is cleared during reset.

Bit 5: OSE Output Strobe Enable

This register decides the enabling or disabling of the output

strobe. When cleared, $P_{\rm 55}$ functions as an I/O port. When set, $P_{\rm 55}$ functions as an $\overline{\rm OS}$ output pin. ($P_{\rm 55}$ DDR is set by OSE.) This bit is cleared during reset.

Bit 6: IS IRQ₁ Enable Input Strobe Interrupt Enable

When set, an $\overline{IRQ_1}$ interrupt to the CPU occurs by setting IS FLAG of bit 7. When cleared, the interrupt does not occur. This bit is cleared during reset.

Bit 7: IS Flag Input Strobe Flag

This flag is set at the IS (P_{bd}) falling edge. This flag is for readonly. When set, the flag is cleared by reading or writing to Port 6 after reading the Port 6 Control Status Register. This bit is cleared during reset.

m MEMORY MAP

The MPU can address up to 65k bytes. Memory map is shown in Fig. 20. 40 addresses ($\$0000 \sim \0027 except \$00, \$02, \$04, \$05, \$06, \$07, \$18) are the internal registers as shown in Table 4.

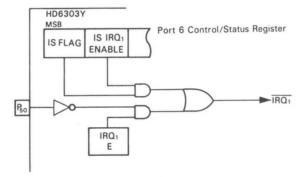


Figure 18 Input Strobe Interrupt block Diagram

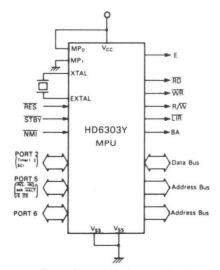


Figure 19 HD6303Y Operating Function



Table 4 Internal Register

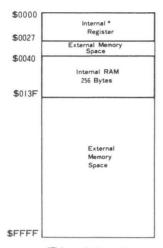
Address	Register		Abbreviation	R/W**	Initialized value during reset***
00°	Port 1 DDR (Data Direction Register)		P1DDR	W	\$FE
01	Port 2 DDR		P2DDR	w	\$00
02°	Port 1		PORT1	R/W	indefinite
03	Port 2		PORT2	R/W	indefinite
04°	Port 3 DDR		P3DDR	W	\$FE
05°	Port 4 DDR		P4DDR	w	\$00
06*	Port 3		PORT3	R/W	indefinite
07°	Port 4		PORT4	R/W	indefinite
08	Timer Control/Status Register 1		TCSR1	R/W	\$00
09	Free Running Counter (MSB)		FRCH	R/W	\$00
OA	Free Running Counter (LSB)		FRCL	R/W	\$00
OB	Output Compare Register 1 (MSB)		OCR1H	R/W	\$FF
oc	Output Compare Register 1 (LSB)		OCR1L	R/W	\$FF
OD	Input Capture Register (MSB)		ICRH	R	\$00
OE	Input Capture Register (LSB)		ICRL	R	\$00
OF	Timer Control/Status Register 2		TCSR2	R/W	\$10
10	Rate/Mode Control Register		RMCR	R/W	\$CO
11	Tx/Rx Control Status Register 1		TRCSR1	R/W	\$20
12	Receive Data Register		RDR	R	\$00
13	Transmit Data Register		TDR	W	indefinite
14	RAM/Port 5 Control Register		RP5CR	R/W	\$F8 or \$78
15	Port 5		PORT5	R/W	indefinite
16	Port 6 DDR		P6DDR	W	\$00
17	Port 6		PORT6	R/W	indefinite
18	Port 7		PORT7	R/W	indefinite
19	Output Compare Register 2 (MSB)		OCR2H	R/W	\$FF
1 A	Output Compare Register 2 (LSB)		OCR2L	R/W	\$FF
1B	Timer Control/Status Register 3		TCSR3	R/W	\$20
1 C	Time Constant Register		TCONR	W	\$FF
1D	Timer 2 Up Counter		T2CNT	R/W	\$00
1E	Tx/Rx Control Status Register 2		TRCSR2	R/W	\$28
1F****	Test Register*		TSTREG	-	-
20	PORT 5 DDR		P5DDR	W	\$00
21	PORT 6 Control/Status Register		P6CSR	R/W	\$07
22	_		_	-	_
23			-	-	_
24		nam.ad	_	- 1	_
25	Re	served	-	_	_
26			_	_	_
27	_		_	_	_

External address.

R: Read-only register, W: Write-only register, R/W: Read/Write register.

When empty bit is in the register, it is set to "1".

Register for test. Don't access this register.



*This mode does not include the addresses: \$00, \$02, \$04, \$05, \$06, \$07 or \$18 which can be used externally.

Figure 20 HD6303Y Memory Map

m TIMER 1

The HD6303Y provides a 16-bit programmable timer which can simultaneously measure an input waveform and generate two independent output waveforms. The pulse widths of both input/output waveforms vary from microseconds to seconds.

Timer 1 is configured as follows (refer to Fig. 22).

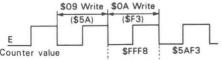
- · Control/Status Register 1 (8 bit)
- · Control/Status Register 2 (7 bit)
- · Free Running Counter (16 bit)
- · Output Compare Register 1 (16 bit)
- · Output Compare Register 2 (16 bit)
- · Input Capture Register (16 bit)

Free-Running Counter (FRC) (\$0009:000A)

The key timer element is a 16-bit free-running counter driven and incremented by system clock. The counter value is readable by software without affecting the counter. The counter is cleared during reset.

When writing to the upper byte (\$09), the CPU writes the preset value (\$FFF8) into the counter (address \$09, \$0A) regardless of the write data value. But when writing to the lower byte (\$0A) after the upper byte writing, the CPU writes not only lower byte data into lower 8 bit, but also upper byte data into higher 8 bit of the FRC.

The counter will be as follows when the CPU writes to it by double store instructions (STD, STX, etc.)



In the case of the CPU write (\$5AF3) to the FRC

Figure 21 Counter Write Timing

Output Compare Register (OCR) (\$000B, \$000C; OCR1) (\$0019, \$001A: OCR2)

The output compare register is a 16-bit read/write register which can control an output waveform. The data of OCR is always compared with the FRC.

When the data matches, output compare flag (OCF) in the timer control/status register (TCSR) is set. If an output enable bit (OE) in the TCSR2 is "1", an output level bit(OLVL) in the TCSR2 will be output to bit 1 (OCR 1) and bit 5 (OCR 2) of port 2. To control the output level again by the next compare, the value of OCR and OLVL should be changed. The OCR is set to \$FFFF at reset. The compare function is inhibited for a cycle just after a write to the upper byte of the OCR or FRC. This is to set the 16-bit value valid in the counter register for compare. In addition, it is because counter is to set \$FFF8 at the next cycle of the CPU's upper byte write to the FRC.

 For data write to the FRC or the OCR, 2-byte transfer instruction (such as STX, etc.) should be used.

• Input Capture Register (ICR) (\$000D : 000E)

The input capture register is a 16-bit read-only register which stores the FRC's value when external input signal transition generates an input capture pulse. Such transition is controled by input edge bit (IEDG) in the TCSR1.

In order to input the external input signal to the edge detector, a bit of the DDR corresponding to bit 0 of port 2 should be cleared ("0"). When an input capture pulse occurs by external input signal transition at the next cycle of CPU's high-byte read of the ICR, the input capture pulse will be delayed by one cycle. In order to ensure the input capture operation, a CPU read of the ICR needs 2-byte transfer instruction. The input pulse width should be at least 2 system cycles. This register is cleared (\$0000) during reset.

• Timer Control/Status Register 1 (TCSR1) (\$0008)

The timer control/status register 1 is an 8-bit register. All bits are readable and the lower 5 bits are also writable. The upper 3 bits are read-only which indicate the following timer status.

- Bit 5 The counter value reached to \$0000 as a result of counting-up (TOF).
- Bit 6 A match has occurred between the FRC and the OCR 1 (OCF1).
- Bit 7 Defined transition of the timer input signal causes the counter to transfer its data to the ICR (ICF).

The followings are the each bit descriptions.

Timer Control/Status Register 1



Bit 0 OLVL1 Output Level 1

OLVL1 is transferred to port 2, bit 1 when a match occurs between the counter and the OCR1. If bit 0 of the TCSR2 (OE1), is set to "1", OLVL1 will appear at bit 1 of port 2.

it 1 IEDG Input Edge

This bit determines which edge, rising or falling, of input signal of bit 0 of port 2 will trigger data transfer from the counter to the ICR. For this function, the DDR corresponding to port 2, bit 0 should be cleared beforehand.

IEDG=0, triggered on a falling edge
("High" to "Low")

IEDG=1, triggered on a rising edge
("Low" to "High")

Bit 2 ETOI Enable Timer Overflow Interrupt

When this bit is set, an internal interrupt (IRQ_3) by TOI interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 3 EOCI1 Enable Output Compare Interrupt 1

When this bit is set, an internal interrupt (IRQ₂) by OCI1 interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 4 **EICI Enable Input Capture Interrupt**

When this bit is set, an internal interrupt (IRO₂) by ICI interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 5 **TOF Timer Overflow Flag**

This read-only bit is set when the counter increments from \$FFFF by 1. Cleared when the counter's MSB byte (\$0009) is read by the CPU after the TCSR1 read at TOF=1.

OCF1 Output Compare Flag 1

This read-only bit is set when a match occurs between the OCR1 and the FRC. Cleared when writing to the OCR1 (\$000B) or \$000C) after the TCSR1 or TCSR2 read at OCF=1.

ICF Input Capture Flag Bit 7

This read-only bit is set when an input signal of port 2, bit 0 makes a transition as defined by IEDG and the FRC is transferred to the ICR. Cleared when reading the upper byte (\$000D) of the ICR after the TCSR1 or TCSR2 read at ICF=1.

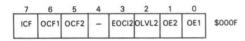
Timer Control/Status Register 2 (TCSR2) (\$000F)

The timer control/status register 2 is a 7-bit register. All bits are readable and the lower 4 bits are also writable. But the upper 3 bits are read-only which indicate the following timer status.

A match has occurred between the FRC and the OCR2 (OCF2)

Rit 6

Timer Control/Status Register 2



Bit 7 The same status flag as the ICF flag of the TCSR1, bit 7. The followings are the each bit descriptions.

OE1 Output Enable 1

This bit enables the OLVL1 to appear at port 2, bit 1 when a match has occurred between the counter and the output compare register 1. When this bit is cleared, bit 1 of port 2 will be an I/O port. When set, it will be an output of OLVL1 automatically.

OE2 Output Enable 2

This bit enables the OLVL2 to appear at port 2, bit 5 when a match has occurred between the counter and the output compare register 2. When this bit is cleared, port 2, bit 5 will be an I/ O port. When set, it will be an output of OLVL2 automatically.

OLVL2 Output Level 2

OLVL2 is transferred to port 2, bit 5 when a match has occurred between the counter and the OCR2. If bit 5 of the TCSR2 (OE2), is set to "1", OLVL2 will appear at port 2, bit 5.

EOCI2 Enable Output Compare Interrupt 2

When this bit is set, an internal interrupt (IRQ3) by OCI2 interrupt is enabled. When cleared, the interrupt is inhibited.

Bit 4 Not used

Bit 5 OCF2 Output Compare Flag 2

This read-only bit is set when a match has occurred between the counter and the OCR2. Cleared when writing to the OCR2 (\$0019 or \$001A) after the TCSR2 read at OCF2=1.

Bit 6 **OCF1 Output Compare Flag 1**

Bit 7 ICF Input Capture Flag

OCF1 and ICF are dual addressed. If which register, TCSR1 or TCSR2, CPU reads, it can read OCF1 and ICF to bit 6 and bit

Both the TCSR1 and TCSR2 will be cleared during reset.

(Note) If OE1 or OE2 is set to "1" before the first output compare match occurs after reset restart, bit 1 or bit 5 of port 2 will produce "0" respectively.

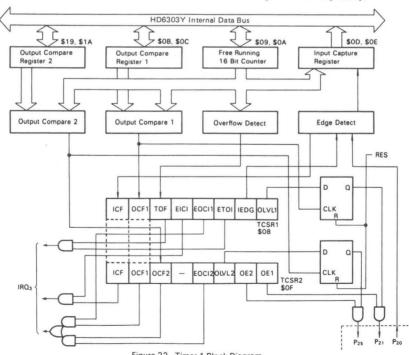


Figure 22 Timer 1 Block Diagram



TIMER 2

In addition to the timer 1, the HD6303Y provides an 8-bit reloadable timer, which is capable of counting the external event. The timer 2 contains a timer output, so the MPU can generate three independent waveforms. (Refer to Fig. 23.)

The timer 2 is configured as follows:

- Control/Status Register 3 (7 bits)
- 8-bit Up Counter
- Time Constant Register (8 bits)

Timer 2 Up Counter (T2CNT) (\$001D)

This is an 8-bit up counter which operates with the clock decided by CKS0 and CKS1 of the TCSR3. The CPU can read the value of the counter without affecting the counter. In addition, any value can be written to the counter by software even during counting.

The counter is cleared when a match occurs between the counter

and the TCONR or during reset.

If the write operation is made by software to the counter at the cycle of counter clear, it does not reset the counter but put the write data to the counter.

Time Constant Register (TCONR) (\$001C)

The time constant register is an 8-bit write only register. The data of register is always compared with the counter.

When a match has occurred, the counter match flag (CMF) of the timer control status register 3 (TCSR3) is set and the value

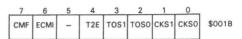
selected by TOS0 and TOS1 of the TCSR3 will appear at port 2, bit 6. When CMF is set, the counter will be cleared simultaneously and then start counting from \$00. This enables regular interrupts and waveform outputs without any software support. The TCONR is set to "\$FF" during reset.

Timer Control/Status Register 3 (TCSR3) (\$001B)

The timer control/status register 3 is a 7-bit register. All bits are readable and 6 bits except for CMF can be written.

The followings are each pin descriptions.

Timer Control/Status Register 3



Rit O CKS0 Input Clock Select 0

Rit 1 CKS1 Input Clock Select 1

Input clock to the counter is selected as shown in Table 5 depending on these two bits. When an external clock is selected, bit 7 of port 2 will be a clock input automatically. Timer 2 detects the rising edge of the external clock and increments the counter. The external clock is countable up to half the frequency of the system clock.

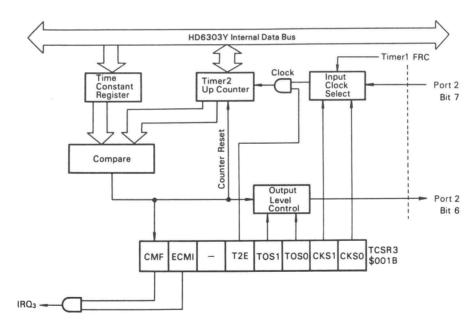


Figure 23 Timer 2 Block Diagram

Table 5 Input Clock Select

CKS1	CKS0	Input Clock to the Counter
0	0	E clock
0	1	E clock/8°
1	0	E clock/128*
1	1	External clock

^{*} These clocks come from the FRC of the timer 1. If one of these clocks is selected as an input clock to the up counter, the CPU should not write to the FRC of the timer 1.

Bit 2 TOSO Timer Output Select 0 Bit 3 TOS1 Timer Output Select 1

When a match occurs between the counter and the TCONR timer 2 outputs shown in Table 6 will appear at port 2, bit 6 depending on these two bits. When both TOS0 and TOS1 are "0", bit 6 of port 2 will be an I/O port.

Table 6 Timer 2 Output Select

TOS1	TOSO	Timer Output
0	0	Timer Output Inhibited
0	1	Toggle Output*
1	0	Output "0"
1	1	Output "1"

When a match occurs between the counter and the TCONR, timer 2 output level is reversed. This leads to production of a square wave with 50% duty to the external without any software support.

Bit 4 T2E Timer 2 Enable Bit

When this bit is cleared, a clock input to the up counter is inhibited and the up counter stops. When set to "1", a clock

selected by CKS1 and CKS0 (Table 5) is input to the up counter.

(Note) P₂₆ outputs "0" when T2E bit cleared and timer 2 set in output enable condition by TOS1 or TOS0. It also outputs "0" when T2E bit set "1" and timer 2 set in output enable condition before the first counter match occurs.

Bit 5 Not Used.

Bit 6 ECMI Enable Counter Match Interrupt

When this bit is set, an internal interrupt (IRQ₃) by CMI is enabled. When cleared, the interrupt is inhibited.

Bit 7 CMF Counter Match Flag

This read-only bit is set when a match occurs between the up counter and the TCONR. Cleared by writing "0" at CMF=1 by software (unable to write "1" by software).

Each bit of the TCSR3 is cleared during reset.

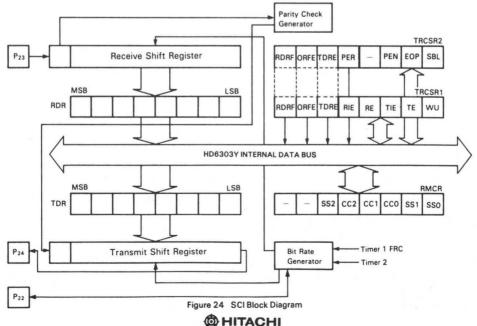
■ SERIAL COMMUNICATION INTERFACE (SCI)

The Serial Communication Interface (SCI) in the HD6303Y contains the following two operating modes: asynchronous mode by the NRZ format, and clocked synchronous mode which transfers data synchronously with the clock. In the asynchronous mode, data length, parity bits and number of stop bits can be selected, and eight transfer formats are provided.

The SCI consists of the following registers as shown in Fig. 24 Block Diagram.

- · Transmit/Receive Control Status Register 1 (TRCSR1)
- · Rate/Mode Control Register (RMCR)
- · Transmit/Receive Control Status Register 2 (TRCSR2)
- · Receive Data Register (RDR)
- · Recevie Shift Register
- · Transmit Data Register (TDR)
- Transmit Shift Register

To operate the SCI, initialize the RMCR and TRCSR2, after selecting the desirable operating mode and transfer format. Next, set the enable bit (TE or RE) of the TRCSR1. Operating mode and transfer format should be changed when the enable bit (TE, RE) is cleared. When setting the TE or RE again after changing the operating mode or transfer format, interval of more than a 1-bit cycle of the baud rate or bit rate is necessary. If a 1-bit cycle or more is not allowed, the SCI block may not be initialized.



Asynchronous Mode

Asynchronous mode contains 8 transfer formats as shown in Fig. 25.

Data transmission is enabled by setting TE bit of the TRCSR1, then port 2, bit 4 will unconditionally become a serial output independently of the corresponding DDR.

To transmit data, set the desirable transmit format with RMCR and TRCSR2. When the TE bit is set, the data can be transmitted after transmitting the one frame of preamble ("1").

The conditions at this stage are as follows.

If the TDR is empty (TDRE=1), consecutive 1's are produced to indicate the idle state.

 If the TDR contains data (TDRE=0), data is sent to the Transmit Shift Register and data transmit starts.

During data transmit, a start bit of "0" is transmitted first. Then 7-bit or 8-bit data (starts from bit 0) is transmitted. With PEN=1, the parity bit, even or odd, selected by EOP bit is added, lastly the stop bit (1 bit or 2 bis) is sent.

When the TDR is "empty", hardware sets TDRE flag bit. If the CPU doesn't respond to the flag in proper timing (the TDRE is in set condition till the next normal data transfer starts from the transmit data register to the transmit sift register), "1" is transferred instead of the start bit "0" and continues to be transferred till data is provided to the data register. While the TDRE is "1", "0" is not transferred.

Data receive is possible by setting RE bit. This makes port 2, bit 3 a serial input. The operation mode of data receive is decided by

the contents of the TRCSR2 and RMCR at first, and set RE bit of TRCSR1. The first "0" (space) synchronizes the receive bit flow. Each bit of the following data will be strobed in the middle. If a stop bit is not "1", a framing error assumed and ORFE is set.

When a framing error occurs, receive data is transferred to the Receive Data Register and the CPU can read the error-generating data. This makes it possible to detect a line break.

When PEN bit is set, the parity check is done. If the parity bit does not match the EOP bit, a parity error occurs and the PER bit is set, not the RDRF bit. Also, when the parity error occurs the receive data can be read just like in the case of the framing error.

The RDRF flag is set when the data is received without a framing error and a parity error.

If RDRF is still set when receiving the stop bit of the next data, ORFE is set to indicate the overrun generation. CPU can get the receive data by reading RDR. When 7 bit data format is selected, the 8th bit of RDR is "0".

When the CPU read the receive Data Register as a response to RDRF flag or ORFE flag after having read TRCSR, RDRF or ORFE is cleared.

(Note) Clock Source in Asynchronous Mode

If CC1:CC0=10, the internal bit rate clock is provided at P_{22} regardless of the values for TE or RE. Maximum clock rate is E+16.

If both CC1 and CC0 are set, an external TTL compatible clock must be connected to P_{22} at sixteen times (16×) the desired bit rate, but not greater than E.

START	7Bit Data	STOP		
START	7Bit Data	2 5	ТОР	
START	7Bit Data	PARITY	STOP	
START	7Bit Data	PARITY	2 STO	Р
START	8Bit Data		STOP	
START	8Bit Data		2 STC)P
START	8Bit Data		PARITY S	ТОР
START	8Bit Data		PARITY	2 STC

Figure 25 Asynchronous Mode Transfer Format

Clocked Synchronous Mode

In the clocked synchronous mode, data transmit is synchronized with the clock pulse. The HD6303Y SCI provides functionally independent transmitter and receiver which makes full duplex operation possible in the asynchronous mode. But in the clocked synchronous mode an SCI clock I/O pin is only P_{22} , so the simultaneous receive and transmit operation is not available. In this mode, TE and RE should not be in set condition ("1") simultaneously. Fig. 26 gives a synchronous clock and a data format in the clocked synchronous mode.

1) Data transmit

Data transmit is realized by setting TE bit in the TRCSR1. Port 2, bit 4 becomes an output unconditionally independent of the value of the corresponding DDR.

Both the RMCR and TRCSR should be set in the desirable operating condition for data transmit.

When an external clock input is selected and the TDRE flag is "0", data transmit is performed from port 2, bit 4, synchronizing with 8 clock pulses input from external to port 2, bit 2.

Data is transmitted from bit 0 and the TDRE is set when the Transmit Shift Register (TSR) is "empty". More than 9th clock pulse of external are ignored.

When data transmit is selected to the clock output, the MPU produces transmit data and synchronous clock at TDRE flag clear.

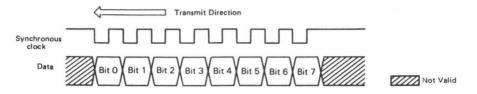
2) Data receive

Data receive is enabled by setting RE bit. Port 2, bit 3 will be a serial input. The operating mode of data receive is decided by the TRCSR1 and the RMCR.

If the external clock input is selected, 8 external clock pulses and the synchronized receive data are input to port 2, bit 2 and bit 3 respectively. The MPU put receive data into the receive data shift register by this clock and set the RDRF flag at the termination of 8 bit

data receive. More than 9th clock pulse of external input are ignored. When RDRF is cleared, the MPU starts receiving the next data instantly. So, RDRF should be cleared with P_{22} "High".

When data receive is selected with the clock output, 8 synchronous clocks are output to the external by setting RE bit. So receive data should be input from external synchronously with this clock. When the first byte data is received, the RDRF flag is set. After the second byte, receive operation is performed by sending the synchronous clock to the external after clearing the RDRF bit.



- · Transmit data is produced from a falling edge of a synchronous clock to the next falling edge.
- · Receive data is latched at the rising edge.

Figure 26 Clocked Synchronous Mode Format

Transmit/Receive Control Status Register (TRCSR1) (\$0011)

The TRCSR1 is composed of 8 bits which are all readable. Bits 0 to 4 are also writable. This register is initialized to \$20 during reset. Each bit functions are as follows.

Transmit/Receive Control Status Register

7	6	5	4	3	2	1	0	
RDRF	ORFE	TDRE	RIE	RE	TIE	TE	WU	\$0011

Bit 0 WU Wake-up

In a typical multi-processor configuration, the software protocol provides the destination address at the first byte of the message. In order to make uninterested MPU ignore the remaining message, a wake-up function is available. By this, uninterested MPU can inhibit all further receive processing till the next message starts.

Then wake-up function is triggered by consecutive 1's with 1 frame length. The software protocol should provide the idle time between messages.

By setting this bit, the MPU stops data receive till the next message. The receive of consecutive "1" with one frame length wakes up and clears this bit by hardware and then the MPU restarts receive operation. However, the RE flag should be already set before setting this bit. In the clocked synchronous mode WU is not available, so this bit should not be set.

Bit 1 TE Transmit Enable

When this bit is set, transmit data will appear at port 2, bit 4 after one frame preamble in asynchronous mode, while in clocked synchronous mode it appears immediately. This is executed regardless of the value of the corresponding DDR. When TE is cleared, the serial I/O doesn't affect port 2, bit 4.

Bit 2 TIE Transmit Interrupt Enable

When this bit is set, an internal interrupt (IRQ₃) is enabled when TDRE (bit 5) is set. When cleared, the interrupt is inhibited.

Bit 3 RE Receive Enable

When set, a signal is input to the receiver from port 2, bit 3 regardless of the value of the DDR. When RE is cleared, the serial I/O doesn't afffect port 2, bit 3.

Bit 4 RIE Receive Interrupt Enable

When this bit is set, an internal interrupt (IRQ₃) is enabled when RDRF (bit 7) or ORFE (bit 6) is set. When cleared, the interrupt is inhibited.

Bit 5 TDRE Transmit Data Register Empty

TDRE is set by hardware when the TDR is transferred to the Transmit Shift Register in the asynchronous mode, while in clocked synchronous mode when the TDSR is "empty". This bit is cleared by reading the TRCSR1 or TRCSR2 and writing new transmit data to the TDR when TDRE=1 TDRE is set to "1" during reset.

Bit 6 ORFE Overrun Framing Error

ORFE is set by hardware when an overrun or a framing error is generated (during data-receive only). An overrun error occurs when new receive data is ready to be transferred to the RDR during RDRF still being set. A framing error occurs when a stop bit is "0". But in clocked synchronous mode, this bit is not affected. This bit is cleared by reading the TRCSR1 or TRCSR2, and the RDR, when RDRF=1. ORFE is cleared during reset.

Bit 7 RDRF Receive Data Register Full

RDRF is set by hardware when data is received normally and transferred from the Receive Shift Register (RSR) to the RDR. This bit is cleared by reading TRCSR1 or TRCSR2, and the RDR, when RDRF=1. This bit is cleared during reset.

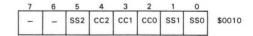
Transmit Rate/Mode Control Register (RMCR)

The RMCR controls the following serial I/O:

- Baud Rate
- · Data Format
- · Clock source
- · Port 2. Bit 2 Function
- · Operation Mode

All bits are readable/writable. Bit 0 to 5 of the RMCR are cleared during reset.

Transfer Rate/Mode Control Register



Bit 0 SSO

Bit 1 SS1 Speed Select

Bit 5 SS2

These bits control the baud rate used for the SCI. Table 7 lists the available baud rates. The timer 1 FRC (SS2=0) and the timer 2 up counter (SS2=1) provide the internal clock to the SCI. When selecting the timer 2 as a baud rate clock source, it functions as a baud rate generator. The timer 2 generates the baud rate listed in Table 8 depending on the value of the TCONR.

(ote) When operating the SCI with internal clock, do not perform write operation to the timer/counter which is the

Table 7 SCI Bit Times and Transfer Rates

(1) Asynchronous Mode

SS2 SS 0 0 0 0			XTAL	2.4576MHz	4.0MHz	4.9152MHz
SS2	SS1	SSO	E	614.4kHz	1.0MHz	1.2288MHz
0	0	0	E÷16	26;is/38400Baud	16µs/62500Baud	13 µs/76800Baud
0	0	1	E÷128	208 µs/4800Baud	128 _{//} s/7812.5Baud	104.2 µs/9600Baud
0	1	0	E ÷ 1024	1.67ms/600Baud	1.024ms/976.6Baud	833.3 µs/1200Baud
0	1	1	E÷4096	6.67ms/150Baud	4.096ms/244.1Baud	3.333ms/300Baud
1	-	-	-	*		

^{*} When SS2 is "1", Timer 2 provides SCI clocks. The baud rate is shown as follows with the TCONR as N.

Baud Rate =
$$\frac{f}{32 \text{ (N+1)}}$$

 $\left(\begin{array}{c} f: \text{ input clock frequency to the} \\ \text{timer 2 counter} \\ N = 0 \sim 255 \end{array}\right)$

(2) Clocked Synchronous Mode *

			XTAL	4.0MHz	6.0MHz	8.0MHz
SS2	SS1	SSO	E	1.0MHz	1.5MHz	2.0MHz
0	0	0	E÷2	2μs/bit	1.33µs/bit	1μs/bit
0	0	1	E÷16	16µs/bit	10.7 µs/bit	8μs/bit
0	1	0	E÷128	128μs/bit	85.3 µs /bit	64µs/bit
0	1	1	E÷512	512μs/bit	341 /s/bit	256µs/bit
1	_	-	-	* *	* *	* *

^{*} Bit rates in the case of internal clock operation. In the case of external clock operation, the external clock is operatable up to DC $\sim 1/2$ system clock.

** The bit rate is shown as follows with the TCONR as N.

Bit Rate (
$$\mu$$
s/bit) = $\frac{4 \text{ (N+1)}}{f}$ $\begin{pmatrix} f: \text{ input clock frequency to the} \\ \text{timer 2 counter} \\ N = 0 \sim 255 \end{pmatrix}$

Table 8 Baud Rate and Time Constant Register Example

Baud Rate (Baud)	2.4576MHz	3.6864MHz	4.0MHz	4.9152MHz	8.0MHz
110	21°	32'	35*	43*	70°
150	127	191	207	255	51°
300	63	95	103	127	207
600	31	47	51	63	103
1200	15	23	25	31	51
2400	7	11	12	15	25
4800	3	5	_	7	12
9600	1	2	_	3	_
19200	0	_	_	1	_
38400	-	_	-	0	_

^{*} E/8 clock is input to the timer 2 up counter and E clock otherwise.

clock source of the SCI.

Bit 2 CC0

Bit 3 CC1 Clock Control/Format Select*

Bit 4 CC2

These bits control the data format and the clock source (refer to Table 9).

* CC0, CC1 and CC2 are cleared during reset and the MPU goes to the clocked synchronous mode of the external clock operation. Then the MPU automatically set port 2, bit 2 into the clock input state. When using port 2, bit 2 as an output port, the DDR of port 2 should be set to "1" and CC1 and CC0 to "0" and "1" respectively.

Bit 6 Not Used. Bit 7 Not Used

• Transmit/Receive Control Status Register 2 (TRCSR2)

The TRCSR2 is a 7-bit register which can select a data format in the asynchronous mode. The upper 3 bits are the same address as the TRCSR1. Therefore, the RDRF, ORFE and TDRE can be read by either the TRCSR1 or TRCSR2. Bits 0 to 2 of the TRCSR2 are used for read/write. Bits 4 to 7 are used only for read.

Transmit/Receive Control Status Register 2

7	6	5	4	3	2	1	0	
RDRF	ORFE	TDRE	PER	-	PEN	EOP	SBL	\$001E

Bit 0 SBL Stop Bit Length

This bit selects the stop bit length in the asynchronous mode. If this bit is "0", the stop bit is 1-bit. If "1", the stop bit is 2-bit. This bit is cleared during reset.

Bit 1 EOP Even/Odd Parity

This bit selects the parity generated and checked when the PEN is "1". If this bit is "0", the parity is even. If "1", it is odd. This bit is cleared during reset.

Bit 2 PEN Parity Enable

This bit decides whether the parity bit should be generated and checked in the asynchronous mode or not. If this bit is "0", the parity bit is neither generated nor checked. If "1", it is generated and checked. This bit is cleared during reset.

The 3 bits above do not affect the SCI opertion in the clocked synchronous mode.

Bit 3 Not Used

Bit 4 PER Parity Error

This bit is set when the PEN is "1" and a parity error occurs. It is cleared by reading the RDR after reading the TRCSR2, when PER=1.

Bit 5 TDRE

Transmit Data Register Empty

Bit 6 ORFE

Overrun/Framing Error

Bit 7 RDRF

Receive Data Register Full

 Each flag of the TDRE, ORFE, and RDRF can be read from either the TRCSR1 or TRCSR2.

m TIMER, SCI STATUS FLAG

Table 10 shows the set and reset conditions of each status flag in the timer 1, timer 2 and SCI.

Table 9 SCI Format and Clock Source Control

CC2	CC1	CCO	Format	Mode	Clock Source	Port 2, Bit 2	Port 2, Bit 3	Port 2, Bit 4					
0	0 0 0 1 0 1 1 0	0	8-bit data	Clocked Synchronous	External	Input	h						
0	0	1	8-bit data	Asynchronous	Internal	Not Used**	When the TRCSR1, RE bit is "1",						
0	0 0 0 0 0 1 0 1	0	8-bit data	Asynchronous	Internal	Output*	bit 3 is used as a						
0	1	1	8-bit data	Asynchronous	External	Input		scriai mpat.					
1	0	0	8-bit data	Clocked Synchronous	Internal	Output	1						
1	0	1	7-bit data	Asynchronous	Internal	Not Used**							
1	0 0 0 0 0 1 0 1 1 0	0	7-bit data	Asynchronous	Internal	Output*	When the TRCSR1, TE bit is "1" bit 4 is used as a serial output.						
1	1	1	7-bit data	Asynchronous	External	Input]	Jones Garpari					

^{*} Clock output regardless of the TRCSR1, bit RE and TE.

^{**} Not used for the SCI.

Table 10 Timer 1, Timer 2 and SCI Status Flag

		Set Condition	Clear Condition
P6CSR	IS FLAG	Falling edge input to P ₅₄ ((S)	Read the P6CSR then read or write the PORT6, when IS FLAG = 1 RES = 0
	ICF	FRC → ICR by Rising or Falling edge input to P ₂₀ (Selecting with the IEDG bit)	Read the TCSR1 or TCSR2 then ICRH, when ICF = 1 RES = 0
	OCF1	OCR1 = FRC	Read the TCSR1 or TCSR2 then write to the OCR1H or OCR1L, when OCF1 = 1 RES = 0
Timer 1	OCF2	OCR2 = FRC	Read the TCSR2 then write to the OCR2H or OCR2L, when OCF2 = 1 RES = 0
	TOF	FRC = \$FFFF+1 cycle	Read the TCSR1 then FRCH, when TOF = 1 RES = 0
Timer 2	CMF	T2CNT = TCONR	 Write "0" to CMF, when CMF = 1 RES = 0
	RDRF	Receive Shift Register → RDR	Read the TRCSR1 or TRCSR2 then RDR, when RDRF = 1 RES = 0
	ORFE	Framing Error (Asynchronous Mode) Stop Bit = 0 Overrun Error (Asynchronous Mode)	Read the TRCSR1 or TRCSR2 then RDR, when ORFE = 1 RES = 0
SCI		Receive Shift Register → RDR when RDRF = 1	2. NES = 0
	TDRE	 Asynchronous Mode TDR → Transmit Shift Register Clocked Synchronous Mode Transmit Shift Register is "empty" RES = 0 	Read the TRCSR1 or TRCSR2 then write to the TDR, when TDRE = 1
	PER	Parity when PEN= 1	Read the TRCSR2 then RDR, when PER= 1 RES=0

(Note) → ; Transfer = ; equal

ICRH; Upper byte of ICR OCR1H; Upper byte of OCR1 OCR2H; Upper byte of OCR2 OCR1L; Lower byte of OCR1 OCR2L; Lower byte of OCR2 FRCH; Upper byte of FRC



LOW POWER DISSIPATION MODE

The HD6303Y provides two low power dissipation modes; sleep and standby.

Sleep Mode

The MPU goes to the sleep mode by SLP instruction execution. In the sleep mode, the CPU stops its operation, while the registers' contents are retained. In this mode, the peripherals except the CPU such as timers, SCI, etc. continue their functions. The power dissipation of sleep-condition is one fourth that of operating condition.

The MPU returns from this mode by an interrupt, RES or STBY; it goes to the reset state by RES and the standby mode by STBY. When the CPU acknowledges an interrupt request, it cancels the sleep mode, returns to the operation mode and branches to the interrupt routine. When the CPU masks this interrupt, it cancels the sleep mode and executes the next instruction. However, for example, if the timer 1 or 2 prohibits a timer interrupt, the CPU doesn't cancel the sleep mode because of no interrupt request.

This sleep mode is effective to reduce the power dissipation for a system with no need of the HD6303Y's consecutive operation.

Standby Mode

The MPU goes to the standby mode with the \overline{STBY} "Low" or by clearing the STBY flag. In this mode, the HD6303Y stops all the clocks and goes to the reset state. In this mode, the power dissipation is reduced to several μ A. During standby, all pins, except the power supply (V_{CC}, V_{SS}), the \overline{STBY} , \overline{RES} and XTAL (which outputs "0"), go to the high impedance state. In this mode, power (V_{CC}) is supplied to the HD6303Y, and the contents of RAM is retained. The MPU returns from this mode during reset. When the MPU goes to the standby mode with \overline{STBY} "Low", it will restart at the timing shown in Fig. 27(a). When the MPU goes to the standby mode by clearing the STBY flag, it will restart only by keeping the \overline{RES} "Low" for longer than the oscillating stabilization time. (Fig. 27(b))

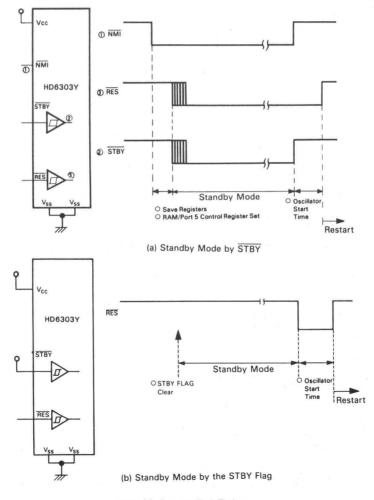


Figure 27 Standby Mode Timing



TRAP FUNCTION

The CPU generates an interrupt with the highest priority (TRAP) when fetching an undefined instruction or an instruction from non-memory space. The TRAP prevents the system-burst caused by noise or a program error.

Op Code Error

When fetching an undefined op code, the CPU saves registers as well as a normal interrupt and branches to the TRAP (\$FFEE, \$FFEF). This has the priority next to reset.

Address Error

When an instruction fetch is made from the address of internal register, the MPU generaters an interrupt as well as an op code error. But on the system with no memory in its external memory area, this function is not applicable if an instruction fetch is made from the external non-memory area. Addresses where an address error occurs are from \$0000 to \$0027.

This function is available only for an instruction fetch and is not applicable to the access of normal data read/write.

te) The TRAP interrupt provides a retry function differently from other interrupts. This is a program flow return to the address where the TRAP occurs when a sequence returns to a main routine from the TRAP interrupt routine by RTI. The retry can prevent the system burst caused by noise, etc.

However, if another TRAP occurs, the program repeats the TRAP interrupt forever, so the consideration is necessary in programming.

■ INSTRUCTION SET

The HD6303Y provides object code upward compatible with the HD6801 to utilize all instruction set of the HMCS6800. It also reduces the execution times of key instructions for throughput improvement.

Bit manipulation instruction, change instruction of the index register and accumulator and sleep instruction are also added.

The followings are explained here.

- · CPU Programming Model (refer to Fig. 28)
- · Addressing Mode
- Accumulator and Memory Manipulation Instruction (refer to Table 11)
- · New Instruction
- Index Register and Stack Manipulation Instruction (refer to Table 12)
- · Jump and Branch Instruction (refer to Table 13)
- · Condition Code Register Manipulation (refer to Table 14)
- · Op Code Map (refer to Table 15)

Programming Model

Fig. 28 depicts the HD6303Y programming model. The double accumulator D consists of accumulator A and B, so when using the accumulator D, the contents of A and B are destroyed.

CPU Addressing Mode

The HD6303Y provides 7 addressing modes. The addressing mode is determined by an instruction type and code. Tables 11 through 15 show addressing modes of each instruction with the execution times counted by the machine cycle.

When the clock frequency is 4MHz, the machine cycle time becomes microseconds directly.

Accumulator (ACCX) Addressing

Only an accumulator is addressed and the accumulator A or B is selected. This is a one-byte instruction.

Immediate Addressing

This addressing locates a data in the second byte of an instruction. However, LDS and LDX locate a data in the second and third byte exceptionally. This addressing is a 2 or 3-byte instruction.

Direct Addressing

In this addressing mode, the second byte of an instruction shows

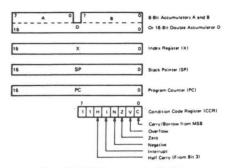


Figure 28 CPU Programming Model

the address where a data is stored. 256 bytes (\$0 through \$255) can be addressed directly. Execution times can be reduced by storing data in this area so it is recommended to make it RAM for users' data area in configurating a system. This is a 2-byte instruction, while 3 byte with regard to AIM, OIM, EIM and TIM.

Extended Addressing

In this mode, the second byte shows the upper 8 bit of the data stored address and the third byte the lower 8 bit. This indicates the absolute address of 3 byte instruction in the memory.

Indexed Addressing

The second byte of an instruction and the lower 8 bit of the index register are added in this mode. As for AIM, OIM, EIM and TIM, the third byte of an instruction and the lower 8 bits of the index register are added.

This carry is added to the upper 8 bit of the index register and the result is used for addressing the memory. The modified address is retained in the temporary address register, so the contents of the index register doesn't change. This is a 2-byte instruction except AIM, OIM, EIM and TIM (3-byte instruction).

Implied Addressing

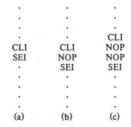
An instruction itself specifies the address. This is, the instruction addresses a stack pointer, index register, etc. This is a one-byte instruction.

Relative Addressing

The second byte of an instruction and the lower 8 bits of the program counter are added. The carry or borrow is added to the upper 8 bit. So addressing from -126 to +129 byte of the current instruction is enabled. This is a 2-byte instruction.

(Note) CLI, SEI Instructions and Interrupt Operation

When accepting the IRQ at a preset timing with CLI and SEI instructions, more than 2 cycles are necessary between the CLI and SEI instructions. For example, the following program (a)(b) don't accept the IRQ but (c) accepts it.



The same thing can be said to the TAP instruction instead of the CLI and SEI instructions.

Table 11 Accumulator, Memory Manipulation Instructions

							Ad	dress	ing	Mod	ies							Condition Code Register							
Operations	Mnemonic	IM	ME	D	DII	REC	T	IN	DE	x	EX	TEN	ND	IMI	PLIE	D	Boolean/ Arithmetic Operation	5	4	3	2	1	0		
		OP	~	#	ОР	~	#	ОР	~	#	ОР	~	#	ОР	~	#	Antimietic Operation	н	1	N	z	v	c		
Add	ADDA	88	2	2	9B	3	2	AB	4	2	88	4	3		\vdash	+	A + M→ A	1	•	1	1	1	1		
	ADDB	СВ	2	2	DB	3	2	EB	4	2	FB	4	3			\vdash	B + M → B	1	•	1	1	1	1		
Add Double	ADDD	СЗ	3	3	D3	4	2	E3	5	2	F3	5	3		\vdash	†	A:B+M:M+1 - A:B			1	1	1	1		
Add Accumulators	ABA	100	+	1		Ť	-		-	-	-	-	۲	18	1	1	A + B → A	1		1	1	1	1		
Add With Carry	ADCA	89	2	2	99	3	2	A9	4	2	89	4	3		Ť	+	A + M + C - A	1		:	1	1	1		
	ADCB	C9	2	2	D9	3	2	E9	4	2	F9	4	3			1	B + M + C → B	1		:	1	1	1		
AND	ANDA	84	2	2	94	3	2	A4	4	2	B4	4	3			1	A·M → A			1	1	R	1		
	ANDB	C4	2	2	D4	3	2	E4	4	2	F4	4	3			1	B·M → B			1	1	R	1		
Bit Test	BITA	85	2	2	95	3	2	A5	4	2	85	4	3	-	-	+	A·M			1	1	R	1		
	BIT B	C5	2	2	D5	3	2	E5	4	2	F5	4	3		\vdash	-	B·M			1	1	R	١,		
Clear	CLR	1-	+	+-	100	-	F	6F	5	2	7F	5	3		\vdash	+	00 → M			R	s	R	F		
0.00	CLRA	+	+	+	_	\vdash	+	0.	-	-	-	1	-	4F	1	1	00 → A			R	S	R	F		
	CLRB	1	+	+	-	\vdash	+		-	+	-		+	5F	1	1	00 → B			R	S	R	1		
Compare	CMPA	81	2	2	91	3	2	A1	4	2	B1	4	3	31	<u>'</u>	+	A - M			1	1	1	1		
Compare	CMPB	C1	2	2	D1	3	2	E1	4	2	F1	4	3	-	-	\vdash	B - M			:	:	1	1		
C		CI	12	2	DI	3	2	E1	-	2	FI	4	3	-	\vdash	-	B - M	٠	-				Ŧ,		
Compare Accumulators	CBA						L							11	1	1	A - B	•	•	:	:	:	1		
Complement, 1's	СОМ							63	6	2	73	6	3				M→M	•	•	1	1	R	9		
	COMA													43	1	1	Ā→A	•	•	1	1	R	1		
	СОМВ												L	53	1	1	B → B	•	•	:	1	R	5		
Complement, 2's	NEG	_			_			60	6	2	70	6	3				00 - M → M	•	•	:	1	1	3		
(Negate)	NEGA	_	1	\vdash	_		L							40	1	1	00 - A → A		•	1	1	ıÎ)	13		
	NEGB	_	-		_					\vdash				50	1	1	00 - B → B	•	•	:	:	1	G		
Decimal Adjust, A	DAA													19	2	1	Converts binary add of BCD characters into BCD format	•		:	:	:	1		
Decrement	DEC							6A	6	2	7A	6	3			Г	M - 1 → M	•	•	:	:	(1)	1		
	DECA													4A	1	1	A - 1 → A		•	:	:	1	1		
	DECB		П											5A	1	1	B - 1 → B		•	:	1	4	t		
Exclusive OR	EORA	88	2	2	98	3	2	A8	4	2	88	4	3				A ⊕ M → A			:	1	R	t		
	EORB	СВ	2	2	DB	3	2	E8	4	2	F8	4	3			\vdash	B ⊕ M→ B			1	1	R	t		
Increment	INC						-	6C	6	2	7C	6	3				M + 1 → M		•	1	1	(3)	١,		
	INCA	1	+	\vdash	\vdash				-	-	-	-	-	4C	1	1	A + 1 → A		•	1	1	(5)	1		
	INCB	\vdash	+	1	1		-			\vdash	-		-	5C	1	1	B + 1 → B		•	1	1	5	1		
Load	LDAA	86	2	2	96	3	2	A6	4	2	86	4	3	-	Ė	+	M → A		•	1	1	R			
Accumulator	LDAB	C6	2	2	D6	3	2	E6	4	2	F6	4	3				M → B			1	:	R			
Load Double Accumulator	LDD	СС	3	3	DC	4	2	EC	5	2	FC	5	3				M + 1 → B, M → A	•		1	1	R			
Multiply Unsigned	MUL		\vdash		1									3D	7	1	A x B → A : B						0		
OR, Inclusive	ORAA	8A	2	2	9A	3	2	AA	4	2	BA	4	3	-	r.	+	A+M→A			1	:	R	1		
o.,	ORAB	CA	2	2	DA	3	2	EA	4	2	FA	4	3	-	\vdash	-	B + M → B			1	1	R	1		
Push Data	PSHA	-	+	-	-	-	-	-	-	-	-	-	-	36	4	1	A → Msp, SP - 1 → SP						1		
. can Dete	PSHB	+	+	-	-		-	-	-	\vdash	-		-	37	4	1	$B \rightarrow Msp, SP - 1 \rightarrow SP$			•	•	•	1		
Pull Data		-	+	-	-	-	\vdash	-	-	-	-	\vdash	-	32	3	-			•	•		•	ł.		
Full Data	PULA	+	+	-	-	-	-	-	-	-	-	-	-	33	3	1	$SP + 1 \rightarrow SP, Msp \rightarrow A$ $SP + 1 \rightarrow SP, Msp \rightarrow B$		•		•	•	ŀ		
Rotate Left	ROL	+	+	-	-	\vdash	+	69	-	-	79	6	3	33	3	+	3F + 1 → 3F, MSD → B	•		-	-	-	1		
notate Lett		+-	+	-	-	-	-	69	6	2	/9	0	3	40			M) [((((((((((((((((((((((((((((((((((((_	-	:	:	(1)	┺		
	ROLA	-	-	-	-	_	-	_	_	-	_	-	_	49	1	1	(*) 454P1111P4	•	•	1	1	(6)	L		
D Dist.	ROLB	-	-	-	-	_	-	-	-	-	70	-	-	59	1	1		•	•	:	1	•	Ľ		
Rotate Right	ROR	+	-	+	-	-	-	66	6	2	76	6	3	40	-	1	M) +0+111111	•	•	8	:	(1)	Ľ		
	RORA	-	-	-	-	_	-	_	-	-	_	-	-	46	1	1	C 67 60	•	•	1	1	(8)	1		
	RORB													56	1	1	-	•	•	1	1	18,	1		

(Note) Condition Code Register will be explained in Note of Table 14.



Table 11 Accumulator, Memory Manipulation Instructions

							Add	iressi	ng f	Aod	les							C	Condition Code Register							
Operations	Mnemonic	IMI	ME	D	DIF	REC	Т	IN	DE	<	EX.	TEN	D	IM	PLIE	D	Boolean/ Arithmetic Operation	5	4	3	2	1	0			
		OP	~	#	ОР	~	#	OP	~	#	OP	~	#	OP	~	#		н	ı	N	z	٧	0			
Shift Left	ASL							68	6	2	78	6	3			Г	м			1	1	6	1			
Arithmetic	ASLA													48	1	1	A D+			:	:	6	1			
	ASLB													58	1	1	B C 67 60			1	1	6	1			
Double Shift Left, Arithmetic	ASLD													05	1	1	ACC A/ ACC B 4-0 C A7 A0 B7 B0	•		:	1	6	1			
Shift Right	ASR							67	6	2	77	6	3				M)			\$	1	6	1			
Arithmetic	ASRA													47	1	1	A 4	•	•	:	1	6	1			
	ASRB													57	1	1	8 57 60 C			1	:	6	1			
Shift Right	LSR							64	6	2	74	6	3				м, —			R	1	6	1			
Logical	LSRA													44	1	1	A 0+			R	:	6	1			
	LSRB													54	1	1	B b7 60 C		•	R	1	6				
Double Shift Right Logical	LSRD													04	1	1	0-ACC A/ ACC B - A7 A0 B7 B0 C	•		R	1	6	1			
Store	STAA				97	3	2	A7	4	2	В7	4	3				A → M		•	:	1	R	1			
Accumulator	STAB				D7	3	2	E7	4	2	F7	4	3				B → M			1	1	R	1			
Store Double Accumulator	STD				DD	4	2	ED	5	2	FD	5	3				A → M B → M + 1	•	•	1	1	R				
Subtract	SUBA	80	2	2	90	3	2	A0	4	2	BO	4	3				A - M → A		•	1	:	:	1			
	SUBB	co	2	2	D0	3	2	EO	4	2	FO	4	3				B - M → B		•	:	‡	1				
Double Subtract	SUBD	83	3	3	93	4	2	A3	5	2	В3	5	3				A : B - M : M + 1 → A : B	•		1	‡	1	1			
Subtract Accumulators	SBA													10	1	1	A - B → A	•	•	:	1	1				
Subtract	SBCA	82	2	2	92	3	2	A2	4	2	B2	4	3				A - M - C → A	•	•	1	1	1	1			
With Carry	SBCB	C2	2	2	D2	3	2	E2	4	2	F2	4	3				B - M - C → B			1	1	1				
Transfer	TAB													16	1	1	A → B		•	1	:	R	1			
Accumulators	TBA													17	1	1	B → A	•		1	1	R	Ŀ			
Test Zero or	TST							6D	4	2	7D	4	3			L	M - 00			1	1	R	1			
Minus	TSTA													4D	1	1	A - 00	•		1	:	R	ľ			
	TSTB													5D	1	1	B - 00			1	\$	R	1			
And Immediate	AIM				71	6	3	61	7	3							M·IMM→M		•	1	1	R	1			
OR Immediate	OIM				72	6	3	62	7	3							M+IMM→M		•	1	1	R	ŀ			
EOR Immediate	EIM				75	6	3	65	7	3							M⊕IMM→M			1	:	R	1			
Test Immediate	TIM				7B	4	3	6B	5	3						Г	M-IMM			1	1	R	t			

(Note) Condition Code Register will be explained in Note of Table 14.

Additional Instruction

In addition to the HD6801 instruction set, the HD6303Y prepares the following new instructions.

AIM (M)·(IMM) → (M)

Executes "AND" operation to immediate data and the memory contents and stores its result in the memory.

OIM (M)+ (IMM) → (M)
Executes "OR" operation to immediate data and the memory contents and stores its result in the memory.

EIM (M) \oplus (IMM) \rightarrow (M) Executes "EOR" operation to immediate data and the memory contents and stores its result in the memory.

 $(M) \cdot (IMM)$

Executes "AND" operation to immediate data and changes the relative flag of the condition code register.

These are the 3-byte instructions; the first byte is op code, the second immediate data and the third address modifier.

XGDX (ACCD)→(IX)

Exchanges the contents of accumulator and the index regis-

SLP

Goes to the sleep mode. Refer to "LOW POWER DISSIPA-TION MODE" for more details of the sleep mode.

Table 12 Index Register, Stack Manipulation Instructions

							Add	dress	ing	Мо	des						Boolean/	(on (e
Pointer Operations	Mnemonic	IM	ME	D.	DII	REC	T	IN	DE	X	EX	TEN	ID	IMP	LIE	D	Arithmetic Operation	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		н	1	N	Z	٧	С
Compare Index Reg	CPX	80	3	3	9C	4	2	AC	5	2	вс	5	3				X-M:M+1	•	•	1	:	1	1
Decrement Index Reg	DEX													09	1	1	X - 1 → X	•	•		:		
Decrement Stack Pntr	DES													34	1	1	SP - 1 → SP	•	•	•	•	•	
Increment Index Reg	INX													08	1	1	X + 1 → X				:		
Increment Stack Pntr	INS													31	1	1	SP + 1 → SP	•					
Load Index Reg	LDX	CE	3	3	DE	4	2	EE	5	2	FE	5	3				$M \rightarrow X_H$, $(M+1) \rightarrow X_L$	•	•	(2)	:	R	
Load Stack Pntr	LDS	8E	3	3	9E	4	2	AE	5	2	BE	5	3				M → SPH. (M+1) → SPL	•	•	1	:	R	
Store Index Reg	STX				DF	4	2	EF	5	2	FF	5	3				$X_H \rightarrow M, X_L \rightarrow (M+1)$		•	9	:	R	
Store Stack Pntr	STS				9F	4	2	AF	5	2	BF	5	3				SPH - M, SPL - (M+1)	•	•	17	:	R	
Index Reg → Stack Pntr	TXS													35	1	1	X - 1 → SP		•				
Stack Pntr → Index Reg	TSX								Г					30	1	1	SP + 1 → X	•	•	•	•	•	
Add	ABX													3A	1	1	B + X → X		•				
Push Data	PSHX													3C	5	1	$X_L \rightarrow M_{sp}$, $SP - 1 \rightarrow SP$ $X_H \rightarrow M_{sp}$, $SP - 1 \rightarrow SP$	•	•	•	•	•	•
Pull Data	PULX													38	4		$SP + 1 \rightarrow SP, M_{ap} \rightarrow X_{H}$ $SP + 1 \rightarrow SP, M_{ap} \rightarrow X_{L}$	•	•	•	•	•	6
Exchange	XGDX													18	2	1	ACCDIX						-

(Note) Condition Code Register will be explained in Note of Table 14.

Table 13 Jump, Branch Instruction

							Ad	dres	ing	Мо	des							(on	Cod	
Operations	Mnemonic	REL	ATI	VE	DII	REC	т	IN	DE	x	EX.	TEN	D	IMP	LIE	D	Branch Test	5	4	3	2	1	0
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#		н	1	N	Z	V	С
Branch Always	BRA	20	3	2													None			•	•	•	
Branch Never	BRN	21	3	2													None			•		•	•
Branch If Carry Clear	всс	24	3	2													C = 0						
Branch If Carry Set	BCS	25	3	2													C = 1	•	•	•	•	•	
Branch If = Zero	BEQ	27	3	2													Z = 1		•	•	•	•	
Branch If > Zero	BGE	2C	3	2													N ⊕ V = 0		•		•		
Branch If > Zero	BGT	2E	3	2													Z + (N + V) = 0		•		•		•
Branch If Higher	ВНІ	22	3	2													C + Z = 0			•	•		•
Branch If < Zero	BLE	2F	3	2													Z + (N + V) = 1			•			•
Branch If Lower Or Same	BLS	23	3	2													C + Z = 1	•	•	•	•	•	•
Branch If < Zero	BLT	2D	3	2												- 1	N ⊕ V = 1				•		•
Branch If Minus	BMI	28	3	2													N = 1		•	•			•
Branch If Not Equal Zero	BNE	26	3	2													Z = 0	•	•	•	•	•	•
Branch If Overflow Clear	BVC	28	3	2													v = 0	•	•	•	•	•	•
Branch If Overflow Set	BVS	29	3	2													V = 1		•	•	•		•
Branch If Plus	BPL	2A	3	2													N = 0		•	•		•	•
Branch To Subroutine	BSR	80	5	2																		•	•
Jump	JMP							6E	3	2	7E	3	3				1		•	•		•	
Jump To Subroutine	JSR				9D	5	2	AD	5	2	BD	6	3					•	•	•		•	•
No Operation	NOP													01	1	1	Advances Prog. Cntr. Only	•	•	•	•	•	•
Return From Interrupt	RTI	\top											Г	3B	10	1		-	_	- (1	_	_
Return From Subroutine	RTS													39	5	1		•	•	•	•	•	•
Softwere Interrupt	SWI													3F	12	1]	•	S	•	•	•	
Wait for Interrupt*	WAI			Г			Г						Γ	3E	9	1			1		•	•	
Sleep	SLP			1	1									1A	4	1							

(Note) *WAI puts R/ \overline{W} high; Address Bus goes to FFFF; Data Bus goes to the three state. Condition Code Register will be explained in Note of Table 14.



Table 14 Condition Code Register Manipulation Instructions

		Addre	ssingf	Modes		C	ondit	ion C	ode f	Regist	ter
Operations	Mnemonic	IM	PLIE	D	Boolean Operation	5	4	3	2	1	0
		OP	~	#		н	1	N	Z	V	C
Clear Carry	CLC	OC.	1	1	0 → C	•	•	•	•	•	R
Clear Interrupt Mask	CLI	0E	1	1	0 → 1	•	R	•		•	
Clear Overflow	CLV	0A	1	1	0 → V	•	•	•		R	
Set Carry	SEC	0D	1	1	1 → C	•	•			•	S
Set Interrupt Mask	SEI	OF	1	1	1 → 1	•	S	•	•		
Set Overflow	SEV	08	1	1	1 → V	•			•	S	
Accumulator A → CCR	TAP	06	1	1	A→ CCR			_ (0 -		_
CCR → Accumulator A	TPA	07	1	1	CCR → A						

LEGEND

- OP Operation Code (Hexadecimal)
- ~ Number of MCU Cycles

MSP Contents of memory location pointed by Stack Pointer

- # Number of Program Bytes
- + Arithmetic Plus
- Arithmetic Minus
- Boolean AND
- + Boolean Inclusive OR
- Boolean Exclusive OR
- M Complement of M
- → Transfer into 0 Bit = Zero
- 00 Byte = Zero

CONDITION CODE SYMBOLS

- H Half-carry from bit 3 to bit 4
- I Interrupt mask
- N Negative (sign bit)
- Z Zero (byte)
- V Overflow, 2's complement
- C Carry/Borrow from/to bit 7
- R Reset Always
- S Set Always
- \$ Set if true after test or clear
- Not Affected

(Note) Condition Code Register Notes: (Bit set if test is true and cleared otherwise)

- (1) (Bit V) Test: Result = 10000000?
- (2) (Bit C) Test: Result + 00000000?
- 3 (Bit C) Test: BCD Character of high-order byte greater than 10? (Not cleared if previously set)
- (Bit V) Test: Operand = 10000000 prior to execution?
- (5) (Bit V) Test: Operand = 01111111 prior to execution?
- (6) (Bit V) Test: Set equal to N C = 1 after the execution of instructions
- (Bit N) Test: Result less than zero? (Bit 15=1)
- (8) (All Bit) Load Condition Code Register from Stack.
- (9) (Bit 1) Set when interrupt occurs. If previously set, a Non-Maskable Interrupt is required to exit the wait state.
- (ii) (All Bit) Set according to the contents of Accumulator A.
- (Bit C) Result of Multiplication Bit 7=1? (ACCB)

Table 15 OP-Code Map

OP						ACC	ACC		EXT		ACCA	or SP			ACCE	or X		1
COD	E				- 1	Α	В	IND	DIR	IMM	DIR	IND	EXT	IMM	DIR	IND	EXT	1
\ H	1	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111	
LO		0	1	2	3	4	5	6	7	8	9	A	В	С	D	E	F	1
0000	0		SBA	BRA	TSX		N	EG					S	UB				1
0001	1	NOP	CBA	BRN	INS			A	IM				С	MP				I
0010	2			ВНІ	PULA			0	MI				S	ВС				2
0011	3			BLS	PULB		C	MC			SL	JBD	0 1000		AD	DD		3
0100	4	LSRD		BCC	DES		L	SR					A	ND				4
0101	5	ASLD		BCS	TXS			E	IM				8	HT				5
0110	6	TAP	TAB	BNE	PSHA		R	OR					L	DA				•
0111	7	TPA	TBA	BEQ	PSHB		A	SR				STA				STA		7
1000	8	INX	XGDX	BVC	PULX		A	SL						OR				1
1001	9	DEX	DAA	BVS	RTS		R	OL					A	DC.				9
1010	A	CLV	SLP	BPL	ABX		D	EC					0	RA				1
1011	В	SEV	ABA	BMI	RTI			1	IM				A	DD				E
1100	С	CLC		BGE	PSHX		- 1	NC			С	PX			L	DD		(
1101	D	SEC		BLT	MUL		T	ST		BSR		JSR				STD		
1110	E	CLI		BGT	WAI		/	J	MP		L	DS			L	DX		8
1111	F	SEI		BLE	SWI		C	LR			1	STS				STX		1
		0	1	2	3	4	5	6	7	8	9	A	В	С	D	E	F	T

UNDEFINED OP CODE

Only each instructions of AIM, OIM, EIM, TIM

CPU OPERATION

• CPU Instruction Flow

When operating, the CPU fetches an instrution from a memory and executes the required function. This sequence starts with \overline{RES} cancel and repeats itself limitlessly if not affected by a special instruction or a control signal. SWI, RTI, WAI and SLP instructions change this operation, while \overline{NMI} , \overline{IRQ}_1 , \overline{IRQ}_2 , \overline{IRQ}_3 , \overline{HALT} and STBY control it. Fig. 29 gives the CPU mode transition and Fig. 30 the CPU system flow chart. Table 16 shows CPU operating states

and port states.

Operation at Each Instruction Cycle

Table 17 shows the operation at each instruction cycle. By the pipeline control of the HD6303Y, MULT, PUL, DAA and XGDX instructions, etc. prefetch the next instruction. So attention is necessary to the counting of the instruction cycles because it is different from the usual one—from op code fetch to the next instruction op code.

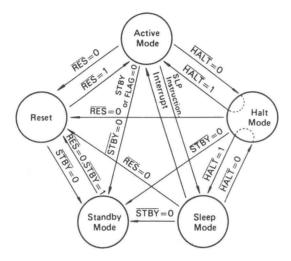


Figure 29 CPU Operation Mode Transition

Table 16 CPU Operation State and Port, Bus, Control Signal State

Port	Reset	STBY'3	HALT	Sleep
$A_0 \sim A_7$	Н	Т	Т	Н
A ₀ ~ A ₇ Port 2	Т	Т	Keep	Keep
$D_0 \sim D_7$	Т	T	Т	Т
$D_0 \sim D_7$ $A_8 \sim A_{15}$	Н	Т	Т	Н
Port 5	Т	Т	Keep	Keep
Port 6	Т	T	Keep	Keep
Control Signal	•1	T	•2	*1

^{*1} \overline{RD} , \overline{WR} , R/\overline{W} , $\overline{LIR} = H$, BA = L

^{*2} \overline{RD} , \overline{WR} , $R/\overline{W} = T$, \overline{LIR} , BA = H

^{*3} E pin goes to high impedance state.

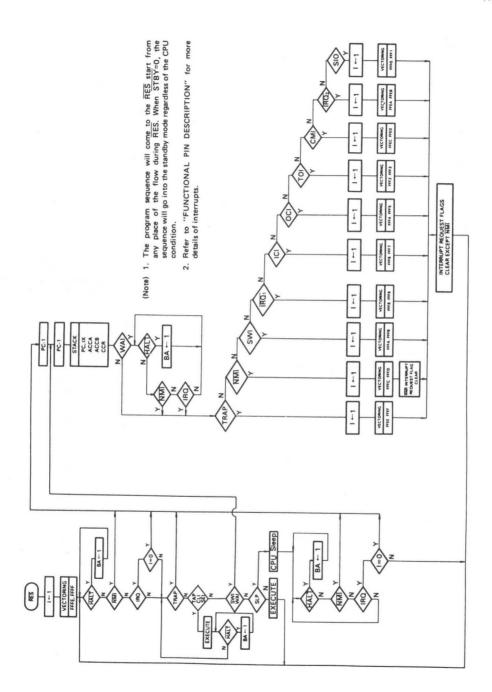


Figure 30 HD6303Y System Flow Chart

Table 17 Cycle-by-Cycle Operation

	ss Mode & ructions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
MMEDIA	ATE								
ADC	ADD	T	1	Op Code Address + 1	1	0	1	1	Operand Data
AND	BIT		2	Op Code Address + 2	1	0	1	0	Next Op Code
CMP	EOR	2							
LDA	ORA								
SBC	SUB								
ADDD	CPX		1	Op Code Address + 1	1	0	1	1	Operand Data (MSB)
LDD	LDS	3	2	Op Code Address + 2	1	0	1	1	Operand Data (LSB)
LDX	SUBD		3	Op Code Address+3	1	0	1	0	Next Op Code
DIRECT									
ADC	ADD		1	Op Code Address + 1	1	0	1	1	Address of Operand (LSB
AND	BIT		2	Address of Operand	1	0	1	1	Operand Data
CMP	EOR	3	3	Op Code Address + 2	1	0	1	0	Next Op Code
LDA	ORA								
SBC	SUB								
STA			1	Op Code Address + 1	1	0	1	1	Destination Address
		3	2	Destination Address	0	1	0	1	Accumulator Data
			3	Op Code Address + 2	1	0	1	0	Next Op Code
ADDD	CPX		1	Op Code Address + 1	1	0	1	1	Address of Operand (LSB
LDD	LDS	4	2	Address of Operand	1	0	1	1	Operand Data (MSB)
LDX	SUBD	"	3	Address of Operand + 1	1	0	1	1	Operand Data (LSB)
			4	Op Code Address + 2	1	0	1	0	Next Op Code
STD	STS		1	Op Code Address + 1	1	0	1	1	Destination Address (LSB
STX		4	2	Destination Address	0	1	0	1	Register Data (MSB)
		4	3	Destination Address + 1	0	1	0	1	Register Data (LSB)
			4	Op Code Address + 2	1	0	1	0	Next Op Code
JSR			1	Op Code Address + 1	1	0	1	1	Jump Address (LSB)
			2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer	0	1	0	1	Return Address (LSB)
			4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
			5	Jump Address	1	0	1	0	First Subroutine Op Code
TIM			1	Op Code Address + 1	1	0	1	1	Immediate Data
		4	2	Op Code Address + 2	1	0	1 .	. 1	Address of Operand (LSB
		-	3	Address of Operand	1	0	1	1	Operand Data
			4	Op Code Address+3	1	0	1	0	Next Op Code
AIM	EIM		1	Op Code Address + 1	1	0	1	1	Immediate Data
OIM			2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB
		6	3	Address of Operand	1	0	1	1	Operand Data
		0	4	FFFF	1	1	1	1	Restart Address (LSB)
			5	Address of Operand	0	1	0	1	New Operand Data
			6	Op Code Address + 3	1	0	1	0	Next Op Code



Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
NDEXED								
JMP		1	Op Code Address+1	1	0	1	1	Offset
	3	2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Jump Address	1	0	1	0	First Op Code of Jump Routin
ADC ADD		1	Op Code Address + 1	1	0	1	1	Offset
AND BIT		2	FFFF	1	1	1	1	Restart Address (LSB)
CMP EOR	4	3	IX+Offset	1	0	1	1	Operand Data
LDA ORA		4	Op Code Address+2	1	0	1	0	Next Op Code
SBC SUB								
TST								
STA		1	Op Code Address + 1	1	0	1	1	Offset
	4	2	FFFF	1	1	1	1	Restart Address (LSB)
	1	3	IX+Offset	0	1	0	1	Accumulator Data
		4	Op Code Address+2	1	0	1	0	Next Op Code
ADDD		1	Op Code Address+1	1	0	1	1	Offset
CPX LDD	_	2	FFFF	1	1	1	1	Restart Address (LSB)
LDS LDX	5	3	IX+Offset	1	0	1	1	Operand Data (MSB)
SUBD		4	IX+Offset+1	1 1	0	1	1	Operand Data (LSB)
STD STS	-	5	Op Code Address + 2	1	0	1	0	Next Op Code
STX		2	Op Code Address + 1 FFFF	1	1	1	1	Offset
317	5	3		0	1	0	1	Restart Address (LSB)
	5	4	IX + Offset IX + Offset + 1	0	1	0	1	Register Data (MSB)
		5	William Commence of the Commen	1	0	1	0	Register Data (LSB)
JSR	+	1	Op Code Address + 2 Op Code Address + 1	1	0			Next Op Code
Jon		2	FFFF		(100)	1	1	Offset
	5	3	2.1.5.1		1	1	1	Restart Address (LSB)
	5	4	Stack Pointer Stack Pointer – 1	0	1	0	1	Return Address (LSB)
		5		1	1	0	1	Return Address (MSB)
ASL ASR	-	1	IX+Offset Op Code Address+1	1	0	1	0	First Subroutine Op Code
COM DEC		2	FFFF	1	1	1	1	Offset
INC LSR		3	IX+Offset	1	0	1	1	Restart Address (LSB) Operand Data
NEG ROL	6	4	FFFF	1	1	1	1	Restart Address (LSB)
ROR		5	IX+Offset	o	1	o	1	New Operand Data
		6	OP Code Address + 2	1	ò	1	o	Next Op Code
TIM	1	1	Op Code Address + 1	1	0	1	1	Immediate Data
		2	Op Code Address+2	1	0	1	1	Offset
	5	3	FFFF	1	1	1	1	Restart Address (LSB)
		4	IX+Offset	1	0	1	1	Operand Data
		5	Op Code Address+3	1	0	1	o	Next Op Code
CLR	_	1	Op Code Address + 1	1	0	1	1	Offset
0211		2	FFFF	1	1	1	1	Restart Address (LSB)
	5	3	IX+Offset	1	o	i	1	Operand Data
	"	4	IX+Offset	0	1	o	1	00
		5	Op Code Address + 2	1	o	1	o	Next Op Code
AIM EIM		1	Op Code Address + 1	1	0	1	1	Immediate Data
OIM		2	Op Code Address + 2	1	0	1	1	Offset
		3	FFFF	1	1	1	1	Restart Address (LSB)
	7	4	IX+Offset	1	0	1	1	Operand Data
		5	FFFF	1	1	1	1	Restart Address (LSB)
		6	IX+Offset	0	1	0	1	New Operand Data
		7	Op Code Address+3	1	0	1	0	Next Op Code

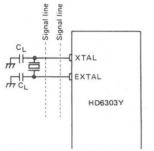
	ss Mode & ructions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
XTEND									
JMP			1	Op Code Address + 1	1	0	1	1	Jump Address (MSB)
		3	2	Op Code Address + 2	1	0	1	1	Jump Address (LSB)
			3	Jump Address	1	0	1	0	Next Op Code
ADC	ADD TST		1	Op Code Address + 1	1	0	1	1	Address of Operand (MSE
AND	BIT	4	2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB
CMP	EOR	4	3	Address of Operand	- 1	0	1	1	Operand Data
LDA SBC	ORA SUB		4	Op Code Address+3	1	0	1	0	Next Op Code
STA			1	Op Code Address + 1	1	0	1	1	Destination Address (MSE
		4	2	Op Code Address + 2	1	0	1	1	Destination Address (LSB
		4	3	Destination Address	0	1	0	1	Accumulator Data
			4	Op Code Address+3	1	0	1	0	Next Op Code
ADDD			1	Op Code Address + 1	1	0	1	1	Address of Operand (MSI
CPX	LDD		2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB
LDS	LDX	5	3	Address of Operand	1	0	1	1	Operand Data (MSB)
SUBD			4	Address of Operand + 1	1	0	1	1	Operand Data (LSB)
			5	Op Code Address+3	1	0	1	0	Next Op Code
STD	STS		1	Op Code Address + 1	1	0	1	1	Destination Address (MSE
STX			2	Op Code Address + 2	1	0	1	1	Destination Address (LSB
		5	3	Destination Address	0	1	0	1	Register Data (MSB)
			4	Destination Address + 1	0	1	0	1	Register Data (LSB)
			5	Op Code Address+3	1	0	1	0	Next Op Code
JSR			1	Op Code Address + 1	1	0	1	1	Jump Address (MSB)
			2	Op Code Address + 2	1	0	1	1	Jump Address (LSB)
		6	3	FFFF	1	1	1	1	Restart Address (LSB)
			4	Stack Pointer	0	1	0	1	Return Address (LSB)
			5	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
			6	Jump Address	1	0	1	0	First Subroutine Op Code
ASL	ASR		1	Op Code Address + 1	1	0	1	1	Address of Operand (MSE
COM	DEC		2	Op Code Address+2	1	0	1	1	Address of Operand (LSB
INC	LSR	6	3	Address of Operand	1	0	1	1	Operand Data
NEG	ROL		4	FFFF	1	1	1	1	Restart Address (LSB)
ROR			5	Address of Operand	0	1	0	1	New Operand Data
			6	Op Code Address+3	1	0	1	0	Next Op Code
CLR			1	Op Code Address + 1	1	0	1	1	Address of Operand (MSE
			2	Op Code Address + 2	1	0	1	1	Address of Operand (LSB
		5	3	Address of Operand	1	0	1	1	Operand Data
			4	Address of Operand	0	1	0	1	00
			5	Op Code Address+3	1	0	1	0	Next Op Code

	Mode & ctions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
MPLIED							-		
ABA	ABX		1	Op Code Address+1	1	0	1	0	Next Op Code
ASL	ASLD			200 EN 1000 STATE				"	THERE OF CODE
ASR	CBA							1	
CLC	CLI				İ				
	CLV								
	DEC								
A CONTRACTOR OF THE STATE OF TH	DEX								
-	INS								
	LSR	1							
	TO 100 100 100 100 100 100 100 100 100 10	1							
	ROL								
	NOP								
	SEC								
SEI	SEV								
TAB	TAP								
TBA	TPA	1 1							
TST	TSX								
TXS		1 1							
DAA	XGDX	2	1	Op Code Address+1	1	0	1	0	Next Op Code
		2	2	FFFF	1	1	1	1	Restart Address (LSB)
PULA	PULB		1	Op Code Address + 1	1	0	1	0	Next Op Code
		3	2	FFFF	1	1	1	1	Restart Address (LSB)
			3	Stack Pointer + 1	1	0	1	1	Data from Stack
PSHA	PSHB		1	Op Code Address+1	1	0	1	1	Next Op Code
			2	FFFF	1	1	1	1	Restart Address (LSB)
		4	3	Stack Pointer	0	1	o	1	Accumulator Data
		1 1	4	Op Code Address + 1	1	0	1	ò	Next Op Code
PULX			1	Op Code Address + 1	1	0	1	0	Next Op Code
· OLX			2	FFFF	i	1	i	1	
		4	3	Stack Pointer + 1	1	o	1	il	Restart Address (LSB)
			4	Stack Pointer + 2	i	0	1	1	Data from Stack (MSB)
PSHX		-	1	Op Code Address + 1	+ †	0	1	1	Data from Stack (LSB)
1 3117			2	FFFF	1	1	9 8	10.1	Next Op Code
		5	3	Stack Pointer	0	1	1	1	Restart Address (LSB)
		5	4	Electrical Contract			0	1	Index Register (LSB)
				Stack Pointer - 1	0	1	0	1	Index Register (MSB)
D.T.O.			5	Op Code Address + 1	1	0	1	0	Next Op Code
RTS			1	Op Code Address + 1	1	0	1	1	Next Op Code
		2000	2	FFFF	1	1	1	1	Restart Address (LSB)
		5	3	Stack Pointer + 1	1	0	1	1	Return Address (MSB)
			4	Stack Pointer + 2	1	0	1	1	Return Address (LSB)
			5	Return Address	1	0	1	0	First Op Code of Return Routi
MUL			1	Op Code Address + 1	1	0	1	0	Next Op Code
			2	FFFF	1	1	1	1	Restart Address (LSB)
			3	FFFF	1	1	1	1	Restart Address (LSB)
		7	4	FFFF	1	1	1	1	Restart Address (LSB)
			5	FFFF	1	1	1	1	Restart Address (LSB)
			6	FFFF	1	1	1	1	Restart Address (LSB)
		1	7	FFFF	1	1	1	1	Restart Address (LSB)

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	RD	WR	LIR	Data Bus
MPLIED								
WAI	T	1	Op Code Address+1	1	0	1	1	Next Op Code
		2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Stack Pointer	0	1	0	1	Return Address (LSB)
		4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
	9	5	Stack Pointer - 2	0	1	0	1	Index Register (LSB)
		6	Stack Pointer - 3	0	1	0	1	Index Register (MSB)
		7	Stack Pointer - 4	0	1	0	1	Accumulator A
		8	Stack Pointer - 5	0	1	0	1	Accumulator B
		9	Stack Pointer - 6	0	1	0	1	Conditional Code Register
RTI		1	Op Code Address + 1	1	0	1	1	Next Op Code
		2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Stack Pointer + 1	1	0	1	1	Conditional Code Register
		4	Stack Pointer + 2	1	0	1	1	Accumulator B
	10	5	Stack Pointer + 3	1	0	1	1	Accumulator A
	10	6	Stack Pointer + 4	1	0	1	1	Index Register (MSB)
		7	Stack Pointer + 5	1	0	1	1	Index Register (LSB)
		8	Stack Pointer + 6	1	0	1	1	Return Address (MSB)
		9	Stack Pointer + 7	1	0	1	1	Return Address (LSB)
		10	Return Address	1	0	1	0	First Op Code of Return Routin
SWI		1	Op Code Address + 1	1	0	1	1	Next Op Code
		2	FFFF	1	1	1	1	Restart Address (LSB)
		3	Stack Pointer	0	1	0	1	Return Address (LSB)
		4	Stack Pointer - 1	0	1	0	1	Return Address (MSB)
		5	Stack Pointer - 2	0	1	0	1	Index Register (LSB)
	12	6	Stack Pointer - 3	0	1	0	1	Index Register (MSB)
		7	Stack Pointer - 4	0	1	0	1	Accumulator A Accumulator B
		8	Stack Pointer - 5	0	1	0	1	Conditional Code Register
		9	Stack Pointer - 6	1	0	1	1	Address of SWI Routine (MSB
		10	Vector Address FFFA	1	0	1	1	Address of SWI Routine (LSB)
		11	Vector Address FFFB	1	0	1	0	First Op Code of SWI Routine
01.0		12	Address of SWI Routine	1	0	1	1	Next Op Code
SLP		1	Op Code Address + 1		1	1	1	Restart Address (LSB)
		2	FFFF			1	1	Restart Address (LSB)
	1							
	4	Sleep						
		3	FFFF	1	1	1	1	Restart Address (LSB)
		4	Op Code Address + 1	1	o	1	o	Next Op Code
		4	op code Address 1 1					
RELATIVE								
BCC BCS	-	1	Op Code Address + 1	1	0	1	1	Branch Offset
BEQ BGE	3	2	FFFF	1	1	1	1	Restart Address (LSB)
BGT BHI		3	Branch Address·····Test="1"	1	0	1	0	First Op Code of Branch Routi
BLE BLS		"	Op Code Address + 1 ··· Test = "0"				0	Next Op Code
BLT BMT								
BNE BPL								
BRA BRN		1		1				
BVC BVS	-	4	On Code Address 14	4	^	4	4	04
		1 2	Op Code Address + 1	1	0	1	1	Offset
BVC BVS	-	2	FFFF	1	1	1	1	Restart Address (LSB)
BVC BVS	5					220		

PRECAUTION TO THE BOARD DESIGN OF OSCILLA-TION CIRCUIT

As shown in Fig. 31, there is a case that the cross talk disturbs the normal oscillation if signal lines are put near the oscillation circuit. When designing a board, pay attention to this. Crystal and C_L must be put as near the HD6303Y as possible.



Do not use this kind of print board design.

Figure 31 Precaution to the boad design of oscillation circuit

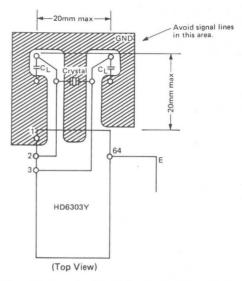


Figure 32 Example of Oscillation Circuits in Board Design

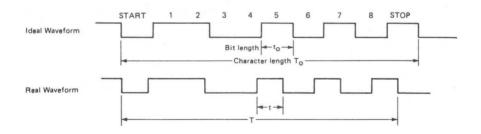
■ RECEIVE MARGIN OF THE SCI

Receive margin of the SCI contained in the $HD6303\,Y$ is shown in Table 18.

Note: SCI = Serial Communication Interface

Table 18

	Bit distortion tolerance (t-to) /to	Character distortion tolerance (T-To) /To
HD6303Y	±43.7%	±4.37%



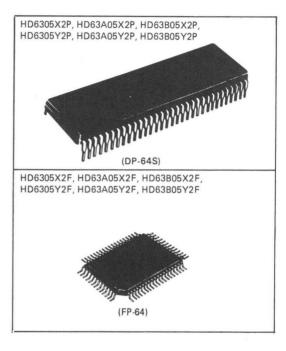
HD6305X2,HD63A05X2,HD63B05X2 HD6305Y2,HD63A05Y2,HD63B05Y2 CMOS MPU (Micro Processing Unit)

The HD6305X2 and the HD6305Y2 are CMOS 8-bit micro processing units which contains a CPU, a clock generator, RAM, I/O terminals, two timers, and a Serial Communication Interface (SCI). The memory space is expandable up to 16k bytes externally.

The HD6305X2 and the HD6305Y2 provides the equivalent functions as the HD6305X0 and the HD6305Y0 except for the number of I/O terminals.

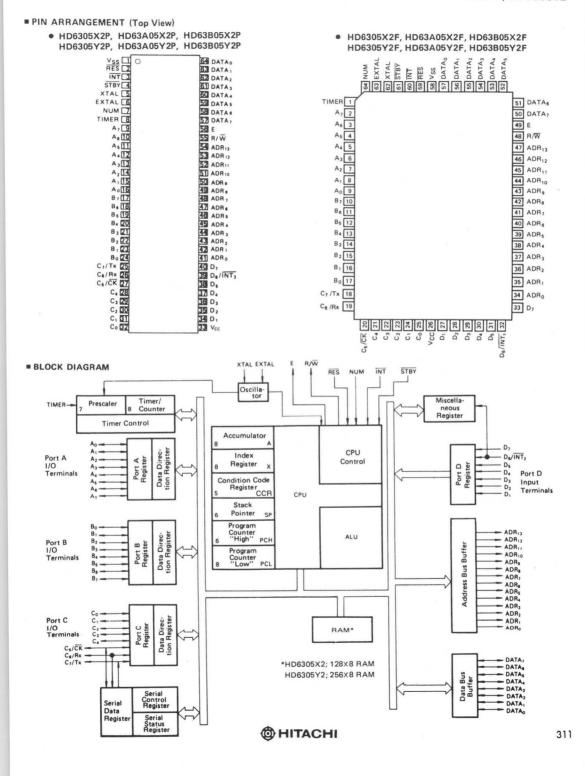
■ HARDWARE FEATURES

- 8-bit based MPU
- 128-bytes of RAM (HD6305X2), 256-bytes of RAM (HD6305Y2)
- A total of 31 terminals, including 24 I/O's, 7 inputs
- Two timers
 - 8-bit timer with a 7-bit prescaler (programmable prescaler; event counter)
 - 15-bit timer (multiplexed with the SCI clock divider)
- On-chip serial interface circuit (synchronized with clock)
- Six interrupts (two external, two timer, one serial and one software)
- Low power dissipation modes
- Wait In this mode, the clock oscillator is on and the CPU halts but the timer/serial/interrupt function is operatable.
- Stop.... In this mode, the clock stops but the RAM data, I/O status and registers are held.
- Standby. In this mode, the clock stops, the RAM data is held, and the other internal condition is reset.
- Minimum instruction cycle time
- HD6305X2/Y2 1 μ s (f = 1 MHz)
- $HD63A05X2/Y2...0.67\mu s$ (f = 1.5 MHz)
- HD63B05X2/Y2 . . . 0.5 μ s (f = 2 MHz)
- Wide operating range
 - $V_{CC} = 3 \text{ to 6V (f = 0.1 to 0.5 MHz)}$
 - HD6305X2/Y2 $f = 0.1 \text{ to } 1 \text{ MHz } (V_{CC} = 5V \pm 10\%)$
- HD63A05X2/Y2 f = 0.1 to 1.5 MHz(V_{CC} = 5V ± 10%)
- HD63B05X2/Y2 f = 0.1 to 2 MHz ($V_{CC} = 5V \pm 10\%$)
- System development fully supported by an evaluation kit
- Compatibility with the HD6305X0 and the HD6305Y0 except for external memory expansion and the number of I/O terminals.



■ SOFTWARE FEATURES

- Similar to HD6800
- Byte efficient instruction set
- Powerful bit manipulation instructions (Bit Set, Bit Clear, and Bit Test and Branch usable for all RAM bits and all I/O terminals)
- · A variety of interrupt operations
- Index addressing mode useful for table processing
- · A variety of conditional branch instructions
- Ten powerful addressing modes
- All addressing modes adaptable to RAM, and I/O instructions
- Three new instructions, STOP, WAIT and DAA, added to the HD6805 family instruction set



■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{CC}	-0.3 ~ +7.0	V
Input Voltage	V _{in}	$-0.3 \sim V_{CC} + 0.3$	V
Operating Temperature	Topr	0~+70	°C
Storage Temperature	T _{stg}	-55 ∼ +150	°C

[NOTE] These products have a protection circuit in their input terminals against high electrostatic voltage or high electric fields. Notwithstanding, be careful not to apply any voltage higher than the absolute maximum rating to these high input impedance circuits. To assure normal operation, we recommended V_{1n} , V_{out} ; $V_{SS} \subseteq (V_{in} \text{ or } V_{out}) \subseteq V_{CC}$.

■ ELECTRICAL CHARACTERISTICS

DC CHARACTERISTICS (V_{CC} = 5.0V ±10%, V_{SS} = 0V, Ta = 0 \sim +70°C, unless otherwise noted.)

	Item	Symbol	Test Condition	min	typ	max	Unit
	RES, STBY			V _{CC} -0.5	_	V _{cc} +0.3	
Input "High" Voltage	EXTAL	ViH		V _{CC} x0.7	_	V _{CC} +0.3	V
	Other Inputs			2.0	_	V _{CC} +0.3	
Input "Low" Voltage	All Inputs	VIL		-0.3	-	0.8	V
O. 44 // Ul-// \/ - 4	All Outputs		I _{OH} = -200μA	2.4	_	-	V
Output "High" Voltage	All Outputs	V_{OH} $I_{OH} = -10\mu A$		V _{CC} -0.7	-	-	V
Output "Low" Voltage	All Outputs	VoL	I _{OL} = 1.6mA	_	_	0.55	V
Input Leakage Current	TIMER, \overline{INT} , $D_1 \sim D_7$, \overline{STBY}	I _{IL}		-	_	1.0	μА
Three-state Current	$A_0 \sim A_7, B_0 \sim B_7,$ $C_0 \sim C_7, ADR_0 \sim ADR_{13}^*,$ $DATA_0 \sim DATA_7, E^*, R/W^*$	I _{TSI}	$Vin = 0.5 \sim V_{CC} - 0.5$	-	-	1.0	μΑ
	Operating			-	5	10	mA
	Wait	1	f = 1MHz***	-	2	5	mA
Current Dissipation**	Stop	Icc	1 - TIVITIZ	-	2	10	μΑ
	Standby			-	2	10	μΑ
Input Capacitance	All Terminals	Cin	f = 1MHz, Vin = 0V	-	_	12	pF

^{*} Only at standby

• AC CHARACTERISTICS (V_{CC} = $5.0V\pm10\%$, V_{SS} = 0V, Ta = $0\sim+70^{\circ}$ C, unless otherwise noted.)

Item	Symbol	Test		06305X			63A05			63B05		Unit
		Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Cycle Time	t _{cyc}		1	-	10	0.666	-	10	0.5	_	10	μs
Enable Rise Time	t _{Er}	1	_	-	20	_	_	20	_	_	20	ns
Enable Fall Time	t _{Ef}		-	-	20	-	-	20	-	-	20	ns
Enable Pulse Width("High" Level)	PW _{EH}	1 1	450	-	-	300	-	_	220	-	_	ns
Enable Pulse Width("Low" Level)	PWEL	1	450	-	-	300	_	_	220	-	_	ns
Address Delay Time	t _{AD}	Fig. 1	-	-	250	-	_	190	-	-	180	ns
Address Hold Time	t _{AH}	1	40	_	-	30	-	_	20	-	_	nș
Data Delay Time	t _{DW}	1	-	-	200	_	_	160	_	_	120	ns
Data Hold Time (Write)	t _{HW}		40	_	-	30	_	_	20	-	_	ns
Data Set-up Time (Read)	t _{DSR}		80	-	_	60	_	-	50	_	-	ns
Data Hold Time (Read)	t _{HR}		0	-	_	0	_	-	0	-	-	ns

^{***} V_{IH} min = V_{CC}-1.0V, V_{IL} max = 0.8V, all output and RES terminal are open and penetrate current of input are not included.

*** The value at f = xMHz is given by using.

I_{CC} (f = xMHz) = I_{CC} (f = 1MHz) x x

• PORT TIMING (V_{CC} = 5.0V±10%, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

Item	Symbol	Test	HD630	5X2, HD6	305Y2	HD63A05X2,		05X2, HD63A05Y2		HD63B05X2, HD63B05Y2		
rtem	Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Port Data Set-up Time (Port A, B, C, D)	t _{PDS}	F: 0	200	-	-	200	_	_	200	-	_	ns
Port Data Hold Time (Port A, B, C, D)	t _{PDH}	Fig. 2	200	_	_	200	<u></u>	-	200	-	-	ns
Port Data Delay Time (Port A, B, C)	t _{PDW}	Fig. 3	_	_	300	_	_	300	_	_	300	ns

• CONTROL SIGNAL TIMING (V_{CC} = 5.0V ±10%, V_{SS} = 0V, Ta = 0 \sim +70°C, unless otherwise noted.)

Item	Symbol	Test	HD630	5X2, HD6	305Y2	HD63A0	5X2, HD6	2, HD63A05Y2		HD63B05X2, HD63B05Y2		
rtem	Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
INT Pulse Width	t _{IWL}		t _{cyc} +250	-	-	t _{cyc} +200	-	-	t _{cyc} +200	-	-	ns
INT ₂ Pulse Width	t _{IWL2}		t _{cyc} +250	_	_	t _{cyc} +200	-	-	t _{cyc} +200	_	-	ns
RES Pulse Width	t _{RWL}		5	_	_	5	_	-	5	_	_	t _{cyc}
Control Set-up Time	t _{CS}	Fig. 5	250	_	-	250	-	-	250	-	-	ns
Timer Pulse Width	t _{TWL}		t _{cyc} +250	_	-	t _{cyc} +200	-	-	t _{cyc} +200	-	-	ns
Oscillation Start Time (Crystal)	tosc	Fig.5, Fig.20*	_	_	20	_	-	20	_	_	20	ms
Reset Delay Time	t _{RHL}	Fig. 19	80	_	-	80	-	-	80	-	-	ms

^{*} C_L = 22pF ±20%, R_s = 60Ω max.

• SCI TIMING (V_{CC} = 5.0V±10%, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

Item	Symbol	Test	HD630	ID6305X2, HD6305Y2			HD63A05X2, HD63A05Y2			HD63B05X2, HD63B05Y2		
rtem	Symbol	Condition	min	typ	max	min	typ	max	min	typ	max	Unit
Clock Cycle	t _{Scyc}		1	-	32768	0.67	_	21845	0.5	-	16384	μs
Data Output Delay Time	t _{TXD}	Fig. 6,	-	1-1	250	-	_	250	-	_	250	ns
Data Set-up Time	t _{SRX}	Fig. 7	200	-	-	200	-	-	200	-	-	ns
Data Hold Time	t _{HRX}		100	-	-	100	-	-	100	-	-	ns

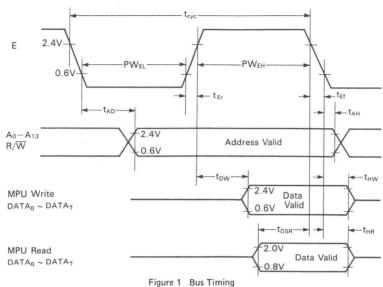


Figure 1 Bus Timin

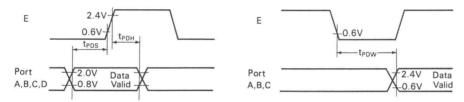


Figure 2 Port Data Set-up and Hold Times (MPU Read)

Figure 3 Port Data Delay Time (MPU Write)

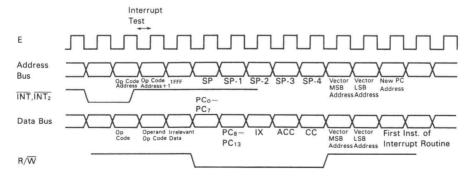


Figure 4 Interrupt Sequence



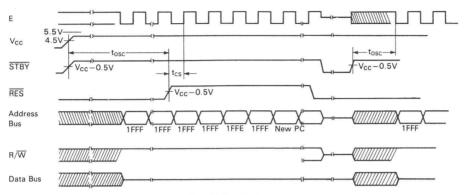


Figure 5 Reset Timing

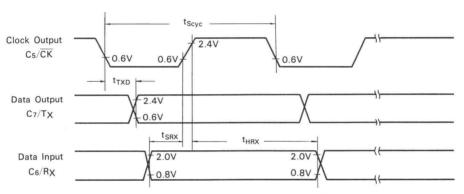


Figure 6 SCI Timing (Internal Clock)

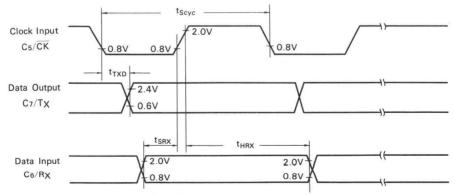
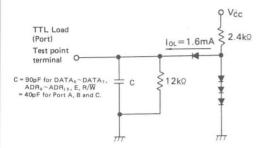


Figure 7 SCI Timing(External Clock)



[NOTES] 1. The load capacitance includes stary capacitance caused by the probe, etc.

2. All diodes are 1S2074 (H).

Figure 8 Test Load

■ DESCRIPTION OF TERMINAL FUNCTIONS

The input and output signals of the MPU are described here.

·Vcc, Vss

Voltage is applied to the MPU through these two terminals. V_{CC} is 5.0V \pm 10%, while V_{SS} is grounded.

• INT, INT2

External interrupt request inputs to the MPU. For details, refer to "INTERRUPT". The $\overline{\text{INT}_2}$ terminal is also used as the port D₆ terminal.

• XTAL, EXTAL

These terminals provide input to the on-chip clock circuit. A crystal oscillator (AT cut, 2.0 to 8.0 MHz) or ceramic filter is connected to the terminal. Refer to "INTERNAL OSCILLATOR" for using these input terminals.

• TIMER

This is an input terminal for event counter. Refer to "TIMER" for details.

• RES

Used to reset the MPU. Refer to "RESET" for details.

• NUM

This terminal is not for user application. This terminal should be connected to V_{SS} .

• Enable (E)

This output terminal supplies E clock. Output is a single-phase, TTL compatible and 1/4 crystal oscillation frequency or 1/4 external clock frequency. It can drive one TTL load and a 90 pF condenser.

• Read/Write (R/W)

This TTL compatible output signal indicates to peripheral and memory devices whether MPU is in Read ("High"), or in Write ("Low"). The normal standby state is Read ("High"). Its output can drive one TTL load and a 90pF condenser.

• Data Bus (DATA₀ - DATA₇)

This TTL compatible three-state buffer can drive one TTL load and $90 \mathrm{pF}.$

• Address Bus (ADR₀ -ADR₁₃)

Each terminal is TTL compatible and can drive one TTL load and 90pF.

Ports A, B, C (A₀ - A₇, B₀ - B₇, C₀ - C₇)

These 24 terminals consist of three 8-bit I/O ports (A, B, C). Each of them can be used as an input or output terminal on a bit through program control of the data direction register. For details, refer to "I/O PORTS."

Port D (D₁ - D₂)

These seven input-only terminals are TTL or CMOS compatible. Of the port $D^{\prime}s$, D_6 is also used as $\overline{INT_2}$. If D_6 is used as a port, the $\overline{INT_2}$ interrupt mask bit of the miscellaneous register must be set to "1" to prevent an $\overline{INT_2}$ interrupt from being accidentally accepted.

• STBY

This terminal is used to place the MPU into the standby mode. With \overline{STBY} at "Low" level, the oscillation stops and the internal condition is reset. For details, refer to "Standby Mode."

The terminals described in the following are I/O pins for serial communication interface (SCI). They are also used as ports C_5 , C_6 and C_7 . For details, refer to "SERIAL COMMUNICATION INTERFACE."

• CK (Cs)

Used to input or output clocks for serial operation.

• Rx (C6)

Used to receive serial data.

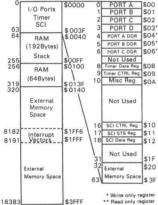
• Tx (C7)

Used to transmit serial data.

■MEMORY MAP

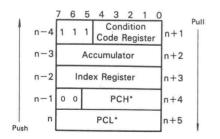
The memory map of the MPU is shown in Fig. 9. During interrupt processing, the contents of the CPU registers are saved into the stack in the sequence shown in Fig. 10. This saving begins with the lower byte (PCL) of the program counter. Then the value of the stack pointer is decremented and the higher byte (PCH) of the program counter, index register (X), accumulator (A) and condition code register (CCR) are stacked in that order. In a subroutine call, only the contents of the program counter (PCH and PCL) are stacked.





(b) HD6305Y2

Figure 9 Memory Maps of MPU



* In a subroutine call, only PCL and PCH are stacked.

Figure 10 Sequence of Interrupt Stacking

REGISTERS

There are five registers which the programmer can operate.

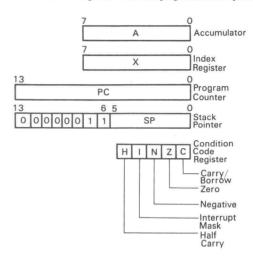


Figure 11 Programming Model

Accumulator (A)

This accumulator is a general purpose 8-bit register which holds operands or the result of arithmetic operation or data processing.

• Index Register (X)

The index register is an 8-bit register, and is used for index addressing mode. Each of the addresses contained in the register consists of 8 bits which, combined with an offset value, provides an effective address.

In the case of a read/modify/write instruction, the index register can be used like an accumulator to hold operation data or the result of operation.

If not used in the index addressing mode, the register can be used to store data temporarily.

Program Counter (PC)

The program counter is a 14-bit register that contains the address of the next instruction to be executed.

Stack Pointer (SP)

The stack pointer is a 14-bit register that indicates the address of the next stacking space. Just after reset, the stack pointer is set at address \$00FF. It is decremented when data is pushed, and incremented when pulled. The upper 8 bits of the stack pointer are fixed to 00000011. During the MPU being reset or during a reset stack pointer (RSP) instruction, the pointer is set to address \$00FF. Since a subroutine or interrupt can use space up to address \$00C1 for stacking, the subroutine can be used up to 31 levels and the interrupt up to 12 levels.

• Condition Code Register (CCR)

The condition code register is a 5-bit register, each bit indicating the result of the instruction just executed. The bits can be individually tested by conditional branch instruc-

tions. The CCR bits are as follows:

Half Carry (H): Used to indicate that a carry occurred between bits 3 and 4 during an arithmetic operation (ADD, ADC).

Interrupt (I): Setting this bit causes all interrupts, except a software interrupt, to be masked. If an interrupt occurs with the bit I set, it is latched. It will be processed the instant the interrupt mask bit is reset. (More specifically, it will enter the interrupt processing routine after the instruction following the CLI has been executed.)

Negative (N):

Negative (N): Used to indicate that the result of the most recent arithmetic operation, logical operation or data processing is negative (bit 7 is logic "1").

Zero (Z): Used to indicate that the result of the most recent arithmetic operation, logical operation or data processing is zero.

Carry/ Represents a carry or borrow that occurred Borrow (C): in the most recent arithmetic operation. This bit is also affected by the Bit Test and Branch instruction and a Rotate instruction.

■ INTERRUPT

There are six different types of interrupt: external interrupts $(\overline{INT}, \overline{INT_2})$, internal timer interrupts (TIMER, TIMER₂), serial interrupt (SCI) and interrupt by an instruction (SWI).

Of these six interrupts, the $\overline{INT_2}$ and TIMER or the SCI and TIMER₂ generate the same vector address, respectively.

When an interrupt occurs, the program in progress stops and the then CPU status is saved onto the stack. And then, the interrupt mask bit (I) of the condition code register is set and the start address of the interrupt processing routine is obtained from a particular interrupt vector address. Then the interrupt routine starts from the start address. System can exit from the interrupt routine by an RTI instruction. When this instruction is executed, the CPU status before the interrupt (saved onto the stack) is pulled and the CPU restarts the sequence with the instruction next to the one at which the interrupt occurred. Table 1 lists the priority of interrupts and their vector addresses.

Table 1 Priority of Interrupts

Interrupt	Priority	Vector Address
RES	1	\$1FFE, \$1FFF
SWI	2	\$1FFC, \$1FFD
ĪNT	3	\$1FFA, \$1FFB
TIMER/INT ₂	4	\$1FF8, \$1FF9
SCI/TIMER ₂	5	\$1FF6, \$1FF7

A flowchart of the interrupt sequence is shown in Fig. 12. A block diagram of the interrupt request source is shown in Fig. 13.

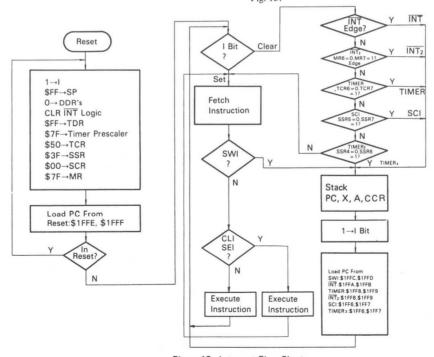


Figure 12 Interrupt Flow Chart



 $\overline{\text{INT}}$ are edge trigger inputs. At the falling edge of each input, an interrupt request is generated, and latched. The $\overline{\text{INT}}$ interrupt request is automatically cleared if jumping is made to $\overline{\text{INT}}$ processing routine. Meanwhile, the $\overline{\text{INT}}$ request is cleared if "0" is written in bit 7 of the miscellaneous register.

For the external interrupts (\overline{INT} , $\overline{INT2}$), internal timer interrupts (TIMER, TIMER2) and serial interrupt (SCI), each interrupt request is held, but not processed, if the I bit of the condition code register is set. Immediately after the I bit is cleared, the corresponding interrupt processing starts according to the priority.

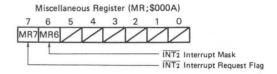
The $\overline{\text{INT}_2}$ interrupt can be masked by setting bit 6 of the miscellaneous register; the TIMER interrupt by setting bit 6 of the timer control register; the SCI interrupt by setting bit 5 of the serial status register; and the TIMER2 interrupt by setting bit 4 of the serial status register.

The status of the \overline{INT} terminal can be tested by a BIL or BIH instruction. The \overline{INT} falling edge detector circuit and its latching circuit are independent of testing by these instructions. This is also true with the status of the $\overline{INT_2}$ terminal.

• Miscellaneous Register (MR; \$000A)

The interrupt vector address for the external interrupt $\overline{INT2}$ is the same as that for the TIMER interrupt, as shown in Table 1. For this reason, a special register called the miscellaneous register (MR; \$000A) is available to control the $\overline{INT2}$ interrupts.

Bit 7 of this register is the $\overline{INT2}$ interrupt request flag. When the falling edge is detected at the $\overline{INT2}$ terminal, "1" is set in bit 7. Then the software in the interrupt routine (vector addresses: \$1FF8, \$1FF9) checks bit 7 to see if it is $\overline{INT2}$ interrupt. Bit 7 can be reset by software.



Miscellaneous Register (MR; \$000A)

Bit 6 is the $\overline{\text{INT}_2}$ interrupt mask bit. If this bit is set to "1", then the $\overline{\text{INT}_2}$ interrupt is disabled. Both read and write are possible with bit 7 but "1" cannot be written in this bit by software. This means that an interrupt request by software is impossible.

When reset, bit 7 is cleared to "0" and bit 6 is set to "1".

TIMER

Figure 14 shows a MPU timer block diagram. The timer data register is loaded by software and, upon receipt of a clock input, begins to count down. When the timer data

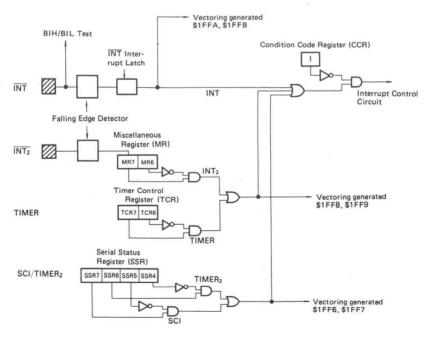


Figure 13 Interrupt Request Generation Circuitry

register (TDR) becomes "0", the timer interrupt request bit (bit 7) in the timer control register is set. In response to the interrupt request, the CPU saves its status into the stack and fetches timer interrupt routine address from addresses \$1FF8 and \$1FF9 and execute the interrupt routine. The timer interrupt can be masked by setting the timer interrupt mask bit (bit 6) in the timer control register. The mask bit (I) in the condition code register can also mask the timer interrupt.

The source clock to the timer can be either an external signal from the timer input terminal or the internal E signal (the oscillator clock divided by 4). If the E signal is used as the source, the clock input can be gated by the input to the timer input terminal.

Once the timer count has reached "0", it starts counting down with "\$FF". The count can be monitored whenever desired by reading the timer data register. This permits the program to know the length of time having passed after the occurrence of a timer interrupt, without disturbing the contents of the counter.

When the MPU is reset, both the prescaler and counter are initialized to logic "1". The timer interrupt request bit (bit 7) then is cleared and the timer interrupt mask bit (bit 6) is set.

To clear the timer interrupt request bit (bit 7), it is necessary to write "0" in that bit.

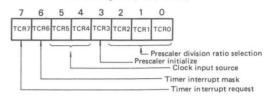
TCR7	Timer interrupt request
0	Absent
1	Present
TCR6	Timer interrupt mask
0	Enabled
	Disabled

• Timer Control Register (TCR: \$0009)

Selection of a clock source, selection of a prescaler frequency division ratio, and a timer interrupt can be controlled by the timer control register (TCR; \$0009).

For the selection of a clock source, any one of the four modes (see Table 2) can be selected by bits 5 and 4 of the timer control register (TCR).

Timer Control Register (TCR: \$0009)



After reset, the TCR is initialized to "E under timer terminal control" (bit 5 = 0, bit 4 = 1). If the timer terminal is "1", the counter starts counting down with "\$FF" immediately after reset.

When "1" is written in bit 3, the prescaler is initialized. This bit always shows "0" when read.

Table 2 Clock Source Selection

TC	R	Clock input source	
Bit 5	Bit 4	Clock input source	
0	0	Internal clock E	
0	1	E under timer terminal control	
1	0	No clock input (counting stopped)	
1	1	Event input from timer terminal	

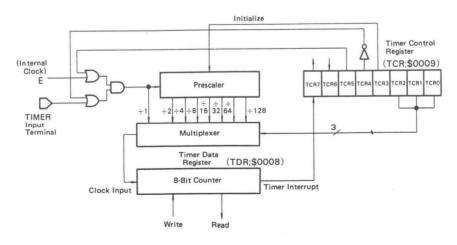


Figure 14 Timer Block Diagram



A prescaler division ratio is selected by the combination of three bits (bits 0, 1 and 2) of the timer control register (see Table 3). There are eight different division ratios: $\div 1$, $\div 2$, $\div 4$, $\div 8$, $\div 16$, $\div 32$, $\div 64$ and $\div 128$. After reset, the TCR is set to the $\div 1$ mode.

Table 3 Prescaler Division Ratio Selection

	TCR		
Bit 2	Bit 1	Bit 0	Prescaler division ratio
0	0	0	÷1:
0	0	1	÷2
0	1	0	÷4
0	1	1	÷8
1	0	0	÷16
1	0	1	÷32
1	1	0	÷64
1	1	1	÷128

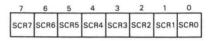
A timer interrupt is enabled when the timer interrupt mask bit is "0", and disabled when the bit is "1". When a timer interrupt occurs, "1" is set in the timer interrupt request bit. This bit can be cleared by writing "0" in that bit.

SERIAL COMMUNICATION INTERFACE (SCI)

This interface is used for serial transmission or reception of 8-bit data. Sixteen transfer rates are available in the range from 1 μ s to approx. 32 ms (for oscillation at 4 MHz).

The SCI consists of three registers, one eighth counter and one prescaler. (See Fig. 15.) SCI communicates with the CPU via the data bus, and with the outside world through bits 5, 6 and 7 of port C. Described below are the operations of each register and data transfer.

•SCI Control Register (SCR; \$0010)



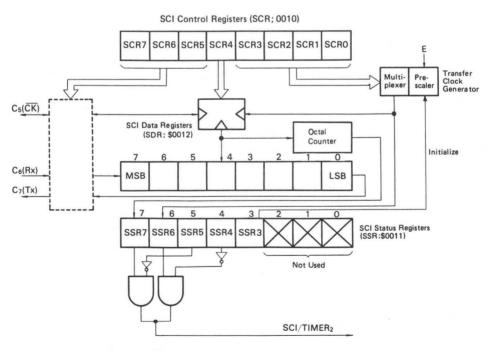


Figure 15 SCI Block Diagram

SCR7	C ₇ terminal
0	Used as I/O terminal (by DDR).
1	Serial data output (DDR output)

SCR6	C ₆ terminal
0	Used as I/O terminal (by DDR).
1	Serial data input (DDR input)

SCR5	SCR4	Clock source	C _s terminal
0	0	-	Used as I/O terminal (by
0	1	-	DDR).
1	0	Internal	Clock output (DDR output)
1	1	External	Clock input (DDR input)

Bit 7 (SCR7)

When this bit is set, the DDR corresponding to the C_7 becomes "1" and this terminal serves for output of SCI data. After reset, the bit is cleared to "0".

Bit 6 (SCR6)

When this bit is set, the DDR corresponding to the C_6 becomes "0" and this terminal serves for input of SCI data. After reset, the bit is cleared to "0".

Bits 5 and 4 (SCR5, SCR4)

These bits are used to select a clock source. After reset, the bits are cleared to "0".

Bits 3 - 0 (SCR3 - SCR0)

These bits are used to select a transfer clock rate. After reset, the bits are cleared to "0".

0000	CODO	CODA	CORO	Transfer	clock rate
SCR3	SCR2	SCR1	SCR0	4.00 MHz	4.194 MHz
0	0	0	0	1 μs	0.95 μs
0	0	0	1	2 μs	1.91 μs
0	0	1	0	4 μs	3.82 µs
0	0	1	1	8 μs	7.64 µs
2		5	>	5	>
1	1	1	1	32768 μs	1/32 s

•SCI Data Register (SDR; \$0012)

A serial-parallel conversion register that is used for transfer of data.

•SCI Status Register (SSR; \$0011)

7	6	5	4	3	2	1_	0
SSR7	SSR6	SSR5	SSR4	SSR3	\boxtimes	\times	\times

Bit 7 (SSR7)

Bit 7 is the SCI interrupt request bit which is set upon completion of transmitting or receiving 8-bit data. It is cleared when reset or data is written to or read from the SCI data register with the SCR5="1". The bit can also be cleared by writing "0" in it.

Bit 6 (SSR6)

Bit 6 is the TIMER₂ interrupt request bit. TIMER₂ is multiplexed with the serial clock generator, and SSR6 is set each time the internal transfer clock falls. When reset, the bit is cleared. It also be cleared by writing "0" in it. (For details, see TIMER₂.)

Bit 5 (SSR5)

Bit 5 is the SCI interrupt mask bit which can be set or cleared by software. When it is "1", the SCI interrupt (SSR7) is masked. When reset, it is set to "1".

Bit 4 (SSR4)

Bit 4 is the TIMER₂ interrupt mask bit which can be set or cleared by software. When the bit is "1", the TIMER₂ interrupt (SSR6) is masked. When reset, it is set to "1".

Bit 3 (SSR3)

When "1" is written in this bit, the prescaler of the transfer clock generator is initialized. When read, the bit always is "0".

Bits 2 - 0Not used.

SSR7	SCI interrupt request
0	Absent
1	Present

SSR6	TIMER ₂ interrupt request
0	Absent
1	Present

00110	oor interrupt mask	
0	Enabled	
1	Disabled	
SSR4	TIMED	
	IIMER interrupt mask	
33114	TIMER ₂ interrupt mask	

SCI interrunt mask

Disabled

Data Transmission

CCDE

By writing the desired control bits into the SCI control registers, a transfer rate and a source of transfer clock are determined and bits 7 and 5 of port C are set at the serial data output terminal and the serial clock terminal, respectively. The transmit data should be stored from the accumulator or index register into the SCI data register. The data written in the SCI data register is output from the C_7/T_X terminal, starting with the LSB, synchronously with the falling edge of the serial clock. (See Fig. 16.) When 8 bit of

data have been transmitted, the interrupt request bit is set in bit 7 of the SCI status register with the rising edge of the last serial clock. This request can be masked by setting bit 5 of the SCI status register. Once the data has been sent, the 8th bit data (MSB) stays at the C $_7/\mathrm{Tx}$ terminal. If an external clock source has been selected, the transfer rate determined by bits 0-3 of the SCI control register is ignored, and the C_5/\overline{CK} terminal is set as input. If the internal clock has been selected, the C_5/\overline{CK} terminal is set as output and clocks are output at the transfer rate selected by bits 0-3 of the SCI control register.

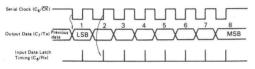


Figure 16 SCI Timing Chart

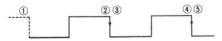
Data Reception

By writing the desired control bits into the SCI control register, a transfer rate and a source of transfer clock are determined and bit 6 and 5 of port C are set at the serial data input terminal and the serial clock terminal, respectively. Then dummy-writing or -reading the SCI data register, the system is ready for receiving data. (This procedure is not needed after reading the subsequent received data. It must be taken after reset and after not reading the subsequent received data.)

The data from the C_6/Rx terminal is input to the SCI data register synchronously with the rising edge of the serial clock (see Fig. 16). When 8 bits of data have been received, the interrupt request bit is set in bit 7 of the SCI status register. This request can be masked by setting bit 5 of the SCI status register. If an external clock source have been selected, the transfer rate determined by bits 0-3 of the SCI control register is ignored and the data is received synchronously with the clock from the C_5/\overline{CK} terminal. If the internal clock has been selected, the C_5/\overline{CK} terminal is set as output and clocks are output at the transfer rate selected by bits 0-3 of the SCI control register.

• TIMER₂

The SCI transfer clock generator can be used as a timer. The clock selected by bits 3-0 of the SCI control register $(4\mu s - approx. 32 \text{ ms} (\text{for oscillation at 4 MHz}))$ is input to bit 6 of the SCI status register and the TIMER2 interrupt request bit is set at each falling edge of the clock. Since interrupt requests occur periodically, TIMER2 can be used as a reload counter or clock.



- :Transfer clock generator is reset and mask bit (bit 4 of SCI status register) is cleared.
- 2, 4 : TIMER2 interrupt request
- 3, 5 : TIMER2 interrupt request bit cleared

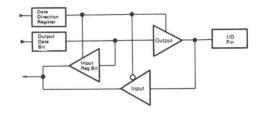
TIMER₂ is multiplexed with the SCI transfer clock generator. If wanting to use TIMER₂ independently of the SCI, specify "External" (SCR5 = 1, SCR4 = 1) as the SCI clock source.

If "Internal" is selected as the clock source, reading or writing the SDR causes the prescaler of the transfer clock generator to be initialized.

■I/O PORTS

There are 24 input/output terminals (ports A, B, C). Each I/O terminal can be selected for either input or output by the data direction register. More specifically, an I/O port will be input if "0" is written in the data direction register, and output if "1" is written in the data direction register, Port A, B or C reads latched data if it has been programmed as output, even with the output level being fluctuated by the output load. (See Fig. 17.)

When reset, the data direction register and data register go to "0" and all the input/output terminals are used as input.



Bit of data direction register	Bit of output data	Status of output	Input to CPU
1	0	0	0
1	1	1	1
0	Х	3-state	Pin

Figure 17 Input/Output Port Diagram

Seven input-only terminals are available (port D). Writing to an input terminal is invalid.

All input/output terminals and input terminals are TTL compatible and CMOS compatible in respect of both input and output.

If I/O ports or input ports are not used, they should be connected to VSS via resistors. With none connected to these terminals, there is the possibility of power being consumed despite that they are not used.

RESET

The MPU can be reset either by external reset input (\overline{RES}) or power-on reset. (See Fig. 18.) On power up, the reset input must be held "Low" for at least υ_{OSC} to assure that the internal oscillator is stabilized. A sufficient time of delay can be obtained by connecting a capacitance to the \overline{RES} input as shown in Fig. 19.

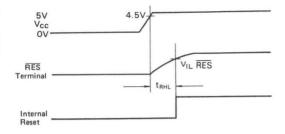


Figure 18 Power On and Reset Timing

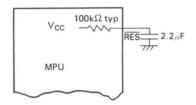


Figure 19 Input Reset Delay Circuit

INTERNAL OSCILLATOR

The internal oscillator circuit is designed to meet the

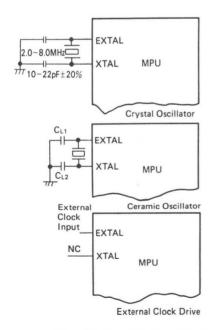


Figure 20 Internal Oscillator Circuit

requirement for minimum external configurations. It can be driven by connecting a crystal (AT cut 2.0 - 8.0MHz) or ceramic oscillator between pins 5 and 6 depending on the required oscillation frequency stability.

Three different terminal connections are shown in Fig. 20. Figs. 21, and 22 illustrate the specifications and typical arrange-

ment of the crystal, respectively.

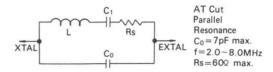
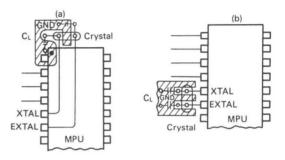


Figure 21 Parameters of Crystal



[NOTE] Use as short wirings as possible for connection of the crystal with the EXTAL and XTAL terminals. Do not allow these wirings to cross others.

Figure 22 Typical Crystal Arrangement

LOW POWER DISSIPATION MODE

The HD6305X2 and the HD6305Y2 provides three low power dissipation modes: wait, stop and standby.

Wait Mode

When WAIT instruction being executed, the MPU enters into the wait mode. In this mode, the oscillator stays active but the internal clock stops. The CPU stops but the peripheral functions — the timer and the serial communication interface — stay active. (NOTE: Once the system has entered the wait mode, the serial communication interface can no longer be retriggered.) In the wait mode, the registers, RAM and I/O terminals hold their condition just before entering into the wait mode.

The escape from this mode can be done by interrupt (INT, TIMER/INT2 or SCI/TIMER2), RES or STBY. The RES resets the MPU and the STBY brings it into the standby mode. (This will be mentioned later.)

When interrupt is requested to the CPU and accepted, the wait mode escapes, then the CPU is brought to the operation mode and vectors to the interrupt routine. If the interrupt is masked by the I bit of the condition code register, after releasing from the wait mode the MPU executes the instruction next to the WAIT. If an interrupt other than the \overline{INT} (i.e., TIMER/ $\overline{INT2}$ or SCI/TIMER₂) is masked by the timer control

register, miscellaneous register or serial status register, there is no interrupt request to the CPU, so the wait mode cannot be released.

Fig. 23 shows a flowchart for the wait function.

Stop Mode

When STOP instruction being executed, MPU enters into the stop mode. In this mode, the oscillator stops and the CPU and peripheral functions become inactive but the RAM, registers and I/O terminals hold their condition just before entering into the stop mode.

The escape from this mode can be done by an external interrupt (INT or INT₂), RES or STBY. The RES resets the MPU and the STBY brings into the standby mode.

When interrupt is requested to the CPU and accepted, the stop mode escapes, then the CPU is brought to the operation mode and vectors to the interrupt routine. If the interrupt is masked by the I bit of the condition code register, after releasing from the stop mode, the MPU executes the instruction next to the STOP. If the $\overline{\text{INT}_2}$ interrupt is masked by the miscellaneous register, there is no interrupt request to the MPU, so the stop mode cannot be released.

Fig. 24 shows a flowchart for the stop function. Fig. 25 shows a timing chart of return to the operation mode from the stop mode.

For releasing from the stop mode by an interrupt, oscillation starts upon input of the interrupt and, after the internal delay time for stabilized oscillation, the CPU becomes active. For restarting by \overline{RES} , oscillation starts when the \overline{RES} goes "0" and the CPU restarts when the \overline{RES} goes "1". The duration of \overline{RES} ="0" must exceed t_{osc} to assure stabilized oscillation.

Standby Mode

The MPU enters into the standby mode when the STBY terminal goes "Low". In this mode, all operations stop and the internal condition is reset but the contents of the RAM are hold. The I/O terminals turn to high-impedance state. The standby mode should escape by bringing STBY "High". The CPU must be restarted by reset. The timing of input signals at the RES and STBY terminals is shown in Fig. 26.

Table 4 lists the status of each parts of the MPU in each low power dissipation modes. Transitions between each mode are shown in Fig. 27.

(Note) When I bit of condition code register is "1" and interrupt (INT, TIMER/INT₂, SCI/TIMER₂) is held, MPU does not enter WAIT mode by the execution of WAIT instruction.

In that case, after the 4 dummy cycles MCU executes the next instruction.

In the same way, when external interrupts $(\overline{INT}, \overline{INT_2})$ are held at the bit I set, MPU does not enter STOP mode by the execution of STOP instruction. In that case, also, MPU executes the next instruction after the 4 dummy cycles.

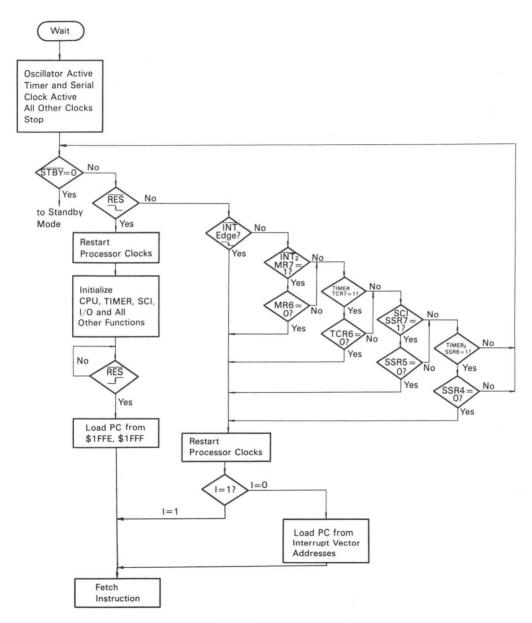


Figure 23 Wait Mode Flow Chart

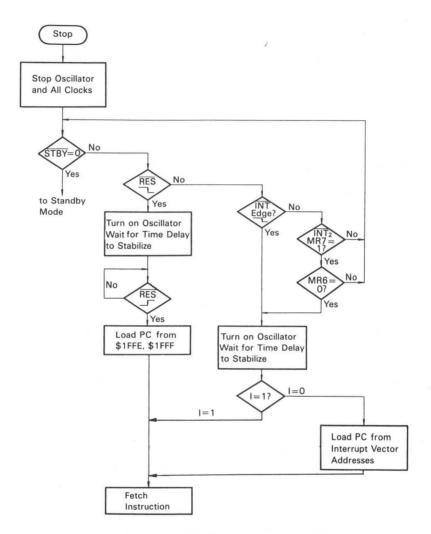


Figure 24 Stop Mode Flow Chart

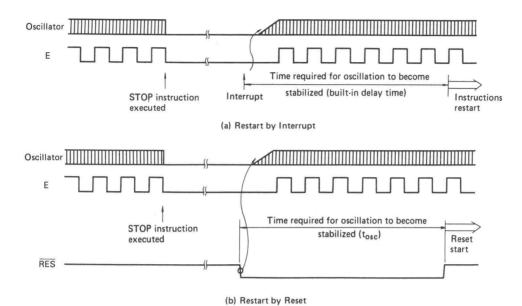


Figure 25 Timing Chart of Releasing from Stop Mode

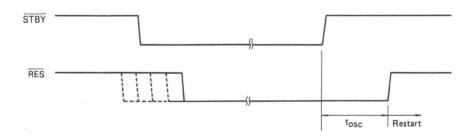


Figure 26 Timing Chart of Releasing from Standby Mode

Table 4 Status of Each Part of MPU in Low Power Dissipation Modes

					Cor	ndition			
Mode		Start	Oscil- lator	CPU	Timer, Serial	Register	RAM	I/O terminal	Escape
WAIT	Soft-	WAIT in- struction	Active	Stop	Active	Keep	Keep	Keep	STBY, RES, INT, INT ₂ , each interrupt request of TIMER, TIMER ₂ , SCI
STOP	ware	STOP in- struction	Stop	Stop	Stop	Keep	Keep	Keep	STBY, RES, INT, INT ₂
Stand- by	Hard- ware	STBY="Low"	Stop	Stop	Stop	Reset	Keep	High im- pedance	STBY="High"

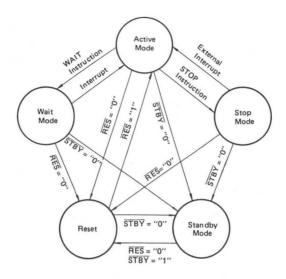


Figure 27 Transitions among Active Mode, Wait Mode, Stop Mode, Standby Mode and Reset

BIT MANIPULATION

The MPU can use a single instruction (BSET or BCLR) to set or clear one bit of the RAM within page 0 or an I/O port (except the write-only registers such as the data direction register). Every bit of memory or I/O within page 0 (\$00 — \$FF) can be tested by the BRSET or BRCLR instruction; depending on the result of the test, the program can branch to required destinations. Since bits in the RAM, or I/O can be manipulated, the user may use a bit within the RAM as a flag or handle a single I/O bit as an independent I/O terminal. Fig. 28 shows an example of bit manipulation and the validity of test instructions. In the example, the program is configured assuming that bit 0 of port A is connected to a zero cross detector circuit and bit 1 of the same port to the trigger of a triac.

The program shown can activate the triac within a time of 10μ s from zero-crossing through the use of only 7 bytes on the memory. The on-chip timer provides a required time of delay and pulse width modulation of power is also possible.

SELF 1. BRCLR 0, PORT A, SELF 1 BSET 1, PORT A BCLR 1, PORT A

Figure 28 Example of Bit Manipulation

ADDRESSING MODES

Ten different addressing modes are available to the MPU.

• Immediate

See Fig. 29. The immediate addressing mode provides access to a constant which does not vary during execution of the program.

This access requires an instruction length of 2 bytes. The effective address (EA) is PC and the operand is fetched from

the byte that follows the operation code.

Direct

See Fig. 30. In the direct addressing mode, the address of the operand is contained in the 2nd byte of the instruction. The user can gain direct access to memory up to the lower 255th address. All RAM (HD6305X2) or 192 bytes of RAM (HD6305Y2), and I/O registers are on page 0 of address space so that the direct addressing mode may be utilized.

Extended

See Fig. 31. The extended addressing is used for referencing to all addresses of memory. The EA is the contents of the 2 bytes that follow the operation code. An extended addressing instruction requires 3 bytes.

e Relative

See Fig. 32. The relative addressing mode is used with branch instructions only. When a branch occurs, the program counter is loaded with the contents of the byte following the operation code. EA = (PC) + 2 + Rel, where Rel. indicates a signed 8-bit data following the operation code. If no branch occurs, Rel. = 0. When a branch occurs, the program jumps to any byte in the range +129 to -127. A branch instruction requires 2 bytes.

• Indexed (No Offset)

See Fig. 33. The indexed addressing mode allows access up to the lower 255th address of memory. In this mode, an instruction requires a length of one byte. The EA is the contents of the index register.



• Indexed (8-bit Offset)

See Fig. 34. The EA is the contents of the byte following the operation code, plus the contents of the index register. This mode allows access up to the lower 511th address of memory. Each instruction when used in the index addressing mode (8-bit offset) requires 2 bytes.

• Indexed (16-bit Offset)

See Fig. 35. The contents of the 2 bytes following the operation code are added to content of the index register to compute the value of EA. In this mode, the complete memory can be accessed. When used in the indexed addressing mode (16-bit offset), an instruction requires 3 bytes.

• Bit Set/Clear

See Fig. 36. This addressing mode is applied to the BSET and BCLR instructions that can set or clear any bit on page 0. The lower 3 bits of the operation code specify the bit to be set or cleared. The byte that follows the operation code indicates an address within page 0.

Bit Test and Branch

See Fig. 37. This addressing mode is applied to the BRSET and BRCLR instructions that can test any bit within page 0 and can be branched in the relative addressing mode. The byte to be tested is addressed depending on the contents of the byte following the operation code. Individual bits within the byte to be tested are specified by the lower 3 bits of the operation code. The 3rd byte represents a relative value which will be added to the program counter when a branch condition is established. Each of these instructions requires 3 bytes. The value of the test bit is written in the carry bit of the condition code register.

Implied

See Fig. 38. This mode involves no EA. All information needed for execution of an instruction is contained in the operation code. Direct manipulation on the accumulator and index register is included in the implied addressing mode. Other instructions such as SWI and RTI are also used in this mode. All instructions used in the implied addressing mode requires one byte.

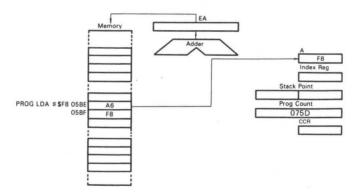


Figure 29 Example of Immediate Addressing

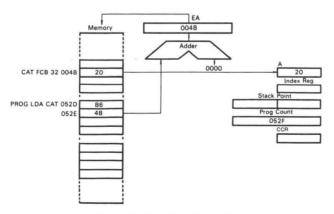


Figure 30 Example of Direct Addressing



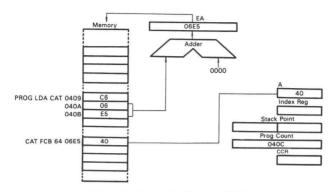


Figure 31 Example of Extended Addressing

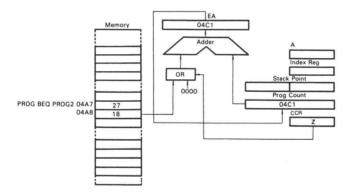


Figure 32 Example of Relative Addressing

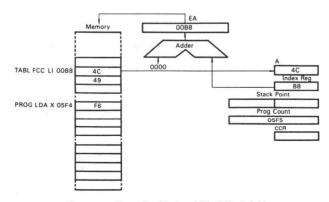


Figure 33 Example of Indexed (No Offset) Addressing



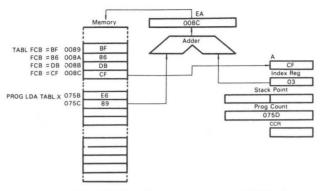


Figure 34 Example of Index (8-bit Offset) Addressing

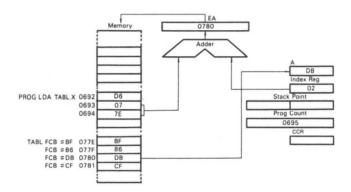


Figure 35 Example of Index (16-bit Offset) Addressing

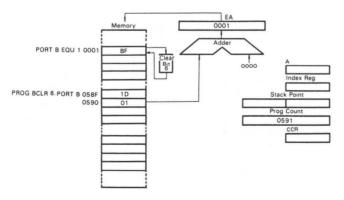


Figure 36 Example of Bit Set/Clear Addressing



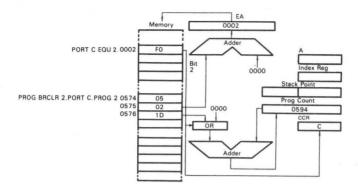


Figure 37 Example of Bit Test and Branch Addressing

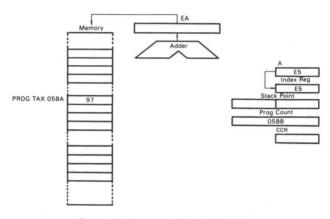


Figure 38 Example of Implied Addressing

■INSTRUCTION SET

There are 62 basic instructions available to the HD6305X2 and the HD6305Y2. They can be classified into five categories: register/memory, read/modify/write, branch, bit manipulation, and control. The details of each instruction are described in Tables 5 through 11.

Register/Memory Instructions

Most of these instructions use two operands. One operand is either an accumulator or index register. The other is derived from memory using one of the addressing modes used on the HD6305X2 and the HD6305Y2. There is no register operand in the unconditional jump instruction (JMP) and the subroutine jump instruction (JSR). See Table 5.

• Read/Modify/Write Instructions

These instructions read a memory or register, then modify or test its contents, and write the modified value into the memory or register. Zero test instruction (TST) does not write data, and is handled as an exception in the read/modify/ write group. See Table 6.

Branch Instructions

A branch instruction branches from the program sequence in progress if a particular condition is established. See Table 7.

Bit Manipulation Instructions

These instructions can be used with any bit located up to the lower 255th address of memory. Two groups are available; one for setting or clearing and the other for bit testing and branching. See Table 8.

Control Instructions

The control instructions control the operation of the MPU which is executing a program. See Table 9.

• List of Instructions in Alphabetical Order

Table 10 lists all the instructions used on the HD6305X2 and the HD6305Y2 MPU in the alphabetical order.

Operation Code Map

Table 11 shows the operation code map for the instructions used on the MPU.

Table 5 Register/Memory Instructions

								A	ddre	ssin	ng M	ode	5												
Operations	Mnemonic				Γ.			_				dex			dex			dex		Boolean/ Arithmetic			ndi		
500 g 100 000 000 000 000 000 000 000 000		OP	med #	iate	OP	Direct #	t	OP	tend #	ed ~	OP		set)	OP		rset)	(16- OP	_	ffset)	Operation	н	1	N	Z	С
Load A from Memory	LDA	A6		2	_		3	C6		4	-		3	E6	-	4	D6	-	5	M→A	•		V	^	
Load X from Memory	LDX	AE	-	2	BE	2	3	CE	3	4	FE	1	3	EE	2	4	DE	3	5	M→X			^	^	
Store A in Memory	STA	-	-	-	В7	2	3	C7	3	4	F7	1	4	E7	2	4	D7	3	5	A→M			^	^	
Store X in Memory	STX	-	-	-	BF	2	3	CF	3	4	FF	1	4	EF	2	4	DF	3	5	X→M			^	^	
Add Memory to A	ADD	AB	2	2	вв	2	3	СВ	3	4	FB	1	3	EB	2	4	DB	3	5	A+M→A	^		^	^	^
Add Memory and Carry to A	ADC	A9	2	2	В9	2	3	C9	3	4	F9	1	3	E9	2	4	D9	3	5	A+M+C→A	^		^	^	^
Subtract Memory	SUB	AO	2	2	во	2	3	СО	3	4	FO	1	3	EO	2	4	DO	3	5	$A-M\rightarrow A$			Λ	Λ	٨
Subtract Memory from A with Borrow	SBC	A2	2	2	B2	2	3	C2	3	4	F2	1	3	E2	2	4	D2	3	5	A-M-C→A			^	^	٨
AND Memory to A	AND	A4	2	2	В4	2	3	C4	3	4	F4	1	3	E4	2	4	D4	3	5	A · M→A			^	Λ	
OR Memory with A	ORA	AA	2	2	ВА	2	3	CA	3	4	FA	1	3	EA	2	4	DA	3	5	A+M→A			Λ	^	
Exclusive OR Memory with A	EOR	A8	2	2	B8	2	3	C8	3	4	F8	1	3	E8	2	4	D8	3	5	A⊕ M→A			^	^	
Arithmetic Compare A with Memory	СМР	A1	2	2	В1	2	3	C1	3	4	F1	1	3	E1	2	4	D1	3	5	A-M			^	^	^
Arithmetic Compare X with Memory	CPX	А3	2	2	В3	2	3	СЗ	3	4	F3	1	3	E3	2	4	D3	3	5	X-M			^	٨	^
Bit Test Memory with A (Logical Compare)	BIT	A5	2	2	B5	2	3	C5	3	4	F5	1	3	E5	2	4	D5	3	5	A · M			^	^	
Jump Unconditional	JMP	-	-	-	вс	2	2	СС	3	3	FC	1	2	EC	2	3	DC	3	4			•	•	•	
Jump to Subroutine	JSR	-	_	-	BD	2	5	CD	3	6	FD	1	5	ED	2	5	DD	3	6						

Symbols: Op = Operation
= Number of bytes
~ = Number of cycles

Table 6 Read/Modify/Write Instructions

							Add	iress	ing	Mod	les											
Operations	Mnemonic	Im	plied	i(A)	Im	plied	1(X)		Direc	et	18583	dex		(8-E	dexi		Boolean/Arithmetic Operation			Code		
		OP	#	~	OP	#	~	OP	#	~	OP	#	~	OP	#	~		Н	1	N	Z	С
Increment	INC	4C	1	2	5C	1	2	3C	2	5	7C	1	5	6C	2	6	$A+1\rightarrow A$ or $X+1\rightarrow X$ or $M+1\rightarrow M$	•		Λ	Λ	
Decrement	DEC	4A	1	2	5A	1	2	3A	2	5	7A	1	5	6A	2	6	$A-1 \rightarrow A$ or $X-1 \rightarrow X$ or $M-1 \rightarrow M$		•	٨	٨	•
Clear	CLR	4F	1	2	5F	1	2	3F	2	5	7F	1	5	6F	2	6	00→A or 00→X or 00→M		•	0	1	
Complement	СОМ	43	1	2	53	1	2	33	2	5	73	1	5	63	2	6	$\overline{A} \rightarrow A$ or $\overline{X} \rightarrow X$ or $\overline{M} \rightarrow M$			^	^	1
Negate																	00-A→A or 00-X→X					
(2's Complement)	NEG	40	1	2	50	1	2	30	2	5	70	1	5	60	2	6	or 00−M→M	•		٨	٨	٨
Rotate Left Thru Carry	ROL	49	1	2	59	1	2	39	2	5	79	1	5	69	2	6	C b; A or X or M bo	•	•	٨	٨	^
Rotate Right Thru Carry	ROR	46	1	2	56	1	2	36	2	5	76	1	5	66	2	6	C A or X or M	•	•	^	٨	^
Logical Shift Left	LSL	48	1	2	58	1	2	38	2	5	78	1	5	68	2	6	C b, bo bo	•	•	^	^	^
Logical Shift Right	LSR	44	1	2	54	1	2	34	2	5	74	1	5	64	2	6	0 - D, A or X or M C	•	•	0	٨	^
Arithmetic Shift Right	ASR	47	1	2	57	1	2	37	2	5	77	1	5	67	2	6	b, bo c	•	•	٨	٨	٨
Arithmetic Shift Left	ASL	48	1	2	58	1	2	38	2	5	78	1	5	68	2	6	Equal to LSL	•	•	٨	^	٨
Test for Negative																						
or Zero	TST	4D	1	2	5D	1	2	3D	2	4	7D	1	4	6D	2	5	A-00 or X-00 or M-00			٨	^	

Symbols: Op = Operation
= Number of bytes
~ = Number of cycles

Table 7 Branch Instructions

		Addr	essing f	Modes			Cond	lition	Cod	la
Operations	Mnemonic	F	Relativ	е	Branch Test		Jona	lition	Cod	е
		OP	#	~		Н	1	N	Z	С
Branch Always	BRA	20	2	3	None	•	•	•	•	•
Branch Never	BRN	21	2	3	None	•	•	•	•	
Branch IF Higher	ВНІ	22	2	3	C+Z=0	•	•		•	
Branch IF Lower or Same	BLS	23	2	3	C+Z=1	•	•		•	•
Branch IF Carry Clear	BCC	24	2	3	C=0	•		•	•	
(Branch IF Higher or Same)	(BHS)	24	2	3	C=0	•	•	•	•	•
Branch IF Carry Set	BCS	25	2	3	C = 1	•	•	•	•	
(Branch IF Lower)	(BLO)	25	2	3	C = 1	•	•			•
Branch IF Not Equal	BNE	26	2	3	Z=0	•	•	•	•	•
Branch IF Equal	BEQ	27	2	3	Z=1	•	•	•	•	•
Branch IF Half Carry Clear	ВНСС	28	2	3	H=0	•	•	•	•	•
Branch IF Half Carry Set	BHCS	29	2	3	H=1	•	•	•	•	•
Branch IF Plus	BPL	2A	2	3	N=0	•		•	•	
Branch IF Minus	BMI	2B	2	3	N = 1	•	•	•	•	
Branch IF Interrupt Mask Bit is Clear	ВМС	2C	2	3	I=0		•	•	•	•
Branch IF Interrupt Mask Bit is Set	BMS	2D	2	3	I=1	•	•		•	•
Branch IF Interrupt Line is Low	BIL	2E	2	3	INT=0	•	•		•	•
Branch IF Interrupt Line is High	BIH	2F	2	3	INT = 1					
Branch to Subroutine	BSR	AD	2	5			•	•	•	

Symbols: Op = Operation
= Number of bytes
~ = Number of cycles

Table 8 Bit Manipulation Instructions

		,	Add	ressi	ng Modes			Boolean/			1		0	
Operations	Mnemonic	Bit Set	Clea	ar	Bit Test and	d Bra	nch	Arithmetic	Branch Test	-	ona	ition	Coc	16
		OP	#	~	OP	#	~	Operation	1031	Н	1	N	Z	C
Branch IF Bit n is set	BRSET n(n=0···7)	-	-	-	2·n	3	5		Mn = 1			•	•	^
Branch IF Bit n is clear	BRCLR n(n=0···7)	-	-	1	01+2·n	3	5		Mn=0	•		•	•	^
Set Bit n	BSET n(n=0···7)	10+2·n	2	5	_	_		1→Mn					•	
Clear Bit n	BCLR n(n=07)	11+2·n	2	5		_	-	0→Mn		•		•	•	

Symbols: Op = Operation # = Number of bytes ~ = Number of cycles

Table 9 Control Instructions

		Addre	essing	Modes					_	
Operations	Mnemonic	1	mplie	d	Boolean Operation	C	ond	tion	Coc	1e
		OP	#	~		Н	1	N	Z	C
Transfer A to X	TAX	97	1	2	A→X		•			
Transfer X to A	TXA	9F	1	2	X→A	•			•	
Set Carry Bit	SEC	99	1	1	1→C		•			1
Clear Carry Bit	CLC	98	1	1	0→C	•	•			0
Set Interrupt Mask Bit	SEI	9B	1	2	1→I		1			
Clear Interrupt Mask Bit	CLI	9A	1	2	0→I		0			
Software Interrupt	SWI	83	1	10			1			
Return from Subroutine	RTS	81	1	5						
Return from Interrupt	RTI	80	1	8		?	?	?	?	?
Reset Stack Pointer	RSP	90	1	2	\$FF→SP	•	•			
No-Operation	NOP	9D	1	1	Advance Prog. Cntr. Only		•			
Decimal Adjust A	DAA	8D	1	2	Converts binary add of BCD charcters into BCD format			^	Λ	^*
Stop	STOP	8E	1	4		•	•	•		
Wait	WAIT	8F	1	4						

Symbols: Op = Operation
= Number of bytes
~ = Number of cycles

* Are BCD characters of upper byte 10 or more? (They are not cleared if set in advance.)

Table 10 Instruction Set (in Alphabetical Order)

					Addressin	g Modes					C	ond	ition	Cod	е
Mnemonic	Implied	Immediate	Direct	Extended	Relative	Indexed (No Offset)	Indexed (8-Bit)	Indexed (16-Bit)	Bit Set/ Clear	Bit Test & Branch	н	1	N	z	С
ADC		×	×	×		×	×	×			٨	•	Λ	^	٨
ADD		×	×	×		×	×	×			٨		٨	٨	٨
AND		×	×	×		×	×	×			•	•	^	٨	
ASL	×		×			×	×					•	Λ	Λ	Λ
ASR	×		×			×	×						٨	٨	٨
BCC					×						•	•	•	•	
BCLR									×		•				
BCS					×						•	•			
BEQ					×								•		
ВНСС					×										
BHCS					×										
BHI					×										
(BHS)					×									•	
BIH					×										
BIL					×						•			•	•
BIT		×	×	×		×	×	×					٨	٨	
(BLO)					×										
BLS					×								•	•	
ВМС					×						•				
BMI					×						•				•
BMS					×						•	•		•	
BNE					×						•				
BPL					×						•			•	
BRA					×									•	

Condition Code Symbols:

Half Carry (From Bit 3) Н

Interrupt Mask

Negative (Sign Bit)

N Z Zero C Carry/Borrow

Test and Set if True, Cleared Otherwise Not Affected ^

• Not Affected

Load CC Register From Stack

Table 10 Instruction Set (in Alphabetical Order)

					Addressin	g Modes					(Cond	lition	Coc	de
Mnemonic	Implied	Immediate	Direct	Extended	Relative	Indexed (No Offset)	Indexed (8-Bit)	Indexed (16-Bit)	Bit Set/ Clear	Bit Test & Branch	н	1	N	z	С
BRN					×										
BRCLR										×					^
BRSET										×	•			•	1
BSET									×						
BSR			Market Market State of State o		×										
CLC	×											•			0
CLI	×											0			
CLR	×		×			×	×						0	1	
CMP		×	×	×		×	×	×			•	•	٨	^	1
COM	×		×			×	×				•	•	^	Λ	1
CPX		×	×	×		×	×	×			•	•	٨	Λ	^
DAA	×												٨	Λ	^
DEC	×		×			×	×					•	٨	Λ	
EOR		×	×	×		×	×	×			•		٨	Λ	
INC	×		×			×	×						1	Λ	
JMP			×	×		×	×	×			•		•	•	
JSR			×	×		×	×	×			•	•	•	•	•
LDA		×	×	×		×	×	×			•	•	٨	^	
LDX		×	×	×		×	×	×			•		^	^	•
LSL	×		×			×	×				•		^	^	^
LSR	×		×			×	×				•		0	^	^
NEG	×		×			×	×				•	•	٨	^	^
NOP	×										•	•	•	•	
ORA		×	×	×		×	×	×			•		^	^	
ROL	×		×			×	×				•		^	^	_
ROR	×		×			×	×				•	•	٨	Λ	Λ
RSP	×												•	•	•
RTI	×										?	?	?	?	?
RTS	×										•	•		•	
SBC		×	×	×		×	×	×			•	•	٨	^	٨
SEC	×										•		•	•	1
SEI	×										•	1		•	
STA			×	×		×	×	×					^	٨	
STOP	×										•	•	•	•	•
STX			×	×		×	×	×			•	•	٨	^	•
SUB		×	×	×		×	×	×		-	•	•	^	^	٨
SWI	×										•	1		•	
TAX	×										•	•	•	•	•
TST	×		×			×	×				•	•	^	^	
TXA	×										•	•	•	•	•
WAIT	×										•	•	•	•	•

Condition Code Symbols: H Half Carry (From Bit 3)

1 Interrupt Mask

N Negative (Sign Bit)

Z Zero C Carry/Borrow

Test and Set if True, Cleared Otherwise

Not Affected

Load CC Register From Stack

Table 11 Operation Code Map

	Bit Man	ipulation	Branch	F	Read/	Modif	y/Write	е	Cor	ntrol		Re	gister	Mem	ory			
	Test & Branch	Set/ Clear	Rel	DIR	A	Х	,X1	,X0	IMP	IMP	IMM	DIR	EXT	,X2	,X1	,xo		
	0	1	2	3	4	5	6	7	8	9	Α	В	С	D	Е	F	←	Н
0	BRSET0	BSETO	BRA			NEG			RTI*	_			SI	JB			0	7
1	BRCLRO	BCLRO	BRN			_			RTS*	_			CI	MP			1	1
2	BRSET1	BSET1	BHI			-			-	-			SI	ВС			2	
3	BRCLR1	BCLR1	BLS			COM			SWI*	-			CI	PX			3	
4	BRSET2	BSET2	BCC			LSR			_				Αſ	D			4	
5	BRCLR2	BCLR2	BCS							_			В	IT			5	
6	BRSET3	BSET3	BNE			ROR				_			L	AC			6	
7	BRCLR3	BCLR3	BEQ			ASR			_	TAX*	-		ST	ГА		STA(+1)	7	
8	BRSET4	BSET4	BHCC		L	SL/AS	SL		-	CLC			E	OR			8	
9	BRCLR4	BCLR4	BHCS			ROL			-	SEC			A[OC			9	
Α	BRSET5	BSET5	BPL			DEC				CLI*			Ol	RA			Α	
В	BRCLR5	BCLR5	BMI			_			_	SEI*			A	DD			В	1
С	BRSET6	BSET6	ВМС			INC				RSP*			J	MP(-	1)		С	1
D	BRCLR6	BCLR6	BMS	TST(-1)	T	ST	TST	(-1)	DAA*	NOP	BSR*	JSR	(+2)	JSR	(+1)	JSR(+2)	D	1
Е	BRSET7	BSET7	BIL			_			STOP*	-			L	X			Е	1
F	BRCLR7	BCLR7	BIH			CLR			WAIT*	TXA*	-		S	ГХ		STX(+1)	F	1
	3/5	2/5	2/3	2/5	1/2	1/2	2/6	1/5	1/*	1/1	2/2	2/3	3/4	3/5	2/4	1/3		_

(NOTES) 1. "-" is an undefined operation code.

The lowermost numbers in each column represent a byte count and the number of cycles required (byte count/number of cycles).
 The number of cycles for the mnemonics asterisked (*) is as follows:

RTI	8	TAX	2
RTS	5	RSP	2
SWI	10	TXA	2
DAA	2	BSR	5
STOP	4	CLI	2
WAIT	4	SEI	2

3. The parenthesized numbers must be added to the cycle count of the particular instruction.

Additional Instructions

The following new instructions are used on the HD6305X2 and the HD6305Y2:

DAA Converts the contents of the accumulator into BCD code.

WAIT Causes the MPU to enter the wait mode. For this mode, see the topic, Wait Mode.

STOP Causes the MPU to enter the stop mode. For this mode, see the topic, Stop Mode.

■ OPERATION AT EACH INSTRUCTION CYCLE

The HD6305X2 and the HD6305Y2 employs a mechanism of the pipeline control for the instruction fetch and the subsequent instruction fetch is performed during the current instruction being executed.

Table 12 provides the information about the relationship among each data on the Address Bus, Data Bus and R/\overline{W} status in cycle-by-cycle basis during the execution of each instruction.

Table 12 Cycle-by-Cycle Operation

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
IMMEDIATE					
ADC, ADD, AND,	2	1	Op Code Address +1	1	Operand Data
BIT, CMP, CPX, EOR,		2	Op Code Address +2	1	Next Op Code
LDA, LDX, ORA,					
SBC, SUB					
DIRECT					
ADC, ADD, AND,	3	1	Op Code Address +1	1	Address of Operand
BIT, CMP, CPX,		2	Address of Operand	1	Operand Data
EOR, LDA, LDX,		3	Op Code Address +2	1	Next Op Code
ORA, SBC, SUB					

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
STA, STX	3	1	Op Code Address +1	1	Address of Operand
		2	Address of Operand	0	Data from Acc. Data from Ix.
		3	Op Code Address +1	1	Next Op Code
JMP	2	1	Op Code Address +1	1	Jump Address
		2	Jump Address	1	Next Op Code
JSR	5	1	Op Code Address +1	1	Jump Address (LSB)
		2	1FFF	1	Irrelevant Data
		3	Stack Pointer	0	Return Address (LSB)
		4 5	Stack Pointer –1	0	Return Address (MSB)
ACD OLD 0014			Jump Address	1	First Subroutine Op Code
ASR, CLR, COM,	5	1 2	Op Code Address +1	1	Address of Operand
DEC, INC, LSL,		3	Address of Operand	1 1	Operand Data
LSR, NEG, ROL, ROR		4	Address of Operand	0	Irrelevant Data New Operand Data
non		5	Op Code Address +2	1	Next Op Code
TST	4				
131	4	1 2	Op Code Address +1	1	Address of Operand
		3	Address of Operand	1	Operand Data
		4	Op Code Address +2	1	Irrelevant Data Next Op Code
EVTENDED	l	-4	Op Code Address +2		Next Op Code
EXTENDED	4	1	0-0-1-0-1-1		4.11 (0 1/400)
ADC, ADD, AND,	4	1 2	Op Code Address +1 Op Code Address +2	1	Address of Operand (MSB)
BIT, CMP, CPX, EOR, LDA, LDX,		3	Address of Operand	1	Address of Operand (LSB) Operand Data
ORA, SBC, SUB		4	Op Code Address +3	1	Next Op Code
STA, STX	4	1	Op Code Address +1	1	
51A, 51A	4	2	Op Code Address +2	1	Address of Operand (MSB) Address of Operand (LSB)
		_	- 1 programme - 2		/ Data from Acc.
		3	Address of Operand	0	Data from Ix.
		4	Op Code Address +3	1	Next Op Code
JMP	3	1	Op Code Address +1	1	Jump Address (MSB)
		2	Op Code Address +2	1	Jump Address (LSB)
		3	Jump Address	1	Next Op Code
JSR	6	1	Op Code Address +1	1	Jump Address (MSB)
		2	Op Code Address +2	1	Jump Address (LSB)
		3	1FFF	1	Irrelevant Data
		4	Stack Pointer	0	Return Address (LSB)
		5	Stack Pointer -1	0	Return Address (MSB)
		6	Jump Address	1	First Subroutine Op Code
INDEXED (No offset)				,	
ADC, ADD, AND,	3	1	Op Code Address +1	1	Next Op Code
BIT, CMP, CPX,		2	lx	1	Operand Data
EOR, LDA, LDX,		3	Op Code Address +1	1	Next Op Code
ORA, SBC, SUB					
STA, STX	4	1	Op Code Address +1	1	Next Op Code
		2	1FFF	1	Irrelevant Data
		3	lx	0	Data from Acc.
		4	Op Code Address +1	1	Next Op Code
JMP	2	1	Op Code Address +1	1	Next Op Code
JIVII	4		OP COUR MUUTESS TT	1	Mexi op Code



HD6305X2/HD6305Y2-----

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
JSR	5	1	Op Code Address +1	1	Next Op Code
Joh	3	2	1FFF	1	Irrelevant Data
		3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer –1	0	
		5	Ix	1	Return Address (MSB) First Subroutine Op Code
ASR, CLR, COM,	5	1	Op Code Address +1	1	Next Op Code
DEC, INC, LSL,		2	Ix	1	Operand Data
LSR, NEG, ROL,		3	1FFF	1	Irrelevant Data
ROR		4	lx	0	New Operand Data
1011		5	Op Code Address +1	1	Next Op Code
TST	4	1	Op Code Address +1	1	Next Op Code
		2	lx	1	Operand Data
		3	1FFF	1	Irrelevant Data
		4	Op Code Address +1	1	Next Op Code
INDEXED (8-bit offset)					
ADC, ADD, AND,	4	1	Op Code Address +1	1	Offset
BIT, CMP, CPX,		2	1FFF	1	Irrelevant Data
EOR, LDA, LDX,		3	Ix + Offset	1	Operand Data
ORA, SBC, SUB		4	Op Code Address +2	1	Next Op Code
STA, STX	4	1	Op Code Address +1	1	Offset
		2	1FFF	1	Irrelevant Data
		3	Ix + Offset	0	Data from Acc. Data from Ix.
		4	Op Code Address +2	1	Next Op Code
JMP	3	1	Op Code Address +1	1	Offset
		2	1FFF	1	Irrelevant Data
		3	Ix + Offset	1	First Op Code of Jump Routine
JSR	5	1	Op Code Address +1	1	Offset
		2	1FFF	1	Irrelevant Data
		3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer –1	0	Return Address (MSB)
		5	Ix + Offset	1	First Subroutine Op Code
ASR, CLR, COM,	6	1	Op Code Address +1	1	Offset
DEC, INC, LSL,		2	1FFF	1	Irrelevant Data
LSR, NEG, ROL,		3	Ix + Offset	1	Operand Data
ROR	1	4	1FFF	1	Irrelevant Data
		5	Ix + Offset	0	New Operand Data
		6	Op Code Address +1	1	Next Op Code
TST	5	1	Op Code Address +1	1	Offset
		2	1FFF	1	Irrelevant Data
		3	Ix + Offset	1	Operand Data
		4	1FFF	1	Irrelevant Data
		5	Op Code Address +2	1	Next Op Code
NDEXED (16-bit offset)	-	1	On Code Address : 4		Office (MCD)
ADC, ADD, AND,	5	1	Op Code Address +1	1	Offset (MSB)
BIT, CMP, CPX,		2	Op Code Address +2	1	Offset (LSB)
EOR, LDA, LDX,		3	1FFF	1	Irrelevant Data
ORA, SBC, SUB		4	Ix + Offset	1	Operand Data
		5	Op Code Address +1	1	Next Op Code



Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
STA, STX	5	1	Op Code Address +1	1	Offset (MSB)
		2	Op Code Address +2	1	Offset (LSB)
		3	1FFF	1	Irrelevant Data
		4	Ix + Offset	0	/ Data from Acc.
		4	IX + Offset	U	Data from Ix.
		5	Op Code Address +3	1	Next Op Code
JMP	4	1	Op Code Address +1	1	Offset (MSB)
		2	Op Code Address +2	1	Offset (LSB)
		3	1FFF	1	Irrelevant Data
		4	Ix + Offset	1	First Op Code of Jump Routine
JSR	6	1	Op Code Address +1	1	Offset (MSB)
		2	Op Code Address +2	1	Offset (LSB)
		3	1FFF	1	Irrelevant Data
		4	Stack Pointer	0	Return Address (LSB)
		5	Stack Pointer -1	0	Return Address (MSB)
		6	Ix + Offset	1	First Subroutine Op Code
IMPLIED					
ASR, CLR, COM,	2	1	Op Code Address +1	1	Next Op Code
DEC, INC, LSL,		2	Op Code Address +1	1	Next Op Code
LSR, NEG, ROL,					
ROR, TST					
CLC, NOP, SEC	1	1	Op Code Address +1	1	Next Op Code
RSP, TAX, TXA	2	1	Op Code Address +1	1	Next Op Code
		2	Op Code Address +1	1	Next Op Code
CLI, SEI	2	1	Op Code Address +1	1	Next Op Code
		2	1FFF	1	Irrelevant Data
DAA	2	1	Op Code Address +1	1	Next Op Code
		2	Op Code Address +1	1	Next Op Code
STOP, WAIT	4	1	Op Code Address +1	1	Next Op Code
0.0.,		2	1FFF	1	Irrelevant Data
		3	1FFF	1	Irrelevant Data
		4	Op Code Address +1	1	Next Op Code
RTI	8	1	Op Code Address +1	1	Next Op Code
NTT	"	2	1FFF	1	Irrelevant Data
		3	Stack Pointer	1	CC
		4	Stack Pointer +1	1	Acc.
		5	Stack Pointer +2	1	Ix.
		6	Stack Pointer +3	1	Return Address (MSB)
		7	Stack Pointer +4	1	Return Address (USB)
		8	Return Address	1	First Op Code of Return Routine
LITE	5			-	
RTS	5	1	Op Code Address +1	1	Next Op Code
		2	1FFF	1	Irrelevant Data
		3	Stack Pointer	1	Return Address (MSB)
		4	Stack Pointer +1	1	Return Address (LSB)
		5	Return Address	1	First Op Code of Return Routine
SWI	10	1	Op Code Address +1	1	Next Op Code
		2	1FFF	1	Irrelevant Data
		3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer-1	0	Return Address (MSB)
		5	Stack Pointer-2	0	lx.
		6	Stack Pointer - 3	0	Acc.
		7	Stack Pointer-4	0	CC
		8	Vector Address 1FFC	1	Address of SWI Routine (MSB)
		9	Vector Address 1FFD	1	Address of SWI Routine (LSB)
		10	Address of SWI Routine	1	First Op Code of SWI Routine

Address Mode & Instructions	Cycles	Cycle #	Address Bus	R/W	Data Bus
RELATIVE					
BCC, BCS, BEQ,	3	1	Op Code Address +1	1	Next Op Code
BHCC, BHCS, BHI,		2	1FFF	1	Irrelevant Data
BIH, BIL, BLS, BMC, BMI, BMS, BNE, BPL, BRA, BRN		3	(Branch AddressTest = "1" Op Code Address +1 Test = "0"	1	First Op Code of Branch Routine Next Op Code
BSR	5	1	Op Code Address +1	1	Offset
		2	1FFF	1	Irrelevant Data
		3	Stack Pointer	0	Return Address (LSB)
		4	Stack Pointer-1	0	Return Address (MSB)
		5	Branch Address	1	First Op Code of Subroutine
BIT TEST AND BRANCH					
BRCLR, BRSET	5	1	Op Code Address +1	1	Address of Operand
		2	Address of Operand	1	Operand Data
		3	Op Code Address +2	1	Offset
		4	1FFF	1	Irrelevant Data
		5	Branch AddressTest = "1" Op Code Address +3Test = "0"	1	(First Op Code of Branch Address Next Op Code
BIT SET/CLEAR					
BCLR, BSET	5	1	Op Code Address +1	1	Address of Operand
		2	Address of Operand	1	Operand Data
		3	1FFF	1	Irrelevant Data
		4	Address of Operand	0	New Operand Data
		5	Op Code Address +1	1	Next Op Code

■ PRECAUTIONS

Precaution; Board Design of Oscillation Circuit

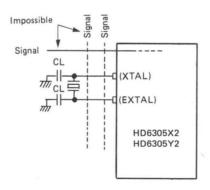


Figure 39 Example of Circuit Causing Trouble in Oscillation

Wire the signal lines to the neighboring XTAL and EXTAL pins as far apart as possible. And locate crystal and capacity as close to XTAL and EXTAL as possible.

Precaution: Program of Write Only Register

Read/Modify/Write instructions are applied to Write Only Register (e.g. DDR; Data Direction Register of I/O port) of the HD6305X2 and the HD6305Y2 and its contents cannot be changed.

(1) Data cannot be read from Write Only Register.

(e.g. DDR of I/O port)

Read/Modify/Write instructions are executed in the following sequence.

(i) Reads the contents from appointed address.

(ii) Changes the data which has been read.

(iii) Turn the data back to the original address.

Evidently, Read/Modify/Write instructions cannot be applied to Write Only Register such as DDR.

(2) For the same reason, do not set DDR of I/O port using BSET and BCLR instructions of the HD6305X2 and the HD6305Y2.

(3) In the correct writing method into Write Only Register, stored instruction as STA and STX, etc. are used.

Precaution; Sending/Receiving Program of Serial Data

Reading from or Writing into the SCI data register (SDR: \$0012) during sending/receiving of serial data may make sending/receiving operation of SCI out of order.

Precaution; WAIT/STOP Instructions Program

When I bit of condition code register is "1" and interrupt (INT, TIMER/INT₂, SCI/TIMER₂) is held, MCU does not enter WAIT mode by the execution of WAIT instruction.

In that case, after the 4 dummy cycles MCU executes the next instruction.

In the same way, when external interrupts $(\overline{INT}, \overline{INT_2})$ are held at the bit I set, MCU does not enter STOP mode by the execution of STOP instruction. In that case, also, MCU executes the next instruction after the 4 dummy cycles.

HD63B09E, HD63C09E CMOS MPU (Micro Processing Unit)

The HD6309E is the highest 8-bit microprocessor of HMCS6800 family, which is just compatible with the conventional HD6809E.

The HD6309E has hardware and software features which make it an ideal processor for higher level language execution or standard controller applications. External clock inputs are provided to allow synchronization with peripherals, systems or other MPUs.

The HD6309E is complete CMOS device and the power dissipation is extremely low. Moreover, the SYNC and CWAI instruction makes low power application possible.

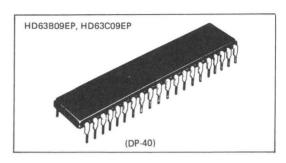
- FEATURES
- Hardware Interface with All HMCS6800 Peripherals
- Software Object Code Compatible with the HD6809E
- Low Power Consumption Mode (Sleep mode)

SYNC state of SYNC Instruction WAIT state of CWAI Instruction

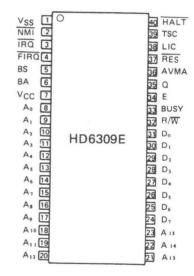
- External Clock Inputs, E and Q, Allow Synchronization
- Wide Operation Range

 $f = 0.5 \text{ to 3MHz} (V_{CC} = 5V \pm 10\%)$

Type No.	Bus Timing
HD63B09E	2.0MHz
HD63C09E	3.0MHz



■ PIN ARRANGEMENT



(Top View)

■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	v _{cc} *	-0.3 ~ +7.0	V
Input Voltage	V _{in} *	-0.3 ~ +7.0	V
Maximum Output Current	1101**	5	mA
Maximum Total Output Current	ΣI _O ***	100	mA
Operating Temperature	T _{opr}	-20 ∼ +75	°C
Storage Temperature	T _{stg}	-55 ∼ +150	°C

^{*} With respect to VSS (SYSTEM GND)

■ RECOMMENDED OPERATING CONDITIONS

Item		Symbol	min	typ	max	Unit
Suppl	y Voltage	Vcc*	4.5	5.0	5.5	V
	Logic, RES	V _{IL} *	-0.3	_	0.8	V
E, Q	V _{ILC} *	-0.3	-	0.4	V	
Input Voltage	Logic		2.0	_	V _{CC}	V
	E, Q	V _{IH} *	3.0	_	Vcc	V
RES			V _{CC} -0.5	_	Vcc	V
perating Temper	ature	T _{opr}	-20	25	75	°C

^{*} With respect to VSS (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC}=5.0V±10%, V_{SS}=0V, Ta=- 20 ~ +75°C, unless otherwise noted.)

Item		Symbol	Test Condition	Н	D63B09E		Н		Unit		
Item		Symbol	rest Condition	min	typ*	max	min	typ*	max	Unit	
	Logic	VIH		2.0	-	Vcc	2.0	-	Vcc	V	
Input "High" Voltage	E, Q	VIH		3.0	-	Vcc	3.0	-	Vcc	V	
	RES	VIHR		V _{CC} -0.5	-	Vcc	V _{CC} -0.5	-	Vcc	V	
Input "Low" Voltage	Logic, RES	VIL		-0.3	-	0.8	-0.3	-	0.8	V	
Input Low Vortage	E, Q	VILC		-b.3	-	0.4	-0.3	-	0.4	V	
Input Leakage Current	Logic, Q, RES		Vin=0 ~ VCC,	-2.5	-	2.5	-2.5	-	2.5	μА	
Input Leakage Current	E	lin	V _{CC} =max	-10	_	10	-10	-	10	μА	
	D D		I _{LOAD} =-400μA	4.1	-	-	4.1	-	_		
	$D_0 \sim D_7$		ILOAD≦-10μA	V _{CC} -0.1	-	-	V _{CC} -0.1	-	-	V	
		1 1	ILOAD=-400μA	4.1	_	_	4.1	-	-	· ·	
	$A_0 \sim A_{15}$, R/W	Voн	ILOAD≦-10µA	V _{CC} -0.1	-	_	V _{CC} -0.1	-	_	V	
	BA, BS, LIC,	1 [ILOAD=-400μA	4.1	-	-	4.1	-	-	V	
	AVMA, BUSY		I _{LOAD} ≦-10μA	V _{CC} -0.1	-	_	V _{CC} -0.1	-	-		
Output "Low" Voltage		VOL	ILOAD=2mA	-	-	0.5	-	-	0.5	V	
Input Capacitance	$D_0 \sim D_7$, Logic Input Q, RES	Cin	V _{in} =0V, Ta=25°C,	-	10	15	-	10	15	pF	
Impar suparrones	E		f=1MHz	_	30	50	-	30	50	pF	
Output Capacitance	A₀ ~A₁₅, R/W, BA, BS, LIC, AVMA, BUSY	C _{out}	V _{in} =0V, Ta=25°C, f=1MHz	-	10	15	-	10	15	pF	
Frequency of Operation	E, Q	f		0.5	-	2.0	0.5	-	3.0	MHz	
Three-State (Off State)	D ₀ ~ D ₇		Vin=0.4~VCC,	-10	-	10	-10	-	10	μА	
Input Current	$A_0 \sim A_{15}$, R/\overline{W}	TSI	V _{CC} =max	-10	-	10	-10	-	10	μА	
Correct Dissipantia		lcc	Operating	-	_	20	-	-	30	m A	
Current Dissipation		100	Sleeping	-	_	10	-	-	15	mA	

^{*}Ta=25° C, V_{CC}=5V

^{**} Maximum output current is the maximum currents which can flow out from one output terminal and I/O common terminal.

^{***} Maximum total output current is the maximum currents which can flow out from one output terminal and I/O common terminal.

(A₀ ~ A₁₅, R/W, D₀ ~ D₇, BA, BS, LIC, AVMA, BUSY)

*** Maximum total output current is the total sum of output currents which can flow out simultaneously from output terminals and I/O common terminals. (A₀ ~ A₁₅, R/W, D₀ ~ D₇, BA, BS, LIC, AVMA, BUSY)

⁽NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

• AC CHARACTERISTICS (V_{CC}=5.0V \pm 10%, V_{SS}=0, Ta=-20 \sim +75 $^{\circ}$ C, unless otherwise noted.)

1. CLOCK TIMING

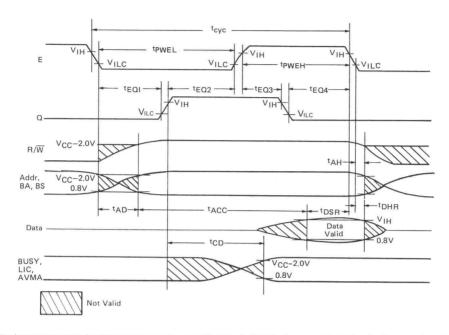
No.	Combal	Test Condition	HD63B09E				HD63C09	E	Unit
Item	Symbol	lest Condition	min	typ	max	min	typ	max	Unit
Cycle Time	tcyc		500	-	2000	333	-	2000	ns
E Clock "Low"	tPWEL		210	_	1000	140	-	1000	ns
E Clock "High" (Measured at V _{IH})	tPWEH		220	-	1000	140	_	1000	ns
E Rise and Fall Time	t _{Er} , t _{Ef}	Fig. 1,2	-	-	20	-	-	15	ns
Q Clock "High"	tPWQH		220	-	1000	140		1000	ns
Q Rise and Fall Time	tQr, tQf		-	-	20	-	-	15	ns
E "Low" to Q Rising E "Low"→Q"High"	tEQ1		100	-	-	65	_	-	ns
Q "High" to E Rising Q "High"→E "High"	tEQ2		100	-	-	65	-	-	ns
E "High" to Q Falling E "High"→Q"Low"	tEQ3		100	-	-	65	-	_	ns
Q "Low" to E Falling Q "Low"→E "Low"	tEQ4		100	-	-	65	-	-	ns

2. BUS TIMING

leaves.		Symbol	Test Condition	HD63B09E			HD63C09E			Unit
Item		Symbol	Test Condition	min	typ	max	min	typ	max	Unit
Address Delay		tAD		-	-	110	-	-	110	ns
Address Hold Time	Ta = 0 ~ 75° C	tAH	1 [20		-	20	-	-	
(Address, R/W, BA, BS)	Ta = −20~0° C	YAH		10	-	-	10	-	-	ns
Peripheral Read Access Times (tcyc-tEf-tAD-tDSR=tACC)		tACC	Fig. 1, 2	330	_	-	185	_	-	ns
Data Setup Time (Read)		†DSR		40	-	-	20	_	-	ns
Input Data Hold Time		tDHR		20	-	-	20	-	-	ns
Data Delay Time (Write)		tDDW	1 1	-	-	110	-	-	70	ns
Ta = 0~75° C		tDHW		30	-	-	30	-	-	
Output Data Hold Time	Ta = -20~0° C	,DHM		20	-	-	20	_	-	ns

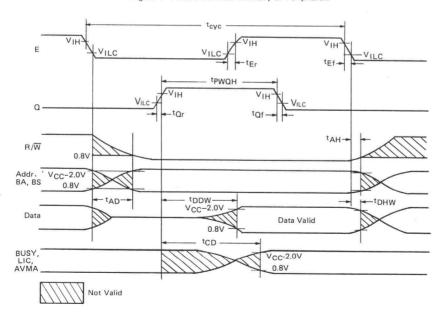
3. PROCESSOR CONTROL TIMING

1	Combal	Test Condition	HD63B09E			HD63C09E			Unit	
Item	Symbol	rest Condition	min	typ	max	min	typ	max	Omit	
Control Delay (BUSY, LIC, AVMA)	tCD		-	_	200	-	-	130	ns	
Interrupts Set Up Time	tPCS	Fig. 1, 2,	110	-	-	70	-	_	ns	
HALT Set Up Time	tPCS		110	-	-	70	-	-	ns	
RES Set Up Time	tPCS		110	_	-	70	-	-	ns	
TSC Setup, Time	tPCS		110	-	-	70	-	-	ns	
TSC Drive to Valid Logic Levels	^t TSA	7 ~ 10, 14 and 17	-	-	120	-	-	120	ns	
TSC Release MOS Buffers to High Impedance	tTSR		-	_	110	_	-	110	ns	
TSC Three-State Delay	tTSD		-	-	80	-	-	80	ns	
Processor Control Rise/Fall	tPCr, tPCf		-	-	100	-	-	100	ns	
TSC Input Delay	^t PCT		30	_	-	30	_	-	ns	



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V_{1Hmin} and logic "Low" = V_{1Lmax} unless otherwise specified.

Figure 1 Read Data from Memory or Peripherals



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V_{1Hmin} and logic "Low" = V_{1Lmax} unless otherwise specified.

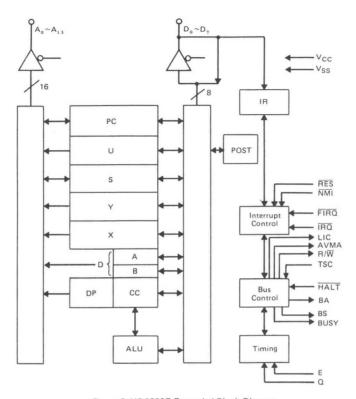
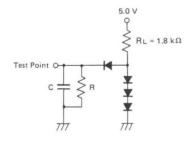


Figure 3 HD6309E Expanded Block Diagram



C = 30 pF for BA, BS, LIC, AVMA, BUSY 130 pF for $D_0 \sim D_7$ 90 pF for $A_0 \sim A_{15}$, R/\overline{W}

R = 10 k Ω for D₀ ~ D₇ 10 k Ω for A₀ ~ A₁₅, R/ \overline{W} 10 k Ω for BA, BS , LIC, AVMA, BUSY

All diodes are 1S2074 (H) or equivalent, C includes stray capacitance,

Figure 4 Bus Timing Test Load

■ PROGRAMMING MODEL

As shown in Figure 5, the HD6309E adds three registers to the set available in the HD6800. The added registers include a Direct Page Register, the User Stack pointer and a second Index Register.

Accumulators (A, B, D)

The A and B registers are general purpose accumulators which are used for arithmetic calculations and manipulation of data.

Certain instructions concatenate the A and B registers to form a single 16-bit accumulator. This is referred to as the D Register, and is formed with the A Register as the most significant byte.

• Direct Page Register (DP)

The Direct Page Register of the HD6309E serves to enhance the Direct Addressing Mode. The content of this register appears at the higher address outputs ($A_8 \sim A_{15}$) during direct addressing instruction execution. This allows the direct mode to be used at any place in memory, under program control. To ensure HD6800 compatibility, all bits of this register are cleared during Processor Reset.

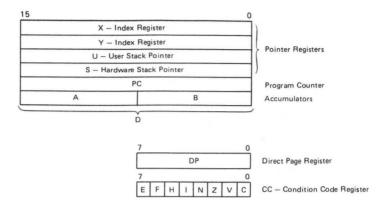


Figure 5 Programming Model of The Microprocessing Unit

Index Registers (X, Y)

The Index Registers are used in indexed mode of addressing. The 16-bit address in this register takes part in the calculation of effective addresses. This address may be used to point to data directly or may be modified by an optional constant or register offset. During some indexed modes, the contents of the index register are incremented or decremented to point to the next item of tabular type data. All four pointer registers (X, Y, U, S) may be used as index registers.

Stack Pointer (U, S)

The Hardware Stack Pointer (S) is used automatically by the processor during subroutine calls and interrupts. The User Stack Pointer (U) is controlled exclusively by the programmer thus allowing arguments to be passed to and from subroutines with ease. The U-register is frequently used as a stack marker. Both Stack Pointers have the same indexed mode addressing capabilities as the X and Y registers, but also support Push and Pull instructions. This allows the HD6309E to be used efficiently as a stack processor, greatly enhancing its ability to support higher level languages and modular programming.

(NOTE) The stack pointers of the HD6309E point to the top of the stack, in contrast to the HD6800 stack pointer, which pointed to the next free location on stack.

Program Counter (PC)

The Program Counter is used by the processor to point to the address of the next instruction to be executed by the processor. Relative Addressing is provided allowing the Program Counter to be used like an index register in some situations.

• Condition Code Register (CC)

The Condition Code Register defines the state of the processor at any given time. See Figure 6.

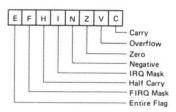


Figure 6 Condition Code Register Format

■ CONDITION CODE REGISTER DESCRIPTION

Bit 0 (C)

Bit 0 is the carry flag, and is usually the carry from the binary ALU. C is also used to represent a 'borrow' from subtract like instructions (CMP, NEG, SUB, SBC) and is the complement of the carry from the binary ALU.

Bit 1 (V)

Bit 1 is the overflow flag, and is set to a one by an operation which causes a signed two's complement arithmetic overflow. This overflow is detected in an operation in which the carry from the MSB in the ALU does not match the carry from the MSB-1.

Bit 2 (Z)

Bit 2 is the zero flag, and is set to a one if the result of the previous operation was identically zero.

Bit 3 (N)

Bit 3 is the negative flag, which contains exactly the value of the MSB of the result of the preceding operation. Thus, a negative two's-complement result will leave N set to a one.

• Bit 4 (1)

Bit 4 is the \overline{IRQ} mask bit. The processor will not recognize interrupts from the \overline{IRQ} line if this bit is set to a one. \overline{NMI} , \overline{FIRQ} , \overline{IRQ} , \overline{RES} and SWI all set I to a one; SWI2 and SWI3 do not affect I.

• Bit 5 (H)

Bit 5 is the half-carry bit, and is used to indicate a carry from bit 3 in the ALU as a result of an 8-bit addition only (ADC or ADD). This bit is used by the DAA instruction to perform a BCD decimal add adjust operation. The state of this flag is undefined in all subtract-like instructions.

• Bit 6 (F)

Bit 6 is the \overline{FIRQ} mask bit. The processor will not recognize interrupts from the \overline{FIRQ} line if this bit is a one. \overline{NMI} , \overline{FIRQ} , SWI, and \overline{RES} all set F to a one. \overline{IRQ} , SWI2 and SWI3 do not affect F.

Bit 7 (E)

Bit 7 is the entire flag, and when set to a one indicates that the complete machine state (all the registers) was stacked, as opposed to the subset state (PC and CC). The E bit of the stacked CC is used on a return from interrupt (RTI) to determine the extent of the unstacking. Therefore, the current E left in the Condition Code Register represents past action.

■ HD6309E MPU SIGNAL DESCRIPTION

Power (Vss, Vcc)

Two pins are used to supply power to the part: Vss is ground or 0 volts, while Vcc is +5.0 V ±10%.

Address Bus (A₀ ~ A₁₅)

Sixteen pins are used to output address information from the MPU onto the Address Bus. When the processor does not require the bus for a data transfer, it will output address FFFF $_{16}$, R/W = "High", and BS = "Low"; this is a "dummy access" or VMA cycle. All address bus drivers are made high-impedance when output Bus Available (BA) is "High" or when TSC is asserted. Each pin will drive one Schottky TTL load or four LS TTL loads, and 90 pF. Refer to Figures 1 and 2.

• Data Bus ($D_0 \sim D_7$)

These eight pins provide communication with the system bi-directional data bus. Each pin will drive one Schottky TTL load or four LS TTL loads, and 130 pF.

Read/Write (R/W)

This signal indicates the direction of data transfer on the data bus. A "Low" indicates that the MPU is writing data-onto the data bus. R/\overline{W} is made high impedance when BA is "High" or when TSC is asserted. Refer to Figures 1 and 2.

• RES

A "Low" level on this Schmitt-trigger input for greater than one bus cycle will reset the MPU, as shown in Figure 7. The Reset vectors are fetched from locations $FFFE_{16}$ and $FFFF_{16}$ (Table 1) when Interrupt Acknowledge is true, $(BA \cdot BS = 1)$. During initial power-on, the Reset line should be held "Low" until the clock input signals are fully operational.

Because the HD6309E Reset pin has a Schmitt-trigger input with a threshold voltage higher than that of standard peripherals, a simple R/C network may be used to reset the entire system.

This higher threshold voltage ensures that all peripherals are out of the reset state before the Processor.

Table 1 Memory Map for Interrupt Vectors

Memory Ma Locat	p for Vector ions	Interrupt Vector Description
MS	LS	Description
FFFE	FFFF	RES
FFFC	FFFD	NMI
FFFA	FFFB	SWI
FFF8	FFF9	ĪRQ
FFF6	FFF7	FIRO
FFF4	FFF5	SW12
FFF2	FFF3	SWI3
FFF0	FFF1	Reserved

• HALT

A "Low" level on this input pin will cause the MPU to stop running at the end of the present instruction and remain halted indefinitely without loss of data. When halted, the BA output is driven "High" indicating the buses are high impedance. BS is also "High" which indicates the processor is in the Halt state. While halted, the MPU will not respond to external real-time requests (FIRQ, \overline{IRQ}) although \overline{NMI} or \overline{RES} will be latched for later response. During the Halt state Q and E should continue to run normally. A halted state (BA \cdot BS = 1) can be achieved by pulling \overline{HALT} "Low" while \overline{RES} is still "Low". See Figure 8.

Bus Available, Bus Status (BA, BS)

The Bus Available output is an indication of an internal control signal which makes the MOS buses of the MPU high impedance. When BA goes "Low", a dead cycle will elapse before the MPU acquires the bus. BA will not be asserted when TSC is active, thus allowing dead cycle consistency.

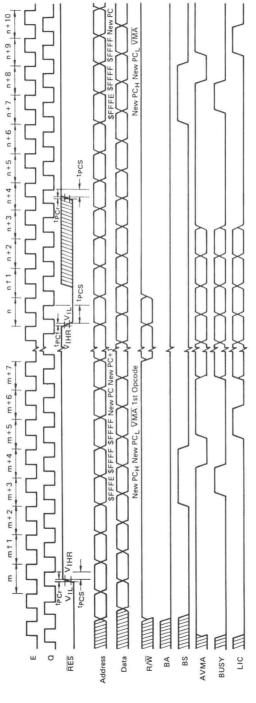
The Bus Status output signal, when decoded with BA, represents the MPU state (valid with leading edge of Q).

MPU State		MDI C D. C
ВА	BS	MPU State Definition
0	0	Normal (Running)
0	1	Interrupt or RESET Acknowledge
1	0	SYNC Acknowledge
1	1	HALT Acknowledge

Interrupt Acknowledge is indicated during both cycles of a hardware-vector-fetch (\overline{RES} , \overline{NMI} , \overline{FIRQ} , \overline{IRQ} , SWI, SWI2, SWI3). This signal, plus decoding of the lower four address lines, can provide the user with an indication of which interrupt level is being serviced and allow vectoring by device. See Table 1.

Sync Acknowledge is indicated while the MPU is waiting for external synchronization on an interrupt line.

Halt Acknowledge is indicated when the HD6309E is in a Halt condition.



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V_{IHmin} and logic "Low" = V_{ILmax} unless otherwise specified.

Figure 7 RES Timing

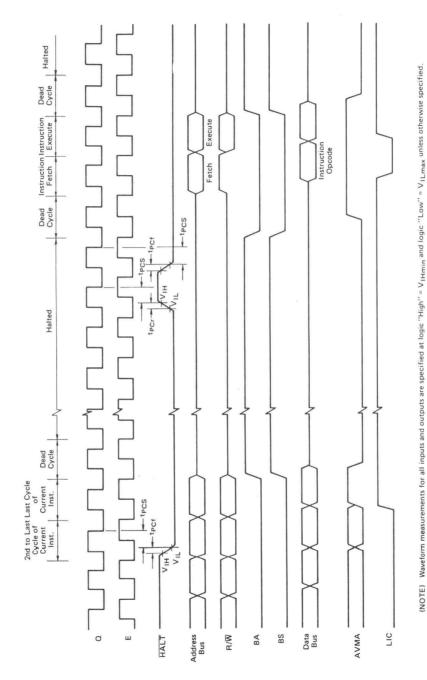


Figure 8 HALT and Single Instruction Execution for System Debug

Non Maskable Interrupt (NMI)*

A negative transition on this input requests that a non-maskable interrupt sequence be generated. A non-maskable interrupt cannot be inhibited by the program, and also has a higher priority than \overline{FIRQ} , \overline{IRQ} or software interrupts. During recognition of an \overline{NMI} , the entire machine state is saved on the hardware stack. After reset, an \overline{NMI} will not be recognized until the first program load of the Hardware Stack Pointer (S). The pulse width of \overline{NMI} low must be at least one E cycle. If the \overline{NMI} input does not meet the minimum set up with respect to Q, the interrupt will not be recognized until the next cycle. See Figure 9.

• Fast-Interrupt Request (FIRQ)*

A "Low" level on this input pin will initiate a fast interrupt sequence, provided its mask bit (F) in the CC is clear. This sequence has priority over the standard Interrupt Request (IRQ), and is fast in the sense that it stacks only the contents of the condition code register and the program counter. The interrupt service routine should clear the source of the interrupt before doing an RTI. See Figure 10.

• Interrupt Request (IRQ)*

A "Low" level input on this pin will initiate an Interrupt Request sequence provided the mask bit (I) in the CC is clear. Since IRQ stacks the entire machine state it provides a slower response to interrupts than FIRQ. IRQ also has a lower priority than FIRQ. Again, the interrupt service routine should clear the source of the interrupt before doing an RTI. See Figure 9.

* NMI, FIRQ, and IRQ requests are sampled on the falling edge of Q. One cycle is required for synchronization before these interrupts are recognized. The pending interrupt(s) will not be serviced until completion of the current instruction unless a SYNC or CWAI condition is present. If IRQ and FIRQ do not remain "Low" until completion of the current instruction they may not be recognized. However, NMI is latched and need only remain "Low" for one cycle.

Clock Inputs E, Q

E and Q are the clock signals required by the HD6309E, Q must lead E; that is, a transition on Q must be followed by a similar transition on E after a minimum delay. Addresses will be valid from the MPU, t_{AD} after the falling edge of E, and data will be latched from the bus by the falling edge of E. While the Q input is fully TTL compatible, the E input directly drives internal MOS circuitry and, thus, requires levels above normal TTL levels. This approach minimizes clock skew inherent with an internal buffer. Timing and waveforms for E and Q are shown in Figures 1 and 2 while Figure 11 shows a simple clock generator for the HD6309E.

BUSY

Busy will be "High" for the read and modify cycles of a readmodify-write instruction and during the access of the first byte of a double-byte operation (e.g., LDX, STD, ADDD). Busy is also "High" during the first byte of any indirect or other vector fetch (e.g., jump extended, SWI indirect etc.).

In a multi-processor system, busy indicates the need to defer the rearbitration of the next bus cycle to insure the integrity of the above operations. This difference provides the indivisible memory access required for a "test-and-set" primitive, using any one of several read-modify-write instructions.

Busy does not become active during PSH or PUL operations. A typical read-modify-write instruction (ASL) is shown in Figure 12. Timing information is given in Figure 13. Busy is valid t_{CD} after the rising edge of Q.

AVMA

AVMA is the Advanced VMA signal and indicates that the MPU will use the bus in the following bus cycle. The predictive nature of the AVMA signal allows efficient shared-bus multiprocessor systems. AVMA is "Low" when the MPU is in either a HALT or SYNC state. AVMA is valid t_{CD} after the rising edge of Q.

· LIC

LIC (Last Instruction Cycle) is "High" during the last cycle of every instruction, and its transition from "High" to "Low" will indicate that the first byte of an opcode will be latched at the end of the present bus cycle. LIC will be "High" when the MPU is Halted at the end of an instruction, (i.e., not in CWAI or RESET) in SYNC state or while stacking during interrupts. LIC is valid t_{CD} after the rising edge of Q.

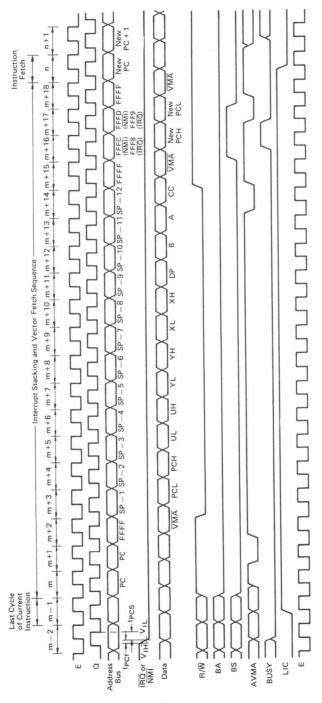
• TSC

TSC (Three-State Control) will cause MOS address, data, and R/W buffers to assume a high-impedance state. The control signals (BA, BS, BUSY, AVMA and LIC) will not go to the high-impedance state. TSC is intended to allow a single bus to be shared with other bus masters (processors or DMA controllers)

While E is "Low", TSC controls the address buffers and R/\overline{W} directly. The data bus buffers during a write operation are in a high-impedance state until Q rises at which time, if TSC is true, they will remain in a high-impedance state. If TSC is held beyond the rising edge of E, then it will be internally latched, keeping the bus drivers in a high-impedance state for the remainder of the bus cycle. See Figure 14.

MPU Operation

During normal operation, the MPU fetches an instruction from memory and then executes the requested function. This sequence begins after \overline{RES} and is repeated indefinitely unless altered by a special instruction or hardware occurrence. Software instructions that alter normal MPU operation are: SWI, SWI2, SWI3, CWAI, RTI and SYNC. An interrupt or \overline{HALT} input can also alter the normal execution of instructions. Figure 15 illustrates the flow chart for the HD6309E.



(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = VIHmin and logic "Low" = VILmax unless otherwise specified. E clock shown for reference only.

Figure 9 IRQ and NMI Interrupt Timing

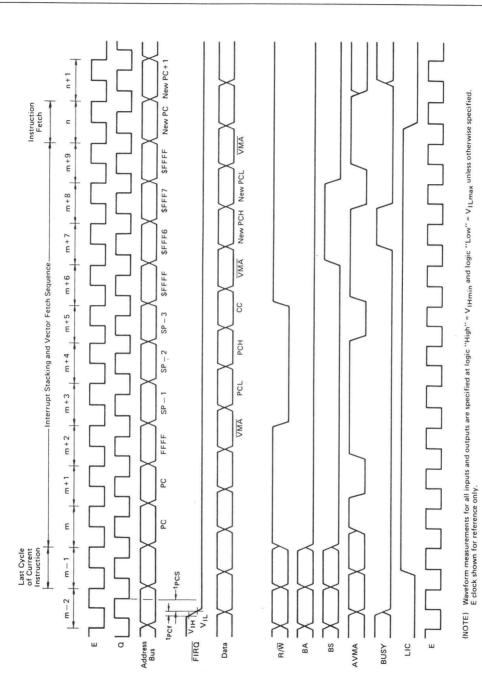


Figure 10 FIRO Interrupt Timing

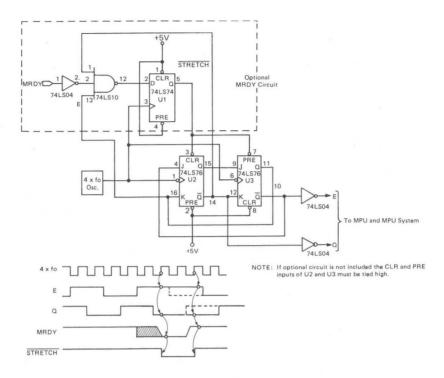


Figure 11 HD6309E Clock Generator

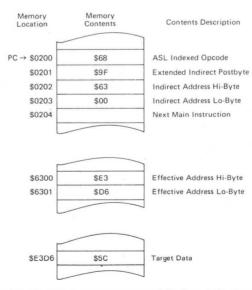
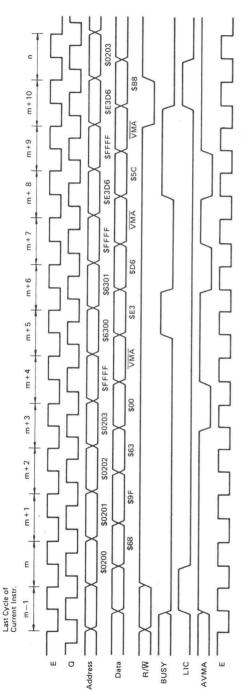
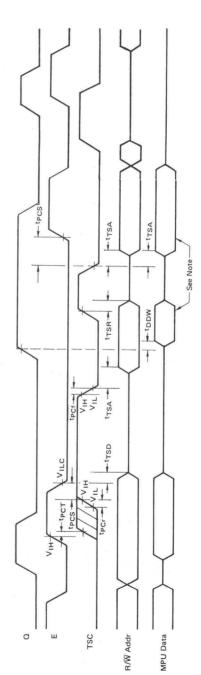


Figure 12 Read Modify Write Instruction Example (ASL Extended Indirect)



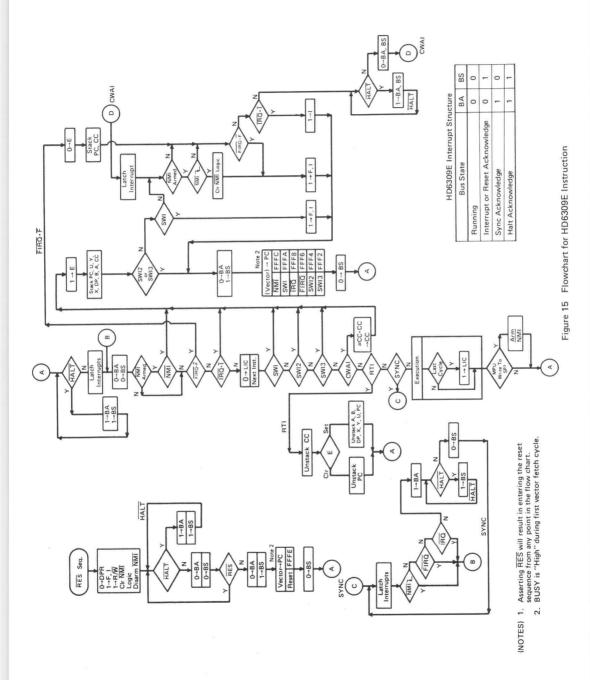
(NOTE) Waveform measurements for all inputs and outputs are specified at logic "High" = V_{IHmin} and logic "Low" = V_{ILmax} unless otherwise specified.

Figure 13 BUSY Timing (ASL Extended Indirect Instruction)



(NOTES) Data will be asserted by the MPU only during the interval while R/W is "Low" and E or Q is "High".
Waveform measurements for all inputs and outputs are specified at logic "High" = V _{I Hmin} and logic "Low" = V_{I Lmax} unless otherwise specified.

Figure 14 TSC Timing



ADDRESSING MODES

The basic instructions of any computer are greatly enhanced by the presence of powerful addressing modes. The HD6309E has the most complete set of addressing modes available on any microcomputer today. For example, the HD6309E has 59 basic instructions; however, it recognizes 1464 different variations of instructions and addressing modes. The addressing modes support modern programming techniques. The following addressing modes are available on the HD6309E:

- (1) Implied (Includes Accumulator)
- (2) Immediate
- (3) Extended
- (4) Extended Indirect
- (5) Direct
- (6) Register
- (7) Indexed

Zero-Offset

Constant Offset

Accumulator Offset

Auto Increment/Decrement

- (8) Indexed Indirect
- (9) Relative
- (10) Program Counter Relative

Implied (Includes Accumulator)

In this addressing mode, the opcode of the instruction contains all the address information necessary. Examples of Implied Addressing are: ABX, DAA, SWI, ASRA, and CLRB.

Immediate Addressing

In Immediate Addressing, the effective address of the data is the location immediately following the opcode (i.e., the data to be used in the instruction immediately follows the opcode of the instruction). The HD6309E uses both 8 and 16-bit immediate values depending on the size of argument specified by the opcode. Examples of instructions with Immediate Addressing are:

LDA #\$20 LDX #\$F000

LDY #CAT

(NOTE) # signifies immediate addressing, \$ signifies hexadecimal value.

Extended Addressing

In Extended Addressing, the contents of the two bytes immediately following the opcode fully specify the 16-bit effective address used by the instruction. Note that the address generated by an extended instruction defines an absolute address and is not position independent. Examples of Extended Addressing include:

LDA CAT STX MOUSE

LDD \$2000

Extended Indirect

As a special case of indexed addressing (discussed below), one level of indirection may be added to Extended Addressing. In Extended Indirect, the two bytes following the postbyte of an Indexed instruction contain the address of the data.

LDA [CAT] LDX [\$FFFE] STU [DOG]

Direct Addressing

Direct addressing is similar to extended addressing except that only one byte of address follows the opcode. This byte specifies the lower 8 bits of the address to be used. The upper 8 bits of the address are supplied by the direct page register. Since only one byte of address is required in direct addressing, this mode requires less memory and executes faster than extended addressing. Of course, only 256 locations (one page) can be accessed without redefining the contents of the DP register. Since the DP register is set to \$00 on Reset, direct addressing on the HD6309E is compatible with direct addressing on the HD6800. Indirection is not allowed in direct addressing. Some examples of direct addressing are:

LDA \$30 SETDP \$10 (Assembler directive) LDB \$1030 LDD < CAT

(NOTE) < is an assembler directive which forces direct addressing.

Register Addressing

Some opcodes are followed by a byte that defines a register or set of registers to be used by the instruction. This is called a postbyte. Some examples of register addressing are:

TFR X, Y Transfer X into Y
EXG A, B Exchanges A with B
PSHS A, B, X, Y Push Y, X, B and A onto S
PULU X, Y, D Pull D, X, and Y from U

Indexed Addressing

In all indexed addressing, one of the pointer registers $(X,\,Y,\,U,\,S,\,$ and sometimes PC) is used in a calculation of the effective address of the operand to be used by the instruction. Five basic types of indexing are available and are discussed below. The postbyte of an indexed instruction specifies the basic type and variation of the addressing mode as well as the pointer register to be used. Figure 16 lists the legal formats for the postbyte. Table 2 gives the assembler form and the number of cycles and bytes added to the basic values for indexed addressing for each variation.

	F	Post-E	Byte f	Regis	ter Bi	it		Indexed
7	6	5	4	3	2	1	0	Addressing Mode
0	R	R	d	d	d	d	d	EA = ,R + 5 Bit Offset
1	R	R	0	0	0	0	0	,R +
1	R	R	i	0	0	0	1	,R + +
1	R	R	0	0	0	1	0	, -R
1	R	R	i	0	0	1	1	, R
1	R	R	i	0	1	0	0	EA = ,R + 0 Offset
1	R	R	i	0	1	0	1	EA = ,R + ACCB Offset
1	R	R	i	0	1	1	0	EA = ,R + ACCA Offset
1	R	R	i	1	0	0	0	EA = , R + 8 Bit Offset
1	R	R	i	1	0	0	1	EA = ,R + 16 Bit Offset
1	R	R	i	1	0	1	1	EA = ,R + D Offset
1	×	×	i	1	1	0	0	EA = ,PC + 8 Bit Offset
1	×	×	i	1	1	0	1	EA = ,PC + 16 Bit Offse
1	R	R	i	1	1	1	1	EA = [,Address]
			L			Ĺ		Addressing Mode Field Indirect Field (Sigh bit when b7 = 0) Register Field : RR 00 = X
- Of	fset E	Bit on In		t				00 = X 01 = Y 10 = U 11 = S

Figure 16 Index Addressing Postbyte Register Bit Assignments

Table 2 Indexed Addressing Mode

		N	on Indirect				Indirect		_
Type	Forms	Assembler Form	Postbyte OP Code	+ ~	+ #	Assembler Form	Postbyte OP Code	+ ~	10
Constant Offset From R	No Offset	,R	1RR00100	0	0	[,R]	1RR10100	3	0
(2's Complement Offsets)	5 Bit Offset	n, R	0RRnnnnn	1	0	defaul	ts to 8-bit		
	8 Bit Offset	n, R	1RR01000	1	1	[n, R]	1RR11000	4	1
	16 Bit Offset	n, R	1RR01001	4	2	[n, R]	1RR11001	7	2
Accumulator Offset From R	A Register Offset	A, R	1RR00110	1	0	[A, R]	1RR10110	4	0
(2's Complement Offsets)	B Register Offset	B, R	1RR00101	1	0	[B, R]	1RR10101	4	0
	D Register Offset	D, R	1RR01011	4	0	[D, R]	1RR11011	7	0
Auto Increment/Decrement R	Increment By 1	,R +	1RR00000	2	0	not	allowed		
	Increment By 2	,R + +	1RR00001	3	0	[,R++]	1RR10001	6	0
	Decrement By 1	, - R	1RR00010	2	0	not	allowed		
	Decrement By 2	, R	1RR00011	3	0	[, R]	1RR10011	6	0
Constant Offset From PC	8 Bit Offset	n, PCR	1xx01100	1	1	[n, PCR]	1xx11100	4	1
(2's Complement Offsets)	16 Bit Offset	n, PCR	1xx01101	5	2	[n, PCR]	1xx11101	8	2
Extended Indirect	16 Bit Address	-	-	-	-	[n]	10011111	5	2

R = X, Y, U or S

RR:

x = Don't Care

00 = X01 = Y

10 = U

11 = S

Zero-Offset Indexed

In this mode, the selected pointer register contains the effective address of the data to be used by the instruction. This is the fastest indexing mode.

Examples are:

LDD 0, X

LDA S

Constant Offset Indexed

In this mode, a two's-complement offset and the contents of one of the pointer registers are added to form the effective address of the operand. The pointer register's initial content is unchanged by the addition.

Three sizes of offsets are available:

5-bit (-16 to +15)

8-bit (-128 to +127)

16-bit (-32768 to +32767)

The two's complement 5-bit offset is included in the postbyte and, therefore, is most efficient in use of bytes and cycles. The two's complement 8-bit offset is contained in a single byte following the postbyte. The two's complement 16-bit offset is in the two bytes following the postbyte. In most cases the programmer need not be concerned with the size of this offset since the assembler will select the optimal size automatically.

Examples of constant-offset indexing are:

LDA 23, X

LDX -2, S

LDY 300, X LDU CAT. Y

Accumulator-Offset Indexed

This mode is similar to constant offset indexed except that the two's-complement value in one of the accumulators (A, B or D) and the contents of one of the pointer registers are added to form the effective address of the operand. The contents of both the accumulator and the pointer register are unchanged by the addition. The postbyte specifies which accumulator to use as an offset and no additional bytes are required. The advantage of an accumulator offset is that the value of the offset can be calculated by a program at run-time.

Some examples are:

LDA B, Y

LDX D, Y

LEAX B, X

Auto Increment/Decrement Indexed

In the auto increment addressing mode, the pointer register contains the address of the operand. Then, after the pointer register is used it is incremented by one or two. This addressing mode is useful in stepping through tables, moving data, or for tie creation of software stacks. In auto decrement, the pointer register is decremented prior to use as the address of the data. The use of auto decrement is similar to that of auto increment; but the tables, etc., are scanned from the high to low addresses. The size of the increment/decrement can be either one or two to allow for tables of either 8- or 16-bit data to be accessed and is selectable by the programmer. The pre-

 $[\]stackrel{+}{\sim}$ and $\stackrel{+}{\#}$ indicate the number of additional cycles and bytes for the particular variation.

decrement, post-increment nature of these modes allow them to be used to create additional software stacks that behave identically to the U and S stacks.

Some examples of the auto increment/decrement addressing modes are:

LDA ,X+ STD ,Y++ LDB ,-Y LDX ,-S

Care should be taken in performing operations on 16-bit pointer registers (X, Y, U, S) where the same register is used to calculate the effective address.

Consider the following instruction:

STX 0, X + + (X initialized to <math>0)

The desired result is to store a 0 in locations \$0000 and \$0001 then increment X to point to \$0002. In reality, the following occurs:

 $0 \rightarrow \text{temp}$ calculate the EA; temp is a holding register $X + 2 \rightarrow X$ perform autoincrement $X \rightarrow (\text{temp})$ do store operation

Indexed Indirect

All of the indexing modes with the exception of auto increment/decrement by one, or a ±4-bit offset may have an additional level of indirection specified. In indirect addressing, the effective address is contained at the location specified by the contents of the Index Register plus any offset. In the example below, the A accumulator is loaded indirectly using an effective address calculated from the Index Register and an offset.

Before Execution
A = XX (don't care)
X = \$F000

\$0100 LDA [\$10, X] EA is now \$F010

\$F010 \$F1 \$F150 is now the
\$F011 \$50 new EA

\$F150 \$AA
After Execution
A = \$AA (Actual Data Loaded)
X = \$F000

All modes of indexed indirect are included except those which are meaningless (e.g., auto increment/decrement by 1 indirect). Some examples of indexed indirect are:

LDA [, X] LDD [10, S] LDA [B, Y] LDD [, X++]

Relative Addressing

The byte(s) following the branch opcode is (are) treated as a signed offset which may be added to the program counter. If the branch condition is true then the calculated address (PC + signed offset) is loaded into the program counter. Program execution continues at the new location as indicated by the PC; short (1 byte offset) and long (2 bytes offset) relative addressing modes are available. All of memory can be reached in long relative addressing as an effective address is interpreted modulo 2¹⁶. Some examples of relative addressing are:

BEQ CAT (short) BGT DOG (short) Program Counter Relative

The PC can be used as the pointer register with 8 or 16-bit signed offsets. As in relative addressing, the offset is added to the current PC to create the effective address. The effective address is then used as the address of the operand or data. Program Counter Relative Addressing is used for writing position independent programs. Tables related to a particular routine will maintain the same relationship after the routine is moved, if referenced relative to the Program Counter. Examples are:

LDA CAT, PCR LEAX TABLE, PCR

Since program counter relative is a type of indexing, an additional level of indirection is available.

LDA [CAT, PCR] LDU [DOG, PCR]

■ HD6309E INSTRUCTION SET

The instruction set of the HD6309E is similar to that of the HD6800 and is upward compatible at the source code level. The number of opcodes has been reduced from 72 to 59, but because of the expanded architecture and additional addressing modes, the number of available opcodes (with different addressing modes) has risen from 197 to 1464.

Some of the instructions are described in detail below:

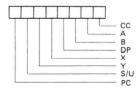
PSHU/PSHS

The push instructions have the capability of pushing onto either the hardware stack (S) or user stack (U) any single register, or set of registers with a single instruction.

PULU/PULS

The pull instructions have the same capability of the push instruction, in reverse order. The byte immediately following the push or pull opcode determines which register or registers are to be pushed or pulled. The actual PUSH/PULL sequence is fixed; each bit defines a unique register to push or pull, as shown in below.

PUSH/PULL POST BYTE



 ← Pull Order
 Push Order →

 PC
 U
 Y
 X
 DP
 B
 A
 CC

 FFFF

 ← increasing memory address

 0000

 PC
 S
 Y
 X
 DP
 B
 A
 CC

TFR/EXG

Within the HD6309E, any register may be transferred to or exchanged with another of like-size; i.e., 8-bit to 8-bit or 16-bit to 16-bit. Bits $4\sim7$ of postbyte define the source register, while bits $0\sim3$ represent the destination register. These are denoted as follows:

0000 - D	0101 - PC
0001 - X	1000 - A
0010 - Y	1001 - B
0011 - U	1010 - CC
0100 - S	1011 - DP

(NOTE) All other combinations are undefined and INVALID.

TRANSFER/EXCHANGE POST BYTE

	SOURCE	DESTINATION
--	--------	-------------

LEAX/LEAY/LEAU/LEAS

The LEA (Load Effective Address) works by calculating the effective address used in an indexed instruction and stores that address value, rather than the data at that address, in a pointer register. This makes all the features of the internal addressing hardware available to the programmer. Some of the implications of this instruction are illustrated in Table 3.

The LEA instruction also allows the user to access data in a position independent manner. For example:

	LEAX LBSR	MSG1, PCR PDATA (Print message routine)
MSG1	FCC	'MESSAGE'

This sample program prints: 'MESSAGE'. By writing MSG1, PCR, the assembler computes the distance between the present address and MSG1. This result is placed as a constant into the LEAX instruction which will be indexed from the PC value at the time of execution. No matter where the code is located, when it is executed, the computed offset from the PC will put the absolute address of MSG1 into the X pointer register. This code is totally position independent.

The LEA instructions are very powerful and use an internal holding register (temp). Care must be exercised when using the LEA instructions with the autoincrement and autodecrement addressing modes due to the sequence of internal operations. The LEA internal sequence is outlined as follows:

LEAa, b+ (any of the 16-bit pointer registers X, Y, U or S may be substituted for a and b.)

1. b → temp (calculate the EA)

2. b + 1 → b (modify b, postincrement)

3. temp \rightarrow a (load a)

LEAa, - b 1. $b-1 \rightarrow temp$ (calculate EA with predecrement) 2. $b-1 \rightarrow b$ (modify b, predecrement) 3. $temp \rightarrow a$ (load a)

Autoincrement-by-two and autodecrement-by-two instructions work similarly. Note that LEAX, X+ does not change X, however LEAX, -X does decrement X. LEAX 1, X should be used to increment X by one.

Table 3 LEA Examples

Instruction	Operation	Comment
LEAX 10, X	X + 10 → X	Adds 5-bit constant 10 to X
LEAX 500, X	X + 500 → X	Adds 16-bit constant 500 to X
LEAY A, Y	$Y + A \rightarrow Y$	Adds 8-bit A accumulator to Y
LEAY D, Y	$Y + D \rightarrow Y$	Adds 16-bit D accumulator to Y
LEAU -10, U	U - 10 → U	Subtracts 10 from U
LEAS -10, S	S - 10 → S	Used to reserve area on stack
LEAS 10. S	S + 10 → S	Used to 'clean up' stack
LEAX 5, S	$S+5 \rightarrow X$	Transfers as well as adds

MUL

Multiplies the unsigned binary numbers in the A and B accumulator and places the unsigned result into the 16-bit D accumulator. This unsigned multiply also allows multiple-precision multiplications.

Long and Short Relative Branches

The HD6309E has the capability of program counter relative branching throughout the entire memory map. In this mode, if the branch is to be taken, the 8 or 16-bit signed offset is added to the value of the program counter to be used as the effective address. This allows the program to branch anywhere in the 64k memory map. Position independent code can be easily generated through the use of relative branching. Both short (8-bit) and long (16-bit) branches are available.

SYNC

After encountering a Sync instruction, the MPU enters a Sync state, stops processing instructions and waits for an interrupt. If the pending interrupt is non-maskable (\overline{NMI}) or maskable $(\overline{FIRQ}, \overline{IRQ})$ with its mask bit (F or I) clear, the processor will clear the Sync state and perform the normal interrupt stacking and service routine. Since \overline{FIRQ} and \overline{IRQ} are not edge-triggered, a low level with a minimum duration of three bus cycles is required to assure that the interrupt will be taken. If the pending interrupt is maskable $(\overline{FIRQ}, \overline{IRQ})$ with its mask bit (F or I) set, the processor will clear the Sync state and continue processing by executing the next inline instruction. Figure 17 depicts Sync timing.

Software Interrupts

A Software Interrupt is an instruction which will cause an interrupt, and its associated vector fetch. These Software Interrupts are useful in operating system calls, software debugging, trace operations, memory mapping, and software development systems. Three levels of SWI are available on this HD6309E, and are prioritized in the following order: SWI, SWI2, SWI3.

16-Bit Operation

The HD6309E has the capability of processing 16-bit data. These instructions include loads, stores, compares, adds, subtracts, transfers, exchanges, pushes and pulls.

■ CYCLE-BY-CYCLE OPERATION

The address bus cycle-by-cycle performance chart illustrates the memory-access sequence corresponding to each possible instruction and addressing mode in the HD6309E. Each instruction begins with an opcode fetch. While that opcode is being internally decoded, the next program byte is always fetched. (Most instructions will use the next byte, so this

technique considerably speeds throughput.) Next, the operation of each opcode will follow the flow chart. \overline{VMA} is an indication of FFFF₁₆ on the address bus, R/\overline{W} = "High" and BS = "Low". The following examples illustrate the use of the chart; see Figure 18.

Example 1: LBSR (Branch Taken) Before Execution SP = F000

		•		
\$8000		LBSR	(CAT
\$A000	CAT			
		CYCLE	E-BY-CY	CLE FLOW
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	17	1	Opcode Fetch
2	8001	1 F	1	Offset High Byte
3	8002	FD	1	Offset Low Byte
4	FFFF	*	1	VMA Cycle
5	FFFF	*	1	VMA Cycle
6	FFFF	*	1	VMA Cycle
7	FFFF	*	1	VMA Cycle
8	EFFF	03	0	Stack Low Order
				Byte of Return
				Address

Example 2: DEC (Extended)

EFFE

\$8000	DEC		\$A0	00
\$A000	FCB		\$80	
		CYCL	E-BY-CYC	CLE FLOW
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	7A	1	Opcode Fetch
2	8001	A0	1	Operand Address,
				High Byte
3	8002	00	1	Operand Address,
				Low Byte
4	FFFF	*	1	VMA Cycle
5	A000	80	1	Read the Data
6	FFFF	*	1	VMA Cycle
7	A000	7F	0	Store the Decre-
				mented Data

80

Stack High Order Byte of Return Address

■ SLEEP MODE

During the interrupt wait period in the SYNC instruction (the SYNC state) and that period in the CWAI instruction (the WAIT state), MPU operation is halted and goes to the sleep mode. However, the state of I/O pins is the same as that of the HD6809E in this mode.

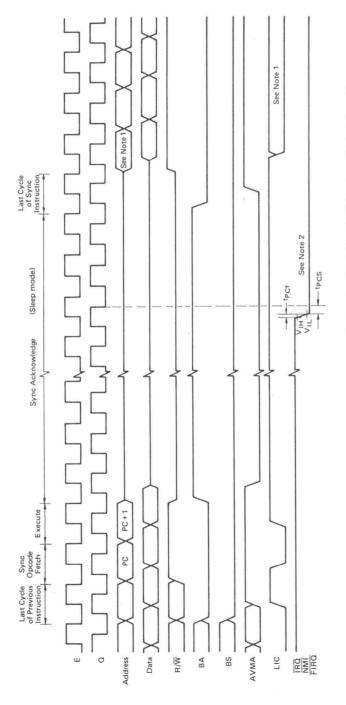
■ HD6309E INSTRUCTION SET TABLES

The instructions of the HD6309E have been broken down into five different categories. They are as follows:

8-Bit operation (Table 4)
16-Bit operation (Table 5)
Index register/stack pointer instructions (Table 6)
Relative branches (long or short) (Table 7)
Miscellaneous instructions (Table 8)

HD6309E instruction set tables and Hexadecimal Values of instructions are shown in Table 9 and Table 10.

^{*} The data bus has the data at that particular address.

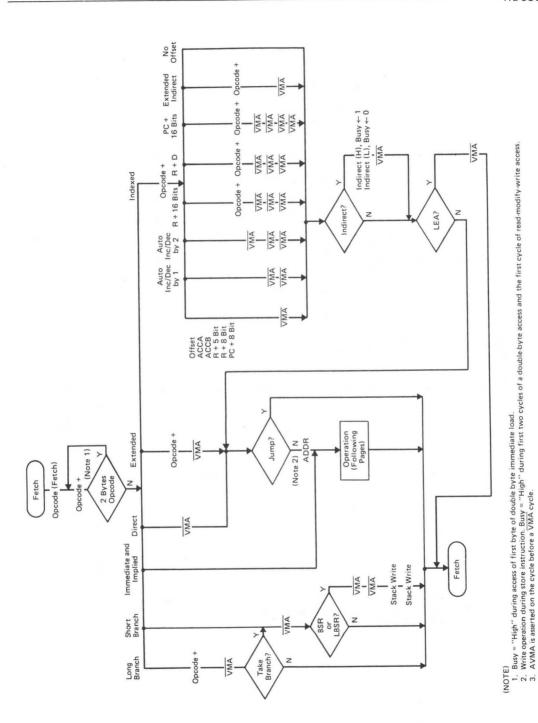


(NOTES) 1. If the associated mask bit is set when the interrupt is requested, LIC will go "Low" and this cycle will be an instruction fetch from address location PC + 1. However, it the interrupt is accepted (NMI) or a numasked FIRQ or IRQ) LIC will remain "High" and interrupt processing will start with this cycle as (m) on Figure 9 and 10 (Interrupt Timing).

2. If mask bits are clear, IRQ and FIRQ must be held "Low" for three cycles to guarantee that interrupt will be taken, although only one cycle is necessary to bring the processor out of SYMC.

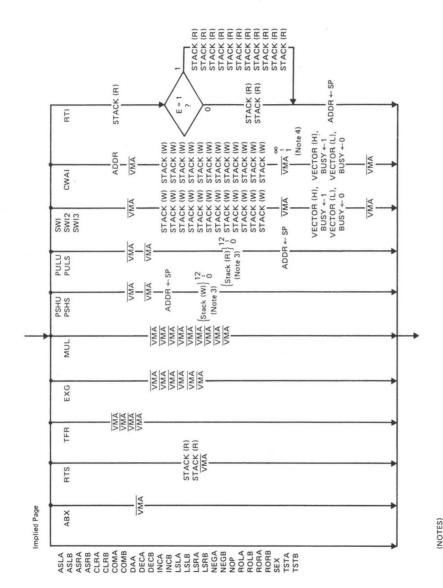
3. Waveform measurements for all inputs and outputs are specified at logic "High" = V₁Hmin and logic "Low" = V₁Lmax unless otherwise

Figure 17 SYNC Timing



(1) HITACHI

Figure 18 Address Bus Cycle-by-Cycle Performance

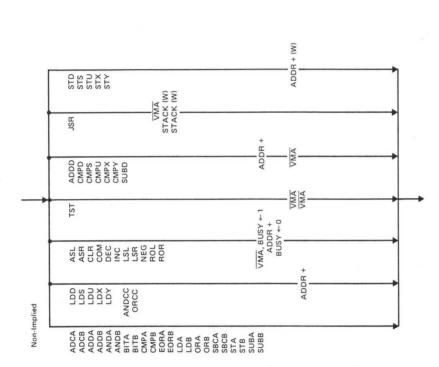


PSHU, PULU instructions use the user stack pointer (i.e., SP = U) and PSHS, PULS use the hardware stack pointer (i.e., SP = S). Stack (R) refers to the following sequence: ADDR ← SP with R/W = "High", then SP ← SP + 1. 1. Stack (W) refers to the following sequence: SP \leftarrow SP - 1, then ADDR \leftarrow SP with R/W = "Low"

Vector refers to the address of an interrupt or reset vector (see Table 1).
 The number of stack accesses will vary according to the number of bytes saved.
 VMA evoles will occur until an interrupt occurs.

VMA cycles will occur until an interrupt occurs,

Figure 18 Address Bus Cycle-by-Cycle Performance (Continued)



(NOTES)

1. Stack (W) refers to the following sequence: SP \leftarrow SP - 1, then ADDR \leftarrow SP with R/W = "Low" Stack (R) refers to the following sequence: ADDR \leftarrow SP with R/W = "High", then SP \leftarrow SP + 1. PSHU, PULU instructions use the user stack pointer (i.e., SP = S).

Vector refers to the address of an interrupt or reset vector (see Table 1).
 The number of stack accesses will vary according to the number of bytes saved.
 VMA cycles will occur until an interrupt occurs.

Figure 18 Address Bus Cycle-by-Cycle Performance (Continued)

Table 4 8-Bit Accumulator and Memory Instructions

Mnemonic(s)	Operation
ADCA, ADCB	Add memory to accumulator with carry
ADDA, ADDB	Add memory to accumulator
ANDA, ANDB	And memory with accumulator
ASL, ASLA, ASLB	Arithmetic shift of accumulator or memory left
ASR, ASRA, ASRB	Arithmetic shift of accumulator or memory right
BITA, BITB	Bit test memory with accumulator
CLR, CLRA, CLRB	Clear accumulator or memory location
CMPA, CMPB	Compare memory from accumulator
COM, COMA, COMB	Complement accumultor or memory location
DAA	Decimal adjust A accumulator
DEC, DECA, DECB	Decrement accumulator or memory location
EORA, EORB	Exclusive or memory with accumulator
EXG R1, R2	Exchange R1 with R2 (R1, R2 = A, B, CC, DP)
INC, INCA, INCB	Increment accumulator or memory location
LDA, LDB	Load accumulator from memory
LSL, LSLA, LSLB	Logical shift left accumulator or memory location
LSR, LSRA, LSRB	Logical shift right accumulator or memory location
MUL	Unsigned multiply $(A \times B \rightarrow D)$
NEG, NEGA, NEGB	Negate accumulator or memory
ORA, ORB	Or memory with accumulator
ROL, ROLA, ROLB	Rotate accumulator or memory left
ROR, RORA, RORB	Rotate accumulator or memory right
SBCA, SBCB	Subtract memory from accumulator with borrow
STA, STB	Store accumulator to memory
SUBA, SUBB	Subtract memory from accumulator
TST, TSTA, TSTB	Test accumulator or memory location
TFR R1, R2	Transfer R1 to R2 (R1, R2 = A, B, CC, DP)

(NOTE) A, B, CC or DP may be pushed to (pulled from) either stack with PSHS, PSHU (PULS, PULU) instructions.

Table 5 16-Bit Accumulator and Memory Instructions

Mnemonic(s)	Operation	
ADDD	Add memory to D accumulator	
CMPD	Compare memory from D accumulator	
EXG D, R	Exchange D with X, Y, S, U or PC	
LDD	Load D accumulator from memory	
SEX	Sign Extend B accumulator into A accumulator	
STD	Store D accumulator to memory	
SUBD	Subtract memory from D accumulator	
TFR D, R Transfer D to X, Y, S, U or PC		
TFR R, D	Transfer X, Y, S, U or PC to D	

(NOTE) D may be pushed (pulled) to either stack with PSHS, PSHU (PULS, PULU) instructions.



Table 6 Index Register Stack Pointer Instructions

Mnemonic(s)	Operation				
CMPS, CMPU	Compare memory from stack pointer				
CMPX, CMPY	Compare memory from index register				
EXG R1, R2	Exchange D, X, Y, S, U or PC with D, X, Y, S, U or PC				
LEAS, LEAU	Load effective address into stack pointer				
LEAX, LEAY	Load effective address into index register				
LDS, LDU	Load stack pointer from memory				
LDX, LDY	Load index register from memory				
PSHS	Push A, B, CC, DP, D, X, Y, U, or PC onto hardware stack				
PSHU	Push A, B, CC, DP, D, X, Y, S, or PC onto user stack				
PULS	Pull A, B, CC, DP, D, X, Y, U or PC from hardware stack				
PULU	Pull A, B, CC, DP, D, X, Y, S or PC from user stack				
STS, STU	Store stack pointer to memory				
STX, STY	Store index register to memory				
TFR R1, R2	Transfer D, X, Y, S, U or PC to D, X, Y, S, U or PC				
ABX	Add B accumulator to X (unsigned)				

Table 7 Branch Instructions

Mnemonic(s)	Operation
	SIMPLE BRANCHES
BEQ, LBEQ	Branch if equal
BNE, LBNE	Branch if not equal
BMI, LBMI	Branch if minus
BPL, LBPL	Branch if plus
BCS, LBCS	Branch if carry set
BCC, LBCC	Branch if carry clear
BVS, LBVS	Branch if overflow set
BVC, LBVC	Branch if overflow clear
	SIGNED BRANCHES
BGT, LBGT	Branch if greater (signed)
BGE, LBGE	Branch if greater than or equal (signed)
BEQ, LBEQ	Branch if equal
BLE, LBLE	Branch if less than or equal (signed)
BLT, LBLT	Branch if less than (signed)
	UNSIGNED BRANCHES
BHI, LBHI	Branch if higher (unsigned)
BHS, LBHS	Branch if higher or same (unsigned)
BEQ, LBEQ	Branch if equal
BLS, LBLS	Branch if lower or same (unsigned)
BLO, LBLO	Branch if lower (unsigned)
	OTHER BRANCHES
BSR, LBSR	Branch to subroutine
BRA, LBRA	Branch always
BRN, LBRN	Branch never

Table 8 Miscellaneous Instructions

Mnemonic(s)	Operation
ANDCC	AND condition code register
CWAI	AND condition code register, then wait for interrupt
NOP	No operation
ORCC	OR condition code register
JMP	Jump
JSR	Jump to subroutine
RTI	Return from interrupt
RTS	Return from subroutine
SWI, SWI2, SWI3	Software interrupt (absolute indirect)
SYNC	Synchronize with interrupt line

Table 9 HD 6309E Instruction Set Table

	UCTION/	12	MPLI	ED	D	IREC		1	TEN		IMN	IEDI		-	DEX	FD®	PE	LATI	VE	DECORVE	5	3	2	1	T
FC	ORMS	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~'5	#	DESCRIPTION	Н	N	Z	V	+
ABX	-	3A	3	1						-		8	_			-			-	B + X → X	•	•		•	+
ADC	ADCA ADCB				99 D9	4	2 2	B9 F9	5 5	3	89 C9	2 2	2 2	A9 E9	4+ 4+	2+ 2+				B + X → X (UNSIGNED) A + M + C → A B + M + C → B	1	‡	‡	‡	
ADD	ADDA ADDB ADDD				9B DB D3	4 4 6	2 2 2	BB FB F3	5 5 7	3 3 3	8B CB C3	2 2 4	2 2 3	AB EB E3	4+ 4+ 6+	2+ 2+ 2+				$A + M \rightarrow A$ $B + M \rightarrow B$	1	1	1	1	
AND	ANDA ANDB ANDCC				94 D4	4 4	2 2	B4 F4	5 5	3	84 C4 1C	2 2 3	2 2 2	A4 E4	4+	2+ 2+ 2+				$D + M:M + 1 \rightarrow D$ $A \land M \rightarrow A$ $B \land M \rightarrow B$ $CC \land IMM \rightarrow CC$		1 1	1 1 1	0 0 1	
ASL	ASLA ASLB ASL	48 58	2 2	1	08	6	2	78	7	3				68	6+	2+				A B C b7 b0	8 8 8	‡	1 1	1 1 1	
ASR	ASRA ASRB ASR	47 57	2 2	1	07	6	2	77	7	3				67	6+	2+				A B B B B B B B B B B B B B B B B B B B	8 8 8	: :	1		
всс	BCC LBCC																24 10 24	3 5(6)	2 4	Branch C = 0 Long Branch C = 0	•	•	•		
BCS	BCS LBCS																25 10 25	3 5(6)	2 4	Branch C = 1 Long Branch C = 1	•	•	•	•	-
BEQ	BEQ LBEQ																27 10 27	3 5(6)	2 4	Branch Z = 1 Long Branch Z = 1	•	•	:	•	
BGE	BGE LBGE																2C 10 2C	3 5(6)	2 4	Branch N⊕V=0 Long Branch N⊕V=0	•	•	•	•	
BGT	BGT LBGT																2E 10 2E	3 5(6)	2 4	Branch $Z \lor (N \oplus V) = 0$ Long Branch $Z \lor (N \oplus V) = 0$:	•	•	•	
ВНІ	BHI LBHI																22 10 22	3 5(6)	2 4	Branch C∨Z=0 Long Branch C∨Z=0	•	•	•		
BHS	BHS																24	3	2	Branch	•	0.			
	LBHS																10 24	5(6)	4	C=0 Long Branch C=0	•	•	•	•	
BIT	BITA BITB				95 D5	4	2 2	B5 F5	5 5	3	85 C5	2 2	2 2	A5 E5	4+ 4+	2+ 2+				Bit Test A $(M \land A)$ Bit Test B $(M \land B)$	•	1	1	0	
BLE	BLE LBLE																2F 10 2F	3 5(6)	2 4	Branch Z∨(N⊕V)=1 Long Branch Z∨(N⊕V)=1	:	•	•	•	
lLO	BLO LBLO																25 10 25	3 5(6)	2 4	Branch C=1 Long Branch C=1	•	•		•	
BLS	BLS																23	3	2	Branch	•	•	•	•	
	LBLS																10 23	5(6)	4	C∨Z=1 Long Branch C∨Z=1	•	•	•	•	
BLT	BLT LBLT						N.					#I					2D 10 2D	3 5(6)	2 4	Branch N ⊕ V=1 Long Branch N ⊕ V=1	•	•	•	•	
ВМІ	BMI LBMI																2B 10 2B	3 5(6)	2 4	Branch N=1 Long Branch N=1	•	•	•	•	
BNE	BNE LBNE																26 10 26	3 5(6)	2	Branch Z = 0 Long Branch Z = 0	•	•	•	•	
BPL	BPL LBPL																2A 10 2A	3 5(6)	2	Branch N = 0 Long Branch N = 0	:	•	•	•	
BRA	BRA LBRA																20 16	3 5	2 3	Branch Always Long Branch/ Always	:	•	•	•	
BRN	BRN LBRN																21 10 21	3 5	2 4	Branch Never Long Branch Never	•		•	•	

(to be continued)

INISTE	NOTTON/				,		_	09E A	_		T											_	_	_	_
	ORMS	11	IPLI	ED	D	IREC	T	EX	TEN	DED	IMN	/EDI	ATE	IN	DEX	ED@	RE	LATI	VE	DESCRIPTION	5	3	2	1	-
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~3	#		Н	N	Z	V	1
BSR	BSR																8D .	7	2	Branch to Subroutine	•	•	•		
	LBSR																17	9	3	Long Branch to Subroutine	•		•	•	
BVC	BVC LBVC																28 10 28	3 5(6)	2 4	Branch V = 0 Long Branch V = 0	•	•	•	•	
3VS	BVS LBVS																29 10 29	3 5(6)	2 4	Branch V = 1 Long Branch V = 1	•	•	•	•	
CLR	CLRA CLRB CLR	4F 5F	2	1	0F	6	2	7F	7	3				6F	6+	2+				0 → A 0 → B 0 → M		0 0	1 1 1	0 0 0	
CMP	CMPA CMPB CMPD				91 D1 10	4 4 7	2 2 3	B1 F1 10	5 5 8	3 3 4	81 C1 10	2 2 5	2 2 4	A1 E1 10	4+ 4+ 7+	2+ 2+ 3+				Compare M from A Compare M from B Compare M: M + 1	8	1 1 1 1 1	1	1	
	CMPS				93	7	3	B3	8	4	83	5	4	A3 11	7+	3+				from D Compare M: M + 1	•	1	1	1	
	CMPU				9C 11	7	3	BC 11	8	4	8C	5	4	AC 11	7+	3+				from S Compare M: M + 1	•	I	1	1	
	CMPX				93 9C	6	2	B3 BC	7	3	83 8C	4	3	A3 AC	6+	2+				from U Compare M: M + 1 from X	•	1	I	1	
	CMPY				10 9C	7	3	10 BC	8	4	10 8C	5	4	10 AC	7+	3+				Compare M: M + 1 from Y	•	1	1	1	
СОМ	COMA COMB COM	43 53	2	1	03	6	2	73	7	3				63	6+	2+				$\overline{A} \rightarrow A$ $\overline{B} \rightarrow B$ $\overline{M} \rightarrow M$	•	I I	1	0 0	
WAI											3C	≥20	2							CC ∧ IMM → CC (except 1→E) Wait for Interrupt	(-		7		
AA	DECA	19	2	1																Decimal Adjust A A – 1 → A	•	1	1	8	
DEC	DECA DECB DEC	4A 5A	2	1	0A	6	2	7A	7	3				6A	6+	2+				$\begin{array}{c} A - I \rightarrow A \\ B - 1 \rightarrow B \\ M - 1 \rightarrow M \end{array}$		I I	1	1	
OR	EORA EORB				98 D8	4	2 2	B8 F8	5 5	3	88 C8	2 2	2 2	A8 E8	4+ 4+	2+ 2+				$A \oplus M \rightarrow A$ $B \oplus M \rightarrow B$	•	1	1	0	
XG	R1, R2	1E	7	2																R1 R2 2	ţ-	-	10	_	
NC	INCA INCB INC	4C 5C	2	1	0C	6	2	7C	7	3				6C	6+	2+				$A + 1 \rightarrow A$ $B + 1 \rightarrow B$ $M + 1 \rightarrow M$		1 1 1	1	1	
MP					0E	3	2	7E	4	3				6E	3+	2+				EA PC					
SR					9D	7	2	BD	8	3				AD	7+	2+				Jump to Subroutine		•	•		
.D	LDA LDB LDD LDS				96 D6 DC	4 4 5 6	2 2 2 3	B6 F6 FC	5 5 6 7	3 3 4	86 C6 CC 10	2 2 3 4	2 2 3 4	A6 E6 EC	4+ 4+ 5+ 6+	2+ 2+ 2+ 3+				M → A M → B M: M + 1 → D M: M + 1 → S		1 1 1 1		0000	
	LDU				DE DE 9E	5	2 2	FE FE BE	6	3	CE CE 8E	3	3	EE EE AE	5+ 5+	2+				M: M + 1 → U M: M + 1 → X		1	1	0 0	
	LDX				10 9E	6	3	10 BE	7	4	10 8E	4	4	10 AE	6+	3+				M: M + 1 → Y	•	i	i	0	
.EA	LEAS LEAU LEAX LEAY							× .						32 33 30 31	4+ 4+ 4+ 4+	2+ 2+ 2+ 2+				$EA^{\frac{3}{2}} \rightarrow S$ $EA^{\frac{3}{2}} \rightarrow U$ $EA^{\frac{3}{2}} \rightarrow X$ $EA^{\frac{3}{2}} \rightarrow Y$			•		
SL	LSLA LSLB LSL	48 58	2 2	1	08	6	2	78	7	3				68	6+	2+				A B M		1 1	1 1 1	1 1 1	
SR	LSRA LSRB LSR	44 54	2 2	1	04	6	2	74	7	3				64	6+	2+				A B M		0 0 0	1 1 1		
IUL	2011	3D	11	1	54	J	2	, ,		3				-		-				$A \times B \rightarrow D$ (Unsigned)	•	•	t	•	
NEG	NEGA NEGB NEG	40 50	2 2	1 1.	00	6	2	70	7	3				60	6+	2+				$\overline{A} + 1 \rightarrow A$ $\overline{B} + 1 \rightarrow B$ $\overline{M} + 1 \rightarrow M$	(8)	1 1 1	1 1 1	‡	
IOP	IVEG	12	2	1	00	0	2	/0	/	3				60	0+	2+				M + 1 → M No Operation		•		•	

(to be continued)



INISTR	UCTION/						Н	D6309	EAD	DDRI	ESSIN	IG M	ODE								_			
	DRMS	- 11	MPLIE	ED	, D	IREC	T	EXTE	NDE	D	IMN	1EDI	ATE	IN	DEX	ED®	RE	LAT		DESCRIPTION	5	3	2	1
		OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~	#	OP	~3	#		Н	N	Z	V
OR	ORA ORB ORCC				9A DA	4	2 2	BA FA	5	3	8A CA 1A	2 2 3	2 2 2	AA EA	4+ 4+	2+ 2+				$A \lor M \rightarrow A$ $B \lor M \rightarrow B$ $CC \lor IMM \rightarrow CC$. (-	1	1 1 70	0
PSH	PSHS	34	5+4	2																Push Registers on	•	•	•	•
	PSHU	36	5+4	2																S Stack Push Registers on U Stack	•	•	•	•
PUL	PULS	35	5+4	2	- 1															Pull Registers from S Stack	(-	-	(10)	
	PULU	37	5+4	2																Pull Registers from U Stack	(-		(10)	
ROL	ROLA ROLB ROL	49 59	2 2	1	09	6	2	79	7	3				69	6+	2+				A B C b)		1 1 1	1 1 1	!!
ROR	RORA RORB ROR	46 56	2 2	1	06	6	2	76	7	3				66	6+	2+				A B		1 1 1	1 1	
RTI		3B	6/15	1																Return From Interrupt	(-		.7.	-
TS		39	5	1																Return From Subroutine	•	•	•	•
вс	SBCA SBCB				92 D2	4	2 2	B2 F2	5	3	82 C2	2 2	2	A2 E2	4+	2+ 2+				$\begin{array}{c} A-M-C \rightarrow A \\ B-M-C \rightarrow B \end{array}$	(8)	1	1	1
EX		1D	2	1																Sign Extend B into A	•	1	1	•
Т	STA STB STD STS				97 D7 DD 10 DF	4 4 5 6	2 2 2 3	B7 F7 FD 10 FF	5 5 6 7	3 3 4				A7 E7 ED 10 EF	4+ 4+ 5+ 6+	2+ 2+ 2+ 3+				$A \rightarrow M$ $B \rightarrow M$ $D \rightarrow M$: $M+1$ $S \rightarrow M$: $M+1$	•	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	1 1	0 0 0
	STU STX STY				DF 9F 10 9F	5 5 6	2 2 3	FF BF 10 BF	6 6 7	3 3 4				EF AF 10 AF	5+ 5+ 6+	2+ 2+ 3+				U → M: M + 1 X → M: M + 1 Y → M: M + 1	•	1 1	1	0 0
UB	SUBA SUBB SUBD				90 D0 93	4 4 6	2 2 2	B0 F0 B3	5 5 7	3 3	80 C0 83	2 2 4	2 2 3	A0 E0 A3	4+ 4+ 6+	2+ 2+ 2+				$A - M \rightarrow A$ $B - M \rightarrow B$ $D - M$: $M + 1 \rightarrow D$	8	1 1	:	1 1
WI	SWI ⁻⁶ . SWI ²⁻⁶ .	3F 10	19 20	1 2																Software Interrupt1 Software Interrupt2	•	:	:	•
	SWI3 6	3F 11 3F	20	2																Software Interrupt3	•	•	•	•
YNC		13	≥4	1																Synchronize to Interrupt	•	•	•	•
FR	R1, R2	1F	6	2																R1 → R2 2	(-	-	(10)	-
ST	TSTA TSTB TST	4D 5D	2 2	1	0D	6	2	7D	7	3				6D	6+	2+				Test A Test B Test M	•	1 1	1 1	0 0 0

(NOTES)

- 1 This column gives a base cycle and byte count. To obtain total count, and the values obtained from the INDEXED ADDRESSING MODES table.
 2 R1 and R2 may be any pair of 8 bit or any pair of 16 bit registers.
 The 8 bit registers are: A, B, CC, DP
 The 16 bit registers are: X, Y, U, S, D, PC
 3 EA is the effective address.
 4 The PSH and PUL instructions require 5 cycle plus 1 cycle for each byte pushed or pulled.
 5 16 means: 5 cycles if branch not taken, 6 cycles if taken.
 5 WI sets 1 and F bits, SWI2 and SWI3 do not affect I and F.
 6 Conditions Code sets and diverse result of the instruction.

- Conditions Codes set as a direct result of the instruction.
- Value of half-carry flag is undefined.
- Special Case Carry set if b7 is SET.
- Condition Codes set as a direct result of the instruction if CC is specified, and not affected otherwise.
 - LEGEND:
 - Operation Code (Hexadecimal)
 - Number of MPU Cycles Number of Program Bytes
 - #+ Arithmetic Plus
 - Arithmetic Minus Multiply Complement of M

 - ×
 - Transfer Into Half-carry (from bit 3) Negative (sign bit) → H N

- Zero (byte)
- Overflow, 2's complement Carry from bit 7
- Č Test and set if true, cleared otherwise
- Not Affected Condition Code Register
- CC
- Concatenation
- Logical or Logical and
- Logical Exclusive or



Table 10 Hexadecimal Values of Machine Codes

OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#
00	NEG	Direct	6	2	30	LEAX	Indexed	4+	2+	60	NEG	Indexed	6+	2+
01		A		-	31	LEAY	A	4+	2+	61		4		
02					32	LEAS	1	4+	2+	62				
03	COM		6	2	33	LEAU	Indexed	4+	2+	63	COM		6+	2+
04	LSR	1	6	2	34	PSHS	Implied	5+	2'	64	LSR		6+	2+
05	*	1	O	-	35	PULS	A	5+	2	65				_
06	ROR	1	6	2	36	PSHU	T	5+	2	66	ROR		6+	2+
07	ASR		6	2	37	PULU		5+	2	67	ASR		6+	2+
08	ASL, LSL		6	2	38	*		3.	2	68	ASL, LS	1	6+	2+
09	ROL	1	6	2	39	RTS		5	1	69	ROL	_	6+	2+
0A	DEC		6	2	3A	ABX	*	3	1	6A	DEC		6+	2+
OB	*	-		-	3B	RTI	Implied	6, 15	1	6B				
OC	INC		6	2	3C	CWAI	Immed	≥ 20	2	6C	INC		6+	2+
0D	TST	1	6	2	3D	MUL	Implied	11	1	6D	TST		6+	2+
OE	JMP	. ↓	3	2	3E					6E	JMP	•	3+	2+
OF	CLR	Direct	6	2	3F	SWI	Implied	19	1	6F	CLR	Indexed	6+	2+
10) See		-	_	40	NEGA	Implied	2	1	70	NEG	Extended	7	3
11	Next Page	-	-	_	41	•	4			71		A		
12	NOP	Implied	2	1	42	•	1			72	•			
13	SYNC	Implied	≥4	1	43	COMA		2	1	73	COM		7	3
14			= '		44	LSRA	1	2	1	74	LSR		7	3
15					45	•				75				
16	LBRA	Relative	5	3	46	RORA		2	1	76	ROR		7	3
17	LBSR	Relative	9	3	47	ASRA		2	1	77	ASR		7	3
18					48	ASLA, LSLA	1	2	1	78	ASL, LS	L	7	3
19	DAA	Implied	2	1	49	ROLA		2	1	79	ROL		7	3
1A	ORCC	Immed	3	2	4A	DECA		2	1	7A	DEC		7	3
1B	•	-			4B	•				7B	•			
1C	ANDCC	Immed	3	2	4C	INCA		2	1	7C	INC		7	3
1D	SEX	Implied	2	1	4D	TSTA		2	1	7D	TST		7	3
1E	EXG	Î	8	2	4E		*			7E	JMP	*	4	3
1F	TFR	Implied	6	2	4F	CLRA	Implied	2	1	7F	CLR	Extended	7	3
												,		
20	BRA	Relative	3	2	50	NEGB	Implied	2	1	80	SUBA	Immed	2	2
21	BRN	A	3	.2	51		4			81	CMPA	A	2	2
22	ВНІ		3	2	52					82	SBCA		2	2
23	BLS	1	3	2	53	COMB	1	2	1	83	SUBD		4	3
24	BHS, BCC	1	3	2	54	LSRB	1	2	1	84	ANDA		2	2
25	BLO, BCS		3	2	55	•				85	BITA		2	2
26	BNE	1	3	2	56	RORB	1	2	1	86	LDA	1	2	2
27	BEQ		3	2	57	ASRB	1	2	1	87		1		
28	BVC		3	2	58	ASLB, LSLB		2	1	88	EORA		2	2
29	BVS		3	2	59	ROLB		2	1	89	ADCA		2	2
2A	BPL		3	2	5A	DECB		2	1	8A	ORA	1	2	2
2B	BMI		3	2	5B					8B	ADDA	*	2	2
2C	BGE		3	2	5C	INCB		2	1	8C	CMPX	Immed	4	3
2D	BLT		3	2	5D	TSTB		2	1	8D	BSR	Relative	7	2
2E	BGT	₩	3	2	5E	•	*			8E	LDX	Immed	3	3
2F	BLE	Relative	3	2	5F	CLRB	Implied	2	1	8F	•			

LEGEND:

Number of MPU cycles (less possible push pull or indexed-mode cycles)

Number of program bytes

Denotes unused opcode

(to be continued)



OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	OP	Mnem	Mode	~	#	
90	SUBA	Direct	4	2	C6.	LDB	Immed	2	2	FC	LDD	Extended	6	3	
91	CMPA	A	4	2	C7		A			FD	STD	A	6	3	
92	SBCA	T	4	2	C8	EORB	T	2	2	FE	LDU	1	6	3	
93	SUBD	1	6	2	C9	ADCB		2	2	FF	STU	Extended	6	3	
94	ANDA		4	2	CA	ORB		2	2				•	•	
95	BITA		4	2	СВ	ADDB		2	2						
96	LDA		4	2	CC	LDD		3	3		2 Byte	s Opcode			
97	STA		4	2	CD	*	<u> </u>	J			20110				
98	EORA		4	2	CE	LDU	Immed	3	3	1021	LBRN	Relative	5	4	
99	ADCA		4	2	CF	*	mineu	3	3			helative			
9A	ORA			2	CF						LBHI	Ť	5(6)	4	
9B	ADDA		4	2	-	CLIDD			2		LBLS		5(6)	4	
					D0	SUBB	Direct	4	_		LBHS, I		5(6)	4	
9C	CMPX		6	2	D1	CMPB	A	4	2		LBCS, I	_BLO	5(6)	4	
9D	JSR	1	7	2	D2	SBCB		4	2		LBNE	1	5(6)	4	
9E	LDX	*	5	2	D3	ADDD		6	2		LBEQ	1	5(6)	4	
9F	STX	Direct	5	2	D4	ANDB		4	2		LBVC		5(6)	4	
					D5	BITB		4	2	1029	LBVS	1	5(6)	4	
A0	SUBA	Indexed	4+	2+	D6	LDB		4	2		LBPL		5(6)	4	
A1	CMPA	A	4+	2+	D7	STB	1	4	2	102B	LBMI		5(6)	4	
A2	SBCA	1	4+	2+	D8	EORB		4	2	102C	LBGE		5(6)	4	
A3	SUBD	1	6+	2+	D9	ADCB		4	2	102D	LBLT		5(6)	4	
A4	ANDA		4+	2+	DA	ORB		4	2	102E	LBGT	*	5(6)	4	
A5	BITA		4+	2+	DB	ADDB		4	2	102F	LBLE	Relative	5(6)	4	
A6	LDA		4+	2+	DC	LDD		5	2	103F	SWI2	Implied	20	2	
A7	STA		4+	2+	DD	STD		5	2		CMPD	Immed	5	4	
A8	EORA		4+	2+	DE	LDU		5	2		CMPY	‡	5	4	
A9	ADCA		4+	2+	DF	STU	Direct	5	2	108E		I mmed	4	4	
AA	ORA		4+	2+	0.	0.0	Birect	9	-		CMPD	Direct	7	3	
AB	ADDA		4+	2+	EO	SUBB	Indexed	4+	2+			Direct			
AC	CMPX		6+	2+	E1	CMPB	Maexed	4+	2+		CMPY	Ť	7	3	
AD	JSR		7+	2+	E2	SBCB	†			109E		*	6	3	
AE	LDX	L	5+	2+	E3	ADDD		4+ 6+	2+	109F		Direct	6	3	
AF	STX	, V							2+		CMPD	Indexed	7+	3+	
AF	SIX	Indexed	5+	2+	E4	ANDB		4+	2+		CMPY	Ť	7+	3+	
во	SUBA	Formar days	-	2	E5	BITB		4+	2+	10AE			6+	3+	
		Extended	5	3	E6	LDB		4+	2+	10AF		Indexed	6+	3+	
B1	CMPA	Ť	5	3	E7	STB		4+	2+		CMPD	Extended	8	4	
B2	SBCA		5	3	E8	EORB		4+	2+		CMPY	†	8	4	
B3	SUBD		7	3	E9	ADCB		4+	2+	10BE		*	7	4	
B4	ANDA		5	3	EA	ORB		4+	2+	10BF		Extended	7	4	
B5	BITA		5	3	EB	ADDB		4+	2+	10CE	LDS	Immed	4	4	
B6	LDA		5	3	EC	LDD		5+	2+	10DE	LDS	Direct	6	3	
B7	STA		5	3	ED	STD		5+	2+	10DF	STS	Direct	6	3	
B8	EORA		5	3	EE	LDU	•	5+	2+	10EE	LDS	Indexed	6+	3+	
B9	ADCA		5	3	EF	STU	Indexed	5+	2+	10EF	STS	Indexed	6+	3+	
BA	ORA		5	3						10FE	LDS	Extended	7	4	
BB	ADDA		5	3	FO	SUBB	Extended	5	3	10FF	STS	Extended	7	4	
BC	CMPX		7	3	F1	СМРВ	A	5	3	113F	SWI3	Implied	20	2	
BD	JSR	1	8	3	F2	SBCB	T	5	3		CMPU	Immed	5	4	
BE	LDX	•	6	3	F3	ADDD		7	3		CMPS	Immed	5	4	
BF	STX	Extended	6	3	F4	ANDB		5	3		CMPU	Direct	7	3	
			-	•	F5	BITB		5	3		CMPS	Direct	7	3	
CO	SUBB	Immed	2	2	F6	LDB		5	3		CMPU	Indexed	7+	3+	
C1	CMPB	A	2	2	F7	STB		5	3		CMPS	Indexed	7+	3+	1
C2	SBCB		2	2	F8	EORB		5	3		CMPU	Extended	8	4	1
C3	ADDD		4	3	F9	ADCB		5	3						
C4	ANDB	1	2	2						LIBC	CMPS	Extended	8	4	
					FA	ORB		5	3						
C5	BITB	Immed	2	2	FB	ADDB	Extended	5	3						

(NOTE): All unused opcodes are both undefined and illegal

■ NOTE FOR USE

Execution Sequence of CLR Instruction

Example: CLR (Extended)

\$8000	CLR	\$A000		
\$A000	FCB	\$80		
Cycle #	Address	Data	R/\overline{W}	Description
1	8000	7F	1	Opcode Fetch
2	8001	A0	1	Operand Address,
				High Byte
3	8002	00	1	Operand Address,
				Low Byte
4.	FFFF	*	1	VMA Cycle
5	A000	80	1	Read the Data
6	FFFF	*	1	VMA Cycle
7	A000	00	0	Store Fixed "00"
				into Specified
				Location

* The data bus has the data at that particular address.

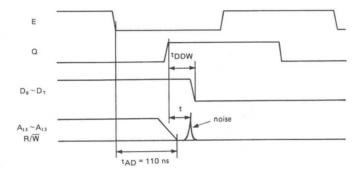
Cycle-by-cycle flow of CLR instruction (Direct, Extended, Indexed Addressing Mode) is shown below. In this sequence the content of the memory location specified by the operand is read before writing "00" into it. Note that status Flags, such as IRQ Flag, will be cleared by this extra data read operation when accessing the control/status register (sharing the same address between read and write) of peripheral devices.

The Noise of HD6309E at Bus Outputs Changing

We shall notify you of the noise of the HD6309E.

The noise over 0.8V may appear on the output signals when data bus or address bus outputs change from "High" to "Low". Problems and countermeasure are shown as follows.

The Noise at Data Bus Outputs Changing ("High→"Low")
 Problem: The noise over 0.8V may appear on A₁₅~A₁₃, R/W outputs change (worst case; \$FF→\$00) as shown in Figure 19.



Noise peak (worst case); about 1.5V

Test condition

 $T_a = -20^{\circ} C$ $V_{CC} = 5.5 V$

Number of data bus lines switching from "High" to "Low" = 8

(\$FF→\$00) data bus load capacitance = 130pF

Period of the noise occurrence (reference data)

 $t = 6 \sim 34 \text{ns} (Ta = -20^{\circ} C)$

t = 8~43ns (Ta = 25°C)

t = 12~54ns (Ta = 75°C)

Figure 19 Noise at data bus output changing

Countermeasure: If the noise level can not be reduced by controlling data bus load capacitance or reducing $V_{\rm CC}$ in your application system, connect damping resistors (about $100{\sim}150\Omega$) to data bus to reduce the noise level as shown in

Figure 20. Table 11 shows the relationship between damping resistors and electrical characteristics. Connecting damping resistors to data bus is effective to reduce the noise level as shown in Figure 21.



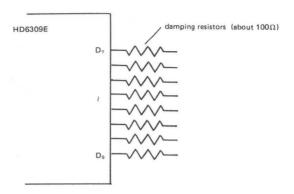


Figure 20 Connecting damping resistors to data bus

Table 11 The relationship between damping resistors and electrical characteristics

			$R = 0\Omega$	$R = 100 \sim 150\Omega$
HD63B09E		Ta = −20~0°C	20 ns	10 ns
(2MHz)	tDHW	Ta = 0~75°C	30 ns	15 ns
	t _{DDW}		70 ns	80 ns
HD63C09E (3MHz)	tounu	Ta = -20~0°C	20 ns	10 ns
	[†] DHW	Ta = 0~75°C	30 ns	15 ns

V peak Vn 10ns

Test condition $V_{CC} = 5.5V$ $Ta = -20^{\circ}C$ data bus load capacitance = 130pF

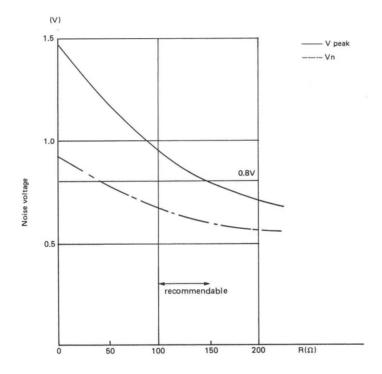
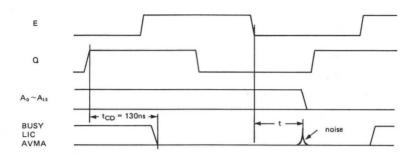


Figure 21 An example of the dependency of the noise voltage on damping resistors

2. The Noise at Address Bus Outputs Changing ("High" → "Low")

Problem: The noise over 0.8V may appear on BUSY, LIC,

AVMA outputs when address bus outputs change (worst case; \$FFFF→\$0000) as shown in Figure 22.



Noise peak (worst case); about 1.5V

Test condition

 $Ta = -20^{\circ}C$

V_{CC} = 5.5V Number of address bus lines switching from "High" to "Low" = 16 (\$FFFF→\$0000) address bus load capacitance = 90pF

Period of the noise occurrence (reference data)

 $t = 25\sim65$ ns (Ta = -20° C) $t = 30\sim74$ ns (Ta = 25° C) $t = 34\sim83$ ns (Ta = 75° C)

Figure 22 Noise at address bus output changing

Countermeasure: To prevent the noise on BUSY, LIC, AVMA outputs from appearing, this signals must be latched at the negative edge of E or Q clock as

shown in Figure 23. An example of countermeasure circuit is shown in Figure 24.

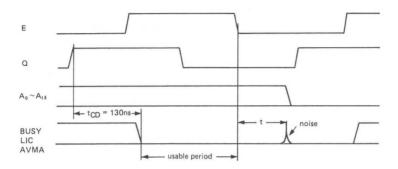


Figure 23 An example of countermeasure of the noise

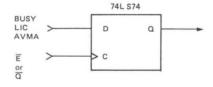


Figure 24 An example of countermeasure circuit

HD64A180R0, HD64B180R0 - CMOS MPU (Micro Processing Unit)

Based on a microcoded execution unit and advanced CMOS manufacturing technology, the HD64180 is an 8-bit MPU which provides the benefits of high performance, reduced system cost and low power operation while maintaining compatibility with the large base of industry standard 8-bit software.

Performance is improved by virtue of high operating frequency, pipelining, enhanced instruction set and an integrated Memory Management Unit (MMU) with 512k bytes memory physical address space.

System cost is reduced by incorporating key system functions on-chip including the MMU, two channel Direct Memory Access Controller (DMAC), wait state generator, dynamic RAM refresh, two channel Asynchronous Serial Communication Interface (ASCI), Clocked Serial I/O Port (CSI/O), two channel 16-bit Programmable Reload Timer (PRT), Versatile 12 source interrupt controller and a 'dual' $(68\times \times, 80\times \times)$ bus interface.

Low power consumption during normal CPU operation is supplemented by two specific software controlled low power operation modes.

The HD64180, when combined with CMOS VLSI memories and peripherals, is useful in system applications requiring high performance, battery power operation and standard software compatibility.

■ FEATURES

High Performance, High Integration CPU.

- · Operating Frequency to 6 MHz.
- On-Chip MMU Supports 512k Bytes Memory and 64k Bytes I/ O Address Space.
- Two Channel DMAC With Memory

 Memory, Memory
 Memory Mapped I/O Transfer Capability.
- WAIT Input and Wait State Generator for Slow Memory and I/O Device Interface.
- Programmable Dynamic RAM Refresh Addressing and Timing.
 Two Channel, Full Duplex Asynchronous Serial Communication
- Interface (ASCI) with Programmable Baud Rate Generator and Modem Control Handshake Signals.

 Clocked Serial I/O Port (CSI/O) with High Speed Operation
- Clocked Serial I/O Port (CSI/O) with High Speed Operation (200k Bits/Second at 4 MHz).
- Two Channel 16-bit Programmable Reload Timer (PRT) for Counting, Timing and Output Waveform Generation.
- Versatile Interrupt Controller Manages Four External and Eight Internal Interrupt Sources.
- 'Dual Bus' Interface Compatible With All Standard Memory and Peripheral LSI.
- · On-chip Clock Generator.

Enhanced Standard 8-bit Software Architecture.

- Fully Compatible with CP/M-80, CP/M Plus** and Existing System and Application Software.
- . Seven new Instructions including Multiply.
- On-chip I/O Address Relocation Register for Board Level Compatibility with Existing Systems and Software.
- SLEEP mode and SYSTEM STOP mode for Low Power Operation.

VLSI CMOS Process Technology.

Low Power Operation — 75 mW at 6 MHz Operation.

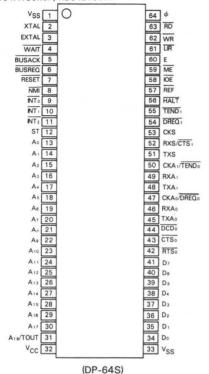
19 mW SYSTEM STOP mode at 6 MHz operation

- $V_{CC} = 5V \pm 10\% Fully TTL Compatible$.
- ** CP/M-80 and CP/M plus are registered trademarks of Digital Research, Inc.

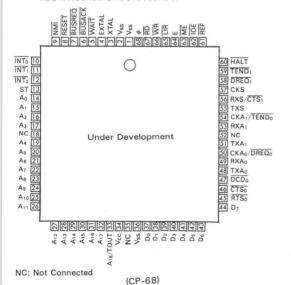


■ PIN ARRANGEMENT (Top View)

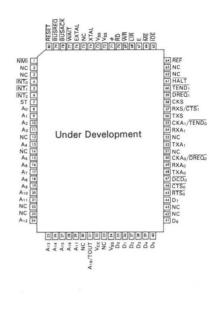
HD64A180ROP, HD64B180ROP



HD64A180R0CP, HD64B180R0CP



HD64A180R0F, HD64B180R0F

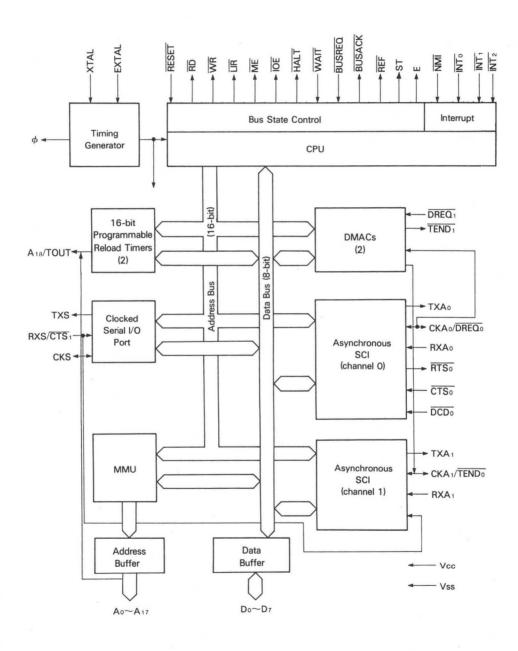


(FP-84)

Type Name	Operating Frequency	Package
HD64A180R0P	4	DD 040
HD64B180R0P	6	DP-64S
HD64A180R0F	4	FD 00*
HD64B180R0F	6	FP-80°
HD64A180R0CP	4	CP-68*
HD64B180R0CP	6	1 CP-68

^{*} Under Development

■ BLOCK DIAGRAM



M ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V _{cc}	-0.3~+7.0	V
Input Voltage	V _{in}	-0.3~V _{CC} +0.3	V
Operating Temperature	T _{opr}	0~+70	°C
Storage Temperature	T _{stg}	-55~+150	°C

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC} = 5V \pm 10%, V_{SS} = 0V, Ta = 0 \sim + 70 $^{\circ}$ C unless otherwise specified)

Item	Symbol	Condition	min	typ	max	Unit
Input ''H'' Voltage RESET, EXTAL, NMI	V _{IH1}		V _{CC} -0.6	-	V _{CC} +0.3	V
Input "H" Voltage Except RESET, EXTAL, NMI	V _{IH2}		2.0	-	V _{CC} +0.3	V
Input "L" Voltage RESET, EXTAL, NMI	V _{IL1}		-0.3	-	0.6	V
Input "L" Voltage Except RESET, EXTAL, NMI	V _{IL2}		-0.3	-	0.8	V
Output "H" Voltage	V	$I_{OH} = -200\mu A$	2.4	-	_	V
II Outputs	V _{OH}	$I_{OH} = -20\mu A$	V _{CC} -1.2	-	_	٧
Output "L" Voltage All Outputs	V _{OL}	$I_{OL} = 1.6 \text{ mA}$	-	-	0.45	V
Input Leakage Current All Inputs Except XTAL, EXTAL	I _{IL}	Vin=0.5 ~ V _{CC} -0.5	-	-	1.0	μΑ
Three State Leakage Current	I _{TL}	Vin=0.5 ~ V _{CC} -0.5	-	-	1.0	μΑ
Power Dissipation		f=4 MHz	_	10	20	mA
(Normal Operation)		f=6 MHz	_	15	30	
Power Dissipation	lcc	f=4 MHz	-	2.5	5.0	mA
(SYSTEM STOP mode)		f=6 MHz		3.8	7.5	mA
Pin Capacitance	Ср	Vin=0V, f=1 MHz Ta=25°C	_	-	12	pF

• AC CHARACTERISTICS ($V_{CC} = 5V \pm 10\%$, $V_{SS} = 0V$, $Ta = 0 \sim +70$ °C unless otherwise specified)

Item	Symbol	Condition	Н	D64A180	RO	H	ID64B180	RO	Unit
		Condition	min	typ	max	min	typ	max	Oilit
Clock Cycle Time	t _{cyc}		250	_	2000	162	_	2000	ns
Clock "H" Pulse Width	t _{CHW}		110	_	-	57	_	_	ns
Clock "L" Pulse Width	t _{CLW}		100	_	-	57	-	-	ns
Clock Fall Time	t _{cf}		-	-	25	-	_	25	ns
Clock Rise Time	t _{cr}		_	-	20	_	_	20	ns
Address Delay Time	t _{AD}		-	_	110 130*	-	-	105 125*	ns
Address Set-up Time (ME or IOE ↓)	t _{AS}		45 30**	-	-	10 -15**	-	-	ns
ME Delay Time 1	t _{MED1}	Fig.1(1)	_	-	85	_	_	75	ns
RD Delay Time 1	t _{RDD1}				85	_	_	75	ns
LIR Delay Time 1	t _{LD1}		-	-	105 120***	-	*	100	ns
Address Hold Time (ME or IOE †)	t _{AH}		80	-	-	35	-	-	ns
ME Delay Time 2	t _{MED2}	1	-	-	85	_	_	75	ns
RD Delay Time 2	t _{RDD2}	1	_	_	85	_	_	75	ns
LIR Delay Time 2	t _{LD2}		_	_	105	-	-	100	ns
Data Read Set-up Time	t _{DRS}	Fig. 1(1),(2),	50	_	_	45	_	_	ns
Data Read Hold Time	t _{DRH}	Fig.3(1)	0	_	_	0	_	_	ns
ST Delay Time 1	t _{STD1}	Fig.1(1),	_	_	110	-	_	100	ns
ST Delay Time 2	t _{STD2}	Fig.2	_	_	110	_	_	100	ns
WAIT Set-up Time	t _{ws}		80	_	-	70	_	_	ns
WAIT Hold Time	t _{WH}	1	70	_	1-1	60	-		ns
Write Data Floating Delay Time	t _{WDZ}	1 1	-	_	100	-	-	95	ns
WR Delay Time 1	t _{WRD1}	1	_	_	90	_	_	80	ns
Write Data Delay Time	t _{WDD}	1 1	_	_	110	_	_	90	ns
Write Data Set-up Time (WR ↓)	t _{WDS}	Fig.1(1)	60	-	-	40	_	-	ns
WR Delay Time 2	t _{WRD2}	1	-	_	90	_	_	80	ns
WR Pulse Width	t _{WRP}	1 1	220	-	_	135	_	_	ns
Write Data Hold Time (WR ↑)	t _{WDH}	1	60	_	-	40	-	-	ns
IOE Delay Time 1	t _{IOD1}	1 1	-	_	85	_	_	75	ns
IOE Delay Time 2	t _{IOD2}	1	-	_	85		_	75	ns
IOE Delay Time 3 (LIR ↓)	t _{IOD3}	Fig.1(2)	540	-	-	340	-		ns
INT Set-up Time (φ ↓)	t _{INTS}	Fig.1(2),	80	-	_	70	-		ns
INT Hold Time (φ ͺ)	\$NTH	Fig.5	70	-	i	60	_	-	ns
								(to be o	continued

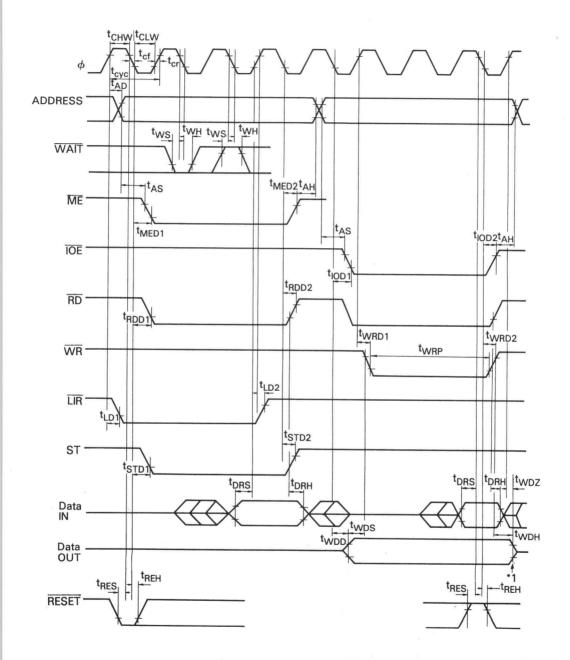
NOTE) Each symbols shows the value at the following conditions.

- *1. Just after RESET (Restart address = 00000H)

 2. At the beginning of SLEEP mode or SYSTEM STOP mode (Starting address = 7FFFFH)
- 3. After BUS RELEASE mode
- **1. Just after RESET (Restart address = 00000H)
- 2. After BUS RELEASE mode
- ***1. Just after RESET (Restart address = 00000H)

Item	Symbol	Condition	HD64A180R0			HD64B180R0			Unit
item	Symbol	Condition	min	typ	max	min	typ	max	Oill
NMI Pulse Width	t _{NMIW}	Fig.1(2), Fig.5	120	-	-	120	-	-	ns
BUSREQ Set-up Time	t _{BRS}		80	_	_	70	-	-	ns
BUSREQ Hold Time	t _{BRH}		70	-	_	60	_	-	ns
BUSACK Delay Time 1	t _{BAD1}	1	_	_	100	-	-	95	ns
BUSACK Delay Time 2	t _{BAD2}	1 1	_	-	100	_	_	95	ns
Bus Floating Delay Time	t _{BZD}]	_	_	130	-	_	125	ns
ME Pulse Width (HIGH)	^t MEWH	Fig.1(2)	200	-	-	110	-	-	ns
ME Pulse Width (LOW)	t _{MEWL}		210	-	-	125	-	-	ns
REF Delay Time 1	t _{RFD1}	1 1	_	-	110	_	_	100	ns
REF Delay Time 2	t _{RFD2}	1		-	110	-	_	100	ns
HALT Delay Time 1	t _{HAD1}	Fig. 1 (2),	_	-	110	-	-	100	ns
HALT Delay Time 2	t _{HAD2}	Fig.5	_	-	110	_	_	100	ns
DREQi Set-up Time	t _{DRQS}		80	-	-	70	-	_	ns
DREQi Hold Time	t _{DRQH}	Fig.2	70	_	-	60	_	-	ns
TENDi Delay Time 1	t _{TED1}		_		85	_	_	70	ns
TENDi Delay Time 2	t _{TED2}		_	-	85	_	-	70	ns
Enable Delay Time 1	t _{ED1}		_	-	100	-	_	95	ns
Enable Delay Time 2	t _{ED2}	Fig.3(1),(2)	_	_	100	_	_	95	ns
Timer Output Delay Time	t _{TOD}	Fig.4	_	1-1	300	_	-	300	ns
CSI/O Transmit Data Delay Time (Internal Clock Operation)	t _{STDI}		-	-	200	-	_	200	ns
CSI/O Transmit Data Delay Time (External Clock Operation)	t _{STDE}		-	-	7.5 t _{cyc} +300	-	-	7.5 t _{cyc} +300	ns
CSI/O Receive Data Set-up time (Internal Clock Operation)	t _{SRSI}	Fig.6	1	-	-	1	-	-	t _{cyc}
CSI/O Receive Data Hold Time (Internal Clock Operation)	t _{SRHI}		1	-	_	1	_	_	t _{cyc}
CSI/O Receive Data Set-up Time (External Clock Operation)	t _{SRSE}		1	-	-	1	-	-	t _{cyc}
CSI/O Receive Data Hold Time (External Clock Operation)	t _{SRHE}		1	-	_	1	-	-	t _{cyc}
RESET Set-up Time	t _{RES}	Fig.1(1)	120	_	_	120	_		ns
RESET Hold Time	t _{REH}	rig. 1(1)	80		-	80	-	-	ns
Oscillator Stabilization Time	tosc		-	-	20	-	-	20	ms





*1 Output buffer is off at this point.

Figure 1 CPU Timing (1)



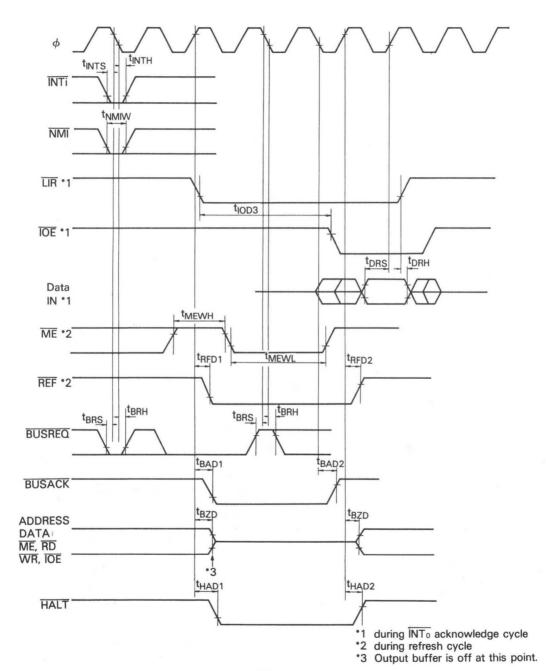


Figure 1 CPU Timing (2)



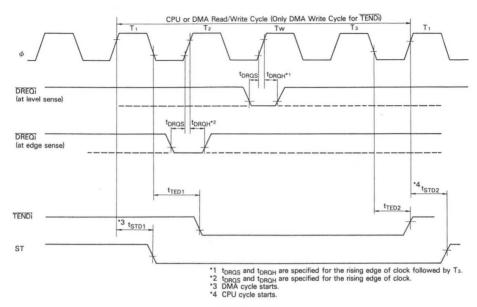


Figure 2 DMA Control Signals

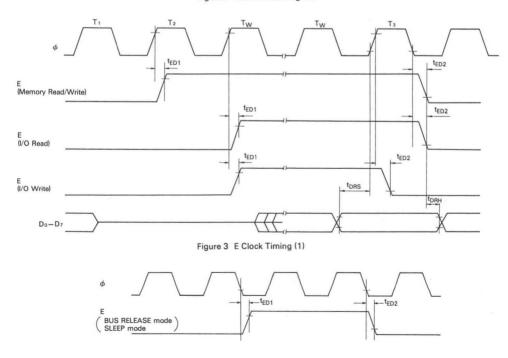


Figure 3 E Clock Timing (2)



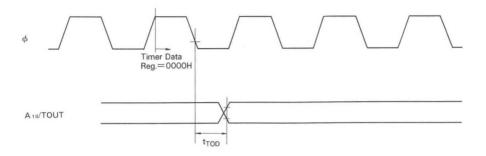


Figure 4 Timer Output Timing

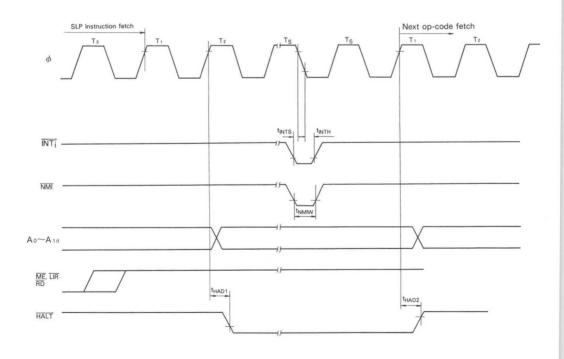


Figure 5 SLP Execution Cycle



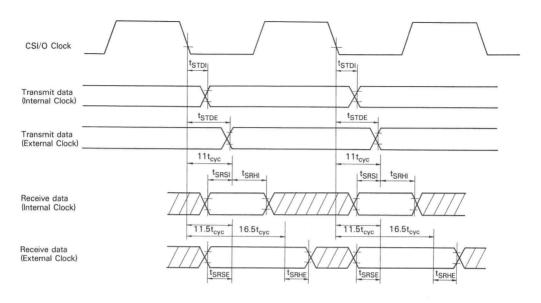
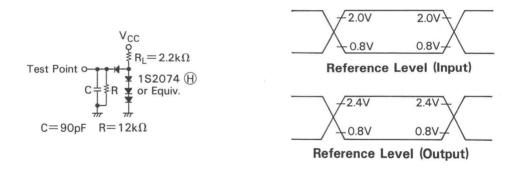
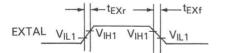


Figure 6 CSI/O Receive/Transmit Timing





tlf

EXTAL Rise time and Fall time

Inputs, other than EXTAL, Rise time and Fall time

Figure 7 Bus Timing Test Load (TTL Load)



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1 PIN DESCRIPTION

XTAL (IN)

Crystal oscillator connection. Should be left open if an external TTL clock is used. It is noted this input is not a TTL level input. See Table D.C. characteristics.

EXTAL (IN)

Crystal oscillator connection. An external TTL clock can be input on this line. This input is schmitt triggered.

System Clock. The frequency is equal to one-half of crystal oscillator.

RESET - CPU Reset (IN)

When LOW, initializes the HD64180 CPU, All output signals are held inactive during RESET.

A₀-A₁₇ - Address Bus (OUT, 3-STATE)

A₁₈/TOUT 19-bit address bus provides physical memory addresses of up to 512k bytes. The address bus enters the high impedance state during RESET and when another device acquires the bus as indicated by BUSREQ and BUSACK LOW. A, is multiplexed with the TOUT output from PRT channel 1. During RESET, the address bus function is selected. TOUT function can be selected under software control.

Do-D7 - Data Bus (IN/OUT, 3-STATE)

Bidirectional 8-bit data bus. The data bus enters the high impedance state during RESET and when another device acquires the bus as indicated by BUSREQ and BUSACK LOW.

RD - Read (OUT, 3-STATE)

Used during a CPU read cycle to enable transfer from the external memory or I/O device to the CPU data bus.

WR - Write (OUT, 3-STATE)

Used during a CPU write cycle to enable transfer from the CPU data bus to the external memory or I/O device.

ME - Memory Enable (OUT, 3-STATE)

Indicates memory read or write operation. The HD64180 asserts ME LOW in the following cases.

- (a) When fetching instructions and operands.
- (b) When reading or writing memory data.
- (c) During memory access cycles of DMA.
- (d) During dynamic RAM refresh cycles.

IOE - I/O Enable (OUT, 3-STATE)

Indicates I/O read or write operation. The HD64180 asserts IOE LOW in the following cases.

- (a) When reading or writing I/O data.
- (b) During I/O access cycles of DMA.
- (c) During INT₀ acknowledge cycle

WAIT - Bus Cycle Wait (IN)

Introduces wait states to extend memory and I/O cycles. If LOW at the falling edge of T2, a wait state (Tw) is inserted. Wait states will continue to be inserted until the WAIT input is sampled HIGH at the falling edge of Tw, at which time the bus cycle will proceed to completion.

E - Enable (OUT)

Synchronous clock for connection to HD63×× series and other 6800/6500 series compatible peripheral LSIs.

BUSREQ - Bus Request (IN)

Another device may request use of the bus by asserting BUSREQ LOW. The CPU will stop executing instructions and

places the address bus, data bus, RD, WR, ME and IOE in the high impedance state.

BUSACK - Bus Acknowledge (OUT)

When the CPU completes bus release (in response to BUSREQ LOW), it will assert BUSACK LOW. This acknowledges that the bus is free for use by the requesting device.

HALT - Halt/Sleep Status (OUT)

Asserted LOW after execution of the HALT or SLP instructions. Used with LIR and ST output pins to encode CPU status.

LIR - Load Instruction Register (OUT)

Asserted LOW when the current cycle is an op-code fetch cycle. Used with HALT and ST output pins to encode CPU status.

ST - Status (OUT)

Used with the HALT and LIR output pins to encode CPU

Table 1 Status Summary

ST	HALT	LIR	Operation
0	1	0	CPU operation (1st op-code fetch)
1	1	0	CPU operation (2nd op-code and 3rd op-code fetch)
1	1	1	CPU operation (MC except for op-code fetch)
0	Х	1	DMA operation
0	0	0	HALT mode
1	0	1	SLEEP mode (including SYSTEM STOP mode)

NOTE) X. Don't care

MC: Machine cycle

REF - Refresh (OUT)

When LOW, indicates the CPU is in the dynamic RAM refresh cycle and the low-order 8 bits (A₀-A₇) of the address bus contain the refresh address

NMI - Non-Maskable Interrupt (IN)

When edge transition from HIGH to LOW is detected, forces the CPU to save certain state information and vector to an interrupt service routine at address 0066H. The saved state information is restored by executing the RETN (Return from Non-Maskable Interrupt) instruction.

INT₀ - Maskable Interrupt Level 0 (IN)

When LOW, requests a CPU interrupt (unless masked) and saves certain state information unless masked by software. INTo requests service using one of three software programmable interrupt modes.

Mode	Operation		
0	Instruction fetched and executed from data bus.		
1	Instruction fetched and executed from address 0038H.		
2	Vector System — Low-order 8 bits vector table address fetched from data bus.		

In all modes, the saved state information is restored by executing RETI (Return from Interrupt) instruction.

INT₁, INT₂ - Maskable Interrupt Level 1, 2 (IN)
When LOW, requests a CPU interrupt (unless masked) and saves certain state information unless masked by software. INT and INT, (and internally generated interrupts) request interrupt service using a vector system similar to Mode 2 of INT₀.

DREQ - DMA Request - Channel 0 (IN)

When LOW (programmable edge or level sensitive), requests DMA transfer service from channel 0 of the HD64180 DMAC. \overline{DREQ}_0 is used for Channel 0 memory \iff I/O and memory \iff memory mapped I/O transfers. \overline{DREQ}_0 is not used for memory \iff memory transfers. This pin is multiplexed with CKA₀.

TEND₀ - Transfer End - Channel 0 (OUT)

Asserted LOW synchronous with the last write cycle of channel 0 DMA transfer to indicate DMA completion to an external device. This pin is multiplexed with CKA1.

DREQ1 - DMA Request - Channel 1 (IN)

When LOW (programmable edge or level sense), requests DMA transfer service from channel 1 of the HD64180 DMAC. Channel 1 supports Memory ← > I/O transfers.

TEND₁ - Transfer End - Channel 1 (OUT)

nous Serial Communication Interface (ASCI).

Asserted LOW synchronous with the last write cycle of channel 1 DMA transfer to indicate DMA completion to an external device.

TXA₀ - Asynchronous Transmit Data - Channel 0 (OUT) Asynchronous transmit data from channel 0 of the Asynchro-

RXA₀ - Asynchronous Receive Data - Channel 0 (IN) Asynchronous receive data to channel 0 of the ASCI.

CKA₀ - Asynchronous Clock - Channel 0 (IN/OUT)

Clock input/output for channel 0 of the ASCI. This pin is multiplexed (software selectable) with DREQ0.

RTS₀ - Request to Send - Channel 0 (OUT)

Programmable modem control output signal for channel 0 of the

CTS₀ - Clear to Send - Channel 0 (IN)

Modem control input signal for channel 0 of the ASCI.

DCD₀ - Data Carrier Detect - Channel 0 (IN)

Modem control input signal for channel 0 of the ASCI.

TXA₁ - Asynchronous Transmit Data - Channel 1 (OUT) Asynchronous transmit data from channel 1 of the ASCI. RXA₁ - Asynchronous Receive Data - Channel 1 (IN)

Asynchronous receive data to channel 1 of the ASCI.

CKA₁ - Asynchronous Clock - Channel 1 (IN/OUT)

Clock input/output for channel 1 of the ASCI. This pin is multiplexed (software selectable) with TEND

CTS₁ - Clear to Send - Channel 1 (IN)

Modem control input signal for channel 1 of the ASCI. This pin is multiplexed (software selectable) with RXS.

TXS - Clocked Serial Transmit Data (OUT)

Clocked serial transmit data from the Clocked Serial I/O Port (CSI/O).

RXS - Clocked Serial Receive Data (IN)

Clocked serial receive data to the CSI/O. This pin is multiplexed (software selectable) with ASCI channel 1 CTS1 modem control

CKS - Serial Clock (IN/OUT)

Input or output clock for the CSI/O.

TOUT - Timer Output (OUT)

Pulse output from Programmable Reload Timer channel 1. This pin is multiplexed (software selectable) with A₁₈ (Address 18).

V_{CC} - Power Supply

V_{SS} - Ground

Multiplexed pin descriptions

A₁₈/TOUT

During RESET, this pin is initialized as A18 pin. If either TOC1 or TOC0 bit in Timer Control Register (TCR) is set to 1, TOUT function is selected.

If TOC1 and TOC0 bits are cleared to 0, A₁₈ function is selected.

CKA0/DREQ0

During RESET, this pin is initialized as CKA₀ pin. If either DM1 or SM1 in DMA Mode Register (DMODE) is set to 1, DREQ0 function is always selected.

 ${\sf CKA_1/\overline{TEND_0}}$ During RESET, this pin is initialized as ${\sf CKA_1}$ pin. If $\overline{\sf CKA1D}$ bit in ASCI control register ch 1 (CNTLA1) is set to 1, TEND, function is selected. If CKA1D bit is set to 0, CKA, function is selected.

RXS/CTS₁

During RESET, this pin is initialized as RXS pin. If CTS1E bit in ASCI status register ch1 (STAT1) is set to 1, CTS, function is selected.

If CTS1E bit is set to 0, RXS function is selected.

2 CPU REGISTERS

The HD64180 CPU registers consist of Register Set GR, Register Set GR' and Special Registers.

The Register Set GR consists of 8-bit Accumulator (A), 8-bit Flag Register (F), and three General Purpose Registers (BC, DE, and HL) which may be treated as 16-bit registers (BC, DE, and HL) or as individual 8-bit registers (B, C, D, E, H, and L) depending on the instruction to be executed. The Register Set GR' is alternate register set of Register Set GR and also contains Accumulator

(A'), Flag Register (F') and three General Purpose Registers (BC', DE', and HL). While the alternate Register Set GR' contents are not directly accessible, the contents can be programmably exchanged at high speed with those of Register Set GR.

The Special Registers consist of 8-bit Interrupt Vector Register (I), 8-bit R Counter (R), two 16-bit Index Registers (IX and IY), 16-bit Stack Pointer (SP), and 16-bit Program Counter (PC).

Fig. 8 shows CPU registers configuration.

Register Set GR

Accumulator A	Flag Register F
B Register	C Register
D Register	E Register
H Register	L Register

General Purpose Registers

Register Set GR'

Accumulator A'	Flag Register F'
B' Register	C' Register
D' Register	E' Register
H' Register	L' Register

General Purpose Registers

	0
Interrupt Vector Register	R Counter
1	R
Index Register	IX
Index Register	IY
Stack Pointer	SP
Program Coun	ter PC

Special Registers

Figure 8 CPU Register Configuration

2.1 Register Description

(1) Accumulator (A, A')

The Accumulator (A) serves as the primary register used for many arithmetic, logical and I/O instructions.

(2) Flag Registers (F, F')

The flag register stores various status bits (described in the next section) which reflect the results of instruction execution.

(3) General Purpose Registers (BC, BC', DE, DE', HL, HL')

The General Purpose Registers are used for both address and data operation. Depending on instruction, each half (8 bits) of these registers (B, C, D, E, H, and L) may also be used.

(4) Interrupt Vector Register (I)

For interrupts which require a vector table address to be calculated $(\overline{INT}_0 \text{ Mode 2, } \overline{INT}_1, \overline{INT}_2 \text{ and internal interrupts})$, the Interrupt Vector Register (I) provides the most significant byte of the vector table address.

(5) R Counter (R)

The least significant seven bits of the R Counter (R) serve to count the number of instructions executed by the HD64180. R is

incremented for each CPU op-code fetch cycles (each LIR cycles).

(6) Index Registers (IX, and IY)

The Index Registers are used for both address and data operations. For addressing, the contents of a displacement specified in the instruction are added to or subtracted from the Index Register to determine an effective operand address.

(7) Stack Pointer (SP)

The Stack Pointer (SP) contains the memory address based LIFO stack.

(8) Program Counter (PC)

The Program Counter (PC) contains the address of the instruction to be executed and is automatically updated after each instruction fetch.

(9) Flag Register (F)

The Flag Register stores the logical state reflecting the results of instruction execution. The contents of the Flag Register are used to control program flow and instruction operation.

bit 7 6 5 4 3 2 1 0
S Z - H - P/V N C Flag Register (F)

S: Sign (bit 7)

S stores the state of the most significant bit (bit 7) of the result. This is useful for operations with signed numbers in which values with bit 7 = 1 are interpreted as negative.

Z: Zero (bit 6)

Z is set to 1 when instruction execution results containing 0. Otherwise, Z is reset to 0.

H: Half Carry (bit 4)

H is used by the DAA (Decimal Adjust Accumulator) instruction to reflect borrow or carry from the least significant 4 bits and thereby adjust the results of BCD addition and subtraction.

P/V: Parity/Overflow (bit 2)

P/V serves a dual purpose. For logical operations P/V is set to 1 if the number of 1 bit in the result is even and P/V is reset to 0 if the number of 1 bit in the result is odd. For two complement arithmetic, P/V is set to 1 if the operation produces a result which is outside the allowable range (+127 to -128 for 8-bit operations, +32767 to -32768 for 16-bit operations).

N: Negative (bit 1)

N is set to 1 if the last arithmetic instruction was a subtract operation (SUB, DEC, CP, etc.) and N is reset to 0 if the last arithmetic

8-bit Register

g or g' field	Register
0 0 0	В
0 0 1	С
0 1 0	D
0 1 1	Е
1 0 0	Н
1 0 1	L
1 1 0	_
1 1 1	Α

16-bit Register

zz field	Register
0 0	ВС
0 1	DE
1 0	HL
1 1	A F

instruction was an addition operation (ADD, INC, etc.).

C: Carry (bit 0)

C is set to 1 when a carry (addition) or borrow (subtraction) from the most significant bit of the result occurs. C is also affected by Accumulator logic operations such as shifts and rotates.

3 ADDRESSING MODES

The HD64180 instruction set includes eight addressing modes.

Implied Register

Register Direct Register Indirect

Indexed

Extended

Immediate

Relative

IO

(1) Implied Register (IMP)

Certain op-codes automatically imply register usage, such as the arithmetic operations which inherently reference the Accumulator, Index Registers, Stack Pointer and General Purpose Registers.

(2) Register Direct (REG)

Many op-codes contain bit fields specifying registers to be used for the operation. The exact bit field definition vary depending on instruction as follows.

ww field	Register	
0 0	ВС	
0 1	DE	
1 0	HL	
1 1	SP	

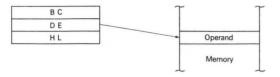
Register	
ВС	
DE	
ΙX	
SP	
	B C D E I X

yy field	Register
0 0	ВС
0 1	DE
1 0	LIY
1 1	SP

Suffixed H and L to ww,xx,yy,zz (ex. wwH,IXL) indicate upper and lower 8-bit of the 16-bit register respectively.

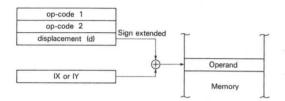
(3) Register Indirect (REG)

The memory operand address is contained in one of the 16-bit General Purpose Registers (BC, DE and HL).



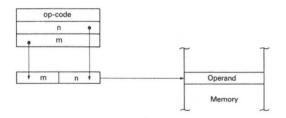
(4) Indexed (INDX)

The memory operand address is calculated using the contents of an Index Register (IX or IY) and an 8-bit signed displacement specified in the instruction.



(5) Extended (EXT)

The memory operand address is specified by two bytes contained in the instruction.



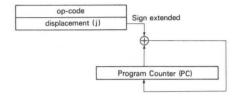
(6) Immediate (IMMED)

The memory operands are contained within one or two bytes of the instruction.



(7) Relative (REL)

Relative addressing mode is only used by the conditional and unconditional branch instructions. The branch displacement (relative to the contents of the program counter) is contained in the instruction.



(8) 10 (10)

IO addressing mode is used only by I/O instructions. This mode specifies I/O address ($\overline{\text{IOE}} = 0$) and outputs them as follows.

- (1) An operand is output to A₀-A₇. The Contents of Accumulator is output to A8-A15.
- (2) The Contents of Register B is output to A₀-A₇. The Contents
- of Register C is output to A_8 - A_{15} . (3) An operand is output to A_0 - A_7 . 00H is output to A_8 - A_{15} . (useful for internal I/O register access)
- (4) The Contents of Register C is output to A₀-A₇. 00H is output to A8-A15. (useful for internal I/O register access)

4 CPU BUS TIMING

This section explains the HD64180 CPU timing for the following operations.

- (1) Instruction (op-code) fetch timing.
- (2) Operand and data read/write timing.
- (3) I/O read/write timing.
- (4) Basic instruction (fetch and execute) timing.
- (5) RESET timing
- (6) BUSREQ/BUSACK bus exchange timing.

The basic CPU operation consists of one or more "machine cycles" (MC). A machine cycle consists of three system clocks, T_1 , T_2 and T_3 while accessing memory or I/O, or it consists of one system clock, Ti while the CPU internal operation. The system clock (ϕ) is half frequency of crystal oscillation (Ex. 8 MHz crystal $\rightarrow \phi$ of 4

MHz, 250 nsec). For interfacing to slow memory or peripherals, optional wait states (Tw) may be inserted between T_2 and T_3 .

4.1 Instruction (op-code) Fetch Timing

Fig. 9 shows the instruction (op-code) fetch timing with no wait

An op-code fetch cycle is externally indicated when the $\overline{\text{LIR}}$ (Load Instruction Register) output pin is LOW.

In the first half of T_1 , the address bus (A_0-A_{18}) is driven with the contents of the Program Counter (PC). Note that this is the translated address output of the HD64180 on-chip MMU.

lated address output of the HD64180 on-chip MMU.

In the second half of T_1 , the ME (Memory Enable) and RD (Read) signals are asserted LOW, enabling the memory.

The op-code on the data bus is latched at the rising edge of T_3 and the bus cycle terminates at the end of T_3 .

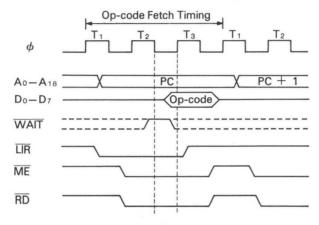


Figure 9 Op-Code Fetch Timing

Fig. 10 illustrates the insertion of wait states (Tw) into the opcode fetch cycle. Wait states (Tw) are controlled by the external WAIT input combined with an on-chip programmable wait state generator.

At the falling edge of T2 the combined WAIT input is sampled. If

 \overline{WAIT} input is asserted LOW, a wait state (Tw) is inserted. The address bus, \overline{ME} , \overline{RD} and LIR are held stable during wait states, When the \overline{WAIT} is sampled inactive HIGH at the falling edge of Tw, the bus cycle enters T_3 and completes at the end of T_3 .

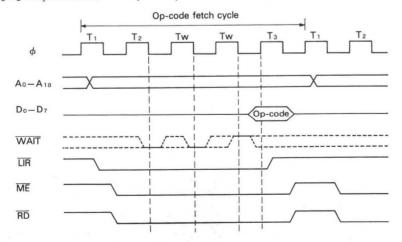


Figure 10 Op-Code Fetch Timing (with wait state)



4.2 Operand and Data Read/Write Timing

The instruction operand and data read/write timing differs from op-code fetch timing in two ways. First, the LIR output is held inactive. Second, the read cycle timing is relaxed by one-half clock cycle since data is latched at the falling edge of $T_{\rm a}$.

Instruction operands include immediate data, displacement and extended addresses and have the same timing as memory data reads.

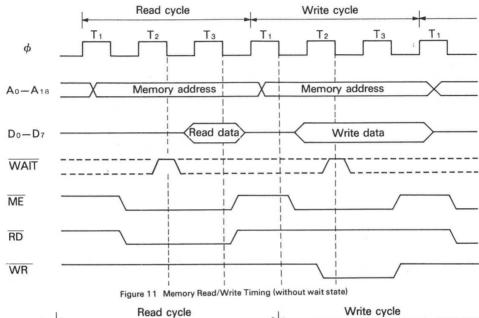
During memory write cycles the ME signal goes active in the

second half of T_1 . At the end of T_1 , the data bus is driven with the write data.

At the start of $\underline{T_2}$, the \overline{WR} signal is asserted LOW enabling the memory. \overline{ME} and \overline{WR} go inactive in the second half of T_3 followed by deactivation of the write data on the data bus.

Wait states (Tw) are inserted as previously described for op-code fetch cycles.

Fig. 11 illustrates the read/write timing without wait states (Tw), while Fig. 12 illustrates read/write timing with wait states (Tw).



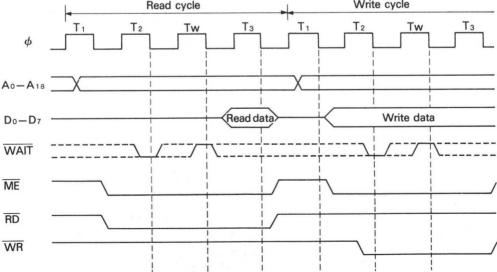


Figure 12 Memory Read/Write Timing (with wait state)



4.3 I/O Read/Write Timing

I/O instructions cause data read/write transfer which differs from memory data transfer in the following three ways. The IOE (I/O Enable) signal is asserted LOW instead of the ME signal. The 16-bit I/O address is not translated by the MMU and A₁₆-A₁₈ are held

LOW. At least one wait state (Tw) is always inserted for I/O read and write cycles (except internal I/O cycles).

Fig. 13 shows I/O read/write timing with the automatically inserted wait state (Tw).

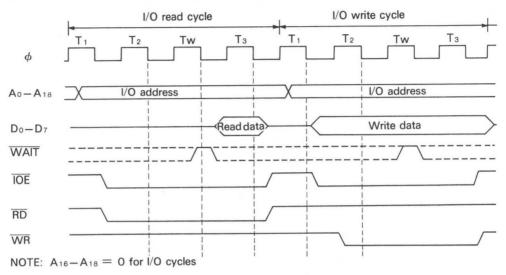


Figure 13 I/O Read/Write Timing

4.4 Basic Instruction Timing

An instruction may consist of a number of machine cycles including op-code fetch, operand fetch and data read/write cycles. An instruction may also include cycles for internal processing in which case the bus is idle.

The example in Fig. 14 illustrates the bus timing for the data transfer instruction LD (IX+d),g. This instruction moves the contents of a CPU register (g) to the memory location with address

computed by adding an signed 8-bit displacement (d) to the contents of an index register (IX).

The instruction cycle starts with the two machine cycles to read the two bytes instruction op-code as indicated by \overline{LIR} LOW. Next, the instruction operand (d) is fetched.

The external bus is idle while the CPU computes the effective address. Finally, the computed memory location is written with the contents of the CPU register (g).

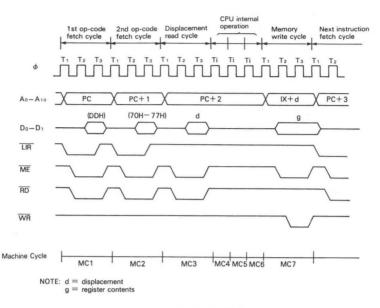


Figure 14 LD (IX+d), g Instruction Timing

4.5 RESET Timing

Fig. 15 shows the HD64180 hardware RESET timing. If the RE-SET pin is LOW for at least six clock cycles, processing is terminated and the HD64180 restarts execution from (logical and physical) address 00000H. $\,$

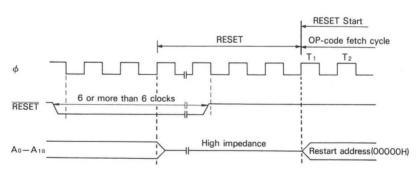


Figure 15 RESET Timing

4.6 BUSREQ/BUSACK Bus Exchange Timing

The HD64180 can coordinate the exchange of control, address and data bus ownership with another bus master. The alternate bus master can request the bus release by asserting the \overline{BUSREQ} (Bus Request) input LOW. After the HD64180 releases the bus, it relinquishes control to the alternate bus master by asserting the \overline{BUSACK} (Bus Acknowledge) output LOW.

The bus may be released by the HD64180 at the end of each machine cycle. In this context a machine cycle consists of a minimum of 3 clock cycles (more if wait states are inserted) for op-code fetch, memory read/write and I/O read/write cycles. Except for these cases, a machine cycle corresponds to one clock cycle.

When the bus is released, the address (A₀-A₁₈), data (D₀-D₇)

and control $(\overline{ME},\,\overline{IOE},\,\overline{RD},$ and $\overline{WR})$ signals are placed in the high impedance state.

Note that dynamic RAM refresh is not performed when the HD64180 has released the bus. The alternate bus master must provide dynamic memory refreshing if the bus is released for long periods of time.

Fig. 16 illustrates BUSREQ/BUSACK bus exchange during a memory read cycle. Fig. 17 illustrates bus exchange when the bus release is requested during an HD64180 CPU internal operation. BUSREQ is sampled at the falling edge of the system clock prior to T₃, Ti and Tx (BUS RELEASE state). If BUSREQ is asserted LOW at the falling edge of the clock state prior to Tx, another Tx is executed.



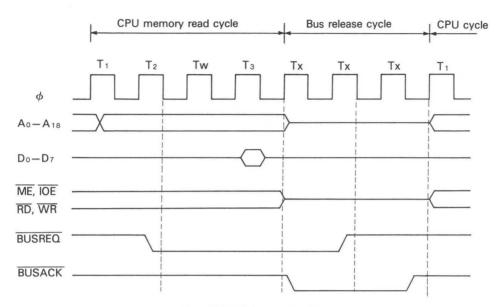


Figure 16 Bus Exchange Timing (1)

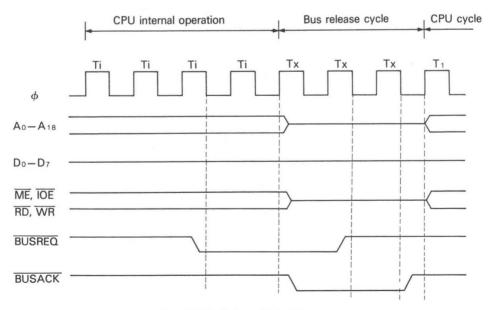


Figure 17 Bus Exchange Timing (2)

5 HALT AND LOW POWER OPERATION MODES

The HD64180 can operate in 4 different modes. HALT mode, IOSTOP mode and two low power operation modes — SLEEP and SYSTEM STOP. Note that in all operating modes, the basic CPU clock (XTAL, EXTAL) must remain active.

5.1 HALT Mode

HALT mode is entered by execution of the HALT instruction (op-code = 76H) and has the following characteristics.

- (1) The internal CPU clock remains active.
- (2) All internal and external interrupts can be received.
- (3) Bus exchange (BUSREQ and BUSACK) can occur.
- (4) Dynamic RAM refresh cycle (REF) insertion continues at the programmed interval.
- (5) I/O operations (ASCI, CSI/O and PRT) continue.
- (6) The DMAC can operate.
- (7) The HALT output pin is asserted LOW.
- (8) The external bus activity consists of repeated 'dummy' fetches of the op-code following the HALT instruction.

Essentially, the HD64180 operates normally in HALT mode, except that instruction execution is stopped.

HALT mode can be exited in the following two ways.

RESET Exit from HALT Mode

If the RESET input is asserted LOW for at least six clock cycles, HALT mode is exited and the normal RESET sequence (restart at address 00000H) is initiated.

Interrupt Exit from HALT Mode

When an internal or external interrupt is generated, HALT mode is exited and the normal interrupt response sequence is initiated.

If the interrupt source is masked (individually by enable bit, or globally by $\overline{\rm IEF}_1$ state), the HD64180 remains $\underline{\rm in}$ HALT mode. However, $\overline{\rm NMI}$ interrupt will initiate the normal $\overline{\rm NMI}$ interrupt response sequence independent of the state of $\overline{\rm IEF}_1$.

HALT timing is shown in Fig. 18.

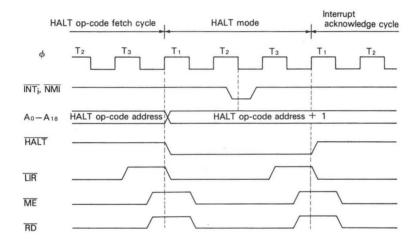


Figure 18 HALT Timing

5.2 SLEEP Mode

SLEEP mode is entered by execution of the 2 byte SLP instruction. SLEEP mode has the following characteristics.

- (1) The internal CPU clock stops, reducing power consumption.
- (2) The internal crystal oscillator does not stop.
- (3) Internal and external interrupt inputs can be received.
- (4) DRAM refresh cycles stop.
- (5) I/O operations using on-chip peripherals continue.
- (6) The internal DMAC stop.
- (7) BUSREQ can be received and acknowledged.
- (8) Address outputs go HIGH and all other control signal output become inactive HIGH.
- (9) Data Bus, 3-state.

SLEEP mode is exited in one of two ways as shown below.

RESET Exit from SLEEP Mode

If the RESET input is held LOW for at least six clock cycles, the HD64180 will exit SLEEP mode and begin the normal RESET sequence with execution starting at address (logical and physical) 00000H.

Interrupt Exit from SLEEP Mode

The SLEEP mode is exited by detection of an external $(\overline{NMI}, \overline{INT_0}, \overline{INT_1}, \overline{INT_2})$ or internal (ASCI, CSI/O, PRT) interrupt.

In the case of \overline{NMI} , SLEEP Mode is exited and the CPU begins the normal \overline{NMI} interrupt response sequence.

In the case of all other interrupts, the interrupt response depends on the state of the global interrupt enable flag (IEF₁) and the individual interrupt source enable bit.

If the individual interrupt condition is disabled by the corresponding enable bit, occurrence of that interrupt is ignored and the CPU remains in the SLEEP state.

Assuming the individual interrupt condition is enabled, the response to that interrupt depends on the global interrupt enable flag ($\mathrm{IEF_1}$). If interrupts are globally enabled ($\mathrm{IEF_1}$ =1) and an individually enabled interrupt occurs, SLEEP mode is exited and the appropriate normal interrupt response sequence is executed.

If interrupts are globally disabled ($\mathrm{IEF_1}{=}0$) and an individually enabled interrupt occurs, SLEEP mode is exited and instruction execution begins with the instruction following the SLP instruction. Note that this provides a technique for synchronization with high speed external events without incurring the latency imposed by an interrupt response sequence.

Fig. 19 shows SLEEP timing.



5.3 IOSTOP Mode

IOSTOP mode is entered by setting the IOSTP bit of the I/O Control Register (ICR) to 1. In this case, on-chip I/O (ASCI, CSI/O, PRT) stops operating. However, the CPU continues to operate. Recovery from IOSTOP mode is by clearing the IOSTP bit in ICR to 0.

5.4 SYSTEM STOP Mode

SYSTEM STOP mode is the combination of SLEEP and IOSTOP modes. SYSTEM STOP mode is entered by setting the IOSTP bit in ICR to 1 followed by execution of the SLP instruction. In this mode, on-chip I/O and CPU stop operating, reducing power consumption. Recovery from SYSTEM STOP mode is the same as recovery from SLEEP mode, noting that internal I/O sources (disabled by IOSTOP) cannot generate a recovery interrupt.

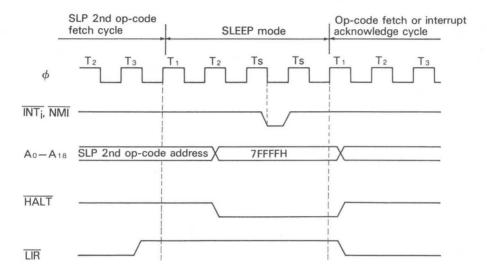


Figure 19 SLEEP Timing

6 INTERRUPTS

The HD64180 CPU has twelve interrupt sources, four external and eight internal, with fixed priority.

This section explains the CPU registers associated with interrupt

processing, the TRAP interrupt, interrupt response modes and the external interrupts. The detailed discussion of internal interrupt generation (except TRAP) is presented in the appropriate hardware section (i.e. PRT, DMAC, ASCI and CSI/O).

Priori	ity	Interrupt	
Higher	1	TRAP (Undefined Op-code Trap)	Internal Interrupt
Priority	2	NMI (Non Maskable Interrupt)	
†	3	INTo (Maskable Interrupt Level 0)	External Interrupt
	4	INT ₁ (Maskable Interrupt Level 1)	
	5	INT ₂ (Maskable Interrupt Level 2)	
	6	Timer 0	
	7	Timer 1	
	8	DMA channel 0	
	9	DMA channel 1	Internal Interrupt
1	10	Clocked Serial I/O Port	
Lower	11	Asynchronous SCI channel 0	
Priority	12	Asynchronous SCI channel 1	

Figure 20 Interrupt Sources

6.1 Interrupt Control Registers and Flags

The HD64180 contains three registers and two flags which are associated with interrupt processing.

Register and Flag Name	Function	Access Method LD A, I and LD I, A instructions				
1	Contains upper 8-bit of interrupt vector					
IL	Contains lower 8-bit of interrupt vector	I/O instruction (addr = 33H)				
ITC	Interrupt/Trap control	I/O instruction (addr = 34H)				
IEF ₁ , IEF ₂	Enable/disable interrupt	EI, DI, LD A, I, and LD A, R instructions				

(1) Interrupt Vector Register (I)

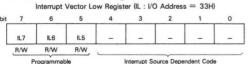
Mode 2 for \overline{INT}_0 external interrupt, \overline{INT}_1 and \overline{INT}_2 external interrupts and all internal interrupts (except TRAP) use a programmable vectored technique to determine the address at which interrupt processing starts. In response to the interrupt a 16-bit address is generated. This address accesses a vector table in memory to obtain the address at which execution restarts.

While the method for generation of the least significant byte of the table address differs, all vectored interrupts use the contents of I as the most significant byte of the table address. By programming the contents of I, vector tables can be relocated on 256 bytes boundaries throughout the 64k bytes logical address space.

Note that I is read/written with the LD A, I and LD I, A instructions rather than I/O (IN, OUT) instructions.

I is initialized to 00H during RESET.

(2) Interrupt Vector Low Register (IL)

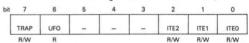


This register determines the most significant three bits of the low-order byte of the interrupt vector table address for external interrupts \overline{INT}_1 and \overline{INT}_2 and all internal interrupts (except TRAP). The five least significant bits are fixed for each specific interrupt source. By programming IL the vector table can be relocated on 32 bytes boundaries.

IL is initialized to 00H during RESET.

(3) INT/TRAP Control Register (ITC)

INT/TRAP Control Register (ITC : I/O Address = 34H)



ITC is used to handle TRAP interrupts and to enable or disable the external maskable interrupt inputs $\overline{INT_0}$, $\overline{INT_1}$, and $\overline{INT_2}$.

TRAP (bit 7)

This bit is set to 1 when an undefined op-code is fetched. TRAP can be reset under program control by writing it with 0, however it cannot be written with 1 under program control. TRAP is cleared to 0 during RESET.

UFO: Undefined Fetch Object (bit 6)

When a TRAP interrupt occurs (TRAP bit is set to 1), the contents of UFO allow determination of the starting address of the undefined instruction. This is necessary since the TRAP may occur on either the second or third byte of the op-code. UFO allows the stacked PC value (stacked in response to TRAP) to be correctly adjusted. If UFO = 0, the first op-code should be interpreted as the stacked PC-1. If UFO = 1, the first op-code address is stacked PC-2. UFO is read-only.

ITE2,1,0: Interrupt Enable 2,1,0 (bits 2-0)

ITE2, ITE1 and ITE0 enable and disable the external interrupt inputs \overline{INT}_2 , \overline{INT}_1 , and \overline{INT}_0 respectively. If cleared to 0, the interrupt is masked. During RESET, ITE0 is initialized to 1 while ITE1 and ITE2 are initialized to 0.

· Interrupt Enable Flag 1,2 (IEF1, IEF2)

 ${\rm IEF_1}$ controls the overall enabling and disabling of all internal and external maskable interrupts (i.e. all interrupts except $\overline{\rm NMI}$ and

TRAP)

If $IEF_1 = 0$, all maskable interrupts are disabled. IEF_1 can be reset to 0 by the DI (Disable Interrupts) instruction and set to 1 by the EI (Enable Interrupts) instruction.

The purpose of $\overline{IEF_2}$ is to correctly manage the occurrence of \overline{NMI} . During \overline{NMI} , the prior interrupt reception state is saved and all maskable interrupts are automatically disabled (IEF, copied to

 ${\rm IEF_2}$ and then ${\rm IEF_1}$ cleared to 0). At the end of the $\overline{\rm NMI}$ interrupt service routine, execution of the RETN (Return from Non-maskable Interrupt) will automatically restore the interrupt receiving state (by copying ${\rm IEF_2}$ to ${\rm IEF_1}$) prior to the occurrence of $\overline{\rm NMI}$.

IEF₂ state can be reflected in the P/V bit of the CPU Status register by executing LD A, I or LD A, R instructions.

Table 2 shows the state of IEF₁ and IEF₂.

Table 2 State of IEF, and IEF,

CPU Operation	IEF,	IEF ₂	REMARKS
RESET	0	0	Inhibits the interrupt except NMI and TRAP.
NMI	0	IEF 1	Copies the contents of IEF 1 to IEF 2.
RETN	IEF ₂	not affected	Returns from the NMI service routine.
Interrupt except NMI and TRAP	0	0	Inhibits the interrupt except NMI and TRAP.
RETI	not affected	not affected	
TRAP	not affected	not affected	
El	1	1	
DI	0	0	
LD A, I	not affected	not affected	Transfers the contents of IEF ₂ to P/V flag.
LD A, R	not affected	not affected	Transfers the contents of IEF ₂ to P/V flag.

6.2 TRAP Interrupt

The HD64180 generates a non-maskable (not affected by the state of IEF₁) TRAP interrupt when an undefined op-code fetch occurs. This feature can be used to increase software reliability, implement an 'extended' instruction set, or both. TRAP may occur during op-code fetch cycles and also if an undefined op-code is fetched during the interrupt acknowledge cycle for $\overline{\text{INT}_0}$ when Mode 0 is used.

When a TRAP interrupt occurs the HD64180 operates as follows.

- (1) The TRAP bit in the Interrupt TRAP/Control (ITC) register is set to 1.
- (2) The current PC (Program Counter) value, reflecting the location of the undefined op-code, is saved on the stack.
- (3) The HD64180 vectors to logical address 0. Note that if logical

address 0000H is mapped to physical address 00000H, the vector is the same as for RESET. In this case, testing the TRAP bit in ITC will reveal whether the restart at physical address 00000H was caused by RESET or TRAP.

The state of the UFO (Undefined Fetch Object) bit in ITC allows TRAP manipulation software to correctly 'adjust' the stacked PC depending on whether the second or third byte of the op-code generated the TRAP. If UFO = 0, the starting address of the invalid instruction is equal to the stacked PC-1. If UFO = 1, the starting address of the invalid instruction is equal to the stacked PC-2. Fig. 21 shows TRAP Timing.

Note that Bus Release cycle, Refresh cycle, DMA cycle and WAIT cycle can't be inserted just after T_{TP} state which is inserted for TRAP interrupt sequence.

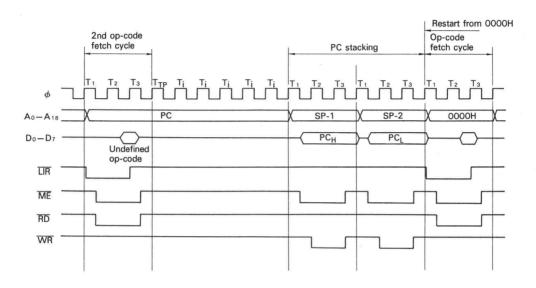


Figure 21 (a) TRAP Timing - 2nd Op-code Undefined

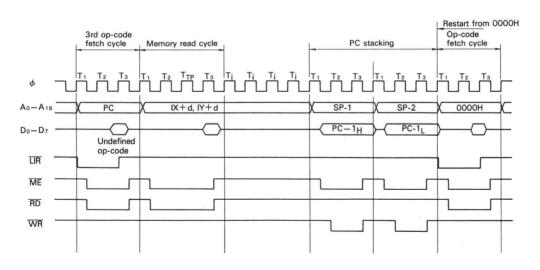


Figure 21 (b) TRAP Timing - 2nd Op-code Undefined

6.3 External Interrupts

The HD64180 has four external hardware interrupt inputs.

- (1) NMI Non-maskable Interrupt
- (2) INT₀ Maskable Interrupt Level 0
- (3) INT Maskable Interrupt Level 1
- (4) INT₂ Maskable Interrupt Level 2

NMI, INT₁ and INT₂ have fixed interrupt response modes. INT₀ has three different software programmable interrupt response modes — Mode 0, Mode 1 and Mode 2.

6.4 NMI - Non-Maskable Interrupt

The NMI interrupt input is edge sensitive and cannot be masked by software. When NMI is detected, the HD64180 operates as follows.

- DMAC operation is suspended by clearing the DME (DMA Main Enable) bit in DCNTL.
- 2) The PC is pushed onto the stack.
- (3) The contents of IEF₁ are copied to IEF₂. This saves the interrupt reception state that existed prior to NMI.
- (4) IEF₁ is cleared to 0. This disables all external and internal maskable interrupts (i.e. all interrupts except NMI and TRAP).

(5) Execution commences at logical address 0066H.

The last instruction of an NMI service routine should be RETN (Return from Non-maskable Interrupt). This restores the stacked PC, allowing the interrupted program to continue. Furthermore, RETN causes IEF₂ to be copied to IEF₁, restoring the interrupt reception state that existed prior to the NMI.

Note that NMI, since it can be accepted during HD64180 onchip DMAC operation, can be used to externally interrupt DMA transfer. The NMI service routine can reactivate or abort the DMAC operation as required by the application.

For NMI, special care must be taken to insure that interrupt inputs do not 'overrun' the NMI service routine. Unlimited NMI inputs without a corresponding number of RETN instructions will eventually cause stack overflow.

Fig. 22 shows the use of $\overline{\text{NM}}$ and RETN while Fig. 23 details $\overline{\text{NM}}$ response timing. $\overline{\text{NM}}$ is edge sensitive and the internally latched $\overline{\text{NM}}$ falling edge is held until it is sampled. If the falling edge of $\overline{\text{NM}}$ is latched before the falling edge of clock state prior to T_3 or Ti in the last machine cycle, the internally latched $\overline{\text{NM}}$ is sampled at the falling edge of the clock state prior to T_3 or Ti in the last machine cycle and $\overline{\text{NM}}$ acknowledge cycle begins at the end of the current machine cycle.

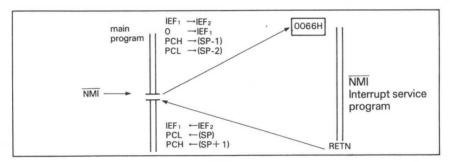
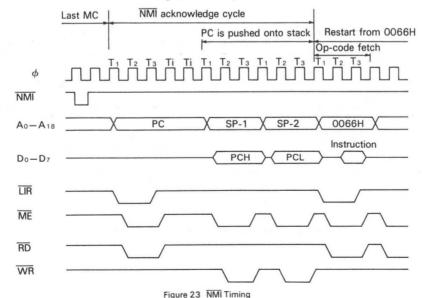


Figure 22 NMI Sequence



riguro 20 mm mm



6.5 INT₀ - Maskable Interrupt Level 0

The next highest priority external interrupt after NMI is INT₀ $\overline{INT_0}$ is sampled at the falling edge of the clock state prior to T_3 or T_3 in the last machine cycle. If $\overline{INT_0}$ is asserted LOW at the falling edge of the clock state prior to T₃ or Ti in the last machine cycle, INT₀ is accepted. The interrupt is masked if either the IEF, flag or the ITE0 (Interrupt Enable 0) bit in ITC are cleared to 0. Note that after RE-SET the state is as follows.

(1) IEF_1 is 0, so $\overline{\text{INT}_0}$ is masked. (2) ITEO is 1, so $\overline{\text{INT}_0}$ is enabled by execution of the EI (Enable

Interrupts) instruction.

The INT interrupt is unique in that three programmable interrupt response modes are available - Mode 0, Mode 1, and Mode 2. The specific mode is selected with the IM 0, IM 1 and IM 2 (Set Interrupt Mode) instructions. During RESET, the HD64180 is initialized to use Mode 0 for INTa.

The three interrupt response modes for INT₀ are...

(1) Mode 0 - Instruction fetch from data bus.

(2) Mode 1 - Restart at logical address 0038H.

(3) Mode 2 - Low byte vector table address fetch from data bus.

INTo Mode 0

During the interrupt acknowledge cycle, an instruction is fetched from the data bus (D₀-D₇) at the rising edge of T₃. Often, this instruction is one of the eight single byte RST (RESTART) instructions which stack the PC and restart execution at a fixed logical address. However, multibyte instructions can be processed if the interrupt acknowledging device can provide a multibyte response. Unlike all other interrupts, the PC is not automatically stacked.

Note that TRAP interrupt will occur if an invalid instruction is fetched during $\overline{INT_0}$ Mode 0 interrupt acknowledge. Fig. 24 shows $\overline{INT_0}$ Mode 0 Timing.

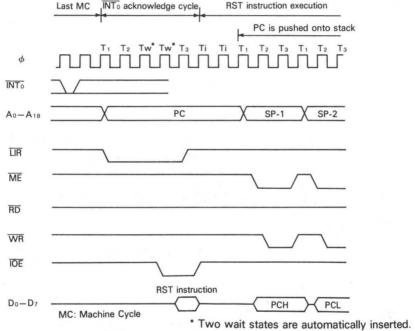


Figure 24 INT Mode 0 Timing (RST Instruction on the Data Bus)

 $\overline{\text{INT}_0}$ Mode 1 When $\overline{\text{INT}_0}$ is received, the PC is stacked and instruction execution $\overline{\text{INT}_0}$ is received, the PC is stacked and instruction execution $\overline{\text{INT}_0}$ is received, the PC is stacked and instruction execution $\overline{\text{INT}_0}$ is received, the PC is stacked and instruction execution $\overline{\text{INT}_0}$ is received, the PC is stacked and instruction execution $\overline{\text{INT}_0}$ is received. reset to 0, disabling all maskable interrupts. The interrupt service routine should normally terminate with the EI (Enable Interrupts)

instruction followed by the RETI (Return from Interrupt) instrucis that the interrupts are reenabled. Fig. 25 shows the use of $\overline{\text{INT}_0}$ (Mode 1) and RETI.

Fig. 26 shows $\overline{\text{INT}_0}$ Mode 1 timing.

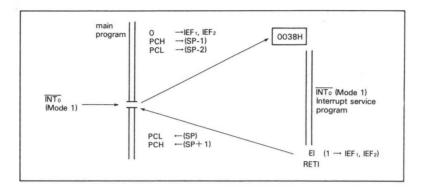


Figure 25 INT Mode 1 Interrupt Sequence

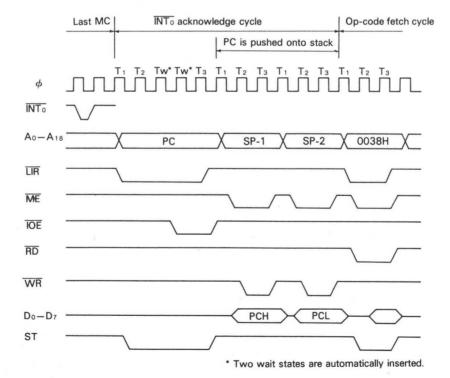


Figure 26 INT Mode 1 Timing



INT₀ Mode 2

This method determines the restart address by reading the contents of a table residing in memory. The vector table consists of up to 128 two-byte restart addresses stored in low byte, high byte order.

The vector table address is located on 256 bytes boundaries in the 64k bytes logical address space as programmed in the 8-bit Interrupt Vector Register (I). Fig. 27 shows the $\overline{INT_0}$ Mode 2 Vector acquisition.

During INT₀ Mode 2 acknowledge cycle, first, the low-order 8 bits of vector is fetched from the data bus at the rising edge of T₀.

and CPU acquires the 16-bit vector.

Next, the PC is stacked. Finally, the 16-bit restart address is fetched from the vector table and execution commences at that address.

Note that external vector acquisition is indicated by \overline{LIR} and \overline{IOE} both LOW. Two wait states (Tw) are automatically inserted for external vector fetch cycles.

During RESET the Interrupt Vector Register (I) is initialized to 00H and, if necessary, should be set to a different value prior to the occurrence of a $\overline{INT_0}$ Mode 2 interrupt. Fig. 28 shows $\overline{INT_0}$ Mode 2 interrupt Timing.

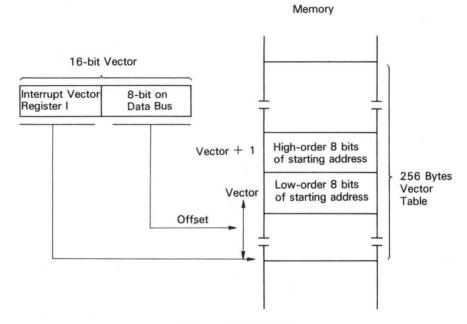
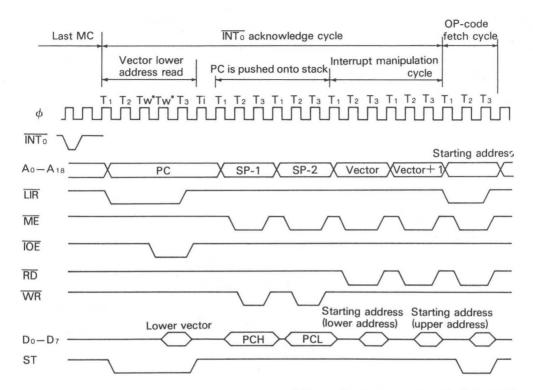


Figure 27 INT Mode 2 Vector Acquisition



* Two wait states are automatically inserted.

Figure 28 INT Mode 2 Timing

6.6 INT₁, INT₂

The operation of external interrupts $\overline{INT_1}$ and $\overline{INT_2}$ is a vector mode similar to $\overline{INT_0}$ Mode 2. The difference is that $\overline{INT_1}$ and $\overline{INT_2}$ generate the low-order byte of vector table address using the IL (Interrupt Vector Low) register rather than fetching it from the data bus. This is also the interrupt response sequence used for all internal interrupts (except TRAP).

As shown in Fig. 29 the low-order byte of vector table address is comprised of the most significant three bits of the software programmable IL register and the least significant five bits which are a unique fixed value for each interrupt ($\overline{\text{INT}}_1$, $\overline{\text{INT}}_2$ and internal) source.

 $\overline{\text{INT}_1}$ and $\overline{\text{INT}_2}$ are globally masked by IEF₁ = 0. Each is also individually maskable by respectively clearing the ITE1 and ITE2 (bits 1, 2) of the INT/TRAP control register to 0. During RESET, IEF₁, ITE1 and ITE2 bits are initialized to 0.

6.7 Internal Interrupts

Internal interrupts (except TRAP) use the same vectored response mode as $\overline{INT_1}$ and $\overline{INT_2}$ (Fig. 29). Internal interrupts are globally masked by $IEF_1=0$. Individual internal interrupts are enabled/disabled by programming each individual I/O (PRT, DMAC, CSI/O, ASCI) control register. The lower vector of $\overline{INT_1}$, $\overline{INT_2}$, and internal interrupt are summarized in Table 3.

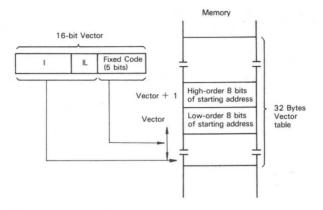


Figure 29 INT, INT, and Internal Interrupts Vector Acquisition

Table 3 Interrupt Source and Lower Vector

Interrupt Course	Daily alter	IL			Fixed Code				
Interrupt Source	Priority	b ₇	b_6	b ₅	b ₄	b_3	b ₂	b ₁	bo
INT ₁	Highest				0	0	0	0	0
INT ₂	1				0	0	0	1	0
PRT channel 0					0	0	1	0	0
PRT channel 1					0	0	1	1	0
DMA channel 0					0	1	0	0	0
DMA channel 1					0	1	0	1	0
CSI/O					0	. 1	1	0	0
ASCI channel 0					0	1	1	1	0
ASCI channel 1	Lowest				1	0	0	0	0

^{*} Programmable

Interrupt Acknowledge Cycle Timing

Fig. 30 shows interrupt acknowledge cycle timing for internal interrupts, $\overline{INT_1}$, and $\overline{INT_2}$, $\overline{INT_1}$ and $\overline{INT_2}$ are sampled at the falling

edge of clock state prior to T_3 or Ti in the last machine cycle. If $\overline{INT_1}$ or $\overline{INT_2}$ is asserted LOW at the falling edge of clock state prior to T_3 or Ti in the last machine cycle, the interrupt request is accepted.

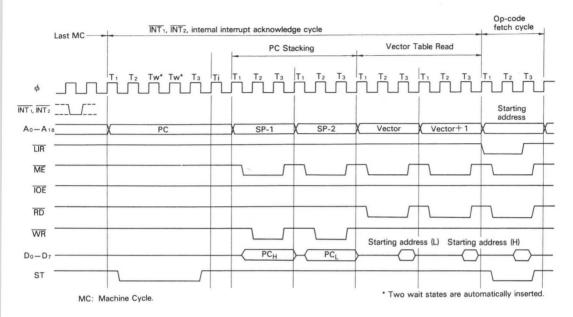


Figure 30 INT, INT, and Internal Interrupts Timing

6.8 Interrupt Sources and Reset

(1) Interrupt Vector Register (I)

All bits are reset to 0. Since I=0 locates the vector tables starting at logical address 0000H, vectored interrupts $(\overline{INT}_0 \text{ Mode } 2, \overline{INT}_1, \overline{INT}_2 \text{ and internal interrupts})$ will overlap with fixed restart interrupts like RESET (0), \overline{NMI} (0066H), \overline{INT}_0 Mode 1 (0038H) and RST (0000H - 0038H). The vector table(s) can be built elsewhere in memory and located on 256 bytes boundaries by reprogramming I with the LD I, A instruction.

(2) IL Register

Bits 7 - 5 are reset to 0.

The IL Register can be programmed to locate the vector table for \overline{INT}_1 , \overline{INT}_2 and internal interrupts on 32 bytes sub-boundaries within the 256 bytes area specified by I.

(3) IEF₁, IEF₂ Flags

Reset to 0.

Interrupts other than NMI and TRAP are disabled.

(4) ITC Register

ITE0 are set to 1. ITE1 and ITE2 are reset to 0.

 $\overline{\text{INT}_0}$ can be enabled by the EI instruction, which sets IEF $_1=1$. To enable $\overline{\text{INT}_1}$ and $\overline{\text{INT}_2}$ also requires that the ITE1 and ITE2 bits be respectively set =1 by writing to ITC.

(5) I/O Control Registers

Interrupt enable bits reset to 0.

All HD64180 on-chip I/O (PRT, DMAC, CSI/O, ASCI) interrupts are disabled and can be individually enabled by writing to each I/O control register interrupt enable bit.

6.9 Difference between $\overline{\text{INT}_0}$ interrupt and the other interrupts ($\overline{\text{INT}_1}$, $\overline{\text{INT}_2}$ and internal interrupts) in the interrupt acknowledge cycles

As shown in Fig. 24, Fig. 26, Fig. 28 and Fig. 30, the interrupt acknowledge cycle of $\overline{1NT_0}$ is different from those of the other interrupts, that is, $\overline{1NT_1}$, $\overline{1NT_2}$ and internal interrupts concerning the state of control signals. The state of the control signals in each interrupt acknowledge cycle are shown below.

 \overline{INT}_0 interrupt acknowledge cycle: $\overline{LIR}=0,\ \overline{IOE}=0,\ ST=0$ $\overline{INT}_1,\ \overline{INT}_2,\ and\ internal\ interrupt\ acknowledge\ cycle: <math display="inline">\overline{LIR}=1,\ \overline{IOE}=1,\ ST=0$

7 MEMORY MANAGEMENT UNIT (MMU)

The HD64180 contains an on-chip MMU which performs the translation of the CPU 64k bytes (16-bit addresses-0000H to FFFFH) logical memory address space into a 512k bytes (19-bit addresses-00000H to 7FFFFH) physical memory address space. Address translation occurs internally in parallel with other CPU operation.

7.1 Logical Address Spaces

The 64k bytes CPU logical address space is interpreted by the MMU as consisting of up to three separate logical address areas, Common Area 0, Bank Area and Common Area 1.

As shown in Fig. 31 a variety of logical memory configurations are possible. The boundaries between the Common and Bank Areas can be programmed with 4k bytes resolution.

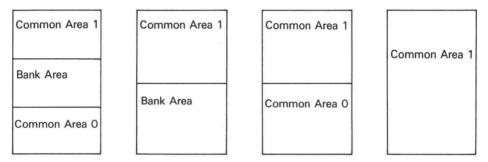


Figure 31 Logical Address Mapping Examples

7.2 Logical to Physical Address Translation

Fig. 32 shows an example in which the three logical address space portions are mapped into a 512k bytes physical address space. The important points to note are that Common and Bank Areas can

overlap and that Common Area 1 and Bank Area can be freely relocated (on 4k bytes physical address boundaries). Common Area 0 (if it exists) is always based at physical address 00000H.

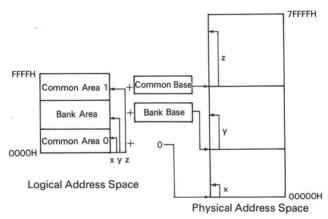


Figure 32 Logical → Physical Memory Mapping Example

7.3 MMU Block Diagram

The MMU block diagram is shown in Fig. 33. The MMU translates internal 16-bit logical addresses to external 19-bit physical addresses.

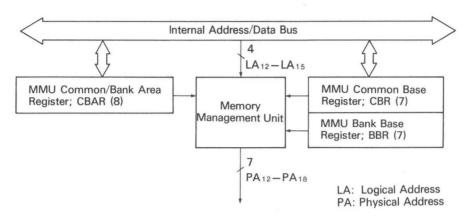


Figure 33 MMU Block Diagram

Whether address translation takes place depends on the type of CPU cycle as follows.

(1) Memory Cycles

Address Translation occurs for all memory access cycles including instruction and operand fetches, memory data reads and writes, hardware interrupt vector fetch and software interrupt restarts.

(2) I/O Cycles

The MMU is logically bypassed for I/O cycles. The 16-bit logical I/O address space corresponds directly with the 16-bit physical I/O address space. The upper three bits $(A_{16}-A_{18})$ of the physical address are always 0 during I/O cycles.

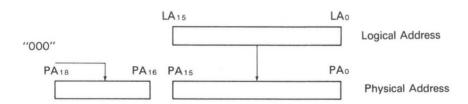


Figure 34 I/O Address Translation

(3) DMA Cycles

When the HD64180 on-chip DMAC is using the external bus, the MMU is physically bypassed. The 19-bit source and destination

registers in the DMAC are directly output on the physical address bus $(A_n - A_{1n})$.

7.4 MMU Registers

Three MMU registers are used to program a specific configuration of logical and physical memory.

(1) MMU Common/Bank Area Register (CBAR)

(2) MMU Common Base Register (CBR)

(3) MMU Bank Base Register (BBR)

CBAR is used to define the logical memory organization, while CBR and BBR are used to relocate logical areas within the 512k bytes physical address space. The resolution for both setting boundaries within the logical space and relocation within the physical

space is 4k bytes.

The CAR field of CBAR determines the start address of Common Area 1 (Upper Common) and by default, the end address of the Bank Area. The BAR field determines the start address of the Bank Area and by default, the end address of Common Area 0 (Lower Common).

The CA and BA fields of CBAR may be freely programmed subject only to the restriction that CA may never be less than BA. Fig. 35 and Fig. 36 shows example of logical memory organizations associated with different values of CA and BA.

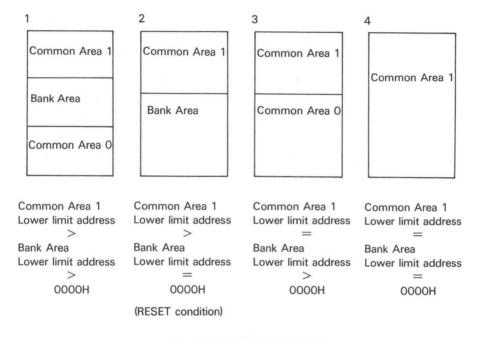


Figure 35 Logical Memory Organization

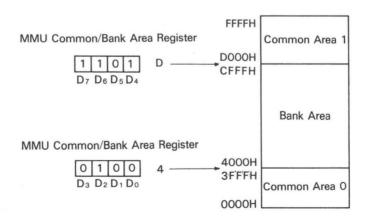


Figure 36 Logical Space Configuration (Example)



7.5 MMU Register Description

(1) MMU Common/Bank Area Register (CBAR)

CBAR specifies boundaries within the HD64180 64k bytes logical address space for up to three areas, Common Area 0, Bank Area, and Common Area 1.

MMU Common/Bank Area Register (CBAR : I/O Address = 3AH)
bit 7 6 5 4 3 2 1 0

CA3 CA2 CA1 CA0 BA3 BA2 BA1 BA0

RWW R/W R/W R/W R/W R/W R/W R/W R/W R/W

CA3-CA0: CA (bits 7-4)

CA specifies the start (low) address (on 4k bytes boundaries) for the Common Area 1. This also determines the last address of the Bank Area. All bits of CA are initialized to 1 during RESET.

BA3-BA0: BA (bits 3-0)

BA specifies the start (low) address (on 4k bytes boundaries) for the Bank Area. This also determines the last address of the Common Area 0. All bits of BA are initialized to 0 during RESET.

(2) MMU Common Base Register (CBR)

CBR specifies the base address (on 4k bytes boundaries) used to generate a 19-bit physical address for Common Area 1 accesses. All bits of CBR are initialized to 0 during RESET.



RAW

R/W

R/M

R/M

(3) MMU Bank Base Register (BBR)

R/W

BBR specifies the base address (on 4k bytes boundaries) used to generate a 19-bit physical address for Bank Area accesses. All bits of BBR are initialized to 0 during RESET.

RAN



7.6 Physical Address Translation

Fig. 37 shows the way in which physical addresses are generated based on the contents of CBAR, CBR and BBR. MMU comparators classify an access by logical area as defined by CBAR. Depending on which of the three potential logical areas (Common Area 1, Bank Area or Common Area 0) is being accessed, the appropriate 7-bit base address is added to the upper 4 bits of the logical address, yielding a 19-bit physical address. CBR is associated with Common Area 1 accesses. Common Area 0 accesses use a (non-accessible, internal) base register which contains 0. Thus, Common Area 0, if defined, is always based at physical address 00000H.

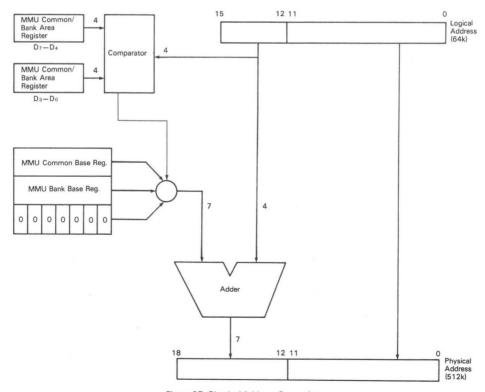


Figure 37 Physical Address Generation



7.7 MMU and RESET

During RESET, all bits of the CA field of CBAR are set to 1 while all bits of the BA field of CBAR, CBR, and BBR are cleared to 0. The logical 64k bytes address space corresponds directly with the first 64k bytes (0000H to FFFFH) of the 512k bytes (00000H to 7FFFFH) physical address space. Thus, after RESET, the HD64180 will begin execution at logical and physical address 0.

7.8 MMU Register Access Timing

When data is written into CBAR, CBR, or BBR, the value will be effective from the cycle immediately following the I/O write cycle which updates these registers.

Care must be taken during MMU programming to insure that CPU program execution is not disrupted. Observe that the next cycle following MMU register programming will normally be an opcode fetch from the newly translated address. One simple technique is to localize all MMU programming routines in a Common Area that is always enabled.

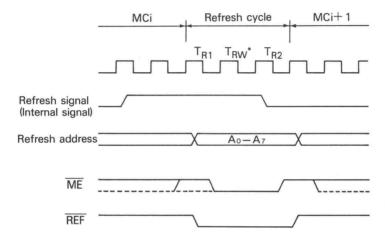
B DYNAMIC BAM REFRESH CONTROL

The HD64180 incorporates a dynamic RAM refresh control circuit including 8-bit refresh address generation and programmable refresh timing. This circuit generates asynchronous refresh cycles inserted at the programmable interval independent of CPU program execution. For systems which don't use dynamic RAM, the refresh function can be disabled.

When the internal refresh controller determines that a refresh cycle should occur, the current instruction is interrupted at the first breakpoint between machine cycles. The refresh cycle is inserted by placing the refresh address on $A_0\text{-}A_7$ and the \overline{REF} output is driven LOW.

Refresh cycles may be programmed to be either two or three clock cycles in duration by programming the REFW (Refresh Wait) bit in Refresh Control Register (RCR). Note that the external WAIT input and the internal wait state generator are not effective during refresh.

Fig. 38 shows the timing of a refresh cycle with a refresh wait (T_{RW}) cycle.



NOTE: * If three refresh cycles are specified, T_{RW}, is inserted.

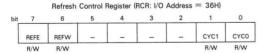
Otherwise, T_{RW} is not inserted.

MC: Machine Cycle

Figure 38 Refresh Timing

8.1 Refresh Control Register (RCR)

RCR specifies the interval and length of refresh cycles, as well as enabling or disabling the refresh function.



REFE: Refresh Enable (bit 7)

REFE=0 disables the refresh controller while REFE=1 enables refresh cycle insertion. REFE is set to 1 during RESET.

REFW: Refresh Wait (bit 6)

REFW = 0 causes the refresh cycle to be two clocks in duration. REFW = 1 causes the refresh cycle to be three clocks in duration by adding a refresh wait cycle (T_{RW}) . REFW is set to 1 during RESET.

CYC1, 0: Cycle Interval (bits 1-0)

CYC1 and CYC0 specify the interval (in clock cycles) between refresh cycles.

In the case of dynamic RAMs requiring 128 refresh cycles every 2 ms (or 256 cycles every 4 ms), the required refresh interval is less than or equal to $15.625~\mu s$. Thus, the underlined values indicate the best refresh interval depending on CPU clock frequency. CYC0 and CYC1 are cleared to 0 during RESET.

Table 4 Refresh Interval

CYC1		Insertion		Time	e interval		
	CYCO	interval	φ: 10 MHz	8 MHz	6 MHz	4 MHz	2.5 MHz
0	0	10 states	(1.0 μs)*	(1.25 μs)*	1.66 μs	2.5 μs	4.0 μs
0	1	20 states	(2.0 μs)*	(2.5 μs)*	3.3 µs	5.0 μs	8.0 µs
1	0	40 states	(4.0 μs)*	(5.0 μs)*	6.6 µs	10.0 μs	16.0 μs
1	1	80 states	(8.0 μs)*	(10.0 μs)*	$13.3 \mu s$	20.0 μs	32.0 μs

^{*} calculated interval

8.2 Refresh control and reset

After RESET, based on the initialized value of RCR, refresh cycles will occur with an interval of 10 clock cycles and be 3 clock cycles in duration.

8.3 Dynamic RAM refresh operation notes

- (1) Refresh cycle insertion is stopped when the CPU is in the following states.
 - (a) During RESET
 - (b) When the bus is released in response to BUSREQ
 - (c) During SLEEP mode
 - (d) During WAIT states
- (2) Refresh cycles are suppressed when the bus is released in response to BUSREQ. However, the refresh timer continues to operate. Thus, the time at which the first refresh cycle occurs after the HD64180 re-acquires the bus depends on the refresh timer, and has no timing relationship with the bus exchange.
- (3) Refresh cycles are suppressed during SLEEP mode. If a refresh cycle is requested during SLEEP mode, the refresh cycle request is internally 'latched' (until replaced with the next refresh request). The 'latched' refresh cycle is inserted at the end of the first machine cycle after SLEEP mode is exited. After this initial cycle, the time at which the next refresh cycle will occur depending on the refresh time, and has no timing relationship with the exit from SLEEP mode.
- (4) Regarding (2) and (3), the refresh address is incremented by 1 for each successful refresh cycle, not for each refresh request. Thus, independent of the number of 'missed' refresh requests, each refresh bus cycle will use a refresh address incremented by 1 from that of the previous refresh bus cycles.

9 WAIT STATE GENERATOR

9.1 Wait State Timing

To ease interfacing with slow memory and I/O devices, the HD64180 uses wait states (Tw) to extend bus cycle timing. A wait state(s) is inserted based on the combined (logical OR) state of the external WAIT input and an internal programmable wait state (Tw) generator. Wait states (Tw) can be inserted in both CPU execution and DMA transfer cycles.

9.2 WAIT Input

When the external \overline{WAIT} input is asserted LOW, wait state (Tw) are inserted between T_2 and T_3 to extend the bus cycle duration. The \overline{WAIT} input is sampled at the falling edge of the system clock in T_2 or Tw. If the \overline{WAIT} input is asserted LOW at the falling edge of the system clock in Tw, another Tw is inserted into the bus cycle. Note that \overline{WAIT} input transitions must meet specified set-up and hold times. This can easily be accomplished by externally synchronizing \overline{WAIT} input transitions with the rising edge of the system clock.

Dynamic RAM refresh is not performed during wait states (Tw) and thus systems designs which uses the automatic refresh function must consider the affects of the occurrence and duration of wait states (Tw).

Fig. 39 shows WAIT timing.

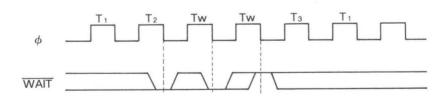


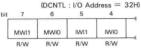
Figure 39 WAIT Timing

9.3 Programmable Wait State Insertion

In addition to the WAIT input, wait states (Tw) can also be programmably inserted using the HD64180 on-chip wait state generator. Wait state (Tw) timing applies for both CPU execution and on-chip DMAC cycles.

By programming the 4 significant bits of the DMA/WAIT Control Register (DCNTL), the number of wait states (Tw) automatically inserted in memory and I/O cycles can be separately specified. Bits 4-5 specify the number of wait states (Tw) inserted for I/O access and bits 6-7 specify the number of wait states (Tw) inserted for memory access.

DMA/WAIT Control Register



The number of wait states (Tw) inserted in a specific cycle is the maximum of the number requested by the WAIT input, and the

number automatically generated by the on-chip wait state generator.

MWI1, MWI0: Memory Wait Insertion (bits 7-6)

For CPU and DMAC cycles which access memory (including memory mapped I/O), 0 to 3 wait states may be automatically inserted depending on the programmed value in MWI1 and MWI0.

MWI1	MWIO	The number of wait states
0	0	0
0	1	1
1	0	2
1	1	3

IWI1, IWI0: I/O Wait Insertion (bits 5-4)

For CPU and DMA cycles which access external I/O (and interrupt acknowledge cycles), 1 to 6 wait states (Tw) may be automatically inserted depending on the programmed value in IWI1 and IWI0

		The number of wait states							
IWI1	IWIO	For external I/O registers accesses	For internal I/O registers accesses	For INT o interrupt acknowledge cy- cles when LIR is LOW	For INT ₁ , INT ₂ and internal interrupts acknowledge cycles (Note (2))	For NMI interrupt acknowledge cy- cles when LIR is LOW (Note (2))			
0	0	1		2					
0	1	2	0	4					
1	0	3	(Note (1))	5					
1	1 1 4			6					

NOTE: (1) For HD64180 internal I/O register access (I/O addresses 0000H-003FH), IWI1 and IWI0 do not determine wait state (Tw) timing. For ASCI, CSI/O and PRT Data Register accesses, 0 to 4 wait states (Tw) will be generated. Wait states inserted during access to these registers is a function of internal synchronization requirements and CPU state.

All other on-chip I/O register accesses (i.e. MMU, DMAC, ASCI Control Registers, etc.) have 0 wait states inserted and thus require only three clock cycles.

(2) For interrupt acknowledge cycles in which LIR is HIGH, such as interrupt vector table read and PC stacking cycle, memory access timing applies.

9.4 WAIT Input and RESET

During RESET, MWI1, MWI0, IWI1 and IWI0 are all set to 1, selecting the maximum number of wait states (Tw) (3 for memory accesses, 4 for external I/O accesses).

Also, note that the WAIT input is ignored during RESET. For

example, if RESET is detected while the HD64180 is in a wait state (Tw), the wait stated cycle in progress will be aborted, and the RESET sequence initiated. Thus, RESET has higher priority than \overline{WAIT} .

10 DMA CONTROLLER (DMAC)

The HD64180 contains a two channel DMA (Direct Memory Access) controller which supports high speed data transfer. Both channels (channel 0 and channel 1) have the following capabilities.

Memory Address Space

Memory source and destination addresses can be directly specified anywhere within the 512k bytes physical address space using 19-bit source and destination memory addresses. In addition, memory transfers can arbitrarily cross 64k bytes physical address boundaries without CPU intervention.

I/O Address Space

I/O source and destination addresses can be directly specified anywhere within the 64k bytes I/O address space (16-bit source and destination I/O addresses).

Transfer Length

Up to 64k bytes can be transferred based on a 16-bit byte count register.

DREO Input

Level and edge sense DREQ input detection are selectable.

TEND Output

Used to indicate DMA completion to external devices.

Each byte transfer can occur every six clock cycles. Wait states can be inserted in DMA cycles for slow memory or I/O devices. At the system clock $(\phi) = 6$ MHz, the DMA transfer rate is as high as 1.0 megabytes/second (no wait states).

Additional feature disk for DMA interrupt request by DMA END.

Each channel has the following additional specific capabilities.

Channel 0

- · Memory \longleftrightarrow memory, memory \longleftrightarrow I/O, memory \longleftrightarrow memory mapped I/O transfers
- · Memory address increment, decrement, no-change
- · Burst or cycle steal memory ← → memory transfers
- · DMA to and from both ASCI channels
- · Higher priority than DMAC channel 1

- · Memory <>> I/O transfer
- · Memory address increment, decrement

DMAC Registers

Each channel of the DMAC (channel 0, 1) has three registers specifically associated with that channel.

Channel 0

SAR₀ - Source Address Register DARO - Destination Address Register BCR₀ - Byte Count Register

Channel 1

MAR1 - Memory Address Register IAR1 I/O Address Register - Byte Count Register BCR1

The two channels share the following three additional registers in common.

- DMA Status Register DSTAT DMODE - DMA Mode Register DCNTL - DMA Control Register

10.1 DMAC Block Diagram

Fig. 40 shows the HD64180 DMAC Block Diagram.

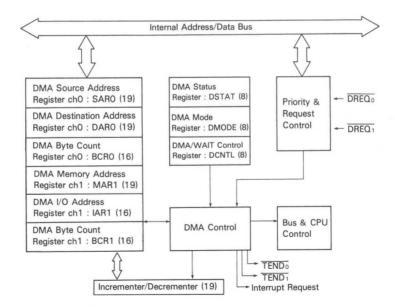


Figure 40 DMAC Block Diagram



10.2 DMAC Register Description

DMA Source Address Register Channel 0 (SAR0: I/O Address = 20H to 22H)

Specifies the physical source address for channel 0 transfers. The register contains 19 bits and may specify up to 512k bytes memory addresses or up to 64k bytes I/O addresses. Channel 0 source can be memory, I/O or memory mapped I/O.

(2) DMA Destination Address Register Channel 0 (DAR0: I/O Address = 23H to 25H)

Specifies the physical destination address for channel 0 transfers. The register contains 19 bits and may specify up to 512k bytes memory addresses or up to 64k bytes I/O addresses. Channel 0 destination can be memory, I/O or memory mapped I/O.

(3) DMA Byte Count Register Channel 0 (BCR0: I/O Address = 26H to 27H)

Specifies the number of bytes to be transferred. This register contains 16 bits and may specify up to 64k bytes transfers. When one byte is transferred, the register is decremented by one. If "n" bytes should be transferred, "n" must be stored before the DMA operation.

(4) DMA Memory Address Register Channel 1 (MAR1: I/O Address = 28H to 2AH)

Specifies the physical memory address for channel 1 transfers. This may be destination or source memory address.

This register contains 19 bits and may specify up to 512k bytes memory addresses.

(5) DMA I/O Address Register Channel 1 (IAR1: I/O Address = 2BH to 2CH)

Specifies the I/O address for channel 1 transfers. This may be destination or source I/O address. This register contains 16 bits and may specify up to 64k bytes I/O addresses.

(6) DMA Byte Count Register Channel 1 (BCR1: I/O Address = 2EH to 2FH)

Specifies the number of bytes to be transferred. This register contains 16 bits and may specify up to 64k bytes transfers. When one byte is transferred, the register is decremented by one.

(7) DMA Status Register (DSTAT)

DSTAT is used to enable and disable DMA transfer and DMA termination interrupts. DSTAT also allows determining the status of a DMA transfer i.e. completed or in progress.

DMA Status Register (DSTAT : I/O Address = 30H)



DE1: DMA Enable Channel 1 (bit 7)

When DEI = 1 and DME = 1, channel 1 DMA is enabled. When a DMA transfer terminates (BCR1 = 0), DEI is reset to 0 by the DMAC. When DEI = 0 and the DMA interrupt is enabled (DIE1 = 1), a DMA interrupt request is \underline{made} to the CPU.

To perform a software write to DE1, DWE1 should be written with 0 during the same register write access. Writing DE1 to 0 disables channel 1 DMA, but DMA is restartable. Writing DE1 to 1 enables channel 1 DMA and automatically sets DME (DMA Main Enable) to 1. DE1 is cleared to 0 during RESET.

DE0: DMA Enable Channel 0 (bit 6)

When DE0 = 1 and DME = 1, channel 0 DMA is enabled. When a DMA transfer terminates (BCR0 = 0), DE0 is cleared to 0 by the DMAC. When DE0 = 0 and the DMA interrupt is enabled (DIE0 = 1), a DMA interrupt request is made to the CPU.

To perform a software write to DE0, DWE0 should be written with 0 during the same register write access. Writing DE0 to 0 disables channel 0 DMA. Writing DE0 to 1 enables channel 0 DMA and automatically sets DME (DMA Main Enable) to 1. DE0 is cleared to 0 during RESET.

DWE1: DE1 Bit Write Enable (bit 5)

When performing any software write to DE1, $\overline{DWE1}$ should be written with 0 during the same access. $\overline{DWE1}$ write value of 0 is not held and $\overline{DWE1}$ is always read as 1.

DWEO: DEO Bit Write Enable (bit 4)

When performing any software write to DE0, $\overline{DWE0}$ should be written with 0 during the same access. $\overline{DWE0}$ write value of 0 is not held and $\overline{DWE0}$ is always read as 1.

DIE1: DMA Interrupt Enable Channel 1 (bit 3)

When DIE1 is set to 1, the termination of channel 1 DMA transfer (indicated when DE1 = 0) causes a CPU interrupt request to be generated. When DIE1 = 0, the channel 1 DMA termination interrupt is disabled. DIE1 is cleared to 0 during RESET.

DIEO: DMA Interrupt Enable Channel 0 (bit 2)

When DIE0 is set to 1, the termination channel 0 of DMA transfer (indicated when DE0 = 0) causes a CPU interrupt request to be generated. When DIE0 = 0, the channel 0 DMA termination interrupt is disabled. DIE0 is cleared to 0 during RESET.

DME: DMA Main Enable (bit 0)

A DMA operation is only enabled when its DE bit (DE0 for channel 0, DE1 for channel 1) and the DME bit are set to 1.

When NMI occurs, DME is reset to 0, thus disabling DMA activity during the NMI interrupt service routine. To restart DMA, DE0 and/or DE1 should be written with 1 (even if the contents are already 1). This automatically sets DME to 1, allowing DMA operations to continue. Note that DME cannot be directly written. It is cleared to 0 by NMI or indirectly set to 1 by setting DE0 and/or DE1 to 1. DME is cleared to 0 during RESET.

(8) DMA Mode Register (DMODE)

DMODE is used to set the addressing and transfer mode for channel 0.

DMA Mode Register (DMODE : I/O Address = 31H)



DM1, DM0: Destination Mode Channel 0 (bits 5, 4)

Specifies whether the destination for channel 0 transfers is memory, I/O or memory mapped I/O and the corresponding address modifier. DM1 and DM0 are cleared to 0 during RESET.

Table 5 Destination

DM1	DMO	Memory/I/O	Address Increment/Decrement
0	0	Memory	+1
0	1	Memory	-1
1	0	Memory	fixed
1	1	I/O	fixed

SM1, SM0: Source Mode Channel 0 (bits 3, 2)

Specifies whether the source for channel 0 transfers is memory, I/O or memory mapped I/O and the corresponding address modifier. SM1 and SM0 are cleared to 0 during RESET.

Table 7 shows all DMA transfer mode combinations of DM0, DM1, SM0, SM1. Since I/O ←→ I/O transfers are not implemented, twelve combinations are available.

Table 6 Source

SM1	SMO	Memory/I/O	Address Increment/Decrement
0	0	Memory	+1
0	1	Memory	-1
1	0	Memory	fixed
1	1	I/O	fixed

Table 7 Combination of Transfer Mode

DM1	DM1 DM0 SM1 SM0		SMO	Transfer Mode	Address Increment/Decrement
0	0	0	0	Memory→Memory	SAR0+1, DAR0+1
0	0	0	1	Memory→Memory	SARO-1, DARO+1
0	0	1	0	Memory*→Memory	SARO fixed, DARO+1
0	0	1	1	I/O→Memory	SARO fixed, DARO+1
0	1	0	0	Memory→Memory	SAR0+1, DAR0-1
0	1	0	1	Memory→Memory	SAR0-1, DAR0-1
0	1	1	0	Memory*→Memory	SAR0 fixed, DAR0-1
0	1	1	1	I/O→Memory	SARO fixed, DARO-1
1	0	0	0	Memory→Memory*	SAR0+1, DAR0 fixed
1	0	0	1	Memory→Memory*	SARO-1, DARO fixed
1	0	1	0	reserved	
1	0	1	1	reserved	
1	1	0	0	Memory→I/O	SARO+1, DARO fixed
1	1	0	1	Memory→I/O	SARO-1, DARO fixed
1	1	1	0	reserved	
1	1	1	1	reserved	

•: includes memory mapped I/O

MMOD: Memory Mode Channel 0 (bit 1)

When channel 0 is configured for memory \iff memory transfers, the external $\overline{DREQ_o}$ input is not used to control the transfer timing. Instead, two automatic transfer timing modes are selectable – burst (MMOD = 1) and cycle steal (MMOD = 0). For burst memory \iff memory transfers, the DMAC will sieze control of the bus continuously until the DMA transfer completes (as shown by the byte count register = 0). In cycle steal mode, the CPU is given a cycle for each DMA byte transfer cycle until the transfer is completed.

For channel 0 DMA with I/O source or destination, the \overline{DREQ}_0 input times the transfer and thus MMOD is ignored. MMOD is cleared to 0 during RESET.

DMA/WAIT Control Register (DCNTL)

DCNTL controls the insertion of wait states into DMAC (and CPU) accesses of memory or I/O. Also, the DMA request mode for each DREQ (DREQ₀ and DREQ₁) input is defined as level or edge sense. DCNTL also sets the DMA transfer mode for channel 1, which is limited to memory \longleftrightarrow I/O transfers.

DMA/WAIT Control Register (DCNTL : I/O Address = 32H)

bit	7	6	5	4	3	2	11	0
	MWI1	MWIO	IWI1	IWIO	DMS1	DMS0	DIM1	DIMO
	R/W							

MWI1, MWI0: Memory Wait Insertion (bits 7-6)

Specifies the number of wait states introduced into CPU or DMAC memory access cycles. MWII and MWI0 are set to 1 during RESET. See section of Wait State Control for details.

IWI1, IWI0: I/O Wait Insertion (bits 5-4)

Specifies the number of wait states introduced into CPU or DMAC I/O access cycles. IWI1 and IWI0 are set to 1 during RE-SET, See section of Wait State Control for details.

DMS1, DMS0: DMA Request Sense (bits 3-2)

 $\overline{DMS1}$ and DMS0 specify the DMA request sense for channel 0 ($\overline{DREQ_0}$) and channel 1 ($\overline{DREQ_1}$) respectively. When reset to 0, the input is level sense. When set to 1, the input is edge sense. DMS1 and DMS0 are cleared to 0 during RESET.

DIM1, DIM0: DMA Channel 1 I/O and Memory Mode (bits 1-0)

Specifies the source/destination and address modifier for channel 1 memory \iff I/O transfer modes. IM1 and IM0 are cleared to 0 during RESET.

Table 8 Channel 1 Transfer Mode

DIM1	DIMO	Transfer Mode	Address Increment/Decrement
0	0	Memory→I/O	MAR1+1, IAR1 fixed
0	1	Memory→I/O	MAR1-1, IAR1 fixed
1	0	I/O→Memory	IAR1 fixed, MAR1+1
1	1	I/O→Memory	IAR1 fixed, MAR1 - 1

10.3 DMA Operation

This section discusses the three DMA operation modes for channel 0, memory → memory, memory ←→ I/O and memory ←→ memory mapped I/O. In addition, the operation of channel 0 DMA with the on-chip ASCI (Asynchronous Serial Communication Interface) as well as Channel 1 DMA are described.



(1) Memory ← → Memory - Channel 0

For memory \iff memory transfers, the external $\overline{DREQ_0}$ input is not used for DMA transfer timing. Rather, the DMA operation is timed in one of two programmable modes — burst or cycle steal. In both modes, the DMA operation will automatically proceed until termination as shown by byte count (BCR0) = 0.

In burst mode, the DMA operation will proceed until termination. In this case, the CPU cannot perform any program execution until the DMA operation is completed.

In cycle steal mode, the DMA and CPU operation are alternated after each DMA byte transfer until the DMA is completed. The sequence ...

1 CPU Machine Cycle DMA Byte Transfer

 \dots is repeated until DMA is completed. Fig. 41 shows cycle steal mode DMA timing.

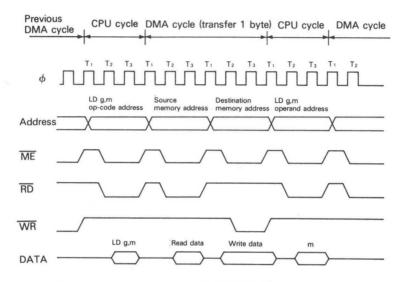


Figure 41 Cycle Steal Mode DMA Timing

To initiate memory \iff memory DMA transfer for channel 0, perform the following operations.

- Load the memory source and destination addresses into SAR0 and DAR0.
- ② Specify memory \(\lefta\rightarrow\) memory mode and address increment/decrement in the SM0, SM1, DM0 and DM1 bits of DMODE.
- 3 Load the number of bytes to transfer in BCR0.
- (4) Specify burst or cycle steal mode in the MMOD bit of DCNTL.
- ⑤ Program DE0 = 1 (with DWE0 = 0 in the same access) in DSTAT and the DMA operation will start 1 machine cycle later. If interrupt occurs at the same time, the DIE0 bit should be set to 1.

(2) Memory ←→ I/O (Memory Mapped I/O) – Channel O

For memory \iff 1/O (and memory \iff memory mapped 1/O) the \overline{DREQ}_0 input is used to time the DMA transfers. In addition, the \overline{TEND}_0 (Transfer End) output is used to indicate the last (byte count register BCR0 = 00H) transfer.

The $\overline{DREQ_0}$ input can be programmed as level or edge sensitive. When level sense is programmed, the DMA operation begins when $\overline{DREQ_0}$ is sampled LOW. If $\overline{DREQ_0}$ is sampled HIGH, after the next DMA byte transfer, control is relinquished to the HD64180 CPU. As shown in Fig. 42. $\overline{DREQ_0}$ is sampled at the rising edge of the clock cycle prior to T_3 i.e. either T_2 or Tw.

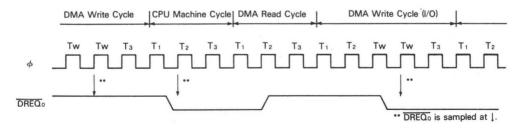


Figure 42 CPU Operation and DMA Operation (DREQ o is programmed for level sense)



When edge sense is programmed, DMA operation begins at the falling edge of \overline{DREQ}_0 . If another falling edge is detected before the rising edge of the clock prior to T_3 during DMA write cycle (i.e. T_2 or Tw), the DMAC continues operating. If an edge is not detected, the CPU is given control after the current byte DMA transfer com-

pletes. The CPU will continue operating until a \overline{DREQ}_0 falling edge is detected before the rising edge of the clock prior to T_a at which time the DMA operation will (re)start. Fig. 43 shows the edge sense DMA timing.

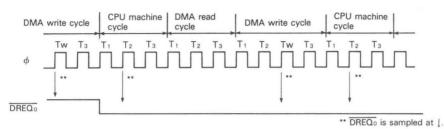


Figure 43 CPU Operation and DMA Operation (DREQ is programmed for edge sense)

During the transfers for channel 0, the \overline{TEND}_0 output will go LOW synchronous with the write cycle of the last (BCR0 = 00H)

DMA transfer as shown in Fig. 44.

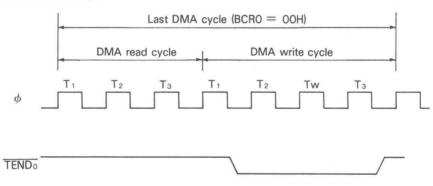


Figure 44 TEND Output Timing

The \overline{DREQ}_0 and \overline{TEND}_0 pins are programmably multiplexed with the CKA0 and CKA1 ASCI clock input/outputs. However, when DMA channel 0 is programmed for memory \longleftrightarrow I/O (and memory \longleftrightarrow memory mapped I/O) transfers, the CKA0/DRE- \overline{Q}_0 pin automatically functions as input pin even if it has been programmed as output pin for CKA0. And the CKA1/ \overline{TEND}_0 pin functions as output pin for \overline{TEND}_0 by setting CKA1D to 1 in CNTLA1.

To initiate memory \iff I/O (and memory \iff memory mapped I/O) DMA transfer for channel 0, perform the following operations.

① Load the memory and I/O or memory mapped I/O source and destination addresses into SAR0 and DAR0. Note that I/O addresses (not memory mapped I/O) are limited to 16 bits (A₀-A₁₅). Make sure that bits A₁₆ and A₁₇ are 0 (A₁₈ is a don't care) to correctly enable the external DREQ₀ input.

② Specify memory ←→ I/O or memory ←→ memory mapped I/O mode and address increment/decrement in the SM0, SM1, DM0, and DM1 bits of DMODE.

3) Load the number of bytes to transfer in BCR0.

Specify whether DREQ₀ is edge or level sense by programming the DMS0 bit of DCNTL.

(5) Enable or disable DMA termination interrupt with the DIE0 bit in DSTAT.

⑥ Program DE0 = 1 (with $\overline{DWE0} = 0$ in the same access) in

DSTAT and the DMA operation will begin under the control of the \overline{DREQ}_0 input.

(3) Memory ← → ASCI - Channel 0

Channel 0 has extra capability to support DMA transfer to and from the on-chip two channel ASCI. In this case the external \overline{DRE} - \overline{Q}_0 input is not used for DMA timing. Rather, the ASCI status bits are used to generate an internal \overline{DREQ}_0 . The TDRE (Transmit Data Register Empty) bit and the RDRF (Receive Data Register Full) bit are used to generate an internal \overline{DREQ}_0 for ASCI transmission and reception respectively.

To initiate memory \iff ASCI DMA transfer, perform the following operations.

 Load the source and destination addresses into SAR0 and DAR0. Specify the I/O (ASCI) address as follows.
 Bits A₀-A₇ should be contain the address of the ASCI channel

transmitter or receiver (I/O addresses 06H-09H).

Bits A₈-A₁₅ should equal 0.

Bits A_{17} - A_{16} should be set according to the following table to enable use of the appropriate ASCI status bit as an internal DMA request.

Table 9 DMA Request

SAR18	SAR17	SAR16	DMA Transfer Request
X	0	0	DREQ
X	0	1	RDRF (ASCI channel 0)
X	1	0	RDRF (ASCI channel 1)
X	1	1	reserved

X: Don't care

DAR18	DAR17	DAR16	DMA Transfer Request
X	0	0	DREQ
X	0	1	TDRE (ASCI channel 0)
X	1	0	TDRE (ASCI channel 1)
X	1	1	reserved

X: Don't care

- Specify memory ← → I/O transfer mode and address increment/decrement in the SM0, SM1, DM0 and DM1 bits of DMODE.
- 3 Load the number of bytes to transfer in BCR0.
- The DMA request sense mode (DMS0 bit in DCNTL) MUST be specified as 'edge sense'.
- S Enable or disable DMA termination interrupt with the DIE0 bit in DSTAT.
- 6 Program DE0 = 1 (with DWE0 = 0 in the same access) in DSTAT and the DMA operation with the ASCI will begin under control of the ASCI generated internal DMA request.

under control of the ASCI generated internal DMA request.

The ASCI receiver or transmitter being used for DMA must be initialized to allow the first DMA transfer to begin.

The ASCI receiver must be 'empty' as shown by RDRF = 0. The ASCI transmitter must be 'full' as shown by TDRE = 0. Thus, the first byte should be written to the ASCI Transmit Data Register under program control. The remaining bytes will be transferred using DMA.

(4) Channel 1 DMA

DMAC Channel 1 can perform memory \iff I/O transfers. Except for different registers and status/control bits, operation is exactly the same as described for channel 0 memory \iff I/O DMA.

To initiate DMA channel 1 memory \iff I/O transfer perform the following operations.

- ① Load the memory address (19 bits) into MAR1.
- 2 Load the I/O address (16 bits) into IAR1.
- ③ Program the source/destination and address increment/decrement mode using the DIM1 and DIM0 bits in DCNTL.
- 4 Specify whether DREQ₁ is level or edge sense in the DMS1 bit

- in DCNTL.
- ⑤ Enable or disable DMA termination interrupt with the DIE1 bit in DSTAT.
- 6 Program DE1 = 1 (with DWE1 = 0 in the same access) in DSTAT and the DMA operation with the external I/O device will begin using the external DREQ₁ input and TEND₁ output.

10.4 DMA Bus Timing

When memory (and memory mapped I/O) is specified as a source or destination, \overline{ME} goes LOW during the memory access. When I/O is specified as a source or destination, \overline{IOE} goes LOW during the I/O access.

When I/O (and memory mapped I/O) is specified as a source or destination, the \underline{DMA} timing is controlled by the external \overline{DREQ} input and the \overline{TEND} output indicates \underline{DMA} termination. Note that external I/O devices may not overlap addresses with internal I/O and control registers, even using \underline{DMA} .

For I/O accesses, 1 wait state is automatically inserted. Additional wait states can be inserted by programming the on-chip wait state generator or using the external WAIT input. Note that for memory mapped I/O accesses, this automatic I/O wait state is not inserted.

 $\overline{DREQ_0}$ input is ignored. Automatic DMA timing is programmed as either burst or cycle steal.

When a DMA memory address carry/borrow between bits $\rm A_{15}$ and $\rm A_{16}$ of the address bus occurs (when crossing 64k bytes boundaries), the minimum bus cycle is extended to four clocks by automatic insertion of one internal Ti state.

10.5 DMAC Channel Priority

For simultaneous $\overline{DREQ_0}$ and $\overline{DREQ_1}$ requests, channel 0 has priority over channel 1. When channel 0 is performing a memory \iff memory transfer, channel 1 cannot operate until the channel 0 operation has terminated. If channel 1 is operating, channel 0 cannot operate until channel 1 releases control of the bus.

10.6 DMAC and BUSREQ, BUSACK

The BUSREQ and BUSACK inputs allow another bus master to take control of the HD64180 bus. BUSREQ and BUSACK have priority over the on-chip DMAC and will suspend DMAC operation. The DMAC releases the bus to the external bus master at the breakpoint of the DMAC memory or I/O access. Since a single byte DMAC transfer requires a read and a write cycle, it is possible for the DMAC to be suspended after the DMAC read, but before the DMAC write. Even in this case, when the external master releases the HD64180 bus (BUSREQ HIGH), the on-chip DMAC will correctly continue the suspended DMA operation.

10.7 DMAC Internal Interrupts

Fig. 45 illustrates the internal DMA interrupt request generation circuit.

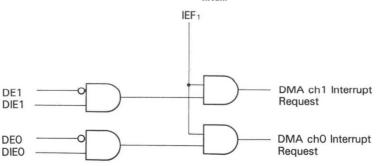


Figure 45 DMAC Interrupt Request Circuit Diagram



DE0 and DE1 are automatically cleared to 0 by the HD64180 at the completion (byte count = 0) of a DMA operation for channel 0 and channel 1 respectively. They remain 0 until a 1 is written. Since DE0 and DE1 use level sense, an interrupt will occur if the CPU IEF₁ flag is set to 1. Therefore, the DMA termination interrupt service routine should disable further DMA interrupts (by programming the channel DIE bit = 0) before enabling CPU interrupts (i.e. IEF₁ is set to 1). After reloading the DMAC address and count registers, the DIE bit can be set to 1 to reenable the channel interrupt, and at the same time DMA can resume by programming the channel DE bit = 1.

10.8 DMAC and NMI

NMI, unlike all other interrupts, automatically disables DMAC operation by clearing the DME bit of DSTAT. Thus, the NMI interrupt service routine may respond to time critical events without delay due to DMAC bus usage. Also, NMI can be effectively used as an external DMA abort input, recognizing that both channels are suspended by the clearing of DME.

If the falling edge of \overline{NMI} occurs before the falling clock of the state prior to T_3 (T_2 or Tw) of the DMA write cycle, the DMAC will be suspended and the CPU will start the \overline{NMI} response at the end of

the current cycle.

By setting a channels DE bit to 1, that channels operation can be restarted, and DMA will correctly resume from the point at which it was suspended by \overline{NMI} . See Fig. 46 for details.

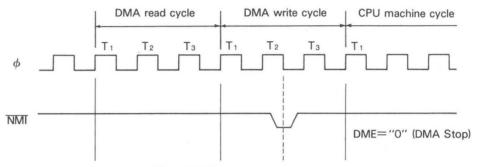


Figure 46 NMI and DMA Operation

10.9 DMAC and RESET

During RESET the bits in DSTAT, DMODE, and DCNTL are initialized as stated in their individual register descriptions. Any DMA operation in progress is stopped allowing the CPU to use the

bus to perform the RESET sequence. However, the address register (SAR0, DAR0, MAR1, IAR1) and byte count register (BCR0, BCR1) contents are not changed during RESET.



11 ASYNCHRONOUS SERIAL COMMUNICATION INTER-FACE (ASCI)

The HD64180 on-chip ASCI has two independent full duplex channels. Based on full programmability of the following functions, the ASCI can directly communicate with a wide variety of standard UARTs (Universal Asynchronous Receiver/Transmitter) including the HD6350 CMOS ACIA and the Serial Communication Interface (SCI) contained on the HD6301 series CMOS single chip controllers.

The key functions for ASCI are shown below. Each channel is independently programmable.

- · Full duplex communication
- · 7- or 8-bit data length
- · Program controlled 9th data bit for multiprocessor communica-

- tion
- · 1 or 2 stop bits
- · Odd, even, no parity
- · Parity, overrun, framing error detection
- Programmable baud rate generator, /16 and /64 modes Speed to 38.4k bits per second (CPU $f_C = 6.144 \text{ MHz}$)
- Modem control signals Channel 0 has DCD₀, CTS₀ and RTS₀ Channel 1 has CTS.
- · Programmable interrupt condition enable and disable
- · Operation with on-chip DMAC

11.1 ASCI Block Diagram

Fig. 47 shows the ASCI Block Diagram.

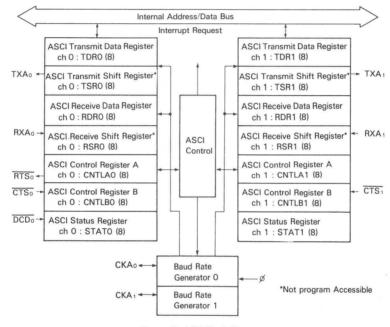


Figure 47 ASCI Block Diagram

11.2 ASCI Register Description

(1) ASCI Transmit Shift Register 0, 1 (TSR0, 1)

When the ASCI Transmit Shift Register receives data from the ASCI Transmit Data Register (TDR), the data is shifted out to the TXA pin. When transmission is completed, the next byte (if available) is automatically loaded from TDR into TSR and the next transmission starts. If no data is available for transmission, TSR idles by outputting a continuous HIGH level. This register is not program accessible.

(2) ASCI Transmit Data Register 0, 1 (TDR0, 1: I/O Address = 06H, 07H)

Data written to the ASCI Transmit Data Register is transferred to the TSR as soon as TSR is empty. Data can be written to while TSR is shifting out the previous byte of data. Thus, the ASCI transmitter is double bufferred.

Data can be written into and read from the ASCI Transmit Data Register.

If data is read from the ASCI Transmit Data Register, the ASCI

data transmit operation won't be affected by this read operation.

(3) ASCI Receive Shift Register 0, 1 (RSR0, 1)

This register receives data shifted in on the RXA pin. When full, data is automatically transferred to the ASCI Receive Data Register (RDR) if it is empty. If RSR is not empty when the next incoming data byte is shifted in, an overrun error occurs. This register is not program accessible.

(4) ASCI Receive Data Register 0, 1 (RDR0, 1: I/O Address = 08H, 09H)

When a complete incoming data byte is assembled in RSR, it is automatically transferred to the RDR if RDR is empty. The next incoming data byte can be shifted into RSR while RDR contains the previous received data byte. Thus, the ASCI receiver is double buffered.

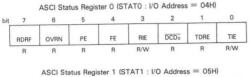
The ASCI Receive Data Register is read-only-register.

However, if RDRF = 0, data can be written into the ASCI Receive Data Register, and the data can be read.



(5) ASCI Status Register 0, 1 (STATO, 1)

Each channel status register allows interrogation of ASCI communication, error and modem control signal status as well as enabling and disabling of ASCI interrupts.



t	7	6	5	4	3	2	1	0
	RDRF	OVRN	PE	FE	RIE	CTS1E	TDRE	TIE
_	R	R	R	R	R/W	R/W	R	R/W

RDRF: Receive Data Register Full (bit 7)

RDRF is set to 1 when an incoming data byte is loaded into RDR. Note that if a framing or parity error occurs, RDRF is still set and the receive data (which generated the error) is still loaded into RDR, RDRF is cleared to 0 by reading RDR, when the $\overline{DCD_0}$ input is HIGH, in IOSTOP mode and during RESET.

OVRN: Overrun Error (bit 6)

OVRN is set to 1 when RDR is full and RSR becomes full. OVRN is cleared to 0 when the EFR bit (Error Flag Reset) of CNTLA is written to 0, when $\overline{DCD_0}$ is HIGH, in IOSTOP mode and during RESET.

PE: Parity Error (bit 5)

PE is set to 1 when a parity error is detected on an incoming data byte and ASCI parity detection is enabled (the MOD1 bit of CNTLA is set to 1). PE is cleared to 0 when the EFR bit (Error Flag Reset) of CNTLA is written to 0, when $\overline{DCD_0}$ is HIGH, in IOSTOP mode and during RESET.

FE: Framing Error (bit 4)

If a receive data byte frame is delimited by an invalid stop bit (i.e. 0, should be 1), FE is set to 1. FE is cleared to 0 when the EFR bit (Error Flag Reset) of CNTLA is written to 0, when $\overline{DCD_0}$ is HIGH, in IOSTOP mode and during RESET.

RIE: Receive Interrupt Enable (bit 3)

RIE should be set to 1 to enable ASCI receive interrupt requests. When RIE to 1, if any of the flags RDRF, OVRN, PE, FE become set to 1 an interrupt request is generated. For channel 0, an interrupt will also be generated by the transition of the external $\overline{DCD_0}$ input from LOW to HIGH. RIE is cleared to 0 during RESET.

DCD₀: Data Carrier Detect (bit 2 STAT0)

Channel 0 has an external $\overline{DCD_0}$ input pin. The $\overline{DCD_0}$ bit is set to 1 when the $\overline{DCD_0}$ input is HIGH. It is cleared to 0 on the first read of STAT0 following the HIGH to LOW transition of $\overline{DCD_0}$ input and during RESET. When $\overline{DCD_0} = 1$, receiver unit is reset and receiver operation is inhibited.

CTS1E: Channel 1 CTS Enable (bit 2 STAT1)

Channel 1 has an external \overline{CTS}_1 input which is multiplexed with the receive data pin (RXS) for the CSI/O (Clocked Serial I/O Port). Setting CTS1E to 1 selects the \overline{CTS}_1 function and clearing CTS1E to 0 selects the RXS function.

TDRE: Transmit Data Register Empty (bit 1)

TDRE = 1 indicates that the TDR is empty and the next transmit data byte can be written to TDR. After the byte is written to TDR, TDRE is cleared to 0 until the ASCI transfers the byte from the TDR to the TSR, at which time TDRE is again set to 1. TDRE

is set to 1 in IOSTOP mode and during RESET. When the external CTS input is HIGH, TDRE is reset to 0.

TIE: Transmit Interrupt Enable (bit 0)

TIE should be set to 1 to enable ASCI transmit interrupt requests. If TIE = 1, an interrupt will be requested when TDRE = 1. TIE is cleared to 0 during RESET.

· ASCI Control Register A0, 1 (CNTLA0, 1)

Each ASCI channel Control Register A configures the major operating modes such as receiver/transmitter enable and disable, data format, and multiprocessor communication mode.

ASCI Control Register A 0 (CNTLA0 : I/O Address = 00H) 3 2 4 MPBR/ RTS MOD2 MOD1 MODO TF FFR MPE RF R/W R/W R/W RAM R/W R/W R/W

ASCI Control Register A 1 (CNTLA1 : I/O Address = .01H) 0 4 3 2 MPRR CKA1D MOD2 MOD1 MODO EFR MPF RE TF R/W R/W R/W R/W R/W R/W R/W R/W

MPE: Multi Processor Mode Enable (bit 7)

The ASCI has a multiprocessor communication mode which utilizes an extra data bit for selective communication when a number of processors share a common serial bus. Multiprocessor data format is selected when the MP bit in CNTLB is set to 1. If multiprocessor mode is not selected (MP bit in CNTLB = 0), MPE has no effect. If multiprocessor mode is selected, MPE enables or disables the 'wake-up' feature as follows. If MPE is set to 1, only received bytes in which the MPB (multiprocessor bit) = 1 can affect the RDRF and error flags. Effectively, other bytes (with MPB = 0) are 'ignored' by the ASCI. If MPE is reset to 0, all bytes, regardless of the state of the MPB data bit, affect the RDRF and error flags. MPE is cleared to 0 during RESET.

RE: Receiver Enable (bit 6)

When RE is set to 1, the ASCI receiver is enabled. When RE is cleared to 0, the receiver is disabled and any receive operation in progress is interrupted. However, the RDRF and error flags are not reset and the previous contents of RDRF and error flags are held. RE is cleared to 0 in IOSTOP mode and during RESET.

TE: Transmitter Enable (bit 5)

When TE is set to 1, the ASCI transmitter is enabled. When TE is cleared to 0, the transmitter is disabled and any transmit operation in progress is interrupted. However, the TDRE flag is not reset and the previous contents of TDRE are held. TE is cleared to 0 in IOSTOP mode and during RESET.

RTS₀ - Request to Send Channel 0 (bit 4 in CNTLA0)

When $\overline{RTS_0}$ is cleared to 0, the $\overline{RTS_0}$ output pin will go LOW. When $\overline{RTS_0}$ is set to 1, the $\overline{RTS_0}$ output immediately goes HIGH. $\overline{RTS_0}$ is set to 1 during RESET.

CKA1D: CKA1 Clock Disable (bit 4 in CNTLA1)

When CKA1D is set to 1, the multiplexed CKA1/ $\overline{TEND_0}$ pin is used for the $\overline{TEND_0}$ function. When CKA1D = 0, the pin is used as CKA1, an external data clock input/output for channel 1. CKA1D is cleared to 0 during RESET.

MPBR/EFR: Multiprocessor Bit Receive/Error Flag Reset (bit 3)

When multiprocessor mode is enabled (MP in CNTLB = 1), MPBR, when read, contains the value of the MPB bit for the last re-

ceive operation. When written to 0, the EFR function is selected to reset all error flags (OVRN, FE and PE) to 0. MPBR/EFR is undefined during RESET.

MOD2, 1, 0: ASCI Data Format Mode 2, 1, 0 (bits 2-0)

These bits program the ASCI data format as follows. MOD2

 $= 0 \rightarrow 7$ bit data

 $= 1 \rightarrow 8$ bit data

MOD1

 $= 0 \rightarrow No parity$

= 1 → Parity enabled

MOD0

 $= 0 \rightarrow 1$ stop bit

 $= 1 \rightarrow 2$ stop bits

The data formats available based on all combinations of MOD2, MOD1 and MOD0 are shown in Table 10.

Table 10 Combination of Data Format

MOD2	MOD1	MODO	Data Format	
0	0	0	Start+7 bit data+1 stop	
0	0	1	Start+7 bit data+2 stop	
0	1	0	Start + 7 bit data + parity + 1 stop	
0	1	1	Start + 7 bit data + parity + 2 stop	
1	0	0	Start + 8 bit data + 1 stop	
1	0	1	Start+8 bit data+2 stop	
1	1	0	Start+8 bit data+parity+1 stop	
1	1	1	Start+8 bit data+parity+2 stop	

(6) ASCI Control Register BO, 1 (CNTLBO, 1)

Each ASCI channel control register B configures multiprocessor mode, parity and baud rate selection.

ASCI Control Register B 0 (CNTLB0 : I/O Address = 02H) ASCI Control Register B 1 (CNTLB1 : I/O Address = 03H)

bit	7	6	5	4	3	2	1	0
	MPBT	MP	CTS/ PS	PEO	DR	SS2	SS1	SSO
L	B/W	R/W	R/W	B/W	R/W	R/W	R/W	R/W

MPBT: Multiprocessor Bit Transmit (bit 7)

When multiprocessor communication format is selected (MP bit = 1), MPBT is used to specify the MPB data bit for transmission. If MPBT = 1, then MPB = 1 is transmitted. If MPBT = 0, then MPB = 0 is transmitted. MPBT state is undefined during and after RESET.

MP: Multiprocessor Mode (bit 6)

When MP is set to 1, the data format is configured for multiprocessor mode based on the MOD2 (number of data bits) and MOD0 (number of stop bits) bits in CNTLA. The format is as follows.

Start bit + 7 or 8 data bits + MPB bit + 1 or 2 stop bits

Note that multiprocessor (MP = 1) format has no provision for parity. If MP = 0, the data format is based on MOD0, MOD1 and MOD2 and may include parity. The MP bit is cleared to 0 during RESET.

CTS/PS: Clear to Send/Prescale (bit 5)

When read, CTS/PS reflects the state of the external \overline{CTS} input. If the \overline{CTS} input pin is HIGH, \overline{CTS} /PS will be read as 1. Note that when the \overline{CTS} input pin is HIGH, the TDRE bit is inhibited (i.e. held at 0). For channel 1, the \overline{CTS} , input is multiplexed with RXS pin (Clocked Serial Receive Data). Thus, \overline{CTS} /PS is only valid when read if the channel 1 \overline{CTS} 1E bit = 1 and the \overline{CTS} 1 input pin function is selected. The read data of \overline{CTS} /PS is not affected by RESET.

When written, CTS/PS specifies the baud rate generator prescale factor. If CTS/PS is set to 1, the system clock (\$\phi\$) is prescaled by 30 while if CTS/PS is cleared to 0, the system clock is prescaled by 10. CTS/PS is cleared to 0 during RESET.

PEO: Parity Even Odd (bit 4)

PEO selects even or odd parity. PEO does not affect the enabling/disabling of parity (MOD1 bit of CNTLA). If PEO is cleared to 0, even parity is selected. If PEO is set to 1, odd parity is selected. PEO is cleared to 0 during RESET.

DR: Divide Ratio (bit 3)

DR specifies the divider used to obtain baud rate from the data sampling clock. If DR is cleared to 0, divide by 16 is used while if DR is set to 1, divide by 64 is used. DR is cleared to 0 during RE-SET.

SS2, 1, 0: Source/Speed Select 2, 1, 0 (bits 2-0)

Specify the data clock source (internal or external) and baud rate prescale factor. SS2, SS1, and SS0 are all set to 1 during RESET. Table 11 shows the divide ratio corresponding to SS2, SS1, and SS0.

Table 11 Divide Ratio

SS2	SS1	SS0	Divide Ratio
0	0	0	÷1
0	0	1	÷ 2
0	1	0	÷4
0	1	1	÷8
1	0	0	÷16
1	0	1	÷32
1	1	0	÷64
1	1	1	external clock

The external ASCI channel $\frac{0}{0}$ data clock pins are multiplexed with DMA control lines (CKA₀/DREQ₀ and CKA₁/TEND₀). During RESET, these pins are initialized as ASCI data clock inputs. If SS2, SS1, and SS0 are reprogrammed (any other value than SS2, SS1, SS0 = 1) these pins become ASCI data clock outputs. However, if DMAC channel 0 is configured to perform memory \iff I/O (and memory mapped I/O) transfers the CKA₀/DREQ₀ pin revert to DMA control signals regardless of SS2, SS1, and SS0 programming. Also, if the CKA1D bit in the CNTLA register is set to 1, then the CKA₁/TEND₀ reverts to the DMA Control output function regardless of SS2, SS1, and SS0 programming.

Final data clock rates are based on $\overline{\text{CTS/PS}}$ (prescale), DR, SS2, SS1, SS0, and the HD64180 system clock (ϕ) frequency as shown

in Table 12.

Table 12 Baud Rate List

Pre	scaler		npling ate		Вац	ıd Rate		General Divide	Bau	d Rate (Exam (BPS)	nple)		CKA
PS	Divide Ratio	DR	Rate	SS2	SS1	SSO	Divide Ratio	Ratio	φ=6.144 MHz	φ=4.608 MHz	φ=3.072 MHz	I/O	Clock
				0	0	0	÷1	φ÷160	38400		19200		φ÷10
				0	0	1	2	320	19200		9600		20
				0	1	0	4	640	9600		4800		40
		0	16	0	1	1	8	1280	4800		2400	0	80
				1	0	0	16	2560	2400		1200		160
				1	0	1	32	5120	1200		600		320
				1	1	0	64	10240	600		300		640
0	φ÷10			1	1	1	_	fc÷16	-	_	-	T	fo
				0	0	0	÷ 1	φ÷640	9600		4800		φ÷10
				0	0	1	2	1280	4800		2400		20
				0	1	0	4	2560	2400		1200		40
		1	64	0	1	1	8	5120	1200		600	0	80
				1	0	0	16	10240	600		300		160
				1	0	1	32	20480	300		150		320
				1	1	0	64	40960	150		75		640
				1	1	1	_	fc÷64	_	-	-	1	fc
				0	0	0	÷ 1	φ÷480		9600			φ÷30
				0	0	1	2	960		4800			60
				0	1	0	4	1920		2400			120
		0	16	0	1	1	8	3840		1200		0	240
				1	0	0	16	7680		600			480
				1	0	1	32	15360		300			960
				1	1	0	64	30720		150			1920
1	φ÷30			1	1	1	-	fc÷16	_	-	-	1	fc
				0	0	0	÷1	φ÷1920		2400			φ÷30
				0	0	1	2	3840		1200	1		60
				0	1	0	4	7680		600	1		120
		1	64	0	1	1	8	15360		300		0	240
				1	0	0	16	30720		150			480
				1	0	1	32	61440		75			960
				1	1	0	64	122880		37.5			1920
				1	1	1	-	fc÷64	-	-	-	1	fc

 $\begin{array}{c} \textbf{11.3 MODEM Control } \underline{\textbf{Signals}} \\ ASCI \ channel \ 0 \ has \ \overline{CTS_0}, \ \overline{DCD_0}, \ \underline{and} \ \overline{RTS_0} \ external \ modem \\ control \ signals. \ ASCI \ channel \ 1 \ has \ a \ \overline{CTS_1} \ modem \ control \ signal \\ \end{array}$ which is multiplexed with RXS pin (Clocked Serial Receive Data).

(1) CTS₀: Clear to Send 0 (input)

The CTS₀ input allows external control (start/stop) of ASCI channel 0 transmit operations. When CTS₀ is HIGH, channel 0 TDRE bit is held at 0 regardless of whether the TDR0 (Transmit Data Register) is full or empty. When CTS₀ is LOW, TDRE will reflect the state of $\overline{TDR0}$. Note that the actual transmit operation is not disabled by \overline{CTS}_0 HIGH, only TDRE is inhibited.

(2) DCD₀: Data Carrier Detect 0 (input)

The DCD input allows external control (start/stop) of ASCI channel 0 receive operations. When DCD is HIGH, channel 0 RDRF bit is held at 0 regardless of whether the RDR0 (Receive Data Register) is full or empty. The error flags (PE, FE and OVRN bits) are also held at 0. Even after the DCD₀ input goes LOW, these bits will not resume normal operation until the status register (STAT0) is read. Note that this first read of STAT0, while enabling normal operation, will still indicate the $\overline{DCD_0}$ input is HIGH $(\overline{DCD0}$ bit = 1) even though it has gone LOW. Thus, the STATO register should be read twice to insure the $\overline{DCD0}$ bit is cleared to 0.

RTS₀: Request to Send 0 (output)

RTS, allows the ASCI to control (start/stop) another communication devices transmission (for example, by connection to that devices CTS input). RTS₀ is essentially a 1 bit output port, having no side effects on other ASCI registers or flags.

(4) CTS1: Clear to Send 1 (input)

Channel 1 CTS, input is multiplexed with the RXS pin (Clocked Serial Receive Data). The CTS₁ function is selected when the CTS1E bit in STAT1 is set to 1. When enabled, the CTS1 operation is equivalent to CTS₀.

Modem control signal timing is shown in Fig. 48 (a) and Fig. 48 (b).

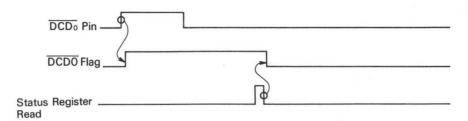


Figure 48 (a) DCD Timing

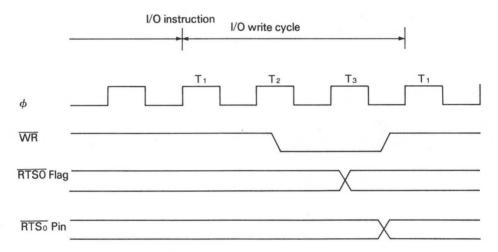


Figure 48 (b) RTS Timing

11.4 ASCI Interrupts
Fig. 49 shows the ASCI interrupt request generation circuit.

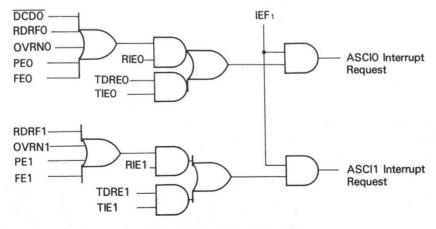


Figure 49 ASCI Interrupt Request Circuit Diagram



11.5 ASCI ←→ DMAC operation

Operation of the ASCI with the on-chip DMAC channel 0 requires the DMAC be correctly configured to utilize the ASCI flags as DMA request signals.

11.6 ASCI and RESET

During RESET, the ASCI status and control registers are initialized as defined in the individual register descriptions.

Receive and Transmit operations are stopped during RESET. However, the contents of the transmit and receive data registers (TDR and RDR) are not changed by RESET.

11.7 ASCI Clock

In external clock input mode, the external clock is directly input to the sampling rate $(\pm 16/\pm 64)$ as shown in Fig. 50.

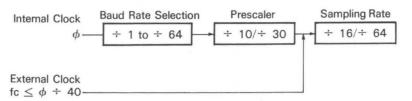


Figure 50 ASCI Clock Block Diagram

12 CLOCKED SERIAL I/O PORT (CSI/O)

The HD64180 includes a simple, high speed clock synchronous serial 1/O port. The CSI/O includes transmit/receive (half duplex), fixed 8-bit data and internal or external data clock selection. High speed operation (baud rate as high as 200k bits/second at $f_{\rm C}=4$ MHz) is provided. The CSI/O is ideal for implementing a multiprocessor communication link between the HD64180 and the HMCS400 series (4-bit) and the HD6301 series (8-bit) single chip

controllers as well as additional HD64180s. These secondary devices may typically perform a portion of the system I/O processing such as keyboard scan/decode, LDC interface etc.

12.1 CSI/O Block Diagram

The CSI/O block diagram is shown in Fig. 51. The CSI/O consists of two registers — the Transmit/Receive Data Register (TRDR) and Control Register (CNTR).

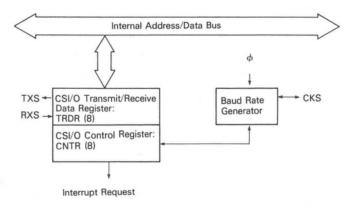


Figure 51 CSI/O Block Diagram

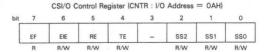
12.2 CSI/O Register Description

CSI/O Transmit/Receive Data Register (TRDR: I/O Address = OBH)

TRDR is used for both CSI/O transmission and reception. Thus, the system design must insure that the constraints of half-duplex operation are met (Transmit and receive operation can't occur simultaneously). For example, if a CSI/O transmission is attempted at the same time that the CSI/O is receiving data, a CSI/O will not work. Also note that TRDR is not buffered. Therefore, attempting to perform a CSI/O transmit while the previous transmit data is still being shifted out causes the shift data to be immediately updated, thereby corrupting the transmit operation in progress. Similarly, reading TRDR while a transmit or receive is in progress should be avoided.

(2) CSI/O Control/Status Register (CNTR: I/O Address = 0AH)

CNTR is used to monitor CSI/O status, enable and disable the CSI/O, enable and disable interrupt generation and select the data clock speed and source.



EF: End Flag (bit 7)

EF is set to 1 by the CSI/O to indicate completion of an 8-bit data transmit or receive operation. If EIE (End Interrupt Enable)

bit =1 during the time EF =1, a CPU interrupt request will be generated. Program access of TRDR should only occur if EF =1. The CSI/O clears EF to 0 when TRDR is read or written. EF is cleared to 0 during RESET and IOSTOP mode.

EIE: End Interrupt Enable (bit 6)

EIE should be set to 1 to enable EF = 1 to generate a CPU interrupt request. The interrupt request is inhibited if EIE is cleared to 0. EIE is cleared to 0 during RESET.

RE: Receive Enable (bit 5)

A CSI/O receive operation is started by setting RE to 1. When RE is set to 1, the data clock is enabled. In internal clock mode, the data clock is output from the CKS pin. In external clock mode, the clock is input on the CKS pin. In either case, data is shifted in on the RXS pin in synchronization with the (internal or external) data clock. After receiving 8 bits of data, the CSI/O automatically clears RE to 0, EF is set to 1 and an interrupt (if enabled by EIE = 1) will be generated. Note that RE and TE should never both be set to 1 at the same time. RE is cleared to 0 during RESET and IOSTOP mode.

Note that the RXS pin (pin 52) is multiplexed with $\overline{CTS_1}$ modem control input of ASCI channel 1. In order to enable the RXS function, the CTS1E bit in CNTA1 should be reset to 0.

TE: Transmit Enable (bit 4)

A CSI/O transmit operation is started by setting TE to 1. When TE is set to 1, the data clock is enabled. In internal clock mode, the data clock is output from the CKS pin. In external clock mode, the clock is input on the CKS pin. In either case, data is shifted out on the TXS pin synchronous with the (internal or external) data clock. After transmitting 8 bits of data, the CSI/O automatically clears TE

to 0, EF is set to 1 and an interrupt (if enabled by EIE = 1) will be generated. Note that TE and RE should never both be set to 1 at the same time. TE is cleared to 0 during RESET and IOSTOP mode.

SS2, 1, 0: Speed Select 2, 1, 0 (bits 2-0)

SS2, SS1 and SS0 select the CSI/O transmit/receive clock source and speed. SS2, SS1 and SS0 are all set to 1 during RESET. Table 13 shows CSI/O Baud Rate Selection.

Table 13 CSI/O Baud Rate Selection

SS2	SS1	SS0	Divide Ratio	Baud Rate
0	0	0	÷20	(200000)
0	0	1	÷40	(100000)
0	1	0	÷80	(50000)
0	1	1	÷160	(25000)
1	0	0	÷320	(12500)
1	0	1	÷640	(6250)
1	1	0	÷1280	(3125)
1	1	1		Clock input an ÷ 20)

() shows the baud rate (BPS) at $\phi = 4$ MHz.

After RESET, the CKS pin is configured as an external clock input (SS2, SS1, SS0 = 1). Changing these values causes CKS to become an output pin and the selected clock will be output when transmit or receive operations are enabled.

12.3 CSI/O Interrupts

The CSI/O interrupt request circuit is shown in Fig. 52.

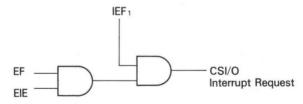


Figure 52 CSI/O Interrupt Circuit Diagram

12.4 CSI/O Operation

The CSI/O can be operated using status polling or interrupt driven algorithms.

(1) Transmit - Polling

- ① Poll the TE bit in CNTR until TE = 0.
- 2 Write the transmit data into TRDR.
- 3 Set the TE bit in CNTR to 1.
- 4 Repeat 1 to 3 for each transmit data byte.

(2) Transmit - Interrupts

- 1) Poll the TE bit in CNTR until TE = 0.
- 2 Write the first transmit data byte into TRDR.
- 3 Set the TE and EIE bits in CNTR to 1.
- When the transmit interrupt occurs, write the next transmit data byte into TRDR.
- Set the TE bit in CNTR to 1.
- 6 Repeat 4 to 5 for each transmit data byte.

(3) Receive - Polling

- 1) Poll the RE bit in CNTR until RE = 0.
- ② Set the RE bit in CNTR to 1.
- (3) Poll the RE bit in CNTR until RE = 0.

- 4 Read the receive data from TRDR.
- S Repeat 2 to 4 for each receive data byte.

(4) Receive - Interrupts

- ① Poll the RE bit in CNTR until RE = 0.
- ② Set the RE and EIE bits in CNTR to 1.
- 3 When the receive interrupt occurs read the receive data from TRDR.
- 4 Set the RE bit in CNTR to 1.
- (5) Repeat 3 to 4 for each receive data byte.

12.5 CSI/O Operation Timing Notes

- Note that transmitter clocking and receiver sampling timings are different from internal and external clocking modes. Fig. 53 to Fig. 54 shows CSI/O Transmit/Receive Timing.
- (2) The transmitter and receiver should be disabled (TE and RE = 0) when initializing or changing the baud rate.

12.6 CSI/O Operation Notes

Disable the transmitter and receiver (TE and RE = 0) before
initializing or changing the baud rate. When changing the baud
rate after completion of transmission or reception, a delay of at
least one bit time is required before baud rate modification.

- (2) When RE or TE is cleared to 0 by software, a corresponding receive or transmit operation is immediately terminated. Normally, TE or RE should only be cleared to 0 when EF = 1.
- (3) Simultaneous transmission and reception is not possible. Thus, TE and RE should not both be 1 at the same time.

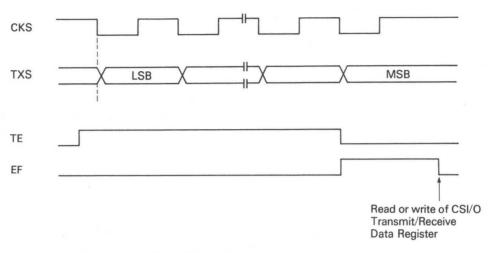


Figure 53 Transmit Timing - Internal Clock

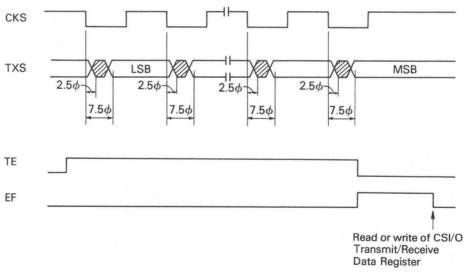


Figure 54 Transmit Timing - External Clock

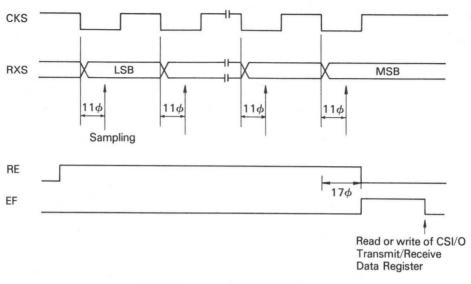


Figure 55 Receive Timing - Internal Clock

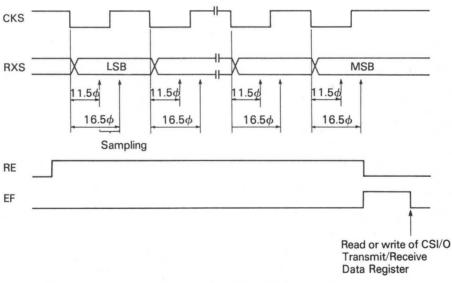


Figure 56 Receive Timing — External Clock

12.7 CSI/O and RESET During RESET each bit in the CNTR is initialized as defined in

the CNTR register description.

CSI/O transmit and receive operations in progress are aborted during RESET. However, the contents of TRDR are not changed.

13 PROGRAMMABLE RELOAD TIMER (PRT)

The HD64180 contains a two channel 16-bit Programmable Reload Timer. Each PRT channel contains a 16-bit down counter and a 16-bit reload register. The down counter can be directly read and written and a down counter overflow interrupt can be programmably enabled or disabled. In addition, PRT channel 1 has a TOUT output pin (multiplexed with A_{18}) which can be set HIGH, LOW, or toggled. Thus PRT1 can perform programmable output waveform

generation.

13.1 PRT Block Diagram

The PRT block diagram is shown in Fig. 57. The two channels have separate timer data and reload registers and a common status/control register. The PRT input clock for both channels is equal to the system clock (ϕ) divided by 20.

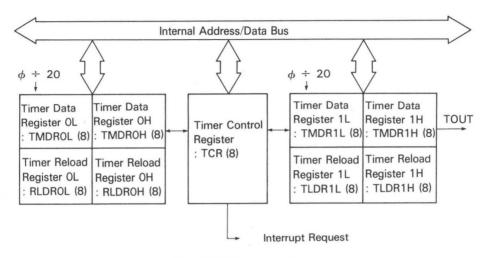


Figure 57 PRT Block Diagram

13.2 PRT Register Description

(1) Timer Data Register (TMDR: I/O Address = CH0: ODH, OCH CH1: 15H, 14H)

PRT0 and PRT1 each have 16-bit Timer Data Registers (TMDR). TMDR0 and TMDR1 are each accessed as low and high byte registers (TMDR0H, TMDR0L and TMDR1H, TMDR1L). During RESET, TMDR0 and TMDR1 are set to FFFFH.

TMDR is decremented once every twenty ϕ clocks. When TMDR counts down to 0, it is automatically reloaded with the value contained in the Reload Register (RLDR).

TMDR can be read and written by software using the following procedures. The read procedure uses a PRT internal temporary storage register to return accurate data without requiring the timer to be stopped. The write procedure requires the PRT to be stopped.

For reading (without stopping the timer), TMDR must be read in the order of lower byte — higher byte (TMDRnL, TMDRnH). The lower byte read (TMDRnL) will store the higher byte value in an internal register. The following higher byte read (TMDRnH) will access this internal register. This procedure insures timer data validity by eliminating the problem of potential 16-bit timer updating between each 8-bit read. Specifically, reading TMDR in higher byte — lower byte order may result in invalid data. Note the implications of TMDR higher byte internal storage for applications which may read only the lower and/or higher bytes. In normal operation all TMDR read routines should access both the lower and higher bytes, in that order.

For writing, the TMDR down counting must be inhibited using the TDE (Timer Down Count Enable) bits in the TCR (Timer Control Register), following which any or both higher and lower bytes of TMDR can be freely written (and read) in any order.

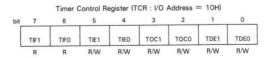
(2) Timer Reload Register (RLDR: I/O Address = CH0: OEH, OFH CH1: 16H, 17H)

PRT0 and PRT1 each have 16-bit Timer Reload Registers (RLDR). RLDR0 and RLDR1 are each accessed as low and high byte registers (RLDR0H, RLDR0L and RLDR1H, RLDR1L). During RESET RLDR0 and RLDR1 are set to FFFFH.

When the TMDR counts down to 0, it is automatically reloaded with the contents of RLDR.

(3) Timer Control Register (TCR)

TCR monitors both channels (PRT0, PRT1) TMDR status and controls enabling and disabling of down counting and interrupts as well as controlling the output pin ($A_{18}/TOUT$) for PRT 1.



TIF1: Timer Interrupt Flag 1 (bit 7)

When TMDR1 decrements to 0, TIF1 is set to 1. This can generate an interrupt request if enabled by TIE1 = 1. TIF1 is reset to 0 when TCR is read and the higher or lower byte of TMDR1 are read. During RESET, TIF1 is cleared to 0.

TIFO: Timer Interrupt Flag 0 (bit 6)

When TMDR0 decrements to 0, TIF0 is set to 1. This can generate an interrupt request if enabled by TIE0 = 1. TIF0 is reset to 0 when TCR is read and the higher or lower byte of TMDR0 are read. During RESET, TIF0 is cleared to 0.



TIE1: Timer Interrupt Enable 1 (bit 5)

When TIE1 is set to 1, TIF1 = 1 will generate a CPU interrupt request. When TIE1 is reset to 0, the interrupt request is inhibited. During RESET, TIE1 is cleared to 0.

TIEO: Timer Interrupt Enable 0 (bit 4)

When TIE0 is set to 1, TIF0 = 1 will generate a CPU interrupt request. When TIE0 is reset to 0, the interrupt request is inhibited. During RESET, TIE0 is cleared to 0.

TOC1, 0: Timer Output Control (bits 3, 2)

TOC1 and TOC0 control the output of PRT1 using the multip-lexed A_{1s} /TOUT pin as shown below. During RESET, TOC1 and TOC0 are cleared to 0. This selects the address function for A_{1s} /TOUT. By programming TOC1 and TOC0, the A_{1s} /TOUT pin can be forced HIGH, LOW or toggled when TMDR1 decrements to 0.

TOC1	TOCO		OUTPUT
0	0	Inhibited	(A 18/TOUT pin is selected as an address output function.)
0	1	toggled*	/4 /70117 : : :
1	0	0 -	(A 18/TOUT pin is selected as a PRT1 output function.)
1	1	1 .1	as a ritt i output function.

 When TMDR1 decrements to 0, TOUT level is reversed. This can provide square wave with 50% duty to external devices without any software support.

TDE1, 0: Timer Down Count Enable (bits 1, 0)

TDE1 and TDE0 enable and disable down counting for TMDR1 and TMDR0 respectively. When TDEn (n = 0, 1) is set to 1, down counting is executed for TMDRn. When TDEn is reset to 0, down counting is stopped and TMDRn can be freely read or written. TDE1 and TDE0 are cleared to 0 during RESET and TMDRn will not decrement until TDEn is set to 1.

Fig. 58 shows timer initialization, count down and reload timing. Fig. 59 shows timer output (A₁₈/TOUT) timing.

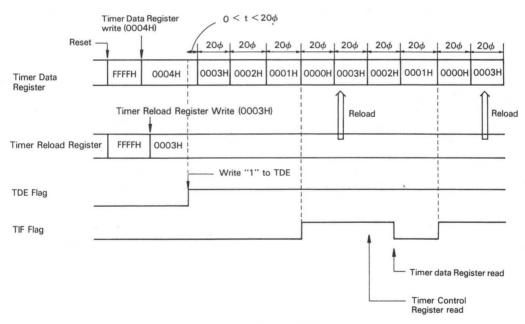


Figure 58 PRT Operation Timing

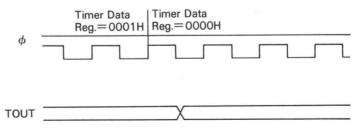


Figure 59 PRT Output Timing



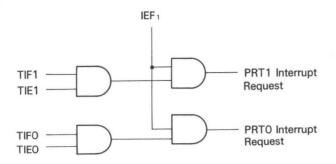


Figure 60 PRT Interrupt Request Circuit Diagram

13.3 PRT Interrupts

The PRT interrupt request circuit is shown in Fig. 60.

13.4 PRT and RESET

During RESET the bits in TCR are initialized as defined in the TCR register description. Down counting is stopped and the TMDR and RLDR registers are initialized to FFFFH. The $A_{18}/TOUT$ pin reverts to the address output function.

13.5 PRT Operation Notes

- TMDR data can be accurately read without stopping down counting by reading the lower (TMDRnL*) and higher (TMDRnH*) bytes in that order. Or, TMDR can be freely read or written by stopping the down counting.
- (2) Care should be taken to insure that a timer reload does not occur during or between lower (RLDRnL*) and higher (RLDRnH*) byte writes. This may be guaranteed by system design/timing or by stopping down counting (with TMDR containing a non-zero value) during the RLDR updating. Similarly, in applications in which TMDR is written at each TMDR overflow, the system/software design should guarantee that RLDR can be updated before the next overflow occurs. Otherwise, time base inaccuracy will occur.
- NOTE: * n = 0, 1

 (3) During RESET, the multiplexed A₁₈/TOUT pin reverts to the address output.
 - By reprogramming the TOC1 and TOC0 bits, the timer output

function for PRT channel 1 can be selected. The following shows the initial state of the TOUT pin after TOC1 and TOC0 are programmed to select the PRT channel 1 timer output function.

(i) PRT (channel 1) has not counted down to 0.

If the PRT has not counted down to 0 (timed out), the initial state of TOUT depends on the programmed value in TOC1 and TOC0.

TOC1 TOCO		TOUT State After Programming TOC1/TOC0	TOUT State After Next Timeout
0	1	HIGH (1)	LOW (0)
1	0	HIGH (1)	LOW (0)
1	1	HIGH (1)	HIGH (1)

(ii)PRT (channel 1) has counted down to 0 at least once. If the PRT has counted down to 0 (timed out) at least once, the initial state of TOUT depends on the number of time outs (even or odd) that have occurred.

Numbers of Timeouts (even or odd)	TOUT State After Programming TOC1/TOC0
Even (2, 4, 6)	HIGH (1)
Odd (1, 3, 5)	LOW (0)

14 INTERNAL I/O REGISTERS

The HD64180 internal I/O Registers occupy 64 I/O addresses (including reserved addresses). These registers access the internal I/O modules (ASCI, CSI/O, PRT) and control functions (DMAC, DRAM refresh, interrupts, wait state generator, MMU and I/O relocation).

To avoid address conflicts with external I/O, the HD64180 internal I/O addresses can be relocated on 64 bytes boundaries within the bottom 256 bytes of the 64k bytes I/O address space.

14.1 I/O Control Register (ICR)

ICR allows relocating of the internal I/O addresses. ICR also controls enabling/disabling of the IOSTOP mode.

		1/0 0	ontrol Reg	ister (IC	R : I/O A	ddress =	3FH)	
bit	7	6	5	4	3	2	1	0
	IOA7	IOA6	IOSTP	_	-	-	-	-
	R/W	R/W	R/W					

IOA7,6: I/O Address Relocation (bits 7-6)

IOA7 and IOA6 relocate internal I/O as shown in Fig. 61. Note that the high-order 8 bits of 16-bit internal I/O addresses are always 0. IOA7 and IOA6 are cleared to 0 during RESET.

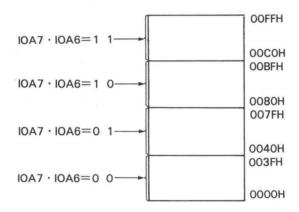


Figure 61 Internal I/O Address Relocation

IOSTP: IOSTOP Mode (bit 5)

IOSTOP mode is enabled when IOSTP is set to 1. Normal I/O operation resumes when IOSTP is reset to 0. IOSTP is cleared to 0 during RESET.

14.2 Internal I/O Registers Address Map

The internal I/O register addresses are shown in Table 14. These addresses are relative to the 64 bytes boundary base address specified in ICR.

Table 14 Internal I/O Register Address Map (1)

	Pagistar	Mnemonic	Add	dress
	Register	Minemonic	Binary	Hexadecima
	ASCI Control Register A Ch 0	CNTLAO	XX000000	00H
	ASCI Control Register A Ch 1	CNTLA1	XX000001	01H
	ASCI Control Register B Ch 0	CNTLBO	XX000010	02H
	ASCI Control Register B Ch 1	CNTLB1	XX000011	03H
ASCI	ASCI Status Register Ch 0	STATO	XX000100	04H
ASCI	ASCI Status Register Ch 1	STAT1	XX000101	05H
	ASCI Transmit Data Register Ch 0	TDRO	XX000110	06H
	ASCI Transmit Data Register Ch 1	TDR1	XX000111	07H
	ASCI Receive Data Register Ch 0	RDR0	XX001000	08H
	ASCI Receive Data Register Ch 1	RDR1	XX001001	09H
CSI/O	CSI/O Control Register	CNTR	XX001010	OAH
CS1/O	CSI/O Transmit/Receive Data Register	TRDR	XX001011	ОВН
	Timer Data Register Ch OL	TMDROL	XX001100	ОСН
	Timer Data Register Ch OH	TMDROH	XX001101	ODH
	Reload Register Ch OL	RLDROL	XX001110	OEH
	Reload Register Ch OH	RLDROH	XX001111	OFH
	Timer Control Register	TCR	XX010000	10H
Timer	Reserved		XX010001	11H
Timer			5	5
			XX010011	13H
	Timer Data Register Ch 1L	TMDR1L	XX010100	14H
	Timer Data Register Ch 1H	TMDR1H	XX010101	15H
	Reload Register Ch 1L	RLDR1L	XX010110	16H
	Reload Register Ch 1H	RLDR1H	XX010111	17H
	Free Running Counter	FRC	XX011000	18H
O4h	Reserved		XX011001	19H
Others			1 5	1 5
			XX011111	1FH



Table 14 Internal I/O Register Address Map (2)

	Register	Mnemonic	Address		
		Willetholic	Binary	Hexadecima	
	я				
	DMA Source Address Register Ch 0L	SAROL	XX100000	20H	
	DMA Source Address Register Ch 0H	SAROH	XX100001	21H	
	DMA Source Address Register Ch 0B	SAROB	XX100010	22H	
	DMA Destination Address Register Ch OL	DAROL	XX100011	23H	
	DMA Destination Address Register Ch OH	DAROH	XX100100	24H	
	DMA Destination Address Register Ch OB	DAROB	XX100101	25H	
	DMA Byte Count Register Ch OL	BCROL	XX100110	26H	
	DMA Byte Count Register Ch 0H	BCROH	XX100111	27H	
	DMA Memory Address Register Ch 1L	MAR1L	XX101000	28H	
DMA	DMA Memory Address Register Ch 1H	MAR1H	XX101001	29H	
	DMA Memory Address Register Ch 1B	MAR1B	XX101010	2AH	
	DMA I/O Address Register Ch 1L	IAR1L	XX101011	2BH	
	DMA I/O Address Register Ch 1H	IAR1H	XX101100	2CH	
	Reserved		XX101101	2DH	
	DMA Byte Count Register Ch 1L	BCR1L	XX101110	2EH	
	DMA Byte Count Register Ch 1H	BCR1H	XX101111	2FH	
	DMA Status Register	DSTAT	XX110000	30H	
	DMA Mode Register	DMODE	XX110001	31H	
	DMA/WAIT Control Register	DCNTL	XX110010	32H	
	IL Register (Interrupt Vector Low Register)	IL.	XX110011	33H	
INT	INT/TRAP Control Register	ITC	XX110100	34H	
	Reserved		XX110101	35H	
Refresh	Refresh Control Register	RCR	XX110110	36H	
Nellesii	Reserved		XX110111	37H	
	MMU Common Base Register	CBR	XX111000	38H	
MMU	MMU Bank Base Register	BBR	XX111001	39H	
	MMU Common/Bank Area Register	CBAR	XX111010	ЗАН	
	Reserved		XX11,1011	3BH	
1/0)		
			XX111110	3EH	
	I/O Control Register	ICR	XX111111	3FH	

14.3 I/O Addressing Notes

The internal I/O register addresses are located in the I/O address space from 0000H to 00FFH (16-bit I/O addresses). Thus, to access the internal I/O registers (using I/O instructions), the high-order 8 bits of the 16-bit I/O address must be 0.

The conventional I/O instructions (OUT (m), A/ IN A, (m) / OUTI / INI/ etc.) place the contents of a CPU register on the high-order 8 bits of the address bus, and thus may be difficult to use for accessing internal I/O registers.

For efficient internal I/O register access, a number of new instructions have been added, which force the high-order 8 bits of the 16-bit I/O address to 0. These instructions are IN0, OUT0, OTIM,

OTIMR, OTDM, OTDMR and TSTIO (See section 19 Instruction Set).

Note that when writing to an internal I/O register, the same I/O write occurs on the external bus. However, the duplicate external I/O write cycle will exhibit internal I/O write cycle timing. For example, the WAIT input and programmable wait state generator are ignored. Similarly, internal I/O read cycles also cause a duplicate external I/O read cycle — however, the external read data is ignored by the HD64180.

Normally, external I/O addresses should be chosen to avoid overlap with internal I/O addresses to avoid duplicate I/O accesses.

15 E CLOCK OUTPUT TIMING - 6800 TYPE BUS INTERFACE

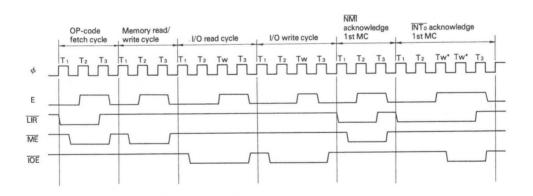
A large selection of 6800 type peripheral devices can be connected to the HD64180, including the Hitachi 6300 CMOS series (6321 PIA, 6350 ACIA, etc.) as well as 6500 family devices.

These devices require connection with the HD64180 synchronous E clock output. The speed (access time) required for the peripheral device are determined by the HD64180 clock rate. Table 15, Fig. 62 and Fig. 63 define E clock output timing.

Table 15 E Clock Timing in Each Condition

Condition	Duration of E Clock Output "High"			
Op-code Fetch Cycle Memory Read/Write Cycle	T2† - T3↓	$(1.5\phi + n_w \cdot \phi)$		
I/O read Cycle	1st Tw↑ — T₃↓	$(0.5\phi + n_w \cdot \phi)$		
I/O Write Cycle	1st Tw↑ - T₃↑	$(n_w \cdot \phi)$		
NMI Acknowledge 1st MC	$T_2 \uparrow - T_3 \downarrow$	(1.5ϕ)		
INTo Acknowledge 1st MC	1st Tw↑ - T₃↓	$(0.5\phi + n_w \cdot \phi)$		
BUS RELEASE mode SLEEP mode SYSTEM STOP mode	$\phi \downarrow - \phi \downarrow$	(2φ or 1φ)		

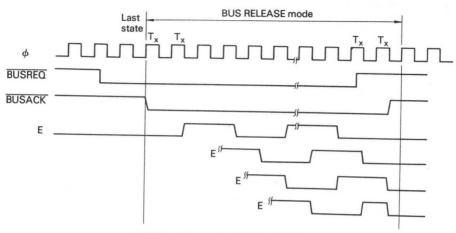
NOTE) n_w : the number of wait states MC : Machine Cycle



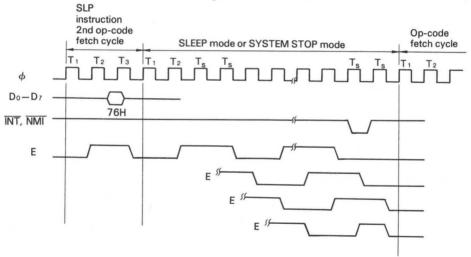
* Two wait states are automatically inserted.

NOTE) MC: Machine Cycle

Figure 62 E Clock Timing (During Read/Write Cycle and Interrupt Acknowledge Cycle)



(a) E Clock Timing in BUS RELEASE Mode



(b) E Clock Timing in SLEEP Mode and SYSTEM STOP Mode

Figure 63 E Clock Timing (in BUS RELEASE mode, SLEEP mode, SYSTEM STOP mode)

Wait states inserted in op-code fetch, memory read/write and I/O read/write cycles extend the duration of E clock output HIGH. Note that during I/O read/write cycles with no wait states (only occurs during on-chip I/O register accesses), E will not go HIGH.

The correspondence between the duration of E clock output HIGH and standard peripheral device speed selections is as follows.

Device Speed Selection	Required duration of E clock output HIGH
I.O MHz (ex: HD6321P)	500 ns min.
.5 MHz (ex: HD63A21P)	333 ns min.
2.0 MHz (ex: HD63B21P)	230 ns min.

15.1 6800 Type Bus Interfacing Note

When the HD64180 is connected to 6800 type peripheral LSIs with E clock, the 6800 type peripheral LSIs should be located in I/O address space.

If the 6800 type peripheral LSIs are located in memory address space, WR set-up time and WR hold time for E clock won't be guaranteed during memory read/write cycles and 6800 type peripheral LSIs can't be connected correctly.

16 ON-CHIP CLOCK GENERATOR

The HD64180 contains a crystal oscillator and system clock (ϕ) generator. A crystal can be directly connected or an external clock input can be provided. In either case, the system clock (ϕ) is equal to one-half the input clock. For example, a crystal or external clock

input of 8 MHz corresponds with a system clock rate of $\phi=4$ MHz.

The following table shows the AT cut crystal characteristics (Co, Rs) and the load capacitance (CL1, CL2) required for various frequencies of HD64180 operation.

Table	16	Cr	ystal	Charact	teristics

Clock Frequency	4MHz	4MHz < f ≤ 12MHz	12MHz < f ≤ 16MHz
Со	< 7 pF	< 7 pF	< 7 pF
Rs	<60Ω	<60Ω	<60Ω
CL ₁ , CL ₂	10 to 22 pF ± 10%	10 to 22 pF ± 10%	10 to 22 pF ± 10%

If an external clock input is used instead of a crystal, the waveform (twice the ϕ clock rate) should exhibit a $50\%\pm5\%$ duty cycle. Note that the minimum clock input HIGH voltage level is $V_{CC}-0.6V.$ The external clock input is connected to the EXTAL pin, while the XTAL pin is left open. Fig. 64 shows external clock interface.

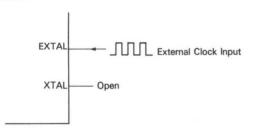


Figure 64 External Clock Interface

Fig. 65 shows the HD64180 clock generator circuit while Fig. 66 and Fig. 67 specify circuit board design rules.

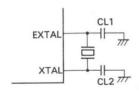


Figure 65 Crystal Interface

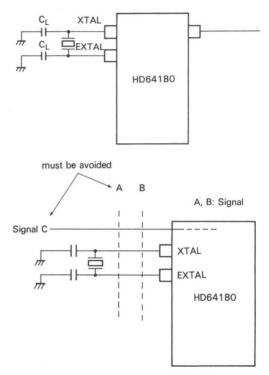


Figure 66 Note for Board Design of the Oscillation Circuit

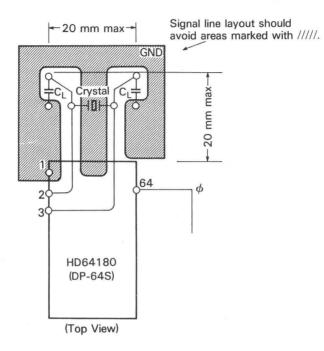


Figure 67 Example of Board Design

Circuit Board design should observe the followings.

- To prevent induced noise, the crystal and load capacitors should be physically located as close to the LSI as possible.
- (2) Signal lines should not run parallel to the clock oscillator inputs. In particular, the clock input circuitry and the system clock φ output should be separated as much as possible.
- (3) Similar to (2), $V_{\rm CC}$ power lines should be separated from the clock oscillator input circuitry.
- (4) Resistivity between XTAL or EXTAL and the other pins should be greater than 10M ohms. Signal line layout should avoid areas marked with /////.

17 MISCELLANEOUS

Free Running Counter (I/O Address = 18H)

Read only 8-bit free running counter without control registers and status registers. The contents of the 8-bit free running counter is counted down by 1 with an interval of 10ϕ clock cycles. The free running counter continues counting down without being affected by the read operation.

If data is written into the free running counter, we can't guarantee the interval of DRAM refresh cycle and baud rates of ASCI and CSI/O.

In IOSTOP mode, the free running counter continues counting down. It is initialized to FFH during RESET.

18 OPERATION NOTES

18.1 Spike Noise on TOUT

When $A_{18}/TOUT$ pin functions as TOUT and outputs LOW, spike noise up to 2V may appear on the TOUT output at address outputs (A_0-A_{17}) changing from HIGH to LOW. This spike noise will become the largest, when all of the A_0-A_{17} address outputs change from HIGH to LOW simultaneously. (Refer to Fig. 68)

To avoid the spike noise on TOUT, a resistor and a capacitor should be connected to TOUT as shown in Fig. 69.

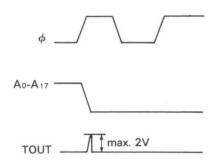


Figure 68 Spike Noise on TOUT

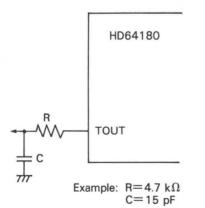


Figure 69 Resistor and Capacitor Connection

18.2 CKA₀/DREQ₀ Function in SLEEP Mode

When the CPU enters into SLEEP mode, the $CKA_0/DREQ_0$ pin always functions as the CKA_0 pin. Therefore, if the CPU enters into SLEEP mode during the time the pin is functioning as the $\overline{DREQ_0}$ input pin and the ASCI selects an internal clock source, the pin immediately reverts to being the CKA_0 output pin. At this time, a conflict between $\overline{DREQ_0}$ input and CKA_0 output may occur and a large surge of current may flow through the pin as a result. To prevent this, a current-limiting resistor should be connected to the pin as shown in Fig. 70.

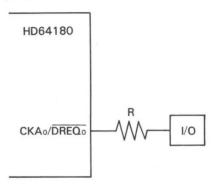


Figure 70 A Current Limit Resistor Connection

18.3 Precaution on Interfacing the Z80* Family Peripheral LSIs to the HD64180

(1) Problem

In daisy chain, the Z80* family peripheral LSI (PIO, DMA, CTC, SIO, or DART) resets interrupt circuit (i.e. IEO changes from LOW to HIGH) by fetching the RETI op-code on the data bus concurrently during the CPU fetches the RETI. Therefore, the followings should be noted for the RETI op-code (EDH, 4DH) fetch timing in the Z80* peripheral LSI.

When the peripheral LSI fetches the first op-code of RETI (EDH), \overline{LIR} should be negated HIGH at the rising edge of system clock ϕ as shown in Fig. 71, A. (This isn't referred in the manuals for the Z80* peripheral LSI.) So, \overline{LIR} hold time (\overline{LIR} = HIGH) should be required as shown in Fig. 71.

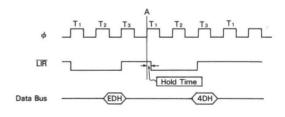


Figure 71 LIR Hold Time

Because LIR changes synchronously with the rising edge of system clock ϕ , \overline{LIR} delay time is equal to \overline{LIR} hold time of the Z80* peripheral LSI. However, this LIR hold time may not be sufficient for the Z80* peripheral LSI in some case and IEO line may not be reset.

(2) An example of countermeasure

Fig. 72 shows an example of circuit, while Fig. 73 shows the LIR and LIR' timing in the circuit.

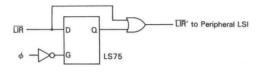


Figure 72 Circuit Example

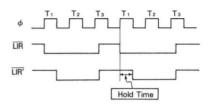


Figure 73 LIR and LIR' Timing in the Circuit

 \overline{LIR} ', which is synchronized with the falling edge of system clock ϕ , is provided to the peripheral LSI. In this case, one-half clock cycle duration is confirmed as the hold time.

Please carefully examine the circuit before you use it on your application.

18.4 Precautions on tAD and tAS

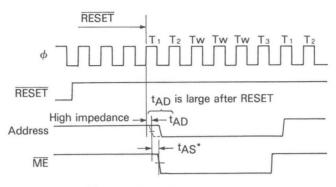
(1) Specification of t_{AD} and t_{AS}
The specification of t_{AD} (Address delay time) and t_{AS} (Address set-up time) is shown in Table 17.

Fig. 74 shows t_{AD} and t_{AS} timings just after RESET and just after recovery from BUS RELEASE mode.

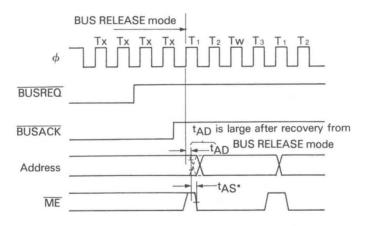
Table 17 Spec. of tab and tas

Symbol	ymbol Item		Spec.					
O y I I I DOI		item	HD64A180R0	HD64B180R0	Remarks			
^t AD	Address Delay Time Just after RESET, or after recovery from BUS RELEASE mode, or at the beginning of SLEEP mode and SYSTEM STOP mode Normal operation		130 (ns) max	125 (ns) max	Refer to 2.(1)			
		Normal operation	110 (ns) max	105 (ns) max				
^t AS Address Set-up Time	Just after RESET, or after recovery from BUS RELEASE mode	30 (ns) min	— 15(ns) min	Refer to - 2.(2) (a)				
		Normal operation	45 (ns) min	10 (ns) min	Refer to 2.(2) (b)			

^{*} Z80 is a registered trademark of Zilog, Inc.



(a) tAD and tAS timing just after RESET



(b) tan and tas timing just after recovery from BUS RELEASE mode

NOTE: Dotted lines show address delay in normal operation. * tas is - 15 ns (min) in case of 6 MHz operation.

Figure 74 t_{AD} and t_{AS} Timings

(2) Problems and countermeasures on t_{AD} and t_{AS}

Due to the above specification of tAD and tAS, the following problems may occur.

- t_{AD} Just after recovery from BUS RELEASE mode, tAD is larger than usual by 20 ns. Therefore, if Memory or I/O LSI access timing is designed based on the old tAD, an access time may not be enough just after recovery from BUS RELEASE mode.

So, one of the following two ways should be taken to design memory or I/O LSI access timing.

(a) All memory or I/O LSI access timing should be designed based on tAD just after recovery from BUS RELEASE

- (b) Wait state (Tw) should be inserted just after recovery from BUS RELEASE mode. (Refer to Example 3.)
- In case of 6 MHz operation, t_{AS} is -15 ns (min) just after RESET or just after recovery from BUS RELEASE mode. Therefore, if it is necessary to assure address set-up time of 0 ns or more than 0 ns (min) for a falling edge of ME or IOE, ME or IOE can't be directry used. Generally speaking, the problem may occur in the following cases.

(i) DRAM access using ME as RAS signal (ii) Pseudo SRAM access using ME as CE signal

DRAM or Pseudo SRAM requires 0 ns (min) of address set-up for a falling edge of RAS or CE. (Refer to Fig. 75 and Fig. 76.)

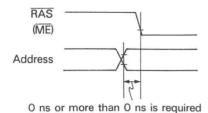


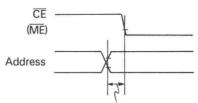
Figure 75 t_{AS} Timing for DRAM

Therefore, if DRAM or Pseudo SRAM is accessed just after RESET or after recovery from BUS RELEASE mode, $\overline{\text{ME}}$ should be delayed by half cycle of system clock ϕ . (Refer to Example 2.)

In the case of PROM, fully static RAM or a peripheral LSI which doesn't require set-up time, \overline{CS} signal may be unstable at the beginning of access when \overline{CS} is synchronized with \overline{ME} or \overline{IOE} . However, there is no problem by the following reason;

Read - If access time is assured enough, data is read

Write — As an address set-up time for a falling edge of WR is assured, unintentional writing into a memory or a peripheral LSI can not occur.



O ns or more than O ns is required

Figure 76 t_{AS} Timing for Pseudo SRAM

Please carefully examine the spec. of a memory or a peripheral LSI for your application.

(b) In case of 6 MHz operation, address set-up time of normal operation is 10 ns (min). If this address set-up time is not enough, ME should be delayed to assure address set-up time. (Refer to Example 2.)

Please check whether the problems mentioned above occur or not, referring to the flowchart in Fig. 77.

If you have some problem, please take some countermeasure as shown in Examples 1 to 3.

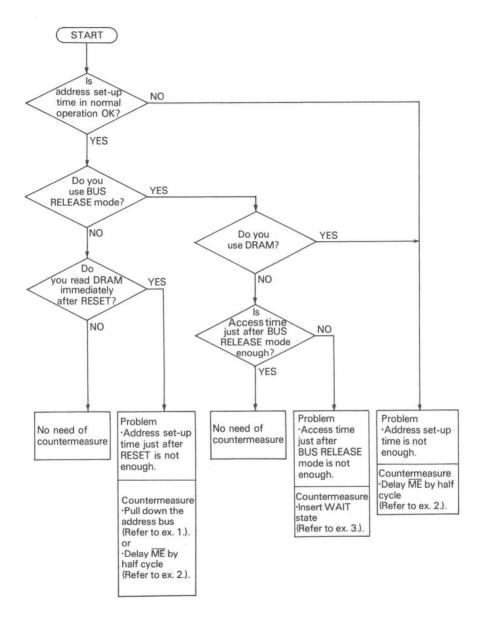


Figure 77 Check Flow

The followings show countermeasures to assure t_{AS} just after RESET or after recovery from BUS RELEASE mode.

Example 1: Countermeasure for tas just after RESET

As Restart address is 00000H, $t_{\rm AS}$ can be assured by pulling down all address lines to "0" during RESET. Fig. 78 shows the circuit for countermeasure.

Address lines become high impedance during RESET. However, if pull-down resistor R are connected as shown in Fig. 78, address lines go "0". In this case, length of RESET cycle T should be much longer than $C \cdot R$. (T $\gg C \cdot R$)

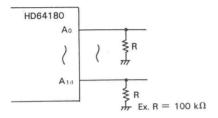
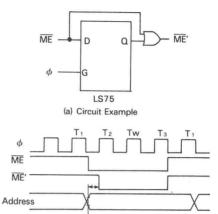


Figure 78 Countermeasure for t_{AS} Just After RESET

Example 2: Countermeasure for tas

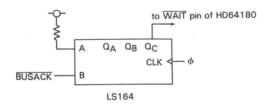
To assure t_{AS} , \overline{ME} should be delayed by half cycle of system clock ϕ by connecting external circuit as shown in Fig. 79 (a). \overline{ME} and \overline{ME} ' timing in the circuit is shown in Fig. 79 (b).



(b) $\overline{\text{ME}}$ and $\overline{\text{ME}}'$ Timing in the Circuit Figure 79 Countermeasure for t_{AS} by Delaying $\overline{\text{ME}}$

Example 3: Countermeasure for \mathbf{t}_{AD} just after recovering from BUS RELEASE mode

 $t_{\rm AD}$ just after recovery from BUS RELEASE mode can be assured by inserting wait state (Tw). To insert wait state (Tw), an external circuit should be connected as shown in Fig. 80 (a). Timing in the circuit is shown in Fig. 80 (b).



(a) Circuit Example

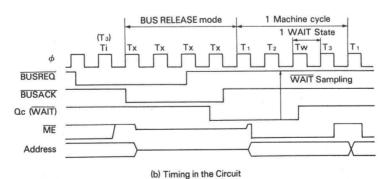


Figure 80 Countermeasure for t_{AD} Just After Recovery from BUS RELEASE Mode



18.5 Precaution on Interfacing HD64180 with Z80° CTC (1) Problem

The following problem may happen when interfacing HD64180 with Z80* CTC (Z8430). Therefore, countermeasure shown in section 2 should be taken. Fig. 81 illustrates Z80* CTC write timing specified in Z80* CTC Data Sheet. Fig. 82 and Fig. 83 show Z80* I/O write timing and HD64180 I/O write timing respectively.

As shown above, $\overline{\rm IOE}$ in HD64180 goes LOW by a half ϕ clock cycle faster than $\overline{\rm IORQ}$ in Z80. When interfacing Z80 with Z80* CTC, data is written into Z80* CTC at the rising edge of Tw. By contrast, when interfacing HD64180 with Z80* CTC, data is written into Z80* CTC at the rising edge of T_2 . In the latter case, data may not be written into Z80* CTC if $\overline{\rm IOE}$ set-up time for the rising edge of T_z is less than the set-up time specified in Z80* CTC.

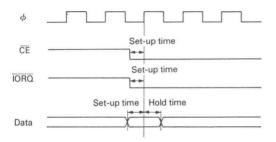


Figure 81 Z80* CTC Write Timing**

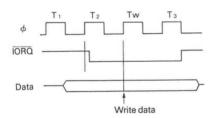


Figure 82 Z80° I/O Write Timing

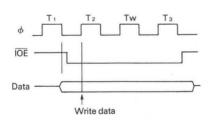
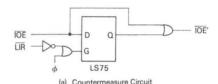


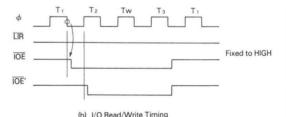
Figure 83 HD64180 I/O Write Timing

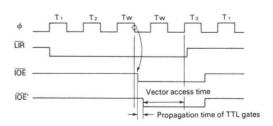
(2) Countermeasure

To Avoid the problem, $\overline{\rm IOE}$ in HD64180 should be asserted LOW at the rising edge of T_2 to assure the set-up time specified in Z80* CTC. Fig. 84 (a) shows a circuit for delaying $\overline{\rm IOE}$ by a half ϕ clock cycle.

If this circuit is externally connected between HD64180 and Z80* CTC, $\overline{\text{IOE}}$ will be pulled LOW at the rising edge of T_2 only in I/O read/write cycle as shown in Fig. 84 (b). While in $\overline{\text{INT}}_0$ acknowledge cycle, $\overline{\text{IOE}}$ and $\overline{\text{IOE}}$ are asserted LOW at the timing shown in Fig. 84 (c). In $\overline{\text{INT}}_0$ acknowledge cycle, $\overline{\text{IOE}}$ delays because of propagation time of TTL gates of the countermeasure circuit and the vector access time is shortened. If vector access time for HD64180 is not assured during $\overline{\text{INT}}_0$ acknowledge cycle, wait states should be inserted by programming IW10 and IW11 bits of DMA/WAIT Control Register. However, note that wait states insertion by software should be inhibited during Z80* CTC read/write cycles, because more than one wait state can not be allowed in the case of Z80* CTC. (Please see Z80* CTC Data Sheet. One wait state is automatically inserted during the cycles.) Refer to "Fig. 85 Z80* CTC Access Flow" for details.







(c) INTo Acknowledge Cycle Timing

Figure 84 Countermeasure Circuit and Timings in the Circuit

^{*} Z80 is a registered trademark of Zilog, Inc.

^{**} Copied from Z80* CTC Data Sheet (April, 1985)

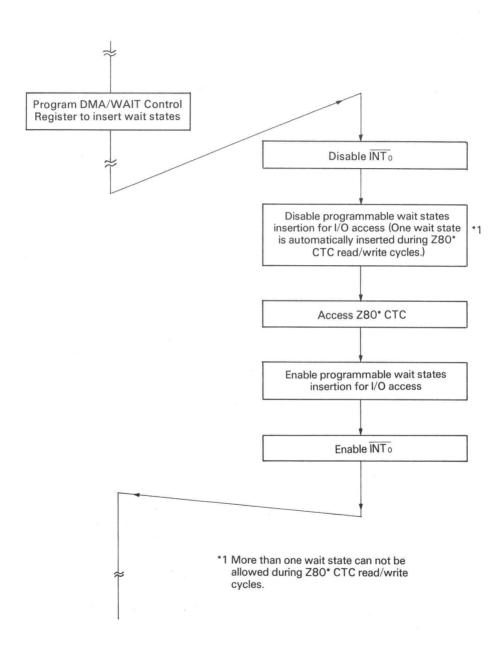


Figure 85 Z80° CTC Access Flow



18.6 Notes on HD64180 INT₀ Mode 0

(1) Problem

In INT₀ Mode 0, the CPU executes an instruction which is placed on the data bus during the interrupt acknowledge cycle. Usually, RST (1-byte instruction) or CALL (3-byte instruction) is placed on the data bus. Then, the CPU pushes the Program Counter (PC) onto the stack and jumps to the interrupt service routine. In the case of RST instruction, the correct return address is pushed onto the stack. However, in the case of CALL instruction, the pushed return address is equal to the correct return address + 2.

(2) Explanation of operation

During the 1st op-code fetch cycle in the interrupt acknowledge

eycle, the CPU stops incrementing the PC. At this time, the PC contains the return address. After the 1st op-code is fetched, the CPU restarts incrementing the PC. Therefore, is RST (1-byte instruction) is executed in the interrupt acknowledge cycle, the correct return address is pushed onto the stack and the CPU can return from the interrupt service routine correctly. While, if CALL (3-byte instruction) is executed in the interrupt acknowledge cycle, the PC is incremented twice during the operand read cycle of the 2 bytes after the 1st op-code is fetched. Therefore, the return address + 2 in the PC is pushed onto the stack. So, when RETI is executed at the end of the interrupt service routine, the CPU can not return from the interrupt correctly.

Fig. 86 shows the CALL execution timing in INT, Mode 0.

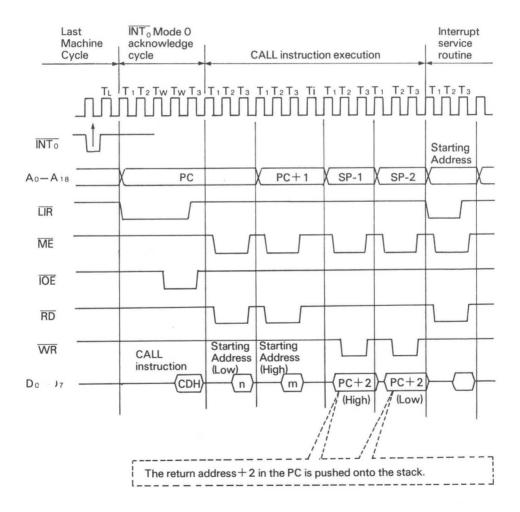


Figure 86 The CALL Execution Timing in INT Mode 0



(3) Countermeasure

The following explains the countermeasure of the problem in $\overline{INT_0}$ Mode 0.

(I) RST

When RST is executed, the correct return address in the PC is pushed onto the stack.

(2) CALL

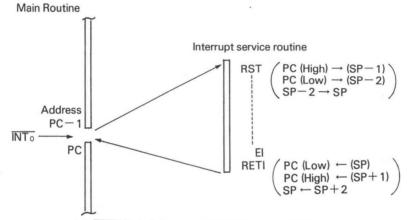
When CALL is executed, the stack contents must be decremented by two in the interrupt service routine to return from the interrupt correctly.

Table 18 summarizes how to adjust the stack contents depending on the instruction to be executed.

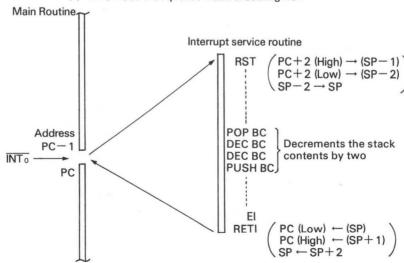
Table 18 Stack Contents Adjustment

Instruction	Stack Contents Adjustment
RST	No
CALL	Decrement the stack contents by two
Other instructions	No (The PC is not stacked.)

The $\overline{INT_0}$ Mode 0 sequences when executing RST and CALL are shown in Fig. 87.



(a) INT₀ Mode 0 Sequence when executing RST



(b) INTo Mode O Sequence when executing CALL

NOTE) PC: PC indicates the return address

Figure 87 INT Mode 0 Sequence



18.7 Note on reset operation when the CPU is in a WAIT state

(1) Problem

When the WAIT signal is asserted low and the CPU is in a WAIT state, the CPU can't be reset and can't restart even if the RESET signal is asserted low.

① Incorrect operation

In the case that RESET signal goes to low level and then goes back to high level while the WAIT signal is asserted low, the CPU can't restart. (Please see Fig. 88)

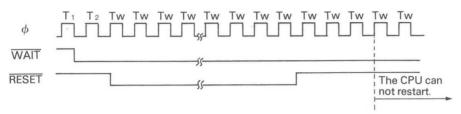


Figure 88 Incorrect Operation

- Correct operation
 In the following cases, the CPU can restart correctly.
- (a) In the case that the \overline{RESET} signal goes to low level by 5 clocks earlier than the \overline{WAIT} goes to low level.

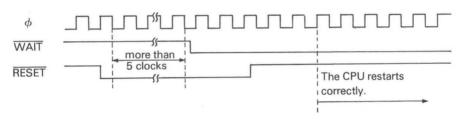


Figure 89 Correct Operation

(b) In the case that the WAIT signal goes to high level by 3 clocks earlier than the RESET signal goes to high.

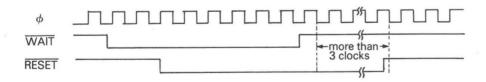


Figure 90 Correct Operation

(c) In the case that the RESET goes to low while the CPU is in a WAIT state caused by the internal programmable

WAIT state generator and while the \overline{WAIT} signal is kept in high level.

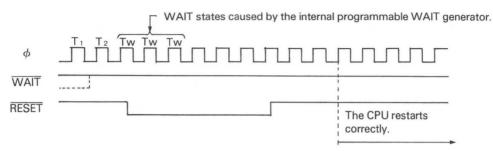
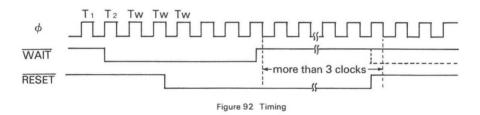


Figure 91 Correct Operation

(2) Countermeasure

Please force the WAIT signal to change to high level by 3 clocks

before the \overline{RESET} signal goes to high level. Please see Fig. 92 and Fig. 93.



(1) An example of countermeasure circuits

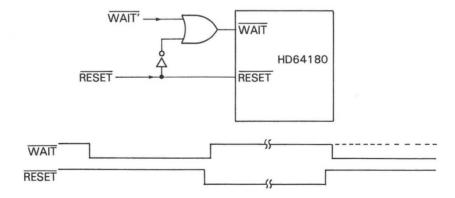


Figure 93 An Example of Circuits and the Timing

18.8 Note on conflict of NMI and TRAP interrupts

(1) Problem

If the CPU reads an undefined op-code normally, the TRAP interrupt occurs.

If the CPU receives a NMI request during fetching an undefined op-code, the CPU jumps to 0066H, that is NMI's jump address, not to the normal TRAP address (0000H). Therefore, in this case, TRAP interrupt routine is not executed.

(2) Explanation

Fig. 94 shows an operation timing when the CPU receives a $\overline{\text{NMI}}$ interrupt during fetching an undefined op-code. In this example, the second op-code is assumed to be undefined one. When a falling transition of $\overline{\text{NMI}}$ signal happens during the period of Ta which is described in Fig. 94, the TRAP interrupt occurs internally and the CPU starts TRAP interrupt acknowledge cycles. In the

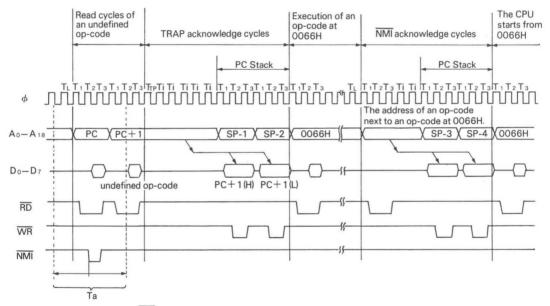
acknowledge cycles, the CPU stacks the address of an undefined op-code, and then the CPU jumps to logical address 0066H, not to logical address 0000H. As the request of $\overline{\text{NMI}}$ interrupt is still suspended at the time, the CPU starts the $\overline{\text{NMI}}$ acknowledge cycles after executing an op-code at logical address 0066H.

In the NMI acknowledge cycles, the CPU jumps to logical address 0066H again after stacking the address of an op-code next to the op-code at logical address 0066H. Then, the CPU executes nor-

mally.

Fig. 95 shows an operation timing in the case that the third opcode is undefined. The CPU also acts similarly.

As mentioned above, if NMI interrupt is requested while the CPU reads an undefined op-code, the CPU can not start from logical address 0000H because the start address changes to logical address 0066H.



If the CPU receives a NMI request during Ta, the CPU jumps to 0066H.

Figure 94 Operation Timing in the Case that the Second Op-code is Undefined

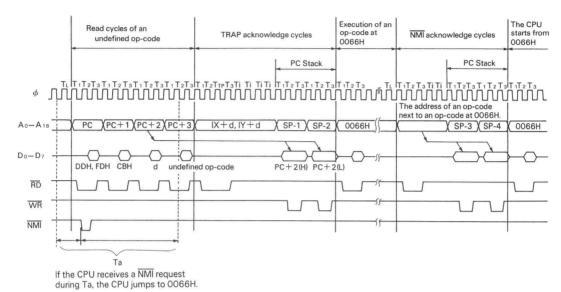


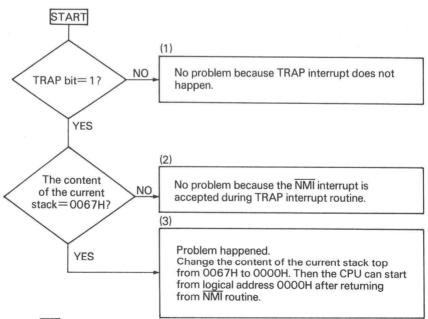
Figure 95 Operation Timing in the Case that the Third Op-code is Undefined

(3) Countermeasure

Please take countermeasure by software.

① Change an op-code at logical address 0066H to NOP.

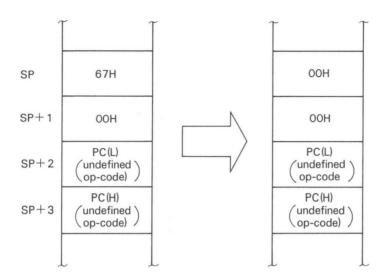
 $\ensuremath{ \ \, 2 \ \, 2 }$ Execute the following at the beginning of \overline{NMI} interrupt routine.



NOTE: In case that the next NMI requests can occur during the NMI interrupt routine, it is necessary to forbid the request until the CPU execute an op-code at logical address 0067H.



After completion of the flow (3), the content of the current stack top changes as follows:



NOTE: The PC (undefined op-code) means an address which is stacked during TRAP acknowledge cycles.

19 INSTRUCTION SET

19.1 Instruction set overview

The HD64180 is object code compatible with standard 8-bit operating system and application software. The instruction set also contains a number of new instructions to improve system and software performance, reliability and efficiency.

New Instructions	Operation
SLP	Enter SLEEP mode
MLT	8-bit multiply with 16-bit result
IN0 g, (m)	Input contents of immediate I/O address into register
OUTO (m), g	Output register contents to immediate I/O address
OTIM	Block output - increment
OTIMR	Block output - increment and repeat
OTDM	Block output - decrement
OTDMR	Block output - decrement and repeat
TSTIO m	Non-destructive AND, I/O port and accumula-
	tor
TST g	Non-destructive AND, register and accumula-
	tor
TST m	Non-destructive AND, immediate data and ac- cumulator
TST (HL)	Non-destructive AND, memory data and ac-

(1) SLP - Sleep

The SLP instruction causes the HD64180 to enter SLEEP low power consumption mode. See section 5 for a complete description of the SLEEP state.

(2) MLT - Multiply

The MLT performs unsigned multiplication on two 8 bit numbers yielding a 16 bit result. MLT may specify BC, DE, HL or SP

registers. In all cases, the 8-bit operands are loaded into each half of the 16-bit register and the 16-bit result is returned in that register.

(3) INO g, (m) - Input, Immediate I/O address

The contents of immediately specified 8-bit I/O address are input into the specified register. When I/O is accessed, 00H is output in high-order bits of address automatically.

(4) OUTO (m), g - Output, immediate I/O address

The contents of the specified register are output to the immediately specified 8-bit I/O address. When I/O is accessed, 00H is output in high-order bits of address automatically.

(5) OTIM, OTIMR, OTDM, OTDMR - Block I/O

The contents of memory pointed to by HL is output to the I/O address in (C). The memory address (HL) and I/O address (C) are incremented in OTIM and OTIMR and decremented in OTDM and OTDMR respectively. B register is decremented. The OTIMR and OTDMR variants repeat the above sequence until register B is decremented to 0. Since the I/O address (C) is automatically incremented or decremented, these instructions are useful for block I/O (such as HD64180 on-chip I/O) initialization. When I/O is accessed, 00H is output in high-order bits of address automatically.

(6) TSTIO m - Test I/O Port

The contents of the I/O port addressed by C are ANDed with 8-bit immediate data and the status flags are updated. The I/O port contents are not written (non-destructive AND). When I/O is accessed, 00H is output in higher bits of address automatically.

(7) TST g - Test Register

The contents of the specified register are ANDed with the accumulator (A) and the status flags are updated. The accumulator and specified register are not changed (non-destructive AND).

(8) TST m - Test Immediate

The 8-bit immediate data is ANDed with the accumulator (A) and the status flags are updated. The accumulator is not changed (non-destructive AND).

(9) TST (HL) - Test Memory

The contents of memory pointed to by HL are ANDed with the accumulator (A) and the status flags are updated. The memory contents and accumulator are not changed (non-destructive AND).

19.2 Instruction set summary

The followings explain the symbols in instruction set, and the following tables summarize the operation of each instruction.

(1) Register

g, g', ww, xx, yy, and zz specify a register to be used. g and g' specify an 8-bit register. ww, xx, yy, and zz specify a pair of 16-bit registers. The following tables show the correspondence between symbols and registers.

g,g'	Reg.	ww	Reg.	XX	Reg.	уу	Reg.	ZZ	Reg.
000	В	00	BC	00	BC	00	BC	00	BC
001	С	01	DE	01	DE	01	DE	01	DE
010	D	10	HL	10	IX	10	IY	10	HL
011	Е	11	SP	11	SP	11	SP	11	AF
100	Н		-						
101	L								
111	A								

NOTE: Suffixed H and L to ww,xx,yy,zz (ex.wwH,IXL) indicate upper and lower 8-bit of the 16-bit register respectively.

(2) Bit

b specifies a bit to be manipulated in the bit manipulation instruction. The following table shows the correspondence between b and bits.

b	Bit
000	0
001	1
010	2
011	3
100	4
101	5
110	6
111	7

(3) Condition

f specifies the condition in program control instructions. The following shows the correspondence between f and conditions.

f	Condition
000	NZ non zero
001	Z zero
010	NC non carry
011	С саггу
100	PO parity odd
101	PE parity even
110	P sign plus
111	M sign minus

(4) Restart Address

v specifies a restart address. The following table shows the correspondence between v and restart addresses.

v	Address
000	00H
001	08H
010	10H
011	18H
100	20H
101	28H
110	30H
111	38H

(5) Flag

The following symbols show the flag conditions.

on the symbols of the symbols of the symbols of the symbols of the symbols of the symbol of the symb

V: overflow

)_M

(6) Miscellaneous

 $)_{I}$ data in the I/O address m or n 8-bit data mn 16-bit data 8-bit register R 16-bit register b.(a content of bit b in the memory address a content of bit b in the register gr b-gr d or j 8-bit signed displacement source addressing mode 5 destination addressing mode D AND operation

data in the memory address

Data Manipulation Instructions

Arithmetic and Logical Instructions (8-bit)

						ddressin							L		FI	ag	
Operation name	MNEMONICS	OP-code	IMMED	EXT	IND	REG	REGI	IMP	REL	Bytes	States	Operation	7 S	6 Z	_	2 P/V	
	100.1	10 000 g	IMMED	EAT	IND	S	NEGI	D	HLL	1	4	Ar+gr→Ar	1	1	1	v	R
ADD	ADD A, (HL)	10 000 g				3	s	D		1	6	Ar+ (HL) _M -Ar	1	1	1	V	R
	ADD A, (BL)	11 000 110	s					D		2	6	Ar+ m→Ar	1	1	1	V	R
	ADD A,III	< m >	"					-					1	•			
	ADD A, (IX+d)	11 011 101			s			D		3	14	Ar+ (IX+d) _M →Ar	1	1	1	V	R
	ADD A, IA I G	10 000 110											1				
1		< d >															
	ADD A, (IY+d)	11 111 101			S			D		3	14	Ar+ (IY+d) _M →Ar	1	1	1	V	R
	ADD A, 11 - U	10 000 110			-								1				
		< d >															
			+	-	-	S		D		1	4	Ar+gr+c→Ar	1	1	1	٧	R
ADC	ADC A,g	10 001 g				3	s	D		1	6	Ar+ (HL) _M + c→Ar	1	1	1	v	R
	ADC A, (HL)	11 001 110	s				3	D		2	6	Ar+m+c→Ar	1	1			R
	ADC A,m	< m >	1 5							1	۰	ATTITIC A	1,				
	ADC A, (IX+d)	11 011 101			s			D		3	14	Ar+ ((X+d) _M +c→Ar	1	1	1	V	R
	ADC A, (IA T d)	10 001 110											1.	•			
		< d >															
	ADC A, (IY+d)	11 111 101			s			D		3	14	Ar+ (IY+d) _M +c→Ar	1	1	1	V	R
		10 001 110															
		< d >	1														
AND	AND g	10 100 g	+-	_	_	S		D		1	4	Ar · gr—Ar	1	1	S	Р	R
	AND (HL)	10 100 110					s	D		1	6	Ar · (HL) _M →Ar	1	1	S	P	R
	AND m	11 100 110	s	1				D		2	6	Ar · m-Ar	1	1	S	P	R
		< m >															
	AND (IX+d)	11 011 101	-		S			D		3	14	Ar · (IX+d) _M →Ar	1	1	S	P	R
		10 100 110	1														
		< d >			1												
)		1	1		1				1.				
	AND (IY+d)	11 111 101			S			D		3	14	Ar · (IY+d) _M →Ar	1	1	S	Р	R
		10 100 110		1													
		< d >	+	-	-	-	-	-		-		-	+		_	_	
Compare	CP g	10 111 g	1			S		D		1	4	Ar-gr	1	1		٧	S
	CP (HL)	10 111 110					S	D		1	6	Ar- (HL) _M	1	1	1	٧	S
	CP m	11 111 110	S					D		2	6	Ar-m	1	1	1	٧	5
	00 001 1	< m >			s			D		3	14	Ar- (1X+d) _M	١,	1	,	V	S
	CP (IX+d)	10 111 110			3			0		3	14	A UX TOM	1,				0
		< d >															
	CP ((Y+d)	11 111 101			s			D		3	14	Ar- (IY+d) _M	١,	1	1	V	S
	CF (IT T U)	10 111 110			"			-		"			1.	•	٠		
		< d >															
COMPLEMENT	CPL	00 101 111	+	_	1		_	S/D		1	3	Ār—Ar	1.		S		s
DEC	DEC g	00 g 101	+	-	+	S/D	-	-	-	1	4	gr− 1→gr	1	1	1	V	s
DEC	DEC (HL)	00 110 101				0.0	S/D			1	10	(HL) _M − 1 → (HL) _M	1	1	1		s
	DEC (IX+d)	11 011 101			S/D					3	18	(IX+d) _M -1→	1	1	1	V	S
		00 110 101			1							(IX+d) _M					
	I .	< d >			1												
				1	S/D					3	18	(IY+d) _M -1→	1	1	1	٧	S
	DEC (IY+d)	11 111 101			5/0	1											
	DEC (IY+d)	00 110 101			5/0							(IY+d) _M			•		
	DEC (IY+d)	A CONTRACT OF THE PARTY OF THE			5/0							(IY+d) _M					
INC	DEC (IY+d)	00 110 101	_		5/0	S/D				1	4	((Y + d) _M gr + 1 → gr	1	1	1	v	R
INC		00 110 101 < d >			5/0	S/D	S/D			1 1	4		1 1	1 1	1	v v	R R
INC	INC g	00 110 101 < d >			S/D	S/D	S/D					gr+1→gr	1.	1	1		R

(to be continued)



						ddressir	va						L		FI	вg	
Operation	MNEMONICS	OP-code			,	adressir	19	,		Bytes	States	Operation	7		4		_
			IMMED	EXT	IND	REG	REGI	IMP	REL				S	Z	Н	P/V	N
NC		< d >															
	INC (IY+d)	11 111 101			S/D					3	18	(IY + d) _M + 1 →	1	1	1	٧	R
		00 110 100										(IY + d) _M					
		< d >	1														
MULT	MLT ww	11 101 101				S/D				2	17	wwHr× wwLr→ww _R	1.				
MOLI	INC. WW	01 ww1 100				0.0					.,						
NEGATE	NEG	11 101 101	-	-	-	-		S/D		2	6	0− Ar→Ar	+,	,	1	v	S
NEGATE	NEG	01 000 100						0,0			٠		Ι.	•	٠	•	
OR	OR g	10 110 g				S		D		1	4	Ar+gr→Ar	1	1	R	Р	R
	OR (HL)	10 110 110					S	D		1	6	Ar + (HL) _M -Ar	1	1	R	Р	R
	OR m	11 110 110	s					D		2	6	Ar+m→Ar	1	1	R	Р	R
		< m >											1				
	00 84 1 4	11 011 101			s			D		3	14	$Ar + (IX + d)_{M} \rightarrow Ar$	1	1	R	P	R
	OR (IX+d)				9			"		3	14						
		10 110 110															
		< d >										Ar + (IY + d) _M →Ar	1	1	R	Р	R
	OR ((Y+d)	11 111 101			S			D		3	14	ALL DIVINOR	1.	•			
		10 110 110															
		< d >											\perp				
SUB	SUB g	10 010 g				S		D		1	4	Ar-gr→Ar	1	1	1	٧	
	SUB (HL)	10 010 110					S	D		1	6	Ar- (HL) _M →Ar	1	1	1	٧	S
	SUB m	11 010 110	S					D		2	6	Ar- m→Ar	1	1	1	٧	S
		< m >															
	SUB (IX+d)	11 011 101	1		S			D		3	14	Ar- (IX ± d) _M →Ar	1	1	1	٧	S
		10 010 110															
		< d >															
	SUB (IY+d)	11 111 101			S			D		3	14	Ar- (IY+d) _M →Ar	1	1	1	٧	S
		10 010 110	1														
		< d >															
SUBC	SBC A.g	10 011 g				S		D		1	4	Ar-gr-c→Ar	1	1	1	v	S
	SBC A, (HL)	10 011 110					s	D		1	6	Ar- (HL) _M -c→Ar	li	1		V	
	SBC A,m	11 011 110	s				-	D		2	6	Ar-m-c→Ar	l'i			v	
	ODC A,III	< m >	"							1		A III C A	1,		1	٠	3
	SBC A, (IX+d)	11 011 101			s			D		3	14	Ar ← (IX + d) _M − c → Ar	1.	1	1	V	0
	55C A, (1A 1 G)	10 011 110			"					"	1.5	A WATER	1,	٠	+	٠	J
		< d >						1									
	SBC A, (IY+d)	11 111 101		1	s			D		3	14	Ar- (IY+d) _M -c→Ar	1,	,	1	v	S
	000 74 87 1 07	10 011 110			"		1	-		"	1.5	A UT OM C A	Ι.		٠	•	0
		< d >															
TEST	TST g	11 101 101	+-	-	-	s	1	+	1	2	7	Ar · gr	+,	1	S	Р	P
1201	10.0	00 g 100				"				-		Ci Gi	1,		3	-	- 13
	TST (HL)	11 101 101			1	1 1	s			2	10	Ar · (HL) _M	1.		s	D	D
	101 012	00 110 100					"					AI THUM	1,	1	3	E	n
	TST m	11 101 101	s							3	9		1.				
	131 111	01 100 100	1 3							1 3		Ar · m	1,	1	S	P	н
	1							1									
		< m >	-	-	_	-	-	-	-	_			\perp				
XOR	XOR g	10 101 g				S		D		1	4	Ar⊕ gr⊶Ar	1	1	R	P	R
	XOR (HL)	10 101 110	1				S	D		1	6	Ar⊕ (HL) _M →Ar	1	1		P	R
	XOR m	11 101 110	S					D		2	6	Ar⊕ m→Ar	1	1	R	P	R
		< m >			1		1		1								
	XOR (IX+d)	11 011 101			s			D		3	14	Ar ⊕ (IX+d) _M —Ar	1	1	R	P	R
		10 101 110		1	1		1		1				1				
	1	< d >	1	1	1		1	1	1	1			1				
	XOR (IY+d)	11 111 101		1	S			D	1	3	14	Ar ⊕ (IY + d) _M →Ar	1	1	R	P	R
	1	10 101 110		1		1	1	1					1				
	1	< d >	1	1	1	1	1	1	1	1	I	1	1				

(to be continued)



Rotate and Shift Instructions

Operation name	MNEMONICS	OP-code	Addressing										7 6 4 2 1				
			IMMED	EXT	IND	REG	REGI	IMP	REL	Bytes	States	Operation	7 S	6 Z		2 P/V	1 N
Rotate	RLA	00 010 111	IIVIIVIED	EAT	140	ned	nedi	S/D	TILL	1	3			-	R		R
and	RL g	11 001 011				S/D		0.0		2	7	-0-(11111111111111111111111111111111111	1	1	R		R
Shift	Inc 9	00 010 g				O/D				-			١.	•			
Data	RL (HL)	11 001 011					S/D			2	13		,	1	R	Р	R
Vala	AL (AL)	00 010 110					3/0			1	13		١,			,	
	RL (IX+d)	11 011 101	1 1		S/D					4	19		1	1	B	Р	R
	HE (IX T U)	11 001 011			SIL					1	1,		١.	•			
			1 1														
		00 010 110			0.0					4	19		١.		D	р	D
	RL (IY+d)	11 111 101			S/D					4	19		1	1	n		п
		11 001 011															
		< d >															
		00 010 110															
	RLCA	00 000 111						S/D		1	3	فشسش			R		
	RLC g	11 001 011				S/D				2	7	C b7	1	1	R	P	R
		00 000 g															
	RLC (HL)	11 001 011					S/D			2	13		1	1	R	P	R
		00 000 110								1							
	RLC (IX+d)	11 011 101			S/D					4	19		1	1	R	P	R
		11 001 011															
	1	< d >															
		00 000 110															
	RLC (IY+d)	11 111 101			S/D					4	19		1	1	R	P	R
		11 001 011	1										1				
		< d >															
		00 000 110										Ar CTITITI					
								S/D		2	16	B/ B0	١.		р	D	0
	RLD	11 101 101						3/0		1	10	67 (HL) _M	١,	1	n		
	(01 101 111			ĺ	ĺ			1	[]							
	RRA	00 011 111	1 1					S/D		1	3				R		R
	RR g	11 001 011	1 1			S/D				2	7	dining for	1	1		P	
		00 011 g	1 1														
	RR (HL)	11 001 011					S/D			2	13		1	1	R	P	R
		00 011 110												(*).			
	RR (DX+d)	11 011 101			S/D					4	19		1	1	R	P	R
		11 001 011	1 1														
		< d >															
		00 011 110	1 1														
	RR (IY+d)	11 111 101			S/D					4	19		١,	,	0	В	D
	nn ur ru	11 001 011			3/0					1	1.5		1	1	n	E	n
	1																R RRRR RRRR
										1							
		00 011 110															
	RRCA	00 001 111						S/D		1	3	0-(1111111)-0	•		R		R
	RRC g	11 001 011				S/D				2	7	b7 — b0 C	1	1	R	P	R
		00 001 g															
	RRC (HL)	11 001 011					S/D			2	13		1	1	R	P	R
		00 001 110							- 27								
	RRC (IX+d)	11 011 101			S/D					4	19		1	1	R	P	R
		11 001 011															
		< d >															
		00 001 110															
	RRC (IY+d)	11 111 101			S/D					4	19		1	1	R	P	R
		11 001 011															
		< d >															
		00 001 110															
	1	1	1						1	1		I	1				

(to be continued)



Operation						ddressir	ng						L		F	ag		_
name	MNEMONICS	OP-code								Bytes	States	Operation	7	6	4	2	1	
			IMMED	EXT	IND	REG	REGI	IMP	REL				S	Z	Н	PΛ	N	
Rotate	RRD	11 101 101						S/D		2	16	Ar S	1	1	R	Р	R	
and		01 100 111										(HU _M						
Shift	SLA g	11 001 011				S/D				2	7	b) b0	1	1	R	P	R	
Data		00 100 g										р-ШППП • «						
	SLA (HL)	11 001 011					S/D			2	13		1	1	R	P	R	
		00 100 110																
	SLA (IX+d)	11 011 101			S/D					4	19		1	1	R	P	R	
		11 001 011																
		< d >																
		00 100 110																
	SLA (IY+d)	11 111 101			S/D					4	19		1	1	R	P	R	
		11 001 011																
		< d >																
		00 100 110																
	SRA g	11 001 011				S/D				2	7	-Çinimirî-o	1	1	R	P	R	
		00 101 g										b7 10 C						
	SRA (HL)	11 001 011					S/D			2	13		1	1	R	P	R	
		00 101 110																
	SRA (IX+d)	11 011 101			S/D					4	19		1	1	R	P	R	
		11 001 011																
		< d >																
		00 101 110																
	SRA (IY+d)	11 111 101			S/D					4	19		1	1	R	P	R	
		11 001 011																
		< d >																
		00 101 110																
	SRL g	11 001 011				S/D				2	7	0 -{,,,,,,,,,,,, ,-	1	1	R	P	R	
	ĺ	00 111 g								1		•						
	SRL (HL)	11 001 011					S/D			2	13		1	1	R	Р	R	
		00 111 110																
	SRL (IX+d)	11 011 101			S/D					4	19		1	t	R	P	R	
		11 001 011											•	•				
		< d >																
		00 111 110									12							
	SRL (IY+d)	11 111 101			S/D					4	19		1	1	R	Р	R	
		11 001 011											•	•				
		< d >																
	1	00 111 110																

Bit Manipulation Instructions

					4	ddressir	na .								_	ag	_	
Operation	MNEMONICS	OP-code								Bytes	States	Operation	7	6	4	2	1	0
name			IMMED	EXT	IND	REG	REGI	iMP	REL				s	Z	Н	P/V	N	C
Bit Set	SET b,g	11 001 011			`	S/D				2	7	1→b · gr			٠		٠	٠
		11 b g																
	SET b, (HL)	11 001 011					S/D			2	13	1→b·(HL) _M			٠			
		11 b 110																
	SET b, (IX+d)	11 011 101			S/D					4	19	1 → b · (IX + d) _M		•	•			٠
		11 001 011																
		< d >																
		11 b 110																
	SET b, (IY+d)	11 111 101			S/D					4	19	1→b · ((Y+d) _M				•		
		11 001 011			1													
		< d >											1					
		11 b 110																
Bit Reset	RES b.g	11 001 011				S/D				2	7	0→b · gr						٠
		10 b g																
	RES b, (HL)	11 001 011	1				S/D			2	13	0→b · (HL) _M						
		10 ь 110																
	RES b, (IX+d)	11 011 101			S/D					4	19	0-b · (IX+d) _M						
		11 001 011																
		< d >																
		10 ь 110	1															
	RES b, (IY+d)	11 111 101			S/D					4	19	0→b · ((Y+d) _M						*
		11 001 011																
		< d >																
		10 b 110																
Bit Test	BIT b,g	11 001 011				s				2	6	. b · gr→z	x	1	s	X	R	
		01 b g																
	BIT b, (HL)	11 001 011					S			2	9	b · (HL) _M →z	×	1	S	×	R	
		01 ь 110			1													
	BIT b, (IX+d)	11 011 101			S					4	15	b · (1X + d) _M →z	×	1	S	X	R	*
		11 001 011																
		< d >																
		01 ь 110										1						
	BIT b, (IY+d)	11 111 101			S					4	15	b · (IY+d) _M →z	X	1	S	X	R	
		11 001 011																
		< d >																
		01 b 110																
		1																

Arithmetic Instructions (16-bit)

						Addressir									FI	ag		
Operation	MNEMONICS	OP-code			,	Addressii	NG.			Bytes	States	Operation	7	6	4	2	1	0
name			IMMED	EXT	IND	REG	REGI	IMP	REL				s	z	н	P/V	N	С
ADD	ADD HL,ww	00 ww1 001				S		D		1	7	HL _R + ww _R →HL _R			X		R	1
	ADD IX,xx	11 011 101 00 xx1 001				S		D		2	10	IX _R + xx _R →IX _R		٠	X		R	1
	ADD IY,yy	11 111 101 00 yy1 001				S		D		2	10	IY _R + _{YYR} →IY _R			×		R	I
ADC	ADC HL,ww	11 101 101 01 ww1 010				S		D		2	10	HLR+wwR+c→HLR	1	1	×	٧	R	1
DEC	DEC ww	00 ww1 011				S/D				1	4	ww _R −1→ww _R						
	DEC IX	11 011 101 00 101 011						S/D		2	7	IX _R −1→IX _R		٠		٠	٠	٠
	DEC IY	11 111 101 00 101 011						S/D		2	7	IY _R −1→IY _R			•	•	,	
INC	INC ww	00 ww0 011				S/D				1	4	ww _R +1→ww _R						
	INC IX	11 011 101						S/D		2	7	IX _R +1→IX _R						,
	INC IY	11 111 101 00 100 011						S/D		2	7	IY _R +1→IY _R		٠		٠		
SBC	SBC HL,ww	11 101 101 01 ww0 010				S		D		2	10	HL _R -ww _R -c→HL _R	1	1	×	٧	S	1

Data Transfer Instructions

8-Bit Load

													L		1	Flag	_	_
Operation	MNEMONICS	OP-code			A	ddressin	g			Bytes	States	Operation	7	6	4	2	1	-
name			IMMED	EXT	IND	REG	REGI	IMP	REL				S	z	Н	PΛ	N	
.oad	LD A,I	11 101 101						S/D		2	6	lr─Ar	1	1	R	IEF:	R	
3-bit		01 010 111																
Data	LD A,R	11 101 101						S/D		2	6	Rr→Ar	1	1	R	IEF	R	
		01 011 111																
	LD A, (BC)	00 001 010					S	D		1	6	(BC) _M →Ar						
	LD A, (DE)	00 011 010					S	D		1	6	(DE) _M →Ar						
	LD A, (mn)	00 111 010		S				D		3	12	(mn) _M →Ar				٠		
		< n >																
		< m >																
	LD LA	11 101 101						S/D		2	6	Ar→lr	1.					
		01 000 111																
	LD RA	11 101 101						S/D		2	6	Ar→Rr						
		01 001 111											1					
	LD (BC),A	00 000 010					D	S		1	7	Ar→(BC) _M						
	LD (DE),A	00 010 010					D	S		1	7	Ar→ (DE) _M						
	LD (mn),A	00 110 010		D				S		3	13	Ar—(mn) _M			•			
		< n >																
		< m >								1								
	LD g.g'	01 g g'				S/D				1	4	gr'→gr					*	
	LD g. (HL)	01 g 110				D	S	1		1	6	(HL) _M →gr						
	LD g,m	00 g 110	S			D				2	6	m→gr				,		
		< m >																
	LD g, (IX+d)	11 011 101			S	D				3	14	(IX+d) _M →gr						
		01 g 110																
		< d >																
	LD g, ((Y+d)	11 111 101		1	S	D				3	14	(IY+d) _M →gr						
		01 g 110	1	1			1		1	1								
	1	< d >	1	1		1				1								
	LD (HL),m	00 110 110	S				D			2	9	m→(HL) _M						
		< m >	1															
	LD (IX+d),m	11 011 101	S		D					4	15	m→(IX+d) _M						
		00 110 110	1															
		< d >																
		< m >	1	1														
	LD (IY+d),m	11 111 101	S		D					4	15	m→(IY+d) _M						
		00 110 110							-	1								
		< d >																
		< m >		1								1						
	LD (HL),g	01 110 g				s	D			1	7	gr→(HL) _M						
	LD (IX+d),g	11 011 101			D	s	-			3	15	gr→(IX+d) _M						
		01 110 g																
		< d >																
	LD (IY+d).g	11 111 101	1		D	s				3	15	gr→(IY+d) _M						
		01 110 g		1	1	1												
		< d >	1	1	1	1	1			1								



16-Bit Load

						ddressin									FI	ag		_
Operation name	MNEMONICS	OP-code					1			Bytes	States	Operation	7	_	_	2	_	-
			IMMED	EXT	IND	REG	REGI	IMP	REL				+	_	_	P/V		-
oad	LD ww, mn	00 ww0 001	S			D				3	9	mn→ww _R		*		•		
6-bit		< n >																
ata		< m >						D		4	12	n/						
	LD IX, mn	11 011 101	S					U		4	12	mn→IX _R	1		•	8		
		00 100 001																
		< n >																
	10.00	< m >	s					D		4	12	mn→IY _R						
	LD IY, mn	00 100 001	3				100	"		-	12	THE STEE	1					
		200																
		100 000											1					
		< m >						0.0										
	LD SP, HL	11 111 001						S/D		1	4	HL _R →SP _R	1					
	LD SP, IX	11 011 101						S/D		2	7	IX _R →SP _R						
		11 111 001																
	LD SP, IY	11 111 101						S/D		2	7	IY _R →SP _R						
		11 111 001									1500	10 To 10						
	LD ww, (mn)	11 101 101		S		D				4	18	(mn+1) _M →wwHr	1.					
		01 ww1 011										(mn) _M →wwLr						
		< n >											1					
		< m >							-									
	LD HL, (mn)	00 101 010		S				D		3	15	(mn+1) _M →Hr	1		•		•	
		< n >		1								(mn) _M →Lr	1					
		< m >				1						1						
	LD IX, (mn)	11 011 101		S				D		4	18	(mn+1) _M →IXHr						
		00 101 010										(mn) _M →IXLr						
		< n >																
	İ	< m >								1 1								
	1.504	1	}	1	}	1	1	D		4			1					
	LD IY, (mn)	11 111 101		S			1	0		4	18	(mn+1) _M →IYHr					٠	
		00 101 010 < n >										(mn) _M →IYLr	1					
					1 1													
	15/>	N 97970		D	1	s				4	19							
	LD (mn),ww	11 101 101 01 ww0 011		0		3			1	4	19	wwHr→(mn+1) _M						
		< n >	1		1		1					wwLr→(mn) _M						
		< m >			1													
	LD (mn),HL	00 100 010		D				s		3	16	11-1-1-1						
	LD WWW,AL	< n >		"		1		3		,	10	Hr→(mn+1) _M	1		÷	•		
							1					Lr→(mn) _M						
	LD (mn), IX						1	s										
	LD (mn), IX	11 011 101		D		1		5		4	19	IXHr→(mn+1) _M					٠	
		00 100 010										IXLr→(mn) _M						
		< n >																
		< m >																
	LD (mn), IY	11 111 101		D	1	1	1	S		4	19	IYHr→(mn+1) _M						
		00 100 010	1									IYLr→ (mn) _M						
	1	< n >	1				1	1	1			1						

Block Transfer

													L		F	lag		
Operation	MNEMONICS	OP-code			Α	ddressin	g			Bytes	States	Operation	7	6	4	2	1	0
name			IMMED	EXT	IND	REG	REGI	IMP	REL				S	Z	Н	P/V	N	С
Block														2		1	1	
Transfer	CPD	11 101 101					S	S		2	12	Ar- (HL) _M	1	1	1	1	S	
Search		10 101 001										BC _R -1→BC _R				_		
Data												HLR-1-HLR	1.	2		1		
	CPDR	11 101 101					S	S		2	14	BC _R ≠0 Ar≠(HL) _M	1	1	1	1	S	
		10 111 001								1 1	12	BC _R =0 or Ar=(HL) _M						
						8						「Ar− (HL) _M						
												Q BC _R -1→BC _R						
												L HLR-1-HLR						
												Repeat Q until						
												Ar= (HL) _M or BC _R =0		2		1		
	СРІ	11 101 101					S	s		2	12	Ar- (HL) _M	1	1	1	1	S	2 *
	CFI	10 100 001										BC _R -1→BC _R						
		10 100 001										HLR+1→HLR		2		0		
	CPIR	11 101 101			1		s	s		2	14	BCR≠0 Ar≠(HL)M	1	Ţ	1	1	5	
	CPIR	10 110 001									12	BC _R = 0 or Ar= (HL) _M \(\Gamma \text{Ar} - (HL) _M						
												Q BC _R -1→BC _R						
												L HLR+1→HLR						
										1		Repeat Q until						
						1						Ar= (HL) _M or BC _R = 0	1			1)	
										2	12	(HL) _M →(DE) _M	١.	100	R	1		
	LDD	11 101 101			1		S/D			1	12	BC _R −1→BC _R						
		10 101 000		1								DE _R − 1 → DE _R						
						1				1		HL _B - 1→HL _B						
	!	1			1	1			1		1000000 11 000		1					
	LDDR	11 101 101					S/D			2	14(BC _R ≠0)	[(HL) _M → (DE) _M		81	F	R		1 6
		10 111 000						1			12(BC _R =0)	Q BC _R −1→BC _R						
										1		DE _R − 1 → DE _R						
												L HL _R - 1 → HL _R						
												Repeat Q until				a	1	
				1					1			BC _R =0				0		
	LDI	11 101 101		1	1		S/D	1		2	12	(HL) _M →(DE) _M	1.		1	1	1	1
		10 100 000		1								BC _R -1→BC _R						
				1								DE _R +1→DE _R						
												HLR+1→HLR						
	LDIR	11 101 101					S/D			2	14(BC _R ≠0)	[(HL) _M → (DE) _M		19.0	-	R F	1	1
	1	10 110 000				1					12(BC _R =0)	Q BC _R -1→BC _R						
				1								DER+1→DER						
				1					1	1		L HLR+1→HLR						
					1							Repeat Q until						
				1			1		1	1		BC _R =0						

Stack and Exchange

						ddressin									FI	ag		
Operation	MNEMONICS	OP-code				OUITESSII	9	-		Bytes	States	Operation	7	6	4	2	1	-
			IMMED	EXT	IND	REG	REĢI	IMP	REL				s	Z	Н	P/V	N	10
PUSH	PUSH zz	11 zz0 101				S		D		1	11	zzLr→(SP-2) _M						
										1 1		zzHr→(SP-1) _M						
												SPR-2→SPR						
	PUSH IX	11 011 101						S/D		2	14	IXLr-(SP-2)M						
		11 100 101								1 1		IXHr→(SP - 1) _M						
												SPR-2→SPR						
	PUSH IY	11 111 101						S/D		2	14	IYLr→(SP-2) _M						
		11 100 101										IYHr→(SP-1) _M						
												SPR-2-SPR						
POP	POP zz	11 zz0 001				D		S		1	9	(SP+1) _M →zzHr	1.					-
												(SP) _M →zzLr						
										1 1		SP _R +2→SP _R						
	POP IX	11 011 101						S/D		2	12	(SP+1) _M →IXHr						
		11 100 001										(SP) _M →IXLr	1					
												SP _R +2→SP _R						
	POP IY	11 111 101						S/D		2	12	(SP+1) _M →IYHr						
		11 100 001										(SP) _M →IYLr						
												SP _R + 2→SP _R						
xchange	EX AF,AF'	00 001 000						S/D		1	4	AF _R →AF _R ′						
	EX DE,HL	11 101 011						S/D		1	3	DER←→HLR						
	EXX	11 011 001						S/D		1	3	BC _R ←BC _R ′					٠	
	1											DE _R ← DE _R						
												HLR-HLR'						
	EX (SP),HL	11 100 011						S/D		1	16	Hr(SP+1) _M						
												Lr-→(SP) _M						
	EX (SP),IX	11 011 101						S/D		2	19	IXHr→(SP+1) _M						
		11 100 011										IXLr-(SP) _M						
	EX (SP),IY	11 111 101						S/D		2	19	IYHr → (SP+1) _M						
		11 100 011										IYLr → (SP) _M						

Program Control Instructions

Operation						Addressin	NG.						-	_	F	lag	_	_
name	MNEMONICS	OP-code	IMMED	EXT	IND	REG	REGI	IMP	REL	Bytes	States	Operation	7 S		4	-	1 / N	-
Call	CALL mn	11 001 101	IMMED	D	IND	ned	nedi	IIVIF	NEL	3	16	PCHr→(SP-1) _M						_
oun .	Orice min	< n >		-								PCLr→(SP-2) _M						
		< m >										mn→PC _R						
												SPR-2→SPR						
	CALL f, mn	11 f 100		D						3	6(f : false)	continue:f is false				·	×	
		< n >									16(f : true)	CALL mn:f is true						
		< m >																
huma	DJNZ j	00 010 000	-	_	_		_	-	D	2	9 (Br≠0)		+					
lump	DSN2 1	< j-2 >								2	7 (Br=0)		1					
												Br−1→Br						
												continue:Br=0	1					
												PC _R +j→PC _R :Br≠0						
	JP f, mn	11 f 010		D						3	6 (f :false)		1					
		< n >								3	9 (f : true)							
		< m >										mn→PC _R :f is true						
												continue:f is false						
		1										9.						
	JP mn	11 000 011		D						3	9	mn→PC _R						
		< n >																
		< m >																
	JP (HL)	11 101 001					D			1	3	HL _R →PC _R						
	JP (IX)	11 011 101					D			2	6	IX _R →PC _R						
	JP (IY)	11 101 001					D			2	6	NBC-	1.					
	3, 417	11 101 001								1		IY _R →PC _R	1			2	ď	
	JR j	00 011 000	'	1				1	D	2	8	PC _R +j→PC _R						
		< j-2 >																
	JR C,j	00 111 000							D	2	6	continue: C=0		*	٠			
		< j-2 >								2	8	PC _R +j→PC _R : C=1						
	JR NC.j	00 110 000							D	2	6	continue: C= 1						
		< j-2 >								2	8	PC _R +j→PC _R : C=0						
	JR Z.j	00 101 000 < j-2 >							D	2 2	6 8	continue: Z=0 PC _R +j-+PC _R : Z=1			•			
		1-2 >								2	8	PCR+ JPCR: Z=1						
	JR NZ,j	00 100 000							D	2	6	continue: Z= 1			×	٠		
		< j-2 >								2	8	PC _R +j→PC _R : Z=0						
Return	RET	11 001 001						D		1	9	(SP) _M →PCLr	1.					
101011	1	11 001 001										(SP+1) _M →PCHr						
												SP _R +2→SP _R						
	RET f	11 f 000						D		1	5(f :false)	continue:f is false						
										1	10(f :true)	RET: f is true						
	RETI	11 101 101						D		2	12	(SP) _M →PCLr	1.					
		01 001 101										(SP+1) _M →PCHr	1					
												SP _R +2→SP _R						
	RETN	11 101 101						D		2	12	(SP) _M →PCLr						
		01 000 101										(SP+1) _M →PCHr						
												SPR+2→SPR						
	1	1	1	1	1	1	1	1				IEF2→IEF1	1					



	-														FI	lag	
Operation	MNEMONICS	OP-code			,	ddressin	g			Bytes	States	Operation	7	6	4	2	1
name			IMMED	EXT	IND	REG	REGI	IMP	REL				s	z	н	P/V	N
Restart	RST v	11 v 111						D		1	11	$\begin{aligned} & \text{PCHr} \!$			٠	٠	

I/O Instructions

0					,	ddressin	а						L		FI	lag		_
Operation	MNEMONICS	OP-code			_		_			Bytes	States	Operation	-			2		_
			IMMED	EXT	IND	REG	REGI	IMP	Ю				+	_	_	P/V	_	-
NPUT	IN A,(m)	11 011 011						D	S	2	9	(Am) _I →Ar	1.			٠		
		< m >								κ .		m→A0~A7						
												A-A8~A15	١.		•		0	
	IN g.(C)	11 101 101				D			S	2	9	(BC)₁→gr	1	1	н	P	н	
		01 g 000										g=110: Only the						
		1										flags will						
												change. Cr→A ₂ ~A ₇						
													1					
						D						Br→As~Aıs	١.		_		_	
	INO g,(m)	11 101 101				В			S	3	12	(00m)₁→gr	1	1	н	P	н	
		00 g 000										g=110: Only the						
		< m >										flags will	1					
												change.						
												m→A ₀ ~A ₇		_			0	
							D					00→A ₆ ~A ₁₅	١	3			4	
	IND	11 101 101					0		S	2	12	(BC) ₁ →(HL) _M HL _B − 1 → HL _B	×	1	X	X	1	
		10 101 010										Br-1-Br						
	1											Cr→A ₀ ~A ₇						
												Br-As-As					4	í
	INDR	11 101 101					D		s	2	14(Br≠0)	[(BC) ₁ →(HL) _M	\ v	S	×	X		
	I WON	10 111 010							"	•	12(Br=0)	Q HLA-1-HLA	1	0	^	^		
		10.111.010										Br−1→Br						
												Repeat Q until						
												Br=0						
												Cr→Ao~Ar						
												Br-As-Ais						
	1	1	1		1		}	1	1			DI-AS-AIS	1	3			0	
	INI	11 101 101					D		s	2	12	(BC),—(HL) _M	1			×	4	
		10 100 010									'-	HL _R +1→HL _R	1^	1	^	^	1	
		10 100 010										Br—1→Br						
			1									Cr-Ao-Ar						
			1									Br→As~A₁s					4	
	INIR	11 101 101		1	1		D		s	2	14(Br≠0)	[(BC) _I → (HL) _M	×	S	×	X	_	
		10 110 010									12(Br=0)	Q HLa+1→HLa	1	_			•	
												LBr−1→Br						
		1										Repeat Q until	1					
												Br= 0						
												Cr-Ao-Ar						
	-	1	1									Br-As-Ais	1					

³ Z=1: Br-1=0 Z=0: Br-1≠0 4 N=1: MSB of Data=1 N=0: MSB of Data=0

													Γ		F	lag		
Operation	MNEMONICS	OP-code			Α.	ddressin	g			Bytes	States	Operation	7	6	4	2	1	0
name			IMMED	EXT	IND	REG	REGI	IMP	Ю				S	Z	Н	PΛ	/ N	С
OUTPUT	OUT (m),A	11 010 011 < m >						S	D	2	10	Ar—(Am)₁ m—A₀—A₁			10	٠		
	OUT (C),g	11 101 101 01 g 001				s			D	2	10	Ar→Ae ~ A15 gr→(BC) ₁ Cr→Ao ~ A7			(*)			
	OUTO (m),g	11 101 101 00 g 001				s			D	3	13	Br→A ₈ ~A ₁₅ gr→(00m) ₁ m→A ₀ ~A ₇			٠			×
	ОТДМ	< m > 11 101 101					s		D	2	14	00→A ₈ ~A ₁₅ (HL) _M →(00C) ₁	1	3		Р	4	1
	OTDMR	11 101 101 10 11 10 011					s		D	2	16(Br≠0) 14(Br=0)	HI _A = 1 -HI _B	R	S	R	s	4	
	OTDR	11 101 101					s		D	2	14(Br≠0) 12(Br=0)	Br= 0 Cr→A ₀ ~ A ₇ 00 ~ A ₈ ~ A ₁₅ GHL _M ~ (BC) ₁ HL _R - 1 → HL _R Br - 1 → Br Repeat Q until	×	S	×	×	4	
	оип	11 101 101 10 100 011					s		D	2	12	Br=0 Cr→Ao → Ar Br→Ao → Ars (HL) _M → (BC) ₁ HL _R +1→HL _R Br-1→Br	×	3	×	×	4) ×
	OTIR	11 101 101 10 110 011					s		D	2	14(Br≠0) 12(Br=0)	Cr—A ₀ —A ₇ Br—A ₈ —A ₁₅ [HL _M —(BC) ₁ HL _R +1—HL _R Br-1—Br Repost Q until	x	S	×	×	1) x
	TSTIO m	11 101 101 01 110 100 < m >	s						s	3	12	Br=0 Cr→Ao-Ar Br→As-A1s (OOC), m Cr→Ao-Ar OO-As-A1s	1	t	S	i P	R	R

³ Z=1:Br-1=0 Z=0:Br-1≠0 4 N=1:MSB of Data=1 N=0:MSB of Data=0

					Adreesi	20								FI	gei		
MNEMONICS	OP-code				-curessii	~			Bytes	States	Operation	7	6	4	2	1	0
		IMMED	EXT	IND	REG	REGI	IMP	Ю				s	Z	н	P/V	N	С
ОТІМ	11 101 101 10 000 011					s		D	2	14	(HL) _M →(OOC) ₁ HL _R +1→HL _R Cr+1→Cr Br-1→Br	1	3	1			1
OTIMR	11 101 101 10 010 011					s		D	2	16(Br≠0) 14(Br=0)	Cr—Ao—Ar OO—Ab—A15 (HL) _M —(OOC) ₁ HL _R +1—HL _R Cr+1—Cr Br-1—Br	R	S	R	S	4	
OUTD	11 101 101 10 101 011					s		D	2	12	Repeat Q until Br= 0 Cr→A ₀ ~A ₇ 00→A ₈ ~A ₁₅ (HL) _M →(BC) ₁	×			x		
						37					Br 1→Br Cr→A ₀ ~A ₇ Br→A ₈ ~A ₁₅		,	^			^
	OTIM	OTIM 11 101 101 10 100 011 10 101 101 101 1	OTIM 11 101 101 101 101 10 101 10 101 10 101 1	OTIMR 11 101 101 10 0UTD 11 101 101	OTIM 11 101 101 OTIMR 11 101 101 10 000 011 OTIMR 11 101 101 10 010 011	OTIM 11 101 101 OTIMR 11 101 101 OUTD 11 101 101	OTIM 11 101 101 S OUTD 11 101 101 S IMMED EXT IND REG REGI S OTIMR 11 101 101 S OUTD 11 101 101 S	MINEMONICS	MNEMONICS	MINEMONICS	MNEMONICS	MNEMONICS OP-code	MNEMONICS	MNEMONICS OP-code	MNEMONICS OP-code	MNEMONICS OP-code	MNEMONICS OP-code

Special Control Instructions

Operation					,	Addressin	ng						L		FI	eg .		
name MNEMONICS	OP-code			Bytes		States	Operation	7	6	4	2	1	0					
			IMMED	EXT	IND	REG	REGI	IMP	REL				s	Z	н	PΛ	N	C
Special Function	DAA	00 100 111						S/D		1	4	Decimal Adjust Accumulator	1	1	1	P	•	1
Carry	CCF	00 111 111								1	3	ō≕c			R		R	1
Control	SCF	00 110 111								1	3	1→c .			R		R	S
CPU	DI	11 110 011								1	3	0→IEF1, 0→IEF2 ⑤						
Control	Ð	11 111 011								1	3	1→IEF1, 1→IEF2 ⑤						
	HALT	01 110 110								1	3	CPU halted						
	IM O	11 101 101 01 000 110								2	6	Interrupt mode 0						
	IM 1	11 101 101 01 010 110								2	6	Interrupt mode 1			٠	٠	٠	
	IM 2	11 101 101 01 011 110								2	6	Interrupt mode 2				•	٠	٠
	NOP	00 000 000								1	3	No operation						
	SLP	11 101 101 01 110 110								2	8	Sleep		•	٠			

(5) Interrupts are not sampled at the end of DI or EI.



³ Z=1:Br-1=0 Z=0:Br-1≠0 4 N=1:MSB of Data=1 N=0:MSB of Data=0

20 INSTRUCTION SUMMARY IN ALPHABETICAL ORDER

ADC A,m 2 ADC A,g 1 ADC A, (HL) 1 ADC A, (IX+d) 3 ADC A, (IY+d) 3 ADD A,m 2 ADD A,g 1	2 2 2 6 6 2 2 2	6 4 6 14 14 6 4
ADC A, (HL) 1 ADC A, (IX+d) 3 ADC A, (IY+d) 3 ADD A,m 2	2 6 6 2 2 2	6 14 14 6 4
ADC A, (IX+d) 3 ADC A, (IY+d) 3 ADD A,m 2	6 6 2 2 2	14 14 6 4
ADC A, (IY+d) 3 ADD A,m 2	6 2 2 2	14 6 4
ADD A,m 2	2 2 2	6 4
	2 2	4
ADD A,g 1	2	,
		6
ADD A, (HL)	6	
ADD A, (IX+d) 3	6	14
ADD A, (IY+d) 3	6	14
ADC HL,ww 2	6	10
ADD HL,ww 1	5	7
ADD IX,xx 2	6	10
ADD IY,yy 2	6	10
AND m 2	2	6
AND g 1	2	4
AND (HL) 1	2	6
AND (IX+d) 3	6	14
AND (IY+d) 3	6	14
BIT b, (HL) 2	3	9
BIT b, (IX+d) 4	5	15
BIT b, (IY+d) 4	5	15
BIT b,g 2	2	6
CALL f,mn 3	2	6
		(If condition is false)
3	6	16
		(If condition is true)



MNEMONICS	Bytes	Machine Cycles	States
CALL mn	3	6	16
CCF	1	1	3
CPD	2	6	12
CPDR	2	8	14
			(If BC _R ≠0 and Ar≠(HL) _M)
	2	6	12
			(If BC _R =0 or Ar=(HL) _M)
CP (HL)	1	2	6
CPI	2	6	12
CPIR	2	8	14
_	I2		(If BC _R ≠0 and Ar≠(HL) _M)
	2	6	12
			(If BC _R =0 or Ar=(HL) _M)
CP (IX+d)	3	6	14
CP (IY+d)	3	6	14
CPL	1	1	3
CP m	2	2	6
CP g	1	2	4
DAA	1	2	4
DEC (HL)	1	4	10
DEC IX	2	3	7
DEC IY	2	3	7
DEC (IX+d)	3	8	18
DEC (IY+d)	3	8	18
DEC g	1	2	4
DEC ww	1	2	4
DI	1	1	3

MNEMONICS	Bytes	Machine Cycles	States
DJNZ j	2	5	9 (If Br≠0)
	2	3	7 (If Br=0)
EI	1	1	3
EX AF,AF'	1	2	4
EX DE,HL	1	1	3
EX (SP),HL	1	6	16
EX (SP),IX	2	7	19
EX (SP),IY	2	7	19
EXX	1	1	3
HALT	1	1	3
IM O	2	2	6
IM 1	2	2	6
IM 2	2	2	6
INC g	1	2	4
INC (HL)	1	4	10
INC (IX+d)	3	8	18
INC (IY+d)	3	8	18
INC ww	1	2	4
INC IX	2	3	7
INC IY	2	3	7
IN A,(m)	2	3	9
IN g,(C)	2	3	9
INI	2	4	12
INIR	2	6	14 (If Br≠0)
	2	4	12 (If Br=0)
IND	2	4	12
INDR	2	6	14 (If Br≠0)



MNEMONICS	Bytes	Machine Cycles	States
INDR	2	4	12 (If Br=0)
INO g,(m)	3	4	12
JP f,mn	3	2	6
			(If f is false)
	3	3	9
			(If f is true)
JP (HL)	1	1	3
JP (IX)	2	2	6
JP (IY)	2	2	6
JP mn	3	3	9
JR j	2	4	8
JR C,j	2	2	6
			(If condition is false)
	2	4	8
			(If condition is true)
JR NC,j	2	2	6
			(If condition is false)
	2	4	8
			(If condition is true)
JR Z,j	2	2	6
			(If condition is false)
	2	4	8
			(If condition is true)
JR NZ,j	2	2	6
			(If condition is false)
	2	4	8
			(If condition is true)

MNEMONICS	Bytes	Machine Cycles	States
LD A, (BC)	1	2	6
LD A, (DE)	1	2	6
LD A,I	2	2	6
LD A, (mn)	3	4	12
LD A,R	2	2	6
LD (BC),A	1	3	7
LDD	2	4	12
LD (DE),A	1	3	7
LD ww,mn	3	3	9
LD ww,(mn)	4	6	18
LDDR	2	6	14 (If BC _R ≠0)
	2	4	12 (If BC _R =0)
LD (HL),m	2	3	9
LD HL,(mn)	3	5	15
LD (HL),g	1	3	7
LDI	2	4	12
LD I,A	2	2	6
LDIR	2	6	14 (If BC _R ≠0)
	2	4	12 (If BC _R =0)
LD IX,mn	4	4	12
LD IX,(mn)	4	6	18
LD (IX+d),m	4	5	15
LD (IX+d),g	3	7	15
LD IY,mn	4	4	12
LD IY,(mn)	4	6	18
LD (IY+d),m	4	5	15
LD (IY+d),g	3	7	15

MNEMONICS	Bytes	Machine Cycles	States
LD (mn),A	3	5	13
LD (mn),ww	4	7	19
LD (mn),HL	3	6	16
LD (mn),IX	4	7	19
LD (mn),IY	4	7	
LD (IIIII),IT	2		19
		2	6
LD g,(HL)	1	2	6
LD g,(IX+d)	3	6	14
LD g,(IY+d)	3	6	14
LD g,m	2	2	6
LD g,g'	1	2	4
LD SP,HL	1	2	4
LD SP,IX	2	3	7
LD SP,IY	2	3	7
MLT ww	2	13	17
NEG	2	2	6
NOP	1	1	3
OR (HL)	1	2	6
OR (IX+d)	3	6	14
OR (IY+d)	3	6	14
OR m	2	2	6
OR g	1	2	4
OTDM	2	6	14
OTDMR	2	8	16 (If Br≠0)
	2	6	14 (If Br=0)
OTDR	2	6	14 (If Br≠0)
	2	4	12 (If Br=0)

MNEMONICS	Bytes	Machine Cycles	States
ОТІМ	2	6	14
OTIMR	2	8	16 (If Br≠0)
	2	6	14 (If Br=0)
OTIR	2	6	14 (If Br≠0)
	2	4	12 (If Br=0)
OUTD	2	4	12
OUTI	2	4	12
OUT (m),A	2	4	10
OUT (C),g	2	4	10
OUTO (m),g	3	5	13
POP IX	2	4	12
POP IY	2	4	12
POP zz	1	3	9
PUSH IX	2	6	14
PUSH IY	2	6	14
PUSH zz	1	5	11
RES b,(HL)	2	5	13
RES b,(IX+d)	4	7	19
RES b,(IY+d)	4	7	19
RES b,g	2	3	7
RET	. 1	3	9
RET f	1	3	5
			(If condition is false)
	1	4	10
			(If condition is true)
RETI	2	4	12
RETN	2	4	12



MNEMONICS	Bytes	Machine Cycles	States
RLA	1	1	3
RLCA	1	1	3
RLC (HL)	2	5	13
RLC (IX+d)	4	7	19
RLC (IY+d)	4	7	19
RLC g	2	3	7
RLD	2	8	16
RL (HL)	2	5	13
RL (IX+d)	4	7	19
RL (IY+d)	4	7	19
RL g	2	3	7
RRA	1	1	3
RRCA	1	1	3
RRC (HL)	2	5	13
RRC (IX+d)	4	7	19
RRC (IY+d)	4	7	19
RRC g	2	3	7
RRD	2	8	16
RR (HL)	2	5	13
RR (IX+d)	4	7	19
RR (IY+d)	4	7	19
RR g	2	3	7
RST v	1	5	11
SBC A,(HL)	1	2	6
SBC A,(IX+d)	3	6	14
SBC A,(IY+d)	3	6	14
SBC A,m	2	2	6

MNEMONICS	Bytes	Machine Cycles	States
SBC A,g	1	2	4
SBC HL,ww	2	6	10
SCF	1	1	3
SET b,(HL)	2	5	13
SET b,(IX+d)	4	7	19
SET b,(IY+d)	4	7	19
SET b,g	2	3	7
SLA (HL)	2	. 5	13
SLA (IX+d)	4	7	19
SLA (IY+d)	4	7	19
SLA g	2	3	7
SLP	2	2	8
SRA (HL)	2	5	13
SRA (IX+d)	4	7,	19
SRA (IY+d)	4	7	19
SRA g	2	3	7
SRL (HL)	2	5	13
SRL (IX+d)	4	7	19
SRL (IY+d)	4	7	19
SRL g	2	3	7
SUB (HL)	1	2	6
SUB (IX+d)	3	6	14
SUB (IY+d)	3	6	14
SUB m	2	2	6
SUB g	1	2	4
TSTIO m	3	4	12
TST g	2	3	7

MNEMONICS	Bytes	Machine Cycles	States
TST m	3	3	9
TST (HL)	2	4	10
XOR (HL)	1	2	6
XOR (IX+d)	3	6	14
XOR (IY+d)	3	6	14
XOR m	2	2	6
XOR g	1	2	4
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	ш																									
	AF	۵	30H	1111	L				ī				OR m			LD SP,	로		П		NOTE3)	CP m		L	Σ	200
1~1	ᅱ	PO	20H	1110	Ш	ţ	77	mn	(B)X	土	f, mn	77	M QNY	^	.	IP (HL)		mn	XDE, HL	f, mn	Table3 NOTE3)	M MOX	>	Ш	PE	700
L0=0-7	DE	NC	10H	1101		RET	POP zz	JP f, mn	OT (m) E	Α,	CALL f, mn	PUSH zz	UB m	RST v	RET f	EXX JP (HL) LD SP,		JP f, mn	I A, (m) E	CALL f, mn	отез)	BC A,m)	RST v	۵	O	101
1	-	NZ	H00	1100	ပ				JP mn 0UT (m) EX (SP)		0		ADD A,m SUB m AND m OR			RET			Table IN A, (m) EXDE, HL		CALL mn NOTES)	DC A,m S		0	Z	700
Ц			_	1011 1	В				7	s H											0	NOTEZ) NOTEZ) NOTEZ) NOTEZ) ADC AM SBC AM XOR M CP		В		
				1010	A					S Q		- 1	OTE2) N						OR s		- 1	OTE2) N		٨		
				1001	6					JB s A		- 1	OTE2) N		_				BC A X	s,	-	OTE2) N		6		
			8	1000	8					ADD A SUB s AND s OR	s,	1	NOTE2) NOTE2) NOTE2)						ADC A SBC A XOR s CP s	s,	- 1	OTE2) N		80		
			(HL)	0111 1	7		NOTE1)			₹			HALT						A		- 1	Z		7	A	Γ
			÷ I	0110	9		ž 						I						(O					9		
				-						LD g,s			NOTE2)						LD g, s			NOTE2)			Ы	
		(/	٥	0 0101	5							1	ž						_					5		ĺ
		~0=	В	0100	4	_					_	_	_		-		٦.							4	0	0 -
	SP	g (L0=0~7)	(HL)	0011	က	JR NC,		LD (mn	Α,		NOTE1)	NOTE1	NOTE1)	SOF	JR G,		LD A	(mm)					CCF	е	4	(10-0-0)
= ALL	님		I	0010	2	JR NZ, JR NC,	LD ww, mn	LD (mn)	ヺ.	ING ww			п	DAA	JR j JRZj	T, w	LD H	(mn)	DEC ww	INC g	DEC g	LD g, m	CPL	2	٦	
ww (LO=ALL	DE		D	0001	-	DJNZ	LD w	LD (ww), A LD (mn) LD (mn)		NC NC	INC g	DEC g	LD g, m	RLA		ADD HL, ww	(ww)		DEC	ž	DE	LD	RRA	-	Ш	
3	BC		В	0000	0	NOP		LD (w					_	RLCA RLA	EXAF, AF		LD A, (ww) LD HL,						RRCA	0	0	
L		× ×		₹	7	0	-	2		က	4	2	9	7	00	6	A		æ	ပ	۵	ш	L			_
	der	Instruction format : XX			/ 	0000	1000	0010		1100	0100	1010	0110	0111	1000	1001	1010		1011	1100	1101	1110	1111			
ı.	Table 18 1st op-code map	tion fo				В	0	۵		ш	I	_	(HL)	A	æ	ပ	۵		ш	I	_	(F	Ø			
21 OP-CODE MAP	st op	struc										(7	זרו	/=	IH)		- 6	3								

NOTE1) (HL) replaces g. (HL) replaces s.

If DDH is supplemented as 1st op-code for the instructions which have HL or (HL) as an operand in Table 18, the instructions are executed replacing HL with IX and (HL) with (IX+d).

ex. 22H: LD (mn), HL 33

L0=8~F

If FDH is supplemented as 1st op-code for the instructions which have HL or (HL) as an operand in Table 18, the instructions are executed DDH 22H: LD (mn), IX

replacing HL with IY and (HL) with (IY+d).

ex.

34H: INC (HL) FDH 34H: INC (IY+d)

However, JP (HL) and EX DE, HL are exception and note the followings. If DDH is supplemented as 1st op-code for JP (HL), (IX) replaces (HL) as operand and JP (IX) is executed. If FDH is supplemented as 1st op-code for JP (HL), (IX) replaces (HL) as operand and JP (IY) is executed.

Even if DDH or FDH is supplemented as 1st op-code for EX DE, HL, HL is not replaced and the instruction is regarded as illegal instruction.

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Table 19 2nd op-code map Instruction format : CB XX

				0	-	2	က	4	გ	9	7	8	6	٨	В	0	۵	Ш	L			
	9	1111	L																	L	7	
	4	1100 1101 1110 1111	Ш					SET b, g		NOTE1)						SET b, g		NOTE1)		Ε	2	
	2	1101	Ω					SET		N N						SET		8		Q	က	
	0	1100	O																	ວ	-	
	9	1011	В																	В	7	
(L0=0-7) d	4	1010	A					RES b, g		E1)						b,g		NOTE1)		A	2	(L0=8-F)
=0T)	2	1001	6					RES		NOTE1)						RES b, g		NO.		6	က	(L0=
q	0	1000	œ																	œ	-	p
	9	0111	7																	7	7	
	4	0110	9					b,g		E1)						b,g	1	E1)		9	വ	
	2	0101	2					BIT b, g		NOTE1)						BIT b, g		NOTE1)		5	ო	
	0	HI 0000 0001 0010 0011 0100 0101 0110 0111 1000 1001 1010 1011	4							 										4	-	
		0011	က													SRL g		NOTE1)	 	က		-
		0010	2					SLA g		NOTE1)						RRC g RR g SRA g SRL		NOTE1) NOTE1) NOTE1)	 	2		
		000	-					RL g		NOTE1) NOTE1)						RR g		NOTE1)	 	-		
		0000	0					RLC g RL g SLA		NOTE1)	 					RRC g		NOTE1)	 	0		
		〒	7	0	-	2	က	4	S	9	7	∞	6	Ø	œ	ပ	۵	ш	ட		•	
			<u>9</u>	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	111			
				æ	0	۵	ш	I	٦	(HL)	۷	æ	0	٥	ш	I	٦	(H	A			
									(7	JA	=1	H)		8								

NOTE1) If DDH is supplemented as 1st op-code for the instructions which have (HL) as operand in Table 19, the instructions are executed replacing (HL) with (IX+d).

[FIDH is supplemented as 1st op-code for the instructions which have (HL) as operand in Table 19, the instructions are executed replacing (HL) with (IY+d).

							0	-	2	က	4	2	9	7	8	6	A	В	0	٥	ш	L			
					1111	L									8								L		
					1110	Ш																	Ш		
					1101	۵																	D		
					1100	0																	C		
					1010 1011 1100 1101 1110 1111	В	LDIR	CPIR	INIR	OTIR					LDD LDDR	CPD CPDR	IND INDR	OTDR					В		
					1010	٨	ΓD	CPI	Z	OTIM OTIMR OUTI OTIR					LDD	CPD	QNI	OTDM OTDM OUTD OTDR					A		
					1001	6				OTIMR								OTDMR					6		
_	_				1000	∞				OTIM								OTDN					8		
	7	SP			0111	7				>	TST m TSTI0 m		SLP				,						7	A	
-	WW (LU=ALL	爿		I	0100 0101 0110	9	IN g, (C)	g,(SBC HL, ww	LD (mn), ww	TST m			I RRD	IN g, (C)	OUT (C), g	ADC HL, ww	LD ww, (mn)	MLT ww			RLD	9	٦	
, ,	W (E	DE	()	۵	0101	2	Z	OUT (C), g	SBC	اله (ا		-	N N	LD I, A LD A, I RRD	Z	OUT	ADC	LD w	ML		IM 2	LD RA LD AR RLD	2	Ш	<u>.</u>
		BC	(L0=0-7)	В		4		0			TST (HL) NEG	RETN	0 <u>M</u>	LD I, A						RET		LD R	4	0	=8~F
			g (L0		0011	3			1		TST (HL					20							က	٨	g (L0=8~F)
DXX				I	0010	2	IN0 g, (m)	n),g			500				IN0 g, (m)	OUTO (m), g			TST g				2	٦	
2nd op-code map				۵	0000 0001	-	0NI	OUT0 (m), g			TST (0N	OUTO			TS				-	Ш	
able 20 2nd op-code map				æ	-	0		0					_					_			_		0	ပ	
2nd o					Ī	/	0 0	-	0	1 3	4	1	9 0	1 7	8	1	0 A	1 B	0	1 D	0 E	<u>F</u>			
able 20						L0	0000	000	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111			

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22 BUS AND CONTROL SIGNAL CONDITION IN EACH MACHINE CYCLE

* (ADDRESS) : invalid Z (DATA) : high impedance.

Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	IOE	LIR	HALT	ST
100 111	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
ADD HL,ww	MC ₂ ~MC ₅	TiTiTiTi		z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
ADD IX,xx ADD IY,yy	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	TITITITI		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	. 1st op-code	0	1	0	1	0	1	0
ADC HL,ww SBC HL,ww	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃ ~MC ₆	тітіті		z	1	1	1	1	1	1	1
ADD A,g ADC A,g SUB g	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
SBC A,g AND g OR g XOR g CP g	MC ₂	Ti		z	1	1	1	1	1	1	1
ADD A,m ADC A,m SUB m SBC A,m	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
AND m OR m XOR m CP m	MC ₂	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1
ADD A, (HL) ADC A, (HL) SUB (HL) SBC A, (HL)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
AND (HL) OR (HL) XOR (HL) CP (HL)	MC ₂	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
ADD A, (IX+d) ADD A, (IY+d) ADC A, (IX+d)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
ADC A, (IX+d) ADC A, (IY+d) SUB (IX+d) SUB (IY+d) SBC A, (IX+d)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
SBC A, (IY+d) AND (IX+d)	MC ₃	T ₁ T ₂ T ₃ '	1st operand Address	d	0	1	0	1	1	1	1
AND (IY+d) OR (IX+d) OR (IY+d) XOR (IX+d) XOR (IY+d)	MC ₄ ~MC ₅	TiTi	*	z	1	1	1	1	1	1	1
CP (IX+d) CP (IY+d)	MC ₆	T ₁ T ₂ T ₃	IX+d IY+d	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
BIT b,g	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
BIT b, (HL)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
BIT b, $(IX+d)$ BIT b, $(IY+d)$	MC ₃	T1T2T3	1st operand Address	d	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	3rd op-code Address	3rd op-code	0	1	0	1	0	1	1
	MC ₅	T ₁ T ₂ T ₃	IX+d IY+d	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
CALL mn	МСз	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
CALL IIII	MC ₄	Ti	•	z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-1	РСН	1	0	0	1	1	1	1
	МСв	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
CALL f,mn	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
is false)	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪOE	LIR	HALT	ST
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
CALL f,mn	MC ₃	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
(If condition is true)	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-1	PCH	1	0	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
CCF	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
CPI	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
CPD	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	TiTiTi		Z	1	1	1	1	1	1	1
	MC	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
CPIR CPDR	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
(If $BC_R \neq 0$ and $Ar \neq (HL)_M$)	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄ ~MC ₈	тітітіті		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
CPIR CPDR	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
(If $BC_R = 0$ or $Ar = (HL)_M$)	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄ ~MC ₆	TiTiTi		Z	1	1	1	1	1	1	1
CPL	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
DAA	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
DAA	MC ₂	Ti		z	1	1	1	1	1	1	1
DI	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
DJNZ j	MC ₂	Ti *1		z	1	1	1	1	1	1	1
(If Br≠O)	МСз	T ₁ T ₂ T ₃	1st operand Address	j-2	0	1	0	1	1	1	1
	MC ₄ ~MC ₅	TiTi		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
DJNZ j (If Br=0)	MC ₂	Ti *1		Z	1	1	1	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	1st operand Address	j-2	0	1	0	1	1	1	1
EI	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
EX DE, HL EXX	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
EV 45 45	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
EX AF, AF'	MC ₂	Ti		z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	SP	DATA	0	1	0	1	1	1	1
EX (SP), HL	MC ₃	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
EX (SF), FIL	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP+1	н	1	0	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	SP	L	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
EX (SP),IX EX (SP),IY	MC ₃	T ₁ T ₂ T ₃	SP	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
	MC ₅	Ti		z	1	1	1	1	1	1	1

^{*1} DMA, REFRESH, or BUS RELEASE cannot be executed after this state. (Request is ignored)



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
EX (SP), IX	MC ₆	T ₁ T ₂ T ₃	SP+1	IXH	1	0	0	1	1	1	1
EX (SP), IY	MC ₇	T ₁ T ₂ T ₃	SP	IXL IYL	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
HALT	_		Next op-code Address	Next op-code	0	1	0	1	0	0	0
IM 0 IM 1	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
IM 2	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
INC g	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
DEC g	MC ₂	Ti		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
INC (HL)	MC ₂	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
DEC (HL)	MC ₃	Ti		z	1	1	1	1	ì	1	1
	MC ₄	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
INC (IX+d)	МСз	T ₁ T ₂ T ₃	1st operand Address	d	0	1	0	1	1	1	1
DEC (IX+d)	MC ₄ ~MC ₅	TiTi		z	1	1	1	1	1	1	1
DEC (IY+d)	MC ₆	T ₁ T ₂ T ₃	IX+d IY+d	DATA	0	1	0	1	1	1	1
	MC ₇	Ti		z	1	1	1	1	1	1	1
	MC ₈	T ₁ T ₂ T ₃	IX+d IY+d	DATA	1	0	0	1	1	1	1
INC ww	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
DEC ww	MC ₂	Ti		Z	1	1	1	1	1	1	1
INC IX	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-dode	0	1	0	1	0	1	0
INC IY DEC IX DEC IY	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
DEC IT	MC ₃	Ti		Z	1	1	1	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	IOE	LIR	HALT	ST
11	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
IN A,(m)	MC ₂	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1
	МСз	T ₁ T ₂ T ₃	m to A ₀ ~A ₇ A to A ₈ ~A ₁₅	DATA	0	1	1	0	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
IN g,(C)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	BC	DATA	0	1	1	0	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
NO - (-)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
INO g,(m)	МСз	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	.1
	MC ₄	T ₁ T ₂ T ₃	m to A ₀ ~A ₇ 00H to A ₈ ~A ₁₅	DATA	0	1	1	0	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
INI	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
IND	МСз	T ₁ T ₂ T ₃	BC	DATA	0	1	1	0	1	1	1
	MC ₄	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
INIR INDR (If Br≠0)	MC ₃	T ₁ T ₂ T ₃	ВС	DATA	0	1	1	0	1	1	1
	MC ₄	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
	MC ₅ ~MC ₆	TiTi		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
INIR INDR	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
(If Br=0)	MC ₃	T ₁ T ₂ T ₃	BC	DATA	0	1	1	0	1	1	1
	MC ₄	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	IOE	LIR	HALT	ST
X.	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
JP mn	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
JP f,mn	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
(If f is false)	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
JP f,mn (If f is true)	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	МСз	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
JP (HL)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
JP (IX)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
JP (IY)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
JR j	MC ₂	T ₁ T ₂ T ₃	1st operand Address	j-2	0	1	0	1	1	1	1
	MC ₃ ~MC ₄	TiTi		Z	1	1	1	1	1	1	1
JR C,j JR NC,j JR Z,j JR NZ,j	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
(If condition is false)	MC ₂	T ₁ T ₂ T ₃	1st operand Address	j-2	0	1	0	1	1	1	1
JR C,j JR NC,j	MC ₁	T1T2T3	1st op-code Address	1st op-code	0	1	0	1	0	1	0
JR Z,j JR NZ,j (If condition	MC ₂	T ₁ T ₂ T ₃	st operand Address	j-2	0	1	0	1	1	1	1
is true)	MC ₃ ~MC ₄	TiTi		z	1	1	1	1	1	1	1
10 1	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD g,g'	MC ₂	Ti		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD g,m	MC ₂	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	MĒ	ĪŌĒ	LIR	HALT	ST
LD g, (HL)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
LD g, $(IX+d)$ LD g, $(IY+d)$	MC ₃	T ₁ T ₂ T ₃	1st operand Address	d	0	1	0	1	1	1	1
	MC ₄ ~MC ₅	TiTi		Z	1	1	1	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	IX+d	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD (HL),g	MC ₂	Ti	•	Z	1	1	1	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	HL	g	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
LD (IX+d),g LD (IY+d),g	MC ₃	T ₁ T ₂ T ₃	1st operand Address	d	0	1	0	1	1	1	1
	MC ₄ ~ MC ₆	TiTiTi		Z	1	1	1	1	1	1	1
	MC ₇	T ₁ T ₂ T ₃	IX+d IY+d	g	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD (HL),m	MC ₂	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1
	МСз	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
LD (IX+d),m LD (IY+d),m	MC ₃	T ₁ T ₂ T ₃	1st operand Address	d	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	IX+d IY+d	DATA	1	0	0	1	1	1	1
LD A, (BC) LD A, (DE)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	e 1	0	1	0	1	0



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
LD A, (BC) LD A, (DE)	MC ₂	T ₁ T ₂ T ₃	BC DE	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
10.4/>	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
LD A,(mn)	MC ₃	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	mn	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD (BC),A LD (DE),A	MC ₂	Ti		z	1	1	1	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	BC DE	A	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
LD (mn),A	MC ₃	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	mn	А	1	0	0	1	1	1	1
LD A,I LD A,R	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD I,A LD R,A	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD ww, mn	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD IX,mn	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
LD IY,mn	MC ₃	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
LD HL, (mn)	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	TIR	HALT	ST
LD HL, (mn)	МСз	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	mn	DATA	0	1	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	mn+ 1	DATA	0	1	0	1	1	1	1
LD ww,(mn)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₅	T1T2T3	mn	DATA	0	1	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	mn+1	DATA	0	1	0	1	1	1	1
LD IX,(mn) LD IY,(mn)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₅	T1T2T3	mn	DATA	0	1	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	mn+1	DATA	0	1	0	1	1	1	1
LD (mn),HL	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₄	Ti	•	Z	1	1	1	1	1	1	1
	MC s	T ₁ T ₂ T ₃	mn	L	1	0	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	mn+1	н	1	0	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
LD (mn),ww	MC ₄	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₅	Ti .	•	Z	1	1	1	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	mn	wwL	1	0	0	1	1	1	1
	MC ₇	T ₁ T ₂ T ₃	mn+1	wwH	1	0	0	1	1	1	1
LD (mn),IX LD (mn),IY	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1 .	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	1st operand Address	n	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	2nd operand Address	m	0	1	0	1	1	1	1
	MC ₅	Ti		z	1	1	1	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	mn	IXL IYL	1	0	0	1	1	1	1
	MC ₇	T ₁ T ₂ T ₃	mn+1	IXH IYH	1	0	0	1	1	1	1
LD SP, HL	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	Ti		z	1	1	1	1	1	1	1
LD SP,IX LD SP,IY	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	Ti		Z	1	1	1	1	1	1	1
LDI LDD	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1 -	0
	MC ₂	T1T2T3	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	DE	DATA	1	0	0	1	1	1	1.



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
LDIR LDDR (If BC _R ≠0)	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	МСз	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	DE	DATA	1	0	0	1	1	1	1
	MC ₅ ~MC ₆	TiTi		Z	1	1	1	1	1	1	1
LDIR LDDR (If BC _R =0)	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	T1T2T3	DE	DATA	1	0	0	1	1	1	1
MLT ww	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃ ~MC ₁₃	TITITITI TITITITI TITITI		z	1	1	1	1	1	1	1
NEG	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
NOP	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
OUT (m),A	MC ₁	T1T2T3	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1
	MC ₃	Ti		Z	1	1	1	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	m to A ₀ ~A ₇ A to A ₈ ~A ₁₅	А	1	0	1	0	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	MĒ	ĪŌĒ	LIR	HALT	ST
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
OUT (C),g	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
001 (0),g	MC ₃	Ti		Z	1	1	1	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	BC	g	1	0	1	0	1	1	1
	MC ₁	T1T2T3	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
OUTO (m),g	MC ₃	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1
	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC ₅	T1T2T3	m to A ₀ ~A ₇ 00H to A _d ~A ₁₅	g	1	0	1	0	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T1T2T3	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
OTIM	MC ₃	Ti		Z	1	1	1	1	1	1	1
OTDM	MC ₄	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	C to A ₀ ~A ₇ 00H to A ₃ ~A ₁₅	DATA	1	0	1	0	1	1	1
	MC ₆	Ti		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
OTIMR OTDMR	МСз	Ti		Z	1	1	1	1	1	1	1
(If Br≠0)	MC ₄	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	C to A ₀ ~A ₇ 00H to A _d ~A ₁₅	DATA	1	0	1	0	1	1	1
	MC ₆ ~MC ₃	TiTiTi		z	1	1	1	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
OTIMR OTDMR	МСз	Ti		Z	1	1	1	1	1	1	1
(If Br=0)	MC ₄	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	C to Ao~A7 OOH to Ad~A15	DATA	1	0	1	0	1	1	1
	MC ₆	Ti		Z	1	1	1	1	1	1	1
	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
OUTI	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
OUTD	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	BC	DATA	1	0	1	0	1	1	1
	MC ₁	T1T2T3	1st op-code Address	1st op-code	0	1	0	1	0	1	0
OTIR	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
OTDR (If Br≠0)	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	ВС	DATA	1	0	1	0	1	1	1
	MCs ~MCs	TiTi		Z	1	1	1	1	1	1	1
	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
OTIR OTDR	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
(If Br=0)	МСз	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	BC	DATA	1	0	1	0	1	1	1
POP zz	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1.	0
T OF ZZ	MC ₂	T ₁ T ₂ T ₃	SP	DATA	0	1	0	1	1	1	1
	МСз	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
POP IX POP IY	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
POP IX POP IY	MC ₃	T ₁ T ₂ T ₃	SP	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
PUSH zz	MC ₂ ~MC ₃	TiTi		Z	1	1	1	1	1	1	1
7 0311 22	MC ₄	T ₁ T ₂ T ₃	SP-1	zzH	1	0	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-2	zzL	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
PUSH IX PUSH IY	MC ₃ ~MC ₄	TiTi		z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-1	IXH IYH	1	0	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	SP-2	IXL IYL	1	0	0	1	1	1	1
RET	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
REI	MC ₂	T1T2T3	SP	DATA	0	1	0	1	1	1	1
	МСз	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
RET f	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
is false)	MC ₂ ~MC ₃	TiTi		z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RET f	MC ₂	Ti		Z	1	1	1	1	1	1	1
is true)	MC ₃	T ₁ T ₂ T ₃	SP	DATA	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
RETI	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RETN	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
RETI	MC ₃	T ₁ T ₂ T ₃	SP	DATA	0	1	0	1	1	1	1
RETN	MC ₄	T ₁ T ₂ T ₃	SP+1	DATA	0	1	0	1	1	1	1
RLCA RLA RRCA RRA	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RLC g RL g	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RRC g RR g SLA g	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
SRA g SRL g	MC ₃	Ti		z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RLC (HL) RL (HL)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
RRC (HL) RR (HL) SLA (HL)	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
SRA (HL) SRL (HL)	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC 5	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
RLC (IX+d)	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RLC (IY+d) RL (IX+d)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
RL (IY+d) RRC (IX+d) RRC (IY+d)	MC ₃	T ₁ T ₂ T ₃	1st operand Address	d	0	1	0	1	1	1	1
RR (IX+d) RR (IY+d)	MC ₄	T ₁ T ₂ T ₃	3rd op-code Address	3rd op-code	0	1	0	1	0	1	1
SLA (IX+d) SLA (IY+d)	MC 5	T ₁ T ₂ T ₃	IX+d IY+d	DATA	0	1	0	1	1	1	1
SRA (IX+d) SRA (IY+d) SRL (IX+d)	MC ₆	Ti		Z	1	1	1	1	1	1	1
SRL (IY+d)	MC ₇	T ₁ T ₂ T ₃	IX+d IY+d	DATA	1	0	0	1	1	1	1
	MC 1	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RLD RRD	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
RLD .	MC ₄ ~MC ₇	TiTiTiTi		Z	1	1	1	1	1	1	1
RRD	MC ₈	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
RST v	MC ₂ ~MC ₃	TiTi		z	1	1	1	1	1	1	1
NOT V	MC ₄	T ₁ T ₂ T ₃	SP-1	РСН	1	0	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
SCF	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
SET b,g RES b,g	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	Ti		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
SET b, (HL) RES b, (HL)	МСз	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	HL	DATA	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
SET b, (IX+d)	MC ₃	T ₁ T ₂ T ₃	1st operand Address	d	0	1	0	1	1	1	1
SET b, (IY+d) RES b, (IX+d)	MC ₄	T1T2T3	3rd op-code Address	3rd op-code	0	1	0	1	0	1	1
RES b, (IY+d)	MC ₅	T ₁ T ₂ T ₃	IX+d IY+d	DATA	0	1	0	1	1	1	1
	MC ₆	Ti		Z	1	1	1	1	1	1	1
	MC ₇	T ₁ T ₂ T ₃	IX+d IY+d	DATA	1	0	0	1	1	1	1



Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	ME	ĪŌĒ	LIR	HALT	ST
SLP	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
SLP	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
			7FFFFH	Z	1	1	1	1	1	0	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
TSTIO m	MC ₂	T1T2T3	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
13110 111	MC ₃	T1T2T3	1st operand Address	m	0	1	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	C to A ₀ ~A ₇ 00H to A ₈ ~A ₁₅	DATA	0	1	1	0	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
TST g	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	МСз	Ti		Z	1	1	1	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
TST m	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
	MC ₃	T ₁ T ₂ T ₃	1st operand Address	m	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T ₃	1st op-code Address	1st op-code	0	1	0	1	0	1	0
TST (HL)	MC ₂	T ₁ T ₂ T ₃	2nd op-code Address	2nd op-code	0	1	0	1	0	1	1
151 (nL)	MC ₃	Ti		Z	1	1	1	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	HL	DATA	0	1	0	1	1	1	1
INTERRUPT								,			
	MCı	T ₁ T ₂ T ₃	Next op-code Address (PC)		0	1	0	1	0	1	0
NMI	MC ₂ ~MC ₃	TiTi		Z	1	1	1	1	1	1	1
IAIAII	MC ₄	T ₁ T ₂ T ₃	SP-1	PCH	1	0	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
INT₀ MODE 0	MC ₁	T ₁ T ₂ T _W T _W T ₃	Next op-code Address (PC)	1st op-code	1	1	1	0	0	1	0

1

1 1



(RST INSERTED)

MC₂

~MC₃ TiTi

Instruction	Machine Cycle	States	ADDRESS	DATA	RD	WR	MĒ	ĪŌĒ	LIR	HALT	ST
INT₀ MODE O	MC ₄	T ₁ T ₂ T ₃	SP-1	PCH	1	0	0	1	1	1	1
(RST INSERTED)	MC ₅	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T _W T _W T ₃	Next op-code Address (PC)	1st op-code	1	1	1	0	0	1	0
	MC ₂	T ₁ T ₂ T ₃	PC	n	0	1	0	1	1	1	1
INT₀ MODE O	MC ₃	T ₁ T ₂ T ₃	PC+1	m	0	1	0	1	1	1	1
(CALL INSERTED)	MC ₄	Ti		Z	1	1	1	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	SP-1	PC+ 2(H)	1	0	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	SP-2	PC+2(L)	1	0	0	1	1	1	1
	MC ₁	T ₁ T ₂ T _W T _W T ₃	Next op-code Address (PC)		1	1	1	0	0	1	0
INT₀ MODE 1	MC ₂	T ₁ T ₂ T ₃	SP-1	PCH	1	0	0	1	1	1	1
	MC ₃	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
	MC 1	T ₁ T ₂ T _W T _W T ₃	Next op-code Address (PC)	Vector	1	1	1	0	0	1	0
	MC ₂	Ti		Z	1	1	1	1	1	1	1
INT₀ MODE 2	MC ₃	T ₁ T ₂ T ₃	SP-1	PCH	1	0	0	1	1	1	1
	MC ₄	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	I, Vector	DATA	0	1	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	I, Vector+1	DATA	0	1	0	1	1	1	1
	MC ₁	T ₁ T ₂ T _W T _W T ₃	Next op-code Address (PC)		1	1	1	1	1	1	0
	MC ₂	Ti		Z	1	1	1	1	1	1	1
INT ₁ INT ₂	MC ₃	T ₁ T ₂ T ₃	SP-1	РСН	1	0	0	1	1	1	1
Internal Interrupts	MC ₄	T ₁ T ₂ T ₃	SP-2	PCL	1	0	0	1	1	1	1
	MC ₅	T ₁ T ₂ T ₃	I, Vector	DATA	0	1	0	1	1	1	1
	MC ₆	T ₁ T ₂ T ₃	I, Vector+1	DATA	0	1	0	1	1	1	1



23 REQUEST ACCEPTANCES IN EACH OPERATING MODE

SYSTEM STOP mode	Not acceptable	Not acceptable	Not acceptable	Acceptable	Acceptable Return from SYSTEM STOP mode to normal operation.	Not acceptable	Acceptable Return from SYSTEM STOP mode to normal operation.
SLEEP mode	Not acceptable	Not acceptable	Not acceptable	Acceptable	Acceptable Return from SLEEP mode to normal operation.	←	, <u>-</u>
BUS RELEASE mode	Not acceptable	Not acceptable	Accentable * After BUS RELEASE cycle, DMA cycle begins at the end of one MC.	Continue BUS RELEASE mode.	Not acceptable	-	-
DMA Cycle	Acceptable	Refresh cycle begins at the end of MC.	Acceptable Refer to "2.9 DMA Controller" for details.	Bus is released at the end of MC.	Not acceptable	ı	Acceptable DMA cycle stops.
Interrupt Acknowledge Cycle	Acceptable	Refresh cycle begins at the end of MC.	Acceptable DMA cycle begins at the end of MC.	Bus is released at the end of MC.	Not acceptable	←	Not acceptable Interrupt acknowledge cycle precedes. NIMI is accepted after executing the next instruction.
Refresh Cycle	Not acceptable	Not acceptable	Acceptable * Refresh cycle precedes. DMA cycle begins at the end of one MC.	Not acceptable	Not acceptable	-	-
WAIT State	Acceptable	Not acceptable	DMA cycle begins at the end of MC.	Not acceptable	Accepted after executing the current instruction	-	-
Normal Operation (CPU mode) (IOSTOP mode)	Acceptable	Refresh cycle begins at the end of MC.	DMA cycle begins at the end of MC.	Bus is released at the end of MC.	Accepted after executing the current instruction.	-	-
Current		Refresh Request (Request of Refresh by the on-chip Refresh Controller)			INT ₀ , INT ₁ ,	Internal I/O Interrupt	NMI
Request	WAIT	Refresh Request (Request of Refresh by the on- Refresh Controller)	DREQ.	BUSREQ	Interrupt		

NOTE) • : not acceptable when DMA Request is in level sense.

| : same as the above
MC : Machine Cycle

24 REQUEST PRIORITY

The HD64180 has the following three types of requests.

Type 1.

Type 2.

To be accepted in each machine cycle..... Refresh Req. DMA Reg.

Bus Reg.

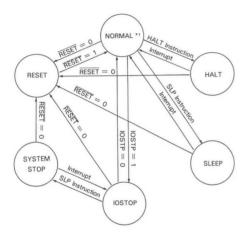
To be accepted in each instruction...... Interrupt Req.

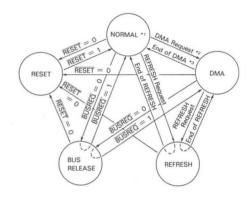
Type 1, Type 2, and Type 3 requests priority is shown as follows. highest priority Type 1 > Type 2 > Type 3 lowest priority Each request priority in Type 2 is shown as follows.

highest priority Bus Req. > Refresh Req. > DMA Req. lowest priority

(NOTE) If Bus Req. and Refresh Req. occurs simultaneously, Bus Req. is accepted but Refresh Req. is cleared. Refer to "2.7 Interrupts" for each request priority in Type 3.

25 OPERATION MODE TRANSITION





NOTE) *1 NORMAL: CPU executes instructions normally in NORMAL mode.

DMA request: DMA is requested in the following cases.

(1) DREQ₀, DREQ₁ = 0 (memory ← → (memory mapped) I/O DMA transfer)

(2) DEO = 1 (memory ←→→ memory DMA transfer)

*3 DMA end: DMA ends in the following cases.

(1) DREQ₀, DREQ₁ = 1 (memory ←→→ (memory mapped) I/O DMA transfer)

(2) BCRO, BCR1 = 0000H (all DMA transfers)

(3) NMI = 0 (all DMA transfers)

Other operation mode transitions

1. HALT

The following operation mode transitions are also possible. (DMA

REFRESH BUS RELEASE IOSTOP _____ REFRESH BUS RELEASE

SLEEP BUS RELEASE

SYSTEM STOP - BUS RELEASE

26 STATUS SIGNALSThe following table shows pin outputs in each operating mode.

	Mode	LIR	ME	ĪŌĒ	RD	WR	REF	HALT	BUSACK	ST	Address BUS	Data BUS
	Op-code Fetch (1st op-code)	0	0	1	0	1	1	1	1	0	А	IN
op.,	Op-code Fetch (except 1st op-code)	0	0	1	0	1	1	1	1	1	А	IN
CPU operation	Memory Read	1	0	1	0	1	1	1	1	1	А	IN
operation	Memory Write	1	0	1	1	0	1	1	1	1	А	OUT
	I/O Read	1	1	0	0	1	1	1	1	1	А	IN
	I/O Write	1	1	0	1	0	1	1	1	1	А	OUT
	Internal Operation	1	1	1	1	1	1	1	1	1	А	IN
Refresh		1	0	1	1	1	0	- 1	1		А	IN
Interrupt	NMI	0	0	1	0	1	1	1	1	0	А	IN
Acknowledge	ĪNT ₀	0	1	0	1	1	1	1	1	0	А	IN
Cycle (1st machine cycle)	INT ₁ , INT ₂ & Internal Interrupts	1	1	1	1	1	1	1	1	0	А	IN
BUS RELEAS	SE	1	Z	Z	Z	Z	1	1	0		Z	IN
HALT		0	0	1	0	1	1	0	1	0	А	IN
SLEEP		1	1	1	1	1	1	0	1	1	1	IN
	Memory Read	1	0	1	0	1	1	1	1	0	Α	IN
Internal	Memory Write	1	0	1	1	0	1	1	1	0	Α	OUT
DMA	I/O Read	1	1	0	0	1	1	1	1	0	Α	IN
	I/O Write	1	1	0	1	0	1	1	1	0	А	OUT
RESET	<u> </u>	1	1	1	1	1	1	1	1	1	Z	IN

NOTE) 1 : HIGH

: LOW 0

A : Programmable

Z : High Impedance IN : Input OUT : Output : Invalid

27 PIN STATUS DURING RESET AND LOW POWER OPERATION MODES

Pin No.	Symbol	Pin function	RESET	Pin status in each SLEEP	IOSTOP	SYSTEM STOR
4	WAIT	_	IN (N)	IN (N)	IN (A)	IN (N)
5	BUSACK		1	OUT	OUT	OUT
6	BUSREQ		IN (N)	IN (A)	IN (A)	IN (A)
7	RESET		0	IN (A)	IN (A)	IN (A)
8	NMI		IN (N)	IN (A)	IN (A)	IN (A)
9	INTo		IN (N)	IN (A)	IN (A)	IN (A)
10	INT ₁		IN (N)	IN (A)	IN (A)	
	INT ₂					IN (A)
11	ST ST	_	IN (N)	IN (A)	IN (A)	IN (A)
12		-		1	OUT	1
3~30	A0~A17	-	Z	1	Α	1
31	A 1 d/TOUT	A1a	Z	1	A	1
		TOUT	Z	OUT	Н	Н
84~41	Do~D7	-	Z	Z	A	Z
42	RTSo		1	Н	OUT	Н
43	CTSo		IN (N)	IN (A)	IN (N)	IN (N)
44	DCD ₀	_	IN (N)	IN (A)	IN (N)	IN (N)
45	TXAo		1	OUT	н	Н
46	RXA ₀		IN (N)	IN (A)	IN (N)	IN (N)
47	CKA ₀ /DREQ ₀	CKA ₀ (internal clock mode)	Z	OUT	Z	Z
		CKAo (external clock mode)	Z	IN (A)	IN (N)	IN (N)
		DREQo	Z	IN (N)	IN (A)	IN (N)
48	TXA ₁	-	1	OUT	Н	Н
49	RXA ₁	-	IN (N)	IN (A)	IN (N)	IN (N)
50	CKA ₁ /TEND ₀	CKA ₁ (internal clock mode)	Z	OUT	Z	Z
		CKA ₁ (external clock mode)	Z	IN (A)	IN (N)	IN (N)
		TEND ₀	Z	1	OUT	1
51	TXS	-	1	OUT	Н	Н
52	RXS/CTS ₁	RXS	IN (N)	IN (A)	IN (N)	IN (N)
		CTS ₁	IN (N)	IN (A)	IN (N)	IN (N)
53	CKS	CKS (internal clock mode)	Z	OUT	1	1
		CKS (external clock mode)	Z	IN (A)	Z	Z
54	DREQ ₁	-	IN (N)	IN (N)	IN (A)	IN (N)
55	TEND ₁	-	1	1	OUT	1
56	HALT	_	1	0	OUT	0
57	REF	_	1	1	OUT	1
58	ĪŌĒ	-	1	1	OUT	1
59	ME	-	1	1	OUT	1
60	E	-	0	E clock output	-	-
61	LIR	-	1	1	OUT	1
62	WR	_	1	1	OUT	1
63	RD		1	1	OUT	1
64	φ	_	φ clock output	-	-	-

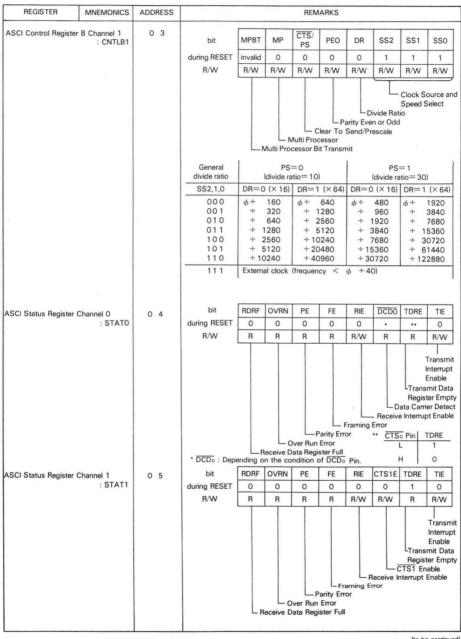
^{1:} HIGH 0: LOW A: Programmable Z: High Impedance IN (A): Input (Active) IN (N): Input (Not active) OUT: Output H: Holds the previous state : same as the left

28 INTERNAL I/O REGISTERS

By programming IOA7 and IOA6 in the I/O control register, in-

ternal I/O register addresses are relocatable within ranges from 0000H to 00FFH in the I/O address space.

REGISTER	MNEMONICS	ADDRESS				REM	MARKS				
ASCI Control Registe	r A Channel 0 : CNTLA0	0 0	bit	MPE	RE	TE	RTSO	MPBR/ EFR	MOD2	MOD1	MODO
			during RESET	0	0	0	1	invalid	0	0	0
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ASSI Souted Business	A ()				Multi Pr	Receive	Transmit Enable	Erro equest T	or Flag F	ssor Bit	Selection Receive/
ASCI Control Registe	: CNTLA1	0 1	bit	MPE	RE	TE	CKA1D	MPBR/ EFR	MOD2	MOD1	MODO
			during RESET	0	0	0	1	invalid	0	0	0
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
			MOD2, 1, 0		/lulti Pro	cessor E	ransmit nable nable	En CKA1 Dis	ror Flag		t Receive.
			0 0 0 0 0 1 0 1 0 0 1 1 1 0 0 1 0 1 1 1 1 0 1 1 1	Start + Start + Start + Start +	7 bit Di 7 bit Di 7 bit Di 8 bit Di 8 bit Di 8 bit Di	ata + 2 ata + P ata + P ata + 1 ata + 2 ata + P	Stop arity + arity + Stop	2 Stop 1 Stop			
ASCI Control Registe	r B Channel 0 ; CNTLBO	0 2	bit	MPBT	MP	CTS/ PS	PEO	DR	SS2	SS1	SSO
			during RESET	invalid	0		0	0	1	1	1
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
			• CTS : Dep PS : Clea	ending o	ulti Prod	Multi Pro essor Bi	lear To S ocessor it Transn	arity Eve Send/Pre	S Divide Ra en or Od	Speed Seatio	ource and elect



REGISTER	MNEMONICS	ADDF	RESS			-	REM	ARKS				
ASCI Transmit Data R	legister Channel	0	6									
0	: TDRO											
ASCI Transmit Data R	legister Channel	0	7									
	: TDR1											
ASCI Receive Data Re	gister Channel	0	8									
0	: TSRO											
ASCI Receive Data Re	gister Channel	0	9									
1	: TSR1											
001/0 0												
CSI/O Control Registe	: CNTR	0	А	bit	EF	EIE	RE	TE	-	SS2	SS1	SSO 1
				during RESET	O R	0 R/W	0 R/W	0 R/W	1	1 R/W	1 R/W	R/W
				n/vv	<u> </u>	1000	1000	1000		10.00	Υ	
							3.	_		a a b l a	Spee	d Select
								ceive En		nable		
					LEn	∟En id Flag	d Intern	upt Enab	ole			
					S2,1,0	l Re	ud Rate	. .	SS2,1,0	l Ra	aud Rate	
					000	_	÷ 20		100	_	+ 320	-
					001		÷ 40 ÷ 80		101		÷ 640 ÷ 1280	
					011		÷160	1	111	Exte	emal	
CSI/O Transmit/Receiv	e Data	0	R							(frec	quency <	< ÷ 20)
Register												
	: TRDR											
Timer Data Register Cl	hannel OL : TMDROL	0	С									
Timer Data Register Cl		0	D									
Timor Buta Hogister Of	: TMDROH											
Timer Reload Register		0	E									
	: RLDROL											
Timer Reload Register	Channel OH : RLDROH	0	F									
			0									
Timer Control Register	: TCR	1	U	bit	TIF1	TIFO	TIE1	TIEO	TOC1	TOCO 0	TDE1	TDEO
				during RESET	O R	0 R	0 R/W	0 R/W	R/W	R/W	0 R/W	0 R/W
				11/ 44	<u></u>							
											L _{Tim}	er Down nable 1,0
						W.		T'		Timer O	utput Co	ontrol 1,0
						Timer	Interrupt			Enable	1,0	
				_	TOC1		A 18/T0					
						00	Inhibit Togg					
					1	0	0					
					,	, 1	1					
											(to t	pe continued)



REGISTER	MNEMONICS	ADDRE	ESS		REMARKS	_
Timer Data Register Ch	nannel 1L : TMDR1L	1 4	4			,
Timer Data Register Ch	nannel 1H : TMDR1H	1 5	5			
Timer Reload Register	Channel 1L : RLDR1L	1 6	6			
Timer Reload Register	Channel 1H : RLDR1H	1 7	7			
Free Running Counter		1 8	8	read only		
	: FRC					
DMA Source Address Channel OL	Register : SAROL	2 (0			
DMA Source Address	Register	2 1	1			
Channel OH	: SAROH					
DMA Source Address Channel OB		2 2	2	Bits 0-2 are used for SAROB. A18, A17, A16 X 0 0	DMA Transfer Request DREQo (external) RDRO (ASCIO)	
DMA Destination Addre	ss Register	2 3		X 0 1 X 1 0 X 1 1	RDR1 (ASCII) Not Used	
Criamiei OL	: DAROL					
DMA Destination Addre Channel OH	ess Register : DAROH	2 4				
DMA Destination Addre	ss Register	2 5	i	Bits 0-2 are used for DAROB.		
Channel OB	: DAROB			A ₁₈ , A ₁₇ , A ₁₆ X O O	DMA Transfer Request DREQo (external)	
DMA Byte Count Regis OL	ter Channel	2 6	3	X 0 1 X 1 0 X 1 1	TDR0 (ASCI0) TDR1 (ASCI1) Not Used	
DMA Byte Count Regis OH	ter Channel : BCROH	2 7	,			
DMA Memory Address Channel 1L	Register : MAR1L	2 8	3			
DMA Memory Address Channel 1H		2 9	9			
DMA Memory Address Channel 1B	Register	2 /	A	Bits 0-2 are used for MAR1B.		
	: MAR1B					
DMA I/O Address Regi 1L	ster Channel : IAR1L	2 8	В			
DMA I/O Address Reg	ster Channel	2 (С			

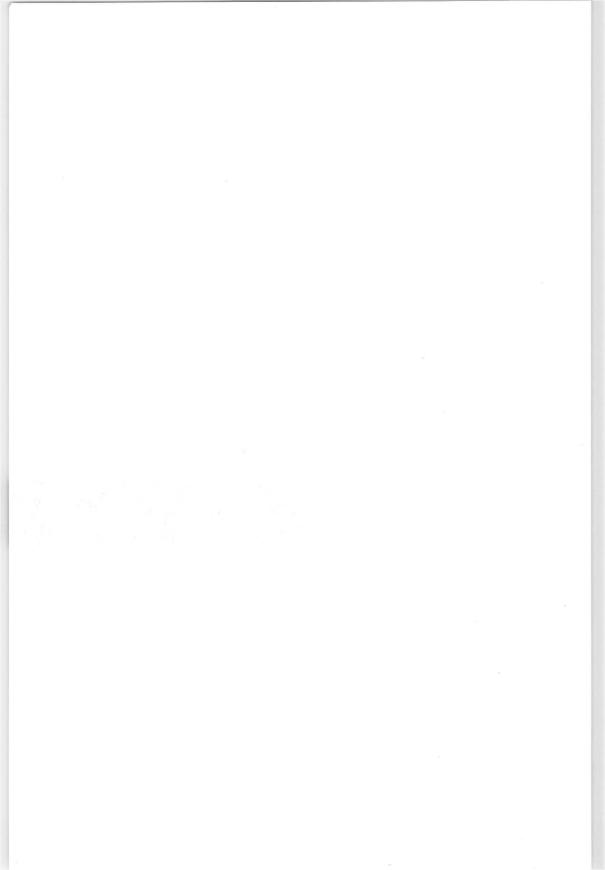


REGISTER	MNEMONICS	ADD	RESS				REM	IARKS				
DMA Byte Count Regis	ster Channel	2	Е		300							
1L	: BCR1L											
DMA Byte Count Regi	ster Channel	2	F	Í								
1Н	: BCR1H											
DMA Status Register		3	0	bit	DE1	DEO	DWE1	DWEO	DIE1	DIEO	_	DME
	: DSTAT			during RE	SET 0	0	1	1	0	0	1	0
				R/W	R/W	R/W	W	W	R/W	R/W		R
						DN	∕IA Enabl		Enable E		errupt En e Enable	
DMA Mode Register		3	1				_					
DMA Mode Register	: DMODE	3	1	bit	_	_	DM1	DMO	SM1	SMO	MMOD	_
DMA Mode Register	: DMODE	3	1	during RE	_	1	0	0	0	0	0	1
DMA Mode Register	: DMODE	3	1		_		7.00					
DMA Mode Register	: DMODE	3	1	DM1, 0 0 0 0 1 1	Destination M M M	Address DARO-DARO-DARO	0 R/W	O R/W - Ch O Mode SM1, C	Destinate 1, 0 Source MM M M	Ch Mo	O R/W O Source de 1,0 dress R0+1 R0-1 R0 fixed	1 Memory MODE Select
DMA Mode Register	: DMODE	3	1	during RE R/W	Destination M M	Address DARO-DARO-	0 R/W	Ch 0 Mode SM1, 0 0 0	Destinate 1, 0 Source MM M M	Ch Mo	0 R/W 0 Source de 1,0 dress R0+1 R0-1	1 Memory MODE Select

REGISTER	MNEMONICS	ADDRESS	REMARKS										
DMA/WAIT Control F		3 2	bit	MWI1	MWIO	IWI1	IWIO	DMS1	DMS0	DIM1	DIMO		
	: DCNTL		during RESET	1	1	1	1	0	0	0	0		
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W		
					— Mer	mory Wa		Vait Inse		I/O Mo	Memory de Select , i = 1,0		
			MWI1,0		umber o		VI1,0		umber o	f			
			0.0		0		00		0				
			01		1		01		2				
			11		3		11		4				
				Sense Ige sense									
			DIM1,0	Transfe	er Mode	Add	lress Inc	rement/	Decreme	nt			
			00		→I/O →I/O		R1+1 R1-1		R1 fixed R1 fixed				
			10	1/0	D→M	IAR	1 fixed	MA	AR1+1				
			1 1	1/0	O→M	IAR	1 fixed	MA	AR1 — 1				
Interrupt Vector Low	Register : IL	3 3	bit	IL7	IL6	IL5	_	_	_	_	_		
	. 12		during RESET	0	0	0	0	0	0	0	0		
			R/W	R/W	R/W	R/W							
					L _{In}	terrupt \	ector L	ow					
INT/TRAP Control Re	aister	3 4	bit	TRAP	UFO	T -	_	Ι_	ITE2	ITE1	ITEO		
	: ITC		during RESET	0	0	1	1	1	0	0	1		
			R/W	R/W	R				R/W	R/W	R/W		
				L	RAP	ndefined	d Fetch	Object		-INT Ena	able 2,1,		
Refresh Control Regis	ter : RCR	3 6	bit	REFE	REFW	-	_	_	_	CYC1	CYCO		
	HCH		during RESET	1	1	1	1	1	1	0	0		
			R/W	R/W	R/W					R/W	R/W		
				LRe	Refresh En	efresh W	/ait Stat	9		Cyc	cle Selec		
			CYC1,0	Inter	val of R	efresh C	ycle						
						0 States	s						
			10										
		1	11	1	0	10							

REGISTER	MNEMONICS	ADDRESS				REM	ARKS				
MMU Common Base	Register : CBR	3 8	bit	_	СВ6	CB5	CB4	СВЗ	CB2	CB1	СВО
	. CBR		during RESET	0	0	0	0	0	0	0	0
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
							Γ,	ими Са	mmon	Base Reg	gister
MMU Bank Base Regis	ster : BBR	3 9	bit	-	BB6	BB5	BB4	BB3	BB2	BB1	BBO
	. DDIT		during RESET	0	0	0	0	0	0	0	0
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
									MMU Ba	ink Base	Register
MMU Common/Bank	Area Register : CBAR	3 A	bit	CA3	CA2	CA1	CA0	ваз	BA2	BA1	BAO
			during RESET	1	1	1	1	0	0	0	0
			R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
NO Control Basista		3 F					IU Com	100000000000000000000000000000000000000			Bank Register
I/O Control Register	: ICR	3 F	bit	IOA7	IOA6	IOSTP	-	-	_	_	_
			during RESET	0	0	0	1	1	1	1	1
			R/W	R/W	R/W	R/W					
					-1/O Ad) Stop				

16-BIT MICROPROCESSOR



HD68000/HD68HC000 MPU (Micro Processing Unit)

- HD68000 -

The HD68000 is the first in a family of advanced microprocessors from Hitachi, Utilizing VLSI technology, the HD68000 is a fully-implemented 16-bit microprocessor with 32-bit registers, a rich basic instruction set, and versatile addressing

The HD68000 possesses an asynchronous bus structure with a 24-bit address bus and a 16-bit data bus.

FEATURES

- 32-Bit Data and Address Registers
- 16 Megabyte Direct Addressing Range
- 56 Powerful Instruction Types
- Operations of Five Main Data Types
- Memory Mapped I/O
- 14 Addressing Modes

- HD68HC000 -

The HD68HC000 is a 16-bit microprocessor of HMCS68000 family, which is exactly compatible with the conventional

The HD68HC000 is a complete CMOS device and the power dissipation is extremely low.

FEATURES

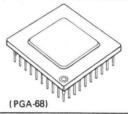
- Instruction Compatible with NMOS HD68000
- Pin Compatible with NMOS HD68000
- AC Timing Compatible with NMOS HD68000
- Low Power Dissipation (I_{CC} typ = 20 mA, I_{CC} max =35 mA at f = 12.5 MHz

The specifications for HD68HC000 are preliminary.

HD68000-6.HD68000-8. HD68000-10.HD68000-12 HD68HC000-8, HD68HC000-10, HD68HC000-12

(DC-64)

HD68000Y6, HD68000Y8, HD68000Y10, HD68000Y12 HD68HC000Y8, HD68HC000Y10, HD68HC000Y12



HD68000P6, HD68000P8

HD68HC000P8, HD68HC000P10, HD68HC000P12



(DP-64)

HD68000PS6, HD68000PS8 HD68HC000PS8, HD68HC000PS10, HD68HC000PS12



(DP-64S)

HD68000CP6 HD68000CP8 HD68HC000CP8, HD68HC000CP10, HD68HC000CP12



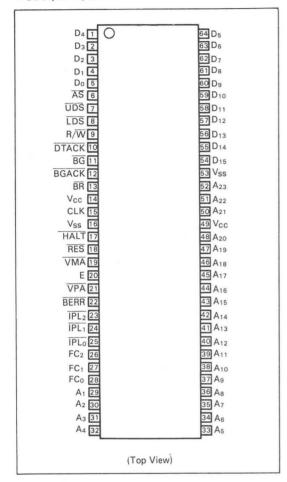
HD68000/HD68HC000-----

■ TYPE OF PRODUCTS

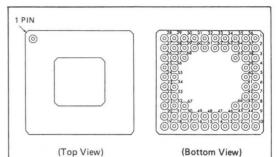
Type No.	Process	Clock Frequency (MHz)	Package
HD68000-6		6.0	
HD68000-8		8.0	DC-64
HD68000-10		10.0	DC-04
HD68000-12		12.5	
HD68000Y6		6.0	
HD68000Y8		8.0	PGA-68
HD68000Y10	NIMOO	10.0	PGA-00
HD68000Y12	NMOS	12.5	
HD68000P6		6.0	DD 04
HD68000P8		8.0	DP-64
HD68000PS6		6.0	DD C4C
HD68000PS8		8.0	DP-64S
HD68000CP6		6.0	CP-68
HD68000CP8		8.0	CF-00
HD68HC000-8		8.0	·
HD68HC000-10		10.0	DC-64
HD68HC000-12		12.5	DC-04
HD68HC000Y8		8.0	
HD68HC000Y10		10.0	PGA-68
HD68HC000Y12		12.5	
HD68HC000P8		8.0	
HD68HC000P10	CMOS	10.0	DP-64
HD68HC000P12		12.5	
HD68HC000PS8		8.0	
HD68HC000PS10		10.0	DP-64S
HD68HC000PS12		12.5	
HD68HC000CP8		8.0	
HD68HC000CP10		10.0	CP-68
HD68HC000CP12		12.5	

(Note) HD68000 refers to the NMOS version 68000, and HD68HC000 refers to the CMOS version 68000. 68000 stands for NMOS and CMOS version.

- PIN ARRANGEMENT
- DC-64, DP-64, DP-64S

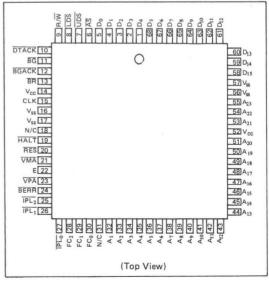


PGA-68



Pin No.	Function	Pin No.	Function	Pin No.	Function	Pin No.	Function
1	N/C	18	A9	35	D ₁	52	A ₁₂
2	DTACK	19	N/C	36	ĀS	53	A15
3	BGACK	20	A ₁₄	37	LDS	54	A ₁₈
4	BR	21	A ₁₆	38	BG	55	Vcc
5	CLK	22	A ₁₇	39	Vcc	56	Vss
6	HALT	23	A19	40	Vss	57	A23
7	VMA	24	A ₂₀	41	RES	58	D ₁₄
8	E	25	A21	42	VPA	59	DII
9	BERR	26	A22	43	IPL ₂	60	D ₉
10	N/C	27	Dis	44	IPLo	61	D ₆
11	FC ₂	28	D ₁₂	45	FC ₁	62	D ₃
12	FC _o	29	D ₁₀	46	N/C	63	Do
13	Aı	30	D ₈	47	A ₂	64	UDS
14	A ₃	31	D ₂	48	As	65	R/W
15	A ₄	32	Ds	49	As	66	IPL
16	A ₆	33	D ₄	50	A ₁₀	67	A ₁₃
17	A ₇	34	D ₂	51	A11	68	D ₁₃

• CP-68



■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	HD68000	HD68HC000	Unit
rtem	Symbol	Value	Value	Onit
Supply Voltage	Vcc*	-0.3 ~ +7.0	-0.3 ∼ +6.5	V
Input Voltage	V _{in} *	-0.3 ~ +7.0	−0.3 ~ +6.5	V
Operating Temperature Range	T _{opr}	0~+70	0~+70	°C
Storage Temperature	T _{stg}	−55 ~ +150	−55 ~ +150	°C

^{*}With respect to VSS (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

Since the HD68HC000 is a C-MOS device, users are expected to be cautious on "latch-up" problem caused by voltage fracturations.

■ RECOMMENDED OPERATING CONDITIONS

les	em	Combal		HD68000		H	D68HC00	00	Unit
116	2111	Symbol	min	typ	max	min	typ	max	Onit
Supply Voltage		V _{CC} *	4.75	5.0	5.25	4.75	5.0	5.25	V
	CLK	*	2.0		1/	2.8	_	Vcc	V
Input Voltage	Other Inputs	VIH*	2.0	_	Vcc	2.0	_	Vcc	٧
	All Inputs	V _{IL} *	-0.3	-	0.8	-0.3	_	0.8	V
Operating Temper	rature	T _{opr}	0	25	70	0	25	70	°C

^{*} With respect to VSS (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

• DC CHARACTERISTICS (V_{CC} = 5V \pm 5%, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, Fig. 1, unless otherwise noted.)

	Item	Symbol	Test Condition	HD68	3000	HD68H	IC000	Unit
	rtem	Зуптьог	Test Condition	min	max	min	max	Onit
	CLK	.,		0.0	.,	2.8	Vcc	
Input "High" Voltage	Other Inputs	VIH		2.0	Vcc	2.0	Vcc	V
Input "Low" Voltage		VIL		V _{SS} -0.3	0.8	V _{SS} -0.3	0.8	V
Lance Lankson Commons	$\frac{\text{BERR, BGACK, BR, DTACK,}}{\text{IPL}_0} \sim \frac{\text{IPL}_2}{\text{VPA, CLK}}$	1	@ 5.25V	_	2.5	_	2.5	
Input Leakage Current	HALT, RES	lin	@ 5.25V	_	20	_	20	μА
Three-State (Off State) Input Current	$\begin{split} \overline{AS}, A_1 &\sim A_{23}, D_0 \sim D_{15}, \\ \overline{FC_0} &\sim \overline{FC_2}, \overline{LDS}, R/\overline{W}, \overline{UDS}, \\ \overline{VMA} \end{split}$	I _{TSI}	@ 2.4V/0.4V	-	20	-	20	μА
Output "High" Voltage	$\begin{array}{l} \overline{AS}, A_1 \sim A_{23}, \overline{BG}, D_0 \sim D_{15},\\ FC_0 \sim FC_2, \overline{LDS}, R/\overline{W}, \overline{UDS},\\ \overline{VMA}, E \end{array}$	V _{OH}	I _{OH} = -400μA	2.4	-	V _{CC} -0.75	-	V
	E*			V _{CC} -0.75	-			
	HALT		I _{OL} =1.6 mA	-	0.5	_	0.5	
Output "Low" Voltage	$A_1 \sim A_{23}$, \overline{BG} , $FC_0 \sim FC_2$	VoL	I _{OL} =3.2 mA	-	0.5	-	0.5	
Output Low Voltage	RES	VOL	I _{OL} =5.0 mA	_	0.5	_	0.5	V
	\overline{AS} , $D_0 \sim D_{15}$, \overline{LDS} , R/\overline{W} , E, \overline{UDS} , \overline{VMA}		I _{OL} =5.3 mA	-	0.5	-	0.5	
Power Dissipation	CERAMIC PACKAGE		f = 6 MHz f = 8 MHz f = 10 MHz	-	1.5			
Power Dissipation		PD	f = 12.5 MHz	-	1.75	_	-	W
	PLASTIC PACKAGE		f = 8 MHz, V _{CC} = 5V, Ta = 25°C	-	0.9			
			f = 8 MHz	_	_	_	25	
Current Dissipation		ID**	f = 10 MHz	_	_	_	30	mA
			f = 12.5 MHz	_	-	_	35	
Capacitance (Package T	ype Dependent)	C _{in}	V _{in} = 0V, Ta = 25°C, f = 1 MHz	-	20.0	_	20.0	pF

^{*}With external pull up resistor of 1.1 k Ω .

^{**}Without load.

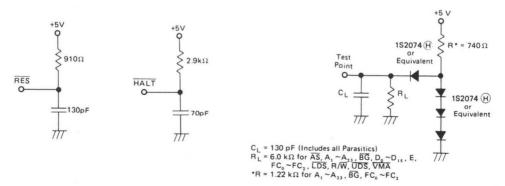
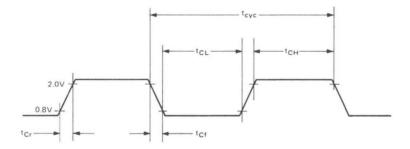


Figure 1 Test Loads

• AC CHARACTERISTICS (V_{CC} = 5V \pm 5%, V_{SS} = 0V, Ta = 0 \sim +70 $^{\circ}$ C, unless otherwise noted.)

CLOCK TIMING

laces	Cumbal	Test Condition	6 N	ИHz	8 1	ИHz	10	MHz	12.5	MHz	Unit
Item	Symbol	rest Condition	min	max	min	max	min	max	min	max	Offit
Frequency of Operation	f		4.0	6.0	4.0	8.0	4.0	10.0	4.0	12.5	MHz
Cycle Time	t _{cyc}		167	250	125	250	100	250	80	250	ns
	t _{CL}	Fig. 2	75	125	55	125	45	125	35	125	ns
Clock Pulse Width	t _{CH}		75	125	55	125	45	125	35	125	ns
5:	t _{Cr}		_	10	_	10	_	10		5	ns
Rise and Fall Times	tCf		-	10	-	10	-	10	-	5	ns



(NOTE)

Timing measurements are referenced to and from a low voltage of 0.8 volt and high a voltage of 2.0 volts, unless otherwise noted.

The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between 0.8 volt and 2.0 volts.

Figure 2 Clock Input Timing

READ AND WRITE CYCLES

Ni	ler	Cumbal	Test		1Hz	8 N	1Hz	10	ИНz	12.5	MHz	Unit
Num.	Item	Symbol	Condition		max	min	max	min	max	min	max	Unit
1	Clock Period	t _{cyc}		167	250	125	250	100	250	80	250	ns
2	Clock Width Low	tcL		75	125	55	125	45	125	35	125	ns
3	Clock Width High	tcH		75	125	55	125	45	125	35	125	ns
4	Clock Fall Time	tcf		_	10	_	10	-	10	-	5	ns
5	Clock Rise Time	tcr		_	10	-	10	_	10	-	5	ns
6	Clock Low to Address Valid	tCLAV		_	80	-	70	-	60	_	55*	ns
6A	Clock High to FC Valid	tCHFCV		_	80	_	70	_	60	-	55	ns
7	Clock High to Address, Data Bus High Impedance (Maximum)	tCHADZ		_	100	_	80	_	70	_	60	ns
8	Clock High to Address, FC Invalid (Minimum)	t _{CHAFI}		0	_	0	_	0	_	0	_	ns
91	Clock High to AS, DS Low	tcHSL		0	70	0	60	0	55	0	55	ns
112	Address Valid to \overline{AS} , \overline{DS} Low (Read)/ \overline{AS} Low (Write)	t _{AVSL}		35	-	30	_	20	_	0	-	ns
11A ²	FC Valid to \overline{AS} , \overline{DS} Low (Read)/ \overline{AS} Low (Write)	tFCVSL		70	_	60	-	50	_	40	_	ns
12 ¹	Clock Low to AS, DS High	tCLSH	Fig. 3,	_	80	_	70	_	55	-	50	ns
13 ²	AS, DS High to Address/FC Invalid	tSHAFI	Fig. 4	40	-	30	-	20	_	10	-	ns
14 ²	AS, DS Width Low (Read)/AS Low (Write)	t _{SL}		337	_	240	-	195	-	160	-	ns
14A ²	DS Width Low (Write)	t _{DSL}		170	_	115	_	95	-	80	_	ns
15 ²	AS, DS Width High	t _{SH}		180	_	150	_	105	_	65	-	ns
16	Clock High to Control Bus High Impedance	tchcz	1	_	100	_	80	_	70	_	60	ns
17 ²	AS, DS High to R/W High (Read)	tshrh		50	_	40	_	20	1-	10	_	ns
18 ¹	Clock High to R/W High	t _{CHRH}		0	80	0	70	0	60	0	60	ns
201	Clock High to R/W Low (Write)	tCHRL		-	80	-	70	-	60	-	60	ns
20A ⁶	AS Low to R/W Valid (Write)	tASRV		-	20	-	20	_	20	-	20	ns
212	Address Valid to R/W Low (Write)	tAVRL		25	-	20	-	0	-	0	-	ns
21A ²	FC Valid to R/W Low (Write)	tFCVRL		70	-	60	-	50	_	30	-	ns
222	R/W Low to DS Low (Write)	tRLSL		140	_	80	\ <u>-</u>	50	_	30	_	ns
23	Clock Low to Data Out Valid (Write)	t _{CLDO}		_	80	_	70	_	55	_	55	ns
25 ²	AS, DS High to Data Out Invalid (Write)	†SHD01		40	_	30	_	20	_	15	-	ns
26 ²	Data Out Valid to DS Low (Write)	tDOSL		35	_	30	-	20	_	15	_	ns
27 ⁵	Data In to Clock Low (Setup Time on Read)	†DICL		25	_	15	_	10	_	10	_	ns
28 ²	AS, DS High to DTACK High	tshdah		0	325	0	245	0	190	0	150	ns
29	AS, DS High to Data In Invalid (Hold Time on Read)	t _{SHDII}		0	_	0	-	0	-	0	_	ns
30	AS, DS High to BERR High	tSHBEH		0	_	0	_	0	_	0	-	ns
31 ^{2, 5}	DTACK Low to Data In (Setup Time)	tDALDI		_	120	-	90	-	65	_	50	ns
32	HALT and RESET Input Transition Time	t _{RHr} , f		0	200	0	200	0	200	0	200	ns
33	Clock High to BG Low	tCHGL		_	80	_	70	_	60	_	50	ns
34	Clock High to BG High	tchgh		-	80	-	70	-	60	-	50	n
35	BR Low to BG Low	tBRLGL		1.5	100 ns +3.5	1.5	90 ns +3.5	1.5	80 ns +3.5	1.5	70 ns +3.5	CIk Per

^{* 57} for HD68HC000

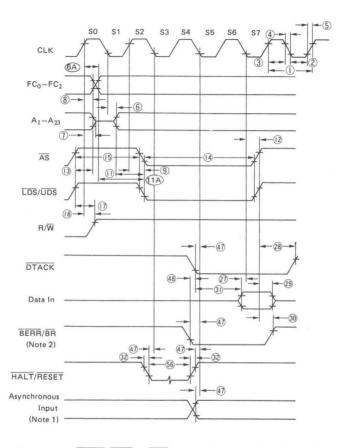
READ AND WRITE CYCLES (CONTINUED)

			Test	6	MHz	8	MHz	10	MHz	12.	5 MHz	11.
Num.	Item	Symbol	Condition	min	max	min	max	min	max	min	max	Unit
36 ⁷	BR High to BG High	†BRHGH		1.5	100 ns +3.5	1.5	90 ns +3.5	1.5	80 ns +3.5	1.5	70 ns +3.5	Clk.Per.
37	BGACK Low to BG High	^t GALGH		1.5	100 ns +3.5	1.5	90 ns +3.5	1.5	80 ns +3.5	1.5	70 ns +3.5	Clk.Per.
37A ⁸	BGACK Low to BR High	[†] GALBRH		20	1.5 Clocks	20	1.5 Clocks	20	1.5 Clocks	20	1.5 Clocks	ns
38	BG Low to Control, Address, Data Bus High Impedance (AS High)	t _{GLZ}	*	_	100	_	80	_	70	_	60	ns
39	BG Width High	^t GH		1.5	-	1.5	_	1.5	_	1.5	_	Clk.Per.
40	Clock Low to VMA Low	tCLVML		_	80	_	70	-	70	1-1	70	ns
41	Clock Low to E Transition	tCLET		_	85	_	70	-	55	-	45	ns
42	E Output Rise and Fall Time	t _{Er} , f		-	25	-	25	_	25	_	25	ns
43	VMA Low to E High	t _{VMLEH}		240	-	200	-	150	_	90	-	ns
44	AS, DS High to VPA High	[†] SHVPH	Fig. 3,	0	160	0	120	0	90	0	70	ns
45	E Low to Control, Address Bus Invalid (Address Hold Time)	t _{ELCAI}	Fig. 4	35		30	_	10	_	10	_	ns
46	BGACK Width Low	tGAL		1.5	_	1.5	-	1.5	_	1.5	-	Clk.Per.
47 ⁵	Asynchronous Input Setup Time	t _{ASI}		25	-	20	-	20	-	20	_	ns
483	BERR Low to DTACK Low	†BELDAL		50	_	20	_	20	-	20	_	ns
49 ⁹	AS, DS High to E Low	tSHEL		-80	-	-70	70	-55	55	-45	45	ns
50	E Width High	t _{EH}		600	-	450	-	350	_	280	_	ns
51	E Width Low	teL		900	-	700	_	550	-	440	_	ns
53	Clock High to Data Out Invalid	[‡] CHDOI		0	-	0	-	0	-	0	_	ns
54	E Low to Data Out Invalid	t _{ELDOI}		40	-	30	-	20	-	15	-	ns
55	R/W to Data Bus Driven	tRLDBD		35	_	30	_	20	_	10	_	ns
564	HALT/RESET Pulse Width	tHRPW		10	_	10	_	10	_	10	_	Clk.Per.
57	BGACK High to Control Bus Driven	tGABD		1.5	_	1.5	-	1.5	-	1.5	-	Clk.Per.
58 ⁷	BG High to Control Bus Driven	tGHBD		1.5	_	1.5	-	1.5	-	1.5	-	Clk.Per.

- 1. For a loading capacitance of less than or equal to 50 picofarads, substract 5 nanoseconds from the value given in the maximum columns.
- 2. Actual value depends on clock period.
- 3. If #47 is satisfied for both DTACK and BERR, #48 may be 0 nanoseconds.
- For power up, the MPU must be held in RES state for 100 ms to allow stabilization of on-chip circuitry. After the system is powered up, #56 refers to the minimum pulse width required to reset the system.
- 5. If the asynchronous setup time (#47) requirements are satisfied, the OTACK low-to-data setup time (#31) requirement can be ignored. The data must only satisfy the date-in clock-low setup time (#27) for the following cycle.
- 6. When $\overline{\rm AS}$ and ${\rm R/W}$ are equally loaded ($\pm 20\%$), subtract 10 nanoseconds from the values given in these columns.
- 7. The processor will negate \overline{BG} and begin driving the bus again if external arbitration logic negates \overline{BR} before asserting \overline{BGACK} .
- 8. The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, BG may be reasserted.
- 9. The falling edge of S6 triggers both the negation of the strobes (AS and xDS) and the falling edge of E. Either of these events can occur first, depending upon the loading on each signal. Specification #49 indicates the absolute maximum skew that will occur between the rising edge of the strobes and the falling edge of the E clock.

These waveforms should only be referenced in regard to the edge-to-edge measurement of the timing specifications. They are not intended as a functional description of the input and

output signals. Refer to other functional descriptions and their related diagrams for device operation.

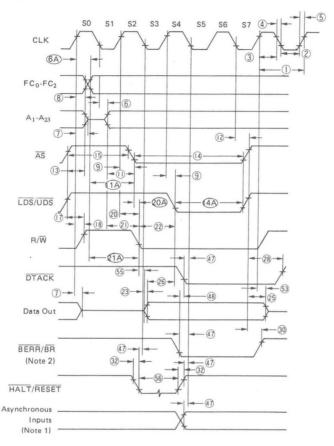


- 1. Setup time for the synchronous inputs \overline{BGACK} , $\overline{IPL_{0-2}}$ and \overline{VPA} guarantees their recognition at the next falling edge of the clock.
- 2. BR need fall at this time only in order to insure being recognized at the end of this bus cycle.
- 3. Timing measurements are referenced to and from a low voltage of 0.8 volt and a high voltage 2.0 volts, unless otherwise noted. The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between 0.8 volt and 2.0 volts.

Figure 3. Read Cycle Timing

These waveforms should only be referenced in regard to the edge-to-edge measurement of the timing specifications. They are not intended as a functional description of the input and output

signals. Refer to other functional descriptions and their related diagrams for device operation.



- Timing measurements are referenced to and from a low voltage of 0.8 volt and a high voltage of 2.0 volts, unless otherwise noted.
 The voltage swing through this range should start outside and pass through the range such that the rise or fall will be linear between
 0.8 volt and 2.0 volts.
- 2. Because of loading variations, R/W may be valid after AS even though both are initiated by the rising edge of S2 (Specification 20A).

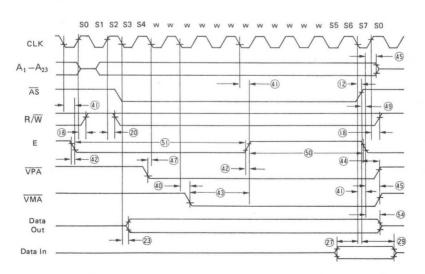
Figure 4. Write Cycle Timing

HMCS6800 TIMING

			Test	6 MHz		8 MHz		10 MHz		12.5 MHz		
Num.	Item	Symbol	Condition	min	max	min	max	min	max	min	max	Unit
12	Clock Low to AS, DS High	†CLSH		_	80	_	70	_	55	_	50	ns
18	Clock High to R/W High	tchrh		0	80	0	70	0	60	0	60	ns
20	Clock High to R/W Low (Write)	tCHRL		_	80	-	70	-	60	-	60	ns
23	Clock Low to Data Out Valid (Write)	tCLDO	1	-	80	-	70	-	55	-	55	ns
27	Data In to Clock Low (Setup Time on Read)	tDICL]	25	-	15	-	10	-	10	-	ns
29	AS, DS High to Data In Invalid (Hold Time on Read)	†SHDII	Fig. 5,	0	_	0	_	0	_	0	_	ns
40	Clock Low to VMA Low	†CLVML	Fig. 6	_	80	_	70	-	70	-	70	ns
41	Clock Low to E Transition	†CLET		_	35	_	70	-	55	-	45	ns
42	E Output Rise and Fall Time	t _{Er, f}			25	-	25	_	25	-	25	ns
43	VMA Low to E High	tVMLEH		240	-	200	-	150	_	90	-	ns
44	AS, DS High to VPA High	[†] SHVPH		0	160	0	120	0	90	0	70	ns
45	E Low to Control, Address Bus Invalid (Address Hold Time)	†ELCAI		35	-	30	-	10	-	10	-	ns
47	Asynchronous Input Setup Time	t _{ASI}	1	25	_	20	_	20	_	20	_	ns
491	AS, DS High to E Low	†SHEL		-80	_	-70	70	-55	55	-45	45	ns
50	E Width High	t _{EH}]	600	_	450	_	350	-	280	-	ns
51	E Width Low	t _{EL}	1	900	-	700	-	550	-	440	-	ns
54	E Low to Data Out Invalid	t _{ELDOI}	1	40	_	30	-	20	-	15	-	ns

NOTE

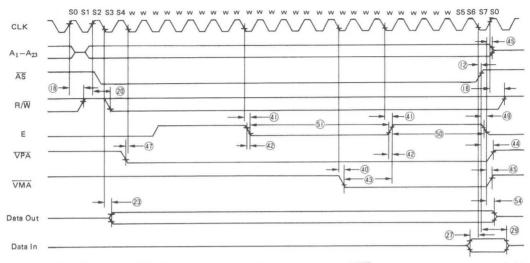
The falling edge of S6 triggers both the negation of the strobes (AS and xDS) and the falling edge of E. Either of these events can occur first, depending upon the loading on each signal. Specification #49 indicates the absolute maximum skew that will occur between the rising edge of the strobes and the falling edge of the E clock.



NOTE: This timing diagram is included for those who wish to design their own circuit to generate VMA. It shows the best case possibly attainable.

Figure 5. HMCS6800 Timing - Best Case





NOTE: This timing diagram is included for those who wish to design their own circuit to generate VMA. It shows the worst case possibly attainable.

Figure 6. HMCS6800 Timing - Worst Case

BUS ARBITRATION

		0 1 1	Test	61	ИНz	8 1	ИHz	10	MHz	12.5	MHz	Unit
Num.	Item	Symbol	Condition	min	max	min	max	min	max	min	max	Unit
7	Clock High to Address, Data Bus High Impedance	tCHADZ		_	100	_	80	_	70	-	60	ns
16	Clock High to Control Bus High Impedance	tchcz		_	100	-	80	-	70	-	60	ns
33	Clock High to BG Low	tCHGL		_	80	-	70	_	60	-	50	ns
34	Clock High to BG High	tchgh		_	80	_	70	1-0	60	-	50	ns
35	BR Low to BG Low	t _{BRLGL}		1.5	100ns +3.5	1.5	90ns +3.5	1.5	80ns +3.5	1.5	70ns +3.5	Clk.Per.
361	BR High to BG High	t _{BRHGH}		1.5	100ns +3.5	1.5	90ns +3.5	1.5	80ns +3.5	1.5	70ns +3.5	Clk.Per.
37	BGACK Low to BG High	tGALGH	Fig. 7 ~ Fig. 9	1.5	100ns +3.5	1.5	90ns +3.5	1.5	80ns +3.5	1.5	70ns +3.5	Clk.Per.
37A ²	BGACK Low to BR High	†GALBRH		20	1.5 Clocks	20	1.5 Clocks	20	1.5 Clocks	20	1.5 Clocks	ns
38	BG Low to Control, Address, Data Bus High Impedance (AS High)	t _{GLZ}		-	100	-	80	-	70	-	60	ns
39	BG Width High	t _{GH}		1.5	-	1.5	_	1.5	-	1.5	-	ak.Per.
46	BGACK Width Low	tGAL		1.5	-	1.5	-	1.5	-	1.5	-	Clk.Per.
47	Asynchronous Input Setup Time	t _{ASI}		25	_	20	-	20	_	20	_	ns
57	BGACK High to Control Bus Driven	tGABD		1.5	_	1.5	_	1.5	-	1.5	_	Clk.Per.
58 ¹	BG High to Control Bus Driven	^t GHBD		1.5	_	1.5	-	1.5	-	1.5	-	Clk.Per.

- 1. The processor will negate \overline{BG} and begin driving the bus again if external arbitration logic negates \overline{BR} before asserting \overline{BGACK} .
- 2. The minimum value must be met to guarantee proper operation. If the maximum value is exceeded, BG may be reasserted.



Figures 7, 8, and 9 depict the three bus arbitration cases that can arise. Figure 7 shows the timing where \overline{AS} is negated when the processor asserts \overline{BG} (Idle Bus Case). Figure 8 shows the timing where \overline{AS} is asserted when the processor asserts \overline{BG} (Active Bus Case). Figure 9 shows the timing where more than one bus master are requesting the bus. Refer to Bus Arbitration for a complete discussion of bus arbitration.

The waveforms shown in Figures 7, 8, and 9 should only be referenced in regard to the edge-to-edge measurement of the timing specifications. They are not intended as a functional description of the input and output signals. Refer to other functional descriptions and their related diagrams for device operation.

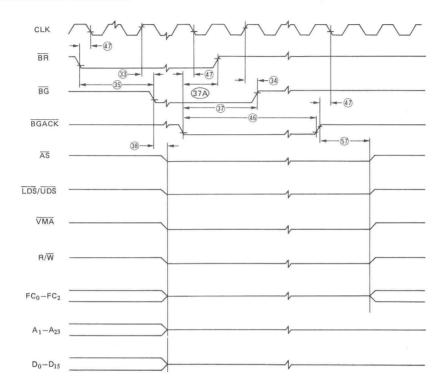


Figure 7. Bus Arbitration Timing Diagram - Idle Bus Case

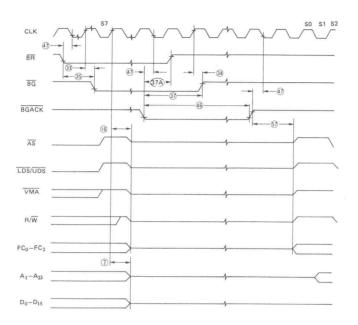


Figure 8. Bus Arbitration Timing Diagram - Active Bus Case

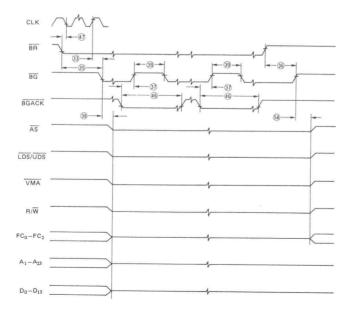


Figure 9. Bus Arbitration Timing Diagram - Multiple Bus Requests

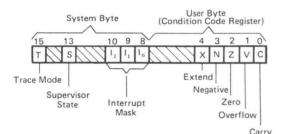


INTRODUCTION

As shown in the programming model, the 68000 offers seventeen 32-bit registers in addition to the 32-bit program counter and a 16-bit status register. The first eight registers (D0 ~ D7) are used as data registers for byte (8-bit), word (16-bit), and long word (32-bit) data operations. The second set of seven registers (A0 ~ A6) and the system stack pointer may be used as software stack pointers and base address registers. In addition, these registers may be used for word and long word address operations. All 17 registers may be used as index regis-

The status register contains the interrupt mask (eight levels available) as well as the condition codes; extend (X), negative (N), zero (Z), overflow (V), and carry (C). Additional status bits indicate that the processor is in a trace (T) mode and/or in a supervisor (S) state.

Status Register



Unused, read as zero.

DATA TYPES AND ADDRESSING MODES

Five basic data types are supported. These data types are:

- (1)
- (2) BCD Digits (4 bits)
- (3) Bytes (8 bits)
- Word (16 bits) (4)
- Long Words (32 bits) (5)

In addition, operations on other data types such as memory address, status word data, etc., are provided for in the instruction set.

The 14 addressing modes, shown in Table 1, includes six basic types:

- (1) Register Direct
- Register Indirect (2)
- Absolute (3)
- (4) Immediate
- (5) Program Counter Relative
- (6) Implied

Included in the register indirect addressing modes is the capability to do postincrementing, predecrementing, offsetting and indexing. Program counter relative mode can also be modified via indexing and offsetting.

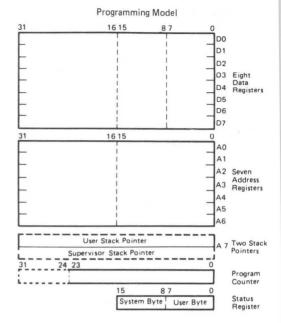


Table 1 Addressing Modes

Mode	Generation
Register Direct Addressing	
Data Register Diredt	EA = Dn
Address Register Direct	EA = An
Absolute Data Addressing	
Absolute Short	EA = (Next Word)
Absolute Long	EA = (Next Two Words)
Program Counter Relative Addressing	
Relative with Offset	$EA = (PC) + d_{16}$
Relative with Index and Offset	$EA = (PC) + (Xn) + d_8$
Register Indirect Addressing	
Register Indirect	EA = (An)
Postincrement Register Indirect	$EA = (AN), An \leftarrow An + N$
Predecrement Register Indirect	$An \leftarrow An - N, EA = (An)$
Register Indirect with Offset	$EA = (An) + d_{16}$
Indexed Register Indirect with Offset	$EA = (An) + (Xn) + d_8$
Immediate Data Addressing	
Immediate	DATA = Next Word(s)
Quick Immediate	Inherent Data
Implied Addressing	
Implied Register	EA = SR, USP, SP, PC

(NOTES)

- EA = Effective Address
- An = Address Register
- Dn = Data Register
- Xn = Address or Data Register used as Index Register
- SR = Status Register
- PC = Program Counter
- () = Contents of ds = Eight-bit Offset
 - (displacement)

- d₁₆ = Sixteen-bit Offset (displacement)
- N = 1 for Byte, 2 for Words and 4 for Long Words. If An is the stack pointer and the operand size is byte, N=2 to keep the stack pointer on a word boundary.
- ← = Replaces

INSTRUCTION SET OVERVIEW

The 68000 instruction set is shown in Table 2. Some additional instructions are variations, or subsets, of these and they appear in Table 3. Special emphasis has been given to the instruction set's support of structured high-level languages to facilitate ease of programming. Each instruction, with few exceptions, operates on bytes, words, and long words and most

instructions can use any of the 14 addressing modes. Combining instruction types, data types, and addressing modes, over 1000 useful instructions are provided. These instructions include signed and unsigned multiply and divide, "quick" arithmetic operations, BCD arithmetic and expanded operations (through traps).

Table 2 Instruction Set

Mnemonic	nemonic Description Mnemonic		Description	Mnemonic	Description		
ABCD ADD AND	Add Decimal with Extend Add Logical And	EOR EXG EXT	Exclusive Or Exchange Registers Sign Extend	PEA RESET	Push Effective Address Reset External Devices		
ASL ASR	Arithmetic Shift Left Arithmetic Shift Right	JMP Jump		ROL ROR ROXL	Rotate Left without Extend Rotate Right without Extend Rotate Left with Extend		
B _{CC} BCHG BCLR BRA	Branch Conditionally Bit Test and Change Bit Test and Clear Branch Always	LEA LINK LSL LSR	Load Effective Address Link Stack Logical Shift Left Logical Shift Right	ROXR RTE RTR RTS	Rotate Right with Extend Return from Exception Return and Restore Return from Subroutine		
BSET BSR BTST	Bit Test and Set Branch to Subroutine Bit Test	Branch to Subroutine	MOVE MOVEM MOVEP	Move Move Multiple Registers Move Peripheral Data	SBCD SCC STOP	Subtract Decimal with Extend Set Conditional Stop	
CHK CLR	Check Register Against Bounds Clear Operand	MULS MULU	Signed Multiply Unsigned Multiply	SUB SWAP	Subtract Swap Data Register Halves		
DB _{CC}	Test Condition, Decrement and Branch	NBCD NEG NOP	Negate Decimal with Extend Negate No Operation	TAS TRAP TRAPV	Test and Set Operand Trap Trap on Overflow		
DIVS DIVU	Signed Divide Unsigned Divide	NOT	One's Complement Logical Or	TST	Test Unlink		

Table 3 Variations of Instruction Types

Instruction Type	Variation	Description	Instruction Type	Variation	Description
ADD	ADD	Add	MOVE	MOVE	Move
	ADDA	Add Address		MOVEA	Move Address
	ADDQ	Add Quick		MOVEQ	Move Quick
	ADDI	Add Immediate		MOVE from SR	Move from Status Register
	ADDX	Add with Extend		MOVE to SR	Move to Status Register
AND	AND	Logical And		MOVE to CCR	Move to Condition Codes
	ANDI	And Immediate		MOVE USP	Move User Stack Pointer
	ANDI to CCR	And Immediate to	NEG	NEG	Negate
		Condition Codes		NEGX	Negate with Extend
	ANDI to SR	And Immediate to Status Register	OR	OR	Logical Or
		Status negister		ORI	Or Immediate
CMP	CMP	Compare		ORI to CCR	Or Immediate to
	CMPA	Compare Address		00100	Condition Codes
	CMPM	Compare Memory		ORI to SR	Or Immediate to
	CMPI	Compare Immediate			Status Register
EOR	EOR	Exclusive Or	SUB	SUB	Subtract
	EORI	Exclusive Or Immediate		SUBA	Subtract Address
	EORI to CCR	Exclusive Or Immediate		SUBI	Subtract Immediate
		to Condition Codes		SUBQ	Subtract Quick
	EORI to SR	Exclusive Or Immediate to Status Register		SUBX	Subtract with Extend

REGISTER DESCRIPTION AND DATA ORGANIZATION

The following paragraphs describe the registers and data organization of the 68000.

OPERAND SIZE

Operand sizes are defined as follows: a byte equals 8 bits, a word equals 16 bits, and a long word equals 32 bits. The operand size for each instruction is either explicitly encoded in the instruction or implicitly defined by the instruction operation. Implict instructions support some subset of all three sizes.

DATA ORGANIZATION IN REGISTERS

The eight data registers support data operands of 1, 8, 16, or 32 bits. The seven address registers together with the active stack pointer support address operands of 32 bits.

DATA REGISTERS

Each data register is 32 bits wide. Byte operands occupy the low order 8 bits, word operands the low order 16 bits, and long word operands the entire 32 bits. The least significant bit is addressed as bit zero; the most significant bit is addressed as bit 31.

When a data register is used as either a source or destination operand, only the appropriate low-order portion is changed; the remaining high-order portion is neither used nor changed.

ADDRESS REGISTERS

Each address register and the stack pointer is 32 bits wide and holds a full 32 bit address. Address registers do not support byte sized operands. Therefore, when an address register is used as a source operand, either the low order word or the entire long word operand is used depending upon the operation size. When an address register is used as the destination operand, the entire register is affected regardless of the operation size. If the operation size is word, any other operands are sign extended to 32 bits before the operation is performed.

DATA ORGANIZATION IN MEMORY

Bytes are individually addressable with the high order byte having an even address the same as the word, as shown in Figure 10. The low order byte has an odd address that is one count higher than the word address. Instructions and multibyte data are accessed only on word (even byte) boundaries. If a long word datum is located at address n (n even), then the second word of that datum is located at address n + 2.

The data types supported by the 68000 are: bit data, integer data of 8, 16, or 32 bits, 32-bit addresses and binary coded decimal data. Each of these data types is put in memory, as shown in Figure 11. The numbers indicate the order in which the data would be accessed from the processor.

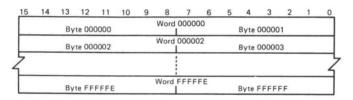


Figure 10 Word Organization in Memory

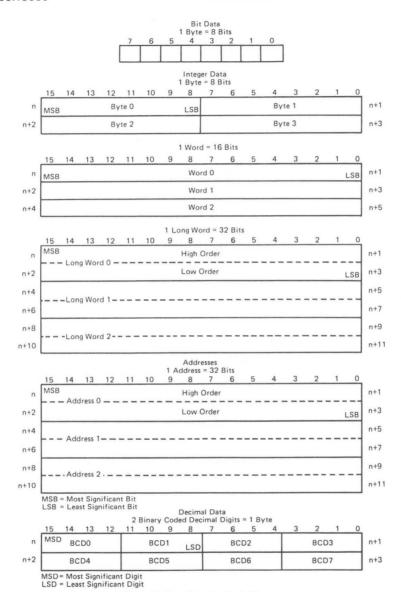


Figure 11 Data Organization in Memory

ADDRESSING

Instructions for the 68000 contain two kinds of information: the type of function to be performed, and the location of the operand(s) on which to perform that function. The methods used to locate (address) the operand(s) are explained in the following paragraphs.

Instructions specify an operand location in one of three ways:

Register Specification — the number of the register is given in the register field of the instruction.

Effective Address — use of the different effective address modes.

Implicit Reference – the definition of certain instructions implies the use of specific registers.

INSTRUCTION FORMAT

Instructions are from one to five words in length, as shown in Figure 12. The length of the instruction and the operation to be performed is specified by the first word of the instruction which is called the operation word. The remaining words further specify the operands. These words are either immediate operands or extensions to the effective address mode specified in the operation word.

PROGRAM/DATA REFERENCES

The 68000 separates memory references into two classes: program references, and data references. Program references, as the name implies, are references to that section of memory that

contains the program being executed. Data references refer to that section of memory that contains data. Operand reads are from the data space except in the case of the program counter relative addressing mode. All operand writes are to the data space.

REGISTER SPECIFICATION

The register field within an instruction specifies the register to be used. Other fields within the instruction specify whether the register selected is an address or data register and how the register is to be used.

EFFECTIVE ADDRESS

Most instructions specify the location of an operand by using the effective address field in the operation word. For example, Figure 13 shows the general format of the single effective address instruction operation word. The effective address is composed of two 3-bit fields: the mode field, and the register field. The value in the mode field selects the different address modes. The register field contains the number of a register.

The effective address field may require additional information to fully specify the operand. This additional information, called the effective address extension, is contained in the following word or words and is considered part of the instruction, as shown in Figure 12. The effective address modes are grouped into three categories: register direct, memory addressing, and special.

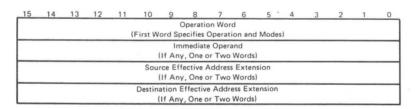


Figure 12 Instruction Format

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
×	х	×	×	×	х	×	х	×	х		Ef Mode	fective	Addre	ss Register	

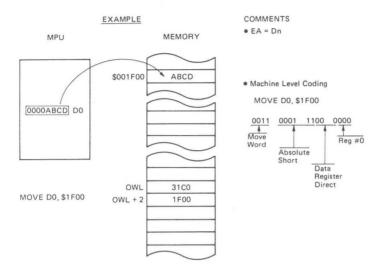
Figure 13 Single-Effective-Address Instruction Operation Word General Format

REGISTER DIRECT MODES

These effective addressing modes specify that the operand is in one of the 16 multifunction registers.

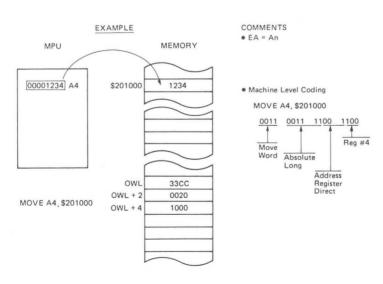
Data Register Direct

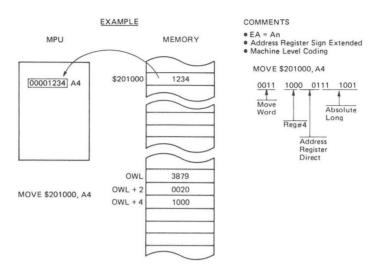
The operand is in the data register specified by the effective address register field.



Address Register Direct

The operand is in the address register specified by the effective address register field.



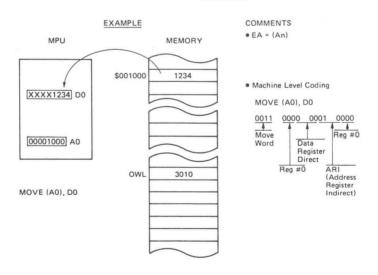


MEMORY ADDRESS MODES

These effective addressing modes specify that the operand is in memory and provide the specific address of the operand.

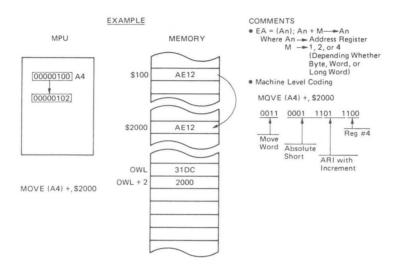
Address Register Indirect

The address of the operand is in the address register specified by the register field. The reference is classified as a data reference with the exception of the jump and jump to subroutine instructions.



Address Register Indirect With Postincrement

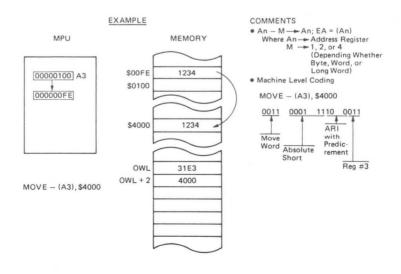
The address of the operand is in the address register specified by the register field. After the operand address is used, it is incremented by one, two, or four depending upon whether the size of the operand is byte, word, or long word. If the address register is the stack pointer and the operand size is byte, the address is incremented by two rather than one to keep the stack pointer on a word boundary. The reference is classified as a data reference.



Address Register Indirect With Predecrement

The address of the operand is in the address register specified by the register field. Before the operand address is used, it is decremented by one, two, or four depending upon whether the operand size is byte, word, or long word. If the address

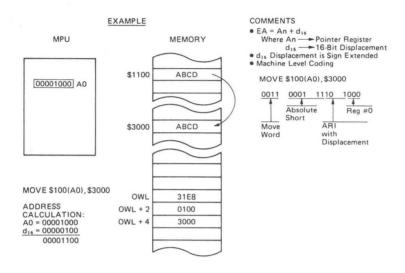
register is the stack pointer and the operand size is byte, the address is decremented by two rather than one to keep the stack pointer on a word boundary. The reference is classified as a data reference.



Address Register Indirect With Displacement

This address mode requires one word of extension. The address of the operand is the sum of the address in the address

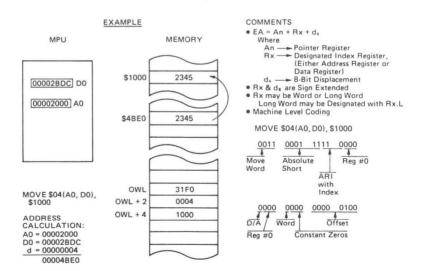
register and the sign-extended 16-bit displacement integer in the extension word. The reference is classified as a data reference with the exception of the jump to subroutine instructions.



Address Register Indirect With Index

This address mode requires one word of extension. The address of the operand is the sum of the address in the address register, the sign-extended displacement integer in the low order

eight bits of the extension word, and the contents of the index register. The reference is classified as a data reference with the exception of the jump and jump to subroutine instructions.

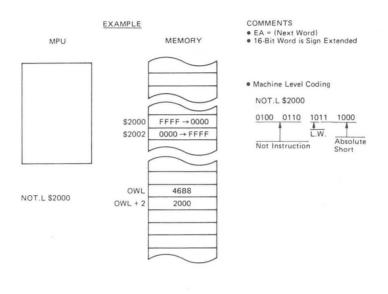


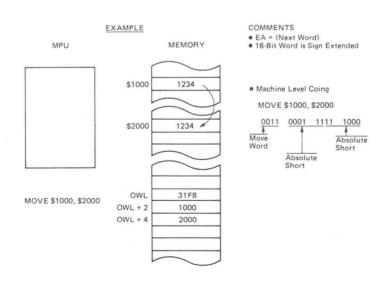
SPECIAL ADDRESS MODE

The special address modes use the effective address register field to specify the special addressing mode instead of a register number.

Absolute Short Address

This address mode requires one word of extension. The address of the operand is the extension word. The 16-bit address is sign extended before it is used. The reference is classified as a data reference with the exception of the jump and jump to subroutine instructions.

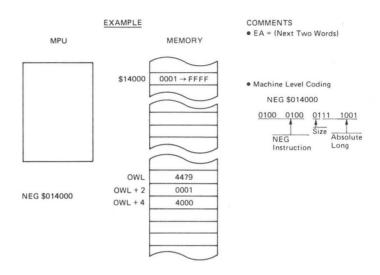




Absolute Long Address

This address mode requires two words of extension. The address of the operand is developed by the concatenation of the extension words. The high-order part of the address is the

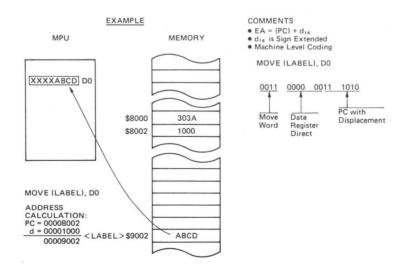
first extension word; the low-order part of the address is the second extension word. The reference is classified as a data reference with the exception of the jump and jump to subroutine instructions.



Program Counter With Displacement

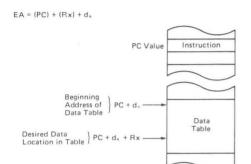
This address mode requires one word of extension. The address of the operand is the sum of the address in the program counter and the sign-extended 16-bit displacement integer in

the extension word. The value in the program counter is the address of the extension word. The reference is classified as a program reference.



Program Counter With Index

This address mode requires one word of extension. This address is the sum of the address in the program counter, the sign-extended displacement integer in the lower eight bits of the extension word, and the contents of the index register. The value in the program counter is the address of the extension word. This reference is classified as a program reference.



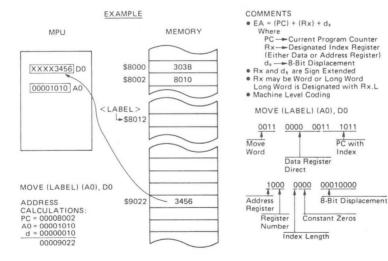
(NOTE)

Extension Word

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
D/A	R	egist	er	W/L	0	0	0		D	ispla	ceme	nt Ir	ntege	r	

D/A : Data Register = 0, Address Register = 1
Register : Index Register Number
W/L : Sign-extented, low order Word integer
in Index Register = 0

Long Word in Index Register = 1



Immediate Data

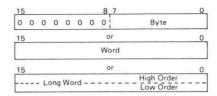
This address mode requires either one or two words of extension depending on the size of the operation.

Byte operation — operand is low order byte of extension word

Word operation – operand is extension word

Long word operation — operand is in the two extension words, high-order 16 bits are in the first extension word, low-order 16 bits are in the second extension word.

Extension Word

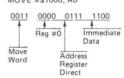


MPU MEMORY [00001000] A0 OWL 307C OWL + 2 1000

COMMENTS

- Data = Next Word(s)
 Data is Sign Extended for Address Register
- but not Data Register
 Machine Level Coding

MOVE #\$1000, A0



EXAMPLE MPU MEMORY 00000005A D3 OWL 765A MOVEQ #\$5A, D3

COMMENTS

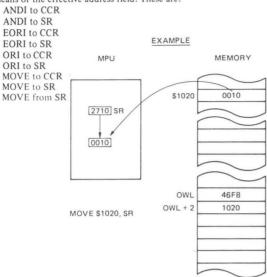
- Inherent Data
- Data is Sign Extended to Long Word
 Destination must be a Data Register
- Destination must be a L
- Machine Level Coding

MOVEQ #\$5A, D3



Condition Codes or Status Register

A selected set of instructions may reference the status register by means of the effective address field. These are:



COMMENTS

- EA = (Next Word)
- Note: This Example is a Privileged Instruction
- Machine Level Coding

MOVE \$1020, SR

0100 0110 1111 100

Move to SR Abs

Absolute

EFFECTIVE ADDRESS ENCODING SUMMARY

Table 4 is a summary of the effective addressing modes discussed in the previous paragraphs.

Table 4 Effective Address Encoding Summary

Addressing Mode	Mode	Register	
Data Register Direct	000	register number	
Address Register Direct	001	register number	
Address Register Indirect	010	register number	
Address Register Indirect with Postincrement	011	register number	
Address Register Indirect with Predecrement	100	register number	
Address Register Indirect with Displacement	101	register numbe	
Address Register Indirect with Index	110	register number	
Absolute Short	111	000	
Absolute Long	111	001	
Program Counter with Displacement	111	010	
Program Counter with Index	111	011	
Immediate	111	100	

IMPLICIT REFERENCE

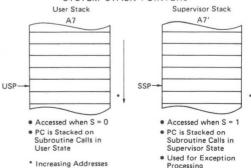
Some instructions make implicit reference to the program counter (PC), the system stack pointer (SP), the supervisor

stack pointer (SSP), the user stack pointer (USP), or the status register (SR).

SYSTEM STACK

The system stack is used implicitly by many instructions; user stacks and queues may be created and maintained through the addressing modes. Address register seven (A7) is the system stack pointer (SP). The system stack pointer is either the supervisor stack pointer (SSP) or the user stack pointer (USP), depending on the state of the S-bit in the status register. If the S-bit indicates supervisor state, SSP is the active system stack pointer, and the USP cannot be referenced as an address register. If the S-bit indicates user state, the USP is the active system stack pointer, and the SSP cannot be referenced. Each system stack fills from high memory to low memory.

SYSTEM STACK POINTERS



The address mode SP@- creates a new item on the active system stack, and the address mode SP @+ deletes an item from the active system stack.

The program counter is saved on the active system stack on subroutine calls, and restored from the active system stack on returns. On the other hand, both the program counter and the status register are saved on the supervisor stack during the processing of traps and interrupts. Thus, the correct execution of the supervisor state code is not dependent on the behavior of user code and user programs may use the user stack pointer arbitrarily.

In order to keep data on the system stack aligned properly, data entry on the stack is restricted so that data is always put in the stack on a word boundary. Thus byte data is pushed on or pulled from the system stack in the high order half of the word; the lower half is unchanged.

USER STACKS

User stacks can be implemented and manipulated by employing the address register indirect with postincrement and predecrement addressing modes. Using an address register (on of A0 through A6), the user may implement stacks which are filled either from high memory to low memory, or vice versa. The important things to remember are:

- using predecrement, the register is decremented before its contents are used as the pointer into the stack,

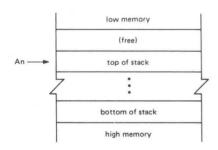
- using postincrement, the register is incremented after its contents are used as the pointer into the stack,

byte data must be put on the stack in pairs when mixed with word or long data so that the stack will not get misaligned when the data is retrieved. Word and long accesses must be on word boundary (even) addresses.

Stack growth from high to low memory is implemented with An@- to push data on the stack,

An@+ to pull data from the stack.

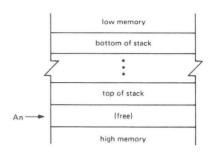
After eigher a push or a pull operation, register An points to the last (top) item on the stack. This is illustrated as:



Stack growth from low to high memory is implemented with An@+ to push data on the stack,

An@- to pull data from the stack.

After either a push or a pull operation, register An points to the next available space on the stack. This is illustrated as:



OUFUES

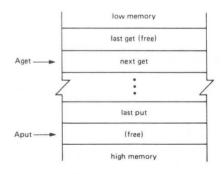
User queues can be implemented and manipulated with the address register indirect with postincrement or predecrement addressing modes. Using a pair of address registers (two of A0 through A6), the user may implement queues which are filled either from high memory to low memory, or vice versa. Because queues are pushed from one end and pulled from the other, two registers are used: the put and get pointers.

Queue growth from low to high memory is implemented with

Aput(a)+ to put data into the queue,

Aget@+ to get data from the queue.

After a put operation, the put address register points to the next available space in the queue and the unchanged get address register points to the next item to remove from the queue. After a get operation, the get address register points to the next item to remove from the queue and the unchanged put address register points to the next available space in the queue. This is illustrated as:



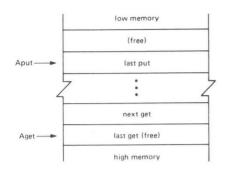
If the queue is to be implemented as a circular buffer, the address register should be checked and, if necessary, adjusted before the put or get operation is performed. The address register is adjusted by subtracting the buffer length (in bytes).

Queue growth from high to low memory is implemented with Aput@- to put data into the queue,

Aget@ - to get data from the queue.

After a put operation, the put address register points to the last item put in the queue, and the unchanged get address register points to the last item removed from the queue. After a get operation, the get address register points to the last item removed from the queue and the unchanged put address register points to the last item put in the queue. This is illustrated as:





If the queue is to be implemented as a circular buffer, the get or put operation should be performed first, and then the address register should be checked and, if necessary, adjusted. The address register is adjusted by adding the buffer length (in bytes).

INSTRUCTION SET SUMMARY

The following paragraphs contain an overview of the form and structure of the 68000 instruction set. The instructions form a set of tools that include all the machine functions to perform the following operations:

Data Movement
Integer Arithmetic
Logical
Shift and Rotate
Bit Manipulation
Binary Coded Decimal
Program Control
System Control

The complete range of instruction capabilities combined with the flexible addressing modes described previously provide a very flexible base for program development.

• DATA MOVEMENT OPERATIONS

The basic method of data acquisition (transfer and storage) is provided by the move (MOVE) instruction. The move instruction and the effective addressing modes allow both address and data manipulation. Data move instructions allow byte, word, and long word operands to be transferred from memory to memory, memory to register, register to memory, and register to memory, and register to memory, and register to register. Address move instructions allow word and long word operand transfers and ensure that only legal address manipulations are executed. In addition to the general move instruction there are several special data movement instructions: move multiple registers (MOVEM), move peripheral data (MOVEP), exchange registers (EXG), load effective address (LEA), push effective address (PEA),

link stack (LINK), unlink stack (UNLK), and move quick (MOVEQ). Table 5 is a summary of the data movement operations.

Table 5 Data Movement Operations

Instruction Operand Size		Operation			
EXG	32	Rx ↔ Ry			
LEA	32	EA → An			
LINK	-	$\begin{pmatrix} An \rightarrow - (SP) \\ SP \rightarrow An; \\ SP + d \rightarrow SP \end{pmatrix}$			
MOVE	8, 16, 32	(EA)s → EAd			
MOVEM	16, 32	(EA) → An, Dn An, Dn → EA			
MOVEP	16, 32	(EA) → Dn Dn → EA			
MOVEQ	8	#xxx → Dn			
PEA	32	EA → -(SP)			
SWAP	32	Dn[31:16] ↔ Dn[15:0			
UNLK	-	$An \rightarrow Sp;$ $SP \rightarrow An$			

(NOTES)

- s = source d = destination () = bit numbers
- -() = indirect with predecrement () + = indirect with postincrement
- # = immediate data

INTEGER ARITHMETIC OPERATIONS

The arithmetic operations include the four basic operations of add (ADD), subtract (SUB), multiply (MUL), and divide (DIV) as well as arithmetic compare (CMP), clear (CLR), and negate (NEG). The add and subtract instructions are available for both address and data operations, with data operations accepting all operand sizes. Address operations are limited to legal address size operands (16 or 32 bits). Data, address, and memory compare operations are also available. The clear and negate instructions may be used on all sizes of data operands.

The multiply and divide operations are available for signed and unsigned operands using word multiply to produce a long word product, and a long word dividend with word divisor to produce a word quotien with a word remainder.

Multiprecision and mixed size arithmetic can be accomplished using a set of extended instructions. These instructions are: add extended (ADDX), subtract extended (SUBX), sign extend (EXT), and negate binary with extend (NEGX).

A test operand (TST) instruction that will set the condition codes as a result of a compare of the operand with zero is also available. Test and set (TAS) is a synchronization instruction useful in multiprocessor systems. Table 6 is a summary of the integer arithmetic operations.

Table 6 Integer Arithmetic Operations

Instruction	Operand Size	Operation		
ADD	8, 16, 32 16, 32	Dn + (EA) → Dn (EA)+ Dn → EA (EA) + #xxx → EA AN + (EA) → An		
ADDX	8, 16, 32 16, 32	$\begin{array}{c} Dx + Dy + X \rightarrow Dx \\ -(Ax) + -(Ay) + X \rightarrow (Ax) \end{array}$		
CLR 8, 16, 32 (EA) → MPU 0 → EA				
СМР	8, 16, 32 16, 32	Dn - (EA) (EA) - #xxx (Ax) + - (Ay) + An - (EA)		
DIVS	DIVS 32 ÷ 16 Dn÷(EA) → Dn			
DIVU	DIVU 32 ÷ 16 Dn÷(EA) → Dn			
EXT	8 → 16 16 → 32	$(Dn)_8 \to Dn_{16}$ $(Dn)_{16} \to Dn_{32}$		
MULS	16×16 → 32	Dn×(EA) → Dn		
MULU	16×16 → 32	Dn×(EA) → Dn		
NEG	8, 16, 32	0 - (EA) → EA		
NEGX	8, 16, 32	0 - (EA) - X - EA		
SUB	8, 16, 32 16, 32	Dn - (EA) → Dn (EA) - Dn → EA (EA) - #xxx → EA An - (EA) → An		
SUBX	8, 16, 32	$\begin{array}{c} Dx - Dy - X \rightarrow Dx \\ -(Ax)(Ay) - X \rightarrow (Ax) \end{array}$		
TAS	8	(EA) - 0, 1 → EA[7]		
TST	8, 16, 32	(EA) - 0		

(NOTE) [] = bit number

- () = indirect with predecrement

() + = indirect with postincrement

= immediate data

LOGICAL OPERATIONS

Logical operation instructions AND, OR, EOR, and NOT are available for all sizes of integer data operands. A similar set of immediate instructions (ANDI, ORI, and EORI) provide these logical operations with all sizes of immediate data. Table 7 is a summary of the logical operations.

Table 7 Logical Operations

Instruction	Operand Size	Operation .		
AND	8, 16, 32	$Dn \land (EA) \rightarrow Dn$ $(EA) \land Dn \rightarrow EA$ $(EA) \land = x \times x \rightarrow EA$ $Dn \lor (EA) \rightarrow Dn$ $(EA) \lor Dn \rightarrow EA$ $(EA) \lor = x \times x \rightarrow EA$		
OR	8, 16, 32			
EOR	8, 16, 32	(EA)⊕Dy → EA (EA)⊕ #xxx → EA		
NOT	8, 16, 32	~ (EA) → EA		

[NOTE] ~ = invert

v = logical OR

= immediate data

∧ = logical AND

⊕ = exclusive OR

SHIFT AND ROTATE OPERATIONS

Shift operations in both directions are provided by the arithmetic instructions ASR and ASL and logical shift instructions LSR and LSL. The rotate instructions (with and without extend) available are ROXR, ROXL, ROR, and ROL. All

shift and rotate operations can be performed in either registers or memory. Register shifts and rotates support all operand sizes and allow a shift count specified in the instruction of one to eight bits, or 0 to 63 specified in a data register.

Memory shifts and rotates are for word operands only and allow only single-bit shifts or rotates. Table 8 is a summary of the shift and rotate operations.

Table 8 Shift and Rotate Operations

Instruction	Operand Size	Operation
ASL	8, 16, 32	X/C - 0
ASR	8, 16, 32	X/C
LSL	8, 16, 32	X/C - 0
LSR	8, 16, 32	0 X/C
ROL	8, 16, 32	C
ROR	8, 16, 32	C
ROXL	8, 16, 32	C - X -
ROXR	8, 16, 32	X C

BIT MANIPULATION OPERATIONS

Bit manipulation operations are accomplished using the following instructions: bit test (BTST), bit test and set (BSET), bit test and clear (BCLR), and bit test and change (BCHG). Table 9 is a summary of the bit manipulation operations. (Bit 2 of the status register is Z.)

Table 9 Bit Manipulation Operations

Instruction	Operand Size	Operation		
BTST	8, 32	~ bit of (EA) → Z		
BSET	8, 32	(~ bit of (EA) → Z; 1 → bit of EA		
BCLR	8, 32	(~ bit of (EA) → Z; 0 → bit of EA		
BCHG	8, 32	(~ bit of (EA) → Z; ~ bit of (EA) → bit of EA		

(Note) ~ = invert

BINARY CODED DECIMAL OPERATIONS

Multiprecision arithmetic operations on binary coded decimal numbers are accomplished using the following instructions: add decimal with extend (ABCD), subtract decimal with extend (SBCD), and negate decimal with extend (NBCD). Table 10 is a summary of the binary coded decimal operations.

Table 10 Binary Coded Decimal Operations

Instruction	Operand Size	Operation
ABCD	8	$Dx_{10} + Dy_{10} + X \rightarrow Dx$ - $(Ax)_{10} + - (Ay)_{10} + X \rightarrow (Ax)$
SBCD	8	$Dx_{10} - Dy_{10} - X \rightarrow Dx$ - $(Ax)_{10} - (Ay)_{10} - X \rightarrow (Ax)$
NBCD	8	0 - (EA) ₁₀ - X → EA

- () = indirect with predecrement

PROGRAM CONTROL OPERATIONS

Program control operations are accomplished using a series of conditional and unconditional branch instructions and return instructions. These instructions are summarized in Table 11.

The conditional instructions provide setting and branching for the following conditions:

CC	_	carry clear	LS	_	low or same
CS	_	carry set	LT	-	less than
EQ	_	equal	MI	_	minus
F	-	never true	NE	_	not equal
GE	_	greater or equal	PL	_	plus
GT	-	greater than	T	_	always true
HI	_	high	VC	_	no overflow
LE	-	less or equal	VS	_	overflow

Table 11 Program Control Operations

Instruction	Operation			
Conditional				
Всс	Branch conditionally (14 conditions) 8- and 16-bit displacement			
DB _{CC}	Test condition, decrement, and branch 16-bit displacement			
Scc	Set byte conditionally (16 conditions)			
Unconditional				
BRA	Branch always 8-and 16-bit displacement			
BSR	Branch to subroutine 8- and 16-bit displacement			
JMP	Jump			
JSR	Jump to subroutine			
Returns				
RTR	Return and restore condition codes			
RTS	Return from subroutine			

SYSTEM CONTROL OPERATIONS

System control operations are accomplished by using privileged instructions, trap generating instructions, and instructions that use or modify the status register. These instructions are summarized in Table 12.

Table 12 System Control Operations

Instruction	Operation		
Privileged			
RESET	Reset external devices		
RTE	Return from exception		
STOP	Stop program execution		
ORI to SR	Logical OR to status register		
MOVE USP	Move user stack pointer		
ANDI to SR	Logical AND to status register		
EORI to SR	Logical EOR to status register		
MOVE EA to SR	Load new status register		
Trap Generating			
TRAP	Trap		
TRAPV	Trap on overflow		
СНК	Check register against bounds		
Status Register			
ANDI to CCR	Logical AND to condition codes		
EORI to CCR	Logical EOR to condition codes		
MOVE EA to CCR	Load new condition codes		
ORI to CCR	Logical OR to condition codes		
MOVE SR to EA	Store status register		

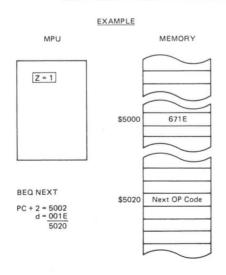
BRANCH INSTRUCTION ADDRESSING

BRANCH INSTRUCTION FORMAT

Operation Word Extension Word

0 Operation Code 8 bit Displacement 16 bit Displacement if 8 bit Displacement = 0

RELATIVE, FORWARD REFERENCE, 8-BIT OFFSET



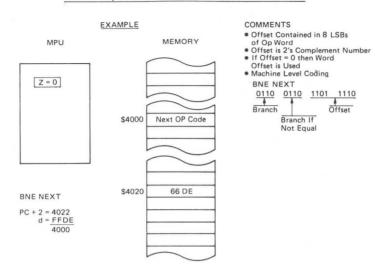
COMMENTS

- Offset Contained in 8 LSBs of Op Word
 Offset is 2's Complement Number
 If Offset = 0 then Word Offset is Used

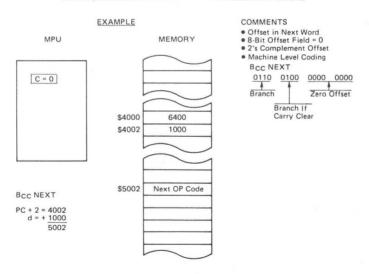
- Machine Level Coding

BEQ NEXT 0110 0111 0001 1110 Offset Branch Branch If Equal

RELATIVE, BACKWARD REFERENCE 8-BIT OFFSET



RELATIVE, FORWARD REFERENCE, 16-BIT OFFSET



■ SIGNAL AND BUS OPERATION DESCRIPTION

The following paragraphs contain a brief description of the input and output signals. A discussion of bus operation during the various machine cycles and operations is also given.

(NOTE) The terms assertion and negation will be used extensively. This is done to avoid confusion when dealing with a mixture of "active-low" and "active-high" signals. The term assert or assertion is used to indicate that a signal is active or true independent of whether that voltage is low or high. The term negate or negation is used to indicate that a signal is inactive or false.

SIGNAL DESCRIPTION

The input and output signals can be functionally organized into the groups shown in Figure 14. The following paragraphs provide a brief description of the signals and also a reference (if applicable) to other paragraphs that contain more detail about the function being performed.

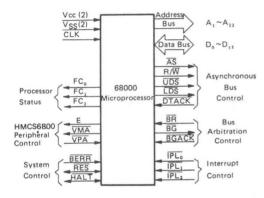


Figure 14 Input and Output Signals

ADDRESS BUS (A1 through A23)

This 23-bit, unidirectional, three-state bus is capable of addressing 8 megawords of data. It provides the address for bus operation during all cycles except interrupt cycles. During interrupt cycles, address lines A₁, A₂, and A₃. Provide information about what level interrupt is being serviced while address lines A₄ through A₂₃ are all set to a logic high.

DATA BUS (Do through D15)

This 16-bit, bidirectional, three-state bus is the general purpose data path. It can transfer and accept data in either word or byte length. During an interrupt acknowledge cycle, an external device supplies the vector number on data lines Do through D7.

ASYNCHRONOUS BUS CONTROL

Asynchronous data transfer are handled using the following control signals: address strobe, read/write, upper and lower data strobes, and data transfer acknowledge. These signals are explained in the following paragraphs.

Address Strobe (AS)

This signal indicates that there is a valid address on the address bus.

Read/Write (R/W)

This signal defines the data bus transfer as a read or write cycle. The R/W signal also works in conjunction with the upper and lower data strobes as explained in the following paragraph.

Upper and Lower Data Strobes (UDS, LDS)

These signals control the data on the data bus, as shown in Table 13. When the R/\overline{W} line is high, the processor will read from the data bus as indicated. When the R/\overline{W} line is low, the processor will write to the data bus as shown.

Table 13 Data Strobe Control of Data Bus

UDS	LDS	R/W	$D_8 \sim D_{15}$	$D_0 \sim D_7$
High	High	-	No valid data	No valid data
Low	Low	High	Valid data bits 8 ∼ 15	Valid data bits 0 ~ 7
High	Low	High	No valid data	Valid data bits 0 ~ 7
Low	High	High	Valid data bits 8 ∼ 15	No valid data
Low	Low	Low	Valid data bits 8 ∼ 15	Valid data bits 0 ~ 7
High	Low	Low	Valid data bits 0 ~ 7*	Valid data bits 0 ~ 7
Low	High	Low	Valid data bits 8 ∼ 15	Valid data bits 8 ~ 15*

^{*} These conditions are a result of current implementation and may not appear on future devices.

Data Transfer Acknowledge (DTACK)

This input indicates that the data transfer is completed. When the processor recognizes \$\overline{DTACK}\$ during a read cycle, data is latched and the bus cycle terminated. When \$\overline{DTACK}\$ is recognized during a write cycle, the bus cycle is terminated. (Refer to ASYNCHRONOUS VERSUS SYNCHRONOUS OPERATION)

BUS ARBITRATION CONTROL

These three signals form a bus arbitration circuit to determine which device will be the bus master device.

Bus Request (BR)

This input is wire ORed with all other devices that could be bus masters. This input indicates to the processor that some other device desires to become the bus master.

Bus Grant (BG)

This output indicates to all other potential bus master devices that the processor will release bus control at the end of the current bus cycle.

Bus Grand Acknowledge (BGACK)

This input indicates that some other device has become the bus master. This signal cannot be asserted until the following four conditions are met:

- (1) A Bus Grant has been received
- (2) Address Strobe is inactive which indicates that the microprocessor is not using the bus
- (3) Data Transfer Acknowledge is inactive which indicates



that neither memory nor peripherals are using the bus

(4) Bus Grant Acknowledge is inactive which indicates that no other device is still claiming bus mastership.

INTERRUPT CONTROL (IPL, IPL, IPL,)

These input pins indicate the encoded priority level of the device requesting an interrupt. Level seven is the highest priority while level zero indicates that no interrupts are requested. Level seven can not be masked. The least significant bit is given in \overline{IPLo} and the most significant bit is contained in \overline{IPLo} . These lines must remain stable until the processor signals interrupt acknowledge (FCo \sim FC2 are all high) to insure that the interrupt is recognized.

SYSTEM CONTROL

The system control inputs are used to either reset or halt the processor and to indicate to the processor that bus errors have occurred. The three system control inputs are explained in the following paragraphs.

Bus Error (BERR)

This input informs the processor that there is a problem with the cycle currently being executed. Problems may be a result of:

- (1) Nonresponding devices
- (2) Interrupt vector number acquisition failure
- (3) Illegal access request as determined by a memory management unit
- (4) Other application dependent errors.

The bus error signal interacts with the halt signal to determine if exception processing should be performed or if the current bus cycle should be retried.

Refer to BUS ERROR AND HALT OPERATION paragraph for additional information about the interaction of the bus error and halt signals.

Reset (RES)

This bidirectional signal line acts to reset (initiate a system initialization sequence) the processor in response to an external reset signal. An internally generated reset (result of a RESET instruction) causes all external devices to be reset and the internal state of the processor is not affected. A total system reset (processor and external devices) is the result of external HALT and RESET signals applied at the same time. Refer to RESET OPERATION paragraph for additional information about reset operation.

Halt (HALT)

When this bidirectional line is driven by an external device, it will cause the processor to stop at the completion of the current bus cycle. When the processor has been halted using this input, all control signals are inactive and all three-state lines are put in their high-impedance state. Refer to BUS ERROR AND HALT OPERATION paragraph for additional information about the interaction between the halt and bus error signals.

When the processor has stopped executing instructions, such as in a double bus fault condition, the halt line is driven by the processor to indicate to external devices that the processor has stopped.

HMCS6800 PERIPHERAL CONTROL

These control signals are used to allow the interfacing of synchronous HMCS6800 peripheral devices with the asynchronous 68000. These signals are explained in the following paragraphs.

Enable (E)

This signal is the standard enable signal common to all HMCS6800 type peripheral devices. The period for this output is ten 68000 clock periods (six clocks low; four clocks high). Enable is generated by an internal ring counter which may come up in any state (i.e., at power on, it is impossible to guarantee phase relationship of E to CLK), E is a free-running clock and runs regardless of the state of the bus on the MPU.

Valid Peripheral Address (VPA)

This input indicates that the device or region addressed is a HMCS6800 family device and that data transfer should be synchronized with the enable (E) signal. This input also indicates that the processor should use automatic vectoring for an interrupt. Refer to INTERFACE WITH HMCS6800 PERIPHERALS.

Valid Memory Address (VMA)

This output is used to indicate to HMCS6800 peripheral devices that there is a valid address on the address bus and the processor is synchronized to enable. This signal only responds to a valid peripheral address (VPA) input which indicates that the peripheral is a HMCS6800 family device.

PROCESSOR STATUS (FC0, FC1, FC2)

These function code outputs indicate the state (user or supervisor) and the cycle type currently being executed, as shown in Table 14. The information indicated by the function code outputs is valid whenever address strobe (\overline{AS}) is active.

Table 14 Function Code Outputs

FC ₂ FC ₁ FC		FC ₀	Cycle Type
Low	Low	Low	(Undefined, Reserved)
Low	Low	High	User Data
Low	High	Low	User Program
Low	High	High	(Undefined, Reserved)
High	Low	Low	(Undefined, Reserved)
High	Low	High	Superviser Data
High	High	Low	Supervisor Program
High	High	High	Interrupt Acknowledge

CLOCK (CLK)

The clock input is a TTL-compatible signal that is internally buffered for development of the internal clocks needed by the processor. The clock input should not be gated off at any time, and the clock signal must conform to minimum and maximum pulse width time.

SIGNAL SUMMARY

Table 15 is a summary of all the signals discussed in the previous paragraphs.

BUS OPERATION

The following paragraphs explain control signal and bus operation during data transfer operations, bus arbitration, bus error and halt conditions, and reset operation.

Table 15 Signal Summary

		1	Active State	Three	State
Signal Name	Mnemonic	Input/Output	Active State	On BGACK	On HAL
Address Bus	A ₁ ~ A ₂₃	output	high	yes	yes
Data Bus	$D_0 \sim D_{15}$	input/output	high	yes	yes
Address Strobe	ĀS	output	low	yes	no
Read/Write	R/W	output	read-high write-low	yes	no
Upper and Lower Data Strobes	UDS, LDS	output	low	yes	no
Data Transfer Acknowledge	DTACK	input	low	no	no
Bus Request	BR	input	low	no	no
Bus Grant	BG	output	low	no	no
Bus Grant Acknowledge	BGACK	input	low	no	no
Interrupt Priority Level	IPL ₀ , IPL ₁ , IPL ₂	input	low	no	no
Bus Error	BERR	input	low	no	no
Reset	RES	input/output	low	no*	no*
Halt	HALT	input/output	low	no*	no*
Enable	E	output	high	no	no
Valid Memory Address	VMA	output	low	yes	no
Valid Peripheral Address	VPA	input	low	no	no
Function Code Output	FC ₀ , FC ₁ , FC ₂	output	high	yes	no
Clock	CLK	input	high	no	no
Power Input	V _{cc}	input	-	-	-
Ground	V _{SS}	input	-	_	-

Open drain

DATA TRANSFER OPERATIONS

Transfer of data between devices involve the following leads:

- (1) Address Bus A1 through A23
- (2) Data Bus Do through D15
- (3) Control Signals

The address and data buses are separate parallel buses used to transfer data using an asynchronous bus structure. In all cycles, the bus master assumes responsibility for deskewing all signals it issues at both the start and end of a cycle. In addition, the bus master is responsible for deskewing the acknowledge and data signals from the slave device.

The following paragraphs explain the read, write, and read-modify-write cycles. The indivisible read-modify-write cycle is the method used by the 68000 for interlocked multiprocessor communications.

Read Cycle

During a read cycle, the processor receives data from memory or a peripheral device. The processor reads bytes of data in all cases. If the instruction specifies a word (or double word) operation, the processor reads both upper and lower bytes simultaneously by asserting both upper and lower data strobes. When the instruction specifies byte operation, the processor uses an internal Ao bit to determine which byte to read and then issues the data strobe required for that byte. For bytes operations, when the Ao bit equals zero, the upper data strobe is issued. When the Ao bit equals one, the lower data strobe is issued. When the data is received, the processor correctly positions it internally.

A word read cycle flow chart is given in Figure 15. A byte

read cycle flow chart is given in Figure 16. Read cycle timing is given in Figure 17. Figure 18 details word and byte read cycle operations. Refer to these illustrations during the following detailed.

At state zero (S0) in the read cycle, the address bus (A_1 through A_{23}) is in the high impedance state. A function code is asserted on the function code output line (FC₀ through FC₂). The read/write (R/W) signal is switched high to indicate a read cycle. One half clock cycle later, at state 1, the address bus is released from the high impedance state. The function code outputs indicate which address space that this cycle will operate

In state 2, the address strobe (\overline{AS}) is asserted to indicate that there is a valid address on the address bus and the upper and lower data strobe $(\overline{UDS}, \overline{LDS})$ is asserted as required. The memory or peripheral device uses the address bus and the address strobe to determine if it has been selected. The selected device uses the read/write signal and the data strobe to place its information on the data bus. Concurrent with placing data on the data bus, the selected device asserts data transfer acknowledge (\overline{DTACK}) .

Data transfer acknowledge must be present at the processor at the start of state 5 or the processor will substitute wait states for states 5 and 6. State 5 starts the synchronization of the returning data transfer acknowledge. At the end of state 6 (beginning of state 7) incoming data is latched into an internal data bus holding register.

During state 7, address strobe and the upper and/or lower data strobes are negated. The address bus is held valid through state 7 to allow for static memory operation and signal skew.



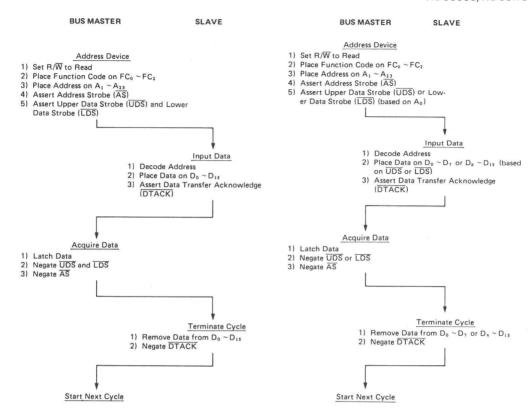


Figure 15 Word Read Cycle Flow Chart

Figure 16 Byte Read Cycle Flow Chart

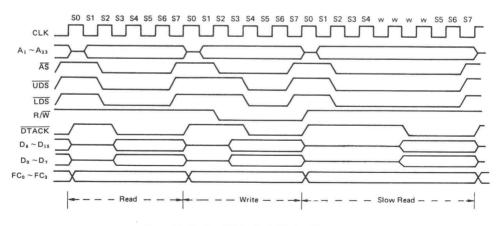


Figure 17 Read and Write Cycle Timing Diagram

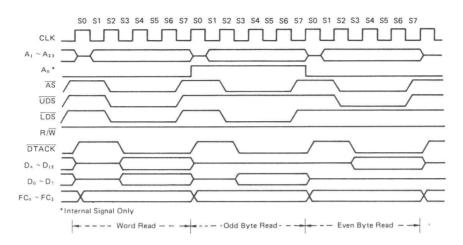


Figure 18 Word and Byte Read Cycle Timing Diagram

The read/write signal and the function code outputs also remain valid through state 7 to ensure a correct transfer operation. The slave device keeps its data asserted until it detects the negation of either the address strobe or the upper and/or lower data strobe. The slave device must remove its data and data transfer acknowledge within one clock period of recognizing the negation of the address or data strobes. Note that the data bus might not become free and data transfer acknowledge might not be removed until state 0 or 1.

When address strobe is negated, the slave device is released. Note that a slave device must remain selected as long as address strobe is asserted to ensure the correct functioning of the readmodify-write cycle.

Write Cycle

During a write cycle, the processor sends data to memory or a peripheral device. The processor writes bytes of data in all cases. If the instruction specifies a word operation, the processor writes both bytes. When the instruction specifies a byte operation, the processor uses an internal A_0 bit to determine which byte to write and then issues the data strobe required for that byte. For byte operations, when the A_0 bit equals zero, the upper data strobe is issued. When the A_0 bit equals one, the lower data strobe is issued. A word write cycle flow chart is given in Figure 19. A byte write cycle flow chart is given in Figure 20. Write cycle timing is given in Figure 17. Figure 21 details word and byte write cycle operation. Refer to these illustrations during the following detailed discussion.

At state zero (S0) in the write cycle, the address bus (A_1 through A_{23}) is in the high impedance state. A function code is asserted on the function code output line (FC₀ through FC₂).

(NOTE) The read/write (R√W) signal remains high until state 2 to prevent bus conflicts with preceding read cycles. The data bus is not driven until state 3.

One half clock later, at state 1, the address bus is released from the high impedance state. The function code outputs indicate which address space that this cycle will operate on.

In state 2, the address strobe (AS) is asserted to indicate that there is a valid address on the address bus. The memory or peripheral device uses the address bus and the address strobe to determine if it has been selected. During state 2, the read/write signal is switched low to indicate a write cycle. When external processor data bus buffers are required, the read/write line provides sufficient directional control. Data is not asserted during this state to allow sufficient turn around time for external data buffers (if used). Data is asserted onto the data bus during state 3.

In state 4, the data strobes are asserted as required to indicate that the data bus is stable. The selected device uses the read/write signal and the data strobes to take its information from the data bus. The selected device asserts data transfer acknowledge (DTACK) when it has successfully stored the data.

Data transfer acknowledge must be present at the processor at the start of state 5 or the processor will substitute wait states for states 5 and 6. State 5 starts the synchronization of the returning data transfer acknowledge.

During state 7, address strobe and the upper and/or lower data strobes are negated. The address and data buses are held valid through state 7 to allow for static memory operation and signal skew. The read/write signal and the function code outputs also remain valid through state 7 to ensure a correct transfer operation. The slave device keeps its data transfer acknowledge asserted until it detects the negation of either the address strobe or the upper and/or lower data strobe. The slave device must remove its data transfer acknowledge within one clock period after recognizing the negation of the address or data strobes. Note that the processor releases the data bus at the end of state 7 but that data transfer acknowledge might not be removed until state 0 or 1. When address strobe is negated, the slave device is released.



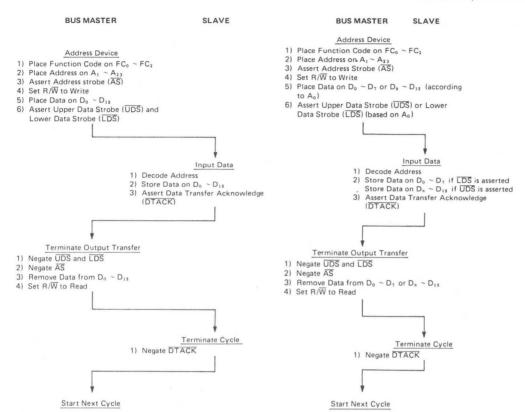


Figure 19 Word Write Cycle Flow Chart

Figure 20 Byte Write Cycle Flow Chart

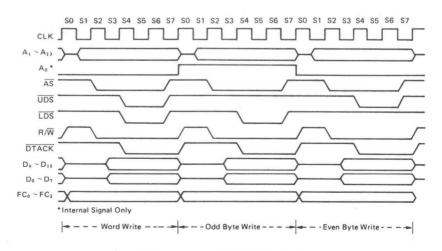


Figure 21 Word and Byte Write Cycle Timing Diagram



Read-Modify-Write Cycle

The read-modify-write cycle performs a read, modifies the data in the arithmetic-logic unit, and writes the data back to the same address. In the 68000 this cycle is indivisible in that the address strobe is asserted throughout the entire cycle. The test and set (TAS) instruction uses this cycle to provide meaningful communication between processors in a multiple processor environment. This instruction is the only instruction that uses the read-modify-write cycle and since the test and set instruction only operates on bytes, all read-modify-write cycles are byte operations. A read-modify-write cycle flow chart is given in Figure 22 and a timing diagram is given in Figure 23. Refer to these illustrations during the following detailed discussions.

At state zero (S0) in the read-modify-write cycle, the address bus (A_1 through A_{23}) is in the high impedance state. A function code is asserted on the function code output line (FC₀ through FC₂). The read/write (R/ \overline{W}) signal is switched high to indicate a read cycle. One half clock cycle later, at state 1, the address bus is released from the high impedance state. The function code outputs indicate which address space that this cycle will operate on.

In state 2, the address strobe (AS) is asserted to indicate that there is a valid address on the address bus and the upper or lower data strobe (\overline{UDS} , \overline{LDS}) is asserted as required. The memory or peripheral device uses the address bus and the address strobe to determine if it has been selected. The selected device uses the read/write signal and the data strobe to place its information on the data bus. Concurrent with placing data on the data bus, the selected device asserts data transfer acknowledge (\overline{DTACK}).

Data transfer acknowledge must be present at the processor at the start of state 5 or the processor will substitute wait states for states 5 and 6. State 5 starts the synchronization of the returning data transfer acknowledge. At the end of state 6 (beginning of state 7) incoming data is latched into an internal data bus holding register.

During state 7, the upper or lower data strobe is negated. The address bus, address strobe, read/write signal, and function code outputs remain as they were in preparation for the write portion of the cycle. The slave device keeps its data asserted until it detects the negation of the upper or lower data strobe. The slave device must remove its data and data transfer acknowledge within one clock period of recognizing the negation of the data strobes. Internal modification of data may occur from state 8 to state 11.

(NOTE) The read/write signal remains high until state 14 to prevent bus conflicts with the preceding read portion of the cycle and the data bus is not asserted by the processor until state 15.

In state 14, the read/write signal is switched low to indicate a write cycle. When external processor data bus buffers are required, the read/write line provides sufficient directional control. Data is not asserted during this state to allow sufficient turn around time for external data buffers (if used). Data is asserted onto the data bus during state 15.

In state 16, the data strobe is asserted as required to indicate

that the data bus is stable. The selected device uses the read/write signal and the data strobe to take its information from the data bus. The selected device asserts data transfer acknowledge (DTACK) when it has successfully stored its data.

Data transfer acknowledge must be present at the processor at the start of state 17 or the processor will substitute wait states for states 17 and 18. State 17 starts the synchronization of the returning data transfer acknowledge for the write portion of the cycle. The bus interface circuitry issues requests for subsequent internal cycles during state 18.

During state 19, address strobe and the upper or lower data strobe is negated. The address and data buses are held valid through state 19 to allow for static memory operation and signal skew. The read/write signal and the function code outputs also remain valid through state 19 to ensure a correct transfer operation. The slave device keeps its data transfer acknowledge asserted until it detects the negation of either the address strobe or the upper or lower data strobe. The slave device must remove its data transfer acknowledge within once clock period after recognizing the negation of the address or data strobes. Note that the processor releases the data bus at the end of state 19 but that data transfer acknowledge might not be removed until state 0 or 1. When address strobe is negated the slave device is released.

BUS ARBITRATION

Bus arbitration is a technique used by master-type devices to request, be granted, and acknowledge bus mastership. In its simplest form, it consists of:

(1) Asserting a bus mastership request.

(2) Receiving a grant that the bus is available at the end of the current cycle.

(3) Acknowledging that mastership has been assumed.

Figure 24 is a flow chart showing the detail involved in a request from a single device. Figure 25 is a timing diagram for the same operations. This technique allows processing of bus requests during data transfer cycles.

The timing diagram shows that the bus request is negated at the time that an acknowledge is asserted. This type of operation would be true for a system consisting of the processor and one device capable of bus mastership. In systems having a number of devices capable of bus mastership, the bus request line from each device is wire ORed to the processor. In this system, it is easy to see that there could be more than one bus request being made. The timing diagram shows that the bus grant signal is negated a few clock cycles after the transition of the acknowledge (BGACK) signal.

However, if the bus requests are still pending, the processor will assert another bus grant within a few clock cycles after it was negated. This additional assertion of bus grant allows external arbitration circuitry to select the next bus master before the current bus master has completed its requirements. The following paragraphs provide additional information about the three steps in the arbitration process.

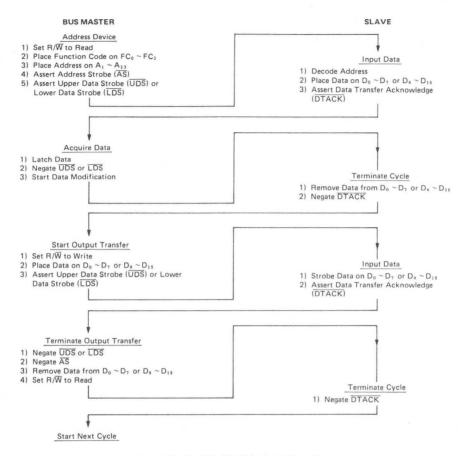


Figure 22 Read-Modify-Write Cycle Flow Chart

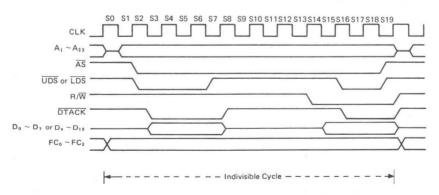


Figure 23 Read-Modify-Write Cycle Timing Diagram

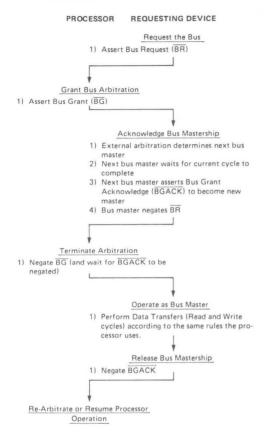


Figure 24 Bus Arbitration Cycle Flow Chart

Requesting the Bus

External devices capable of becoming bus masters request the bus by asserting the bus request (BR) signal. This is a wire ORed signal (although it need not be constructed from open collector devices) that indicates to the processor that some external device requires control of the external bus. The processor is effectively at a lower bus priority level that the external device and will relinquish the bus after it has completed the last bus cycle it has started.

When no acknowledge is received before the bus request signal goes inactive, the processor will continue processing when it detects that the bus request is inactive. This allows ordinary processing to continue if the arbitration circuitry responded to noise inadvertently.

Receiving the Bus Grant

The processor asserts bus grant (\overline{BG}) as soon as possible. Normally this is immediately after internal synchronization. The only exception to this occurs when the processor has made an internal decision to execute the next bus cycle but has not progressed far enough into the cycle to have asserted the address strobe (\overline{AS}) signal. In this case, bus grant will not be asserted until one clock after address strobe is asserted to indicate to external devices that a bus cycle is being executed.

The bus grant signal may be routed through a daisy-chained network or through a specific priority-encoded network. The processor is not affected by the external method of arbitration as long as the protocol is obeyed.

Acknowledgement of Mastership

Upon receiving a bus grant, the requesting device waits until address strobe, data transfer acknowledge, and bus grant acknowledge are negated before issuing its own BGACK. The negation of the address strobe indicates that the previous master has completed its cycle, the negation of bus grant acknowledge indicates that the previous master has released the bus. (While address strobe is asserted no device is allowed to "break into" a cycle.) The negation of data transfer acknowledge indicates the previous slave has terminated its connection to the previous master. Note that in some applications data

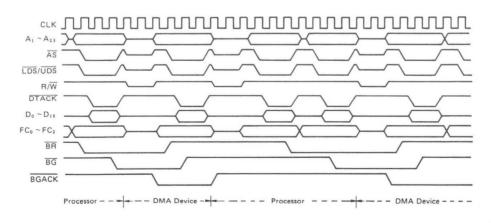


Figure 25 Bus Arbitration Cycle Timing Diagram



transfer acknowledge might not enter into this function. General purpose devices would then be connected such that they were only dependent on address strobe. When bus grant acknowledge is issued the device is bus master until it negates bus grant acknowledge. Bus grant acknowledge should not be negated until after the bus cycle(s) is (are) completed. Bus mastership is terminated at the negation of bus grant acknowledge.

The bus request from the granted device should be dropped after bus grant acknowledge is asserted. If a bus request is still pending, another bus grant will be asserted within a few clocks of the negation of bus grant. Refer to Bus Arbitration Control section. Note that the processor does not perform any external bus cycles before it re-asserts bus grant.

BUS ARBITRATION CONTROL

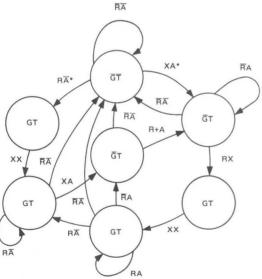
The bus arbitration control unit in the 68000 is implemented with a finite state machine. A state diagram of this machine is shown in Figure 26. All asynchronous signals to the 68000 are synchronized before being used internally. This synchronization is accomplished in a maximum of one cycle of the system clock, assuming that the asynchronous input setup time (#47) has been met (see Figure 27). The input signal is sampled on the falling edge of the clock and is valid internally after the next falling edge.

As shown in Figure 26, input signals labeled R and A are internally synchronized on the bus request and bus grant acknowledge pins respectively. The bus grant output is lebeled G and the internal three-state control signal T. If T is true, the address, data, function code line, and control buses are placed in a high-impedance state when AS is negated. All signals are shown in positive logic (active high) regardless of their true active voltage level.

State changes (valid outputs) occur on the next rising edge after the internal signal is valid.

A timing diagram of the bus arbitration sequence during a processor bus cycle is shown in Figure 28. The bus arbitration sequence while the bus is inactive (i.e., executing internal operations such as a multiply instruction) is shown in Figure 29.

If a bus request is made at a time when the MPU has already begun a bus cycle but AS has not been asserted (bus state SO), BG will not be asserted on the next rising edge. Instead, BG will be delayed until the second rising edge following it's internal assertion. This sequence is shown in Figure 30.



R = Bus Request Internal

Figure 26 State Diagram of 68000 Bus **Arbitration Unit**

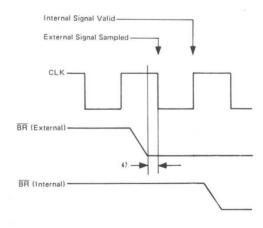


Figure 27 Timing Relationship of External Asynchronous Inputs to Internal Signals

A = Bus Grant Acknowledge Internal

G = Bus Grant

T = Three-State Control to Bus Control Logic * *

X = Don't Care

^{*} State machine will not change state if bus is in SO. Refer to BUS ARBITRATION CONTROL for additional information.

* The address bus will be placed in the high impedance state if T is asserted and AS is negated.

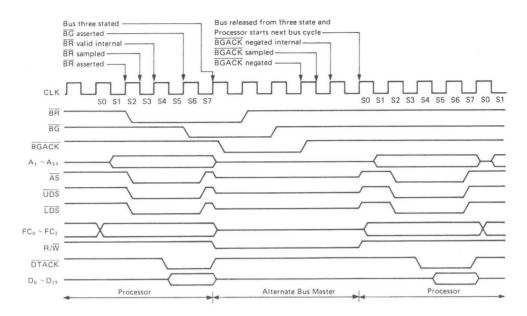


Figure 28 Bus Arbitration During Processor Bus Cycle

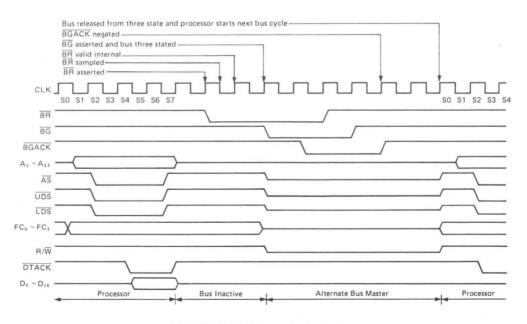


Figure 29 Bus Arbitration with Bus Inactive



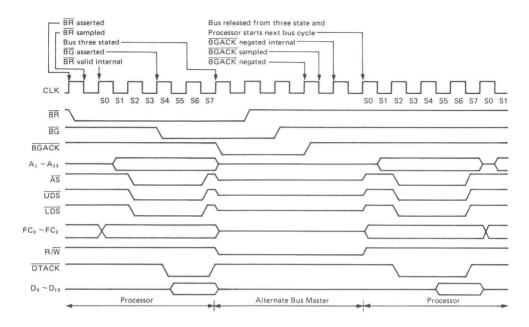


Figure 30 Bus Arbitration During Processor Bus Cycle Special Case

BUS ERROR AND HALT OPERATION

In a bus architecture that requires a handshake from an external device, the possibility exists that the handshake might not occur. Since different systems will require a different maximum response time, a bus error input is provided. External circuitry must be used to determine the duration between address strobe and data transfer acknowledge before issuing a bus error signal. When a bus error signal is received, the processor has two options initiate a bus error exception sequence or try running the bus cycle again.

Exception Sequence

When the bus error signal is asserted, the current bus cycle is terminated. If \overline{BERR} is asserted before the falling edge of S2, \overline{AS} will be negated in S7 in either a read or write cycle. As long as \overline{BERR} remains asserted, the data and address buses will be in the high-impedance state. When \overline{BERR} is negated, the processor will begin stacking for exception processing. Figure 31 is a timing diagram for the exception sequence. The sequence is composed of the following elements.

- (1) Stacking the program counter and status register
- (2) Stacking the error information
- (3) Reading the bus error vector table entry
- (4) Executing the bus error handler routine

The stacking of the program counter and the status register is the same as if an interrupt had occurred. Several additional

items are stacked when a bus error occurs. These items are used to determine the nature of the error and correct it, if possible. The bus error vector is vector number two located at address \$000008. The processor loads the new program counter from this location. A software bus error handler routine is then executed by the processor. Refer to EXCEPTION PROCESSING for additional information.

Re-Running the Bus Cycle

When, during a bus cycle, the processor receives a bus error signal and the halt pin is being driven by an external device, the processor enters the re-run sequence. Figure 32 is a timing diagram for re-running the bus cycle.

The processor terminates the bus cycle, then puts the address and data output lines in the high-impedance state. The processor remains "halted," and will not run another bus cycle until the halt signal is removed by external logic. Then the processor will re-run the previous bus cycle using the same address, the same function codes, the same data (for a write operation), and the same controls. The bus error signal should be removed at least one clock cycle before the halt signal is removed.

(NOTE) The processor will not re-run a read-modify-write cycle. This restriction is made to guarantee that the entire cycle runs correctly and that the write operation of a Test-and-Set operation is performed without ever releasing AS. If BERR and HALT are asserted during a read-modify-write bus cycle, a bus error operation results.

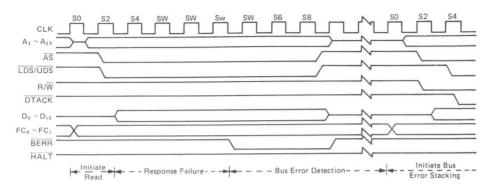


Figure 31 Bus Error Timing Diagram

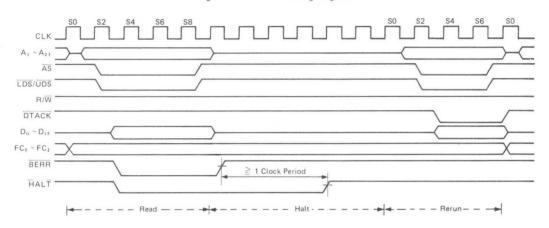


Figure 32 Re-Run Bus Cycle Timing Information

Halt Operation with No Bus Error

The halt input signal to the 68000 perform a Halt/Run/Single-Step function in a similar fashion to the HMCS6800 halt function. The halt and run modes are somewhat self explanatory in that when the halt signal is constantly active the processor "halts" (does nothing) and when the halt signal is constantly inactive the processor "runs" (does something).

The single-step mode is derived from correctly timed transitions on the halt signal input. It forces the processor to execute a single bus cycle by entering the "run" mode until the processor starts a bus cycle then changing to the "halt" mode. Thus, the single-step mode allows the user to proceed through (and therefore debug) processor operations one bus cycle at a time.

Figure 33 details the timing required for correct single-step operations and Figure 34 shows a simple circuit for providing the single-step function. Some care must be exercised to avoid harmful interactions between the bus error signal and the halt

pin when using the single cycle mode as a debugging tool. This is also true of interactions between the halt and reset lines since these can reset the machine.

When the processor completes a bus cycle after recognizing that the halt signal is active, most three-state signals are put in the high-impedance state. These include:

(1) Address lines

(2) Data lines

This is required for correct performance of the re-run bus cycle operation.

While the processor is honoring the halt request, bus arbitration performs as usual. That is, halting has no effect on bus arbitration. It is the bus arbitration function that removes the control signals from the bus.

The halt function and the hardware trace capability allow the hardware debugger to trace single bus cycles or single instructions at a time. These processor capabilities, along with a software debugging package, give total debugging flexibility.



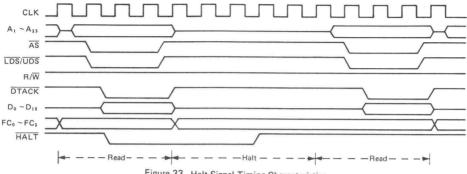


Figure 33 Halt Signal Timing Characteristics

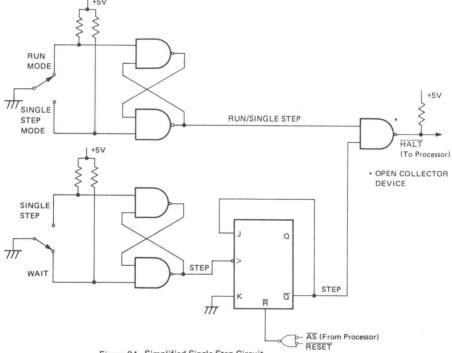


Figure 34 Simplified Single-Step Circuit

Double Bus Faults

When a bus error exception occurs, the processor will attempt to stack several words containing information about the state of the machine. If a bus error exception occurs during the stacking operation, there have been two bus errors in a row. This is commonly referred to as a double bus fault. When a double bus fault occurs, the processor will halt. Once a bus error exception has occurred, any bus error exception occurring before the execution of the next instruction constitutes a double bus fault.

Note that a bus cycle which is re-run does not constitute a bus error exception, and does not contribute to a double bus fault. Note also that this means that as long as the external hardware requests it, the processor will continue to re-run the same bus cycle.

The bus error pin also has an effect on processor operation after the processor receives an external reset input. The processor reads the vector table after a reset to determine the address to start program execution. If a bus error occurs while reading the vector table (or at any time before the first instruction is executed), the processor reacts as if a double bus fault has occurred and it halts. Only an external reset will start a halted processor.

RESET OPERATION

The reset signal is a bidirectional signal that allows either the processor or an external signal to reset the system. Figure 35 is a timing diagram for the reset operations. Both the halt and reset lines must be asserted to ensure total reset of the processor.

When the reset and halt lines are driven by an external device, it is recognized as an entire system reset, including the processor. The processor responds by reading the reset vector table entry (vector unumber zero, address \$000000) and loads it into the supervisor stack pointer (SSP). Vector table entry number one at address \$000004 is read next and loaded into the program counter. The processor initializes the status register to an interrupt level of seven. No other

registers are affected by the reset sequence.

When a RESET instruction is executed, the processor drives the reset pin for 124 clock periods. In this case, the processor is trying to reset the rest of the system. Therefore, there is no effect on the internal state of the processor. All of the processor's internal registers and the status register are unaffected by the execution of a RESET instruction. All external devices connected to the reset line should be reset at the completion of the RESET instruction.

Asserting the Reset and Halt pins for 10 clock cycles will cause a processor reset, except when $V_{\rm CC}$ is initially applied to the processor. In this case, an external reset must be applied for 100 milliseconds.

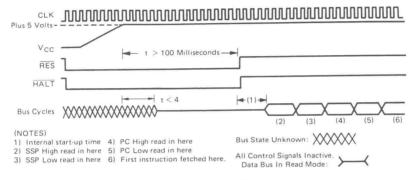


Figure 35 Reset Operation Timing Diagram

THE RELATIONSHIP OF DTACK, BERR, AND HALT

In order to properly control termination of a bus cycle for a re-run or a bus error condition, DTACK, BERR, and HALT should be asserted and negated on the rising edge of the 68000 clock. This will assure that when two signals are asserted simultaneously, the required setup time (#47) for both of them will be met during the same bus state.

This, or some equivalent precaution, should be designed external to the 68000. Parameter #48 is intended to ensure this operation in a totally asynchronous system, and may be ignored if the above conditions are met.

The preferred bus cycle terminations may be summarized as follows (case numbers refer to Table 16):

Normal Termination: DTACK occurs first (case 1).

Halt Termination: HALT is asserted at the same time or

before DTACK and BERR remains

negated (cases 2 and 3).

Bus Error Termination: BERR is asserted in lieu of, at the same time, or before DTACK (case 4); BERR

is negated at the same time or after

DTACK.

Re-Run Termination: HALT and BERR are asserted in lieu

of, at the same time, or before DTACK

(cases 6 and 7); \overline{HALT} must be held at least one cycle after \overline{BERR} . Case 5 indicates \overline{BERR} may precede \overline{HALT} which allows fully asynchronous assertion.

Table 16 details the resulting bus cycle termination under various combinations of control signal sequences. The negation of these same control signals under several conditions is shown in Table 17 (DTACK is assumed to be negated normally in all cases; for best results, both DTACK and BERR should be negated when address strobe is negated.)

Example A: A system uses a watch-dog timer to terminate accesses to un-populated address space. The timer asserts \overline{DTACK} and \overline{BERR} simultaneously after time-out. (case 4)

Example B: A system uses error detection on RAM contents. Designer may (a) delay \$\overline{DTACK}\$ until data verified, and return \$\overline{BERR}\$ and \$\overline{HALT}\$ simultaneously to re-run error cycle (case 6), or if valid, return \$\overline{DTACK}\$; (b) delay \$\overline{DTACK}\$ until data verified, and return \$\overline{BERR}\$ at same time as \$\overline{DTACK}\$ until data in error (case 4); (c) return \$\overline{DTACK}\$ prior to data verification, as described in previous section. If data invalid, \$\overline{BERR}\$ is asserted (case 1) in next cycle. Error-handling software must know how to recover error cycle.

Table 16 DTACK, BERR, HALT Assertion Results

Case No. Control Signa	Control Signal		on Rising of State	Result
		N	N + 2	
1	DTACK BERR HALT	A NA NA	S X X	Normal cycle terminate and continue.
2	DTACK BERR HALT	A NA A	S X S	Normal cycle terminate and halt. Continue when HALT removed.
3	DTACK BERR HALT	NA NA A	A NA S	Normal cycle terminate and halt. Continue when HALT removed.
4	DTACK BERR HALT	X A NA	X S NA	Terminate and take bus error trap.
5	DTACK BERR HALT	NA A NA	X S A	Terminate and re-run,
6	DTACK BERR HALT	X A A	X S S	Terminate and re-run when HALT removed.
7	DTACK BERR HALT	NA NA A	X A S	Terminate and re-run when HALT removed.

gend:

N - The number of the current even bus state (e.g., S4, S6, etc.)

A — Signal is asserted in this bus state

NA — Signal is not asserted in this state

X - Don't care

- Signal was asserted in previous state and remains asserted in this state

Table 17 BERR and HALT Negation Results

Conditions of Termination in	Control Signal	Negated on Rising Edge of State			Results — Next Cycle
Table A		Ν		N + 2	
Bus Error	BERR HALT	•	or or	•	Takes bus error trap.
Re-run	BERR HALT	•	or	•	Illegal sequence; usually traps to vector number 0.
Re-run	BERR HALT	•		•	Re-runs the bus cycle.
Normal	BERR HALT	•	or	•	May lengthen next cycle.
Normal	BERR	•	or	none	If next cycle is started it will be terminated as a bus error

ASYNCHRONOUS VERSUS SYNCHRONOUS OPERATION Asynchronous Operation

To achieve clock frequency independence at a system level, the 68000 can be used in an asynchronous manner. This entails using only the bus handshake lines (AS, UDS, LDS, DTACK, BERR, HALT, and VPA) to control the data transfer. Using this method, AS signals the start of a bus cycle and the data strobes are used as a condition for valid data on a write cycle. The slave device (memory or peripheral) then responds by placing the requested data on the data bus for a read cycle or latching data on a write cycle and asserting the data transfer acknowledge signal (DTACK) to terminate the bus cycle. If no slave responds or the access is invalid, external control logic

asserts the \overline{BERR} , or \overline{BERR} and \overline{HALT} , signal to abort or re-run the bus cycle.

The DTACK signal is allowed to be asserted before the data from a slave device is valid on a read cycle. The length of time that DTACK may precede data is given as parameter #31 and it must be met in any asynchronous system to insure that valid data is latched into the processor. Notice that there is no maximum time specified from the assertion of AS to the assertion of DTACK. This is because the MPU will insert wait cycles of one clock period each until DTACK is recognized.

The BERR signal is allowed to be asserted after the DTACK signal is asserted. BERR must be asserted within the time given as parameter #48 after DTACK is asserted in any asynchronous

system to insure proper operation. If this maximum delay time is violated, the processor may exhibit erratic behavior.

Synchronous Operation

To allow for those systems which use the system clock as a signal to generate DTACK and other asynchronous inputs, the asynchronous input setup time is given as parameter #47. If this setup is met on an input, such as DTACK, the processor is guaranteed to recognize that signal on the next falling edge of the system clock. However, the converse is not true — if the input signal does not meet the setup time it is not guaranteed not to be recognized. In addition, if DTACK is recognized on a falling edge, valid data will be latched into the processor (on a read cycle) on the next falling edge provided that the data meets the setup time given as parameter #27. Given this, parameter #31 may be ignored. Note that if DTACK is asserted, with the required setup time, before the falling edge of S4, no wait status will be incurred and the bus cycle will run at its maximum speed of four clock periods.

In order to assure proper operation in a synchronous system when BERR is asserted after DTACK. BERR must meet the setup time parameter #27A prior to the falling edge of the clock one clock cycle after DTACK was recognized. This setup time is critical to proper operation, and the HD68000 may exhibit erratic behavior if it is violated.

(NOTE)

During an active bus cycle, VPA and BERR are sampled on every falling edge of the clock starting with SO. DTACK is sampled on every falling edge of the clock starting with S4 and data is latched on the falling edge of S6 during a read. The bus cycle will then be terminated in S7 except when BERR is asserted in the absence of DTACK, in which case it will terminate one clock cycle later in S9.

■ PROCESSING STATES

This section describes the actions the 68000 which are outside the normal processing associated with the execution of instructions. The functions of the bits in the supervisor portion of the status register are covered: the supervisor/user bit, the trace enable bit, and the processor interrupt priority mask. Finally, the sequence of memory references and actions taken by the processor on exception conditions is detailed.

The 68000 is always in one of three processing states: normal, exception, or halted. The normal processing state is that associated with instruction execution; the memory references are to fetch instructions and operands, and to store results. A special case of the normal state is the stopped state which the processor enters when a STOP instruction is executed. In this state, no further memory references are made.

The exception processing state is associated with interrupts, trap instructions, tracing and other exceptional conditions. The exception may be internally generated by an instruction or by an unusual condition arising during the execution of an instruction. Externally, exception processing can be forced by an interrupt, by a bus error, or by a reset. Exception processing is designed to provide an efficient context switch so that the processor may handle unusual conditions.

The halted processing state is an indication of catastrophic hardware failure. For example, if during the exception processing of a bus error another bus error occurs, the processor assumes that the system is unusable and halts. Only an external reset can restart a halted processor. Note that a processor in the stopped state is not in the halted state, nor vice versa.

PROCESSING STATES

NORMAL	INSTRUCTION EXECUTION (INCLUDING STOP)
EXCEPTION	INTERRUPTS TRAPS TRACING ETC.
HALTED	HARDWARE HALT DOUBLE BUS FAULT

PRIVILEGE STATES

The processor operates in one of two states of privilege: the "user" state or the "supervisor" state. The privilege state determines which operations are legal, are used to choose between the supervisor stack pointer and the user stack pointer in instruction references, and may be used by an external memory management device to control and translate accesses.

The privileges state is a mechanism for providing security in a computer system. Programs should access only their own code and data areas, and ought to be restricted from accessing information which they do not need and must not modify.

The privilege mechanism provides security by allowing most programs to execute in user state. In this state, the accesses are controlled, and the effects on other parts of the system are limited. The operating system executes in the supervisor state, has access to all resources, and performs the overhead tasks for the user state programs.

SUPERVISOR STATE

The supervisor state is the higher state of privilege. For instruction execution, the supervisor state is determined by the S-bit of the status register; if the S-bit is asserted (high), the processor is in the supervisor state. All instructions can be executed in the supervisor state. The bus cycles generated by instructions executed in the supervisor state are classified as supervisor references. While the processor is in the supervisor privilege state, those instructions which use either the system stack pointer implicitly or address register seven explicitly access the supervisor stack pointer.

All exception processing is done in the supervisor state, regardless of the setting of the S-bit. The bus cycles generated during exception processing are classified as supervisor references. All stacking operations during exception processing use the supervisor stack pointer.

USER STATE

The user state is the lower state of privilege. For instruction execution, the user state is determined by the S-bit of the status register; if the S-bit is negated (low), the processor is executing instructions in the user state.

Most instructions execute the same in user state as in the supervisor state. However, some instructions which have important system effects are made privileged. User programs are not permitted to execute the STOP instruction, or the



RESET instruction. To ensure that a user program cannot enter the supervisor state except in a controlled manner, the instructions which modify the whole status register are privileged. To aid in debugging programs which are to be used as operating systems, the move to user stack pointer (MOVE to USP) and move from user stack pointer (MOVE from USP) instructions are also privileged.

The bus cycles generated by an instruction executed in user state are classified as user state references. This allows an external memory management device to translate the address and to control access to protected portions of the address space. While the processor is in the user privilege state, those instructions which use either the system stack pointer implicitly, or address register seven explicitly, access the use stack pointer.

PRIVILEGE STATE CHANGES

Once the processor is in the user state and executing instructions, only exception processing can change the privilege state. During exception processing, the current setting of the S-bit of the status register is saved and the S-bit is asserted, putting the processing in the supervisor state. Therefore, when instruction execution resumes at the address specified to process the exception, the processor is in the supervisor privilege state.

USER/SUPERVISOR MODES

TRANSITION ONLY MAY OCCUR
DURING EXCEPTION PROCESSING



TRANSITION MAY BE MADE BY: RTE; MOVE, ANDI, EORI TO STATUS WORD

REFERENCE CLASSIFICATION

When the processor makes a reference, it classifies the kind of reference being made, using the encoding on the three function code output lines. This allows external translation of addresses, control of access, and differentiation of special processor states, such as interrupt acknowledge. Table 18 lists the classification of references.

Table 18 Reference Classification

Funct	ion Code (Output	Reference Class	
FC ₂	FC ₁	FC ₀	neterence Class	
0	0	0	(Unassigned)	
0	0	1	User Data	
0	1	0	User Program	
0	1	1	(Unassigned)	
1	0 0		(Unassigned)	
1	0	1	Supervisor Data	
1 1 0		0	Supervisor Program	
1	1	1	Interrupt Acknowledge	

EXCEPTION PROCESSING

Before discussing the details of interrupts, traps, and tracing, a general description of exception processing is in order. The processing of an exception occurs in four steps, with variations for different exception causes. During the first step, a temporary copy of the status register is made, and the status register is set for exception processing. In the second step the exception vector is determined, and the third step is the saving of the current processor context. In the fourth step a new context is obtained, and the processor switches to instruction processing.

EXCEPTION VECTORS

Exception vectors are memory locations from which the processor fetches the address of a routine which will handle that exception. All exception vectors are two words in length (Figure 36), except for the reset vector, which is four words. All exception vectors lie in the supervisor data space, except for the reset vector which is in the supervisor program space. A vector number is an eight-bit number which, when multiplied by four, gives the address of an exception vector. Vector numbers are generated internally or externally depending on the cause of the exception. In the case of interrupts, during the interrupt acknowledge bus cycle, a peripheral provides an 8-bit vector number (Figure 37) to the processor on data bus lines D_0 through D_7 . The processor translates the vector number into a full 24-bit address, as shown in Figure 38. The memory layout for exception vectors is given in Table 19.

As shown in Table 19, the memory layout is 512 words long (1024 bytes). It starts at address 0 and proceeds through address 1023. This provides 255 unique vectors; some of these are reserved for TRAPS and other system functions. Of the 255, there are 192 reserved for user interrupt vectors. However, there is no protection on the first 64 entries, so user interrupt vectors may overlap at the discretion of the systems designer.

KINDS OF EXCEPTIONS

Exceptions can be generated by either internal or external causes. The externally generated exceptions are the interrupts and the bus error and reset requests. The interrupts are requests from peripheral devices for processor action while the bus error and reset inputs are used for access control and processor restart. The internally generated exceptions come from instructions, or from address error or tracing. The trap (TRAP), trap on overflow (TRAPV), check register against bounds (CHK) and divide (DIV) instructions all can generate exceptions as part of their instruction execution. In addition, illegal instructions, word fetches from odd addresses and privilege violations cause exceptions. Tracing behaves like a very high priority, internally generated interrupt after each instruction execution.

EXCEPTION PROCESSING SEQUENCE

Exception processing occurs in four identifiable steps. In the first step, an internal copy is made of the status register. After the copy is made, the S-bit is asserted, putting the processor into the supervisor privilege state. Also, the T-bit is negated which will allow the exception handler to execute unhindered by tracing. For the reset and interrupt exceptions, the interrupt priority mask is also updated.

In the second step, the vector number of the exception is determined. For interrupts, the vector number is obtained by a processor fetch, classified as an interrupt acknowledge. For all other exceptions, internal logic provides the vector number. This vector number is then used to generate the address of the exception vector.



Figure 36 Exception Vector Format



Where

v7 is the MSB of the Vector Number v0 is the LSB of the Vector Number

Figure 37 Peripheral Vector Number Format

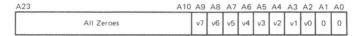


Figure 38 Address Translated From 8-Bit Vector Number

Table 19 Exception Vector Assignment

Vector		Address	Assignment		
Number(s)	Dec	Hex	Space	Assignment	
0	0	000	SP	Reset: Initial SSP	
_	4	004	SP	Reset: Initial PC	
2	8	008	SD	Bus Error	
3	12	00C	SD	Address Error	
4	16	010	SD	Illegal Instruction	
5	20	014	SD	Zero Divide	
6	24	018	SD	CHK Instruction	
7	28	01C	SD	TRAPV Instruction	
8	32	020	SD	Privilege Violation	
9	36	024	SD	Trace	
10	40	028	SD	Line 1010 Emulator	
11	44	02C	SD	Line 1111 Emulator	
12*	48	030	SD	(Unassigned, reserved)	
13*	52	034	SD	(Unassigned, reserved)	
14*	56	038	SD	(Unassigned, reserved)	
15	60	03C	SD	Uninitialized Interrupt Vecto	
10 - 22*	64	040	SD	(Unassigned, reserved)	
16 ~ 23*	95	05F			
24	96	060	SD	Spurious Interrupt	
25	100	064	SD	Level 1 Interrupt Autovector	
26	104	068	SD	Level 2 Interrupt Autovector	
27	108	06C	SD	Level 3 Interrupt Autovector	
28	112	070	SD	Level 4 Interrupt Autovector	
29	116	074	SD	Level 5 Interrupt Autovector	
30	120	078	SD	Level 6 Interrupt Autovector	
31	124	07C	SD	Level 7 Interrupt Autovector	
32 ~ 47	128	080	SD	TRAP Instruction Vectors	
32 - 47	191	OBF	30		
48 ~ 63*	192	0C0	00	(Upassianed reserved)	
40 - 03	255	OFF	SD	(Unassigned, reserved)	
61 ~ 2EE	256	100	20	Hear Intervient Masters	
64 ~ 255	1023	3FF	SD	User Interrupt Vectors	

SP: Supervisor program, SD: Supervisor data

^{*} Vector numbers 12, 13, 14, 16 through 23 and 48 through 63 are reserved for future enhancements by Hitachi. No user peripheral devices should be assigned these numbers.



The third step is to save the current processor status, except for the reset exception. The current program counter value and the saved copy of the status register are stacked using the supervisor stack pointer as shown in Figure 39. The program counter value stacked usually points to the next unexecuted instruction, however for bus error and address error, the value stacked for the program counter is unpredictable, and may be incremented from the address of the instruction which

caused the error. Additional information defining the current context is stacked for the bus error and address error exceptions.

The last step is the same for all exceptions. The new program counter value is fetched from the exception vector. The processor then resumes instruction execution. Then instruction at the address given in the exception vector is fetched, and normal instruction decoding and execution is started.

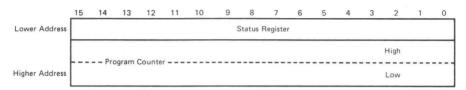


Figure 39 Exception Stack Order (Group 1, 2)

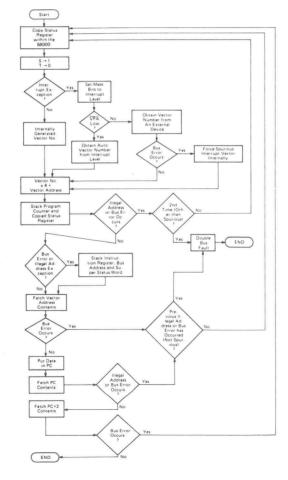


Figure 40 Exception Processing Sequence (Not Reset)



MULTIPLE EXCEPTIONS

These paragraphs describe the processing which occurs when multiple exceptions arise simultaneously. Exceptions can be grouped according to their occurrence and priority. The Group 0 exceptions are reset, bus error, and address error. These exceptions cause the instruction currently being executed to be aborted, and the exeception processing to commence within two clock cycles. The Group 1 exceptions are trace and interrupt, as well as the privilege violations and illegal instructions. These exceptions allow the current instruction to execute to completion, but preempt the execution of the next instruction by forcing exception processing to occur (privilege violations and illegal instructions are detected when they are the next instruction to be executed). The Group 2 exceptions occur as part of the normal processing of instructions. The TRAP, TRAPV, CHK, and zero divide exceptions are in this group. For these exceptions, the normal execution of an instruction may lead to exception processing.

Group 0 exceptions have highest priority, while Group 2 exceptions have lowest priority. Within Group 0, reset has highest priority, followed by address error and then bus error. Within Group 1, trace has priority over external interrupts, which in turn takes priority over illegal instruction and privilege violation. Since only one instruction can be executed at a time, there is no priority relation within Group 2.

The priority relation between two exceptions determines which is taken, or taken first, if the conditions for both arise simultaneously. Therefore, if a bus error occurs during a TRAP instruction, the bus error takes precedence, and the TRAP instruction processing is aborted. In another example, if an interrupt request occurs during the execution of an instruction while the T-bit is asserted, the trace exception has priority, and is processed first. Before instruction processing resumes, however, the interrupt exception is also processed, and instruction processing commences finally in the interrupt handler routine. A summary of exception grouping and priority is given in Table 20.

Table 20 Exception Grouping and Priority

Group	Exception	Processing
0	Reset Address Error Bus Error	Exception processing begins within two clock cycles.
1	Trace Interrupt Illegal Privilege	Exception processing begins before the next instruction
2	TRAP, TRAPV CHK, Zero Divide	Exception processing is started by normal instruction execution

RECOGNITION TIMES OF EXCEPTIONS, HALT, AND BUS ARBITRATION

END OF A CLOCK CYCLE RESET END OF A BUS CYCLE ADDRESS ERROR BUS ERROR HALT BUS ARBITRATION

END OF AN INSTRUCTION CYCLE
TRACE EXCEPTION
INTERRUPT EXCEPTIONS
ILLEGAL INSTRUCTION
UNIMPLEMENTED INSTRUCTION
PRIVILEGE VIOLATION

WITHIN AN INSTRUCTION CYCLE TRAP, TRAPV CHK ZERO DIVIDE

EXCEPTION PROCESSING DETAILED DISCUSSION

Exceptions have a number of sources, and each exception has processing which is peculiar to it. The following paragraphs detail the sources of exceptions, how each arises, and how each is processed.

RESET

The reset input provides the highest exception level. The processing of the reset signal is designed for system initiation, and recovery from catastrophic failure. Any processing in progress at the time of the reset is aborted and cannot be recovered. The processor is forced into the supervisor state, and the trace state is forced off. The processor interrupt priority mask is set at level seven. The vector number is internally generated to reference the reset exception vector at location 0 in the supervisor program space. Because no assumptions can be made about the validity of register contents, in particular the supervisor stack pointer, neither the program counter nor the status register is saved. The address contained in the first two words of the reset exception vector is fetched as the initial supervisor stack pointer, and the address in the last two words of the reset exception vector is fetched as the initial program counter. Finally, instruction execution is started at the address in the program counter. The power-up/restart code should be pointed to by the initial program counter.

The RESET instruction does not cause loading of the reset vector, but does assert the reset line to reset external devices. This allows the software to reset the system to a known state and then continue processing with the next instruction.

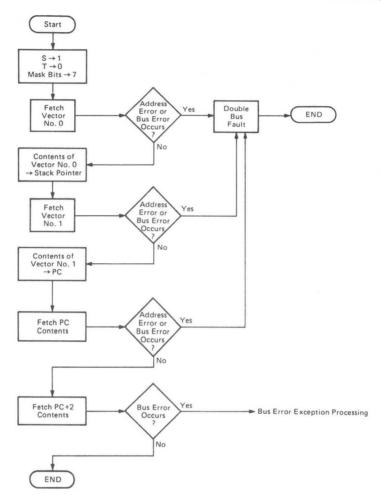


Figure 41 Reset Exception Processing

INTERRUPTS

Seven levels of interrupt priorities are provided. Devices may be chained externally within interrupt priority levels, allowing an unlimited number of peripheral devices to interrupt the processor. Interrupt priority levels are numbered from one to seven, with level seven being the highest priority. The status register contains a three-bit mask which indicates the current processor priority, and interrupts are inhibited for all priority levels less than or equal to the current processor priority.

An interrupt request is made to the processor by encoding the interrupt request level on the interrupt request lines; a zero indicates no interrupt request. Interrupt requests arriving at the processor do not force immediate exception processing, but are made pending. Pending interrupts are detected between instruction executions. If the priority of the pending interrupt is lower than or equal to the current processor priority, execution continues with the next instruction and the interrupt exception processing is postponed. (The recognition of level seven is slightly different, as explained in a following paragraph.)

If the priority of the pending interrupt is greater than the current processor priority, the exception processing sequence is started. First a copy of the status register is saved, and the privilege state is set to supervisor, tracing is suppressed, and the processor priority level is set to the level of the interrupt being acknowledged. The processor fetches the vector number from the interrupting device, classifying the reference as an interrupt acknowledge and displaying the level number of

the interrupt being acknowledged on the address bus. If external logic requests an automatic vectoring, the processor internally generates a vector number which is determined by the interrupt level number. If external logic indicates a bus error, the interrupt is taken to be spurious, and the generated vector number references the spurious interrupt vector. The processor then proceeds with the usual exception processing, saving the program counter and status register on the supervisor stack. The saved value of the program counter is the address of the instruction which would have been executed had the interrupt not been present. The content of the interrupt vector whose vector number was previously obtained is fetched and loaded into the program counter, and normal instruction execution commences in the interrupt handling routine. A flow chart for the interrupt acknowledge sequence is given in Figure 42, a timing diagram is given in Figure 43, and the interrupt exception timing sequence is shown in Figure 44.

Table 21 Internal Interrupt Level

Level	12	11	10	Interrupt
7	1	1	- 1	Non-Maskable Interrupt
6	1	1	0	
5	1	0	1	
4	1	0	0	> Maskable Interrupt
3	0	1	1	
2	0	1	0	
1	0	0	1	
0	0	0	0	No Interrupt

(NOTE) The internal interrupt mask level (I2, I1, I0) are inverted to the logic level applied to the pins (IPL2, IPL1, IPL0).



Grant Interrupt

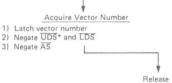
- 1) Compare interrupt level in status register and wait for current instruction to complete
- Place interrupt level on A1, A2, A3
- 3) Set R/W to read

3) Negate AS

- 4) Set function code to interrupt acknowledge
- 5) Assert address strobe (AS)
- 6) Assert lower data strobe (UDS* and LDS)



- 2) Assert data transfer acknowledge (DTACK)

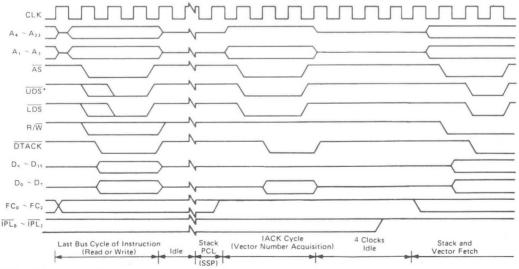


1) Negate DTACK

Start Interrupt Processing

* Although a vector number is one byte, both data strobes are asserted due to the microcode used for exception processing. The processor does not recognize anything on data lines D₈ through D₁₅ at this time

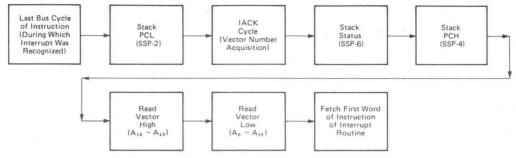
Figure 42 Interrupt Acknowledge Sequence Flow Chart



^{*} Although a vector number is one byte, both data strobes are asserted due to the microcode used for exception processing. The processor does not recognize anything on data lines D₈ through D₁₅ at this time.

Figure 43 Interrupt Acknowledge Sequence Timing Diagram





Note: SSP refers to the value of the supervisor stack pointer before the interrupt occurs.

Figure 44 Interrupt Exception Timing Sequence

Priority level seven is a special case. Level seven interrupts cannot be inhibited by the interrupt priority mask, thus providing a "non-maskable interrupt" capability. An interrupt is generated each time the interrupt request level changes from some lower level to level seven. Note that a level seven interrupt may still be caused by the level comparison if the request level is a seven and the processor priority is set to a lower level by an instruction.

UNINITIALIZED INTERRUPT

An interrupting device asserts \overline{VPA} or provides an interrupt vector during an interrupt acknowledge cycle to the 68000. If the vector register has not been initialized, the responding HMCS68000 Family peripheral will provide vector 15, the unitialized interrupt vector. This provides a uniform way to recover from a programming error.

SPURIOUS INTERRUPT

If during the interrupt acknowledge cycle no device responds by asserting DTACK or VPA, the bus error line should be asserted to terminate the vector acquisition. The processor separates the processing of this error from bus error by fetching the spurious interrupt vector instead of the bus error vector. The processor then proceeds with the usual exception processing.

INSTRUCTION TRAPS

Traps are exceptions caused by instructions. They arise either from processor recognition of abnormal conditions during instruction execution, or from use of instructions whose normal behavior is trapping.

Some instructions are used specifically to generate traps. The TRAP instruction always forces an exception, and is useful for implementing system calls for user programs. The TRAPV and CHK instructions force an exception if the user program detects a runtime error, which may be an arithmetic overflow or a subscript out of bounds.

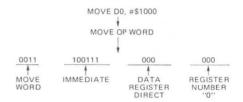
The signed divide (DIVS) and unsigned divide (DIVU) instructions will force an exception if a division operation is attempted with a divisor of zero.

ILLEGAL AND UNIMPLEMENTED INSTRUCTIONS

Illegal instruction is the term used to refer to any of the word bit patterns which are not the bit pattern of the first word of a legal instruction. During instruction execution, if such an instruction is fetched, an illegal instruction exception occurs.

Word patterns with bits 15 through 12 equaling 1010 or 1111 are distinguished as unimplemented instructions and separate exception vectors are given to these patterns to permit efficient emulation. This facility allows the operating system to detect program errors, or to emulate unimplemented instructions in software.

ILLEGAL INSTRUCTION EXAMPLE



PRIVILEGE VIOLATIONS

In order to provide system security, various instructions are privileged. An attempt to execute one of the privileged instructions while in the user state will cause an exception. The privileged instruction are:

STOP AND (word) Immediate to SR
RESET EOR (word) Immediate to SR
RTE OR (word) Immediate to SR
MOVE to SR
MOVE USP

TRACING

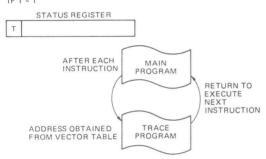
To aid in program development, the 68000 includes a facility to allow instruction by instruction tracing. In the trace state, after each instruction is executed an exceptions is forced, allowing a debugging program to monitor the execution of the program under test.

The trace facility uses the T-bit in the supervisor portion of the status register. If the T-bit is negated (off), tracing is disabled, and instruction execution proceeds from instruction to instruction as normal. If the T-bit is asserted (on) at the beginning of the execution of an instruction, a trace exception will be generated after the execution of that instruction is completed. If the instruction is not executed either because an interrupt is taken, or the instruction is illegal or privileged, the trace exception does not occur. The trace exception also does not occur if the instruction is aborted by a reset, bus

error, or address error exception. If the instruction is indeed executed and an interrupt is pending on completion, the trace exception is processed before the interrupt exception. If, during the execution of the instruction, an exception is forced by that instruction, the forced exception is processed before the trace exception.

As an extreme illustration of the above rules, consider the arrival of an interrupt during the execution of a TRAP instruction while tracing is enabled. First the trap exception is processed, then the trace exception, and finally the interrupt exception. Instruction execution resumes in the interrupt handler routing.

TRACE MODE



- If, upon completion of an instruction, T = 1, go to trace exception processing.
- Execute trace exception processing.
- 3. Execute trace service routine.
- At the end of the service routine, execute return from exception (RTE).

BUS ERROR

Bus error exceptions occur when the external logic requests that a bus error be processed by an exception. The current bus cycle which the processor is making is then aborted. Whether the processor was doing instruction or exception processing, that processing is terminated, and the processor immediately begins exception processing.

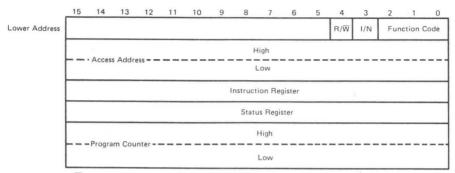
Exception processing for bus error follows the usual sequence of steps. The status register is copied, the supervisor state is entered, and the trace state is turned off. The vector number is generated to refer to the bus error vector. Since the processor was not between instructions when the bus error exception request was made, the context of the processor is

more detailed. To save more of this context, additional information is saved on the supervisor stack. The program counter and the copy of the status register are of course saved. The value saved for the program counter is advanced by some amount, one to five words beyond the address of the first word of the instruction which made the reference causing the bus error. If the bus error occurred during the fetch of the next instruction, the saved program counter has a value in the vicinity of the current instruction, even if the current instruction is a branch, a jump, or a return instruction. Besides the usual information, the processor saves its internal copy of the first word of the instruction being processed, and the address which was being accessed by the aborted bus cycle. Specific information about the access is also saved: whether it was a read or a write, whether the processor was processing an instruction or not, and the classification displayed on the function code outputs when the bus error occurred. The processor is processing an instruction if it is in the normal state or processing a Group 2 exception; the processor is not processing an instruction if it is processing a Group 0 or a Group 1 exception. Figure 45 illustrates how this information is organized on the supervisor stack. Although this information is not sufficient in general to effect full recovery from the bus error, it does allow software diagnosis. Finally, the processor commences instruction processing at the address contained in the vector. It is the responsibility of the error handler routine to clean up the stack and determine where to continue execution.

If a bus error occurs during the exception processing for a bus error, address error, or reset, the processor is halted, and all processing cases. This simplifies the detection of catastrophic system failure, since the processor removes itself from the system rather than destroy all memory contents. Only the $\overline{\text{RES}}$ pin can restart a halted processor.

ADDRESS ERROR

Address error exceptions occur when the processor attempts to access a word or a long word operand or an instruction at an odd address. The effect is much like an internally generated bus error, so that the bus cycle is aborted, and the processor ceases whatever processing it is currently doing and begins exception processing. After exception processing commences, the sequence is the same as that for bus error including the information that is stacked, except that the vector number refers to the address error vector instead. Likewise, if an address error occurs during the exception processing for a bus error, address error, or reset, the processor is halted. As shown in Figure 46, an address error will execute a short bus cycle followed by exception processing.



 R/\overline{W} (read/write): write = 0, read = 1. I/N (instruction/not): instruction = 0, not = 1

Figure 45 Exception Stack Order (Group 0)

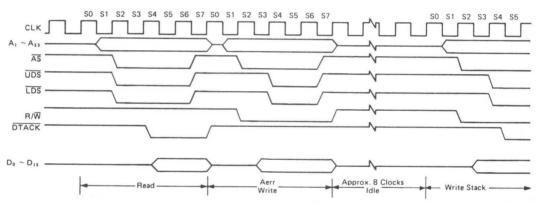


Figure 46 Address Error Timing

■ INTERFACE WITH HMCS6800 PERIPHERALS

HD6852

Hitachi's extensive line of HMCS6800 peripherals are directly compatible with the 68000. Some of these devices that are particularly useful are:

HD6821 Peripheral Interface Adapter
HD6840 Programmable Timer Module
HD6843 Floppy Disk Controller
HD46508 Analog Data Acquisition Unit
Asynchronous Communication Interface
Adapter

To interface the synchronous HMCS6800 peripherals with the asynchronous 68000, the processor modifies its bus cycle to meet the HMCS6800 cycle requirements whenever an HMCS6800 device address is detected. This is possible since both processors use memory mapped I/O. Figure 48 is a flow chart of the interface operation between the processor and HMCS6800 devices.

Synchronous Serial Data Adapter

DATA TRANSFER OPERATION

Three signal on the processor provide the HMCS6800 interface. They are: enable (E), valid memory address (VMA), and valid peripheral address (VPA). Enable corresponds to the E or ϕ_2 signal in existing HMCS6800 systems. The bus frequency is one tenth of the incoming 68000 clock frequency. The timing of E allows 1 MHz peripherals to be used with an 8 MHz68000. Enable has a 60/40 duty cycle; that is, it is low for six input clocks and high for four input clocks. This duty cycle allows the processor to do successive \overline{VPA} accesses on successive E pulses.

HMCS6800 cycle timing is given in Figures 49 and 50. At state zero (S0) in the cycle, the address bus is in the high-impedance state. A function code is asserted on the function code output lines. One-half clock later, in state 1 the address bus is released from the high-impedance state.

During state 2, the address strobe (\overline{AS}) is asserted to indicate that there is a valid address on the address bus. If the bus cycle is a read cycle, the upper and/or lower data strobes are also asserted in state 2. If the bus cycle is a write cycle,

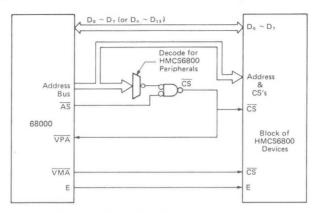


Figure 47 Connection of HMCS6800 Peripherals

the read/write (R/\overline{W}) signal is switched to low (write) during state 2. One half clock later, in state 3, the write data is placed on the data bus, and in state 4 the data strobes are issued to indicate valid data on the data bus. The processor now inserts wait states until it recognizes the assertion of \overline{VPA} .

The $\overline{\text{VPA}}$ input signals the processor that the address on the bus is the address of an HMCS6800 device (or an area reserved for HMCS6800 devices) and that the bus should conform to the ϕ_2 transfer characteristics of the HMCS6800 bus. Valid peripheral address is derived by decoding the address bus, conditioned by address strobe. Chip select for the HMCS6800 peripherals should be derived by decoding the address bus conditioned by $\overline{\text{VMA}}$.

After the recognition of \$\overline{VPA}\$, the processor assures that the Enable (E) is low, by waiting if necessary, and subsequently asserts \$\overline{VMA}\$. Valid memory address is then used as part of the chip select equation of the peripheral. This ensures that the HMCS6800 peripherals are selected and deselected at the correct time. The peripheral now runs its cycle during the high portion of the E signal. Figures 49 and 50 depict the best and worst case HMCS6800 cycle timing. This cycle length is dependent strictly upon when \$\overline{VPA}\$ is asserted in relationship to the E clock.

If we assume that external circuitry asserts \overline{VPA} as soon as possible after the assertion of \overline{AS} , then \overline{VPA} will be recognized as being asserted on the falling edge of S4. In this case, no "extra" wait cycles will be inserted prior to the recognition of \overline{VPA} asserted and only the wait cycles inserted to synchronize with the E clock will determine the total length of the cycle. In any case, the synchronization delay will be some integral number of clock cycles within the following two extremes:

- Best Case VPA is recognized as being asserted on the falling edge three clock cycles before E rises (or three clock cycles after E falls).
- Worst Case VPA is recognized as being asserted on the falling edge two clock cycles before E rises(or four clock cycles after E falls).

During a read cycle, the processor latches the peripheral data in state 6. For all cycles, the processor negates the address and data strobes one half clock cycle later in state 7, and the Enable signal goes low at this time. Another half clock later, the address bus is put in the high-impedance state. During a write cycle, the data bus is put in the high-impedance state

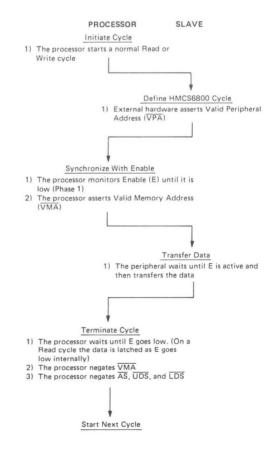


Figure 48 HMCS6800 Interface Flow Chart

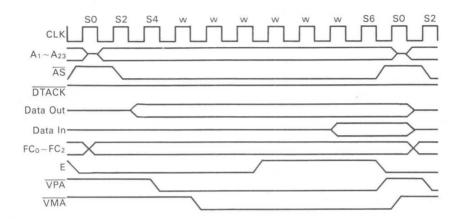


Figure 49 68000 to HMCS6800 Peripheral Timing - Best Case

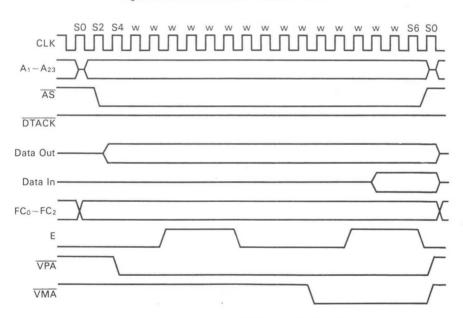


Figure 50 68000 to HMCS6800 Peripheral Timing - Worst Case

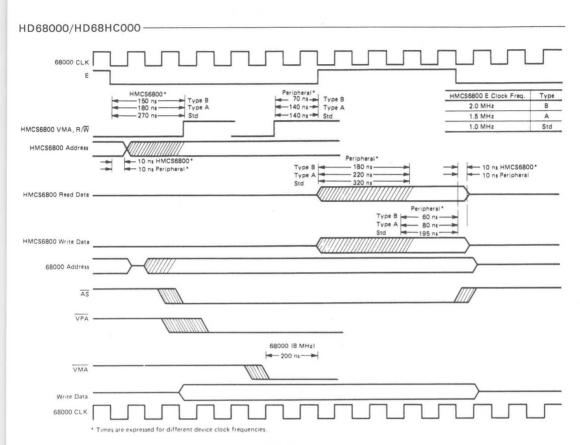


Figure 51 68000 to HMCS6800 Peripheral Timing Diagram

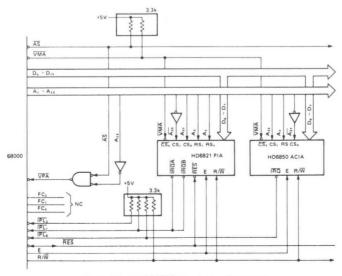
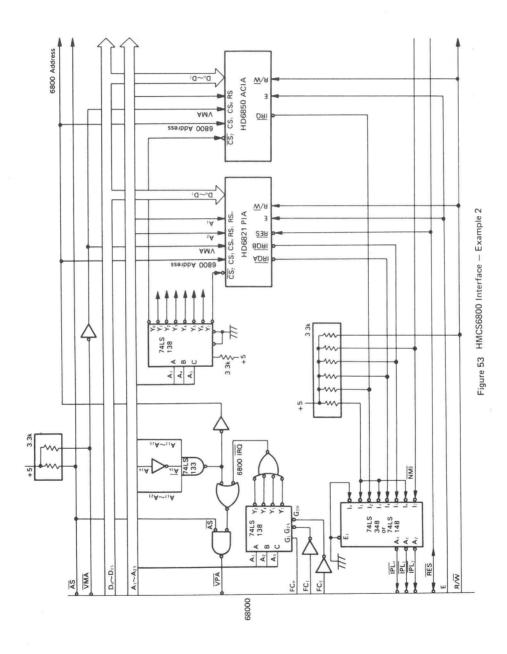


Figure 52 HMCS6800 Interface - Example 1



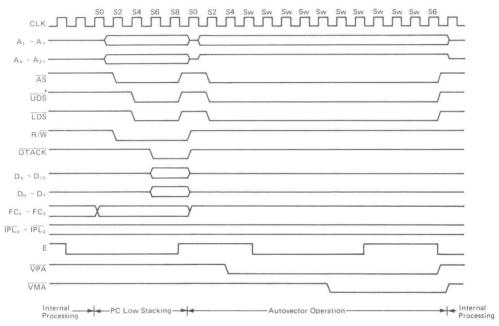
and the read/write signal is switched high. The peripheral logic must remove \overline{VPA} within one clock after address strobe is negated.

Figure 51 shows the timing required by HMCS6800 peripherals, the timing specified for HMCS6800, and the corresponding timing for the 68000. Two example systems with HMCS6800 peripherals are shown in Figures 52 and 53. The system in Figure 52 reserves the upper eight megabytes of memory for HMCS6800 peripherals. The system in Figure 53 is more efficient with memory and easily expandable, but more complex.

 \overline{DTACK} should not be asserted while \overline{VPA} is asserted. Notice that the 68000 \overline{VMA} is active low, contrasted with the active high HMCS6800 VMA. This allows the processor to put its buses in the high-impedance state on DMA requests without inadvertently selecting peripherals.

INTERRUPT OPERATION

During an interrupt acknowledge cycle while the processor is fetching the vector, if \overline{VPA} is asserted, the 68000 will assert \overline{VMA} and complete a normal HMCS6800 read cycle as shown in Figure 54. The processor will then use an internally generated



* Although a vector number is one byte, both data strobes are asserted due to the microcode used for exception processing. The processor does not recognize anything on data lines De through Dis at this time.

Figure 54 Autovector Operation Timing Diagram

vector that is a function of the interrupt being serviced. This process is known as autovectoring. The seven autovectors are vector numbers 25 through 31 (decimal).

This operates in the same fashion (but is not restricted to) the HMCS6800 interrupt sequence. The basic difference is that there are six normal interrupt vectors and one NMI type vector. As with both the HMCS6800 and the 68000's normal vectored interrupt, the interrupt service routine can be located anywhere in the address space. This is due to the fact that while the vector numbers are fixed, the contents of the vector table entries are assigned by the user.

Since VMA is asserted during autovectoring, the HMCS6800 peripheral address decoding should prevent unintended accesses.

CONDITION CODES COMPUTATION

This provides a discussion of how the condition codes were developed, the meanings of each bit, how they are computed, and how they are represented in the instruction set details.

CONDITION CODE REGISTER

The condition code register portion of the status register contains five bits:

N - Negative

Z - Zero

V - Overflow

C - Carry

X - Extend

The first four bits are true condition code bits in that they reflect the condition of the result of a processor operation. The X-bit is an operand for multiprecision computations. The carry bit (C) and the multiprecision operand extend bit (X) are separate in the 68000 to simplify the programming model.



CONDITION CODE REGISTER NOTATION

In the instruction set details, the description of the effect on the condition codes is given in the following form:

Condition Codes:

Z V

N (negative) set if the most significant bit of the result is set. Cleared otherwise.

Z (zero)

set if the result equals zero. Cleared otherwise. V (overflow) set if there was an arithmetic overflow. This implies that the result is not representable in the operand size. Cleared otherwise.

C (carry) set if a carry is generated out of the most significant bit of the operands for an addition. Also set if a borrow is generated in a subtrac-

tion. Cleared otherwise.

X (extend) transparent to data movement. When affected, it is set the same as the C-bit.

The notational convention that appears in the representation of the condition code registers is:

- set according to the result of the operation
- not affected by the operation
- cleared
- U undefined after the operation

CONDITION CODE COMPUTATION

Most operations take a source operand and a destination operand, compute, and store the result in the destination location. Unary operations take a destination operand, compute, and store the result in the destination location. Table 22 details how each instruction sets the condition codes.

Table 22 Condition Code Computations

Operations	X	N	Z	V	C	Special Definition
ABCD		U	?	U	?	C = Decimal Carry Z = Z · Rm · · RO
ADD, ADDI, ADDQ	•	•	•	?	?	$V = Sm \cdot Dm \cdot \overline{Rm} + \overline{Sm} \cdot \overline{Dm} \cdot \overline{Rm}$ $C = Sm \cdot Dm + \overline{Rm} \cdot Dm + Sm \cdot \overline{Rm}$
ADDX	•	*	?	?	?	$V = Sm \cdot Dm \cdot \overline{Rm} + \overline{Sm} \cdot \overline{Dm} \cdot Rm$ $C = Sm \cdot Dm + \overline{Rm} \cdot Dm + Sm \cdot \overline{Rm}$ $Z = Z \cdot \overline{Rm} \cdot \cdot \overline{R0}$
AND, ANDI, EOR, EORI, MOVEO, MOVE, OR, ORI, CLR, EXT, NOT, TAS, TST	-	•	•	0	0	
СНК	-		U	U	U	
SUB, SUBI SUBQ	•	•	•	?	?	$V = \overline{Sm} \cdot \underline{Dm} \cdot \overline{Rm} + \underline{Sm} \cdot \underline{Dm} \cdot Rm$ $C = Sm \cdot \overline{Dm} + Rm \cdot \overline{Dm} + Sm \cdot Rm$
SUBX	•	•	?	?	?	$V = \overline{Sm} \cdot \underline{Dm} \cdot \overline{Rm} + \underline{Sm} \cdot \overline{Dm} \cdot Rm$ $C = Sm \cdot \underline{Dm} + R\underline{m} \cdot \overline{Dm} + Sm \cdot Rm$ $Z = Z \cdot \overline{Rm} \cdot \cdot \overline{R0}$
CMP, CMPI, CMPM	-	•	٠	?	?	$V = \overline{Sm} \cdot \underline{Dm} \cdot \overline{Rm} + \underline{Sm} \cdot \overline{Dm} \cdot \overline{Rm}$ $C = Sm \cdot \overline{Dm} + Rm \cdot \overline{Dm} + Sm \cdot Rm$
DIVS, DIVU	_			?	0	V = Division Overflow
MULS, MULU	_			0	0	A
SBCD, NBCD		U	?	U	?	C = Decimal Borrow Z = Z · Rm · · RO
NEG NEGX	:	:	?	?	?	$V = Dm \cdot Rm, C = Dm + Rm$ $V = Dm \cdot Rm, C = Dm + Rm$ $Z = Z \cdot \overline{Rm} \cdot \cdot \overline{R0}$
BTST, BCHG, BSET, BCLR	-	-	?	-	-	Z = Dn
ASL	•	•	•	?	?	$V = D_{m} \cdot (\overline{D_{m-1}} + + \overline{D_{m-r}}) + \overline{D_{m}} \cdot (D_{m-1} + + D_{m-r}) C = D_{m-r+1}$
ASL (r = 0)	-	•	•	0	0	
LSL, ROXL		•		0	?	C = D _{m-r+1}
LSR (r = 0)	-			0	0	
ROXL (r = 0)	-	•		0	?	C = X
ROL	-			0	?	C = D _{m-r+1}
ROL (r = 0)	-			0	0	
ASR, LSR, ROXR				0	?	C = D _{r-1}
ASR, LSR (r = 0)	-			0	0	
ROXR (r = 0)	-			0	?	C = X
ROR	-			0	?	C = D _{r-1}
ROR (r = 0)	_		*	0	0	

Not affected U Undefined

- shift amount



Other -- see Special Definition

^{*} General Case X = C

 $Z = \overline{Rm} \cdot ... \cdot \overline{R0}$

Sm - Source operand most significant bit Dm - Destination operand most significant bit Rm - Result bit most significant bit - bit number

CONDITIONAL TESTS

Table 23 lists the condition names, encodings, and tests for the conditional branch and set instructions. The test associated with each condition is a logical formula based on the current state of the condition codes. If this formula evaluates to

1. the condition succeeds, or is true. If the formula evaluates to 0, the condition is unsuccessful, or false. For example, the T condition always succeeds, while the EQ condition succeeds only if the Z bit is currently set in the condition codes.

Table 23 Conditional Tests

Mnemonic	Condition	Encoding	Test
Т	true	0000	1
F	false	0001	0
Н	high	0010	C·Z
LS	low or same	0011	C + Z
CC	carry clear	0100	C.
CS	carry set	0101	С
NE	not equal	0110	Z
EQ	equal	0111	Z
VC	overflow clear	1000	\overline{V}
VS	overflow set	1001	V
PL	plus	1010	N
MI	minus	1011	N
GE	greater or equal	1100	$N \cdot V + \overline{N} \cdot \overline{V}$
LT	less than	1101	$N \cdot \nabla + \overline{N} \cdot V$
GT	greater than	1110	$N \cdot V \cdot \overline{Z} + \overline{N} \cdot \overline{V} \cdot \overline{Z}$
LE	less or equal	1111	$Z + N \cdot \overline{V} + \overline{N} \cdot V$

INSTRUCTION SET

The following paragraphs provide information about the addressing categories and instruction set of the 68000.

ADDRESSING CATEGORIES

Effective address modes may be categorized by the ways in which they may used. The following classifications will be used in the instruction definitions.

If an effective address mode may be used to refer Data to data operands, it is considered a data addressing effective address mode.

If an effective address mode may be used to refer Memory to memory operands, it is considered a memory addressing effective address mode.

If an effective address mode may be used to refer Alterable to alterable (writeable) operands, it is considered an alterable addressing effective address mode.

Control If an effective address mode may be used to refer to memory operands without an associated size, it is considered a control addressing effective address mode

Table 24 shows the various categories to which each of the effective address modes belong. Table 25 is the instruction set summary.

The status register addressing mode is not permitted unless it is explicitly mentioned as a legal addressing mode.

These categories may be combined so that additional, more restrictive, classifications may be defined. For example, the instruction descriptions use such classifications as alterable memory or data alterable. The former refers to those addressing modes which are both alterable and memory addresses, and the latter refers to addressing modes which are both data and alterable

INSTRUCTION PRE-FETCH

The 68000 uses a 2-word tightly-coupled instruction prefetch mechanism to enhance performance. This mechanism is described in terms of the microcode operations involved. If the execution of an instruction is defined to begin when the microroutine for that instruction is entered, some features of the prefetch mechanism can be described.

- 1) When execution of an instruction begins, the operation word and the word following have already been fetched. The operation word is in the instruction decoder.
- 2) In the case of multi-word instructions, as each additional word of the instruction is used internally, a fetch is made to the instruction stream to replace it.
- 3) The last fetch from the instruction stream is made when the operation word is discarded and decoding is started on the next instruction.
- If the instruction is a single-word instruction causing a branch, the second word is not used. But because this word is fetched by the preceding instruction, it is impossible to avoid this superfluous fetch. In the case of an interrupt or trace exception, both words are not used.
- 5) The program counter usually points to the last word fetched from the instruction stream.

Table 24 Effective Addressing Mode Categories

Effective Address	Mode	Pagistor	Data	Add	ressing Categ	ories
Modes	iviode	Register	Data	Memory	Control	Alterable
Dn	000	register number	X	_	_	X
An	001	register number	_	_	_	×
An@	010	register number	X	×	×	X
An@+	011	register number	X	×	_	X
An@ -	100	register number	X	×	_	×
An@(d)	101	register number	X	×	X	X
An@(d, ix)	110	register number	X	×	×	X
xxx.W	111	000	X	×	X	×
xxx.L	111	001	X	×	×	X
PC@(d)	111	010	X	×	×	_
PC@(d, ix)	111	011	X	×	×	_
#xxx	111	100	X	×	_	_

The following example illustrates many of the features of instruction prefetch. The contents of memory are assumed to be as illustrated in Figure 55.

	ORG	0	DEFINE RESTART VECTOR
	DC.L DC.L	INISSP RESTART	INITIAL SYSTEM STACK POINTER RESTART SYSTEM ENTRY POINT
	ORG DC.L	INTVECTOR INTHANDLER	DEFINE AN INTERRUPT VECTOR HANDLER ADDRESS FOR THIS VECTOR
	ORG		SYSTEM RESTART CODE
RESTART:			
	NOP BRA.S ADD.W	LABEL DO, D1	NO OPERATION EXAMPLE SHORT BRANCH ADD REGISTER TO REGISTER
LABEL:	SUB.W CMP.W SGE.B	DISP(A0), A1 D2, D3 D7	SUBTRACT REGISTER INDIRECT WITH OFFSET COMPARE REGISTER TO REGISTER Scc TO REGISTER
INTHANDL			
	MOVE.W NOP SWAP.W	LONGADR1, LONGADR2	MOVE WORD FROM AND TO LONG ADDRESS NO OPERATION REGISTER SWAP

Figure 55 Instruction Prefetch Example, Memory Contents

The sequence we shall illustrate consists of the power-up reset, the execution of NOP, BRA, SUB, the taking of an interrupt, and the execution of the MOVE.W xxx.L to yyy.L.

The order of operations described within each microroutine is not exact, but is intended for illustrative purpose only.

Microroutine	Operation	Location	Operand
Reset	Read	0	SSP High
	Read	2	SSP Low
	Read	4	PC High
	Read	6	PC Low
	Read	(PC)	NOP
	Read	+ (PC)	BRA
	 begin NOP>		
NOP	Read	+ (PC)	ADD
	<begin bra=""></begin>		
BRA	PC = PC + d		
	Read	(PC)	SUB
	Read	+ (PC)	DISP
	 begin SUB>		
SUB	Read	+ (PC)	CMP
	Read	DISP(A0)	<src></src>
	Read	+ (PC)	SGE
	 begin CMP>	<take int=""></take>	
INTERRUPT	Write	- (SSP)	PC Low
	Read	<int ack=""></int>	Vector #
	Write	- (SSP)	SR
	Write	- (SSP)	PC High
	Read	(VR)	PC High
	Read	+(VR)	PC Low
	Read	(PC)	MOVE
	Read	+ (PC)	xxx High
	 begin MOVE>		
MOVE	Read	+ (PC)	xxx Low
	Read	+ (PC)	yyy High
	Read	XXX	<src></src>
	Read	+ (PC)	yyy Low
	Write	YYY	<dest></dest>
	Read	+ (PC)	NOP
	Read	+ (PC)	SWAP
	 begin NOP>		1

Figure 56 Instruction Prefetch Example

DATA PREFETCH

Normally the 68000 prefetches only instructions and not data. However, when the MOVEM instruction is used to move data from memory to registers, the data stream is prefetched in

	MOVEM.L	A, D0/D1	MOVE TWO LONGWORDS INTO REGISTERS
^	DC.W	1	WORD 1
A		1	
В	DC.W	2	WORD 2
C	DC.W	3	WORD 3
D	DC.W	4	WORD 4
E	DC.W	5	WORD 5
F	DC.W	6	WORD 6

Figure 57 MOVEM Example, Memory Contents

order to optimize performance. As a result, the processor reads one extra word beyond the higher end of the source area. For example, the instruction sequence in Figure 57 will operate as shown in Figure 58.

Assume Effect	ive Address Ev	aluation is A	Already Done
Microroutine	Operation	Location	Other Operations
MOVEM	Read	А	
			Prepare to Fill D0
	Read	В	$A \rightarrow DOH$
	Read	C	B → DOL
			Prepare to Fill D1
	Read	D	C → D1H
	Read	E	$D \rightarrow D1L$
			Detect Register List Complete

Figure 58 MOVEM Example, Operation Sequence

Table 25 Instruction Set

Mnomonic	Size	Addr.		Dr			An	(An)	(4	(n) +		(An)	d(An)	d(A	ın.Xi)	Ab	w.ac	A	bs.L	d	(PC)	d(1	PC, Xi	d =	mmed SR/CC	Elizabeth de la company	It Pattern	Berlan	Conditio
Operation	9129	Mede		T	-	#	~	#	-	#	-	#	~	#	7	#	~	#	-	#	-	#	-	#	-	#		5432 1888	7854 3218	Boolson	XNZV
BCD id Digits	В	s:Dn 0 s: (An) 0	1		6							2	18															1100 RRR1 1100 RRR1	0000 Orrr	d10 + s10 + X •d	*! *!
BD id nary	B'W	s=Dn d d=Dn s s=Dn d	1 2		4	2 . 1	DDA 4 DDA	2 2 2	8 20	2 2 2	12 8 20	5 5	14 10 22	4 4 4	16 12 24	4	18 14 26	4 4 4	16 12 24	6 6	20 16 28	4	12	4	14	4	8	1101 DDD1 1101 DDD0	SSEE EEEE SSee eeee	d + Dn →d Dn + s → Dn	****
DDA	W	d Dn	2		8 8	2	8	2	14	2 2	14	2	16	4	18	4	20	4	18	6	22	4	18	4	20	6	14	1101 DDD1	10EE EEEE	d + On →d On + s → On	
d Address	B.M.	d An			8	2	8 8 DDA	2	12 14	2	12 14	2	14 16	4	18	4	18 20 22	4	16 18 20	6 6	20 22 24	4	16 18	4	18 20	6	12	1101 AAA0	llee eeee	An + s → An	
d Immed	L B W	s:Imm	1 6		16		DDA 4	6	28 12	6 2	28	6 2	30	8 4	32 16	8 4	34 18	8 4	32	10	36 20							0101 0000	interest to be	d + # →d	****
d Quick	B'W	s:Imm3 o s:Inim3 o	1 2		8	2	8	2	20	2	20	2	14 22	4	24	4	26	4	16 24	6	28	1000	Later CC	Salpere	**************************************	0.000	SHARES !		SSEE EEEE	d• # →d	****
d Multi-	L	s-Un (s-Dn (s-(An))	1: 2		8							2	18																SS00 Orer SS00 Irrr 1000 Orer 1000 Irrr	d - s + X +d	
ID gical And	B W	s:Dn d	1		4		1000000	2	12	2	12	2	14	4	16 12	4	18 14	4	16 12	6	20 16	4	12	4	14	4	8	1100 DDD1 1100 DDD0	SSEE EEEE	d < and > Dn →d Dn < and > s → Dn	- **(
IDH	L B/W	s:Dn d d:Dn s			8	1000	Linear State	2 2	20 14 16	2 2	20 14 16	2 2	22 16 18	4 4 6	24 18	4 4 6	26 20 22	4 4 6	24 18 20	6 6	28 22 24	4	18	4	20	6	14	1100 DDD1 1100 DDD0 0000 0010	10EE EEEE	d < and > Dn → d Dn < and > s → Dn d < and > s → d	-**(
I Immed		s Imm count Dn	1 6		16 + 2n			6	28	6	28	6	30	8	20 32	8	24	8	32	10							20	1110 rrrf	SSIO ODDD		
thmetic	L	count-Dn count: #1~8 c	1 2	6 8	+ 2n + 2n + 2n																							1110 QQQf 1110 rrrf 1110 QQQf	SS00 0DDD 1010 0DDD 1000 0DDD	C Left C Right X	****
mory	W	count: 1 c	1.		2317	101		2 .	12 12	2 .	12 12	2.	14 14	4 .	16	4 .	18	4 .	16 16	6.	20		Hoos	9186	5000			1110 000f	DIEE EEEE	$-(bit) \# of d \rightarrow Z.$	
est and nange	L	bit #=lmm of bit #=Dn of bit #=lmm of	1 2		< 8 < 12			À	16	4	16	•	18	6	20	6	22	6	20	8	24							0000 1000 0000 rrrl 0000 1000	OIEE EEEE OIEE EEEE	~(bit) # of d → (bit) # of d	
CLR est and ear	B	bit#:Dn (bit#:Imm (bit#:Dn (1 2		< 10	South	10(2.00	2 4	12 16	2 4	12 16	2 4	14 18	6	16 20	6	18 22	6	17 20	6 8	20 24							0000 1711	10EE EEEE 10EE EEEE	-(bit) # of d→Z. 0→(bit) # of d	*-
SET st and t	В	bit #: Imm bit #: Imm bit #: Imm bit #: Imm bit #: Imm			< 8			2 4	12 16	2 4	12 16	2 4	14 18	4	16 20	4 6	18 22	4	16 20	6 8	20 24							0000 1000 0000 rrrl 0000 1000 0000 rrrl	10EE EEEE 11EE EEEE 11EE EEEE	~(bit) # of d→Z, 1→(bit) # of d	
TST t Test	B	bit # Imm in bit # Imm in bit # Imm in	1		6	e de la composition della comp		2 4	8 12	2 4	8 12	2 4	10 14	4 6	12	4 6	14 18	4 6	12 16	6 8	16 20	4 6	12 16	4 6	14	4	10	0000 1000 0000 rrr1 0000 1000 0000 rrr1	OOEE EEEE OOEE EEEE	-(bit) # of d →Z	*-
NOR neck Reg- ter Against	W	d=Dn :	1 4		10 < 40		rap →	2	< 4 14	2	< 44	2	< 46 16	4	< 48 18	4	< 50 20	4	< 48	6	< 52 22	4	< 4 18	3 4	< 50 20	4	< 44	0000 1000 0100 DDD1	OOEE EEEE	If Dn < 0. or Dn > (bound), then trap	- * U U
unds	B W				4	and the second	trap	2	12	2	12	2	14	4	16	4	18	4	16	6	20	Ann.	2,000,0		15000	220	131167	0100 0010	SSEE EEEE	d →MPU 0 +d	-010
ear Operand Depois	8/W,		1 2 5 2 5 2	1 3	6	2*	4	2 2 2	20 8 14	2 2 2	20 8 14	2 2 2	22 10 16	4 4	24 12 18	4 4	26 14 20	4 4	24 12 18	6	28 16 22	4 4	12 18	4 4	14 20	4 6	8	1011 DDD0	SSee eeee	Dn - s	- 0 0 0
MPA ompare	W	d:An d:An	5 2		6	2 2	6	2 2	10 14	2 2	10 14	2 2	12 16	4	14 18	4	16 20	4 4	12 18	6	18 22	4 4	14	4 4	16 20	4 6	10 14	1011 AAA0 1011 AAA1	llee eeee	An — s	- * * *
MP1	B'W				8		MPA MPA	4	12 20	4 6	12 20	4	14 22	6	16	6 8	18	6 8	16	8	20			169			Self	0000 1100	SSEE EEEE	d-#	- * * *
MPM ompare	B/W L				14:00		MPA	Ь	20	2 2	12 20	6			24		200		24	10	26	1522	10000	E-Bosses	PORTICI	0.000	Lancons:	1011 RRR1	SS00 Irrr	d – s	-***
emory IVS Ivide Signed	W	d:On	. 2	2 <	158	75 to 100		2	< 16	2 2	< 167	2	< 164	4	< 166	4	< 168	4	< 166	6	< 170	4	< 16	6 4	< 16	8 4	< 162	1000 DDD1	liee eees	Dn32/s16→ Dn(rg)	-++4
vide	W	d:Dn	s a	2 <	140		1220040	2	< 14	4 2	< 14	2	< 146	4	< 148	4	< 150	4	< 148	6	< 15	2 4	< 14	8 4	< 15	0 4	< 144	1000 DDD0	llee eeee	Dn32 s16 + Dn(rq)	- * * *
Insigned IOR Exclusive OR Opical	B/W L		d: i	2	8			2 2	12 20	2 2	12 20	2 2	14 22	4	16 24	4	18 26	4	16 24	6	20 28					STATE OF		1011 rrrl	SSEE EEEE	d ● Dn →d	-**0
ORI clusive OR nmediate	B W				8 16		e-motodic	4	16 28	4 6	16 28	4	18 30	6 8	20 32	6 8	22 34	6 8	20 32	8 10	24 36		tundo	- Park		4	20	0000 1010	SSEE EEEE	d • # →d	-**(
X6 xchange egisters	ı	s:On s:An	d:	2	6	2	6																						0100 QDDD 0100 IAAA 1000 IAAA	s⊶d	
XT ign Extend BA oad Effect	W L	1		2 2	4 4			2	4					4	8	4	12	4	8	6	12	4	8	4	12			0100 1000 0100 1000 0100 AAA1	1000 ODDD 1100 ODDD 11ee eeee	bit 7 → bit 8 − 15 bit 15 + bit 16 − 31 s→An	- * * (
re Address INK Ink and flocate		disp-lmm	\$:			4	16			nds											2000						S-ecolor	0100 1110	0101 0AAA	An→ - (SP) SP→An SP + disp···SP	

Note: Refer to Condition Code Computations as for condition Code

Word only

Maximum value

Number of Clock Periods

| A. Address Register # | 1. Direction 0 - Right. 1 - Left | R. Destination Register | C. Test Condition | M. Destination 0 - Right. 1 - Left | R. Destination Register | M. Destination 0 - Left | Mode | Size (20) Byte | (In the MOVE Instruction 0 - Dutal Register | P. Desplacement | 0 - Mord | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0 - Byte | 0

(to be continued)



Mnomoni c		Addr.		1	On .		An	1	(An)	(An)+		(An)	d	(An)	4(An, Xi)	At	s.W	AŁ	s.L	d(PC)	d(PC.XI)	d=1	mmed SR/CC	Opendo S	it Pattern	Boolean	Conditio
Operation	Size	Mede	1	=		#	-	#	-	Ħ	-	Ħ	-	#	-	n	-	Ħ	-	25	4	#	-	n	-	#		5432 1098	7654 3210		XNZVC
L, LSR great Shift	B W	count: #1~8 count: Dn count: #1~8	d:	2 2	6 + 2n 6 + 2n 8 + 2n 8 + 2n			2.	12	2.	12	2.	14	4 -	16	4.	18	4.	16	6*	20							1110 rrrf 1110 QQgf 1110 rrrf 1110 QQgf 1110 001f	SSIO IDDD SSOO IDDD 1010 IDDD 1000 IDDD 11EE EEEE	C Left C Right	***0
I VE ve Data		s-On s-An s-(An)	d:	2 2 2 2	4 4 8 8	M	IOVEA IOVEA IOVEA	2 2 2 2	8 8 12	2 2 2 2	8 8 12	2 2 2	8 8 12 12	4 4 4	12 12 16 16	4 4 4 4	,14 14 18 18	4 4 4 4	12 12 16 16	6 6 6	16 16 20 20							OOSS RRRM	MMee eece	s →d	- ** 0
		s d(An) s d(An X) s Abs W s Abs L s d(PC) s d(PCX) s Imm	d d d d d d	2 4 4 4 6 4 4	10 12 14 12 16 12 14 8	M M M M M M M M M M M M M M M M M M M	IOVEA IOVEA IOVEA IOVEA IOVEA IOVEA	2 4 4 4 6 4 4	14 16 18 16 20 16 18 12	2 4 4 4 4 4	14 16 18 16 20 16 18 12	2 4 4 4 6 4 4	14 16 18 16 20 16 18	4 6 6 6 8 6 6	18 20 22 20 24 20 22 16	4 6 6 6 6 6 6	20 22 24 22 26 22 24 18	4 6 6 6 6 6 6	18 20 22 20 24 20 22 16	6 8 8 10 8 8	22 24 26 24 28 24 26 20										
	L	s An s (An) s (An) s (An) s d(An) s d(An X) s Abs W	d d d d d d	2 2 2 2 4 4	4 4 12 12 14 16 18 16	M M M M	IOVEA IOVEA IOVEA IOVEA IOVEA IOVEA	2 2 2 2 4 4 4	24 26 24	2 2 2 2 4 4 4 4	24 26 24	2 2 2 2 4 4 4 4	12 12 20 20 22 24 26 24	4 4 4 6 6 6	16 16 24 24 26 28 30 28	4 4 4 6 6 6	18 18 26 26 28 30 32 30	4 4 4 6 6 6	16 16 24 24 26 28 30 28	6 6 6 8 8 8 8	20 20 28 28 30 32 34 32										
IVE ve to Con	×	s d(PC) s d(PCx) s imm	d d	6 4 4 6 2	20 16 18 12 12	N	IOVEA IOVEA IOVEA	6 4 4 6 2	28 24 26 20 16	4 4 6 2	28 24 26 20 16	4 4 6 ?	28 24 26 20 18	6 6 8	32 28 30 24 20	6 6 8	34 30 32 26 22	6 6 8	32 28 30 24 20	10 8 8 10 6	36 32 34 28 24	4	20	4	22	4	16	0100 0100	llee eerc	s *COR	****
on Codes VE ve to from	w	d SR s SR	s d	2 2	12			2 2	16 12	2 2	16 12	2 2	18 14	4 4	20 16	4 4	22 18	4	20 16	6	24 20	4	20	4	22	4	16	0100 0110	THE EEEE	s •SR d →MPU SR •d	****
IVE ve to from er SP(A7)	τ		d			?	4				100			100	515													0100 1110	0110 IAAA 0110 OAAA	USP +An An +USP	
VEA ve Address VEM ve Multiple gisters	W L W	d An s Xn	s d	?	4 4	2 ?	4 4	2 2 4	8 12 8 · 4 12 · 4		8 12 12 · 4	2 2 4	10 14 8 • 4	4 6 6	12 16 12 - 4:	102.0	14 18 14 - 44	15	12 16 12 · 4 16 · 4		16 20 16 - 4n 20 - 4n	4 4	12 16	4 4	14 18	6	8 12	0011 AAA0 0010 AAA0 0100 1000 a7-a0 0100 1100 a7-a0	0 cc cccc 0 cc cccc 10EE EEEE d7 - d0 t 10 ee eeee d7 - d0	s +An Xn +d s +Xn ***	
OVEP	· w		d s					4	12 - 8	1 4	12 - 8	ln d	8 · 8r	6	16-8	6	14 · 8r		12 - 8r 16 - 8r	0	16 - 8n 20 - 8n	6	16 - 8	n 6	18 - 8n			0100 1000 a7~a0 0100 1100 a7~a0	11EE EEEE d7~d0+ 11ee eeee d7~d0 1000 IAAA	Xn +d s +Xn *** On +d by bytes	
ripheral OVEQ	1	s d(An) s Dn s d(An)	d d	4 2	16 24 4				165					4	24			100								100		0000 DDD1 0000 DDD1 0000 DDD1 0111 DDD0	0000 IAAA 1100 IAAA 0100 IAAA QQQQ QQQQ	s *On by bytes On *d by bytes s *On by bytes ## *On	-**0
ove Ouick ULS ultiply ned	w	d Dh	5	2	- 70			2	. 7		- 74		- 76	4	- 78	4	- 80		. 78	6	. 82	4	. 78		. 80	4	< 74	IIOO DDDI	Hee eeee	Dn × s +On	-**0
ultiply signed	*			2	- 70			2	1	2		1 2	< 76	4	· 78	4	< 80	4	< 78	6	< 82	4	< 78	4	< 80	4	< 74	0100 DDD0	OOEE EEEE	On × s • On O d10 - X • d	***0
co pate Digit 6 pate Anary	B W	2000000		2 2	4	ls.		2 2	12 20	2 2	12	2 2	14 22	4	16 24	4	18 26	4 4	16 24	6	20 28							0100 0100	SSEE EEEE	0-4-4	****
cision	8 W		d	2 2	4	100	Livering	2 2	12 20	2 2	12 20	2 2	14 22	4 4	16 24	4 4	18 26	4	16 24	6	20 28		- ryk-stock		F-36-98-2-9			0100 0000	SSEE EEEE	0 - *d x +d	****
gical mplement	B W		d	2	6			2	12 20	2 2	20	2 33	14 22	4	16 24	4	18 26	4	16 24	6	20 28							0100 0110	SSEE EEEE	-4 -6	- **0
t dusive OR gical	8 W	d Dn	d s d	2	4			2 2 2 2	12 8 20 14	2 2 2	12 8 20	2 2 2 2	14 10 22 16	4 4 4	16 12 24 18	4 4 4	18 14 26 20	4 4	16 12 24 18	6 6 6	20 16 28 22	4	12	4	14	4	8	1000 DDD1 1000 DDD0 1000 DDD1	SSEE EEEE SSee eeee 10EE EEEE	d < or > Dn → d Dn < or > s → Dn d < or > Dn → d Dn < or > s → Dn	-**01
RI Immediate EA sh Effect	B W	s-lmm	d d	4	8 16			6 2	16	6	16	6	18 32	6 8 4	20 34 18	6 8 4	22 36 22	6 8 4	20 34 18	8 10 6	24 38 22	4	18	4	22	4	20	0100 1000	SSEE EEEE	d <or> # →d s → (SP)</or>	-**0
Address DR, ROL tate thout X	B W L W	count: #1-8 count: Dh count: #1-8	d d d d d	2 2 2 2	6 + 2n 6 + 2n 8 + 2n 8 + 2n			2.	12	2*	12	2.	14	4.	16	4.	18	4.	16	6*	20							1110 rrrf 1110 qqqf 1110 rrrf 1110 qqqf 1110 011f	SSII IDDD SSOI IDDD 1011 IDDD 1001 IDDD 11EE EEEE	Right n	- **0

(to be continued)



Mnomenie	2120	Addr.		C)n		An	(An)	(A	+ (n	-	(An)	d(An)	d(An.Xi)	Ab	s.W	A	s.L	d(PC)	di	PC.Xi)	3 =1 d = 9	mmed SR/CC	Opcode 8	it Pattern	Boolean	Codes
Operation	2(20	Mode		#		#	-	22		#		2	4	=	7	#	-	n		Ħ		#		#		=		5432 1098	7654 3210		XNZVC
OXR,ROXL state crough X	B W	count:Dn	d:	2 2	6 + 2r 6 + 2r 8 + 2r 8 + 2r																							1110 rrrf 1110 QQQf 1110 rrrf 1110 QQQf	SS11 0DDD SS01 0DDD 1011 0DDD 1001 0DDD	Right n X	***0
emory BGB abtract	W B	count 1 s=Dn s (An)	d:	2	6			2.	12	2.	12	2.	14	4.	16	4.	18	4.	16	6.	20							1000 RRR1	DOOD OFFE 0000 OFFE 0000 Terr	CX Left n	*!!*!!
ets t n ditionally	8	cc	d	2	6 4	660	10000	2	12	2	12	2	14	4	16	4	18	4	16	6	20							0101 CCCC	THEE EEEE	d →MPU If cc true I's •d Else O's •d	CARREN
UB obtract nary	B W	s=On d=On s=On d=On	# 8: # 4: # 5:	2	4	2.	SUBA 4 SUBA 8	2 2 2 2	12 8 20 14	2 2 2 2	12 8 20 14	2 2 2 2 2	14 10 22 16	4 4 4 4	16 12 24 18	4 4 4	18 14 26 20	4 4 4	15 12 24 18	6 6 6	20 16 28 22	4	12	4	14	4	8	1001 DDD1 1001 DDD0 1001 DDD1 1001 DDD0	SSEE EEEE SSee eeee 10EE EEEE 10ee eeee	d Dn +d Dn s +Dn d Dn +d Dn s +Dn	****
UBA btract dress	W L	d: An d: An	5	2	8	2	8	2 2	12	2	12	2	14 16	4	16 18	4	18 20	4	16 18	6	20 22	4	16 18	4	18 20	6	12	1001 AAA0	lice eeee	An s +An	
UMI biract	BW	s-imm s-imm	d d	6	16		SUBA	6	16 28	6	16 28	6	18 30	8	20 32	8	22. 34	8	20 32	10	24 36							0000 0100	SSEE EEEE	d = •d	****
mediate UBQ btract ick	B W	s:Imm3 s:Imm3	d d	2 2	4 8	2.	4 8	2	12 16	2 2	12 16	2 2	14 22	4	16 24	4	18 26	4	16 24	6	20 28	14355	olumbo	1000		Less	Printer	0101 QQQ1	SSEE EEEE	d = ·d	****
UBX ibtract ultiprecision	B W	s=Dn s= (An) s=Dn s= (An)	4 4 4	2	8							2	18															1001 RRR1 1001 RRR1 1001 RRR1 1001 RRR1	\$\$00 Orer \$\$00 Irrr 1000 Orrr 1000 Irrr	Dn(31.16) · ·	****
WAP wap Regis r Halves	w B	· Anna anna anna	d	2	4	No.	2000	2	14	2	95148	2	16	4	18	4	20	4	18	6	22	a steet		1000	1000	1000	1474737	0100 1000	0100 ODDD	Dn(150)	-**0
st and Set lerand												i i																		1 *bit 7 of d	
ST est	B W		d d:	2	4			2	8 12	2 2	8 12	2 2	10 14	4	12 16	4	14 18	4	12 16	6	16 20							0100 1010	SSEE EEEE	test d •cc	- **0
NLK link						2	12							100														0100 1110	0101 1444	An 15P (SP) · · An	••••
e e anch inditionally	B W	di di																						a not bra	taken taken taken	2 2 4 4	10 8 10	0110 CCC	PPPP PPPP	if cc true PC · disp ·PC	
RA anch weys	8 W		SD SD									1986		1000				Distance of the last of the la					gr.	a not	184611	2 4	10	0110 0000	PPPP PPPP	PC + disp +PC	
B R an ch	8		Sp																							2	20	0110 0001	PPPP PPPP	PC + (SP) PC + disp +PC	
Subroutine Bos ic rement punter, & anch Until in dition rus or	*	disp-imm count	ter:		10 17 14	120	ase true laise		tord or	Br	anch yes no no																N	0101 CCCC	1100 1000	If cc false On 1 *On & if On = LPC-disp *PC Else, NOP	
MP mp to	190000	Ballan Parker	d:	0350	10000	1.85	A CONTRACT	2	8		22002	September 1	2000	4	10	4	14	4	10	6	12	4	10	4	14	1020	22.20	0100 1110	THEE EEEE	d •PC	
mp to broutine			d:					2	16					•	18	4	22	4	18	6	20	*	18	4	22			0100 1110	10EE EEEE	PC · (SP) d ·PC	
Operation				2	4														-		-				-		. NOTES TO	0100 1110	0111 0001	assert RESET pin	
ESET iset Exter- it Devices TE				2	20																		100					0100 1110	0111 0001	(SP) • • SR	••••
eturn from acception TR eturn from				2	20																							0100 1110	0111 0111	(2b) + +bC (2b) + +bC	****
eturn from u broutine (lestore CC 1 TS leturn from			100	2	16																							0100 1110	0111 0101	(SP) + +PC	
ubroutine TOP and SR/Stop				2	34																			A COUNTY		•	1	0100 1110	0111 0010 0100 VVVV	# +SR Wait for Interrupt PC + (SSP)	***
rap	1000		2000	-	34	Te	p tak	in	2000		2550	0000	THE REAL PROPERTY.		2000	1000		2.500	2004	1000	200	200	1000	200	1000	N OR	e de la constante de la consta	0100 1110	0111 0110	SR + (SSP) (Vector) +PC	
red if werflow Set				2		Tre	p not				800												15	N STATES		SALES OF				(SSP) SR + (SSP) (TRAPY vector) +PC vise. NOP	
ote: Refer to as for Word only Maximum to Number of Number of	condit	dition Code Colon Code.	ompi	utati	ons					Sour	ess Re Condi Regis ce Effi ination	ective	Addr	ss Addres	15	0.	Direct Destin Displa Quick Source	ion, 0 ation cemer Imme	EA M	i. 1 – L ode	Bit F	R. S.	Destina Size 0 0 1 1 Vector	ation 0 - By 1 - W 0 - Lo	Regist rte ord ong Wo nother	er rd Opera	ition	(in the MOVE ins 01 - Byte 10 - Long Word 11 - Word	truction		

■ INSTRUCTION FORMAT SUMMARY

This provides a summary of the first word in each instruction of the instruction set. Table 26 is an operation code (op-code) map which illustrates how bits 15 through 12 are used to specify the operations. The remaining paragraph groups the

instructions according to the op-code map.
where, Size; Byte = 00 Sz; Word = 0
Word = 01 Long Word = 1

Table 26 Operation Code Map

Bits 15 thru 12	Operation
0000	Bit Manipulation/MOVEP/Immediate
0001	Move Byte
0010	Move Long
0011	Move Word
0100	Miscellaneous
0101	ADDQ/SUBQ/S _{CC} /DB _{CC}
0110	B _{CC}
0111	MOVEQ
1000	OR/DIV/SBCD
1001	SUB/SUBX
1010	(Unassigned)
1011	CMP/EOR
1100	AND/MUL/ABCD/EXG
1101	ADD/ADDX
1110	Shift/Rotate
1111	(Unassigned)

(1) BIT MANIPULATION, MOVE PERIPHERAL, IMMEDIATE INSTRUCTIONS

Dynamic Bit

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0		Registe	r	1	Ту	/ре		Е	ffective	e Addre	ess	

Static Bit

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	1	0	0	0	Ty	ре		Е	ffective	Addre	:SS	

Bit Type Codes: TST = 00, CHG = 01, CLR = 10, SET = 11

MOVEP

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0		Register		(p-Mod	le	0	0	1		Registe	r

Op-Mode; Word to Reg = 100, Long to Reg = 101, Word to Mem = 110, Long to Mem = 111

OR Immediate

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	0	0	Si	ze		E	ffective	Addre	ss	

AND Immediate

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	0	1	0	Si	ze		Е	ffective	Addre	ss	

SH	н	Immed	ilate

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	1	0	0	Si	ize		E	ffective	Addre	ss	

ADD Immediate

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	0	1	1	0	Si	ze		E	ffective	Addre	ss	

EOR Immediate

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	1	0	1	0	Si	ze		E	ffective	Addre	ess	

CMP Immediate

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	0	0	0	1	1	0	0	S	ize		E	ffective	Addre	ss	

(2) MOVE BYTE INSTRUCTION

MOVE Byte

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
		0	1			Desti	nation					Sou	ırce		
0	0	0	'		Register	r	1	Mode			Mode		1	Registe	r

(3) MOVE LONG INSTRUCTION

MOVE Long

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0		1	0			Desti	nation					So	urce		
U	0	1	0		Register	r		Mode			Mode		1	Registe	r

(4) MOVE WORD INSTRUCTION

MOVE Word

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
_		1	1			Desti	nation					Sou	ırce		
U	0	'	'	1	Register	r		Mode			Mode			Registe	r

(5) MISCELLANEOUS INSTRUCTIONS

NEGX

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	0	0	0	Şi	ze		E	ffective	Addre	ss	

MOVE from SR

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	0	0	0	1	1		E	ffective	Addre	ess	

CLR

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	0	1	0	S	ize		Е	ffective	Addre	ss	

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	1	0	0	Si	ze		E	ffective	Addre	SS	

MOVE to CCR

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	1	0	0	1	1		E	ffective	Addre	SS	

NOT

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	1	1	0	Si	ze		Е	ffective	Addre	:SS	

MOVE to SR

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	0	1	1	0	1	1		Е	ffective	Addre	ess	

NBCD

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	0	0	0	0		E	ffective	Addre	ss	

PEA

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	0	0	0	1		Е	ffective	Addre	ss	

SWAP

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	0	0	0	1	0	0	0	-	Registe	r

MOVEM Registers to EA

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	0	0	1	Sz		Е	ffective	Addre	ess	

EXTW

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	0	0	1	0	0	0	0	F	Registe	r

EXTL

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	0	0	1	1	0	0	0		Registe	r

TST

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	0	0	1	0	1	0	Si	ze		E	ffective	Addre	ess	

TAS

15	5	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0		1	0	0	1	0	1	0	1	1		E	ffective	Addre	SS	

MOVEM E	A to R	egister	'S													
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	0	0	1	Sz		Ef	fective	Addre	ess	
TRAP																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	0	0		Ved	ctor	
LINK																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	0	1	0	. 1	Register	
UNLK																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	0	1	1		Register	
MOVE to U	JSP															
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	0	0		Register	
														-	3	
MOVE from																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	0	1		Register	
RESET																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	1	0	0	0	0
NOP																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	1	0	0	0	1
STOP																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	1	0	0	1	0
RTE						31										
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	1	0	0	1	1
								1					-		1	
RTS								-	_	_	-		-	-		6
	15	14	13	12	11	10	9	8	7	6	5	1	3	2	0	0
		1 '	1 0	0		Ι,		1 0		1			1 0	1	1 0	-
TRAPV																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	0	1	0	0	1	1	1	0	0	1	1	1	0	1	1	0

MOVEQ

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
0	1	1	1		Registe	r	0				Di	ata			

(9) OR, I	DIVIDE	, SUE	TRAC	CT DE	CIM	AL IN	STRU	СТІО	NS							
OR	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	0	0	0		Register		0	p-Mod	e		Ef	fective	Addre	ss	
DIVU		W 001 0	p-Mode L 10 10	Dn ∨ EA ∨												
5	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	0	0	0		Register		0	1	1		Ef	ffective	Addre	ss	
DIVS	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	0	0	0	1	Register		1	1	1			ffective	100		
											1					
SBCD	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	0	0	0		estinatio Register		1	0	0	0	0	R/M	Sou	rce Reg	gister
	D/M	Ironiat	0 = / == 0	marul				r = 0	mama	FV .	nomor	· - 1				
(40) 0(10)						ster – r				1 y — 1	nemor	γ – 1				
(10) SUB	TRACT	, SUB	TRAC	; I EX	LEN	DED I	NS I F	10011	ONS							
SUB	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	0	0	1	F	Register		0	p-Mode	,		Ef	fective	Addres	SS	
SUBX		14	10	EA-D An-E	A → A		9	8	7	6	5	4	3	2	1	0
	1	0	0	1		Register		1	Si	ze	0	0	R/M	Sou	rce Reg	gister
	R/M	(regist	er/mei	nory)	regis	ter – r	egiste	r = 0,	memo	ry – r	nemor	y = 1				
(11) COM	MPARE	, EXC	LUSI	VE O	R IN	STRUC	OITS	1S								
CMP	4.5		40	10		10	0	0	-	C	-	4	2	2	1	0
	15	14	13	12	11	10 Register	9	8	7 Op-Mod	6	5	4 F	3 ffective	2 Addre	1	U
		1	Op-Mod	1		riegistei			JP WIOC				11001140	ridari		
	B 000 —	W 001 (L 010 111	Dn-E An-E												
CMPM	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	0	1	1	T	Registe	r	1	S	ze	0	0	1		Registe	er
			-		-											
EOR	45		10	10	11	10	9	8	7	c	5	4	3	2	1	0
	15	14	13	12	11	10 Registe		1	7	6 ize	5		ffective	-		
(12) AN					ECIM				1		TIONS		. Trective	Addi	633	
	D, IVIO		., AL	וט טי	LOTIVI	AL, E.	NOI IF		11401	1100	.0143					
AND	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	1	0	0		Registe	r		Op-Mod	de		Е	ffective	Addr	ess	
	В	w	Dp-Mod L	le												
	000 100	001)10 110	Dn ^ EA ^	EA -											

	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
	1	1	0	0		Registe	r	0	1	1		Е	ffective	Addre	ess	
AL II C																
MULS	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	C
	1	1	0	0		Registe	r	1	1	1		E	ffective	Addre	ess	
ABCD	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	(
	1	1	0	0		estinati Registe		1	0	0	0	0	R/M	Sour	rce Re	giste
	R/M	registe	er/mei	mory)	regis	ter – r	egiste	r = 0,	memo	ry – r	nemor	y = 1				
XGD			4.0	40		10	0	0	-	0	5		2	2		,
	15	14	13	12	11	10 ta Regi	9	8	7	6	0	0	3	2	1 ta Regi	istor
			0		Da	ta riegi	2161								ta rieg	3101
EXGA																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	(
	1	1	0	0	Add	ress Re	gister	1	0	1	0	0	1	Addi	ress Re	gist
EXGM																
	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	(
	1	1	0	0	Da	ta Regis	ster	1	1	0	0	0	1	Addr	ress Re	giste
13) ADI) VDC	FYT	END	ם וע	ISTRI	ICTIO	NS									
	, ADD	LAI	LIVUI	-0 111	101110	,0110	140									
ADD	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	(
	1	1	0	1	1	Registe			Op-Mod		T	E	ffective		ess	
		0	p-Mod	e						-						
	В	W	L													

ADDX

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
1	1	0	1		estinati Registe		1	Si	ze	0	0	R/M	Sou	rce Reg	gister

R/M (register/memory): register - register = 0, memory - memory = 1

(14) SHIFT/ROTATE INSTRUCTIONS

Data Register Shifts

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
1	1	1	0	Cou	int/Reg	ister	d	Si	ze	i/r	Ту	ре	1	Registe	r

Memory Shifts

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
1	1	1	0	0	Ту	ре	d	1	1		Е	ffective	Addre	ss	

Shift Type Codes: AS = 00, LS = 01, ROX = 10, RO = 11 d (direction): Right = 0, Left = 1 i/r (count source): Immediate Count = 0, Register Count = 1



■ INSTRUCTION EXECUTION TIMES

The following paragraphs contain listings of the instruction execution times in terms of external clock (CLK) periods. In this timing data, it is assumed that both memory read and write cycle times are four clock periods. Any wait states caused by a longer memory cycle must be added to the total instruction time. The number of bus read and write cycles for each instruction is also included with the timing data. This data is enclosed in parenthesis following the execution periods and is shown as: (r/w) where r is the number of read cycles and w is the number of write cycles.

(NOTE) The number of periods includes instruction fetch and all applicable operand fetches and stores.

EFFECTIVE ADDRESS OPERAND CALCULATION TIMING

Table 27 lists the number of clock periods required to compute an instruction's effective address. It includes fetching of any extension words, the address computation, and fetching of the memory operand. The number of bus read and write cycles is shown in parenthesis as (r/w). Note there are no write cycles involved in processing the effective address.

MOVE INSTRUCTION CLOCK PERIODS

Table 28 and 29 indicate the number of clock periods for the move instruction. This data includes instruction fetch, operand reads, and operand writes. The number of bus read and write cycles is shown in parenthesis as: (r/w).

STANDARD INSTRUCTION CLOCK PERIODS

The number of clock periods shown in Table 30 indicates

the time required to perform the operations, store the results, and read the next instruction. The number of bus read and write cycles is shown in parenthesis as: (r/w). The number of clock periods and the number of read and write cycles must be added respectively to those of the effective address calculation where indicated.

In Table 30 the headings have the following meanings: An = address register operand, Dn = data register operand, ea = an operand specified by an effective address, and M = memory effective address operand.

IMMEDIATE INSTRUCTION CLOCK PERIODS

The number of clock periods shown in Table 31 includes the time to fetch immediate operands, perform the operations, store the results, and read the next operation. The number of bus read and write cycles is shown in parenthesis as: (r/w). The number of clock periods and the number of read and write cycles must be added respectively to those of the effective address calculation where indicated.

In Table 31, the headings have the following meanings: # = immediate operand, Dn = data register operand, An = address register operand, M = memory operand, CCR = condition code register, and SR = status register.

SINGLE OPERAND INSTRUCTION CLOCK PERIODS

Table 32 indicates the number of clock periods for the single operand instructions. The number of bus read and write cycles is shown in parenthesis as: (r/w). The number of clock periods and the number of read and write cycles must be added respectively to those of the effective address calculation where indicated.

Table 27 Effective Address Calculation Timing

	Addressing Mode	Byte, Word	Long
Dn An	Register Data Register Direct Address Register Direct	0(0/0) 0(0/0)	0(0/0) 0(0/0)
An@ An@ +	Memory Address Register Indirect Address Register Indirect with Postincrement	4(1/0) 4(1/0)	8(2/0) 8(2/0)
An@ -	Address Register Indirect with Predecrement	6(1/0)	10(2/0)
An@(d)	Address Register Indirect with Displacement	8(2/0)	
An@(d, ix)*	Address Register Indirect with Index	10(2/0)	14(3/0
xxx.W	Absolute Short	8(2/0)	12(3/0
xxx. L	Absolute Long Program Counter with Displacement	12(3/0)	16(4/0
PC@(d)		8(2/0)	12(3/0
PC@(d, ix)*	Program Counter with Index	10(2/0)	14(3/0
#xxx	Immediate	4(1/0)	8(2/0

^{*} The size of the index register (ix) does not affect execution time.

Table 28 Move Byte and Word Instruction Clock Periods

0	Destination										
Source	Dn	An	An@	An@+	An@ -	An@(d)	An@(d, ix)*	xxx.W	xxx. L		
Dn	4(1/0)	4(1/0)	8(1/1)	8(1/1)	8(1/1)	12(2/1)	14(2/1)	12(2/1)	16(3/1)		
An	4(1/0)	4(1/0)	8(1/1)	8(1/1)	8(1/1)	12(2/1)	14(2/1)	12(2/1)	16(3/1)		
An@	8(2/0)	8(2/0)	12(2/1)	12(2/1)	12(2/1)	16(3/1)	18(3/1)	16(3/1)	20(4/1)		
An@+	8(2/0)	8(2/0)	12(2/1)	12(2/1)	12(2/1)	16(3/1)	18(3/1)	16(3/1)	20(4/1)		
An@-	10(2/0)	10(2/0)	14(2/1)	14(2/1)	14(2/1)	18(3/1)	20(3/1)	18(3/1)	22(4/1)		
An@(d)	12(3/0)	12(3/0)	16(3/1)	16(3/1)	16(3/1)	20(4/1)	22(4/1)	20(4/1)	24(5/1)		
An@(d, ix)*	14(3/0)	14(3/0)	18(3/1)	18(3/1)	18(3/1)	22(4/1)	24(4/1)	22(4/1)	26(5/1)		
xxx. W	12(3/0)	12(3/0)	16(3/1)	16(3/1)	16(3/1)	20(4/1)	22(4/1)	20(4/1)	24(5/1)		
xxx. L	16(4/0)	16(4/0)	20(4/1)	20(4/1)	20(4/1)	24(5/1)	26(5/1)	24(5/1)	28(6/1)		
PC@(d)	12(2/0)	12(3/0)	16(3/1)	16(3/1)	16(3/1)	20(4/1)	22(4/1)	20(4/1)	24(5/1)		
PC@(d,ix)*	14(3/0)	14(3/0)	18(3/1)	18(3/1)	18(3/1)	22(4/1)	24(4/1)	22(4/1)	26(5/1)		
#xxx	8(2/0)	8(2/0)	12(2/1)	12(2/1)	12(2/1)	16(3/1)	18(3/1)	16(3/1)	20(4/1)		

^{*} The size of the index register (ix) does not affect execution time.

Table 29 Move Long Instruction Clock Periods

C	Destination										
Source	Dn	An	An@	An@ +	An@ -	An@(d)	An@(d, ix)*	xxx.W	xxx. L		
Dn	4(1/0)	4(1/0)	12(1/2)	12(1/2)	12(1/2)	16(2/2)	18(2/2)	16(2/2)	20(3/2)		
An	4(1/0)	4(1/0)	12(1/2)	12(1/2)	12(1/2)	16(2/2)	18(2/2)	16(2/2)	20(3/2)		
An@	12(3/0)	12(3/0)	20(3/2)	20(3/2)	20(3/2)	24(4/2)	26(4/2)	24(4/2)	28(5/2)		
An@ +	12(3/0)	12(3/0)	20(3/2)	20(3/2)	20(3/2)	24(4/2)	26(4/2)	24(4/2)	28(5/2)		
An@ -	14(3/0)	14(3/0)	22(3/2)	22(3/2)	22(3/2)	26(4/2)	28(4/2)	26(4/2)	30(5/2)		
An@(d)	16(4/0)	16(4/0)	24(4/2)	24(4/2)	24(4/2)	28(5/2)	30(5/2)	28(5/2)	32(6/2)		
An@(d, ix)*	18(4/0)	18(4/0)	26(4/2)	26(4/2)	26(4/2)	30(5/2)	32(5/2)	30(5/2)	34(6/2)		
xxx. W	16(4/0)	16(4/0)	24(4/2)	24(4/2)	24(4/2)	28(5/2)	30(5/2)	28(5/2)	32(6/2)		
xxx. L	20(5/0)	20(5/0)	28(5/2)	28(5/2)	28(5/2)	32(6/2)	34(6/2)	32(6/2)	36(7/2)		
PC@(d)	16(4/0)	16(4/0)	24(4/2)	24(4/2)	24(4/2)	28(5/2)	30(5/2)	28(5/2)	32(6/2)		
PC@(d,ix)*	18(4/0)	18(4/0)	26(4/2)	26(4/2)	26(4/2)	30(5/2)	32(5/2)	30(5/2)	34(6/2)		
#xxx	12(3/0)	12(3/0)	20(3/2)	20(3/2)	20(3/2)	24(4/2)	26(4/2)	24(4/2)	28(5/2)		

^{*} The size of the index register (ix) does not affect execution time.

Table 30 Standard Instruction Clock Periods

Instruction	Size	op < ea >, An	op < ea >, Dn	op Dn, < M >
400	Byte, Word	8(1/0) +	4(1/0) +	8(1/1) +
ADD	Long	6(1/0) + **	6(1/0) + **	12(1/2) +
AND	Byte, Word	_	4(1/0) +	8(1/1) +
AND	Long	_	6(1/0) + **	12(1/2) +
CMP	Byte, Word	6(1/0) +	4(1/0) +	-
CIVIP	Long	6(1/0) +	6(1/0) +	-
DIVS		_	158(1/0) + *	_
DIVU		_	140(1/0) + *	_
FOR	Byte, Word	_	4(1/0) ***	8(1/1) +
EOR	Long	_	8(1/0) ***	12(1/2) +
MULS	<u>~</u>)	-	70(1/0) + *	-
MULU	-	-	70(1/0) + *	_
OB	Byte, Word	_	4(1/0) +	8(1/1) +
OR	Long	_	6(1/0) + **	12(1/2) +
SUB	Byte, Word	8(1/0) +	4(1/0) +	8(1/1) +
308	Long	6(1/0) + **	6(1/0) + **	12(1/2) +

⁺ add effective address calculation time

MULU; n = the number of ones in the < ea > MULU; n = concatanate the < ea > with a zero as the LSB; n is the resultant number of 10 or 01 patterns in the 17-bit source; i.e. worst case happens when the source is \$5555.



^{**} total of 8 clock periods for instruction if the effective address is register direct

^{*} indicates maximum value

^{***} only available effective address mode is data register direct

DIVS, DIVU - The divide algorithm used by the 68000 provides less than 10% difference between the best and worst case timings.

MULS, MULU - The multiply algorithm requires 38+2n clocks when n is defined as

Table 31 Immediation Instruction Clock Periods

Instruction	Size	op #, Dn	op #, An	op #, M	op #, CCR/SF
ADDI	Byte, Word	8(2/0)	_	12(2/1) +	_
ADDI	Long	16(3/0)	_	20(3/2) +	_
ADDQ	Byte, Word	4(1/0)	8(1/0)*	8(1/1) +	_
ADDQ	Long	8(1/0)	8(1/0)	12(1/2) +	_
ANDI .	Byte, Word	8(2/0)	_	12(2/1) +	20(3/0)
ANDI	Long	16(3/0)	-	20(3/1) +	_
CAADI	Byte, Word	8(2/0)	8(2/0)	8(2/0) +	-
CMPI	Long	14(3/0)	14(3/0)	12(3/0) +	=
FORI	Byte, Word	8(2/0)	_	12(2/1) +	20(3/0)
EORI	Long	16(3/0)	_	20(3/2) +	_
MOVEQ	Long	4(1/0)	_	-	-
ORI	Byte, Word	8(2/0)	-	12(2/1) +	20(3/0)
ONI	Long	16(3/0)	_	20(3/2) +	
SUBI	Byte, Word	8(2/0)		12(2/1) +	_
3001	Long	16(3/0)	-	20(3/2) +	_
SUBQ	Byte, Word	4(1/0)	8(1/0)*	8(1/1) +	_
SUBU	Long	8(1/0)	8(1/0)	12(1/2) +	_

⁺ add effective address calculation time

Table 32 Single Operand Instruction Clock Periods

Instruction	Size	Register	Memory
OL D	Byte, Word	4(1/0)	8(1/1) +
CLR	Long	6(1/0)	12(1/2) +
NBCD	Byte	6(1/0)	8(1/1) +
NEC	Byte, Word	4(1/0)	8(1/1) +
NEG	Long	6(1/0)	12(1/2) +
NECY	Byte, Word	4(1/0)	8(1/1) +
NEGX	Long	6(1/0)	12(1/2) +
NOT	Byte, Word	4(1/0)	8(1/1) +
NOT	Long	6(1/0)	12(1/2) +
c	Byte, False	4(1/0)	8(1/1) +
Scc	Byte, True	6(1/0)	8(1/1) +
TAS	Byte	4(1/0)	10(1/1) +
TST	Byte, Word	4(1/0)	4(1/0) +
131	Long	4(1/0)	4(1/0) +

⁺ add effective address calculation time

SHIFT/ROTATE INSTRUCTION CLOCK PERIODS

Table 33 indicates the number of clock periods for the shift and rotate instructions. The number of bus read and write cycles is shown in parenthesis as: (r/w). The number of clock periods and the number of read and write cycles must be added respectively to those of the effective address calculation where indicated.

BIT MANIPULATION INSTRUCTION CLOCK PERIODS

Table 34 indicates the number of clock periods required for the bit manipulation instructions. The number of bus read and write cycles is shown in parenthesis as: (r/w). The number of clock periods and the number of read and write cycles must be added respectively to those of the effective address calculation where indicated.

^{*} word only

CONDITIONAL INSTRUCTION CLOCK PERIODS

Table 35 indicates the number of clock periods required for the conditional instructions. The number of bus read and write cycles is indicated in parenthesis as: (r/w). The number of clock periods and the number of read and write cycles must be added respectively to those of the effective address calculation where indicated.

JMP, JSR, LEA, PEA, MOVEM INSTRUCTION CLOCK PERIODS

Table 36 indicates the number of clock periods required for the jump, jump to subroutine, load effective address, push effective address, and move multiple registers instructions. The number of bus read and write cycles is shown in parenthesis as: (r/w).

Table 33 Shift/Rotate Instruction Clock Periods

Instruction	Size	Register	Memory	
4CD 4CI	Byte, Word	6 + 2n(1/0)	8(1/1) +	
ASR, ASL	Long	8 + 2n(1/0)	-	
	Byte, Word	6 + 2n(1/0)	8(1/1) +	
LSR, LSL	Long	8 + 2n(1/0)	_	
	Byte, Word	6 + 2n(1/0)	8(1/1) +	
ROR, ROL	Long	8 + 2n(1/0)	_	
DOVE DOVI	Byte, Word	6 + 2n(1/0)	8(1/1) +	
ROXR, ROXL	Long	8 + 2n(1/0)		

Table 34 Bit Manipulation Instruction Clock Periods

1	C:	Dyn	amic	Static		
Instruction	Size	Register	Memory	Register	Memory	
DOLLO	Byte	-	8(1/1) +	-	12(2/1) +	
BCHG	Long	8(1/0)*	_	12(2/0)*	-	
DOL D	Byte	_	8(1/1) +	-	12(2/1) +	
BCLR	Long	10(1/0)*	_	14(2/0)*	_	
DOET	Byte	_	8(1/1) +	-	12(2/1) +	
BSET	Long	8(1/0)*	-	12(2/0)*	-	
DICT	Byte	_	4(1/0) +	_	8(2/0) +	
BTST	Long	6(1/0)	_	10(2/0)	_	

⁺ add effective address calculation time

Table 35 Conditional Instruction Clock Periods

Instruction	Displacement	Trap or Branch Taken	Trap of Branch Not Taken
D	Byte	10(2/0)	8(1/0)
B _{CC}	Word	10(2/0)	12(2/0)
DDA	Byte	10(2/0)	_
BRA	Word	10(2/0)	_
BSR	Byte	18(2/2)	_
BSH	Word	18(2/2)	_
D.D.	CC true	_	12(2/0)
DB _{CC}	CC false	10(2/0)	14(3/0)
СНК	_	40(5/3) + *	10(1/0) +
TRAP	-	34(4/3)	_
TRAPV	_	34(5/3)	4(1/0)

⁺ add effective address calculation time

^{*} indicates maximum value

^{*} indicates maximum value

Table 36 JMP, JSR, LEA, PEA, MOMEM Instruction Clock Periods

Instr	Size	An@	An@+	An@ -	An@(d)	An@(d, ix) *	xxx.W	xxx. L	PC@(d)	PC@(d, ix) *
JMP	_	8(2/0)	_	-	10(2/0)	14(3/0)	10(2/0)	12(3/0)	10(2/0)	14(3/0)
JSR	_	16(2/2)	_	_	18(2/2)	22(2/2)	18(2/2)	20(3/2)	18(2/2)	22(2/2)
LEA	-	4(1/0)	_	-	8(2/0)	12(2/0)	8(2/0)	12(3/0)	8(2/0)	12(2/0)
PEA	_	12(1/2)	-	-	16(2/2)	20(2/2)	16(2/2)	20(3/2)	16(2/2)	20(2/2)
MOVEM	Word	12+4n (3+n/0)	12+4n (3+n/0)	-	16+4n (4+n/0)	18+4n (4+n/0)	16+4n (4+n/0)	20+4n (5+n/0)	16+4n (4+n/0)	18+4n (4+n/0)
$M \rightarrow R$	Long	12+8n (3+2n/0)	12+8n (3+2n/0)	_	16+8n (4+2n/0)	18+8n (4+2n/0)	16+8n (4+2n/0)	20+8n (5+2n/0)	16+8n (4+2n/0)	18+8n (4+2n/0)
MOVEM	Word	8+4n (2/n)	_	8+4n (2/n)	12+4n (3/n)	14+4n (3/n)	12+4n (3/n)	16+4n (4/n)	_	_
$R \rightarrow M$	Long	8+8n (2/2n)	_	8+8n (2/2n)	12+8n (3/2n)	14+8n (3/2n)	12+8n (3/2n)	16+8n (4/2n)	_	_

n is the number of registers to move

MULTI-PRECISION INSTRUCTION CLOCK PERIODS

Table 37 indicates the number of clock periods for the multiprecision instructions. The number of clock periods includes the time to fetch both operands, perform the operations, store the results, and read the next instructions. The number of read and write cycles is shown in parenthesis as: (r/w).

In Table 37, the headings have the following meanings: Dn = data register operand and M = memory operand.

Table 37 Multi-Precision Instruction Clock Periods

Instruction	Size	op Dn, Dn	op M, M
400V	Byte, Word	4(1/0)	18(3/1)
ADDX	Long	8(1/0)	30(5/2)
014014	Byte, Word	-	12(3/0)
СМРМ	Long	_	20(5/0)
0.15.4	Byte, Word	4(1/0)	18(3/1)
SUBX	Long	8(1/0)	30(5/2)
ABCD	Byte	6(1/0)	18(3/1)
SBCD	Byte	6(1/0)	18(3/1)

MISCELLANEOUS INSTRUCTION CLOCK PERIODS

Table 38 indicates the number of clock periods for the following miscellaneous instructions. The number of bus read and write cycles is shown in parenthesis as: (r/w). The number of clock periods plus the number of read and write cycles must be added to those of the effective address calculation where indicated.

EXCEPTION PROCESSING CLOCK PERIODS

Table 39 indicates the number of clock periods for exception processing. The number of clock periods includes the time for all stacking, the vector fetch, and the fetch of the first instruction of the handler routine. The number of bus read and write cycles is shown in parenthesis as: (r/w).

^{*} is the size of the index register (ix) does not affect the instruction's execution time

Table 38 Miscellaneous Instruction Clock Periods

Instruction	Size	Register	Memory	Register → Memory	Memory → Register
MOVE from SR	_	6(1/0)	8(1/1) +	_	_
MOVE to CCR	_	12(2/0)	12(2/0) +	-	_
MOVE to SR	_	12(2/0)	12(2/0) +	_	_
MOVEP	Word	_	_	16(2/2)	16(4/0)
	Long	-	_	24(2/4)	24(6/0)
EXG	_	6(1/0)	_	_	_
EVT	Word	4(1/0)	_	_	-
EXT	Long	4(1/0)	_	-	-
LINK	_	16(2/2)	-	-	_
MOVE from USP	_	4(1/0)	-	_	-
MOVE to USP	_	4(1/0)	_	_	_
NOP	-	4(1/0)	-	-	_
RESET	_	132(1/0)	_	-	_
RTE	_	20(5/0)	_	-	_
RTR	_	20(5/0	1-1	_	_
RTS	_	16(4/0)	_	_	_
STOP	_	4(0/0)	_	-	-
SWAP	_	4(1/0)	-	_	_
UNLK	-	12(3/0)	_	-	_

⁺ add effective address calculation time

Table 39 Exception Processing Clock Periods

Exception	Periods 38.5 (6/0)	
Reset * *		
Address Error	50(4/7)	
Bus Error	50(4/7)	
Interrupt	44(5/3)*	
Illegal Instruction	34(4/3)	
Privileged Violation	34(4/3)	
Trace	34(4/3)	

The interrupt acknowledge bus cycle is assumed to take four external clock periods.

■ MASK VERSION

Type No.	Mask version	
HD68000-6 HD68000-8		
HD68000-10 HD68000-12	68000S1	
HD68000Y6 HD68000Y8 HD68000Y10 HD68000Y12	0600031	
HD68000P6 HD68000P8 HD68000PS6 HD68000PS8 HD68000CP6 HD68000CP8	68000U	

The difference of function between mask version 68000S1 and 68000U is only as following (Figure 59).

The function of HD68HC000 is as same as mask version 68000U.

^{**} Indicates the time from when RES and HALT are first sampled as negated to when instruction execution starts.

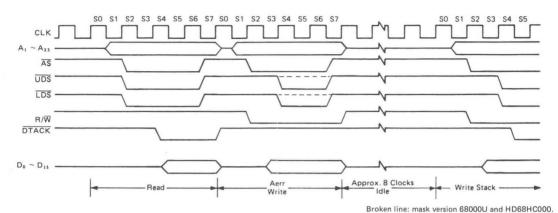


Figure 59 Address Error Timing

NOTE FOR USE

Power Supply Circuit

When designing V_{CC} and V_{SS} pattern of the circuit board, the capacitors need to be located nearest to V_{CC} and V_{SS} as shown in the Figure 60.

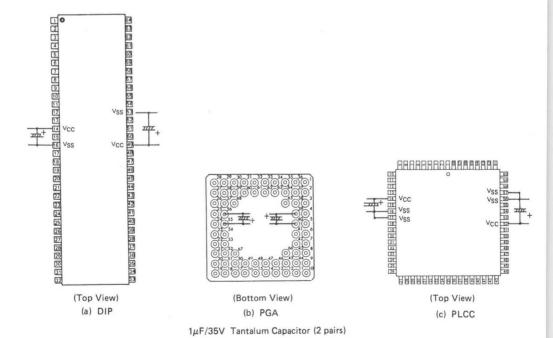


Figure 60 Power Supply Circuit



